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Information technology - Serial Attached SCSI - 5 (SAS-5)

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American National Standard
for Information Technology

Serial Attached SCSI - 5 (SAS-5)

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ABSTRACT

This standard specifies the functional requirements for the Serial Attached SCSI (SAS) physical interconnect, which is compatible with the Serial ATA physical interconnect. The SAS Protocol Layer - 5 (SPL-5) standard documents the SAS protocol layer corresponding to the Serial Attached SCSI - 4.1 (SAS-4.1). This standard is intended to be used in conjunction with SCSI and ATA command set standards.

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Revision Information

R.1 Revision SAS-5r00 (18 May 2018)

First release of SAS-5. The project proposal was 18-024r1.

Incorporated these:

- a) this revision contains the physical contents of the SAS-4 standard;
- b) removal of connectors and cable assemblies that only support slower speeds; and
- c) removal of untrained 1.5 Gbit/s, 3 Gbit/s, and 6 Gbit/s;
- d) removal of trained 1.5 Gbit/s and 3 Gbit/s.

R.2 Revision SAS-5r00a (20 July 2018)

Incorporated these:

- a) 18-080r0 SAS-5 mark up of SAS-4 corrections to fix cross references [Cox].

R.3 Revision SAS-5r01 (10 December 2018)

Incorporated these:

- a) 18-119r0 SAS-5 decoupling capacitor restriction change [Cox].

R.4 Revision SAS-5r01a (22 February 2019)

Incorporated these:

- a) Added missing Revision Information page.

R.5 Revision SAS-5r01b (26 December 2024)

Incorporated these:

- a) Started with sources for SAS-4.1 r04.
- b) Grey-ed out the those parts of the SAS-5 revision history that identified documents not listed in the SAS-4.1 r04 revision history, but kept that for reference and continuity.
- c) Changed editor contact information to the new editor, including changes to the currently preferred format for said information.
- d) Updated the points of contact page.
- e) Disabled FrameMaker change tracking, which this editor declines to use.

Skimmed theses (SAS-4.1 r04) sources to verify the inclusion of these:

- a) 19-028r1 Removal of High Density Drive connector from SAS-4.1 (Alvin Cox, Seagate) [FWIW the application of this proposal in SAS-4.1 was directly visible in the SAS-5 r01b PDF file (i.e., the SAS-5 r01b PDF file is 7 pages shorter than the SAS-5 r01a PDF file).];
- b) 19-120r1 Clarifications to 22.5 Gb/s SAS-4.1 Jitter Measurements and Common Mode (John Gardner, Broadcom);
- c) 19-127r0 SAS-4.1 editorial updates to Table 3 (Alvin Cox, Seagate);
- d) 22-012r0 SAS-4.1 Annex G, proposal (John Gardner, Broadcom) [This review surfaced and fixed an a) b) list that started with e).];
- e) 22-020r2 SAS-4.1 editorial and referenced documents updates (Alvin Cox, Seagate); and
- f) 22-042r2 SAS-4.1 comment resolution updates (Alvin Cox, Seagate).

Reviewed to verify and/or perform the incorporation of previously mentioned documents to ensure the incorporation of these:

- a) 18-080r0 SAS-5 mark up of SAS-4 corrections to fix cross references [Cox]
[In a handful of cases, the 18-080r0 markups appear to be Alvin's notes to himself; thus any amount of change in the seemingly right direction was taken as the right changes (e.g. in 5.8.3.3)]; and
- b) 18-119r0 SAS-5 decoupling capacitor restriction change (Alvin Cox, Seagate).

R.6 Revision SAS-5r02 (28 December 2024)

Incorporated this:

- a) 24-028r1 SAS-5: Add SFF-TA-1016 connectors (Brad Besmer, Broadcom).

During the incorporation of 24-028r1, a couple of instances of '...is the is the mechanical...' were changed to '...is the mechanical...'.

Contents

	Page
FOREWARD	xx
INTRODUCTION.....	xxi
1 Scope	1
2 Normative references	3
3 Definitions, symbols, abbreviations, keywords, and conventions	5
3.1 Definitions.....	5
3.2 Symbols and abbreviations	16
3.2.1 Abbreviations	16
3.2.2 Units.....	18
3.2.3 Symbols	19
3.2.4 Mathematical operators	20
3.3 Keywords.....	20
3.4 Editorial conventions	21
3.5 Numeric and character conventions	22
3.5.1 Numeric conventions	22
3.5.2 Units of measure.....	23
3.5.3 Byte encoded character strings conventions	24
4 General	25
4.1 Physical links and phys	25
4.2 Phy test functions	25
5 Physical layer.....	26
5.1 Physical layer overview	26
5.2 Conventions for defining maximum limits for S-parameters	26
5.3 Compliance points.....	27
5.3.1 Compliance points overview	27
5.3.2 6 Gbit/s compliance points.....	28
5.3.3 12 Gbit/s compliance points.....	36
5.3.4 22.5 Gbit/s compliance points.....	38
5.4 Interconnects	40
5.4.1 SATA connectors and cable assemblies	40
5.4.2 SAS connectors and cables.....	41
5.4.3 Connectors.....	45
5.4.3.1 Connectors overview.....	45
5.4.3.2 Connector categories	48
5.4.3.3 SAS internal connectors.....	48
5.4.3.3.1 SAS Drive connectors.....	48
5.4.3.3.1.1 SAS Drive plug connector	48
5.4.3.3.1.2 SAS Drive cable connector	49
5.4.3.3.1.3 SAS Drive backplane connector	50
5.4.3.3.1.4 SAS Drive connector pin assignments.....	51
5.4.3.3.1.5 SAS MultiLink Drive plug connector	53
5.4.3.3.1.6 SAS MultiLink Drive cable connector	53
5.4.3.3.1.7 SAS MultiLink Drive backplane connector	54
5.4.3.3.1.8 SAS MultiLink Drive connector pin assignments.....	54
5.4.3.3.1.9 Micro SAS plug connector.....	58
5.4.3.3.1.10 Micro SAS receptacle connector	58
5.4.3.3.1.11 Micro SAS connector pin assignments	59
5.4.3.3.2 Mini SAS HD internal connectors	60
5.4.3.3.2.1 Mini SAS HD 4i cable plug connector	60
5.4.3.3.2.2 Mini SAS HD 8i cable plug connector	61

5.4.3.3.2.3 Mini SAS HD 4i receptacle connector	62
5.4.3.3.2.4 Mini SAS HD 8i receptacle connector	63
5.4.3.3.2.5 Mini SAS HD 16i receptacle connector	64
5.4.3.3.2.6 Mini SAS HD 4i connector pin assignments	65
5.4.3.3.3 SlimSAS internal connectors	67
5.4.3.3.3.1 SlimSAS 4i cable plug connector	67
5.4.3.3.3.2 SlimSAS 8i cable plug connector	67
5.4.3.3.3.3 SlimSAS 4i receptacle connector	68
5.4.3.3.3.4 SlimSAS 8i receptacle connector	69
5.4.3.3.3.5 SlimSAS connector pin assignments	70
5.4.3.3.4 SAS MiniLink internal connectors	76
5.4.3.3.4.1 SAS MiniLink 4i cable plug connector	76
5.4.3.3.4.2 SAS MiniLink 8i cable plug connector	77
5.4.3.3.4.3 SAS MiniLink 4i receptacle connector	78
5.4.3.3.4.4 SAS MiniLink 8i receptacle connector	79
5.4.3.3.4.5 SAS MiniLink connector pin assignments	80
5.4.3.3.5 SlimSAS HD internal connectors	86
5.4.3.3.5.1 SlimSAS HD 4i cable plug connector	86
5.4.3.3.5.2 SlimSAS HD 8i cable plug connector	87
5.4.3.3.5.3 SlimSAS HD 16i cable plug connector	87
5.4.3.3.5.4 SlimSAS HD 4i receptacle connector	88
5.4.3.3.5.5 SlimSAS HD 8i receptacle connector	89
5.4.3.3.5.6 SlimSAS HD 16i receptacle connector	89
5.4.3.3.5.7 SlimSAS HD connector pin assignments	91
5.4.3.4 SAS external connectors	105
5.4.3.4.1 Mini SAS HD external connectors	105
5.4.3.4.1.1 Mini SAS HD 4x cable plug connector	105
5.4.3.4.1.2 Mini SAS HD 8x cable plug connector	106
5.4.3.4.1.3 Mini SAS HD 4x receptacle connector	107
5.4.3.4.1.4 Mini SAS HD 8x receptacle connector	108
5.4.3.4.1.5 Mini SAS HD 16x receptacle connector	109
5.4.3.4.1.6 Mini SAS HD 4x connector pin assignments	110
5.4.3.4.1.7 Mini SAS HD external connector management interface	111
5.4.3.4.1.8 Mini SAS HD external connector memory map	112
5.4.3.4.2 QSFP connectors	112
5.4.3.4.2.1 QSFP cable plug	112
5.4.3.4.2.2 QSFP receptacle	113
5.4.3.4.2.3 QSFP connector pin assignments	114
5.4.3.4.2.4 QSFP memory map	115
5.4.4 Cable assemblies	116
5.4.4.1 SAS internal cable assemblies	116
5.4.4.1.1 SAS Drive cable assemblies	116
5.4.4.1.2 SAS internal symmetric cable assemblies	119
5.4.4.1.2.1 SAS internal symmetric cable assemblies overview	119
5.4.4.1.2.2 SAS internal symmetric cable assembly - Mini SAS HD 4i	120
5.4.4.1.2.3 SAS internal symmetric cable assembly - Mini SAS HD 8i	121
5.4.4.1.2.4 SAS internal symmetric cable assembly - SlimSAS 4i	122
5.4.4.1.2.5 SAS internal symmetric cable assembly - SlimSAS 4i to Mini SAS HD 4i	123
5.4.4.1.2.6 SAS internal symmetric cable assembly - SlimSAS 8i	124
5.4.4.1.2.7 SAS internal symmetric cable assembly - SlimSAS 8i to Mini SAS HD 8i	125
5.4.4.1.2.8 SAS internal symmetric cable assembly - SAS MiniLink 4i	126
5.4.4.1.2.9 SAS internal symmetric cable assembly - SAS MiniLink 4i to Mini SAS HD 4i	127
5.4.4.1.2.10 SAS internal symmetric cable assembly - SAS MiniLink 8i	128
5.4.4.1.2.11 SAS internal symmetric cable assembly - SAS MiniLink 8i to Mini SAS HD 8i	129
5.4.4.1.3 SAS internal fanout cable assemblies	130
5.4.4.1.3.1 SAS internal fanout cable assemblies overview	130
5.4.4.1.3.2 SAS internal controller-based fanout cable assembly - Mini SAS HD 4i to SAS Drive	131

5.4.4.1.3.3 SAS internal controller-based fanout cable assembly - SlimSAS 4i to SAS Drive	132
5.4.4.1.3.4 SAS internal controller-based fanout cable assembly - SlimSAS 4i to SATA signal.....	133
5.4.4.1.3.5 SAS internal controller-based fanout cable assembly - SlimSAS 8i to SlimSAS 4i	134
5.4.4.1.3.6 SAS internal controller-based fanout cable assembly - SlimSAS 8i to Mini SAS HD 4i	135
5.4.4.1.3.7 SAS internal controller-based fanout cable assembly - SAS MiniLink 4i to SAS Drive.	136
5.4.4.1.3.8 SAS internal controller-based fanout cable assembly - SAS MiniLink 4i to SATA signal	137
5.4.4.1.3.9 SAS internal controller-based fanout cable assembly - SAS MiniLink 8i to SAS MiniLink 4i	138
5.4.4.1.3.10 SAS internal controller-based fanout cable assembly - SAS MiniLink 8i to Mini SAS HD 4i	139
5.4.4.1.3.11 SAS internal backplane-based fanout cable assembly - SATA signal to Mini SAS HD 4i	140
5.4.4.2 SAS external cable assemblies	141
5.4.4.2.1 SAS external cable assemblies overview	141
5.4.4.2.2 SAS external cable assembly - Mini SAS HD 4x	142
5.4.4.2.3 SAS external cable assembly - Mini SAS HD 8x	144
5.4.4.2.4 SAS external cable assembly - Mini SAS HD 8x to Mini SAS HD 4x	146
5.4.4.2.5 SAS external cable assembly - QSFP	147
5.5 TxRx connection characteristics	148
5.5.1 TxRx connection characteristics overview	148
5.5.2 TxRx connection general characteristics	149
5.5.3 Passive TxRx connection S-parameter limits	150
5.5.4 Passive TxRx connection characteristics for untrained 6 Gbit/s	152
5.5.5 Passive TxRx connection characteristics for trained 6 Gbit/s	152
5.5.6 Passive TxRx connection characteristics for trained 12 Gbit/s	154
5.5.7 Passive TxRx connection electrical characteristics for trained 22.5 Gbit/s	158
5.5.7.1 Passive TxRx connection electrical characteristics for trained 22.5 Gbit/s overview	158
5.5.7.2 Passive TxRx connection insertion loss for trained 22.5 Gbit/s	159
5.5.7.3 Passive TxRx connection fitted insertion loss for trained 22.5 Gbit/s	160
5.5.7.4 Passive TxRx connection insertion loss deviation for trained 22.5 Gbit/s	160
5.5.7.5 Passive TxRx connection integrated crosstalk noise for trained 22.5 Gbit/s	161
5.5.7.6 Passive TxRx maximum limits for SCD21-SDD21 for trained 22.5 Gbit/s between PT and PR	162
5.5.7.7 Passive TxRx maximum limits for SDD22 for trained 22.5 Gbit/s between PT and PR	163
5.5.7.8 Passive TxRx maximum limits for SCD22 for trained 22.5 Gbit/s between PT and PR	163
5.5.8 TxRx connection characteristics for active cable assemblies	164
5.5.8.1 Active cable assembly electrical characteristics for trained 6 Gbit/s overview	164
5.5.8.2 Active cable assembly output electrical characteristics for trained 6 Gbit/s	164
5.5.8.3 Active cable assembly S-parameter limits for trained 6 Gbit/s, trained 12 Gbit/s, and trained 22.5 Gbit/s	165
5.5.8.4 Active cable assembly electrical characteristics overview for 12 Gbit/s and 22.5 Gbit/s	166
5.5.8.5 Active cable assembly electrical characteristics for 12 Gbit/s and 22.5 Gbit/s	167
5.6 Test loads	168
5.6.1 Test loads overview	168
5.6.2 Zero-length test load	169
5.6.3 TCTF test load	171
5.6.4 Trained 6 Gbit/s reference transmitter test load	176
5.7 End to end simulation for trained 12 Gbit/s	179
5.7.1 End to end simulation for trained 12 Gbit/s overview	179
5.7.2 Usage models for end to end simulation for trained 12 Gbit/s	180
5.7.3 Reference transmitter equalization for trained 12 Gbit/s	181
5.7.4 Crosstalk measurement for end to end simulations and 12 Gbit/s jitter tolerance	183
5.8 Transmitter device and receiver device electrical characteristics	185
5.8.1 General electrical characteristics	185
5.8.2 Transmitter device and receiver device transients	186
5.8.3 Eye masks and the JTF	187
5.8.3.1 Eye masks overview	187

5.8.3.2 JTF	187
5.8.3.3 Transmitter device eye mask for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s	188
5.8.3.4 Receiver device eye mask for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s	189
5.8.3.5 Receiver device jitter tolerance eye mask for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s..	189
5.8.4 Transmitter device characteristics	190
5.8.4.1 Transmitter device characteristics overview.....	190
5.8.4.2 Transmitter device coupling requirements	191
5.8.4.3 Transmitter device general electrical characteristics.....	191
5.8.4.4 Transmitter device OOB signal output characteristics for rates of 1.5 Gbit/s and 3 Gbit/s as measured with the zero-length test load	192
5.8.4.5 Transmitter device signal output characteristics for trained 6 Gbit/s.....	193
5.8.4.5.1 Transmitter device signal output characteristics for trained 6 Gbit/s overview	193
5.8.4.5.2 Trained 6 Gbit/s transmitter device test procedure.....	194
5.8.4.5.3 Trained 6 Gbit/s transmitter device S-parameter limits.....	195
5.8.4.5.4 Recommended trained 6 Gbit/s transmitter device settings for interoperability.....	196
5.8.4.5.5 Trained 6 Gbit/s reference transmitter device characteristics.....	196
5.8.4.5.6 Trained 6 Gbit/s transmitter equalization, VMA, and $V_{P,P}$ measurement	198
5.8.4.6 Transmitter device signal output characteristics for trained 12 Gbit/s.....	200
5.8.4.6.1 Transmitter device signal output characteristics for trained 12 Gbit/s overview	200
5.8.4.6.2 Transmitter device equalization for trained 12 Gbit/s and 22.5 Gbit/s	203
5.8.4.6.3 12 Gbit/s transmitter device S-parameter limits	208
5.8.4.6.4 12 Gbit/s reference transmitter device	209
5.8.4.6.5 Transmitter device end to end simulation characteristics for trained 12 Gbit/s	211
5.8.4.6.6 Transmitter device signal output characteristics at CTS for 12 Gbit/s when an active cable is connected	212
5.8.4.7 Transmitter device signal output characteristics for trained 22.5 Gbit/s.....	213
5.8.4.7.1 Transmitter device signal output characteristics for trained 22.5 Gbit/s overview	213
5.8.4.7.2 Transmitter device equalization for trained 22.5 Gbit/s	215
5.8.4.7.3 22.5 Gbit/s transmitter device S-parameter limits.....	215
5.8.4.7.4 22.5 Gbit/s transmitter device jitter measurements	217
5.8.4.7.5 Transmitter device signal output characteristics at CTS for 22.5 Gbit/s when an active cable is connected	218
5.8.4.8 Transmitter device signal output characteristics for OOB signals	218
5.8.5 Receiver device characteristics	220
5.8.5.1 Receiver device characteristics overview.....	220
5.8.5.2 Receiver device coupling requirements	220
5.8.5.3 Receiver device general electrical characteristics.....	221
5.8.5.4 Delivered signal characteristics for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s.....	223
5.8.5.5 Maximum delivered jitter for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s	224
5.8.5.6 Receiver device jitter tolerance for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s	225
5.8.5.7 Receiver device and delivered signal characteristics for trained 6 Gbit/s, 12 Gbit/s, and 22.5 Gbit/s.....	226
5.8.5.7.1 Delivered signal characteristics for trained 6 Gbit/s, 12 Gbit/s, and 22.5 Gbit/s.....	226
5.8.5.7.2 Receiver device S-parameter limits	226
5.8.5.7.3 Reference receiver device characteristics	228
5.8.5.7.3.1 Reference receiver device overview	228
5.8.5.7.3.2 Reference receiver device DFE	230
5.8.5.7.3.3 Reference receiver device equalization for trained 12 Gbit/s.....	230
5.8.5.7.4 Reference receiver device termination characteristics for trained 6 Gbit/s.....	231
5.8.5.7.5 Reference receiver device termination characteristics for trained 12 Gbit/s.....	231
5.8.5.7.6 Stressed receiver device jitter tolerance test	232
5.8.5.7.6.1 Stressed receiver device jitter tolerance test overview for trained 6 Gbit/s.....	232
5.8.5.7.6.2 Stressed receiver device jitter tolerance test procedure for trained 6 Gbit/s.....	234
5.8.5.7.6.3 Test equipment and ISI generator calibration for trained 6 Gbit/s.....	235
5.8.5.7.6.4 Crosstalk source calibration for trained 6 Gbit/s	235
5.8.5.7.6.5 Stressed receiver device jitter tolerance test procedure for trained 12 Gbit/s.....	236
5.8.5.7.6.6 ISI generator calibration for trained 12 Gbit/s	236

5.8.5.7.6.7 Crosstalk calibration for trained 12 Gbit/s stressed receiver device jitter tolerance test	239
5.8.5.7.6.8 Applied RJ for trained 12 Gbit/s stressed receiver device jitter tolerance test	239
5.8.5.7.6.9 Stressed receiver device jitter tolerance test procedure for trained 22.5 Gbit/s	239
5.8.5.7.6.10 Applied SJ	241
5.8.5.8 Delivered signal characteristics for OOB signals	243
5.8.6 Spread spectrum clocking (SSC)	243
5.8.6.1 SSC overview	243
5.8.6.2 Transmitter SSC modulation	244
5.8.6.3 Receiver SSC modulation tolerance	245
5.8.6.4 Expander device center-spreading tolerance buffer	246
5.8.7 Non-tracking clock architecture	247
5.9 READY LED signal electrical characteristics	247
5.10 POWER DISABLE signal electrical characteristics	248
5.11 Out of band (OOB) signals	250
5.11.1 OOB signals overview	250
5.11.2 Transmitting OOB signals	251
5.11.3 Receiving OOB signals	253
5.11.4 Transmitting the SATA port selection signal	254
Annex A (Normative) Jitter tolerance pattern (JTPAT)	255
Annex B (Normative) SASWDP	257
Annex C (Normative) End to end simulation for trained 12 Gbit/s	258
C.1 Detailed end to end simulation procedure description for trained 12 Gbit/s	258
C.2 Trained 12 Gbit/s usage models, S-parameter files, and crosstalk amplitude	260
C.2.1 Transmitter device connected to a separable passive TxRx connection segment	260
C.2.2 Transmitter device connected to a non-separable passive TxRx connection segment	262
C.2.3 TxRx connection segment	265
C.2.4 Stressed receiver device delivered signal calibration end to end simulation diagram	266
Annex D (Informative) StatEye	268
Annex E (Informative) 12 Gbit/s S-parameters and end to end simulation	269
E.1 S-parameters for 12 Gbit/s simulation	269
E.1.1 Measurement procedure	269
E.1.2 Multiple channel segments	270
E.2 End to end simulation using SAS3_EYEOPENING	271
Annex F (Informative) Fitted insertion loss, frequency weighting function, and integrated crosstalk noise calculation methods	272
F.1 Fitted insertion loss	272
F.2 Frequency weighting function	275
F.3 Integrated crosstalk noise	275
Annex G (Informative) Signal performance measurements	277
G.1 Signal performance measurements overview	277
G.2 Glossary	277
G.3 Simple physical link	277
G.3.1 Simple physical link overview	277
G.3.2 Assumptions for the structure of the transmitter device and the receiver device	278
G.3.3 Definition of receiver sensitivity and receiver device sensitivity	279
G.4 Signal measurement architecture	280
G.4.1 General	280
G.4.2 Relationship between signal compliance measurements at interoperability points and operation in systems	280
G.5 De-embedding connectors in test fixtures	281

G.6 De-embedding test fixture for 12 Gbit/s transmitter compliance	281
G.7 Measurement conditions for signal output at the transmitter device	282
G.8 Measurement conditions for signal tolerance at the transmitter device	284
G.9 Measurement conditions for signal output at the receiver device	285
G.10 Measurement conditions for signal tolerance at the receiver device	285
G.11 S-parameter measurements	286
G.11.1 Gain parameter and loss parameter overview	286
G.11.2 S-parameter naming conventions	288
G.11.3 Use of single ended instrumentation in differential applications	289
G.11.4 Measurement configurations for physical link elements	290
G.11.4.1 Measurement configuration overview	290
G.11.4.2 Transmitter device S_{22} measurements	291
G.11.4.3 Receiver device S_{11} measurements	292
G.11.4.4 TxRx connection S_{11} measurements at IT or CT	292
G.11.4.5 TxRx connection S_{22} measurements at IR or CR	293
G.12 Calibration of JMDs	294
G.12.1 Calibration of JMDs overview	294
G.12.1.1 Purpose of JMD calibration	294
G.12.1.2 Overview of low frequency calibration for SSC configurations	294
G.12.1.3 Overview of low frequency calibration for non-SSC configurations	296
G.12.1.4 High frequency calibration	296
G.12.2 JMD calibration procedure	297
G.12.2.1 General characteristics and equipment	297
G.12.2.2 Calibration of the JMD for testing SSC configurations	298
G.12.2.3 Calibration of the JMD for testing non-SSC configurations	299
Annex H (Informative) Description of the included Touchstone models for trained 6 Gbit/s	300
H.1 Description of the included Touchstone models for trained 6 Gbit/s overview	300
H.2 Reference transmitter device termination model for trained 6 Gbit/s	300
H.3 Reference receiver device termination model for trained 6 Gbit/s	301
H.4 Generic return loss circuit model for trained 6 Gbit/s	302
H.5 Reference transmitter test load for trained 6 Gbit/s	303
Annex I (Informative) Recommended electrical performance limits for mated connector pairs supporting rates of 12 Gbit/s	306
Annex J (Informative) Recommended electrical performance limits for mated connector pairs and cable assemblies supporting rates of 22.5 Gbit/s	308
Annex K (Informative) SAS icons	313
Annex L (Informative) Standards bodies contact information	314
Annex M (Informative) Bibliography	315

Tables

	Page
Table 1 — Numbering conventions.....	23
Table 2 — Comparison of decimal prefixes and binary prefixes.....	24
Table 3 — Compliance points.....	28
Table 4 — Connectors.....	45
Table 5 — Connector categories.....	48
Table 6 — SAS Drive connector pin assignments.....	51
Table 7 — SAS MultiLink connector pin assignments.....	55
Table 8 — Micro SAS connector pin assignments.....	59
Table 9 — Controller Mini SAS HD 4i connector pin assignments and physical link usage.....	65
Table 10 — Backplane Mini SAS HD 4i connector pin assignments and physical link usage.....	66
Table 11 — Controller SlimSAS 4i connector pin assignments and physical link usage.....	70
Table 12 — Backplane SlimSAS 4i connector pin assignments and physical link usage.....	71
Table 13 — Controller SlimSAS 8i connector pin assignments and physical link usage.....	72
Table 14 — Backplane SlimSAS 8i connector pin assignments and physical link usage.....	74
Table 15 — Controller SAS MiniLink 4i pin assignments and physical link usage.....	80
Table 16 — Backplane SAS MiniLink 4i pin assignments and physical link usage.....	81
Table 17 — Controller SAS MiniLink 8i connector pin assignments and physical link usage.....	82
Table 18 — Backplane SAS MiniLink 8i connector pin assignments and physical link usage.....	84
Table 19 — Controller SlimSAS HD 4i connector pin assignments and physical link usage.....	91
Table 20 — Backplane SlimSAS HD 4i connector pin assignments and physical link usage.....	92
Table 21 — Controller SlimSAS HD 8i connector pin assignments and physical link usage.....	93
Table 22 — Backplane SlimSAS HD 8i connector pin assignments and physical link usage.....	95
Table 23 — Controller SlimSAS HD 16i connector pin assignments and physical link usage.....	97
Table 24 — Controller SlimSAS HD 16i connector pin assignments and physical link usage.....	101
Table 25 — Mini SAS HD 4x connector pin assignments and physical link usage.....	110
Table 26 — Management interface connection requirements.....	111
Table 27 — QSFP connector pin assignments.....	114
Table 28 — TxRx connection general characteristics.....	149
Table 29 — Maximum limits for S-parameters of the passive TxRx connection between ITS and IR or CTS and CR for 6 Gbit/s and 12 Gbit/s.....	151
Table 30 — Passive TxRx connection characteristics for trained 6 Gbit/s.....	153
Table 31 — Passive TxRx connection characteristics for trained 12 Gbit/s at ET and ER.....	157
Table 32 — Measured S-parameters for passive TxRx connections supporting 22.5 Gbit/s.....	158
Table 33 — Calculated electrical characteristics for passive TxRx connections supporting 22.5 Gbit/s.....	159
Table 34 — Passive TxRx connection fitted insertion loss requirements for trained 22.5 Gbit/s.....	160
Table 35 — Passive TxRx connection ILD requirements for trained 22.5 Gbit/s.....	161
Table 36 — Passive TxRx connection ICN variables for trained 22.5 Gbit/s.....	161
Table 37 — Active cable assembly output electrical characteristics for trained 6 Gbit/s.....	164
Table 38 — Maximum limits for S-parameters for active cable assemblies.....	165
Table 39 — Active cable assembly electrical characteristics for 12 Gbit/s and 22.5 Gbit/s.....	167
Table 40 — General electrical characteristics.....	185
Table 41 — JTF parameters.....	188
Table 42 — Transmitter device general electrical characteristics.....	191
Table 43 — Transmitter device termination characteristics.....	191
Table 44 — Transmitter device OOB signal output characteristics for rates of 1.5 Gbit/s and 3 Gbit/s as measured with the zero-length test load at IT and CT.....	192
Table 45 — Transmitter device signal output characteristics for trained 6 Gbit/s at IT and CT.....	193
Table 46 — Transmitter device common mode voltage limit characteristics.....	194
Table 47 — Maximum limits for S-parameters at IT _S or CT _S	195
Table 48 — Recommended 6 Gbit/s transmitter device settings at IT and CT.....	196
Table 49 — Trained 6 Gbit/s reference transmitter device characteristics at IT and CT.....	197
Table 50 — Transmitter device signal output characteristics for trained 12 Gbit/s at ET, IT, and CT.....	200
Table 51 — 12 Gbit/s transmitter device common mode voltage limit characteristics.....	202
Table 52 — Transmitter coefficient requests and corresponding transmitter circuit response.....	204

Table 53 — Transmitter circuit coefficient presets at ET	207
Table 54 — 12 Gbit/s maximum limits for S-parameters at IT _S or CT _S	208
Table 55 — 12 Gbit/s reference transmitter device characteristics at ET	210
Table 56 — Transmitter device characteristics for trained 12 Gbit/s at ET and ER	211
Table 57 — Transmitter device signal output characteristics for 12 Gbit/s at CTS when an active cable is connected	212
Table 58 — Transmitter device signal output characteristics for trained 22.5 Gbit/s at PT, IT, and CT	213
Table 59 — 22.5 Gbit/s transmitter device common mode voltage limit characteristics	214
Table 60 — 22.5 Gbit/s maximum limits for S-parameters at IT _S or CT _S	215
Table 61 — 22.5 Gbit/s transmitter device maximum limit for S _{DD22} at PT	217
Table 62 — Transmitter device signal output characteristics for 22.5 Gbit/s at CTS when an active cable is connected	218
Table 63 — Transmitter device signal output characteristics for OOB signals	219
Table 64 — Receiver device general electrical characteristics	221
Table 65 — Recommended receiver device common mode tolerance for 6 Gbit/s, 12 Gbit/s, and 22.5 Gbit/s	221
Table 66 — Receiver device termination characteristics	222
Table 67 — Delivered signal characteristics for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s as measured with the zero-length test load at IR and CR	223
Table 68 — Maximum delivered jitter for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s at IR and CR	224
Table 69 — Receiver device jitter tolerance for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s at IR and CR ..	225
Table 70 — f _{min} , f _c , and f _{max} for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s	226
Table 71 — Delivered signal characteristics for trained 6 Gbit/s, 12 Gbit/s, and 22.5 Gbit/s at IR and CR ..	226
Table 72 — Maximum limits for S-parameters at IR or CR	227
Table 73 — 22.5 Gbit/s receiver device maximum limit for S _{DD11} at PR	228
Table 74 — Reference receiver equalization stage characteristics for trained 12 Gbit/s	230
Table 75 — Stressed receiver device jitter tolerance test characteristics for trained 6 Gbit/s	233
Table 76 — Number of bits received per number of errors for desired BER	235
Table 77 — ISI generator characteristics for trained 12 Gbit/s at ET and ER	238
Table 78 — RJ characteristics for trained 12 Gbit/s stressed receiver device tolerance test	239
Table 79 — Test equipment transmitter device signal output characteristics for stressed receiver device testing for trained 22.5 Gbit/s at PT, IT, and CT	240
Table 80 — f _{min} , f _c , and f _{max} for trained 6 Gbit/s, 12 Gbit/s, and 22.5 Gbit/s without SSC support	241
Table 81 — f _{min} , f _c , f _{max} , and S _{Jlf} for trained 6 Gbit/s, 12 Gbit/s, and 22.5 Gbit/s with SSC support	242
Table 82 — Delivered signal characteristics for OOB signals	243
Table 83 — SSC modulation types	243
Table 84 — SAS phy transmitter SSC modulation types	244
Table 85 — Expander phy transmitter SSC modulation types	245
Table 86 — Receiver SSC modulation types tolerance	245
Table 87 — Expander device center-spreading tolerance buffer	246
Table 88 — Output characteristics of the READY LED signal	248
Table 89 — Characteristics of the POWER DISABLE signal applied to the SAS target device	249
Table 90 — OOB signal timing specifications	250
Table 91 — OOB signal transmitter device requirements	251
Table 92 — OOB signal receiver device burst time detection requirements	253
Table 93 — OOB signal receiver device idle time detection requirements	253
Table 94 — OOB signal receiver device negation time detection requirements	253
Table 95 — SATA port selection signal transmitter device requirements	254
Table A.1 — JTPAT for RD+	255
Table A.2 — JTPAT for RD-	256
Table C.1 — Crosstalk transmitter characteristics	259
Table C.2 — S-parameter files for transmitter devices connected to a separable TxRx connection segment	260
Table C.3 — S-parameter files for transmitter devices connected to a non-separable TxRx connection segment	262
Table C.4 — S-parameter files for a TxRx connection segment	265

Table C.5 — S-parameter files for stressed receiver device delivered signal calibration	267
Table D.1 — Python files included in the SAS2_1 directory of SAS-4_1.zip	268
Table G.1 — $ S_{DD21} $ and insertion loss in the linear domain and dB domain.....	287
Table G.2 — $ S_{DD11} $ and return loss in the linear domain and dB domain.....	288
Table G.3 — High frequency jitter source amplitudes.....	297
Table G.4 — Low frequency jitter source calibration amplitudes	299
Table G.5 — Low frequency jitter attenuation targets.....	299
Table I.1 — Recommended electrical performance limits for mated connector pairs supporting rates of 12 Gbit/s.....	306
Table J.1 — Recommended electrical characteristic limits for mated connector pairs supporting rates of 22.5 Gbit/s.....	308
Table J.2 — Mated connector pair ICN variables supporting rates of 22.5 Gbit/s	311
Table J.3 — Recommended ICN limits for mated connector pairs supporting rates of 22.5 Gbit/s	311
Table J.4 — Recommended etch $ S_{DD21} $ for a TFP or a TFR supporting rates of 22.5 Gbit/s.....	312
Table L.1 — Standards bodies.....	314

Figures

	Page
Figure 1 — SCSI document relationships	1
Figure 2 — ATA document relationships	2
Figure 3 — Physical links and phys	25
Figure 4 — Maximum limits for S-parameters definitions	27
Figure 5 — 6 Gbit/s External cable assembly CT compliance points and CR compliance points	29
Figure 6 — Backplane with SAS Drive connector 6 Gbit/s IT compliance points and IR compliance points ...	30
Figure 7 — Backplane with SAS Drive connector 6 Gbit/s compliance points with SATA phy attached	31
Figure 8 — SAS multilane internal cable assembly 6 Gbit/s IT compliance points and IR compliance points	32
Figure 9 — SAS multilane internal cable assembly and backplane 6 Gbit/s IT compliance points and IR compliance points	33
Figure 10 — SAS multilane internal cable assembly and backplane 6 Gbit/s IT compliance points and IR compliance points with SATA device attached	34
Figure 11 — SAS Drive cable assembly 6 Gbit/s IT compliance points and IR compliance points	35
Figure 12 — 12 Gbit/s TxRx connection and compliance points	36
Figure 13 — Simulated 12 Gbit/s TxRx connection and compliance points	36
Figure 14 — 12 Gbit/s CTS and CR compliance points	37
Figure 15 — 22.5 Gbit/s compliance points	38
Figure 16 — 22.5 Gbit/s CTS and CR compliance points	39
Figure 17 — SATA connectors and cables	40
Figure 18 — SAS Drive cable environments	41
Figure 19 — SAS Drive backplane environment	42
Figure 20 — SAS external cable environment	42
Figure 21 — SAS internal symmetric cable environment - controller to backplane	43
Figure 22 — SAS internal symmetric cable environment - controller to controller	43
Figure 23 — SAS internal controller-based fanout cable environment	44
Figure 24 — SAS internal backplane-based fanout cable environment	44
Figure 25 — SAS Drive plug connector	49
Figure 26 — Single-port SAS Drive cable connector	49
Figure 27 — Dual-port SAS Drive cable connector	50
Figure 28 — SAS Drive backplane connector	50
Figure 29 — SAS MultiLink Drive plug connector	53
Figure 30 — SAS MultiLink Drive cable connector	53
Figure 31 — SAS MultiLink Drive backplane connector	54
Figure 32 — Micro SAS plug connector	58
Figure 33 — Micro SAS receptacle connector	58
Figure 34 — Mini SAS HD 4i cable plug connector	60
Figure 35 — Mini SAS HD 8i cable plug connector	61
Figure 36 — Mini SAS HD 4i receptacle connector	62
Figure 37 — Mini SAS HD 8i receptacle connector	63
Figure 38 — Mini SAS HD 16i receptacle connector	64
Figure 39 — SlimSAS 4i cable plug connector	67
Figure 40 — SlimSAS 8i cable plug connector	67
Figure 41 — SlimSAS 4i receptacle connector	68
Figure 42 — SlimSAS 8i receptacle connector	69
Figure 43 — SAS MiniLink 4i cable plug connector	76
Figure 44 — SAS MiniLink 8i cable plug connector	77
Figure 45 — SAS MiniLink 4i receptacle connector	78
Figure 46 — SAS MiniLink 8i receptacle connector	79
Figure 47 — SlimSAS HD 4i cable plug connector	86
Figure 48 — SlimSAS HD 8i cable plug connector	87
Figure 49 — SlimSAS HD 16i cable plug connector	87
Figure 50 — SlimSAS HD 4i receptacle connector	88
Figure 51 — SlimSAS HD 8i receptacle connector	89
Figure 52 — SlimSAS HD 16i receptacle connector	89
Figure 53 — Mini SAS HD 4x cable plug connector	105

Figure 54 — Mini SAS HD 8x cable plug connector	106
Figure 55 — Mini SAS HD 4x receptacle connector	107
Figure 56 — Mini SAS HD 8x receptacle connector	108
Figure 57 — Mini SAS HD 16x receptacle connector	109
Figure 58 — QSFP cable plug connector	112
Figure 59 — QSFP receptacle connector	113
Figure 60 — Single-port SAS Drive cable assembly	116
Figure 61 — Dual-port SAS Drive cable assembly	117
Figure 62 — MultiLink SAS Drive cable assembly	118
Figure 63 — SAS internal symmetric cable assembly - Mini SAS HD 4i	120
Figure 64 — SAS internal symmetric cable assembly - Mini SAS HD 8i	121
Figure 65 — SAS internal symmetric cable assembly - SlimSAS 4i	122
Figure 66 — SAS internal symmetric cable assembly - SlimSAS 4i to Mini SAS HD 4i	123
Figure 67 — SAS internal symmetric cable assembly - SlimSAS 8i	124
Figure 68 — SAS internal symmetric cable assembly - SlimSAS 8i to Mini SAS HD 8i	125
Figure 69 — SAS internal symmetric cable assembly - SAS MiniLink 4i	126
Figure 70 — SAS internal symmetric cable assembly - SAS MiniLink 4i to Mini SAS HD 4i	127
Figure 71 — SAS internal symmetric cable assembly - SAS MiniLink 8i	128
Figure 72 — SAS internal symmetric cable assembly - SAS MiniLink 8i to Mini SAS HD 8i	129
Figure 73 — SAS internal controller-based fanout cable assembly - Mini SAS HD 4i to SAS Drive	131
Figure 74 — SAS internal controller-based fanout cable assembly - SlimSAS 4i to SAS Drive	132
Figure 75 — SAS internal controller-based fanout cable assembly - SlimSAS 4i to SATA signal	133
Figure 76 — SAS internal controller-based fanout cable assembly - SlimSAS 8i to SlimSAS 4i	134
Figure 77 — SAS internal controller-based fanout cable assembly - SlimSAS 8i to Mini SAS HD 4i	135
Figure 78 — SAS internal controller-based fanout cable assembly - SAS MiniLink 4i to SAS Drive	136
Figure 79 — SAS internal controller-based fanout cable assembly - SAS MiniLink 4i to SATA signal	137
Figure 80 — SAS internal controller-based fanout cable assembly - SAS MiniLink 8i to SAS MiniLink 4i	138
Figure 81 — SAS internal backplane-based fanout cable assembly - SAS MiniLink 8i to Mini SAS HD 4i	139
Figure 82 — SAS internal backplane-based fanout cable assembly - SATA signal to Mini SAS HD 4i	140
Figure 83 — SAS external cable assembly - Mini SAS HD 4x	142
Figure 84 — SAS external cable assembly with Mini SAS HD 4x cable plug connectors	143
Figure 85 — SAS external cable assembly - Mini SAS HD 8x	144
Figure 86 — SAS external cable assembly with Mini SAS HD 8x cable plug connectors	145
Figure 87 — SAS external cable assembly - Mini SAS HD 8x to Mini SAS HD 4x	146
Figure 88 — SAS external cable assembly with a Mini SAS HD 8x cable plug connector and two Mini SAS HD 4x cable plug connectors	147
Figure 89 — Passive TxRx connection $ S_{DD22} $, $ S_{CD22} $, $ S_{CD21} $, and NEXT limits for 6 Gbit/s and 12 Gbit/s	152
Figure 90 — Example passive TxRx connection compliance testing for trained 6 Gbit/s	153
Figure 91 — Example passive TxRx connection compliance testing for trained 12 Gbit/s	155
Figure 92 — Passive TxRx connection segment between CTS and CR or ITS and IR end to end simulation diagram for trained 12 Gbit/s	156
Figure 93 — Example TxRx connection for trained 22.5 Gbit/s	158
Figure 94 — Passive TxRx connection differential insertion loss for trained 22.5 Gbit/s	159
Figure 95 — Integrated crosstalk noise limit	162
Figure 96 — Passive TxRx maximum limits for SCD21-SDD21 for trained 22.5 Gbit/s	162
Figure 97 — Passive TxRx maximum limits for SDD22 for trained 22.5 Gbit/s	163
Figure 98 — Passive TxRx maximum limits for SCD22 for trained 22.5 Gbit/s	164
Figure 99 — Active cable S-parameter limits	166
Figure 100 — Active cable eye mask for 12 Gbit/s and 22.5 Gbit/s	167
Figure 101 — Zero-length test load for transmitter device compliance point	169
Figure 102 — Zero-length test load for receiver device compliance point	169
Figure 103 — Zero-length test load $ S_{DD21}(f) $ requirements for 6 Gbit/s and 12 Gbit/s	170
Figure 104 — Zero-length test load $ S_{DD21}(f) $ requirements for 22.5 Gbit/s	171
Figure 105 — TCTF test load	171

Figure 106 — TCTF test load $ S_{DD21}(f) $ and ISI loss requirements at IT for an OOB signaling rate of 3 Gbit/s	172
Figure 107 — TCTF test load $ S_{DD21}(f) $ and ISI loss requirements at CT for an OOB signaling rate of 3 Gbit/s	173
Figure 108 — TCTF test load $ S_{DD21}(f) $ and ISI loss requirements at IT for an OOB signaling rate of 1.5 Gbit/s	174
Figure 109 — TCTF test load $ S_{DD21}(f) $ and ISI loss requirements at CT for an OOB signaling rate of 1.5 Gbit/s	175
Figure 110 — Trained 6 Gbit/s reference transmitter test load $ S_{DD21}(f) $ up to 6 GHz	176
Figure 111 — Trained 6 Gbit/s reference transmitter test load pulse response	177
Figure 112 — Trained 6 Gbit/s reference transmitter test load impulse response for 6 Gbit/s	178
Figure 113 — Trained 6 Gbit/s reference transmitter test load D24.3 response	179
Figure 114 — NEXT and FEXT measurement definition	180
Figure 115 — Reference sampling point and reference pulse response cursor	181
Figure 116 — Reference transmitter coefficient error computation	182
Figure 117 — Convergence of reference transmitter equalization	183
Figure 118 — Transmitter device transient test circuit	186
Figure 119 — Receiver device transient test circuit	186
Figure 120 — Transmitter device eye mask	188
Figure 121 — Receiver device eye mask	189
Figure 122 — Deriving a receiver device jitter tolerance eye mask for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s	190
Figure 123 — Transmitter device common mode voltage limit	194
Figure 124 — Transmitter device $ S_{CC22} $, $ S_{DD22} $, and $ S_{CD22} $ limits	196
Figure 125 — Trained 6 Gbit/s reference transmitter device	197
Figure 126 — Trained 6 Gbit/s reference transmitter device termination S-parameters	198
Figure 127 — Transmitter equalization measurement	199
Figure 128 — 12 Gbit/s transmitter device common mode voltage limit	202
Figure 129 — Minimum and maximum coefficient ranges at maximum peak to peak voltage	203
Figure 130 — Transmitter circuit compliance test configuration	205
Figure 131 — 12 Gbit/s transmitter circuit output waveform	206
Figure 132 — 12 Gbit/s transmitter device $ S_{CC22} $, $ S_{DD22} $, and $ S_{CD22} $ limits	209
Figure 133 — 12 Gbit/s reference transmitter device	209
Figure 134 — 12 Gbit/s reference transmitter	210
Figure 135 — Simulation of the reference transmitter from a captured signal	212
Figure 136 — 22.5 Gbit/s transmitter device common mode voltage limit	214
Figure 137 — 22.5 Gbit/s transmitter device $ S_{CC22} $, $ S_{DD22} $, and $ S_{CD22} $ limits at ITS and CTS	216
Figure 138 — 22.5 Gbit/s transmitter device $ S_{DD22} $ limit at PT	217
Figure 139 — Applied SJ for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s	225
Figure 140 — Receiver device $ S_{CC11} $, $ S_{DD11} $, and $ S_{CD11} $ limits at IR and CR	227
Figure 141 — 22.5 Gbit/s receiver device $ S_{DD11} $ limit at PR	228
Figure 142 — Reference receiver device for trained 6 Gbit/s	229
Figure 143 — Reference receiver device for trained 12 Gbit/s	229
Figure 144 — Reference receiver device termination S-parameters for trained 6 Gbit/s	231
Figure 145 — Stressed receiver device jitter tolerance test block diagram for trained 6 Gbit/s	232
Figure 146 — Stressed receiver device jitter tolerance test D24.3 eye opening for trained 6 Gbit/s	234
Figure 147 — Stressed receiver transmitter equalization adjustment for 12 Gbit/s	236
Figure 148 — Simulation of the reference transmitter from a captured signal	237
Figure 149 — Applied SJ for trained Gbit/s, 12 Gbit/s, and 22.5 Gbit/s without SSC support	241
Figure 150 — Applied SJ for trained 6 Gbit/s, 12 Gbit/s, and 22.5 Gbit/s with SSC support	242
Figure 151 — Center-spreading tolerance buffer	247
Figure 152 — OOB signal transmission	252
Figure 153 — SATA port selection signal	254
Figure C.1 — Trained 12 Gbit/s die to die insertion loss model	258
Figure C.2 — Transmitter device end to end simulation diagram that includes a separable TxRx connection segment	261
Figure C.3 — End to end simulation diagram of the from target device usage model for a transmitter device	

connected to a non-separable TxRx connection segment	263
Figure C.4 — End to end simulation diagram of the to target device usage model for a transmitter device connected to a non-separable TxRx connection segment	264
Figure C.5 — Stressed receiver device delivered signal calibration end to end simulation diagram	266
Figure E.1 — S-parameter measurement connections for a four port VNA	269
Figure E.2 — Example of a SAS three TxRx connection segment	270
Figure G.1 — A simple physical link	277
Figure G.2 — Transmitter device details	278
Figure G.3 — Receiver device details	279
Figure G.4 — De-embedding of connectors in test fixtures	281
Figure G.5 — De-embedding to ET for 12 Gbit/s transmitter compliance	282
Figure G.6 — De-embedding calibration test structure	282
Figure G.7 — Measurement conditions for signal output at the transmitter device	283
Figure G.8 — Transmitter device signal output measurement test fixture details	283
Figure G.9 — Measurement conditions for signal tolerance at the transmitter device	284
Figure G.10 — Calibration of test fixture for signal tolerance at the transmitter device	284
Figure G.11 — Measurement conditions for signal output at the receiver device	285
Figure G.12 — Measurement conditions for signal tolerance at the receiver device	285
Figure G.13 — Calibration of test fixture for signal tolerance at the receiver device	286
Figure G.14 — S-parameter port naming conventions	289
Figure G.15 — Four single ended port or two differential port element	289
Figure G.16 — S-parameters for single ended and differential systems	290
Figure G.17 — Measurement conditions for S_{22} at the transmitter device connector	291
Figure G.18 — Measurement conditions for S_{11} at the receiver device connector	292
Figure G.19 — Measurement conditions for S_{11} at IT or CT	293
Figure G.20 — Measurement conditions for S_{22} at IR or CR	294
Figure H.1 — Reference transmitter device and reference receiver device termination circuit model	300
Figure H.2 — Generic return loss circuit model	302
Figure H.3 — Generic return loss model $ S_{11} $	303
Figure H.4 — Reference transmitter test load measurement setup	304
Figure H.5 — Reference transmitter test load $ S_{DD21}(f) $ up to 20 GHz	305
Figure I.1 — Recommended $ S_{DD21} $, $ S_{CC22} $, $ S_{DD22} $, NEXT, and FEXT limits for connector mated pairs supporting rates of 12 Gbit/s	307
Figure J.1 — Recommended $ S_{DD21} $ limits for connector mated pairs supporting rates of 22.5 Gbit/s	309
Figure J.2 — Recommended $ S_{DD22} $ limit for connector mated pairs supporting rates of 22.5 Gbit/s	309
Figure J.3 — Recommended $ SCD21 $ limit for connector mated pairs supporting rates of 22.5 Gbit/s	310
Figure J.4 — Recommended $ SCD22 $ limit for connector mated pairs supporting rates of 22.5 Gbit/s	310
Figure J.5 — Recommended etch $ S_{DD21} $ for a TFP or a TFR supporting rates of 22.5 Gbit/s	312
Figure K.1 — Primary SAS icon	313
Figure K.2 — MultiLink SAS icon	313

FOREWARD (This foreword is not part of American National Standard INCITS 561.)

This standard defines the physical layer of the Serial Attached SCSI (SAS) interconnect.

This standard contains thirteen annexes. Annexes A, B, and C are normative and are considered part of this standard. Annexes D through M are informative and are not considered part of this standard.

Requests for interpretation, suggestions for improvement and addenda, or defect reports are welcome. They should be sent to the INCITS Secretariat, InterNational Committee for Information Technology Standards, Information Technology Institute, 700 K Street NW, Suite 600, Washington, DC 20001.

This standard was processed and approved for submittal to ANSI by the InterNational Committee for Information Technology Standards (INCITS). Committee approval of the standard does not necessarily imply that all committee members voted for approval. At the time it approved this standard, INCITS had the following members:

Editor's Note 1: <<Insert INCITS member list>>

Technical Committee T10 on SCSI Storage Interfaces, which developed and reviewed this standard, had the following members:

William Martin, Chair
Curtis Ballard, Vice-Chair
Curtis Stevens, Secretary

INTRODUCTION

This standard defines the Serial Attached SCSI (SAS) interconnect.

The standard is organized as follows:

Clause 1 (Scope) describes the relationship of this standard to the SCSI and ATA families of standards.

Clause 2 (Normative references) provides references to other standards and documents.

Clause 3 (Definitions, symbols, abbreviations, keywords, and conventions) defines terms and conventions used throughout this standard.

Clause 4 (General) describes the SAS physical architecture.

Clause 5 (Physical layer) describes the physical layer. It describes passive interconnect components (connectors, cables, and backplanes), the transmitter device and receiver device electrical characteristics, and out of band (OOB) signals.

Normative Annex A (Jitter tolerance pattern (JTPAT)) describes the jitter tolerance patterns.

Normative Annex B (SASWDP) includes the simulation program used for transmitter device and receiver device compliance.

Normative Annex C (End to end simulation for trained 12 Gbit/s) includes end to end simulation procedures and reference S-parameter file descriptions for trained 12 Gbit/s.

Informative Annex D (StatEye) includes a simulation program that may be used for TxRx connection compliance.

Informative Annex E (12 Gbit/s S-parameters and end to end simulation) provides information regarding S-parameter measurement and an end to end simulation tool description for trained 12 Gbit/s.

Informative Annex F (Fitted insertion loss, frequency weighting function, and integrated crosstalk noise calculation methods) describes calculation methods for fitted insertion loss and integrated crosstalk noise.

Informative Annex G (Signal performance measurements) describes signal measurement techniques.

Informative Annex H (Description of the included Touchstone models for trained 6 Gbit/s) provides information about how S-parameter models included with this standard were derived.

Informative Annex I (Recommended electrical performance limits for mated connector pairs supporting rates of 12 Gbit/s) provides recommended electrical performance characteristics for connector mated pairs supporting rates of 12 Gbit/s.

Informative Annex J (Recommended electrical performance limits for mated connector pairs and cable assemblies supporting rates of 22.5 Gbit/s) provides recommended electrical performance characteristics for connector mated pairs supporting rates of 22.5 Gbit/s.

Informative Annex K (SAS icons) defines the SAS icons.

Informative Annex L (Standards bodies contact information) shows standards bodies and their web sites.

Informative Annex M (Bibliography) lists a bibliography for this standard.

**American National Standard
for Information Technology -****Serial Attached SCSI - 5 (SAS-5)****1 Scope**

The SCSI family of standards provides for many different transport protocols that define the rules for exchanging information between different SCSI devices. This standard specifies the functional requirements for the Serial Attached SCSI (SAS) physical interconnect, which is compatible with the Serial ATA physical interconnect. The SAS Protocol Layer - 5 (SPL-5) standard documents the SAS protocol layer corresponding to the Serial Attached SCSI - 4.1 (SAS-4.1) standard, defining the rules for exchanging information between SCSI devices using a serial interconnect. Other SCSI transport protocol standards define the rules for exchanging information between SCSI devices using other interconnects.

Figure 1 shows the relationship of this standard to the other standards and related projects in the SCSI family of standards.

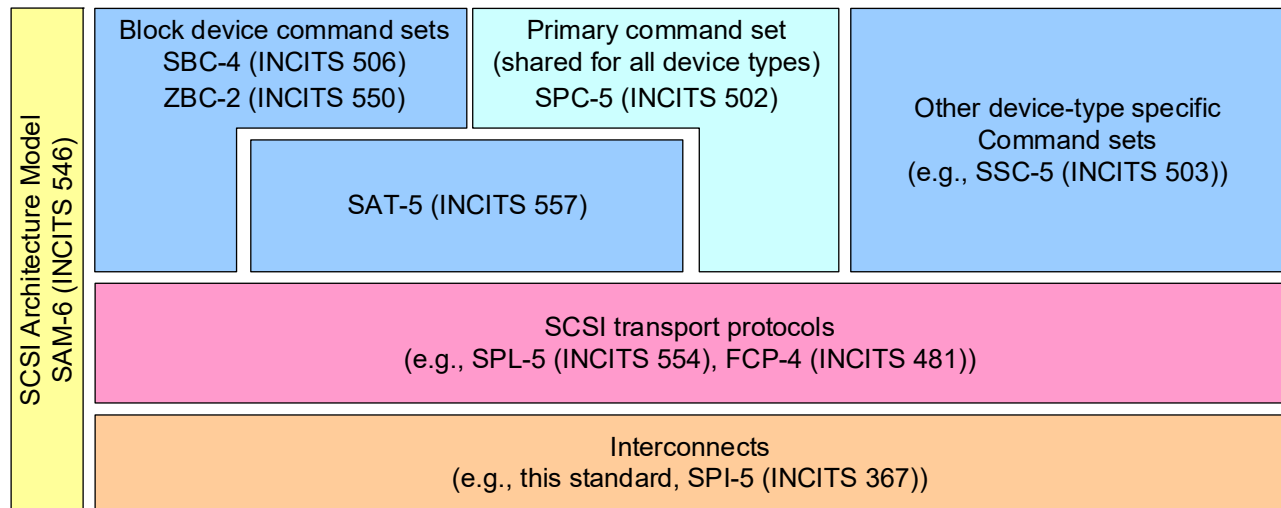


Figure 1 — SCSI document relationships

Figure 2 shows the relationship of this standard to other standards and related projects in the ATA family of standards.

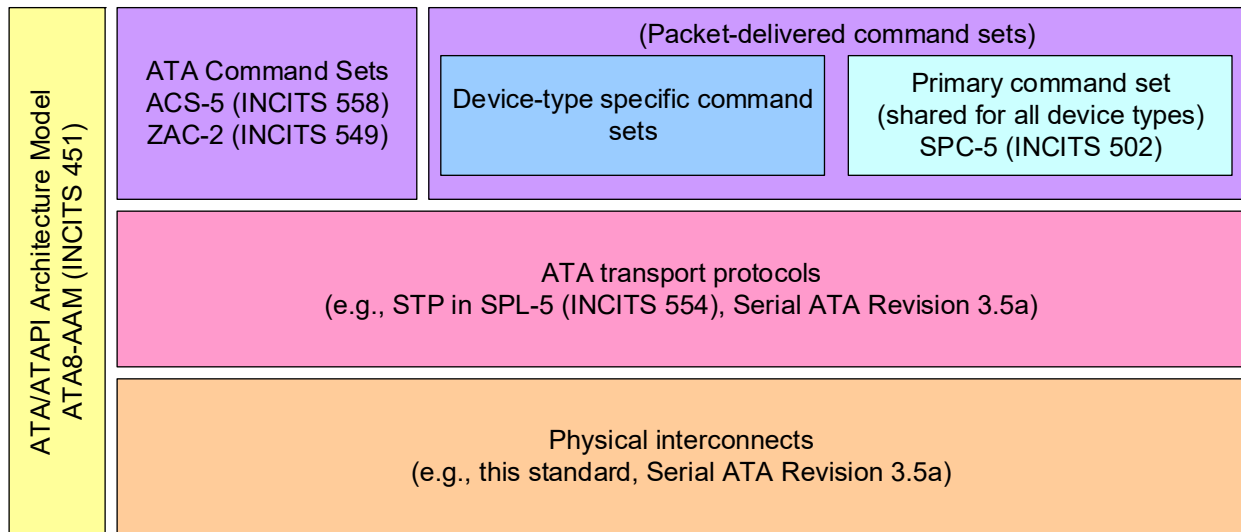


Figure 2 — ATA document relationships

Figure 1 and figure 2 show the general relationship of the documents to one another, and do not imply a relationship such as a hierarchy, protocol stack, or system architecture.

These standards specify the interfaces, functions, and operations necessary to ensure interoperability between conforming implementations. This standard is a functional description. Conforming implementations may employ any design technique that does not violate interoperability.

This standard has made obsolete the following:

- a) Mini SAS 4i connectors and cables;
- b) Mini SAS 4x connectors and cables;
- c) untrained 1.5 Gbit/s, 3 Gbit/s, and 6 Gbit/s;
- d) trained 1.5 Gbit/s and 3 Gbit/s; and
- e) High Density Drive connectors.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

Additional availability contact information is provided in Annex L.

IA # OIF-CEI-03.1, *Common Electrical I/O (CEI) - Electrical and Jitter Interoperability agreements for 6G+ bps, 11G+ bps and 25G+ bps I/O*

IEC 60169-15, First edition 1979-01, *Radio-frequency connectors. Part 15: R.F. coaxial connectors with inner diameter of outer conductor 4.13 mm (0.163 in) with screw coupling - Characteristic impedance 50 Ω (Type SMA)*

INCITS 457, *Information Technology - Serial Attached SCSI - 2 (SAS-2)*

INCITS 534, *Serial Attached SCSI - 4 (SAS-4)*

INCITS 546, *Information technology - SCSI Architecture Model - 6 (SAM-6)*

INCITS 554, *SAS Protocol Layer - 5 (SPL-5)*

INCITS/TR-35-2004 (R2016), *Methodologies for Jitter and Signal Quality Specification (MJSQ)*. When MJSQ is referenced from this standard, the FC Port terminology used within MJSQ is substituted with SAS phy terminology

ISO/IEC 14776-151, *Serial Attached SCSI -1.1 (SAS-1.1)*

ISO/IEC 14776-153, *Information Technology - Serial Attached SCSI - 2.1 (SAS-2.1)*

ISO/IEC 14776-154, *Serial Attached SCSI - 3 (SAS-3)*

ISO 80000-2, *Quantities and units -- Part 2: Mathematical signs and symbols to be used in the natural sciences and technology*

ITU-T Recommendation O.150 (05/96), *General requirements for instrumentation for performance measurements on digital transmission equipment*

ITU-T Recommendation O.150 - Corrigendum 1 (05/2002), *General requirements for instrumentation for performance measurements on digital transmission equipment*

For information on the current status of the listed documents, or regarding availability, contact the indicated organization.

PCI Express® Base Specification Revision 6.0 (PCIe), 16 December 2021

NOTE 1 - For information on the current status of PCI documents, contact the PCI-SIG (see www.pcisig.com).

Serial ATA Revision 3.5a (SATA). 2 March, 2021

NOTE 2 - For information on the current status of Serial ATA documents, contact the Serial ATA international Organization (see www.sata-io.org).

SFF-8147, *54mm x 78.5mm Form Factor with Micro SAS Connector*

SFF-8223, *2.5" Form Factor Drive with Serial Attached Connector*

SFF-8323, *3.5" Form Factor Drive with Serial Attached Connector*

SFF-8449, *Mini Multilane Series Management Interface*

SFF-8410, *HSS Copper Testing and Performance Requirements*

SFF-8416, *Measurement and Performance Requirements for HPEI Bulk Cable*

SFF-8448, *SAS Sideband Signal Assignments*

SFF-8482, *Serial Attachment 2X Unshielded Connector*
 SFF-8485, *Serial GPIO (General Purpose Input/Output) Bus*
 SFF-8486, *Serial Attachment 4X Unshielded Micro Connector*
 SFF-8523, *5.25" Form Factor Drive w/Serial Attachment Connector*
 SFF-8611, *MiniLink 4/8X I/O Cable Assemblies*
 SFF-8612, *MiniLink 4/8X Shielded Connector*
 SFF-8630, *Serial Attachment 4X Unshielded Connector*
 SFF-8636, *Management Interface for Cabled Environments*
 SFF-8639, *Multifunction 6X Unshielded Connector*
 SFF-8643, *Mini Multilane 4/8X Unshielded Connector*
 SFF-8644, *Mini Multilane 4/8X Shielded Connector*
 SFF-8654, *0.6mm 4/8X Unshielded I/O Connector*
 SFF-8662, *QSFP+ 28 Gb/s 4X Connector (Style A)*
 SFF-8672, *QSFP+ 28 Gb/s 4X Connector (Style B)*
 SFF-9402, *Multi-Protocol Internal Cable Pinouts for SAS and/or PCIe*
 SFF-9639, *Multifunction 6X Unshielded Connector Pinouts*
 SFF-TA-1000, *2.5" Form Factor Drive with High Density Connector*
 SFF-TA-1016, *Internal Unshielded High Speed Connector System*

NOTE 3 - For more information on the current status of SFF documents or to obtain copies of these documents, contact the SFF Committee (see <https://www.snia.org/technology-communities/sff/specifications>).

ASTM Standard B 258-02, 2002, *Standard specification for standard nominal diameters and cross-sectional areas of AWG sizes of solid round wires used as electrical conductors*, ASTM International, West Conshohocken, PA, USA.

NOTE 4 - For more information on current status of ASTM International standards, contact ASTM (see www.astm.org).

PANTONE® Color Formula Guide

NOTE 5 - Pantone® is a registered trademark of Pantone, Inc. For more information on Pantone colors, contact Pantone, Inc. (see <https://www.pantone.com>).

Touchstone® File Format Specification. Revision 1.1. IBIS Open Forum.

NOTE 6 - Touchstone® is a registered trademark of Agilent Corporation. For more information on the Touchstone specification, contact the IBIS Open Forum (see <https://ibis.org>).

MATLAB® 7 Programming Fundamentals. Release 2008b.

NOTE 7 - MATLAB® is a registered trademark of The MathWorks, Inc. For more information on MATLAB, contact The Mathworks, Inc. (see <https://www.mathworks.com>).

GNU Octave 3.6.4 or newer

NOTE 8 - For more information on the current status of Octave and to obtain a copy of this software, contact GNU Octave (see <https://www.gnu.org/software/octave/>).

3 Definitions, symbols, abbreviations, keywords, and conventions

3.1 Definitions

3.1.1 active cable assembly

cable assembly (see 3.1.9) that requires power for internal circuitry used in the transmission of the signal through the cable assembly

3.1.2 alternating current (A.C.)

non-D.C. component of a signal

Note 1 to entry: In this standard, all frequency components greater than or equal to 100 kHz.

3.1.3 baud rate

nominal signaling speed, expressed as the maximum number of times per second that the signal (see 3.1.98) changes the state of the physical link (see 3.1.66)

Note 1 to entry: Each state change produces a transition (i.e., signal edge).

Note 2 to entry: Baud rate is the reciprocal of the UI (i.e., $f_{\text{baud}} = 1 / \text{UI}$) (see 3.1.117).

3.1.4 bit error ratio (BER)

number of logical bits output from a receiver circuit that differ from the correct transmitted logical bits, divided by the number of transmitted logical bits

Note 1 to entry: BER is computed on the raw bit stream before 10b8b or 150b128b decoding.

Note 2 to entry: BER is usually expressed as a coefficient and a power of 10 (e.g., 2 erroneous bits out of 100 000 bits transmitted is expressed as 2 out of 10^5 or 2×10^{-5}).

Note 3 to entry: See MJSQ.

3.1.5 bit time

nominal duration of a signal transmission bit (e.g., $666.\overline{6}$ ps at 1.5 Gbit/s, $333.\overline{3}$ ps at 3 Gbit/s, $166.\overline{6}$ ps at 6 Gbit/s, $83.\overline{3}$ ps at 12 Gbit/s, and $44.\overline{4}$ ps at 22.5 Gbit/s)

3.1.6 bounded uncorrelated jitter (BUJ or T_{UBHPJ})

part of DJ (see 3.1.26) not aligned in time with the signal being measured

Note 1 to entry: BUJ excludes ISI (see 3.1.47) and duty cycle distortion (see 3.1.30).

Note 2 to entry: For 1.5 Gbit/s, 3 Gbit/s, 6 Gbit/s, and 12 Gbit/s see MJSQ.

Note 3 to entry: For 22.5 Gbit/s see OIF-CEI.

3.1.7 burst time

part of an OOB signal (see 3.1.60) where the OOB burst (see 3.1.56) is transmitted

Note 1 to entry: See 5.11.

3.1.8 byte

sequence of eight contiguous bits considered as a unit

3.1.9 cable assembly

bulk cable with a separable connector at each end plus any retention, backshell, shielding features, or circuitry used for cable management or signal transmission

Note 1 to entry: See 5.4.4.

3.1.10 clock data recovery (CDR)

function provided by the receiver circuit responsible for producing a regular clock signal (i.e., the recovered clock) from the received signal and for aligning the recovered clock to the symbols (i.e., bits) being transmitted with the signal

Note 1 to entry: CDR uses the recovered clock to recover the bits.

Note 2 to entry: See MJSQ.

3.1.11 common SSC transmit clock

implementation that employs a single transmit clock for multiple transmitter devices and enables or disables SSC (see 5.8.6) on the transmit clock signal to all transmitter devices in common rather than allowing each transmitter device to independently control SSC

3.1.12 compliance point

interoperability point where interoperability specifications are met

Note 1 to entry: See 5.3.

3.1.13 compliant jitter tolerance pattern (CJTPAT)

test pattern for jitter testing in SAS dword mode

Note 1 to entry: See 5.8.3.1 and Annex A.

3.1.14 component edge

compliance point located where the receiver device packaging or transmitter device packaging attaches to the TxRx connection segment

Note 1 to entry: See 5.3.

3.1.15 connector

electro-mechanical components consisting of a receptacle and a plug that provide a separable interface between two transmission segments

Note 1 to entry: See 5.4.3.

3.1.16 consecutive identical digits (CID)

serial bit stream with repeated data bits of the same binary value

3.1.17 cumulative distribution function (CDF)

probability that jitter (see 3.1.48) is less than a given value

Note 1 to entry: See MJSQ.

3.1.18 D.C. idle

differential signal level that is nominally 0 V(P-P), used during the idle time (see 3.1.45) and negation time (see 3.1.55) of an OOB signal (see 3.1.60) when D.C. mode (see 3.1.19) is enabled

Note 1 to entry: See 5.8.4.

3.1.19 D.C. mode

mode in which D.C. idle (see 3.1.18) is used during the idle time (see 3.1.45) and negation time (see 3.1.55) of an OOB signal (see 3.1.60)

3.1.20 data character (Dxx.y)

character containing data information

Note 1 to entry: See SPL-5.

3.1.21 data dependent jitter (DDJ)

jitter (see 3.1.48) that is added when the transmission pattern is changed from a clocklike to a non-clocklike pattern

Note 1 to entry: For 1.5 Gbit/s, 3 Gbit/s, 6 Gbit/s, and 12 Gbit/s see MJSQ.

Note 2 to entry: For 22.5 Gbit/s see OIF-CEI.

3.1.22 decibel (dB)

ten times the common logarithm (i.e., \log_{10}) of the ratio of relative powers

Note 1 to entry: The ratio of powers P_1 and P_2 in dB is $10 \times \log_{10} (P_1 / P_2)$. If $P_1 = V_1^2 / R_1$, $P_2 = V_2^2 / R_2$, and $R_1 = R_2$, then this ratio is equivalent to 20 times the common logarithm of the relative voltage ratio (i.e., dB is $20 \times \log_{10} (V_1 / V_2)$). A ratio of 1 results in a dB value of 0 (e.g., $20 \times \log_{10} (1) = 0$ dB), a ratio greater than 1 results in a positive dB value (e.g., $20 \times \log_{10} (2) = 6$ dB) and a ratio less than 1 results in a negative dB value (e.g., $20 \times \log_{10} (0.5) = -6$ dB).

3.1.23 dB millivolts (dBmV)

decibel ratio of an rms voltage value relative to 1 mV

Note 1 to entry: 20 mV(rms) is equal to $20 \times \log_{10} (20 \text{ mV} / 1 \text{ mV}) = 26$ dBmV. This does not depend on the impedance level.

3.1.24 dB milliwatts (dBm)

decibel ratio of a power value relative to 1 mW

Note 1 to entry: 20 mW is equal to $10 \times \log_{10} (20 \text{ mW} / 1 \text{ mW}) = 13$ dBm. If power is measured with a 50Ω impedance level, then 20 mW is equivalent to $(0.02 \text{ W} \times 50 \Omega)^{(1/2)} = 1 \text{ V}$ or 60 dBmV. If power is measured with a 25Ω impedance level (i.e., the reference impedance for common mode measurements), then 20 mW is equivalent to $(0.02 \text{ W} \times 25 \Omega)^{(1/2)} = 0.707 \text{ V}$ or 57 dBmV.

3.1.25 decision feedback equalizer (DFE)

nonlinear equalizer that uses a feedback loop based on previously decoded symbols

3.1.26 deterministic jitter (DJ)

jitter (see 3.1.48) with non-Gaussian distribution that is bounded in amplitude and has specific causes

Note 1 to entry: See MJSQ.

3.1.27 direct current (D.C.)

non-A.C. component of a signal

Note 1 to entry: In this standard, all frequency components below 100 kHz.

3.1.28 disparity

difference between the number of ones and zeros in a character

Note 1 to entry: See SPL-5.

3.1.29 dispersion

signal pulse distortion from all causes

3.1.30 duty cycle distortion (DCD or T_DCD)

one-half of the difference of the average width of a one and the average width of a zero in a signal waveform eye pattern measurement

Note 1 to entry: For 1.5 Gbit/s, 3 Gbit/s, 6 Gbit/s, and 12 Gbit/s see MJSQ.

Note 2 to entry: For 22.5 Gbit/s see OIF-CEI.

3.1.31 dword

sequence of four contiguous bytes or four contiguous characters considered as a unit

Note 1 to entry: See SPL-5.

3.1.32 electromagnetic interference (EMI)

any electromagnetic disturbance that interrupts, obstructs, or otherwise degrades or limits the effective performance of electronics/electrical equipment

3.1.33 enclosure

box, rack, or set of boxes providing the powering, cooling, mechanical protection, EMI protection, and external electronic interfaces for one or more end device(s) (see 3.1.34) and/or expander device(s) (see SPL-5)

Note 1 to entry: An enclosure provides the outermost electromagnetic boundary and acts as an EMI barrier.

3.1.34 end device

SAS device or SATA device that is not contained within an expander device (see 3.1.37)

Note 1 to entry: See SPL-5.

3.1.35 end to end simulation

simulation performed from a reference transmitter or from a captured signal to a reference receiver device

3.1.36 etch

printed circuit board copper conductor path

3.1.37 expander device

device that is part of a service delivery subsystem (see SAM-5), facilitates communication between SAS devices (see 3.1.88) and SATA devices (see 3.1.94), and is either an externally configurable expander device (see SPL-5) or a self-configuring expander device (see SPL-5)

Note 1 to entry: See SPL-5.

3.1.38 expander phy

phy in an expander device that interfaces to a service delivery subsystem (see SAM-5)

Note 1 to entry: See SPL-5.

3.1.39 expander port

expander device object that interfaces to a service delivery subsystem (see SAM-5) and to SAS ports in other devices

Note 1 to entry: See SPL-5.

3.1.40 external connector

bulkhead connector (see 3.1.15) that carries signals into and out of an enclosure (see 3.1.33) and exits the enclosure with only minor compromise to the shield effectiveness of the enclosure (e.g., a Mini SAS HD receptacle)

Note 1 to entry: See 5.4.3.4.

3.1.41 eye contour

locus of points in a signal level versus time eye diagram where the CDF of 10^{-12} in the actual signal population exists

Note 1 to entry: Comparison of the measured eye contour to the jitter eye mask determines whether a jitter eye mask violation has occurred.

Note 2 to entry: For simulations, a CDF of 10^{-15} is used.

Note 3 to entry: See 5.8.3 and MJSQ.

3.1.42 fall time

time interval for the falling signal edge to transit between specified percentages of the signal amplitude

Note 1 to entry: In this standard, the measurement points are the 80 % and 20 % voltage levels.

Note 2 to entry: Also see rise time (see 3.1.87).

3.1.43 fanout cable assembly

cable assembly with one connector on one end and multiple connectors on the other end

Note 1 to entry: See 5.4.4.1.3.

3.1.44 field

group of one or more contiguous bits

3.1.45 idle time

part of an OOB signal (see 3.1.60) where OOB idle (see 3.1.57) is being transmitted

Note 1 to entry: See 5.11.

3.1.46 insertion loss

ratio of incident power to delivered power

Note 1 to entry: The dB magnitude of S_{12} or S_{21} is the negative of insertion loss in dB.

Note 2 to entry: See G.11.

3.1.47 intersymbol interference (ISI)

reduction in the distinction of a pulse caused by overlapping energy from neighboring pulses

Note 1 to entry: Neighboring pulses are pulses that are close enough to have significant energy overlapping the affected pulse and does not imply or exclude adjacent pulses (i.e., it is possible that many bit times (see 3.1.5) separate the pulses, especially in the case of reflections).

Note 2 to entry: The effects of ISI include DDJ (see 3.1.21) and vertical eye closure.

Note 3 to entry: ISI is produced by several mechanisms (e.g., dispersion, reflections, and circuits that lead to baseline wander).

Note 4 to entry: See MJSQ.

3.1.48 jitter

collection of instantaneous deviations of signal edge times at a defined signal level of the signal from the reference times for those events

Note 1 to entry: Reference times are, for example, times defined by the jitter timing reference.

Note 2 to entry: For 1.5 Gbit/s, 3 Gbit/s, 6 Gbit/s, and 12 Gbit/s see MJSQ.

Note 3 to entry: For 22.5 Gbit/s see OIF-CEI.

3.1.49 jitter timing reference

signal used as the basis for calculating the jitter in the signal under test

Note 1 to entry: For 1.5 Gbit/s, 3 Gbit/s, 6 Gbit/s, and 12 Gbit/s see MJSQ.

Note 2 to entry: For 22.5 Gbit/s see OIF-CEI.

3.1.50 jitter tolerance

ability of the receiver device to recover transmitted bits in an incoming data stream in the presence of specified jitter in the signal applied to the receiver device compliance point

Note 1 to entry: See MJSQ.

3.1.51 jitter tolerance pattern (JTPAT)

data test pattern for jitter testing in SAS dword mode of a receiver device contained within CJTPAT (see 3.1.13)

Note 1 to entry: See Annex A.

3.1.52 least mean square (LMS)

algorithm for adaptively adjusting the tap coefficients of a DFE (see 3.1.25) based on the difference between the desired and actual signal

3.1.53 managed connector category

category of connectors that support a cable management interface

Note 1 to entry: See 5.4.3.2.

3.1.54 near-end crosstalk (NEXT)

crosstalk that is propagated in a disturbed channel in the opposite direction as the propagation of a signal in the disturbing channel

Note 1 to entry: The terminals of the disturbed channel, at which the near-end crosstalk is present, and the energized terminals of the disturbing channel are usually near each other.

3.1.55 negation time

part of an OOB signal (see 3.1.60) during which OOB idle (see 3.1.57) is transmitted after the last OOB burst (see 3.1.56)

Note 1 to entry: See 5.11.

3.1.56 OOB burst

transmission of signal transitions or ALIGN3 primitives for a burst time (see 3.1.7)

Note 1 to entry: See 5.11.1.

3.1.57 OOB idle

transmission of D.C. idle (see 3.1.18) when D.C. mode (see 3.1.19) is enabled or a defined sequence of dwords when optical mode (see 3.1.61) is enabled

3.1.58 OOB interval

time basis for burst times (see 3.1.7), idle times (see 3.1.45), negation times (see 3.1.55), and signal times (see 3.1.101) used to create OOB signals (see 3.1.60)

Note 1 to entry: See 5.11.1.

3.1.59 OOB sequence

sequence where two phys exchange OOB signals (see 3.1.60)

Note 1 to entry: See SPL-5.

3.1.60 OOB signal

pattern of idle time (see 3.1.45), burst time (see 3.1.7), and negation time (see 3.1.55) used during the link reset sequence

Note 1 to entry: See 5.11.

3.1.61 optical mode

mode in which a defined sequence of dwords is used during the idle time (see 3.1.45) and negation time (see 3.1.55) of an OOB signal (see 3.1.60)

Note 1 to entry: See 5.11.

3.1.62 passive cable assembly

cable assembly (see 3.1.9) that does not require external power for internal circuitry used in the transmission of the signal through the cable assembly

3.1.63 passive TxRx connection

complete simplex signal path between the transmitter circuit (see 3.1.110) and receiver circuit (see 3.1.74) that does not include powered circuitry used in the transmission of the signal through the TxRx connection (see 3.1.115)

Note 1 to entry: See 5.5.1.

3.1.64 phy

object in a device that is used to interface to other devices

Note 1 to entry: Other devices are, for example, expander phys and SAS phys.

Note 2 to entry: See 4.1.

3.1.65 physical interconnect TxRx connection segment (PICS)

TxRx connection segment (see 3.1.116) used to model channel loss between the TDCS (see 3.1.114) and the RDCS (see 3.1.78)

Note 1 to entry: See 5.3.3.

3.1.66 physical link

two differential signal pairs, one pair in each direction, that connect two physical phys (see 3.1.64)

Note 1 to entry: See 4.1.

3.1.67 physical link rate

link rate between two physical phys established as a result of speed negotiation between those phys

3.1.68 power on

power being applied

3.1.69 probe point

physical position in a test load where signal characteristics for compliance points are measured

Note 1 to entry: See 5.6.

3.1.70 post cursor equalization ratio (R_{post})

ratio of the equalization peak signal voltage to the nominal signal voltage after a signal voltage change

Note 1 to entry: See 5.8.4.6.1.

3.1.71 precursor equalization ratio (R_{pre})

ratio of the equalization peak signal voltage to the nominal signal voltage prior to a signal voltage change

Note 1 to entry: See 5.8.4.6.1.

3.1.72 random jitter (RJ or T_{UUGJ})

jitter (see 3.1.48) characterized by a Gaussian distribution and that is unbounded

Note 1 to entry: For 1.5 Gbit/s, 3 Gbit/s, 6 Gbit/s, and 12 Gbit/s see MJSQ.

Note 2 to entry: For 22.5 Gbit/s, see OIF-CEI.

3.1.73 rate

data transfer rate of a physical or logical link

Note 1 to entry: Data transfer rates are, for example, 1.5 Gbit/s, 3 Gbit/s, 6 Gbit/s, 12 Gbit/s, or 22.5 Gbit/s.

3.1.74 receiver circuit

electronic circuit that converts an analog serial input signal to a logic signal

3.1.75 receiver circuit TxRx connection segment (RCCS)

TxRx connection segment (see 3.1.116) used to model package loss within the simulated receiver circuit (see 3.1.74)

Note 1 to entry: See 5.3.3.

3.1.76 reference clock

clock generated by the PLL

Note 1 to entry: This clock is filtered by the JTF (see 5.8.3.2) and aligned with the zero-crossing instants.

3.1.77 receiver device (Rx)

device downstream from a receiver device compliance point (see 3.1.12) containing a portion of the physical link and a receiver circuit (see 3.1.74)

3.1.78 receiver device TxRx connection segment (RDCS)

TxRx connection segment (see 3.1.116) between the simulated receiver circuit (see 3.1.74) and a separable connector

Note 1 to entry: See 5.3.3.

3.1.79 reference pulse response cursor (peak to peak)

cursor that is twice the amplitude of the response to a one UI (see 3.1.117) wide positive pulse of the same amplitude and transmitter equalization as the data stream it represents (see 5.7.3), sampled at the reference sampling instant (see 3.1.82)

3.1.80 reference receiver device

set of parameters defining electrical performance characteristics that provide a set of minimum electrical performance requirements for a receiver device and that are also used in mathematical modeling to determine compliance of a TxRx connection or transmitter device

Note 1 to entry: See 5.8.5.7.3.

3.1.81 reference sampling clock

reference clock (see 3.1.76) shifted by 0.5 UI (see 3.1.117)

3.1.82 reference sampling instant

instant at which a reference sampling clock (see 3.1.81) samples the amplitude of the response to a positive pulse generated using the reference sampling clock

Note 1 to entry: See figure 115.

3.1.83 reference transmitter device

set of parameters defining electrical performance characteristics of a transmitter device that are used in mathematical modeling to determine compliance of a TxRx connection

Note 1 to entry: See 5.8.4.5.5 and 5.8.4.6.4.

3.1.84 reference transmitter test load

set of S-parameters defining the electrical characteristics of a TxRx connection used as the basis for transmitter device and receiver device performance evaluation through mathematical modeling

Note 1 to entry: See 5.6.4.

3.1.85 reflection coefficient (ρ)

ratio of reflected voltage to incident voltage

3.1.86 return loss

ratio of incident power to reflected power

Note 1 to entry: The dB magnitude of S_{11} or S_{22} is the negative of return loss in dB.

Note 2 to entry: Return loss is usually expressed in decibel (dB).

Note 3 to entry: See G.11.

3.1.87 rise time

time interval for the rising signal edge to transit between specified percentages of the signal amplitude

Note 1 to entry: In this standard, the measurement points are the 20 % and 80 % voltage levels.

Note 2 to entry: Also see fall time (see 3.1.42).

3.1.88 SAS device

SAS initiator device (see SPL-5) and/or SAS target device (see SPL-5)

3.1.89 SAS dword mode

mode with a physical link rate less than or equal to 12 Gbit/s (i.e., G1, G2, G3, or G4)

Note 1 to entry: See SPL-5.

3.1.90 SAS packet mode

mode with a physical link rate greater than 12 Gbit/s (i.e., G5)

Note 1 to entry: See SPL-5.

3.1.91 SAS phy

phy in a SAS device (see 3.1.88) that interfaces to a service delivery subsystem (see SAM-5)

3.1.92 SAS target device

device containing SSP, STP, and/or SMP target ports in a SAS domain

Note 1 to entry: See SPL-5.

3.1.93 SAS target device circuitry

at a minimum, the circuitry in the SAS target device (see SPL-5) providing control of the SAS phy (see 3.1.91) and protocol support for communication through the physical link (see 3.1.66)

Note 1 to entry: Application of power to the SAS target device circuitry results in actions defined for power on (see SPL-5).

3.1.94 SATA device

ATA device that contains a SATA device port in an ATA domain

Note 1 to entry: See SPL-5.

3.1.95 SATA phy

phy in a SATA device (see SPL-5) or SATA port selector (see SPL-5) that interfaces to a service delivery subsystem (see SAM-5)

Note 1 to entry: Analogous to a SAS phy (see 3.1.91).

3.1.96 Serial ATA (SATA)

protocol defined by SATA

Note 1 to entry: See SATA.

3.1.97 Serial Attached SCSI (SAS)

set of protocols defined in SPL-5 and the interconnect defined by this standard

3.1.98 signal

detectable transmitted energy that is used to carry information

3.1.99 signal amplitude

property of the overall signal (see 3.1.98) that describes the peak or peak to peak values of the signal level (see 3.1.100)

3.1.100 signal level

instantaneous intensity of a signal (see 3.1.98) measured in volts

3.1.101 signal time

time of an OOB signal (see 3.1.60), consisting of six burst times (see 3.1.7), six idle times (see 3.1.45), and one negation time (see 3.1.55)

Note 1 to entry: See 5.11.

3.1.102 signal tolerance

ability of the receiver device to recover transmitted bits in an incoming data stream with maximum jitter and minimum amplitude

Note 1 to entry: See MJSQ.

3.1.103 significant crosstalk

crosstalk source having a magnitude at any point of its transfer function in excess of -50 dB in the range of frequencies up to 6 GHz

3.1.104 sinusoidal jitter (SJ)

single frequency jitter (see 3.1.48) applied during signal tolerance testing

Note 1 to entry: See MJSQ.

3.1.105 spread spectrum clocking (SSC)

technique of modulating the operating frequency of a transmitted signal to reduce the measured peak amplitude of radiated emissions

Note 1 to entry: The operating frequency of a transmitted signal is the physical link rate

Note 2 to entry: See SPL-5.

3.1.106 symbol

smallest unit of data transmission on a physical link

Note 1 to entry: The smallest unit of data is a bit.

Note 2 to entry: A symbol represents a single transition if the maximum transition rate (i.e., a 0101b pattern) is occurring.

3.1.107 total jitter (TJ or T_{TJ})

jitter (see 3.1.48) from all sources

Note 1 to entry: For 1.5 Gbit/s, 3 Gbit/s, 6 Gbit/s, and 12 Gbit/s see MJSQ.

Note 2 to entry: For 22.5 Gbit/s see OIF-CEI.

3.1.108 trained

physical link rate negotiated with Train_Rx-SNW

Note 1 to entry: See SPL-5.

3.1.109 transceiver

physical entity that contains both a transmitter device (see 3.1.113) and a receiver device (see 3.1.77)

3.1.110 transmitter circuit

electronic circuit that converts a logic signal to an analog serial output signal

3.1.111 transmitter circuit TxRx connection segment (TCCS)

TxRx connection segment (see 3.1.116) used to model package loss within the simulated transmitter circuit (see 3.1.110)

Note 1 to entry: See 5.3.3.

3.1.112 transmitter compliance transfer function (TCTF)

mathematical statement of the transfer function through which the transmitter is capable of producing acceptable signals as defined by a receive mask

Note 1 to entry: See 5.8.4.1.

3.1.113 transmitter device (Tx)

device upstream from a transmitter device compliance point (see 3.1.12) containing a portion of the physical link and a transmitter circuit (see 3.1.110)

3.1.114 transmitter device TxRx connection segment (TDCS)

TxRx connection segment (see 3.1.116) between the transmitter circuit (see 3.1.110) and a separable connector

Note 1 to entry: See 5.3.3.

3.1.115 TxRx connection

complete simplex signal path between the transmitter circuit (see 3.1.110) and receiver circuit (see 3.1.74)

Note 1 to entry: See 5.5.1.

3.1.116 TxRx connection segment

portion of a TxRx connection (see 3.1.115) delimited by separable connectors or changes in the conductive material

Note 1 to entry: See 5.5.1.

3.1.117 unit interval (UI)

normalized, dimensionless, nominal duration of a symbol (see 3.1.106)

Note 1 to entry: UIs represent, for example, $666.\overline{6}$ ps at 1.5 Gbit/s, $333.\overline{3}$ ps at 3 Gbit/s, $166.\overline{6}$ ps at 6 Gbit/s, $83.\overline{3}$ ps at 12 Gbit/s, and $44.\overline{4}$ ps at 22.5 Gbit/s.

Note 2 to entry: A UI represents the reciprocal of the baud rate (i.e., $UI = 1 / f_{\text{baud}}$) (see 3.1.3).

Note 3 to entry:

3.1.118 unmanaged passive connector category

category of connectors that do not support power for active external cable assemblies (see) and do not support cable assemblies with a cable management interface

Note 1 to entry: See 5.4.3.2.

3.1.119 untrained

characteristic of a physical link in which the physical link rate has not been negotiated with Train_Rx-SNW

Note 1 to entry: See SPL-5.

3.1.120 usage variable

SASWDP parameter set to a value that determines if the stressor file is to be added to the simulation

Note 1 to entry: See Annex B.

3.1.121 voltage modulation amplitude (VMA)

difference in electrical voltage of a signal (see 3.1.98) between the stable one level and the stable zero level

3.1.122 waveform dispersion penalty (WDP)

simulated measure of the deterministic penalty of the signal waveform from a particular transmitter device transmitting a particular pattern and a particular test load with a reference receiver device

Note 1 to entry: See 5.8.4.5.1 and Annex B.

3.2 Symbols and abbreviations**3.2.1 Abbreviations**

See Annex L for abbreviations of standards bodies (e.g., ISO).

Abbreviations used in this standard:

Abbreviation	Meaning
A.C.	alternating current (see 3.1.2)
ATA	AT attachment
AWG	American wire gauge (see ASTM Standard B 258-02 (see clause 2))
BER	bit error ratio (see 3.1.4)
BUJ	bounded uncorrelated jitter (see 3.1.6)
C1	coefficient 1 (see 5.8.4.6.4)
C2	coefficient 2 (see 5.8.4.6.4)
C3	coefficient 3 (see 5.8.4.6.4)
CDF	cumulative distribution function (see 3.1.17)
CDR	clock data recovery (see 3.1.10)
CIC	compliance interconnect channel (see SATA)
CID	consecutive identical digits (see 3.1.16)
CJTPAT	compliant jitter tolerance pattern (see 3.1.13)
CR	inter-enclosure (i.e., cabinet) receiver device compliance point (see 5.3)
CT	inter-enclosure (i.e., cabinet) transmitter device compliance point (see 5.3)
D.C.	direct current (see 3.1.27)
DCD	duty cycle distortion (see 3.1.30)
DDJ	data dependent jitter (see 3.1.21)
DFE	decision feedback equalizer (see 3.1.25)
DJ	deterministic jitter (see 3.1.26)
EMI	electromagnetic interference (see 3.1.32)
ER	end to end transmitter device compliance point (see 5.3)
ESD	electrostatic discharge
ET	end to end receiver device compliance point (see 5.3)
G1	generation 1 physical link rate (i.e., 1.5 Gbit/s)
G2	generation 2 physical link rate (i.e., 3 Gbit/s)
G3	generation 3 physical link rate (i.e., 6 Gbit/s)
G4	generation 4 physical link rate (i.e., 12 Gbit/s)
G5	generation 5 physical link rate (i.e., 22.5 Gbit/s)
Gbit/s	gigabit per second (i.e., 10 ⁹ bits per second)

Abbreviation	Meaning
Gen1i	SATA generation 1 physical link rate (i.e., 1.5 Gbit/s) (see SATA)
Gen2i	SATA generation 2 physical link rate (i.e., 3 Gbit/s) (see SATA)
Gen3i	SATA generation 3 physical link rate (i.e., 6 Gbit/s) (see SATA)
GPIO	general purpose input/output
HD	high-density
HPJtotal	total high probability jitter (see OIF-CEI)
ICN	integrated crosstalk noise
IR	intra-enclosure (i.e., internal) receiver device compliance point (see 5.3)
ISI	intersymbol interference (see 3.1.47)
IT	intra-enclosure (i.e., internal) transmitter device compliance point (see 5.3)
ITU-T	International Telecommunication Union - Telecommunication Standardization Sector (see 2)
JMD	jitter measurement device
JTF	jitter transfer function (see 5.8.3.2)
JTPAT	jitter tolerance pattern (see 3.1.51)
LED	light-emitting diode
LMS	least mean square (see 3.1.52)
MJSQ	Methodologies for Jitter and Signal Quality Specification
N/A	not applicable
N/C	not connected
NEXT	near-end crosstalk (see 3.1.54)
OIF-CEI	Optical Internetworking Forum - Common Electrical I/O (see 2)
OOB	out-of-band
OOBI	out-of-band interval (see 3.1.58)
PCB	printed circuit board
PCIe	PCI Express (see 2)
PICS	physical interconnect TxRx connection segment (see 3.1.65)
PJ	periodic jitter
PLL	phase lock loop
PR	package edge receiver device compliance point (see 5.3)
PRBS	pseudo-random bit sequence (see ITU-T)
PT	package edge transmitter device compliance point (see 5.3)
P-P	peak to peak
RCCS	receiver circuit TxRx connection segment (see 3.1.75)
RD	running disparity (see SPL-5)
RDCS	receiver device TxRx connection segment (see 3.1.78)
RJ	random jitter (see 3.1.72)
RR	receiver device die attachment point to RCCS
Rx	receiver device (see 3.1.77)
SAM-5	SCSI Architecture Model - 5 standard (see 2)
SAS	Serial Attached SCSI (see 3.1.97)
SATA	Serial ATA (see 3.1.96) or the Serial ATA 3.3 specification (see 2)

Abbreviation	Meaning
SCSI	Small Computer System Interface
SGPIO	serial GPIO (see 2)
SJ	sinusoidal jitter (see 3.1.104)
SMA	subminiature version A connector (see 2)
SPL-5	SAS Protocol Layer - 5 (see 2)
SSC	spread spectrum clocking
STP	Serial ATA Tunneled Protocol
TCCS	transmitter circuit TxRx connection segment (see 3.1.111)
TCTF	transmitter compliance transfer function (see 3.1.112)
TDCS	transmitter device TxRx connection segment (see 3.1.114)
TDNA	time domain network analyzer (i.e., TDR/TDT plus analysis software that performs a VNA-style output)
TDR	time domain reflectometer
TDT	time domain transmission
TFP	test fixture with plug (see Annex J)
TFR	test fixture with receptacle (see Annex J)
TJ	total jitter (see 3.1.107)
TTIU	transmitter training information unit (see SPL-5)
Tx	transmitter device (see 3.1.113)
T_DCD	transmitter device duty cycle distortion (see 3.1.30)
T_TJ	transmitter device total jitter (see 3.1.107)
T_UBHPJ	transmitter device uncorrelated bounded high probability jitter (see 3.1.6)
T_UUGJ	transmitter device uncorrelated unbounded Gaussian jitter (see 3.1.72)
UI	unit interval (see 3.1.117)
VMA	voltage modulation amplitude (see 3.1.121)
VNA	vector network analyzer
WDP	waveform dispersion penalty (see 3.1.122)
XCS	crosstalk connection segment (see 5.5.6)

3.2.2 Units

Units used in this standard:

Units	Meaning
dB	decibel (see 3.1.22)
dBm	decibel milliwatts (see 3.1.24)
dBmV	decibel millivolts (see 3.1.23)
Gbit/s	gigabits per second (i.e., 10^9 bits per second)
GHz	gigahertz (i.e., 10^9 cycles per second) (i.e., s^{-9})
Hz	hertz (i.e., cycles per second) (i.e., s^{-1})
in	inch
kHz	kilohertz (i.e., 10^3 cycles per second) (i.e., s^{-3})
k Ω	kilohm (i.e., 10^3 ohms)

Units	Meaning
μA	microampere (i.e., 10^{-6} amperes)
μs	microsecond (i.e., 10^{-6} seconds)
m	meter
mA	milliampere (i.e., 10^{-3} amperes)
MBps	megabytes per second (i.e., 10^6 bytes per second)
MHz	megahertz (i.e., 10^6 cycles per second) (i.e., s^{-6})
mm	millimeter (i.e., 10^{-3} meters)
ms	millisecond (i.e., 10^{-3} seconds)
mV	millivolt (i.e., 10^{-3} volts)
mW	milliwatt (i.e., 10^{-3} watts)
nF	nanofarad (i.e., 10^{-9} farads)
ns	nanosecond (i.e., 10^{-9} seconds)
pF	picofarad (i.e., 10^{-12} farads)
ppm	parts per million (i.e., 10^{-6})
ps	picosecond (i.e., 10^{-12} seconds)
rms	root mean square (i.e., quadratic mean)
s	second (unit of time)
V	volt
W	watt

3.2.3 Symbols

Symbols used in this standard:

Symbols	Meaning
$D_{xx.y}$	data character (see 3.1.20)
e	2.718 28..., the base of the natural (i.e., hyperbolic) system of logarithms
K_0	output gain
R_{post}	post cursor equalization ratio (see 3.1.70)
R_{pre}	precursor equalization ratio (see 3.1.71)
®	registered trademark
S_{ij}	S-parameter for port j to port i (see G.11)
S_{CCij}	S-parameter for common mode to common mode port j to port i (see G.11)
S_{CDij}	S-parameter for differential to common mode port j to port i (see G.11)
S_{DCij}	S-parameter for common mode to differential port j to port i (see G.11)

Symbols	Meaning
S_{DDij}	S-parameter for differential to differential port j to port i (see G.11)
∞ (lemniscate)	infinity symbol
Δ (delta)	difference operator
π (pi)	3.141 59... , the ratio of the circumference of a circle to its diameter
ρ (rho)	reflection coefficient (see 3.1.85)
σ (sigma)	integrated crosstalk noise (see F.3)
τ (tau)	time constant
ϕ (phi)	phase
Ω (omega)	ohm (unit of electrical resistance)

3.2.4 Mathematical operators

Mathematical operators used in this standard:

Mathematical Operators	Meaning
sgn	signum function (i.e., sign function)
\wedge	exclusive logical OR
$<$	less than
\leq	less than or equal to
$>$	greater than
\geq	greater than or equal to
\pm	plus or minus
\times	multiplication
$/$	division
$ v $	the absolute value (i.e., magnitude) of v
\sim	approximately equal to
\otimes	convolution

3.3 Keywords

3.3.1 invalid

keyword used to describe an illegal or unsupported bit, byte, word, field, or code value

Note 1 to entry: Receipt of an invalid bit, byte, word, field, or code value shall be reported as an error.

3.3.2 mandatory

keyword indicating an item that is required to be implemented as defined in this standard

3.3.3 may

keyword that indicates flexibility of choice with no implied preference

3.3.4 may or may not

keyword that indicates flexibility of choice with no implied preference

Note 1 to entry: Significant uses of “may or may not” occur in descriptions where attention is being drawn to the “may not” case.

3.3.5 obsolete

keyword indicating that an item was defined in prior SCSI standards but has been removed from this standard

3.3.6 option, optional

keywords that describe features that are not required to be implemented by this standard

Note 1 to entry: If any optional feature defined by this standard is implemented, then it shall be implemented as defined in this standard.

3.3.7 prohibited

keyword used to describe a feature, function, or coded value that is defined in a non-SCSI standard (i.e., a standard that is not a member of the SCSI family of standards) to which this standard makes a normative reference where the use of said feature, function, or coded value is not allowed for implementations of this standard

3.3.8 reserved

keyword referring to bits, bytes, words, fields, and code values that are set aside for future standardization

Note 1 to entry: A reserved bit, byte, word, or field shall be set to zero, or in accordance with a future extension to this standard.

Note 2 to entry: Recipients are not required to check reserved bits, bytes, words, or fields for zero values.

Note 3 to entry: Receipt of reserved code values in defined fields shall be reported as error.

3.3.9 restricted

keyword referring to bits, bytes, words, and fields that are set aside for other identified standardization purposes

Note 1 to entry: A restricted bit, byte, word, or field shall be treated as a reserved bit, byte, word or field in the context where the restricted designation appears.

3.3.10 shall

keyword indicating a mandatory requirement

Note 1 to entry: Designers are required to implement all such mandatory requirements to ensure interoperability with other products that conform to this standard.

3.3.11 should

keyword indicating flexibility of choice with a strongly preferred alternative

3.3.12 vendor specific

something (e.g., a bit, field, code value) that is not defined by this standard

Note 1 to entry: Specification of the referenced item is determined by the SCSI device vendor and may be used differently in various implementations.

3.4 Editorial conventions

Certain words and terms used in this standard have a specific meaning beyond the normal English meaning. These words and terms are defined either in the glossary or in the text where they first appear.

Uppercase is used when referring to the name of a numeric value defined in this standard or a formal attribute possessed by an entity. When necessary for clarity, names of objects, procedure calls, arguments or discrete states are capitalized or set in bold type. Names of fields are identified using small capital letters (e.g., NACA bit).

Quantities having a defined numeric value are identified by large capital letters (e.g., CHECK CONDITION). Quantities having a discrete but unspecified value are identified using small capital letters. (e.g., TASK COMPLETE, indicates a quantity returned by the **Execute Command** procedure call). Such quantities are

associated with an event or indication whose observable behavior or value is specific to a given implementation standard.

Lists sequenced by lowercase or uppercase letters show no ordering relationship between the listed items.

EXAMPLE 1 - The following list shows no relationship between the named items:

- a) red (i.e., one of the following colors):
 - A) crimson; or
 - B) amber;
- b) blue; or
- c) green.

Lists sequenced by numbers show an ordering relationship between the listed items.

EXAMPLE 2 -The following list shows an ordered relationship between the named items:

- 1) top;
- 2) middle; and
- 3) bottom.

Lists are associated with an introductory paragraph or phrase, and are numbered relative to that paragraph or phrase (i.e., all lists begin with an a) or 1) entry).

If a conflict arises between text, tables, or figures, the order of precedence to resolve the conflicts is text; then tables; and finally figures. Not all tables or figures are fully described in the text. Tables show data format and values.

Notes and examples do not constitute any requirements for implementers and notes are numbered consecutively throughout this standard.

3.5 Numeric and character conventions

3.5.1 Numeric conventions

A binary number is represented in this standard by any sequence of digits comprised of only the Arabic numerals 0 and 1 immediately followed by a lower-case b (e.g., 0101b). Underscores or spaces may be included in binary number representations to increase readability or delineate field boundaries (e.g., 00010101 11001110b, 00010101_11001110b, 0 0101 1010b, or 0_0101_1010b).

A hexadecimal number is represented in this standard by any sequence of digits comprised of only the Arabic numerals 0 to 9 and/or the upper-case English letters A to F immediately followed by a lower-case h (e.g., FA23h). Underscores or spaces may be included in hexadecimal number representations to increase readability or delineate field boundaries (e.g., B FD8C FA23h or B_FD8C_FA23h).

A decimal number is represented in this standard by any sequence of digits comprised of only the Arabic numerals 0 to 9 not immediately followed by a lower-case b or lower-case h (e.g., 25).

A range of numeric values is represented in this standard in the form “a to z”, where a is the first value included in the range, all values between a and z are included in the range, and z is the last value included in the range (e.g., the representation “0h to 3h” includes the values 0h, 1h, 2h, and 3h).

This standard uses the following conventions for representing decimal numbers:

- a) the decimal separator (i.e., separating the integer and fractional portions of the number) is a period;
- b) the thousands separator (i.e., separating groups of three digits in a portion of the number) is a space;
- c) the thousands separator is used in both the integer portion and the fraction portion of a number; and
- d) the decimal representation for a year is 1999 not 1 999.

Table 1 shows some examples of decimal numbers using various conventions.

Table 1 — Numbering conventions

French	English	This standard
0,6	0.6	0.6
3,141 592 65	3.14159265	3.141 592 65
1 000	1,000	1 000
1 323 462,95	1,323,462.95	1 323 462.95

3.5.2 Units of measure

This standard represents values using both decimal units of measure and binary units of measure. Values are represented by the following formats:

- a) for values based on decimal units of measure:
 - 1) numerical value (e.g., 100);
 - 2) space; and
 - 3) prefix symbol and unit:
 - 1) decimal prefix symbol (e.g., M) (see table 2); and
 - 2) unit abbreviation (e.g., B);
- and
- b) for values based on binary units of measure:
 - 1) numerical value (e.g., 1 024);
 - 2) space;
 - 3) prefix symbol and unit:
 - 1) binary prefix symbol (e.g., Gi) (see table 2); and
 - 2) unit abbreviation (e.g., b).

Table 2 compares the prefix, symbols, and power of the binary and decimal units.

Table 2 — Comparison of decimal prefixes and binary prefixes

Decimal			Binary		
Prefix name	Prefix symbol	Power (base-10)	Prefix name	Prefix symbol	Power (base-2)
kilo	k	10^3	kibi	Ki	2^{10}
mega	M	10^6	mebi	Mi	2^{20}
giga	G	10^9	gibi	Gi	2^{30}
tera	T	10^{12}	tebi	Ti	2^{40}
peta	P	10^{15}	pebi	Pi	2^{50}
exa	E	10^{18}	exbi	Ei	2^{60}
zetta	Z	10^{21}	zebi	Zi	2^{70}
yotta	Y	10^{24}	yobi	Yi	2^{80}

3.5.3 Byte encoded character strings conventions

When this standard requires one or more bytes to contain specific encoded characters, the specific characters are enclosed in single quotation marks. The single quotation marks identify the start and end of the characters that are required to be encoded but are not themselves to be encoded. The characters that are to be encoded are shown in the case that is to be encoded.

An ASCII space character (i.e., 20h) may be represented in a string by the character '¬' (e.g., 'SCSI¬device').

The encoded characters and the single quotation marks that enclose them are preceded by text that specifies the character encoding methodology and the number of characters required to be encoded.

EXAMPLE - Using the notation described in this subclause, stating that eleven ASCII characters 'SCSI device' are to be encoded would be the same writing out the following sequence of byte values: 53h 43h 53h 49h 20h 64h 65h 76h 69h 63h 65h.

4 General

4.1 Physical links and phys

A physical link is a set of four wires used as two differential signal pairs. One differential signal transmits in one direction while the other differential signal transmits in the opposite direction. Data may be transmitted in both directions simultaneously.

A physical phy contains a transceiver which electrically interfaces to a physical link, which attaches to another physical phy.

Phys are contained in ports (see SPL-5). Phys interface to a service delivery subsystem (see SAM-5).

Figure 3 shows two phys attached with a physical link.

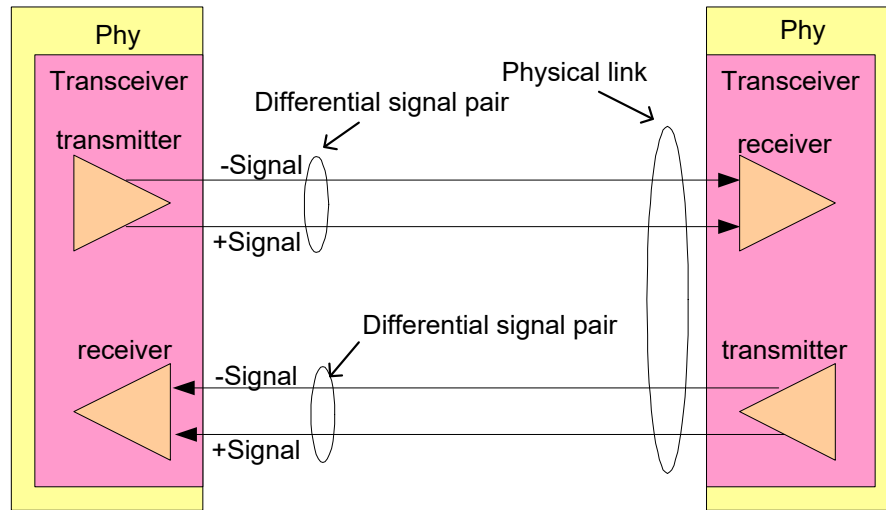


Figure 3 — Physical links and phys

An attached phy is the phy to which a phy is attached over a physical link.

The transceiver follows the electrical specifications defined in 5.8. Phys transmit and receive bits at physical link rates defined in 5.8. In the SAS dword mode the bits are parts of 10-bit characters (see SPL-5), which are parts of dwords (see SPL-5). In the SAS packet mode the bits are parts of 150-bit SPL packets (see SPL-5). The physical link rates supported by a phy are specified or indicated by the following fields in the SMP DISCOVER response (see SPL-5), the SMP PHY CONTROL request (see SPL-5), and the Phy Control and Discover mode page (see SPL-5):

- the NEGOTIATED PHYSICAL LINK RATE field;
- the HARDWARE MINIMUM PHYSICAL LINK RATE field;
- the HARDWARE MAXIMUM PHYSICAL LINK RATE field;
- the PROGRAMMED MINIMUM PHYSICAL LINK RATE field; and
- the PROGRAMMED MAXIMUM PHYSICAL LINK RATE field.

4.2 Phy test functions

Phy test functions (e.g., transmission of test patterns) are used for phy and interconnect characterization and diagnosis. The phy may be attached to test equipment while performing a phy test function. See SPL-5 for the optional mechanisms for invoking phy test function.

Each phy test function is optional.

If the phy test function requires a specific phy test pattern and/or phy test function physical link rate, then the mechanism for invoking the phy test function (see SPL-5) also specifies the phy test pattern and phy test function physical link rate.

5 Physical layer

5.1 Physical layer overview

The physical layer defines:

- a) passive interconnect (e.g., connectors and cable assemblies); and
- b) transmitter and receiver device electrical characteristics.

Within this standard, references to connector gender use the terms plug and receptacle as equivalent to the terms free and fixed, respectively, that may be used in the references that define the connectors. Fixed and free terminology has no relationship to the application of the connector.

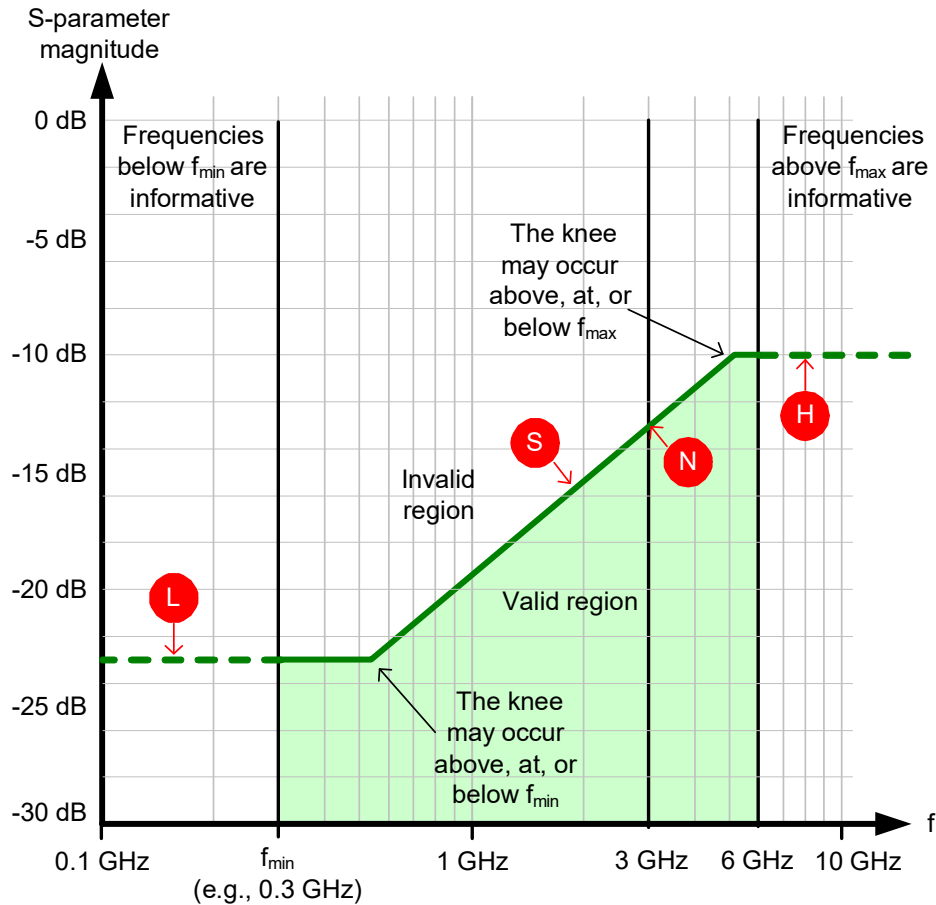
5.2 Conventions for defining maximum limits for S-parameters

The following values are specified by this standard to define the maximum limits for certain S-parameters (e.g., for cable assemblies and backplanes (see 5.5.3), transmitter devices (see 5.8.4.5.3), and receiver devices (see 5.8.5.7.2)):

- a) L is the maximum value in dB at the low frequency asymptote;
- b) N is the maximum value in dB at 3 GHz;
- c) H is the maximum value in dB at the high frequency asymptote;
- d) S is the slope in dB/decade;
- e) f_{\min} is the minimum frequency of interest; and
- f) f_{\max} is the maximum frequency of interest.

The frequencies at which L and H intersect the slope S may or may not be within the region of f_{\min} to f_{\max} . The frequency for N is based on the Nyquist at 6 Gbit/s.

Figure 4 shows the values in a graph.



Note: graph is not to scale

Figure 4 — Maximum limits for S-parameters definitions

5.3 Compliance points

5.3.1 Compliance points overview

A TxRx connection is the complete simplex signal path between the transmitter circuit and receiver circuit.

A TxRx connection segment is that portion of a TxRx connection delimited by separable connectors or changes in conductive material.

This standard defines the electrical requirements of the signal at the following compliance points in a TxRx connection (see table 3):

- for 1.5 Gbit/s, 3 Gbit/s, and 6 Gbit/s IT, IR, CT, and CR;
- for 12 Gbit/s IT, IR, CT, CR, ET, and ER; and
- for 22.5 Gbit/s IT, IR, CT, CR, PT, and PR.

Each compliant phy shall be compatible with these electrical requirements to allow interoperability within a SAS environment.

The TxRx connection characteristics are defined in 5.5.

Signal behavior at separable connectors requires compliance with signal characteristics defined by this standard only if the connectors are identified as compliance points by the supplier of the parts that contain the candidate compliance point.

Signal characteristics for compliance points are measured at physical positions called probe points in a test load (see 5.6). Measurements at the probe points in a test load approximate measurements at the compliance point in the actual TxRx connection. Some components in the test load may be de-embedded as described in G.5.

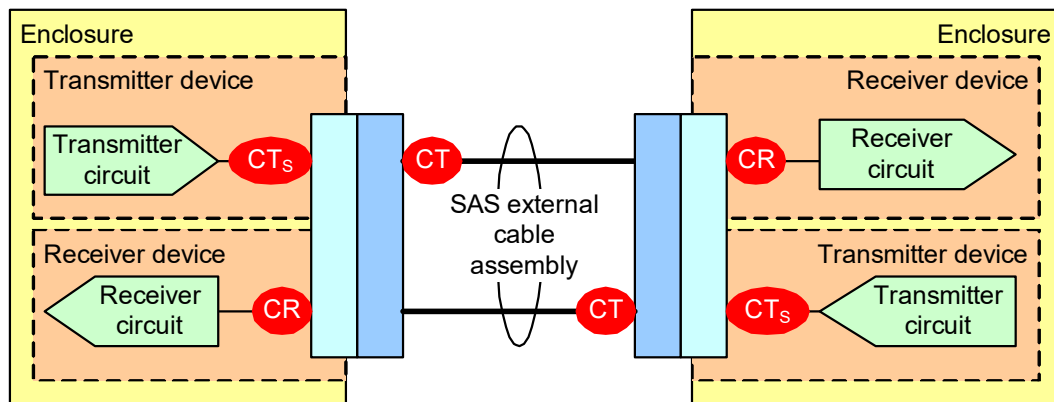
Table 3 — Compliance points

Compliance point	Type	Description
6 Gbit/s, 12 Gbit/s, and 22.5 Gbit/s compliance points		
IT	intra-enclosure (i.e., internal)	The signal from a transmitter device, as measured at probe points in a test load attached with an internal connector.
IT _S	intra-enclosure (i.e., internal)	This location is at the transmitter device side of the internal connector with a test load or a TxRx connection attached with an internal connector.
IR	intra-enclosure (i.e., internal)	The signal going to a receiver device, as measured at probe points in a test load attached with an internal connector.
CT	inter-enclosure (i.e., cabinet)	The signal from a transmitter device, as measured at probe points in a test load attached with an external connector.
CT _S	inter-enclosure (i.e., cabinet)	This location is at the transmitter device side of the external connector with a test load or a TxRx connection attached with an external connector.
CR	inter-enclosure (i.e., cabinet)	The signal going to a receiver device, as measured at probe points in a test load attached with an external connector.
12 Gbit/s only compliance points		
ET	transmitter circuit	The output signal from a transmitter circuit measured with the test load, TDCS, and TCCS de-embedded.
ER	receiver post equalization	A point defined at the output of the reference receiver device.
22.5 Gbit/s only compliance points		
PT	Transmitter device component edge	The location of a transmitter device where S-parameters are measured and where the TxRx connection begins for 22.5 Gbit/s.
PR	Receiver device component edge	The location of a receiver device where S-parameters are measured and where the TxRx connection ends for 22.5 Gbit/s.

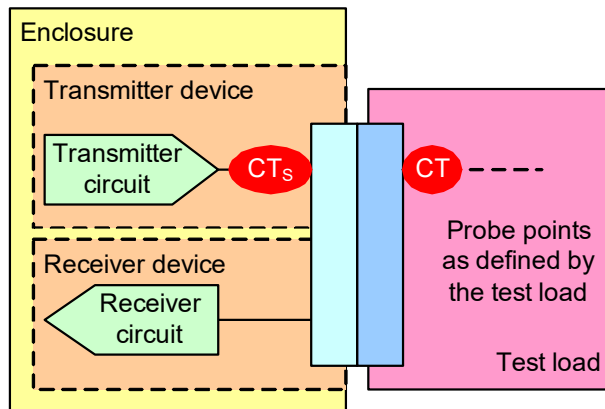
5.3.2 6 Gbit/s compliance points

The 6 Gbit/s TxRx connection includes the characteristics of the mated connectors at both the transmitter device and receiver device ends. One end of a TxRx connection is a IT_S compliance point or CT_S compliance point, and the other end of the TxRx connection is the corresponding IR compliance point or CR compliance point.

Figure 5 shows the locations of the 6 Gbit/s CT compliance points and CR compliance points using an external cable assembly, and shows how two of the compliance points are tested using test loads (see 5.6).



Testing the top-left CT:



Testing the top-right CR:

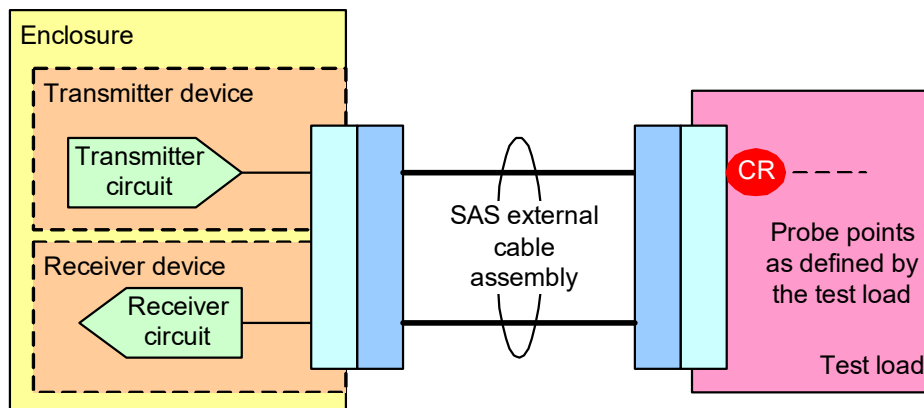


Figure 5 — 6 Gbit/s External cable assembly CT compliance points and CR compliance points

Figure 6 shows the locations of the 6 Gbit/s IT compliance points and IR compliance points using a backplane with a SAS Drive backplane connector (see 5.4.3.3.1.3) that is not using SATA and shows how the compliance points are tested using test loads (see 5.6).

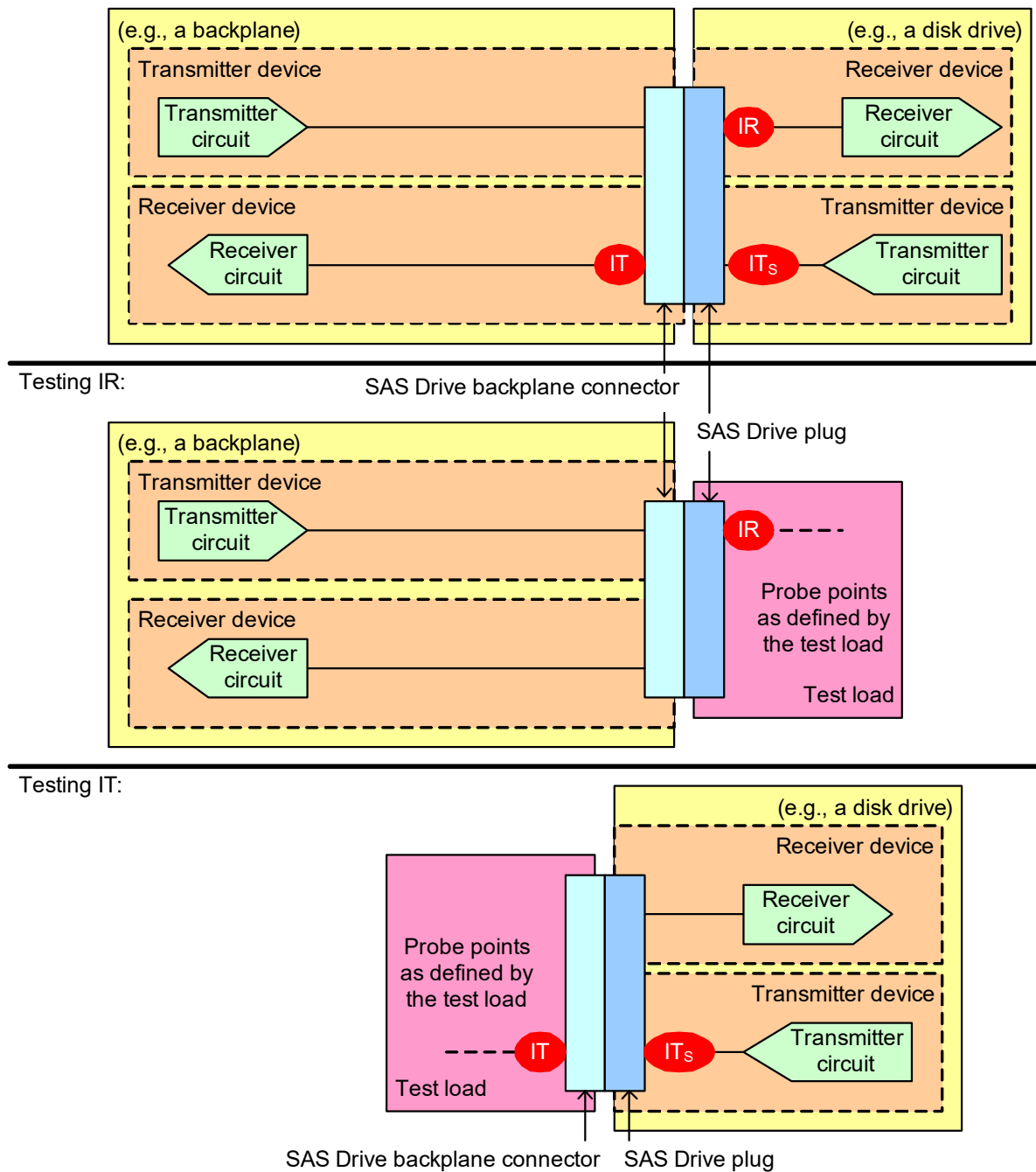


Figure 6 — Backplane with SAS Drive connector 6 Gbit/s IT compliance points and IR compliance points

If the backplane supports SATA, then there are no 6 Gbit/s IT compliance points or IR compliance points. SATA defines the signal characteristics that the SATA phy delivers and that the SAS backplane is required to deliver to the SATA device, as shown in figure 7.

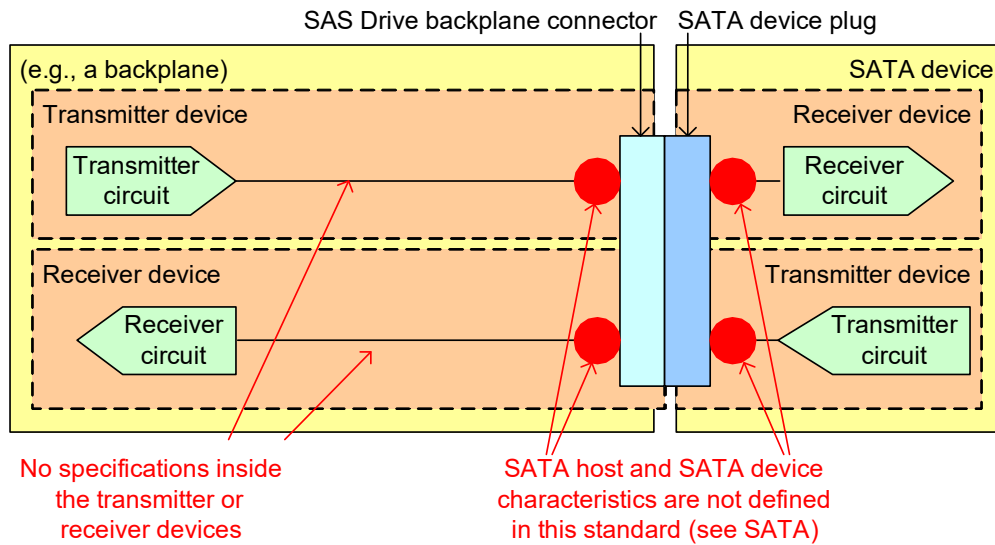


Figure 7 — Backplane with SAS Drive connector 6 Gbit/s compliance points with SATA phy attached

Figure 8 shows the locations of the 6 Gbit/s IT compliance points and IR compliance points using a SAS multilane internal cable assembly, and shows how two of the compliance points are tested using test loads (see 5.6).

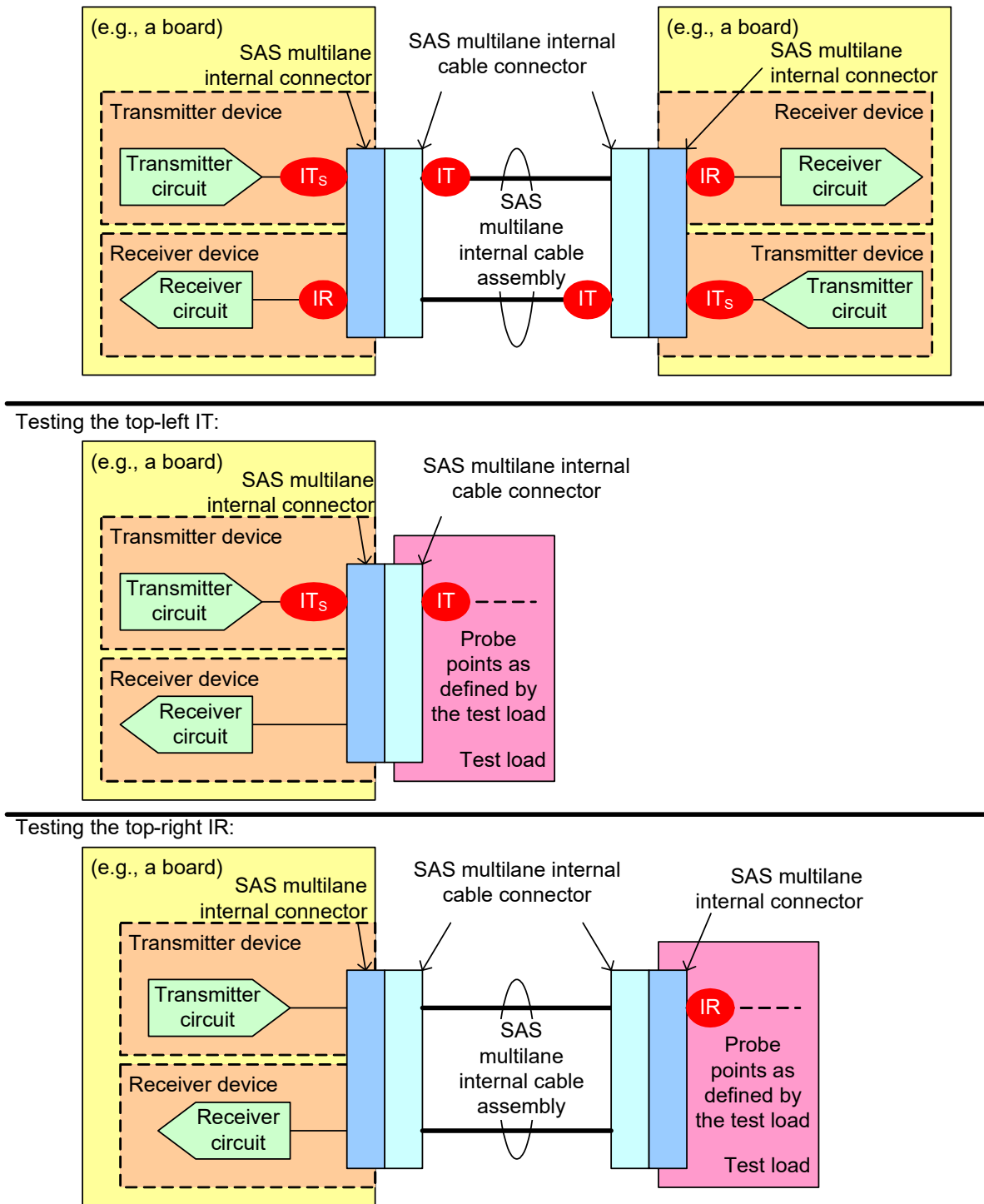


Figure 8 — SAS multilane internal cable assembly 6 Gbit/s IT compliance points and IR compliance points

Figure 9 shows the locations of the 6 Gbit/s IT compliance points and IR compliance points using a SAS multilane internal cable assembly attached to a backplane with a SAS Drive backplane connector (see 5.4.3.3.1.3), where the backplane is not attached to a SATA device, and shows how two of the compliance points are tested using test loads (see 5.6).

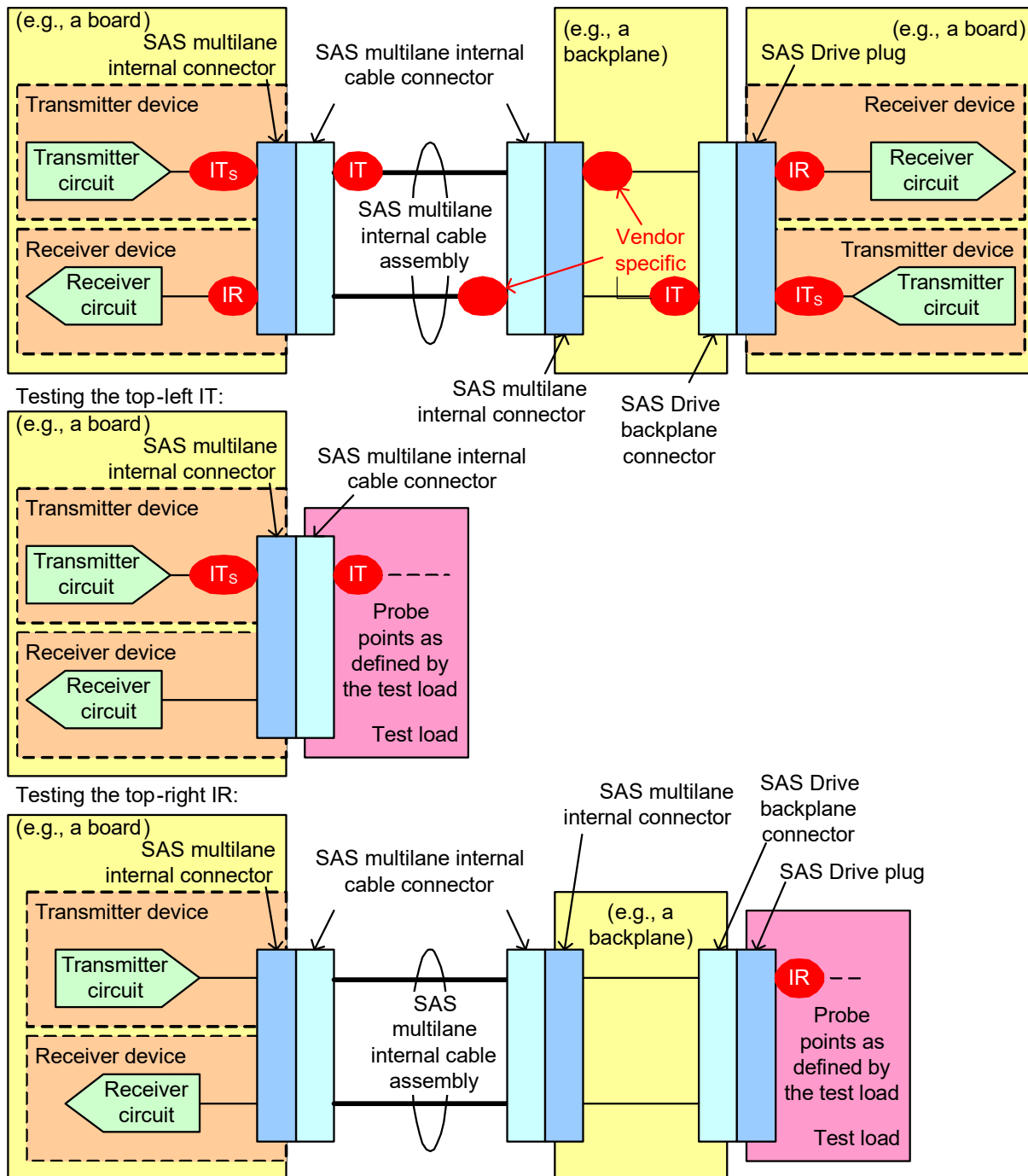


Figure 9 — SAS multilane internal cable assembly and backplane 6 Gbit/s IT compliance points and IR compliance points

Figure 10 shows the locations of the 6 Gbit/s IT compliance points and IR compliance points using a SAS multilane internal cable assembly attached to a backplane with a SAS Drive backplane connector (see 5.4.3.3.1.3) that supports being attached to a SATA device. There are no IT compliance points and IR compliance points at the SAS Drive backplane connector when a SATA device is attached. In that case, SATA defines the signal characteristics that the SATA device delivers and that the SAS backplane is required to deliver to the SATA device. There are compliance points at the SAS multilane internal connector.

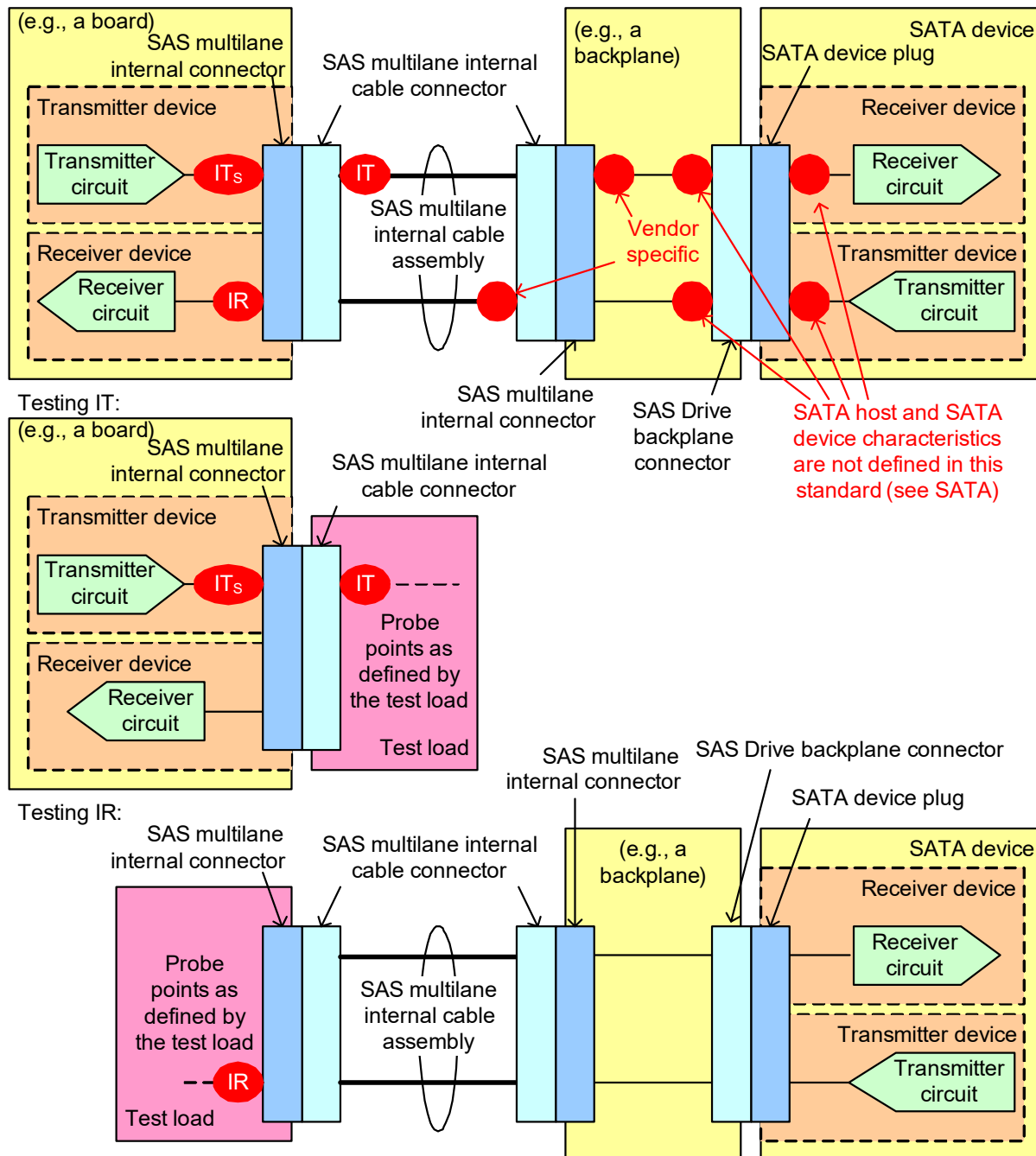
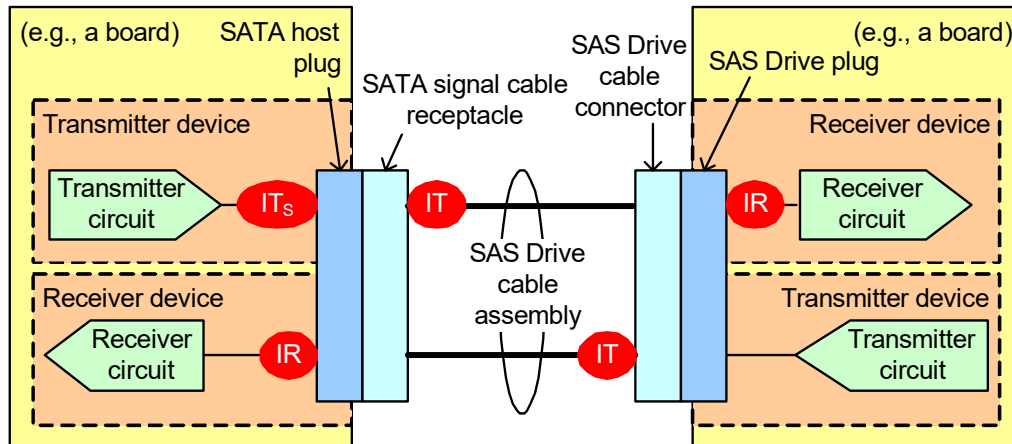
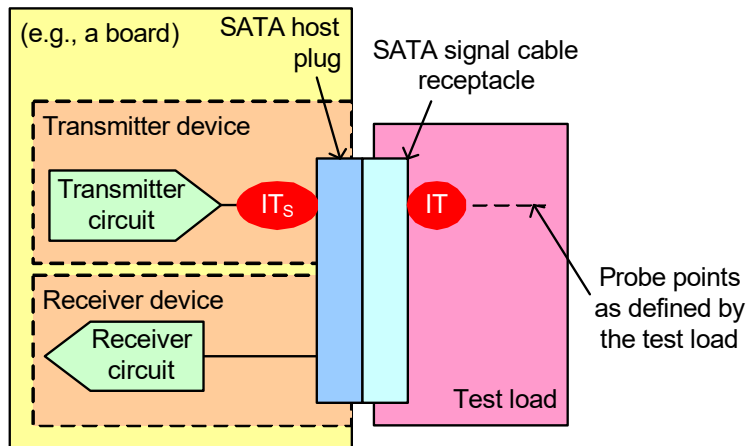


Figure 10 — SAS multilane internal cable assembly and backplane 6 Gbit/s IT compliance points and IR compliance points with SATA device attached

Figure 11 shows the locations of the 6 Gbit/s IT compliance points and IR compliance points using a SAS Drive cable assembly, and shows how two of the compliance points are tested using test loads (see 5.6).



Testing the top-left IT:



Testing the top-right IR:

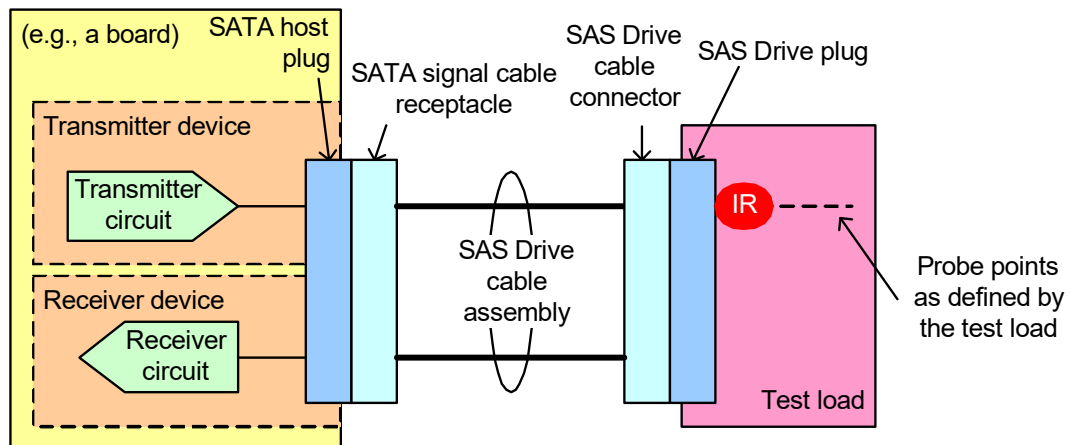


Figure 11 — SAS Drive cable assembly 6 Gbit/s IT compliance points and IR compliance points

5.3.3 12 Gbit/s compliance points

Figure 12 shows an example TxRx connection for trained 12 Gbit/s where PICS is the physical interconnect connection segment.

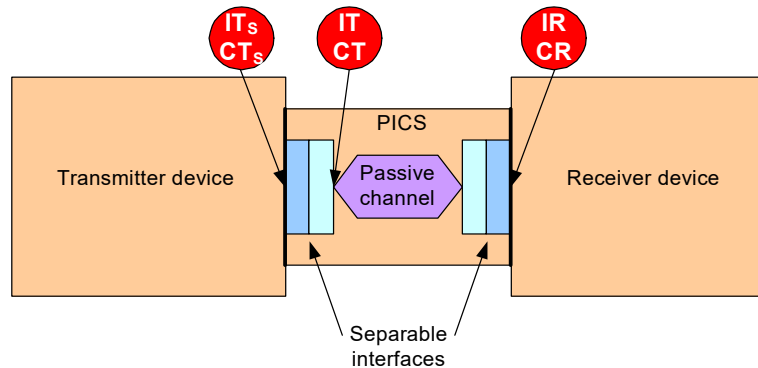


Figure 12 — 12 Gbit/s TxRx connection and compliance points

Figure 13 shows an example of a simulated TxRx connection for trained 12 Gbit/s where:

- a) TDCS is the transmitter device TxRx connection segment;
- b) TCCS is the transmitter circuit TxRx connection segment;
- c) RDCS is the receiver device TxRx connection segment;
- d) RCCS is the receiver circuit TxRx connection segment; and
- e) PICS is the physical interconnect connection segment.

If simulations use a captured signal, then the TxRx connection segments located between ET and the compliance point used to capture the signal should be modeled as a single TxRx connection segment. End to end simulations (see 5.7.1) compute characteristics of the signal at ET and ER, using measurements taken:

- a) at:
 - A) IT;
 - B) CT;
 - C) IR; or
 - D) CR;
 or
- b) between:
 - A) CT_S and CR; or
 - B) IT_S and IR.

If the reference TxRx connection segment models provided for end to end simulations (see C.2) represent TxRx connection segments that are adjacent in the TxRx connection segment, then the TxRx connection segment models may be combined to simulate a single TxRx connection segment model.

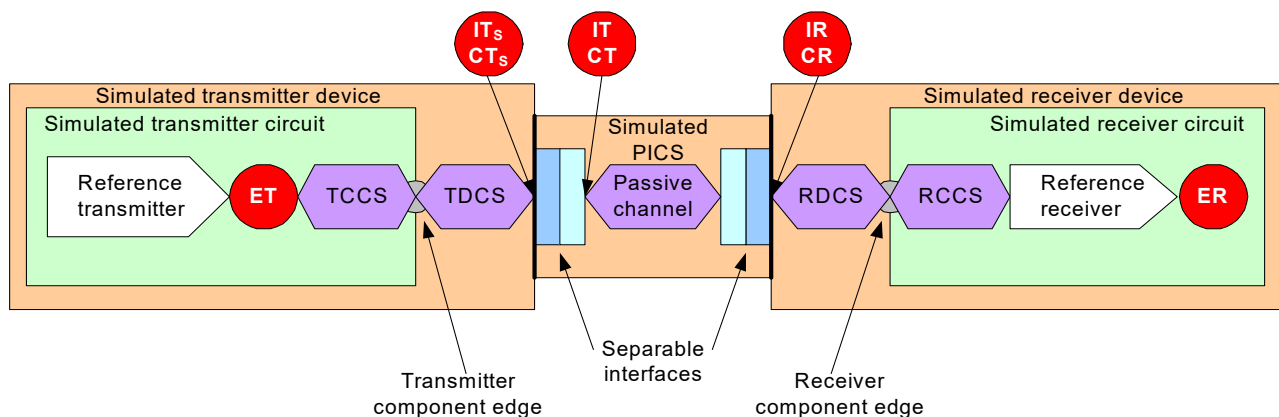
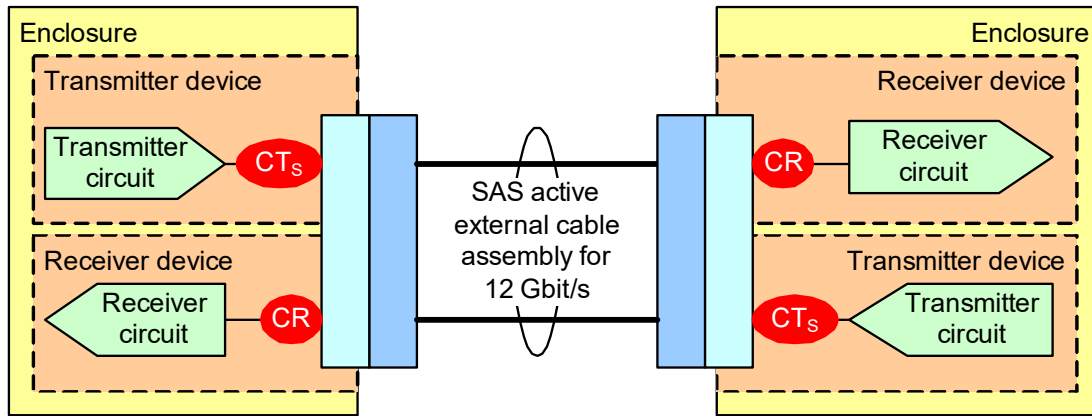


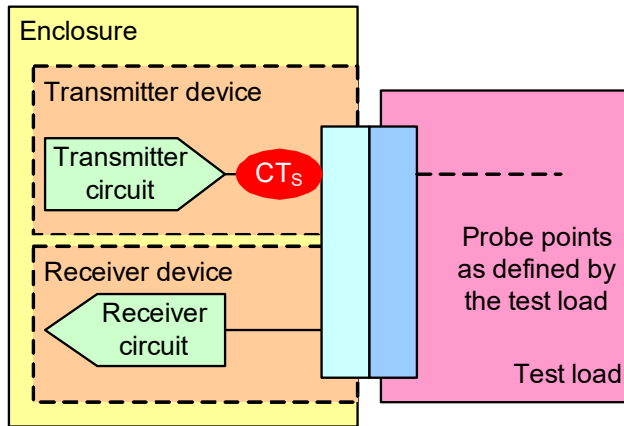
Figure 13 — Simulated 12 Gbit/s TxRx connection and compliance points

Figure 14 shows:

- the locations of the CT_S compliance points and CR compliance points of an enclosure using an external cable connector; and
- how the enclosure CT_S compliance point and the SAS active cable assembly for 12 Gbit/s CR compliance point are tested using test loads (see 5.6).



Testing the enclosure CT_S:



Testing the active cable assembly for 12 Gbit/s differential signal pair CR:

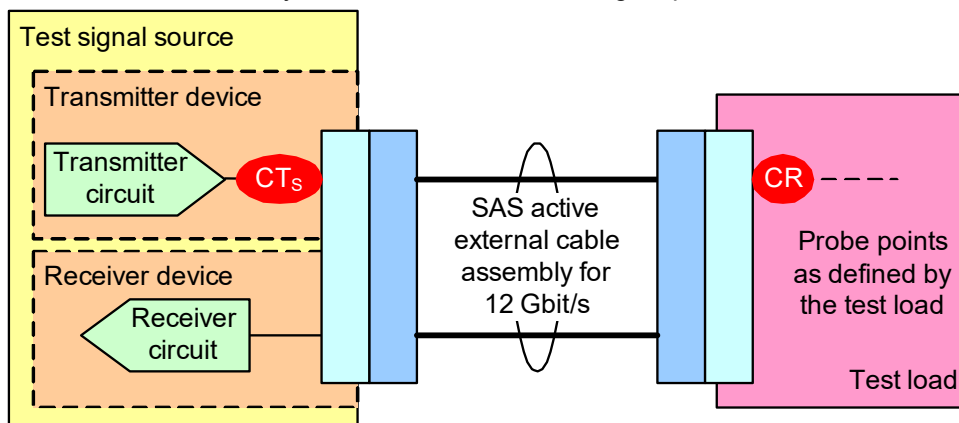


Figure 14 — 12 Gbit/s CT_S and CR compliance points

5.3.4 22.5 Gbit/s compliance points

The trained 22.5 Gbit/s TxRx connection extends from the transmitter device component edge to the receiver device component edge. One end of a TxRx connection is a PT compliance point, and the other end of the TxRx connection is the corresponding PR compliance point. Figure 15 shows an example TxRx connection for trained 22.5 Gbit/s.

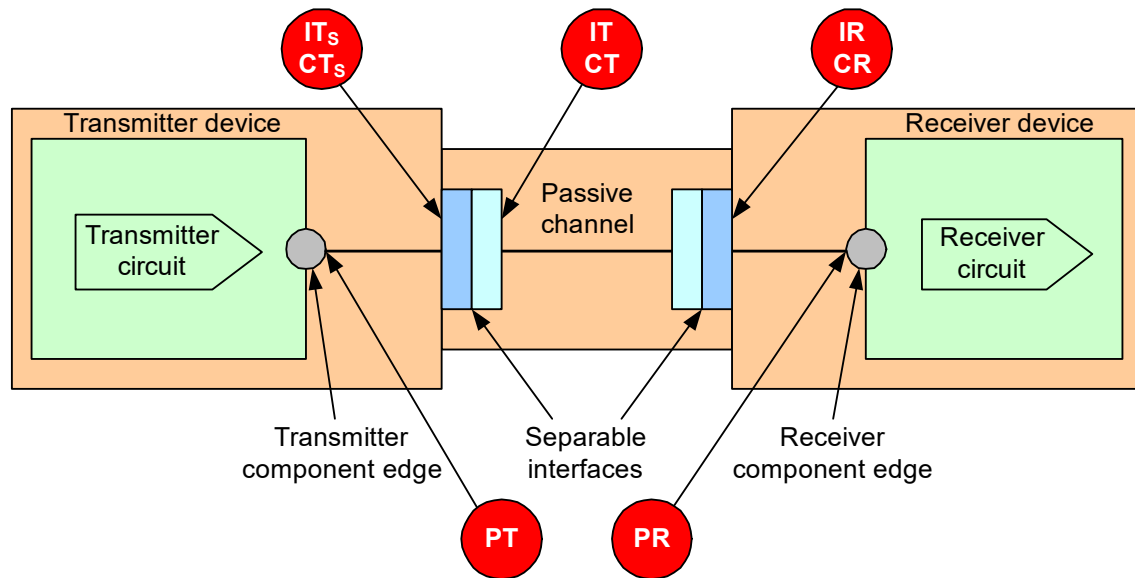
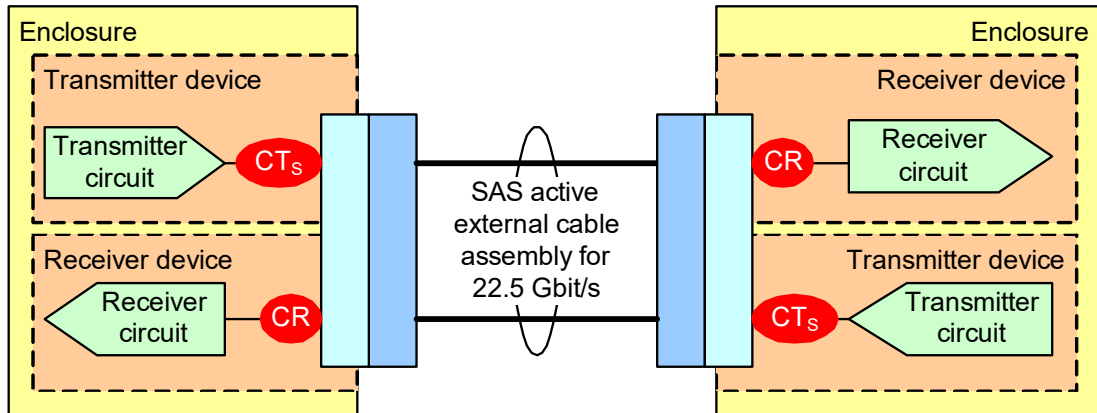


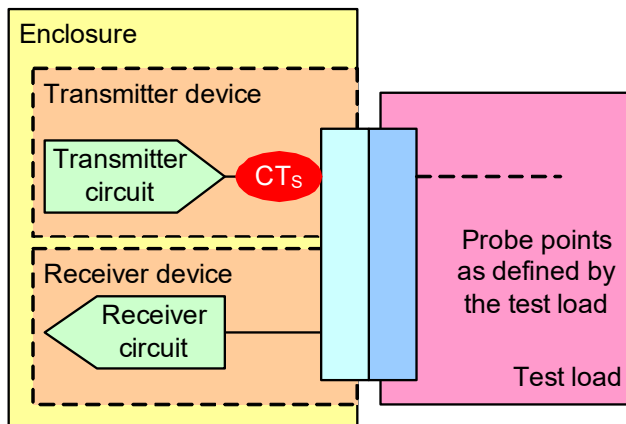
Figure 15 — 22.5 Gbit/s compliance points

Figure 16 shows:

- the locations of the CT_S compliance points and CR compliance points of an enclosure using an external cable connector; and
- how the enclosure CT_S compliance point and the SAS active cable assembly for 22.5 Gbit/s CR compliance point are tested using test loads (see 5.6).



Testing the enclosure CT_S:



Testing the active cable assembly for 22.5 Gbit/s differential signal pair CR:

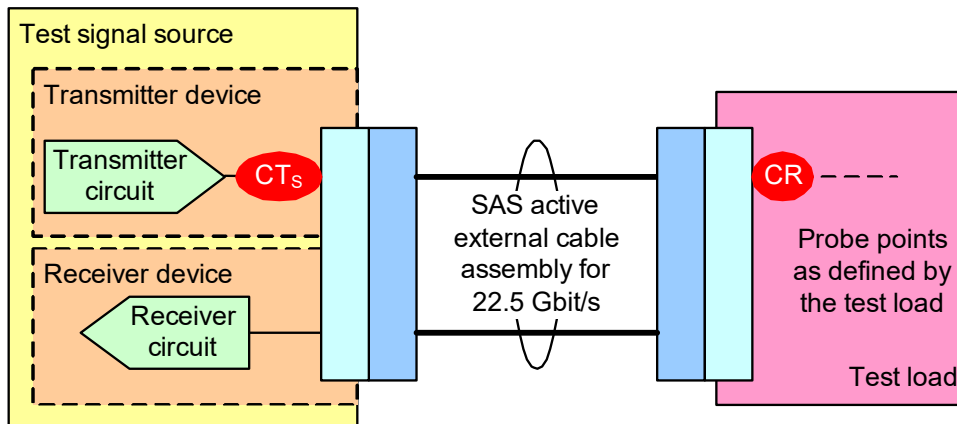


Figure 16 — 22.5 Gbit/s CT_S and CR compliance points

5.4 Interconnects

5.4.1 SATA connectors and cable assemblies

Figure 17 shows a representation of the connectors and cables defined by SATA. A SATA host is analogous to a SAS initiator device (see SPL-5) and a SATA device is analogous to a SAS target device (see SPL-5).

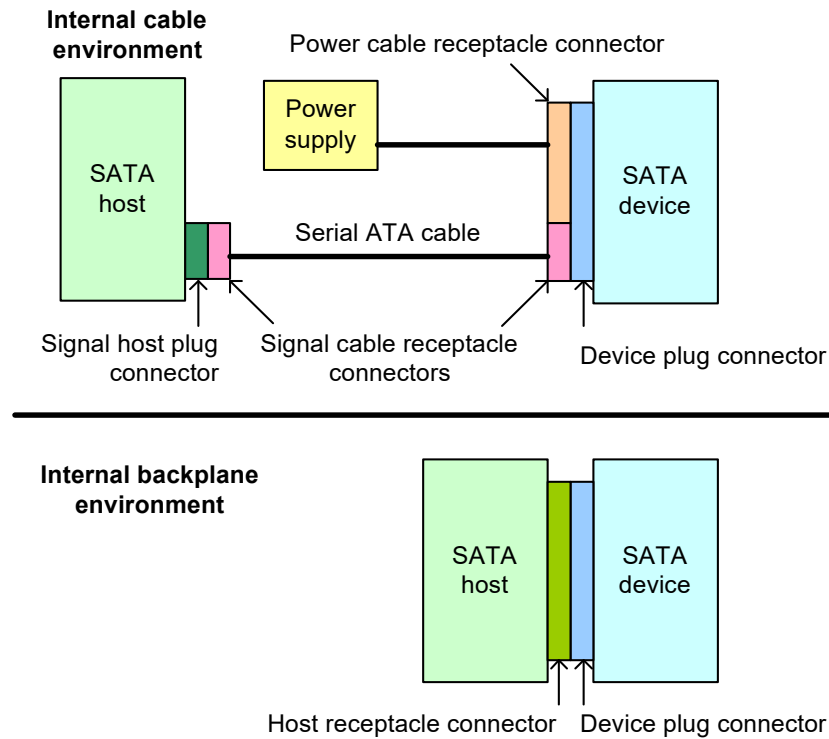


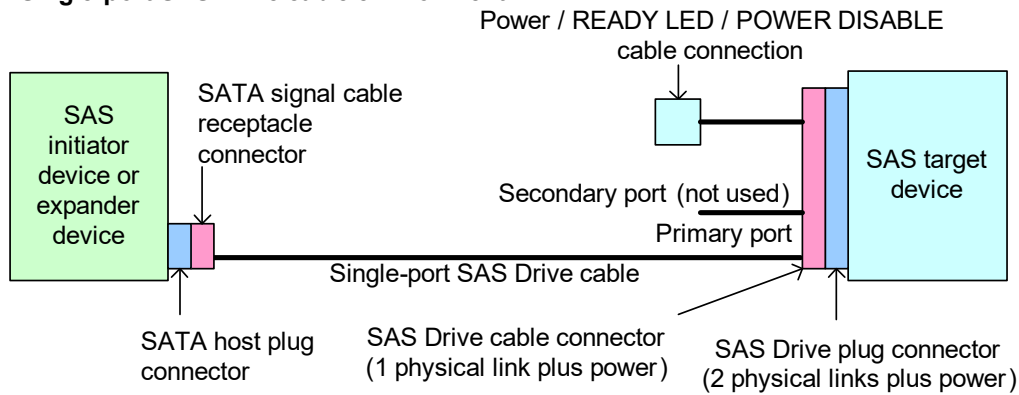
Figure 17 — SATA connectors and cables

5.4.2 SAS connectors and cables

This standard defines SAS Drive cable, SAS Drive backplane, SAS internal cable, and SAS external cable environments.

Figure 18 shows a representation of the SAS Drive cable environments.

Single-port SAS Drive cable environment



Dual-port SAS Drive cable environment

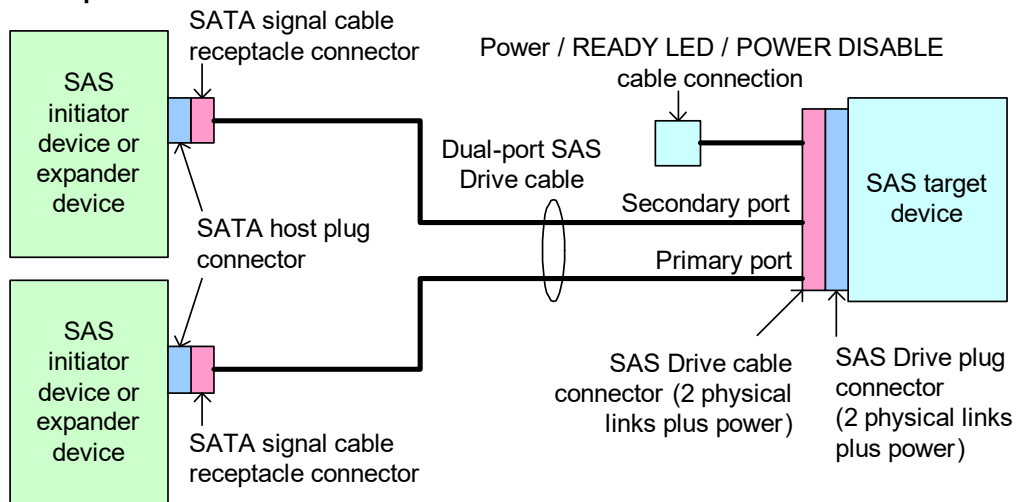


Figure 18 — SAS Drive cable environments

Figure 19 shows a representation of the SAS Drive backplane environment.

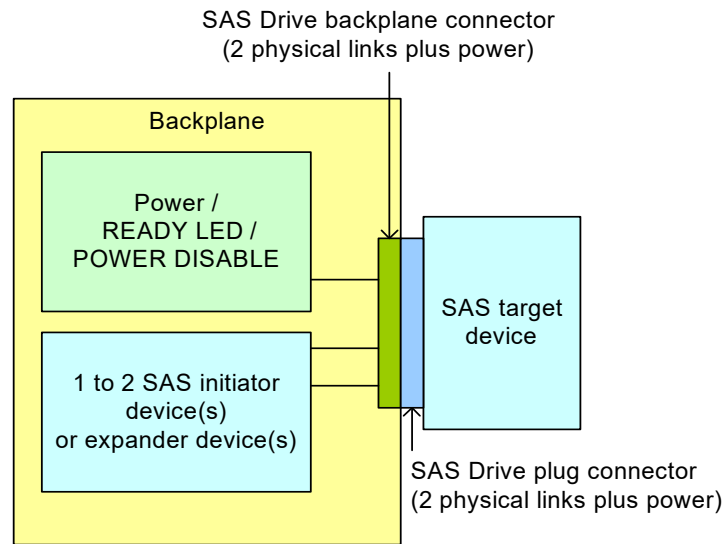


Figure 19 — SAS Drive backplane environment

Figure 20 shows a representation of the SAS external cable environment.

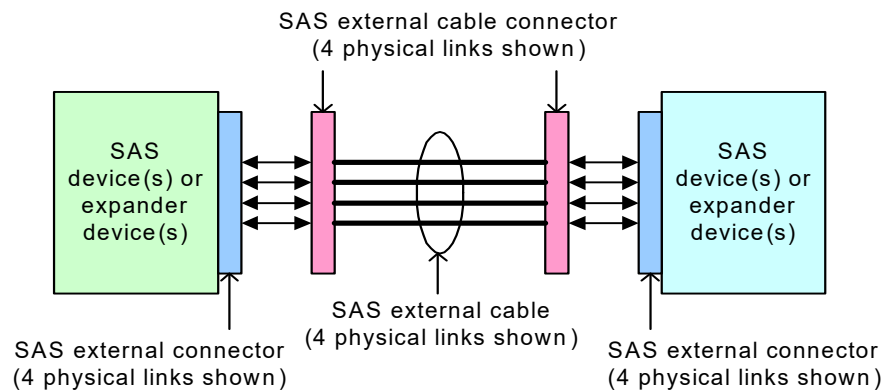


Figure 20 — SAS external cable environment

Figure 21 shows a representation of the SAS internal cable environment attaching a controller to a backplane using a SAS internal symmetric cable (see 5.4.4.1.2).

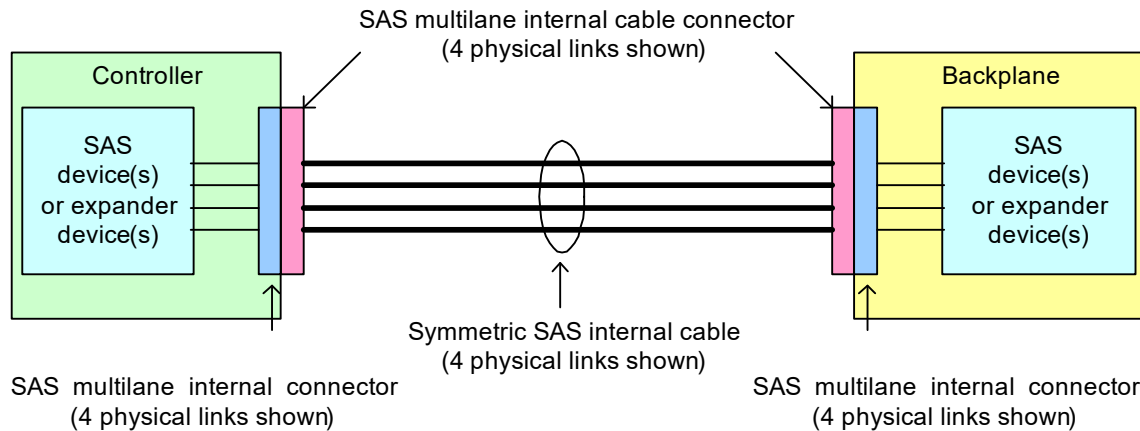


Figure 21 — SAS internal symmetric cable environment - controller to backplane

A SAS internal symmetric cable provides one to eight physical links, and may be used as any combination of wide links and narrow links (see SPL-5) using those physical links.

Figure 22 shows a representation of the SAS internal cable environment attaching a controller to a controller using a SAS internal symmetric cable (see 5.4.4.1.2).

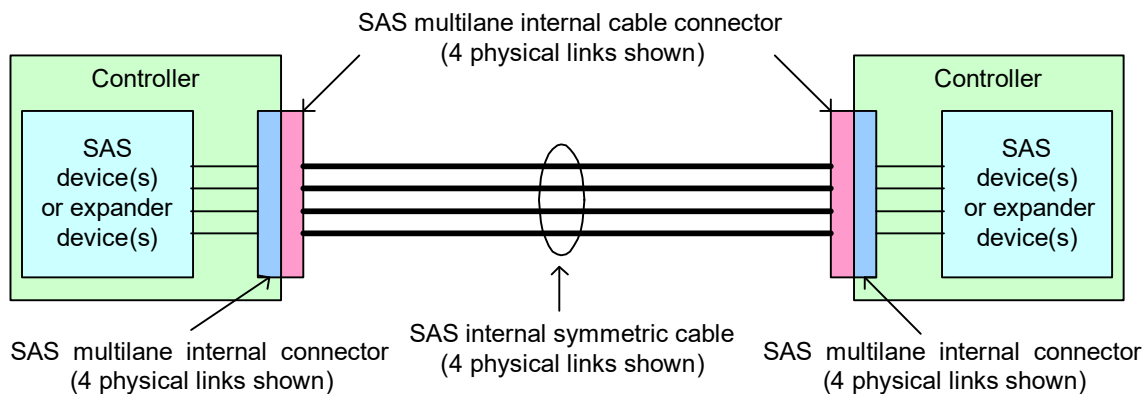


Figure 22 — SAS internal symmetric cable environment - controller to controller

Figure 23 shows a representation of the SAS internal cable environment using a SAS controller-based fanout cable (see 5.4.4.1.3).

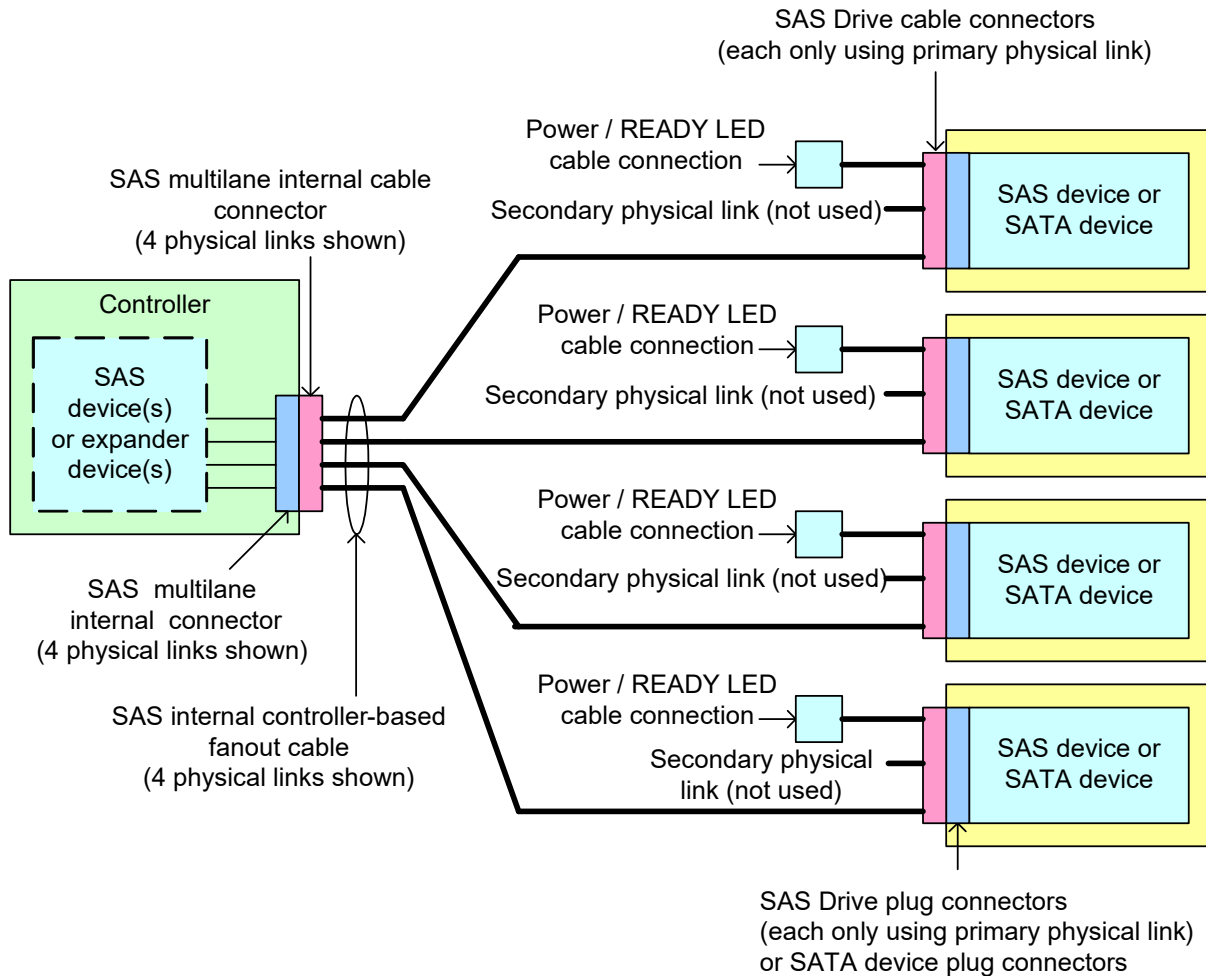


Figure 23 — SAS internal controller-based fanout cable environment

Figure 24 shows a representation of the SAS internal cable environment using a SAS backplane-based fanout cable (see 5.4.4.1.3).

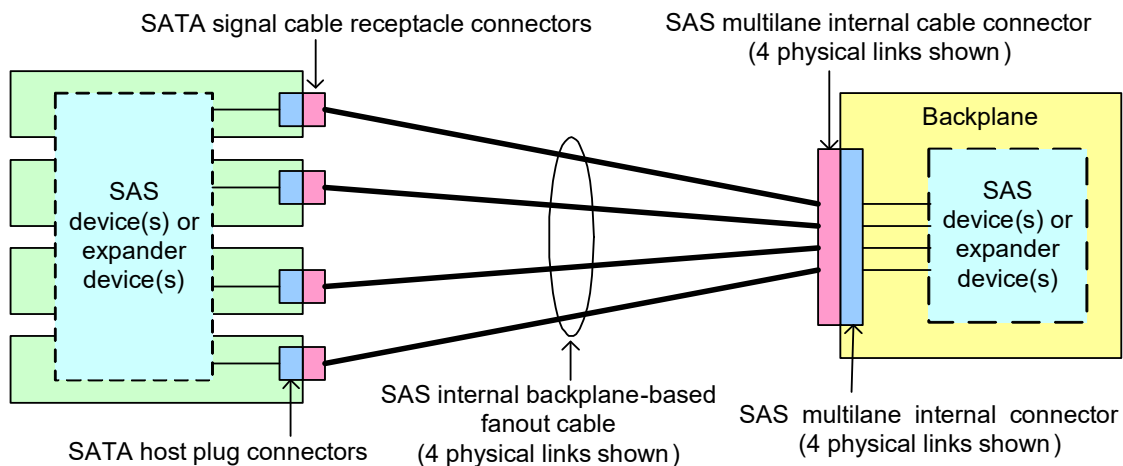


Figure 24 — SAS internal backplane-based fanout cable environment

5.4.3 Connectors

5.4.3.1 Connectors overview

Table 4 summarizes the connectors defined in this standard.

Table 4 — Connectors (part 1 of 4)

Type of connector	Physical links	Reference	Attaches to		
			Type of connector	Physical links	Reference
SATA internal connectors used by SAS					
SATA signal cable receptacle	1	See SATA	SATA host plug	1	See SATA
SATA host plug	1	See SATA	SATA signal cable receptacle	1	See SATA
SATA device plug	1	See SATA	SAS Drive cable connector	1 or 2	5.4.3.3.1.2
			SAS Drive backplane connector	2	5.4.3.3.1.3
			SAS MultiLink Drive cable connector	4	5.4.3.3.1.6
			SAS MultiLink Drive backplane connector	4	5.4.3.3.1.7
			Multifunction 6X Unshielded receptacle connector	6 ^a	See SFF-8639
Micro SATA device plug	1	See SATA	Micro SAS receptacle	2	5.4.3.3.1.10
SAS internal connectors - SAS Drive connectors					
SAS Drive plug	2	5.4.3.3.1.1	SAS Drive cable connector	1 or 2	5.4.3.3.1.2
			SAS Drive backplane connector	2	5.4.3.3.1.3
			SAS MultiLink Drive cable connector	4	5.4.3.3.1.6
			SAS MultiLink Drive backplane connector	4	5.4.3.3.1.7
			Multifunction 6X Unshielded receptacle connector	6 ^a	See SFF-8639
SAS Drive cable connector	1 or 2	5.4.3.3.1.2	SAS Drive plug	2	5.4.3.3.1.1
			SAS MultiLink Drive plug	4	5.4.3.3.1.5
			SATA device plug	1	See SATA
SAS Drive backplane connector	2	5.4.3.3.1.3	SAS Drive plug	2	5.4.3.3.1.1
			SAS MultiLink Drive plug	4	5.4.3.3.1.5
			SATA device plug	1	See SATA
^a A maximum of four physical links support SAS applications.					

Table 4 — Connectors (part 2 of 4)

Type of connector	Physical links	Reference	Attaches to		
			Type of connector	Physical links	Reference
SAS Multilink Drive plug	4	5.4.3.3.1.5	SAS Drive cable connector	1 or 2	5.4.3.3.1.2
			SAS Drive backplane connector	2	5.4.3.3.1.3
			SAS MultiLink Drive cable connector	4	5.4.3.3.1.6
			SAS MultiLink Drive backplane connector	4	5.4.3.3.1.7
			Multifunction 6X Unshielded receptacle connector	6 ^a	See SFF-8639
SAS MultiLink Drive cable connector	4	5.4.3.3.1.6	SAS Drive plug	2	5.4.3.3.1.1
			SAS MultiLink Drive plug	4	5.4.3.3.1.5
			SATA device plug	1	See SATA
SAS MultiLink Drive backplane connector	4	5.4.3.3.1.7	SAS Drive plug	2	5.4.3.3.1.1
			SAS MultiLink Drive plug	4	5.4.3.3.1.5
			SATA device plug	1	See SATA
Multifunction 12 Gb/s 6x Unshielded receptacle connector	6 ^a	See SFF-8639	SAS Drive plug	2	5.4.3.3.1.1
			SAS MultiLink Drive plug	4	5.4.3.3.1.5
			SATA device plug	1	See SATA
Micro SAS plug	2	5.4.3.3.1.9	Micro SAS receptacle	2	5.4.3.3.1.10
Micro SAS receptacle	2	5.4.3.3.1.10	Micro SAS plug	2	5.4.3.3.1.9
			Micro SATA device plug	1	See SATA
SAS High Density Drive plug		Obsolete			
SAS High Density Drive backplane connector		Obsolete			
SAS internal connectors - other					
SAS 4i cable receptacle		Obsolete			
SAS 4i plug		Obsolete			
Mini SAS 4i cable plug		Obsolete			
Mini SAS 4i receptacle		Obsolete			
Mini SAS HD 4i cable plug	4	5.4.3.3.2.1	Mini SAS HD 4i receptacle	4	5.4.3.3.2.3
			Mini SAS HD 8i receptacle	8	5.4.3.3.2.4
			Mini SAS HD 16i receptacle	16	5.4.3.3.2.5
Mini SAS HD 8i cable plug	8	5.4.3.3.2.2	Mini SAS HD 8i receptacle	8	5.4.3.3.2.4
			Mini SAS HD 16i receptacle	16	5.4.3.3.2.5
Mini SAS HD 4i receptacle	4	5.4.3.3.2.3	Mini SAS HD 4i cable plug	4	5.4.3.3.2.1
Mini SAS HD 8i receptacle	8	5.4.3.3.2.4	Mini SAS HD 4i cable plug	4	5.4.3.3.2.1
			Mini SAS HD 8i cable plug	8	5.4.3.3.2.2
^a A maximum of four physical links support SAS applications.					

Table 4 — Connectors (part 3 of 4)

Type of connector	Physical links	Reference	Attaches to		
			Type of connector	Physical links	Reference
Mini SAS HD 16i receptacle	16	5.4.3.3.2.5	Mini SAS HD 4i cable plug	4	5.4.3.3.2.1
			Mini SAS HD 8i cable plug	8	5.4.3.3.2.2
SlimSAS 4i cable plug	4	5.4.3.3.3.1	SlimSAS 4i receptacle	4	5.4.3.3.3.3
SlimSAS 4i receptacle	4	5.4.3.3.3.3	SlimSAS 4i cable plug	4	5.4.3.3.3.1
SlimSAS 8i cable plug	8	5.4.3.3.3.2	SlimSAS 8i receptacle	8	5.4.3.3.3.4
SlimSAS 8i receptacle	8	5.4.3.3.3.4	SlimSAS 8i cable plug	8	5.4.3.3.3.2
SAS MiniLink 4i cable plug	4	5.4.3.3.4.1	SAS MiniLink 4i receptacle	4	5.4.3.3.4.3
SAS MiniLink 4i receptacle	4	5.4.3.3.4.3	SAS MiniLink 4i cable plug	4	5.4.3.3.4.1
SAS MiniLink 8i cable plug	8	5.4.3.3.4.2	SAS MiniLink 8i receptacle	8	5.4.3.3.4.4
SAS MiniLink 8i receptacle	8	5.4.3.3.4.4	SAS MiniLink 8i cable plug	8	5.4.3.3.4.2
SlimSAS HD 4i cable plug	4	5.4.3.3.5.1	SlimSAS HD 4i receptacle	4	5.4.3.3.5.4
SlimSAS HD 4i receptacle	4	5.4.3.3.5.4	SlimSAS HD 4i cable plug	4	5.4.3.3.5.1
SlimSAS HD 8i cable plug	8	5.4.3.3.5.2	SlimSAS HD 8i receptacle	8	5.4.3.3.5.5
SlimSAS HD 8i receptacle	8	5.4.3.3.5.5	SlimSAS HD 8i cable plug	8	5.4.3.3.5.2
SlimSAS HD 16i cable plug	16	5.4.3.3.5.3	SlimSAS HD 16i receptacle	16	5.4.3.3.5.6
SlimSAS HD 16i receptacle	16	5.4.3.3.5.6	SlimSAS HD 16i cable plug	16	5.4.3.3.5.3
SAS external connectors					
Mini SAS 4x cable plug		Obsolete			
Mini SAS 4x receptacle		Obsolete			
Mini SAS 4x active cable assembly plug		Obsolete			
Mini SAS 4x active receptacle		Obsolete			
Mini SAS HD 4x cable plug	4	5.4.3.4.1.1	Mini SAS HD 4x receptacle	4	5.4.3.4.1.3
			Mini SAS HD 8x receptacle	8	5.4.3.4.1.4
			Mini SAS HD 16x receptacle	16	5.4.3.4.1.5
Mini SAS HD 8x cable plug	8	5.4.3.4.1.2	Mini SAS HD 8x receptacle	8	5.4.3.4.1.4
			Mini SAS HD 16x receptacle	16	5.4.3.4.1.5
Mini SAS HD 4x receptacle	4	5.4.3.4.1.3	Mini SAS HD 4x cable plug	4	5.4.3.4.1.1
^a A maximum of four physical links support SAS applications.					

Table 4 — Connectors (part 4 of 4)

Type of connector	Physical links	Reference	Attaches to		
			Type of connector	Physical links	Reference
Mini SAS HD 8x receptacle	8	5.4.3.4.1.4	Mini SAS HD 4x cable plug	4	5.4.3.4.1.1
			Mini SAS HD 8x cable plug	8	5.4.3.4.1.2
Mini SAS HD 16x receptacle	16	5.4.3.4.1.5	Mini SAS HD 4x cable plug	4	5.4.3.4.1.1
			Mini SAS HD 8x cable plug	8	5.4.3.4.1.2
QSFP cable plug	4	5.4.3.4.2.1	QSFP receptacle	4	5.4.3.4.2.2
QSFP receptacle	4	5.4.3.4.2.2	QSFP cable plug	4	5.4.3.4.2.1
^a A maximum of four physical links support SAS applications.					

A SAS icon (see annex K) should be placed on or near each SAS connector.

5.4.3.2 Connector categories

The relationship between connector categories and connectors is shown in table 5.

Table 5 — Connector categories

Connector category	Connectors in category
Unmanaged passive	All connectors listed in table 4 (see 5.4.3.1) that are not listed elsewhere in this table
Managed	Mini SAS HD external connectors (see 5.4.3.4.1) QSFP connectors (see 5.4.3.4.2)

5.4.3.3 SAS internal connectors

5.4.3.3.1 SAS Drive connectors

5.4.3.3.1.1 SAS Drive plug connector

The SAS Drive plug connector mechanical interface is the device free (plug) connector defined in SFF-8482. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

See SFF-8223, SFF-8323, and SFF-8523 for the SAS Drive plug connector locations on common form factors.

Figure 25 shows the SAS Drive plug connector.

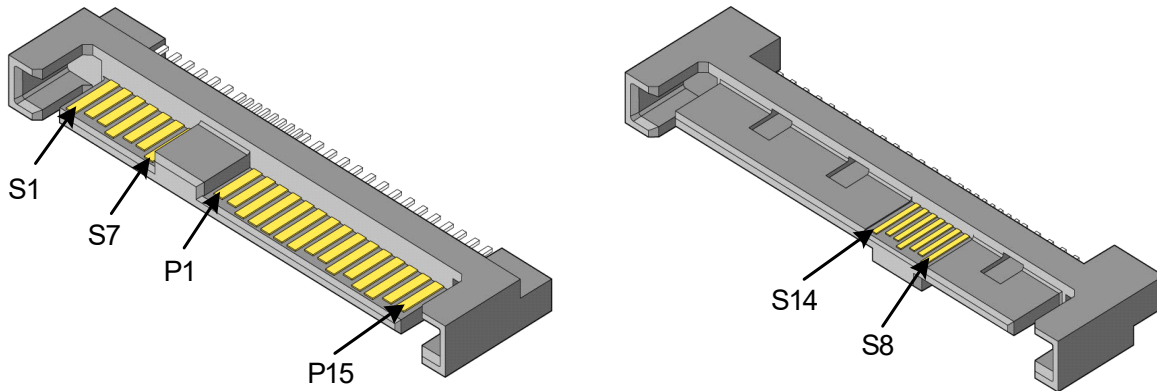


Figure 25 — SAS Drive plug connector

Table 6 defines the pin assignments for the SAS Drive plug connector.

5.4.3.3.1.2 SAS Drive cable connector

The SAS Drive cable connector mechanical interface is the Internal cable fixed (receptacle) connector defined in SFF-8482. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

The single-port version attaches to:

- a SAS Drive plug connector, providing contact for the power pins and only the primary physical link;
- a SAS MultiLink Drive plug connector, providing contact for the power pins and only the primary physical link; or
- a SATA device plug connector, providing contact for the power pins and the primary physical link.

Figure 26 shows the single-port version of the SAS Drive cable connector.

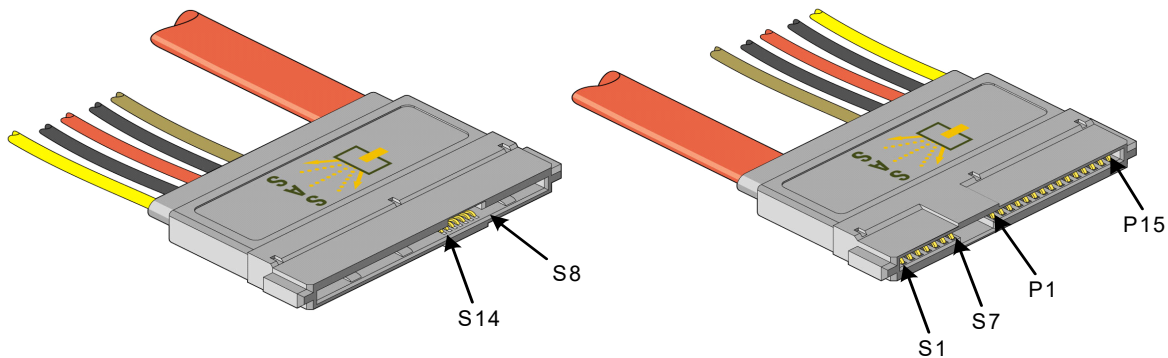


Figure 26 — Single-port SAS Drive cable connector

The dual-port version attaches to:

- a SAS Drive plug connector, providing contact for the power pins and only the primary physical link;
- a SAS Drive plug connector, providing contact for the power pins and both the primary and secondary physical links;
- a SAS MultiLink Drive plug connector, providing contact for the power pins and both the primary and secondary physical links; or
- a SATA device plug connector, providing contact for the power pins and the primary physical link.

Figure 27 shows the dual-port version of the SAS Drive cable connector.

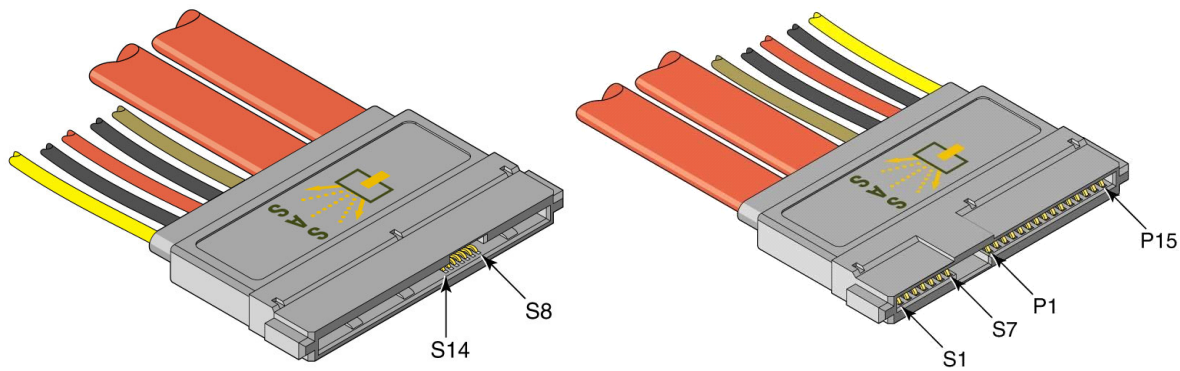


Figure 27 — Dual-port SAS Drive cable connector

Table 6 defines the pin assignments for the SAS Drive cable connector. The secondary physical link (i.e., pins S8 through S14) is not supported by the single-port internal cable connector.

5.4.3.3.1.3 SAS Drive backplane connector

The SAS Drive backplane connector mechanical interface is the backplane fixed (receptacle) connector defined in SFF-8482. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

The SAS Drive backplane connector attaches to:

- a SAS Drive plug connector, providing contact for the power pins and only the primary physical link;
- a SAS Drive plug connector, providing contact for the power pins and both primary and secondary physical links;
- a SAS MultiLink Drive plug connector, providing contact for the power pins and both primary and secondary physical links; or
- a SATA device plug connector, providing contact for the power pins and the primary physical link.

Figure 28 shows the SAS Drive backplane connector.

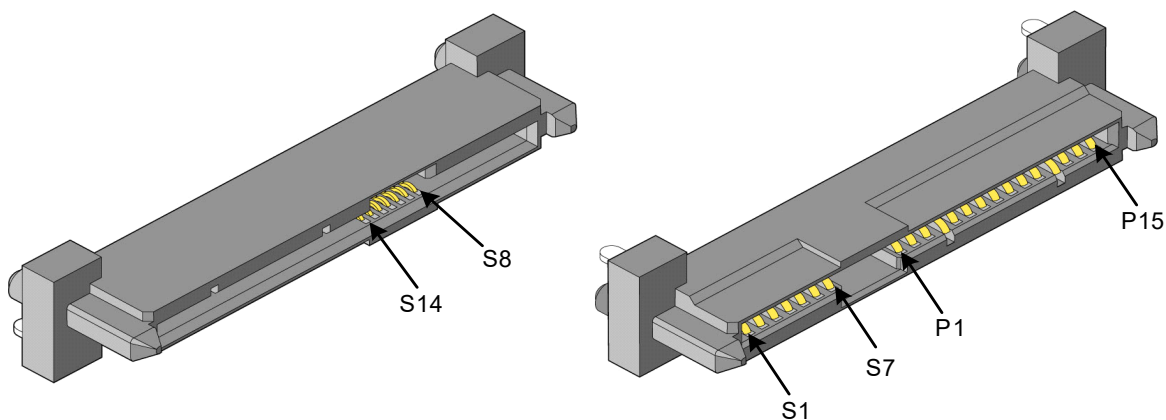


Figure 28 — SAS Drive backplane connector

Table 6 defines the pin assignments for the SAS Drive backplane connector.

5.4.3.3.1.4 SAS Drive connector pin assignments

Table 6 defines the SAS target device pin assignments for the SAS Drive plug connector (see 5.4.3.3.1.1), the SAS Drive cable connector (see 5.4.3.3.1.2), and the SAS Drive backplane connector (see 5.4.3.3.1.3). TP+, TP-, RP+, and RP- are used by the primary physical link. TS+, TS-, RS+, and RS- are used by the secondary physical link, if any.

SAS Drive plug connector pin assignments, except for the addition of the secondary physical link when present, are in the same locations as they are in a SATA device plug connector (see SATA).

Table 6 — SAS Drive connector pin assignments (part 1 of 2)

Segment	Pin ^a	Backplane connector ^a	SAS Drive plug and SAS Drive cable connector ^a
Primary signal segment	S1	SIGNAL GROUND	
	S2	TP+	RP+
	S3	TP-	RP-
	S4	SIGNAL GROUND	
	S5	RP-	TP-
	S6	RP+	TP+
	S7	SIGNAL GROUND	
Secondary signal segment ^b	S8	SIGNAL GROUND	
	S9	TS+	RS+
	S10	TS-	RS-
	S11	SIGNAL GROUND	
	S12	RS-	TS-
	S13	RS+	TS+
	S14	SIGNAL GROUND	

^a Devices supporting other interfaces have different electrical characteristics and functions. See SFF-9639 for a list of interface references and their respective pin assignments.

^b S8 through S14 are not connected on single-port implementations.

^c SAS drive backplane connectors and SAS Drive cable connectors provide V₅ and V₁₂. SAS Drive plug connectors receive V₅ and V₁₂.

^d Behind a SAS Drive plug connector, P1 and P2 are only connected to each other.

^e SAS devices (see SPL-5) with SAS Drive plug connectors compliant with SAS-1.1, SAS-2, or SAS-2.1 connected P1, P2, and P3 together. SAS Drive backplane connectors and SAS Drive cable connectors compliant with SAS-1.1, SAS-2, or SAS-2.1 may provide V_{3.3} to P1, P2, and P3.

^f Electrical characteristics and functions behind SAS Drive backplane connectors, SAS Drive cable connectors, SAS MultiLink Drive backplane connectors (see 5.4.3.3.1.7), and SAS MultiLink Drive cable connectors (see 5.4.3.3.1.6) are beyond the scope of this specification.

^g P3 is not connected behind a SAS Drive plug connector when the POWER DISABLE signal is unsupported. Electrical characteristics for the POWER DISABLE signal are defined in 5.10.

^h Behind a SAS Drive plug connector, the precharge pin and each corresponding voltage pin shall be connected together on the SAS target device (e.g., the V₅, precharge pin P7 is connected to the two V₅ pins P8 and P9).

ⁱ Electrical characteristics for READY LED are defined in 5.9 and signal behavior is defined in SPL-5. SATA devices use P11 for activity indication and staggered spin-up disable and have different electrical characteristics (see SATA).

Table 6 — SAS Drive connector pin assignments (part 2 of 2)

Segment	Pin ^a	Backplane connector ^a	SAS Drive plug and SAS Drive cable connector ^a
Power segment ^c	P1	Vendor specific ^{e f}	See ^{d e f}
	P2	Vendor specific ^{e f}	See ^{d e f}
	P3	Vendor specific or POWER DISABLE ^{e f g}	POWER DISABLE ^{e f g}
	P4	GROUND	
	P5	GROUND	
	P6	GROUND	
	P7	V ₅ , precharge ^h	
	P8	V ₅ ^h	
	P9	V ₅ ^h	
	P10	GROUND	
	P11	READY LED ⁱ	
	P12	GROUND	
	P13	V ₁₂ , precharge ^h	
	P14	V ₁₂ ^h	
	P15	V ₁₂ ^h	
^a Devices supporting other interfaces have different electrical characteristics and functions. See SFF-9639 for a list of interface references and their respective pin assignments. ^b S8 through S14 are not connected on single-port implementations. ^c SAS drive backplane connectors and SAS Drive cable connectors provide V ₅ and V ₁₂ . SAS Drive plug connectors receive V ₅ and V ₁₂ . ^d Behind a SAS Drive plug connector, P1 and P2 are only connected to each other. ^e SAS devices (see SPL-5) with SAS Drive plug connectors compliant with SAS-1.1, SAS-2, or SAS-2.1 connected P1, P2, and P3 together. SAS Drive backplane connectors and SAS Drive cable connectors compliant with SAS-1.1, SAS-2, or SAS-2.1 may provide V _{3.3} to P1, P2, and P3. ^f Electrical characteristics and functions behind SAS Drive backplane connectors, SAS Drive cable connectors, SAS MultiLink Drive backplane connectors (see 5.4.3.3.1.7), and SAS MultiLink Drive cable connectors (see 5.4.3.3.1.6) are beyond the scope of this specification. ^g P3 is not connected behind a SAS Drive plug connector when the POWER DISABLE signal is unsupported. Electrical characteristics for the POWER DISABLE signal are defined in 5.10. ^h Behind a SAS Drive plug connector, the precharge pin and each corresponding voltage pin shall be connected together on the SAS target device (e.g., the V ₅ , precharge pin P7 is connected to the two V ₅ pins P8 and P9). ⁱ Electrical characteristics for READY LED are defined in 5.9 and signal behavior is defined in SPL-5. SATA devices use P11 for activity indication and staggered spin-up disable and have different electrical characteristics (see SATA).			

5.4.3.3.1.5 SAS MultiLink Drive plug connector

The SAS MultiLink Drive plug connector mechanical interface is the device free (plug) connector defined in SFF-8630. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

See SFF-8223, SFF-8323, and SFF-8523 for the SAS Drive plug connector locations on common form factors.

Figure 29 shows the SAS MultiLink Drive plug connector.

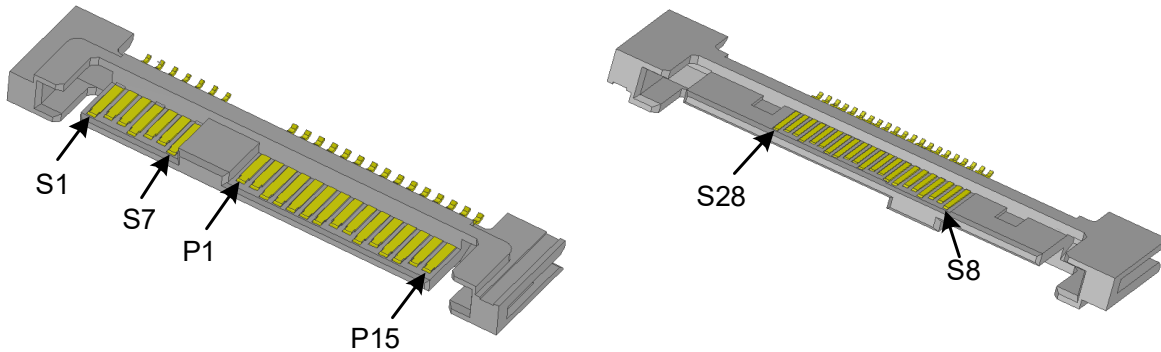


Figure 29 — SAS MultiLink Drive plug connector

Table 7 defines the pin assignments for the SAS MultiLink Drive plug connector.

5.4.3.3.1.6 SAS MultiLink Drive cable connector

The SAS MultiLink Drive cable connector mechanical interface is the Internal cable fixed (receptacle) connector defined in SFF-8630. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

The SAS MultiLink Drive cable connector attaches to:

- a SAS Drive plug connector, providing contact for the power pins and both the primary and secondary physical links;
- a SAS MultiLink Drive plug connector, providing contact for the power pins and four physical links; or
- a SATA device plug connector, providing contact for the power pins and the primary physical link.

Figure 30 shows the SAS MultiLink Drive cable connector.

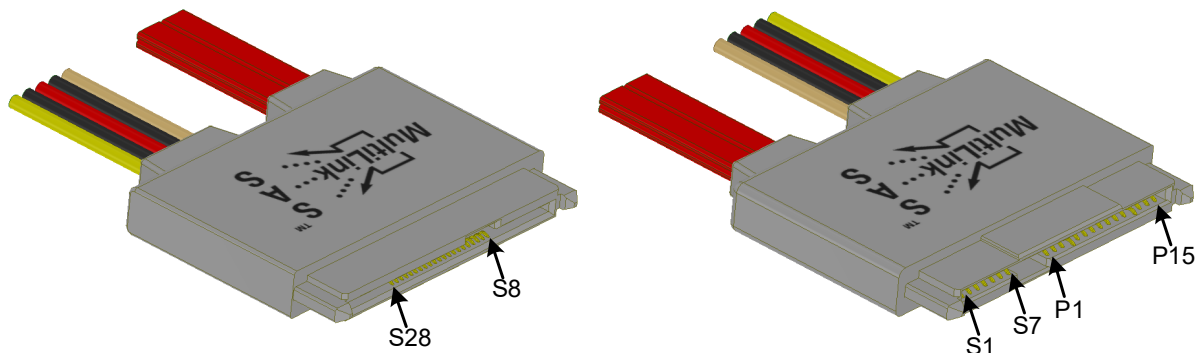


Figure 30 — SAS MultiLink Drive cable connector

Table 7 defines the pin assignments for the SAS MultiLink Drive cable connector.

5.4.3.3.1.7 SAS MultiLink Drive backplane connector

The SAS MultiLink Drive backplane connector mechanical interface is the backplane fixed (receptacle) connector defined in SFF-8630. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

The SAS MultiLink Drive backplane connector attaches to:

- a) a SAS Drive plug connector, providing contact for the power pins and both primary and secondary physical links;
- b) a SAS MultiLink Drive plug connector, providing contact for the power pins and four physical links; or
- c) a SATA device plug connector, providing contact for the power pins and the primary physical link.

Figure 31 shows the SAS MultiLink Drive backplane connector.

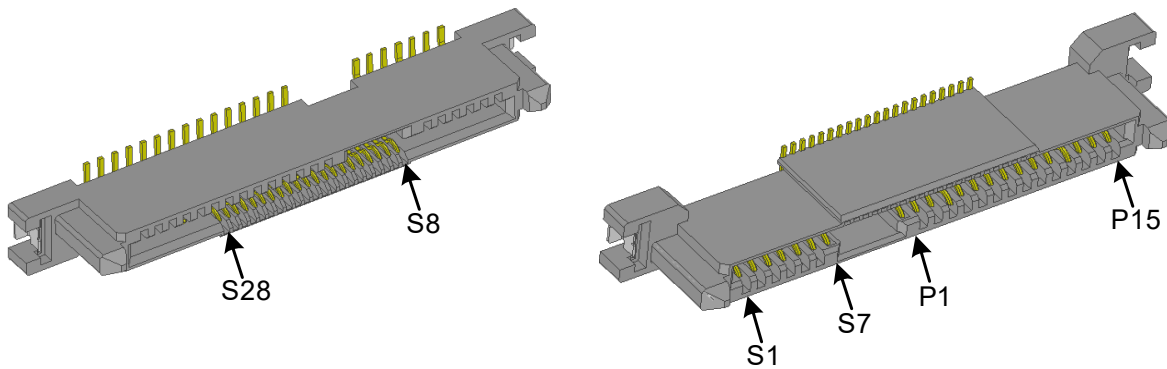


Figure 31 — SAS MultiLink Drive backplane connector

Table 7 defines the pin assignments for the SAS MultiLink Drive backplane connector.

5.4.3.3.1.8 SAS MultiLink Drive connector pin assignments

Table 7 defines the SAS target device pin assignments for the SAS MultiLink Drive plug connector (see 5.4.3.3.1.5), the SAS MultiLink Drive cable connector (see 5.4.3.3.1.6), and the SAS MultiLink Drive backplane connector (see 5.4.3.3.1.7). TX 0+, TX 0-, RX 0+, and RX 0- are used by the signal segment 0 physical link. TX 1+, TX 1-, RX 1+, and RX 1- are used by the signal segment 1 physical link, if any. TX 2+, TX 2-, RX 2+, and RX 2- are used by the signal segment 2 physical link, if any. TX 3+, TX 3-, RX 3+, and RX 3- are used by the signal segment 3 physical link, if any.

Table 7 — SAS MultiLink connector pin assignments (part 1 of 3)

Segment	Pin ^a	SAS MultiLink Drive backplane connector ^a	SAS MultiLink Drive plug and SAS MultiLink Drive cable connector ^a
Signal segment 0	S1	SIGNAL GROUND	
	S2	TX 0+	RX 0+
	S3	TX 0-	RX 0-
	S4	SIGNAL GROUND	
	S5	RX 0-	TX 0-
	S6	RX 0+	TX 0+
	S7	SIGNAL GROUND	
Signal segment 1 ^b	S8	SIGNAL GROUND	
	S9	TX 1+	RX 1+
	S10	TX 1-	RX 1-
	S11	SIGNAL GROUND	
	S12	RX 1-	TX 1-
	S13	RX 1+	TX 1+
	S14	SIGNAL GROUND	
	S15	RESERVED	

^a Devices supporting other interfaces that intermate with SAS devices, backplanes, or cables have different electrical characteristics and functions. See SFF-9639 for a list of interface references and their respective pin assignments.

^b S8 through S28 are not connected on single-port implementations.

^c S16 through S28 are not connected on dual-port implementations.

^d S23 through S28 are not connected on triple-port implementations.

^e SAS MultiLink Drive backplane connectors and SAS MultiLink Drive cable connectors provide V₅ and V₁₂. SAS MultiLink Drive plug connectors receive V₅ and V₁₂.

^f Behind a SAS MultiLink Drive plug connector, P1 and P2 are only connected to each other.

^g SAS devices (see SPL-5) with SAS Drive plug connectors (see 5.4.3.3.1.1) compliant with SAS-1.1, SAS-2, or SAS-2.1 connected P1, P2, and P3 together.

^h SAS Drive backplane connectors (see 5.4.3.3.1.3) and SAS Drive cable connectors (see 5.4.3.3.1.2) compliant with SAS-1.1, SAS-2, or SAS-2.1 may provide V_{3.3} to P1, P2, and P3.

ⁱ Electrical characteristics and functions behind SAS Drive backplane connectors, SAS Drive cable connectors, SAS MultiLink Drive backplane connectors, and SAS MultiLink Drive cable connectors are beyond the scope of this specification.

^j P3 is not connected behind a SAS Drive plug connector when the POWER DISABLE signal is unsupported. Electrical characteristics for the POWER DISABLE signal are defined in 5.10.

^k Behind a SAS MultiLink Drive plug connector, the precharge pin and each corresponding voltage pin shall be connected together on the SAS target device (e.g., the V₅ precharge pin P7 is connected to the two V₅ pins P8 and P9).

^l Electrical characteristics for READY LED are defined in 5.9 and signal behavior is defined in SPL-5. SATA devices use P11 for activity indication and staggered spin-up disable and have different electrical characteristics (see SATA).

Table 7 — SAS MultiLink connector pin assignments (part 3 of 3)

Segment	Pin ^a	SAS MultiLink Drive backplane connector ^a	SAS MultiLink Drive plug and SAS MultiLink Drive cable connector ^a
Power segment ^e	P1	Vendor specific ^{h i}	See ^{f g h i}
	P2	Vendor specific ^{h i}	See ^{f g h i}
	P3	Vendor specific or POWER DISABLE ^{h i j}	POWER DISABLE ^{g h i j}
	P4	GROUND	
	P5	GROUND	
	P6	GROUND	
	P7	V ₅ , precharge ^k	
	P8	V ₅ ^k	
	P9	V ₅ ^k	
	P10	GROUND	
	P11	READY LED ^l	
	P12	GROUND	
	P13	V ₁₂ , precharge ^k	
	P14	V ₁₂ ^k	
	P15	V ₁₂ ^k	
<div><div><div><div>^a</div><div>Devices supporting other interfaces that intermate with SAS devices, backplanes, or cables have different electrical characteristics and functions. See SFF-9639 for a list of interface references and their respective pin assignments.</div></div><div><div>^b</div><div>S8 through S28 are not connected on single-port implementations.</div></div><div><div>^c</div><div>S16 through S28 are not connected on dual-port implementations.</div></div><div><div>^d</div><div>S23 through S28 are not connected on triple-port implementations.</div></div><div><div>^e</div><div>SAS MultiLink Drive backplane connectors and SAS MultiLink Drive cable connectors provide V₅ and V₁₂. SAS MultiLink Drive plug connectors receive V₅ and V₁₂.</div></div><div><div>^f</div><div>Behind a SAS MultiLink Drive plug connector, P1 and P2 are only connected to each other.</div></div><div><div>^g</div><div>SAS devices (see SPL-5) with SAS Drive plug connectors (see 5.4.3.3.1.1) compliant with SAS-1.1, SAS-2, or SAS-2.1 connected P1, P2, and P3 together.</div></div><div><div>^h</div><div>SAS Drive backplane connectors (see 5.4.3.3.1.3) and SAS Drive cable connectors (see 5.4.3.3.1.2) compliant with SAS-1.1, SAS-2, or SAS-2.1 may provide V_{3,3} to P1, P2, and P3.</div></div><div><div>ⁱ</div><div>Electrical characteristics and functions behind SAS Drive backplane connectors, SAS Drive cable connectors, SAS MultiLink Drive backplane connectors, and SAS MultiLink Drive cable connectors are beyond the scope of this specification.</div></div><div><div>^j</div><div>P3 is not connected behind a SAS Drive plug connector when the POWER DISABLE signal is unsupported. Electrical characteristics for the POWER DISABLE signal are defined in 5.10.</div></div><div><div>^k</div><div>Behind a SAS MultiLink Drive plug connector, the precharge pin and each corresponding voltage pin shall be connected together on the SAS target device (e.g., the V₅, precharge pin P7 is connected to the two V₅ pins P8 and P9).</div></div><div><div>^l</div><div>Electrical characteristics for READY LED are defined in 5.9 and signal behavior is defined in SPL-5. SATA devices use P11 for activity indication and staggered spin-up disable and have different electrical characteristics (see SATA).</div></div></div></div>			

5.4.3.3.1.9 Micro SAS plug connector

The Micro SAS plug connector mechanical interface is defined in SFF-8486. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J. The Micro SAS plug mates with the Micro SAS Receptacle (see 5.4.3.3.1.10), but not the Micro SATA receptacle (see SATA).

See SFF-8147 for the Micro SAS plug connector locations on common form factors. Figure 32 shows the Micro SAS plug connector.

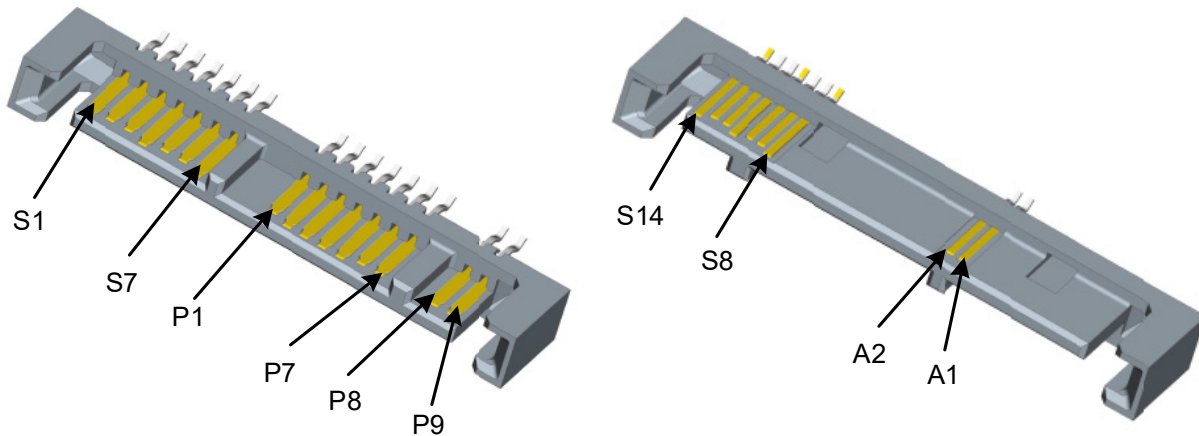


Figure 32 — Micro SAS plug connector

5.4.3.3.1.10 Micro SAS receptacle connector

The Micro SAS receptacle connector mechanical interface is defined in SFF-8486. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J. The Micro SAS receptacle mates with the Micro SAS plug connector (see 5.4.3.3.1.9) or the Micro SATA device plug (see SATA).

Figure 33 shows the Micro SAS receptacle connector.

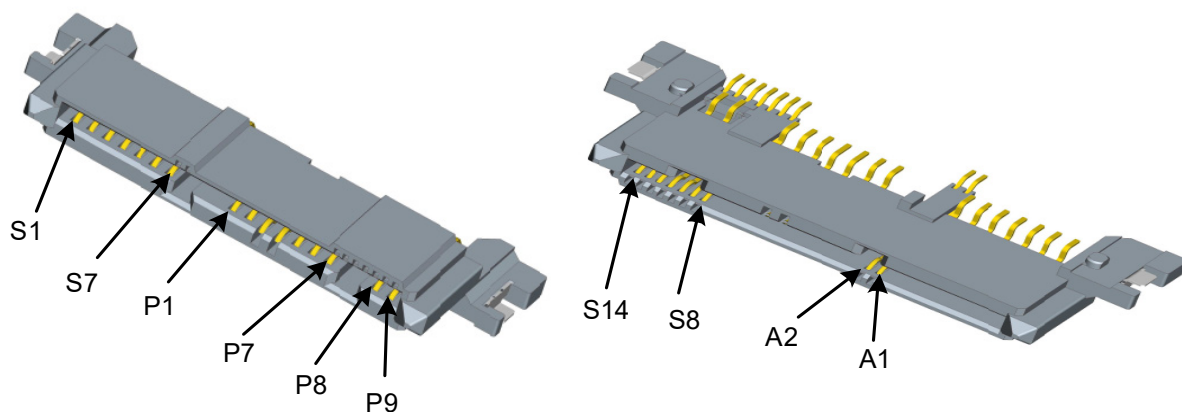


Figure 33 — Micro SAS receptacle connector

5.4.3.3.1.11 Micro SAS connector pin assignments

Table 8 defines the SAS target device pin assignments for the Micro SAS plug connector (see 5.4.3.3.1.9) and the Micro SAS receptacle connector (see 5.4.3.3.1.10). TP+, TP-, RP+, and RP- are used by the primary physical link. TS+, TS-, RS+, and RS- are used by the secondary physical link, if any.

Micro SAS plug connector pin assignments, except for the addition of the secondary physical link when present, are in the same locations as they are in a Micro SATA device plug connector (see SATA).

Table 8 — Micro SAS connector pin assignments

Segment	Pin	Micro SAS receptacle	Micro SAS plug	Mating level ^a
Primary signal segment	S1	SIGNAL GROUND		Second
	S2	TP+	RP+	Third
	S3	TP-	RP-	Third
	S4	SIGNAL GROUND		Second
	S5	RP-	TP-	Third
	S6	RP+	TP+	Third
	S7	SIGNAL GROUND		Second
Secondary signal segment ^b	S8	SIGNAL GROUND		Second
	S9	TS+	RS+	Third
	S10	TS-	RS-	Third
	S11	SIGNAL GROUND		Second
	S12	RS-	TS-	Third
	S13	RS+	TS+	Third
	S14	SIGNAL GROUND		Second
Power segment ^c	P1	$V_{3.3}$ ^d		Third
	P2	$V_{3.3}$, precharge ^d		Second
	P3	GROUND		First
	P4	GROUND		First
	P5	V_5 , precharge ^d		Second
	P6	V_5 ^d		Third
	P7	Reserved		Third
	P8	Not connected	Manufacturing diagnostic	Third
	P9	Not connected	Manufacturing diagnostic	Third
Auxiliary contacts	A1	Vender specific		Third
	A2	Vender specific		Third

^a The mating level assumes zero angular offset between connectors and indicates the physical dimension of the contact (see SFF-8486 and SATA).

^b S8 through S14 are not connected on single-port implementations.

^c The Micro SAS receptacle connector (see 5.4.3.3.1.10) provides $V_{3.3}$ and V_5 . The Micro SATA power receptacle connector (see SATA) provides $V_{3.3}$ and optionally V_5 . The Micro SAS plug connector (see 5.4.3.3.1.9) receives $V_{3.3}$ and V_5 .

^d Behind a Micro SAS plug connector (see 5.4.3.3.1.9), the precharge pin and each corresponding voltage pin shall be connected together on the SAS target device (e.g., the $V_{3.3}$, precharge pin P2 is connected to the $V_{3.3}$ pin P1).

5.4.3.3.2 Mini SAS HD internal connectors

5.4.3.3.2.1 Mini SAS HD 4i cable plug connector

The Mini SAS HD 4i cable plug connector mechanical interface is the four lane cable (free) connector defined in SFF-8643. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 34 shows the Mini SAS HD 4i cable plug connector.

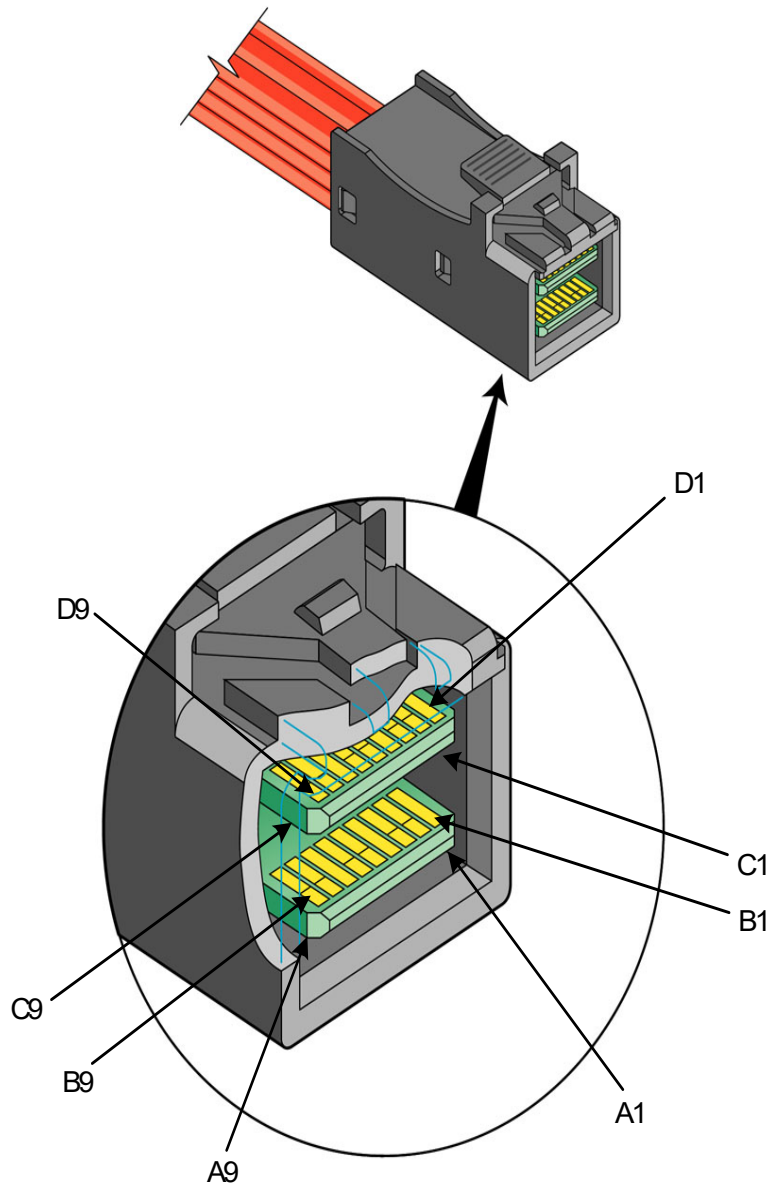


Figure 34 — Mini SAS HD 4i cable plug connector

Table 9 and table 10 define the pin assignments for the Mini SAS HD 4i cable plug connector.

5.4.3.3.2 Mini SAS HD 8i cable plug connector

The Mini SAS HD 8i cable plug connector mechanical interface is the dual four lane cable plug (free) connector defined in SFF-8643. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 35 shows the Mini SAS HD 8i cable plug connector. This connector is a modular version of repeating Mini SAS HD 4i cable plug connectors (see 5.4.3.3.2.1). Module labeling is shown in figure 35. See figure 34 for pin designations.

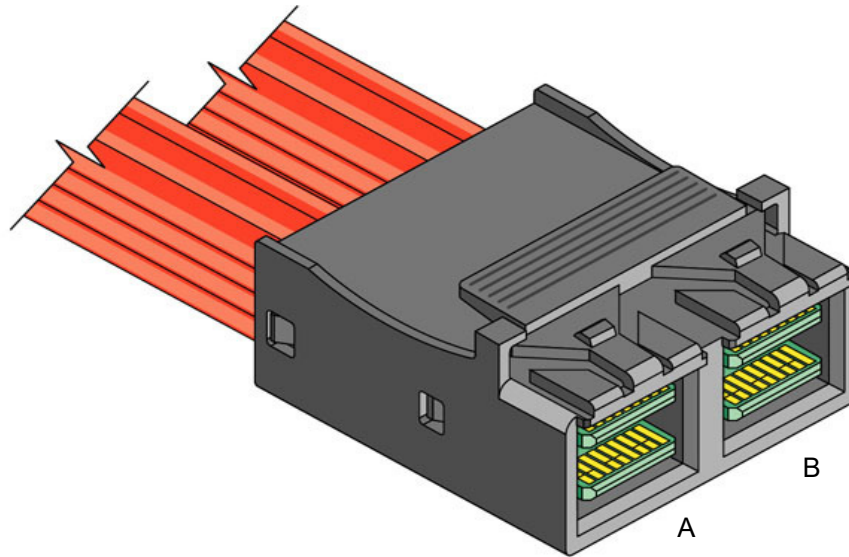


Figure 35 — Mini SAS HD 8i cable plug connector

Table 9 and table 10 define the pin assignments for the Mini SAS HD 4i cable plug connector (see 5.4.3.3.2.1). The pin assignments are repeated for each module of the Mini SAS 8i cable plug connector.

5.4.3.3.2.3 Mini SAS HD 4i receptacle connector

The Mini SAS HD 4i receptacle connector is the four lane receptacle (fixed) connector mechanical interface defined in SFF-8643. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 36 shows the Mini SAS HD 4i receptacle connector.

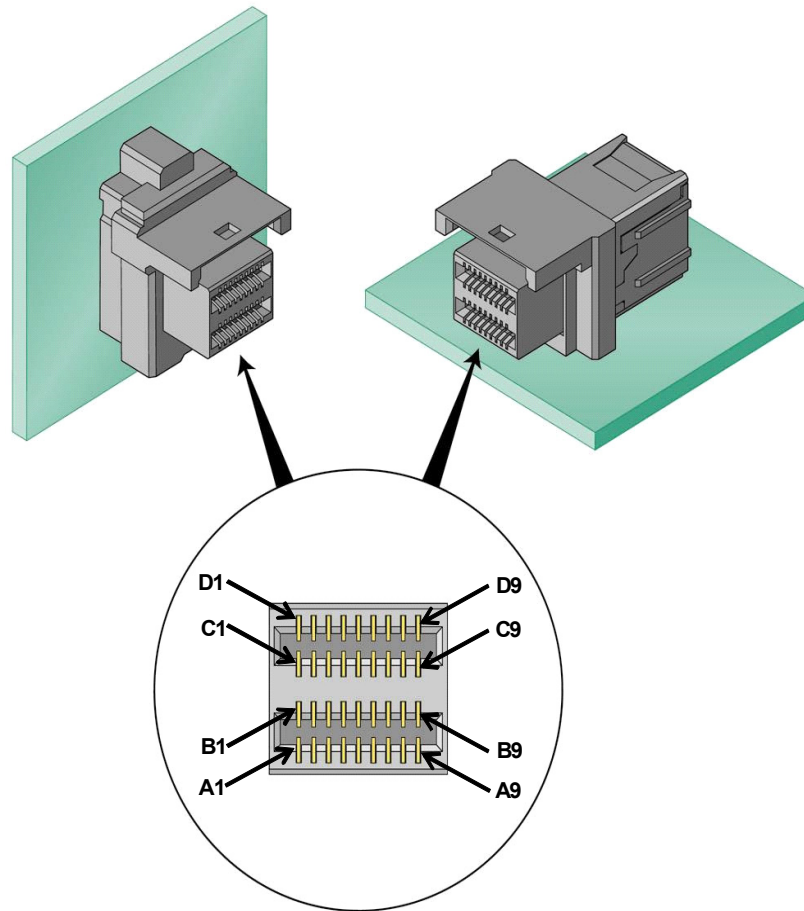


Figure 36 — Mini SAS HD 4i receptacle connector

Table 9 and table 10 define the pin assignments for the Mini SAS HD 4i receptacle connector.

5.4.3.3.2.4 Mini SAS HD 8i receptacle connector

The Mini SAS HD 8i receptacle connector is a dual four lane receptacle (fixed) connector mechanical interface defined in SFF-8643. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 37 shows the Mini SAS HD 8i receptacle connector. This connector is a modular version of the Mini SAS HD 4i receptacle connector (see 5.4.3.3.2.3). Module labeling is shown in figure 37. See figure 36 for pin designations.

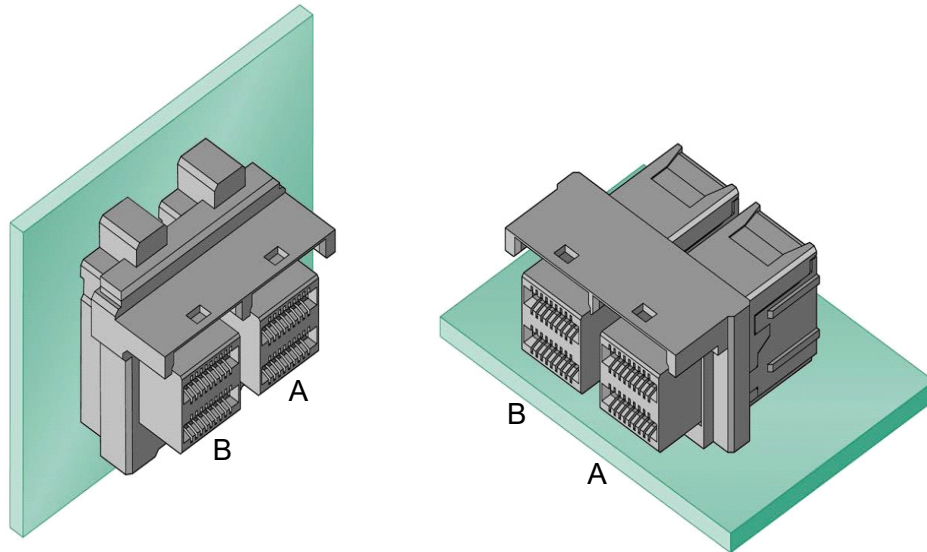


Figure 37 — Mini SAS HD 8i receptacle connector

Table 9 and table 10 define the pin assignments for the Mini SAS HD 8i receptacle connector. The connector is a modular design of repeating Mini SAS HD 4i receptacles (see 5.4.3.3.2.3). This connector accepts one Mini SAS HD 8i cable plug connector (see 5.4.3.3.2.2) or two Mini SAS HD 4i cable plug connectors (see 5.4.3.3.2.1).

5.4.3.3.2.5 Mini SAS HD 16i receptacle connector

The Mini SAS HD 16i receptacle connector is a quad four lane receptacle (fixed) connector mechanical interface defined in SFF-8643. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 38 shows the Mini SAS HD 16i receptacle connector. This connector is a modular version of the Mini SAS HD 4i receptacle connector (see 5.4.3.3.2.3). Module labeling is shown in figure 38. See figure 36 for pin designations.

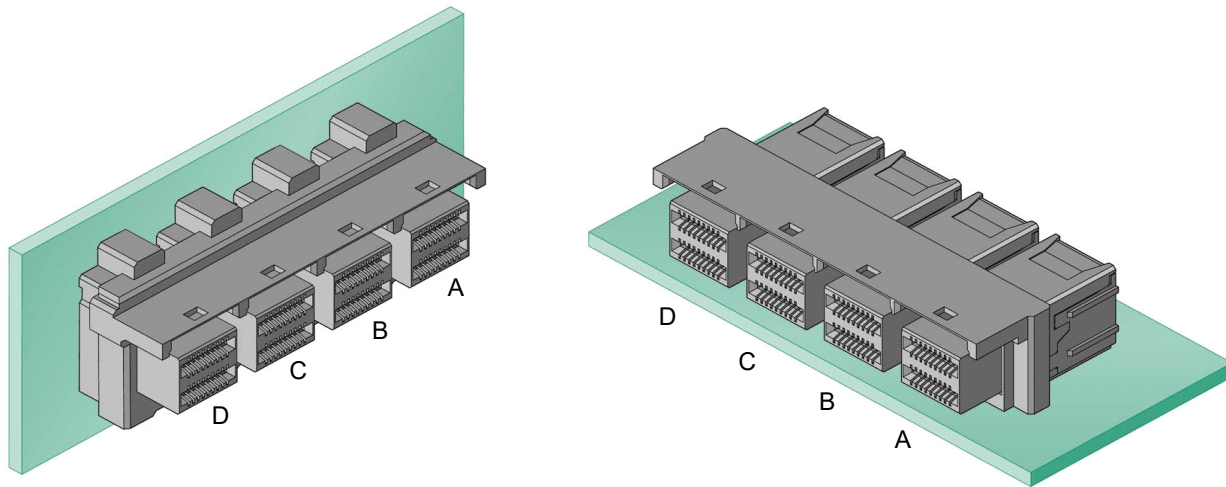


Figure 38 — Mini SAS HD 16i receptacle connector

Table 9 and table 10 define the pin assignments for the Mini SAS HD 16i receptacle connector. The connector is a modular design of repeating Mini SAS HD 4i receptacles (see 5.4.3.3.2.3). The Mini SAS HD 16i receptacle connector accepts:

- a) one or two Mini SAS HD 8i cable plug connectors (see 5.4.3.3.2.2);
- b) one, two, three, or four Mini SAS HD 4i cable plug connectors (see 5.4.3.3.2.1); or
- c) a combination of one Mini SAS HD 8i cable plug connector (see 5.4.3.3.2.2) and one or two Mini SAS HD 4i cable plug connectors (see 5.4.3.3.2.1).

A Mini SAS HD 4i cable plug connector (see 5.4.3.3.2.1) may be plugged into module A, module B, module C, or module D. A Mini SAS HD 8i cable plug connector (see 5.4.3.3.2.2) may be plugged into module A and module B, module B and module C, or module C and module D.

5.4.3.3.2.6 Mini SAS HD 4i connector pin assignments

Table 9 defines the pin assignments for Mini SAS HD 4i cable plug connectors (see 5.4.3.3.2.1) and Mini SAS HD 4i receptacle connectors (see 5.4.3.3.2.3) for controller applications using one, two, three, or four of the physical links.

Table 9 — Controller Mini SAS HD 4i connector pin assignments and physical link usage

Signal	Pin usage based on number of physical links supported by the cable assembly				Mating level ^a
	One	Two	Three	Four	
RX 0+	B4	B4	B4	B4	Third
RX 0-	B5	B5	B5	B5	
RX 1+	N/C	A4	A4	A4	
RX 1-	N/C	A5	A5	A5	
SIDEBAND 7	A1	A1	A1	A1	Second
SIDEBAND 3	B1	B1	B1	B1	
SIDEBAND 4	C1	C1	C1	C1	
SIDEBAND 5	D1	D1	D1	D1	
RX 2+	N/C	N/C	B7	B7	Third
RX 2-	N/C	N/C	B8	B8	
RX 3+	N/C	N/C	N/C	A7	
RX 3-	N/C	N/C	N/C	A8	
TX 0+	D4	D4	D4	D4	Third
TX 0-	D5	D5	D5	D5	
TX 1+	N/C	C4	C4	C4	
TX 1-	N/C	C5	C5	C5	
SIDEBAND 0	A2	A2	A2	A2	Second
SIDEBAND 1	B2	B2	B2	B2	
SIDEBAND 2	C2	C2	C2	C2	
SIDEBAND 6	D2	D2	D2	D2	
TX 2+	N/C	N/C	D7	D7	Third
TX 2-	N/C	N/C	D8	D8	
TX 3+	N/C	N/C	N/C	C7	
TX 3-	N/C	N/C	N/C	C8	
SIGNAL GROUND	A3, A6, A9, B3, B6, B9, C3, C6, C9, D3, D6, D9				First
^a The mating level indicates the physical dimension of the contact (see SFF-8643).					

The use of the sideband signals by controller applications is vendor specific. One implementation of the sideband signals by a controller application is an SGPIO initiator interface (see SFF-8485). Other implementations shall be compatible with the signal levels defined in SFF-8485.

Table 10 defines the pin assignments for Mini SAS HD 4i cable plug connectors (see 5.4.3.3.2.1) and Mini SAS HD 4i receptacle connectors (see 5.4.3.3.2.3) for backplane applications using one, two, three, or four of the physical links.

Table 10 — Backplane Mini SAS HD 4i connector pin assignments and physical link usage

Signal	Pin usage based on number of physical links supported by the cable assembly				Mating level ^a
	One	Two	Three	Four	
RX 0+	B4	B4	B4	B4	Third
RX 0-	B5	B5	B5	B5	
RX 1+	N/C	A4	A4	A4	
RX 1-	N/C	A5	A5	A5	
SIDEBAND 0	A1	A1	A1	A1	Second
SIDEBAND 1	B1	B1	B1	B1	
SIDEBAND 2	C1	C1	C1	C1	
SIDEBAND 6	D1	D1	D1	D1	
RX 2+	N/C	N/C	B7	B7	Third
RX 2-	N/C	N/C	B8	B8	
RX 3+	N/C	N/C	N/C	A7	
RX 3-	N/C	N/C	N/C	A8	
TX 0+	D4	D4	D4	D4	Third
TX 0-	D5	D5	D5	D5	
TX 1+	N/C	C4	C4	C4	
TX 1-	N/C	C5	C5	C5	
SIDEBAND 7	A2	A2	A2	A2	Second
SIDEBAND 3	B2	B2	B2	B2	
SIDEBAND 4	C2	C2	C2	C2	
SIDEBAND 5	D2	D2	D2	D2	
TX 2+	N/C	N/C	D7	D7	Third
TX 2-	N/C	N/C	D8	D8	
TX 3+	N/C	N/C	N/C	C7	
TX 3-	N/C	N/C	N/C	C8	
SIGNAL GROUND	A3, A6, A9, B3, B6, B9, C3, C6, C9, D3, D6, D9				First
^a The mating level indicates the physical dimension of the contact (see SFF-8643).					

The use of the sideband signals by backplane applications is vendor specific. One implementation of the sideband signals by a backplane application is an SGPIO target interface (see SFF-8485). Other implementations shall be compatible with the signal levels defined in SFF-8485.

5.4.3.3.3 SlimSAS internal connectors

5.4.3.3.3.1 SlimSAS 4i cable plug connector

The SlimSAS 4i cable plug connector is the four lane cable (free) connector mechanical interface defined in SFF-8654. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 39 shows the SlimSAS 4i cable plug connector.

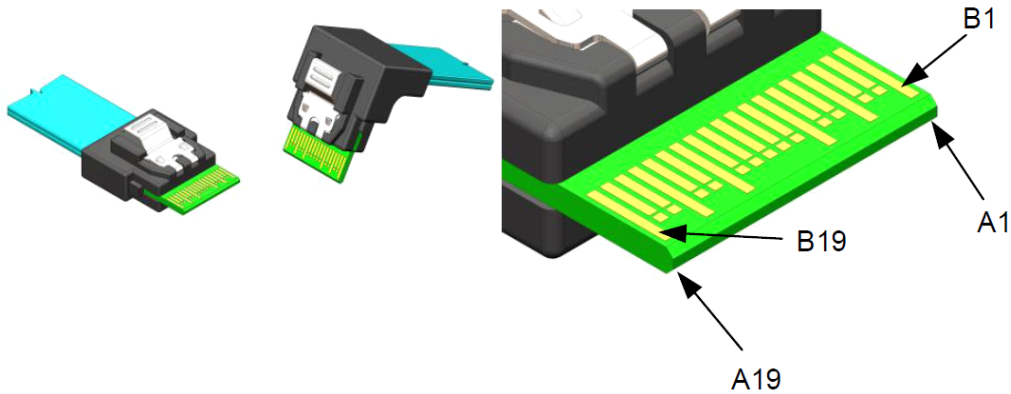


Figure 39 — SlimSAS 4i cable plug connector

Table 11 and table 12 define the pin assignments for the SlimSAS 4i cable plug connector. This connector plugs into the SlimSAS 4i receptacle connector (see 5.4.3.3.3.3).

5.4.3.3.3.2 SlimSAS 8i cable plug connector

The SlimSAS 8i cable plug connector is the dual four lane cable plug (free) connector mechanical interface defined in SFF-8654. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 40 shows the SlimSAS 8i cable plug connector.

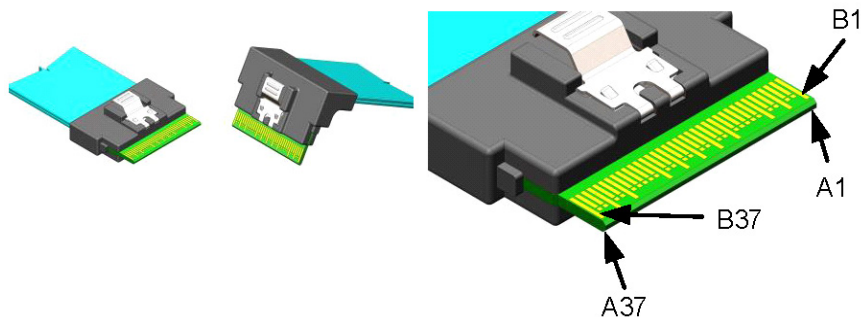


Figure 40 — SlimSAS 8i cable plug connector

Table 13 and table 14 define the pin assignments for the SlimSAS 8i cable plug connector. This connector plugs into the SlimSAS 8i receptacle connector (see 5.4.3.3.3.4).

5.4.3.3.3 SlimSAS 4i receptacle connector

The SlimSAS 4i receptacle connector is the four lane receptacle (fixed) connector mechanical interface defined in SFF-8654. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 41 shows the SlimSAS 4i receptacle connector.

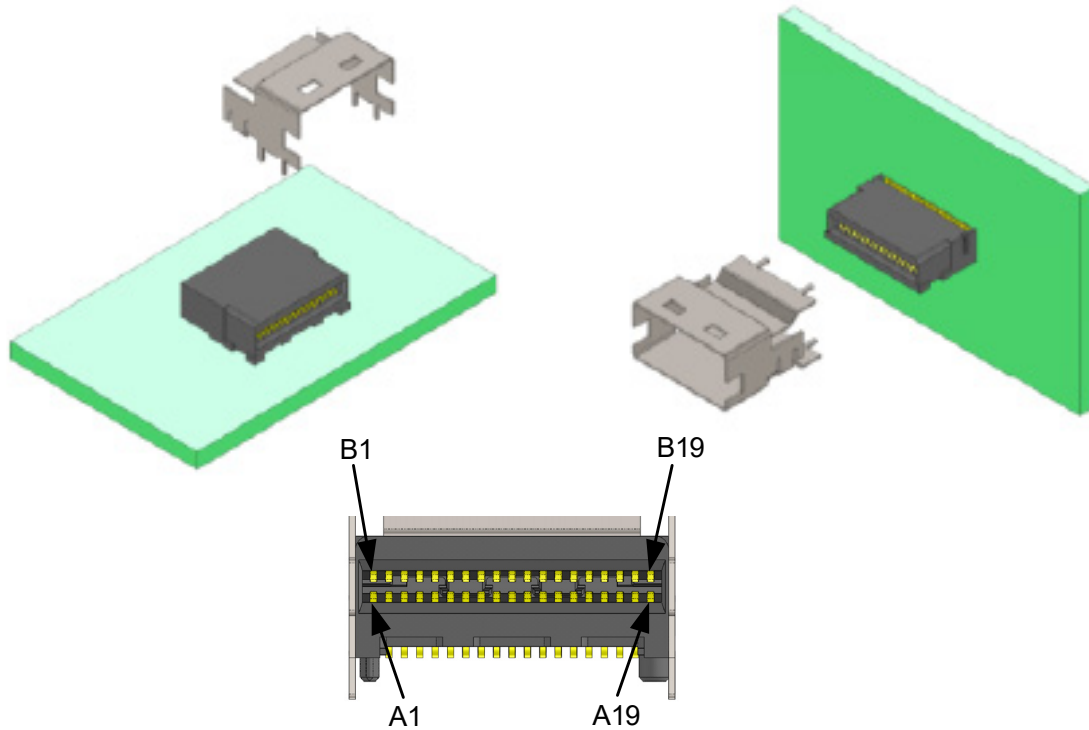


Figure 41 — SlimSAS 4i receptacle connector

Table 11 and table 12 define the pin assignments for the SlimSAS 4i receptacle connector. This connector accepts the SlimSAS 4i cable plug connector (see 5.4.3.3.3.1).

5.4.3.3.4 SlimSAS 8i receptacle connector

The SlimSAS 8i receptacle connector is the four lane receptacle (fixed) connector mechanical interface defined in SFF-8654. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 42 shows the SlimSAS 8i receptacle connector.

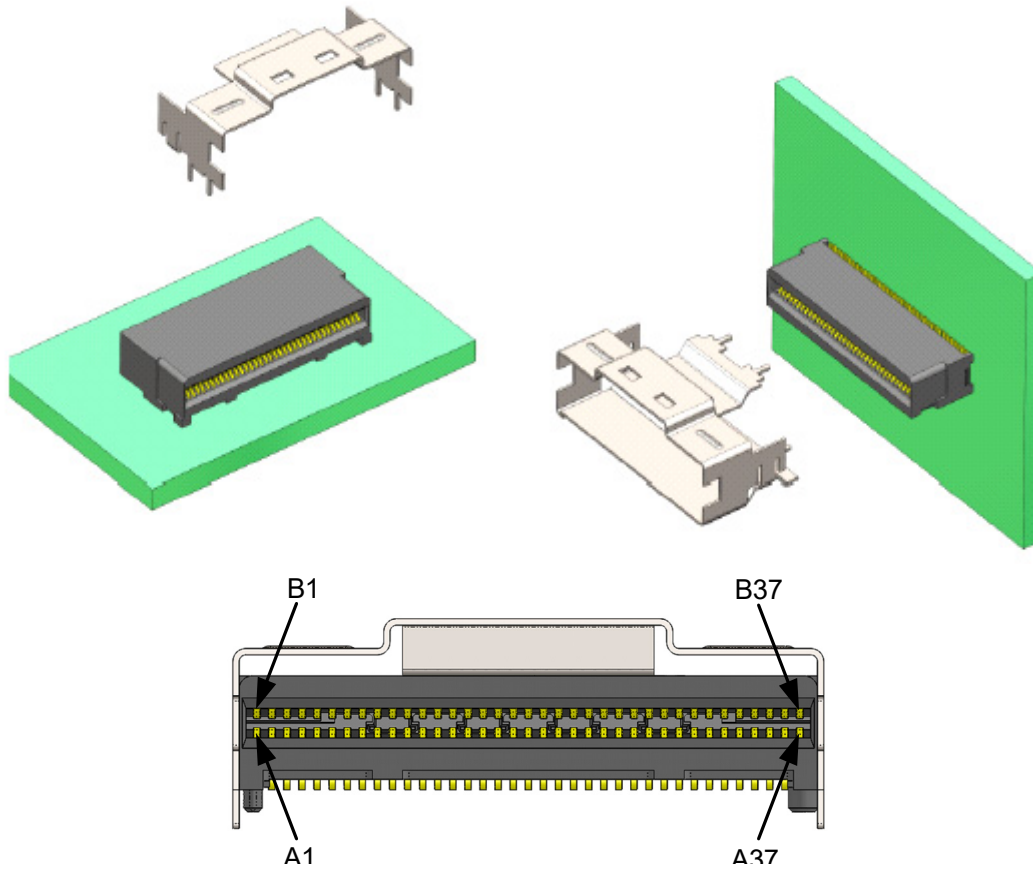


Figure 42 — SlimSAS 8i receptacle connector

Table 13 and table 14 define the pin assignments for the SlimSAS 8i receptacle connector. This connector accepts the SlimSAS 8i cable plug connector (see 5.4.3.3.2).

5.4.3.3.5 SlimSAS connector pin assignments

Table 11 defines the pin assignments for SlimSAS 4i cable plug connectors (see 5.4.3.3.3.1) and SlimSAS 4i receptacle connectors (see 5.4.3.3.3.3) for controller applications using one, two, three, or four of the physical links.

Table 11 — Controller SlimSAS 4i connector pin assignments and physical link usage

Signal	Pin usage based on number of physical links supported by the cable assembly				Mating level ^a
	One	Two	Three	Four	
RX 0+	A2	A2	A2	A2	Third
RX 0-	A3	A3	A3	A3	
RX 1+	N/C	A5	A5	A5	
RX 1-	N/C	A6	A6	A6	
SIDEBAND 7	A8	A8	A8	A8	Third
SIDEBAND 4	A9	A9	A9	A9	
SIDEBAND 3	A10	A10	A10	A10	
SIDEBAND +	A11	A11	A11	A11	
SIDEBAND -	A12	A12	A12	A12	Third
RX 2+	N/C	N/C	A14	A14	
RX 2-	N/C	N/C	A15	A15	
RX 3+	N/C	N/C	N/C	A17	
RX 3-	N/C	N/C	N/C	A18	Third
TX 0+	B2	B2	B2	B2	
TX 0-	B3	B3	B3	B3	
TX 1+	N/C	B5	B5	B5	
TX 1-	N/C	B6	B6	B6	Third
SIDEBAND 0	B8	B8	B8	B8	
SIDEBAND 1	B9	B9	B9	B9	
SIDEBAND 2	B10	B10	B10	B10	
SIDEBAND 5	B11	B11	B11	B11	Third
SIDEBAND 6	B12	B12	B12	B12	
TX 2+	N/C	N/C	B14	B14	
TX 2-	N/C	N/C	B15	B15	
TX 3+	N/C	N/C	N/C	B17	Third
TX 3-	N/C	N/C	N/C	B18	
SIGNAL GROUND	A1, A4, A7, A13, A16, A19, B1, B4, B7, B13, B16, B19				First
^a The mating level indicates the physical dimension of the contact (see SFF-8654).					

The use of the sideband signals is vendor specific.

Table 12 defines the pin assignments for SlimSAS 4i cable plug connectors (see 5.4.3.3.3.1) and SlimSAS 4i receptacle connectors (see 5.4.3.3.3.3) for backplane applications using one, two, three, or four of the physical links.

Table 12 — Backplane SlimSAS 4i connector pin assignments and physical link usage

Signal	Pin usage based on number of physical links supported by the cable assembly				Mating level ^a
	One	Two	Three	Four	
RX 0+	A2	A2	A2	A2	Third
RX 0-	A3	A3	A3	A3	
RX 1+	N/C	A5	A5	A5	
RX 1-	N/C	A6	A6	A6	
SIDEBAND 0	A8	A8	A8	A8	Third
SIDEBAND 1	A9	A9	A9	A9	
SIDEBAND 2	A10	A10	A10	A10	
SIDEBAND 5	A11	A11	A11	A11	
SIDEBAND 6	A12	A12	A12	A12	
RX 2+	N/C	N/C	A14	A14	Third
RX 2-	N/C	N/C	A15	A15	
RX 3+	N/C	N/C	N/C	A17	
RX 3-	N/C	N/C	N/C	A18	
TX 0+	B2	B2	B2	B2	Third
TX 0-	B3	B3	B3	B3	
TX 1+	N/C	B5	B5	B5	
TX 1-	N/C	B6	B6	B6	
SIDEBAND 7	B8	B8	B8	B8	Third
SIDEBAND 4	B9	B9	B9	B9	
SIDEBAND 3	B10	B10	B10	B10	
SIDEBAND +	B11	B11	B11	B11	
SIDEBAND -	B12	B12	B12	B12	
TX 2+	N/C	N/C	B14	B14	Third
TX 2-	N/C	N/C	B15	B15	
TX 3+	N/C	N/C	N/C	B17	
TX 3-	N/C	N/C	N/C	B18	
SIGNAL GROUND	A1, A4, A7, A13, A16, A19, B1, B4, B7, B13, B16, B19				First
^a The mating level indicates the physical dimension of the contact (see SFF-8654).					

The use of the sideband signals is vendor specific.

Table 13 defines the pin assignments for SlimSAS 8i cable plug connectors (see 5.4.3.3.2) and SlimSAS 8i receptacle connectors (see 5.4.3.3.4) for controller applications using one, two, three, four, five, six, seven, or eight of the physical links.

Table 13 — Controller SlimSAS 8i connector pin assignments and physical link usage (part 1 of 2)

Signal	Pin usage based on number of physical links supported by the cable assembly								Mating level ^a
	One	Two	Three	Four	Five	Six	Seven	Eight	
RX 0+	A2	A2	A2	A2	A2	A2	A2	A2	Third
RX 0-	A3	A3	A3	A3	A3	A3	A3	A3	
RX 1+	N/C	A5	A5	A5	A5	A5	A5	A5	
RX 1-	N/C	A6	A6	A6	A6	A6	A6	A6	
SIDEBAND 7A	A8	A8	A8	A8	A8	A8	A8	A8	Third
SIDEBAND 4A	A9	A9	A9	A9	A9	A9	A9	A9	
SIDEBAND 3A	A10	A10	A10	A10	A10	A10	A10	A10	
SIDEBAND A+	A11	A11	A11	A11	A11	A11	A11	A11	
SIDEBAND A-	A12	A12	A12	A12	A12	A12	A12	A12	
RX 2+	N/C	N/C	A14	A14	A14	A14	A14	A14	Third
RX 2-	N/C	N/C	A15	A15	A15	A15	A15	A15	
RX 3+	N/C	N/C	N/C	A17	A17	A17	A17	A17	
RX 3-	N/C	N/C	N/C	A18	A18	A18	A18	A18	
RX 4+	N/C	N/C	N/C	N/C	A20	A20	A20	A20	Third
RX 4-	N/C	N/C	N/C	N/C	A21	A21	A21	A21	
RX 5+	N/C	N/C	N/C	N/C	N/C	A23	A23	A23	
RX 5-	N/C	N/C	N/C	N/C	N/C	A24	A24	A24	
SIDEBAND 7B	A26	A26	A26	A26	A26	A26	A26	A26	Third
SIDEBAND 4B	A27	A27	A27	A27	A27	A27	A27	A27	
SIDEBAND 3B	A28	A28	A28	A28	A28	A28	A28	A28	
SIDEBAND B+	A29	A29	A29	A29	A29	A29	A29	A29	
SIDEBAND B-	A30	A30	A30	A30	A30	A30	A30	A30	
RX 6+	N/C	N/C	N/C	N/C	N/C	N/C	A32	A32	Third
RX 6-	N/C	N/C	N/C	N/C	N/C	N/C	A33	A33	
RX 7+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	A35	
RX 7-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	A36	
TX 0+	B2	B2	B2	B2	B2	B2	B2	B2	Third
TX 0-	B3	B3	B3	B3	B3	B3	B3	B3	
TX 1+	N/C	B5	B5	B5	B5	B5	B5	B5	
TX 1-	N/C	B6	B6	B6	B6	B6	B6	B6	
^a The mating level indicates the physical dimension of the contact (see SFF-8654).									

Table 13 — Controller SlimSAS 8i connector pin assignments and physical link usage (part 2 of 2)

Signal	Pin usage based on number of physical links supported by the cable assembly								Mating level ^a
	One	Two	Three	Four	Five	Six	Seven	Eight	
SIDEBAND 0A	B8	B8	B8	B8	B8	B8	B8	B8	Third
SIDEBAND 1A	B9	B9	B9	B9	B9	B9	B9	B9	
SIDEBAND 2A	B10	B10	B10	B10	B10	B10	B10	B10	
SIDEBAND 5A	B11	B11	B11	B11	B11	B11	B11	B11	
SIDEBAND 6A	B12	B12	B12	B12	B12	B12	B12	B12	
TX 2+	N/C	N/C	B14	B14	B14	B14	B14	B14	Third
TX 2-	N/C	N/C	B15	B15	B15	B15	B15	B15	
TX 3+	N/C	N/C	N/C	B17	B17	B17	B17	B17	
TX 3-	N/C	N/C	N/C	B18	B18	B18	B18	B18	
TX 4+	N/C	N/C	N/C	N/C	B20	B20	B20	B20	Third
TX 4-	N/C	N/C	N/C	N/C	B21	B21	B21	B21	
TX 5+	N/C	N/C	N/C	N/C	N/C	B23	B23	B23	
TX 5-	N/C	N/C	N/C	N/C	N/C	B24	B24	B24	
SIDEBAND 0B	B26	B26	B26	B26	B26	B26	B26	B26	Third
SIDEBAND 1B	B27	B27	B27	B27	B27	B27	B27	B27	
SIDEBAND 2B	B28	B28	B28	B28	B28	B28	B28	B28	
SIDEBAND 5B	B29	B29	B29	B29	B29	B29	B29	B29	
SIDEBAND 6B	B30	B30	B30	B30	B30	B30	B30	B30	
TX 6+	N/C	N/C	N/C	N/C	N/C	N/C	B32	B32	Third
TX 6-	N/C	N/C	N/C	N/C	N/C	N/C	B33	B33	
TX 7+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	B35	
TX 7-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	B36	
SIGNAL GROUND	A1, A4, A7, A13, A16, A19, A22, A25, A31, A34, A37, B1, B4, B7, B13, B16, B19, B22, B25, B31, B34, B37								First
^a The mating level indicates the physical dimension of the contact (see SFF-8654).									

The use of the sideband signals is vendor specific.

Table 14 defines the pin assignments for SlimSAS 8i cable plug connectors (see 5.4.3.3.3.2) and SlimSAS 8i receptacle connectors (see 5.4.3.3.3.4) for backplane applications using one, two, three, four, five, six, seven, or eight of the physical links.

Table 14 — Backplane SlimSAS 8i connector pin assignments and physical link usage (part 1 of 2)

Signal	Pin usage based on number of physical links supported by the cable assembly								Mating level ^a
	One	Two	Three	Four	Five	Six	Seven	Eight	
RX 0+	A2	A2	A2	A2	A2	A2	A2	A2	Third
RX 0-	A3	A3	A3	A3	A3	A3	A3	A3	
RX 1+	N/C	A5	A5	A5	A5	A5	A5	A5	
RX 1-	N/C	A6	A6	A6	A6	A6	A6	A6	
SIDEBAND 0A	A8	A8	A8	A8	A8	A8	A8	A8	Third
SIDEBAND 1A	A9	A9	A9	A9	A9	A9	A9	A9	
SIDEBAND 2A	A10	A10	A10	A10	A10	A10	A10	A10	
SIDEBAND 5A	A11	A11	A11	A11	A11	A11	A11	A11	
SIDEBAND 6A	A12	A12	A12	A12	A12	A12	A12	A12	
RX 2+	N/C	N/C	A14	A14	A14	A14	A14	A14	Third
RX 2-	N/C	N/C	A15	A15	A15	A15	A15	A15	
RX 3+	N/C	N/C	N/C	A17	A17	A17	A17	A17	
RX 3-	N/C	N/C	N/C	A18	A18	A18	A18	A18	
RX 4+	N/C	N/C	N/C	N/C	A20	A20	A20	A20	Third
RX 4-	N/C	N/C	N/C	N/C	A21	A21	A21	A21	
RX 5+	N/C	N/C	N/C	N/C	N/C	A23	A23	A23	
RX 5-	N/C	N/C	N/C	N/C	N/C	A24	A24	A24	
SIDEBAND 0B	A26	A26	A26	A26	A26	A26	A26	A26	Third
SIDEBAND 1B	A27	A27	A27	A27	A27	A27	A27	A27	
SIDEBAND 2B	A28	A28	A28	A28	A28	A28	A28	A28	
SIDEBAND 5B	A29	A29	A29	A29	A29	A29	A29	A29	
SIDEBAND 6B	A30	A30	A30	A30	A30	A30	A30	A30	
RX 6+	N/C	N/C	N/C	N/C	N/C	N/C	A32	A32	Third
RX 6-	N/C	N/C	N/C	N/C	N/C	N/C	A33	A33	
RX 7+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	A35	
RX 7-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	A36	
TX 0+	B2	B2	B2	B2	B2	B2	B2	B2	Third
TX 0-	B3	B3	B3	B3	B3	B3	B3	B3	
TX 1+	N/C	B5	B5	B5	B5	B5	B5	B5	
TX 1-	N/C	B6	B6	B6	B6	B6	B6	B6	
^a The mating level indicates the physical dimension of the contact (see SFF-8654).									

Table 14 — Backplane SlimSAS 8i connector pin assignments and physical link usage (part 2 of 2)

Signal	Pin usage based on number of physical links supported by the cable assembly								Mating level ^a
	One	Two	Three	Four	Five	Six	Seven	Eight	
SIDEBAND 7A	B8	B8	B8	B8	B8	B8	B8	B8	Third
SIDEBAND 4A	B9	B9	B9	B9	B9	B9	B9	B9	
SIDEBAND 3A	B10	B10	B10	B10	B10	B10	B10	B10	
SIDEBAND A+	B11	B11	B11	B11	B11	B11	B11	B11	
SIDEBAND A-	B12	B12	B12	B12	B12	B12	B12	B12	
TX 2+	N/C	N/C	B14	B14	B14	B14	B14	B14	Third
TX 2-	N/C	N/C	B15	B15	B15	B15	B15	B15	
TX 3+	N/C	N/C	N/C	B17	B17	B17	B17	B17	
TX 3-	N/C	N/C	N/C	B18	B18	B18	B18	B18	
TX 4+	N/C	N/C	N/C	N/C	B20	B20	B20	B20	Third
TX 4-	N/C	N/C	N/C	N/C	B21	B21	B21	B21	
TX 5+	N/C	N/C	N/C	N/C	N/C	B23	B23	B23	
TX 5-	N/C	N/C	N/C	N/C	N/C	B24	B24	B24	
SIDEBAND 7B	B26	B26	B26	B26	B26	B26	B26	B26	Third
SIDEBAND 4B	B27	B27	B27	B27	B27	B27	B27	B27	
SIDEBAND 3B	B28	B28	B28	B28	B28	B28	B28	B28	
SIDEBAND B+	B29	B29	B29	B29	B29	B29	B29	B29	
SIDEBAND B-	B30	B30	B30	B30	B30	B30	B30	B30	
TX 6+	N/C	N/C	N/C	N/C	N/C	N/C	B32	B32	Third
TX 6-	N/C	N/C	N/C	N/C	N/C	N/C	B33	B33	
TX 7+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	B35	
TX 7-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	B36	
SIGNAL GROUND	A1, A4, A7, A13, A16, A19, A22, A25, A31, A34, A37, B1, B4, B7, B13, B16, B19, B22, B25, B31, B34, B37								First
^a The mating level indicates the physical dimension of the contact (see SFF-8654).									

The use of the sideband signals is vendor specific.

5.4.3.3.4 SAS MiniLink internal connectors

5.4.3.3.4.1 SAS MiniLink 4i cable plug connector

The SAS MiniLink 4i cable plug connector is the four lane cable (free) connector mechanical interface defined in SFF-8611. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 43 shows the SAS MiniLink 4i cable plug connector.

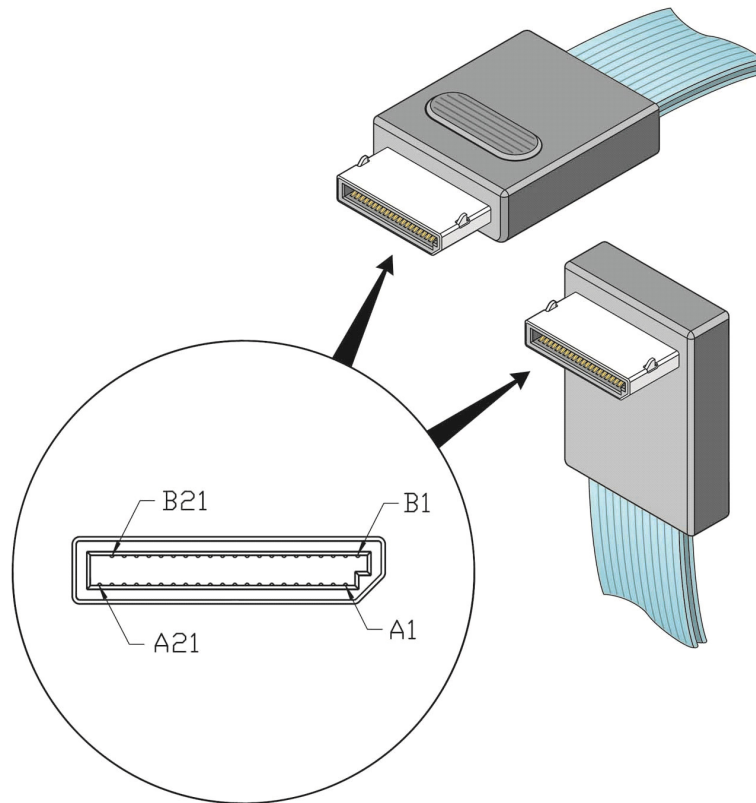


Figure 43 — SAS MiniLink 4i cable plug connector

Table 15 and table 16 define the pin assignments for the SAS MiniLink 4i cable plug connector. This connector plugs into the SAS MiniLink 4i receptacle connector (see 5.4.3.3.4.3).

5.4.3.3.4.2 SAS MiniLink 8i cable plug connector

The SAS MiniLink 8i cable plug connector is the dual four lane cable plug (free) connector mechanical interface defined in SFF-8611. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 44 shows the SAS MiniLink 8i cable plug connector.

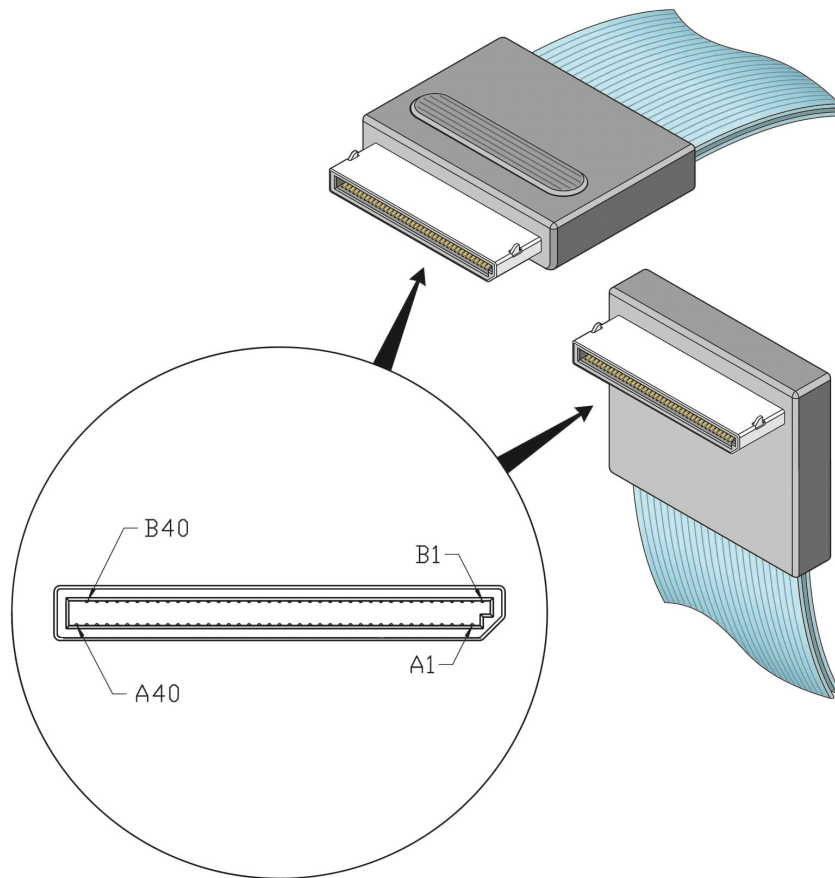


Figure 44 — SAS MiniLink 8i cable plug connector

Table 17 and table 18 define the pin assignments for the SAS MiniLink 8i cable plug connector. This connector plugs into the SAS MiniLink 8i receptacle connector (see 5.4.3.3.4.4).

5.4.3.3.4.3 SAS MiniLink 4i receptacle connector

The SAS MiniLink 4i receptacle connector is the four lane receptacle (fixed) connector mechanical interface defined in SFF-8612. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 45 shows the SAS MiniLink 4i receptacle connector.

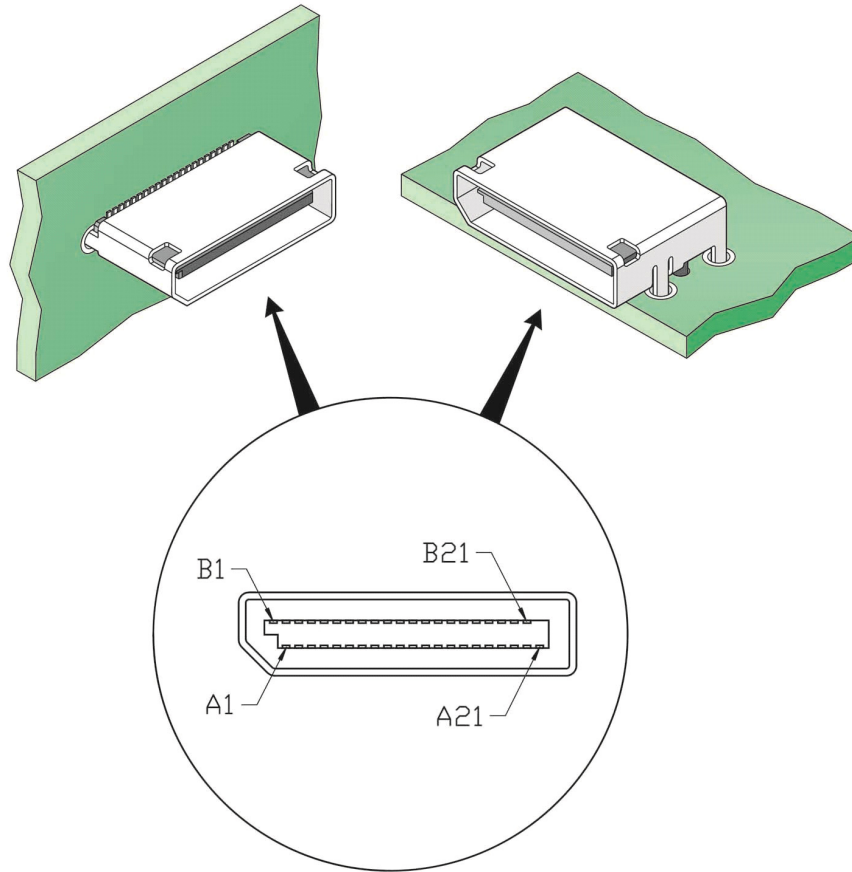


Figure 45 — SAS MiniLink 4i receptacle connector

Table 15 and table 16 define the pin assignments for the SAS MiniLink 4i receptacle connector. This connector accepts the SAS MiniLink 4i cable plug connector (see 5.4.3.3.4.1).

5.4.3.3.4.4 SAS MiniLink 8i receptacle connector

The SAS MiniLink 8i receptacle connector is the eight lane receptacle (fixed) connector mechanical interface defined in SFF-8612. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 46 shows the SAS MiniLink 8i receptacle connector.

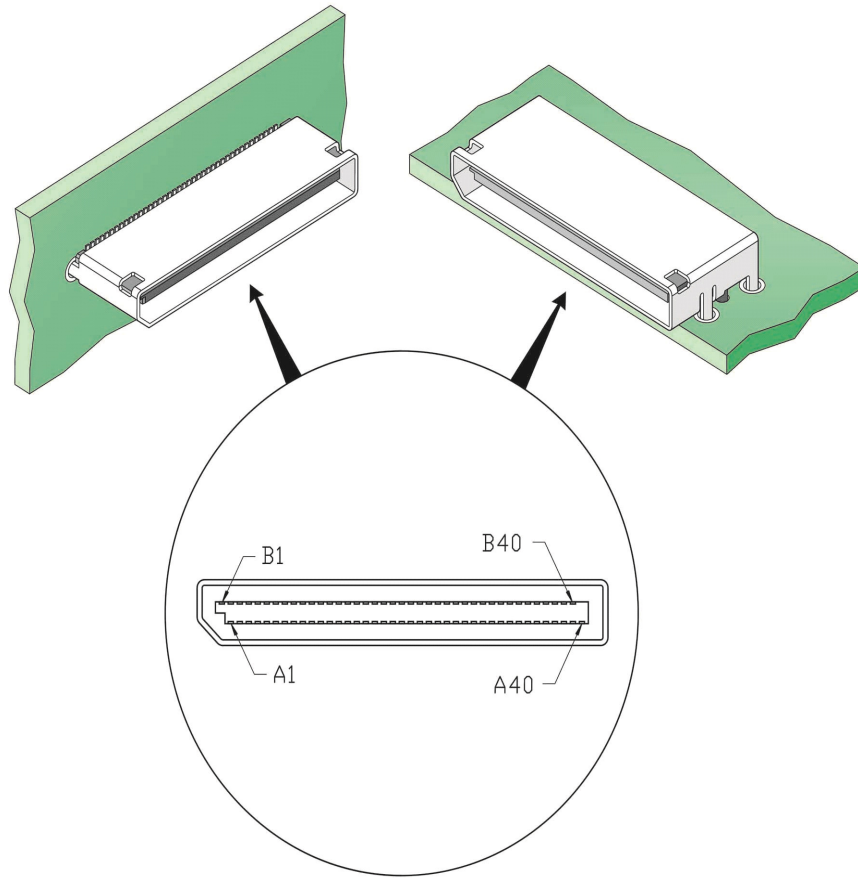


Figure 46 — SAS MiniLink 8i receptacle connector

Table 17 and table 18 define the pin assignments for the SAS MiniLink 8i receptacle connector. This connector accepts the SAS MiniLink 8i cable plug connector (see 5.4.3.3.4.2).

5.4.3.3.4.5 SAS MiniLink connector pin assignments

Table 15 defines the pin assignments for SAS MiniLink 4i cable plug connectors (see 5.4.3.3.4.1) and SAS MiniLink 4i receptacle connectors (see 5.4.3.3.4.3) for controller applications using one, two, three, or four of the physical links.

Table 15 — Controller SAS MiniLink 4i pin assignments and physical link usage

Signal	Pin usage based on number of physical links supported by the cable assembly				Mating level ^a
	One	Two	Three	Four	
RX 0+	A3	A3	A3	A3	Second
RX 0-	A4	A4	A4	A4	
RX 1+	N/C	A6	A6	A6	
RX 1-	N/C	A7	A7	A7	
SIDEBAND 7	A9	A9	A9	A9	Second
SIDEBAND 4	A10	A10	A10	A10	
SIDEBAND 3	A11	A11	A11	A11	First
SIDEBAND +	A12	A12	A12	A12	Second
SIDEBAND -	A13	A13	A13	A13	
RX 2+	N/C	N/C	A15	A15	Second
RX 2-	N/C	N/C	A16	A16	
RX 3+	N/C	N/C	N/C	A18	
RX 3-	N/C	N/C	N/C	A19	
TX 0+	B3	B3	B3	B3	Second
TX 0-	B4	B4	B4	B4	
TX 1+	N/C	B6	B6	B6	
TX 1-	N/C	B7	B7	B7	
SIDEBAND 0	B9	B9	B9	B9	Second
SIDEBAND 1	B10	B10	B10	B10	
SIDEBAND 2	B11	B11	B11	B11	First
SIDEBAND 5	B12	B12	B12	B12	Second
SIDEBAND 6	B13	B13	B13	B13	
TX 2+	N/C	N/C	B15	B15	Second
TX 2-	N/C	N/C	B16	B16	
TX 3+	N/C	N/C	N/C	B18	
TX 3-	N/C	N/C	N/C	B19	
SIGNAL GROUND	A2, A5, A8, A14, A17, A20, B2, B5, B8, B14, B17, B20				First
RESERVED	A1, A21, B1, B21				Second

^a The mating level indicates the physical dimension of the contact (see SFF-8611 and SFF-8612).

The use of the sideband signals is vendor specific.

Table 16 defines the pin assignments for SAS MiniLink 4i cable plug connectors (see 5.4.3.3.4.1) and SAS MiniLink 4i receptacle connectors (see 5.4.3.3.4.3) for backplane applications using one, two, three, or four of the physical links.

Table 16 — Backplane SAS MiniLink 4i pin assignments and physical link usage

Signal	Pin usage based on number of physical links supported by the cable assembly				Mating level ^a
	One	Two	Three	Four	
RX 0+	A3	A3	A3	A3	Second
RX 0-	A4	A4	A4	A4	
RX 1+	N/C	A6	A6	A6	
RX 1-	N/C	A7	A7	A7	
SIDEBAND 0	A9	A9	A9	A9	Second
SIDEBAND 1	A10	A10	A10	A10	
SIDEBAND 2	A11	A11	A11	A11	First
SIDEBAND 5	A12	A12	A12	A12	Second
SIDEBAND 6	A13	A13	A13	A13	
RX 2+	N/C	N/C	A15	A15	Second
RX 2-	N/C	N/C	A16	A16	
RX 3+	N/C	N/C	N/C	A18	
RX 3-	N/C	N/C	N/C	A19	
TX 0+	B3	B3	B3	B3	Second
TX 0-	B4	B4	B4	B4	
TX 1+	N/C	B6	B6	B6	
TX 1-	N/C	B7	B7	B7	
SIDEBAND 7	B9	B9	B9	B9	Second
SIDEBAND 4	B10	B10	B10	B10	
SIDEBAND 3	B11	B11	B11	B11	First
SIDEBAND +	B12	B12	B12	B12	Second
SIDEBAND -	B13	B13	B13	B13	
TX 2+	N/C	N/C	B15	B15	Second
TX 2-	N/C	N/C	B16	B16	
TX 3+	N/C	N/C	N/C	B18	
TX 3-	N/C	N/C	N/C	B19	
SIGNAL GROUND	A2, A5, A8, A14, A17, A20, B2, B5, B8, B14, B17, B20				First
RESERVED	A1, A21, B1, B21				Second
^a The mating level indicates the physical dimension of the contact (see SFF-8611 and SFF-8612).					

Table 17 defines the pin assignments for SAS MiniLink 8i cable plug connectors (see 5.4.3.3.4.2) and SAS MiniLink 8i receptacle connectors (see 5.4.3.3.4.4) for controller applications for using one, two, three, four, five, six, seven, or eight of the physical links.

Table 17 — Controller SAS MiniLink 8i connector pin assignments and physical link usage (part 1 of 2)

Signal	Pin usage based on number of physical links supported by the cable assembly								Mating level ^a
	One	Two	Three	Four	Five	Six	Seven	Eight	
RX 0+	A2	A2	A2	A2	A2	A2	A2	A2	Second
RX 0-	A3	A3	A3	A3	A3	A3	A3	A3	
RX 1+	N/C	A5	A5	A5	A5	A5	A5	A5	
RX 1-	N/C	A6	A6	A6	A6	A6	A6	A6	
SIDEBAND 7A	A8	A8	A8	A8	A8	A8	A8	A8	Second
SIDEBAND 4A	A9	A9	A9	A9	A9	A9	A9	A9	
SIDEBAND 3A	A10	A10	A10	A10	A10	A10	A10	A10	First
SIDEBAND A+	A11	A11	A11	A11	A11	A11	A11	A11	Second
SIDEBAND A-	A12	A12	A12	A12	A12	A12	A12	A12	
RX 2+	N/C	N/C	A14	A14	A14	A14	A14	A14	Second
RX 2-	N/C	N/C	A15	A15	A15	A15	A15	A15	
RX 3+	N/C	N/C	N/C	A17	A17	A17	A17	A17	
RX 3-	N/C	N/C	N/C	A18	A18	A18	A18	A18	
RX 4+	N/C	N/C	N/C	N/C	A23	A23	A23	A23	Second
RX 4-	N/C	N/C	N/C	N/C	A24	A24	A24	A24	
RX 5+	N/C	N/C	N/C	N/C	N/C	A26	A26	A26	
RX 5-	N/C	N/C	N/C	N/C	N/C	A27	A27	A27	
SIDEBAND 7B	A29	A29	A29	A29	A29	A29	A29	A29	Second
SIDEBAND 4B	A30	A30	A30	A30	A30	A30	A30	A30	
SIDEBAND 3B	A31	A31	A31	A31	A31	A31	A31	A31	First
SIDEBAND B+	A32	A32	A32	A32	A32	A32	A32	A32	Second
SIDEBAND B-	A33	A33	A33	A33	A33	A33	A33	A33	
RX 6+	N/C	N/C	N/C	N/C	N/C	N/C	A35	A35	Second
RX 6-	N/C	N/C	N/C	N/C	N/C	N/C	A36	A36	
RX 7+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	A38	
RX 7-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	A39	
TX 0+	B2	B2	B2	B2	B2	B2	B2	B2	Second
TX 0-	B3	B3	B3	B3	B3	B3	B3	B3	
TX 1+	N/C	B5	B5	B5	B5	B5	B5	B5	
TX 1-	N/C	B6	B6	B6	B6	B6	B6	B6	
^a The mating level indicates the physical dimension of the contact (see SFF-8611 and SFF-8612).									

Table 17 — Controller SAS MiniLink 8i connector pin assignments and physical link usage (part 2 of 2)

Signal	Pin usage based on number of physical links supported by the cable assembly								Mating level ^a
	One	Two	Three	Four	Five	Six	Seven	Eight	
SIDEBAND 0A	B8	B8	B8	B8	B8	B8	B8	B8	Second
SIDEBAND 1A	B9	B9	B9	B9	B9	B9	B9	B9	
SIDEBAND 2A	B10	B10	B10	B10	B10	B10	B10	B10	First
SIDEBAND 5A	B11	B11	B11	B11	B11	B11	B11	B11	Second
SIDEBAND 6A	B12	B12	B12	B12	B12	B12	B12	B12	
TX 2+	N/C	N/C	B14	B14	B14	B14	B14	B14	Second
TX 2-	N/C	N/C	B15	B15	B15	B15	B15	B15	
TX 3+	N/C	N/C	N/C	B17	B17	B17	B17	B17	
TX 3-	N/C	N/C	N/C	B18	B18	B18	B18	B18	
TX 4+	N/C	N/C	N/C	N/C	B23	B23	B23	B23	Second
TX 4-	N/C	N/C	N/C	N/C	B24	B24	B24	B24	
TX 5+	N/C	N/C	N/C	N/C	N/C	B26	B26	B26	
TX 5-	N/C	N/C	N/C	N/C	N/C	B27	B27	B27	
SIDEBAND 0B	B29	B29	B29	B29	B29	B29	B29	B29	Second
SIDEBAND 1B	B30	B30	B30	B30	B30	B30	B30	B30	
SIDEBAND 2B	B31	B31	B31	B31	B31	B31	B31	B31	First
SIDEBAND 5B	B32	B32	B32	B32	B32	B32	B32	B32	Second
SIDEBAND 6B	B33	B33	B33	B33	B33	B33	B33	B33	
TX 6+	N/C	N/C	N/C	N/C	N/C	N/C	B35	B35	Second
TX 6-	N/C	N/C	N/C	N/C	N/C	N/C	B36	B36	
TX 7+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	B38	
TX 7-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	B39	
SIGNAL GROUND	A1, A4, A7, A13, A16, A19, A22, A25, A28, A34, A 37, A40, B1 B4, B7, B13, B16, B19, B22, B25, B28, B28, B34, B37, B40								First
RESERVED	A20, A21, B20, B21								Second
^a The mating level indicates the physical dimension of the contact (see SFF-8611 and SFF-8612).									

The use of the sideband signals is vendor specific.

Table 18 defines the pin assignments for SAS MiniLink 8i cable plug connectors (see 5.4.3.3.4.2) and SAS MiniLink 8i receptacle connectors (see 5.4.3.3.4.4) for backplane applications for using one, two, three, four, five, six, seven, or eight of the physical links.

Table 18 — Backplane SAS MiniLink 8i connector pin assignments and physical link usage (part 1 of 2)

Signal	Pin usage based on number of physical links supported by the cable assembly								Mating level ^a
	One	Two	Three	Four	Five	Six	Seven	Eight	
RX 0+	A2	A2	A2	A2	A2	A2	A2	A2	Second
RX 0-	A3	A3	A3	A3	A3	A3	A3	A3	
RX 1+	N/C	A5	A5	A5	A5	A5	A5	A5	
RX 1-	N/C	A6	A6	A6	A6	A6	A6	A6	
SIDEBAND 0A	A8	A8	A8	A8	A8	A8	A8	A8	Second
SIDEBAND 1A	A9	A9	A9	A9	A9	A9	A9	A9	
SIDEBAND 2A	A10	A10	A10	A10	A10	A10	A10	A10	First
SIDEBAND 5A	A11	A11	A11	A11	A11	A11	A11	A11	Second
SIDEBAND 6A	A12	A12	A12	A12	A12	A12	A12	A12	
RX 2+	N/C	N/C	A14	A14	A14	A14	A14	A14	Second
RX 2-	N/C	N/C	A15	A15	A15	A15	A15	A15	
RX 3+	N/C	N/C	N/C	A17	A17	A17	A17	A17	
RX 3-	N/C	N/C	N/C	A18	A18	A18	A18	A18	
RX 4+	N/C	N/C	N/C	N/C	A23	A23	A23	A23	Second
RX 4-	N/C	N/C	N/C	N/C	A24	A24	A24	A24	
RX 5+	N/C	N/C	N/C	N/C	N/C	A26	A26	A26	
RX 5-	N/C	N/C	N/C	N/C	N/C	A27	A27	A27	
SIDEBAND 0B	A29	A29	A29	A29	A29	A29	A29	A29	Second
SIDEBAND 1B	A30	A30	A30	A30	A30	A30	A30	A30	
SIDEBAND 2B	A31	A31	A31	A31	A31	A31	A31	A31	First
SIDEBAND 5B	A32	A32	A32	A32	A32	A32	A32	A32	Second
SIDEBAND 6B	A33	A33	A33	A33	A33	A33	A33	A33	
RX 6+	N/C	N/C	N/C	N/C	N/C	N/C	A35	A35	Second
RX 6-	N/C	N/C	N/C	N/C	N/C	N/C	A36	A36	
RX 7+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	A38	
RX 7-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	A39	
^a The mating level indicates the physical dimension of the contact (see SFF-8611 and SFF-8612).									

Table 18 — Backplane SAS MiniLink 8i connector pin assignments and physical link usage (part 2 of 2)

Signal	Pin usage based on number of physical links supported by the cable assembly								Mating level ^a
	One	Two	Three	Four	Five	Six	Seven	Eight	
TX 0+	B2	B2	B2	B2	B2	B2	B2	B2	Second
TX 0-	B3	B3	B3	B3	B3	B3	B3	B3	
TX 1+	N/C	B5	B5	B5	B5	B5	B5	B5	
TX 1-	N/C	B6	B6	B6	B6	B6	B6	B6	
SIDEBAND 7A	B8	B8	B8	B8	B8	B8	B8	B8	Second
SIDEBAND 4A	B9	B9	B9	B9	B9	B9	B9	B9	
SIDEBAND 3A	B10	B10	B10	B10	B10	B10	B10	B10	First
SIDEBAND A+	B11	B11	B11	B11	B11	B11	B11	B11	Second
SIDEBAND A-	B12	B12	B12	B12	B12	B12	B12	B12	
TX 2+	N/C	B14	B14	B14	B14	B14	B14	B14	Second
TX 2-	N/C	B15	B15	B15	B15	B15	B15	B15	
TX 3+	N/C	B17	B17	B17	B17	B17	B17	B17	
TX 3-	N/C	B18	B18	B18	B18	B18	B18	B18	
TX 4+	N/C	B23	B23	B23	B23	B23	B23	B23	Second
TX 4-	N/C	B24	B24	B24	B24	B24	B24	B24	
TX 5+	N/C	B26	B26	B26	B26	B26	B26	B26	
TX 5-	N/C	B27	B27	B27	B27	B27	B27	B27	
SIDEBAND 7B	B29	B29	B29	B29	B29	B29	B29	B29	Second
SIDEBAND 4B	B30	B30	B30	B30	B30	B30	B30	B30	
SIDEBAND 3B	B31	B31	B31	B31	B31	B31	B31	B31	First
SIDEBAND B+	B32	B32	B32	B32	B32	B32	B32	B32	Second
SIDEBAND B-	B33	B33	B33	B33	B33	B33	B33	B33	
TX 6+	N/C	B35	B35	B35	B35	B35	B35	B35	Second
TX 6-	N/C	B36	B36	B36	B36	B36	B36	B36	
TX 7+	N/C	B38	B38	B38	B38	B38	B38	B38	
TX 7-	N/C	B39	B39	B39	B39	B39	B39	B39	
SIGNAL GROUND	A1, A4, A7, A13, A16, A19, A22, A25, A28, A34, A 37, A40, B1 B4, B7, B13, B16, B19, B22, B25, B28, B28, B34, B37, B40								First
RESERVED	A20, A21, B20, B21								Second
^a The mating level indicates the physical dimension of the contact (see SFF-8611 and SFF-8612).									

5.4.3.3.5 SlimSAS HD internal connectors

5.4.3.3.5.1 SlimSAS HD 4i cable plug connector

The SlimSAS HD 4i cable plug connector is the mechanical interface that SFF-TA-1016 defines as the Plug Connector with 38 Contacts. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 47 shows the SlimSAS HD 4i cable plug connector.

Seeking a better picture

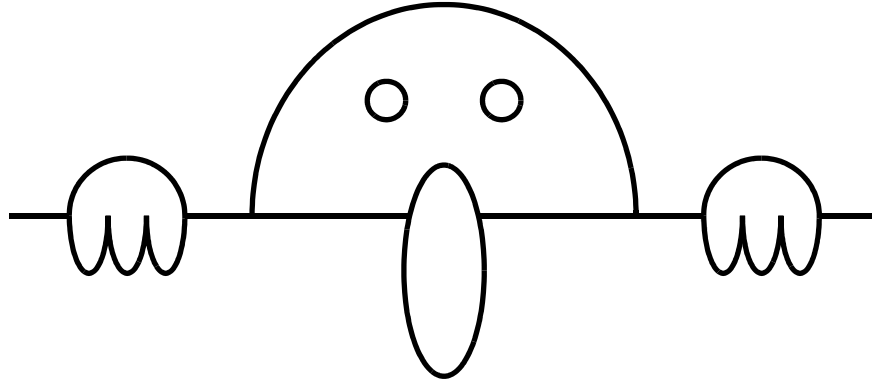


Figure 47 — SlimSAS HD 4i cable plug connector

Table 19 and table 20 define the pin assignments for the SlimSAS HD 4i cable plug connector. This connector plugs into the SlimSAS HD 4i receptacle connector (see 5.4.3.3.5.4).

5.4.3.3.5.2 SlimSAS HD 8i cable plug connector

The SlimSAS HD 8i cable plug connector is the mechanical interface that SFF-TA-1016 defines as the Plug Connector with 74 Contacts. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 48 shows the SlimSAS HD 8i cable plug connector.

Searching for a better picture

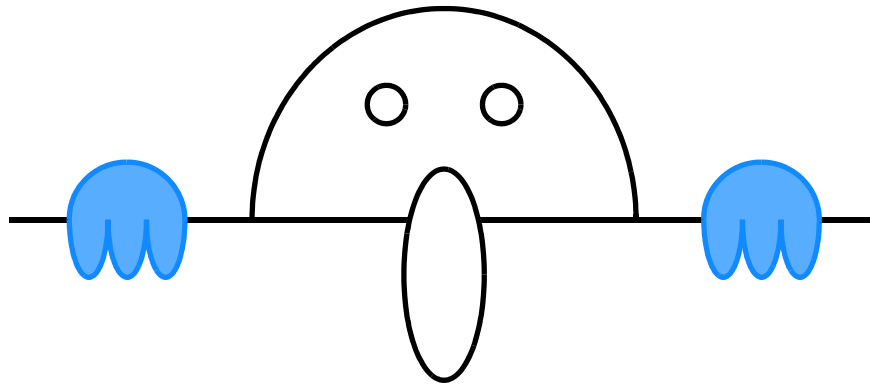


Figure 48 — SlimSAS HD 8i cable plug connector

Table 21 and table 22 define the pin assignments for the SlimSAS HD 8i cable plug connector. This connector plugs into the SlimSAS HD 8i receptacle connector (see 5.4.3.3.5.5).

5.4.3.3.5.3 SlimSAS HD 16i cable plug connector

The SlimSAS HD 16i cable plug connector is the mechanical interface that SFF-TA-1016 defines as the Plug Connector with 148 Contacts. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 49 shows the SlimSAS HD 16i cable plug connector.

Wishing for a better picture

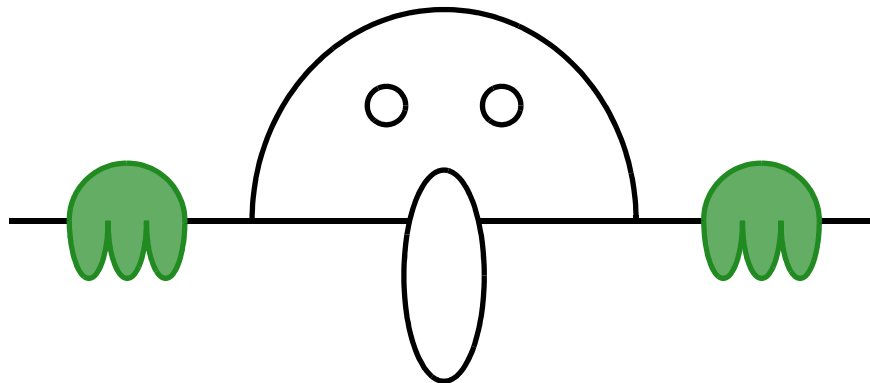


Figure 49 — SlimSAS HD 16i cable plug connector

Table 23 and table 24 define the pin assignments for the SlimSAS HD 16i cable plug connector. This connector plugs into the SlimSAS HD 16i receptacle connector (see 5.4.3.3.5.6).

5.4.3.3.5.4 SlimSAS HD 4i receptacle connector

The SlimSAS HD 4i receptacle connector is the mechanical interface that SFF-TA-1016 defines as the Receptacle Connector with 38 Contacts. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 50 shows the SlimSAS HD 4i receptacle connector.

Yearning for a better picture

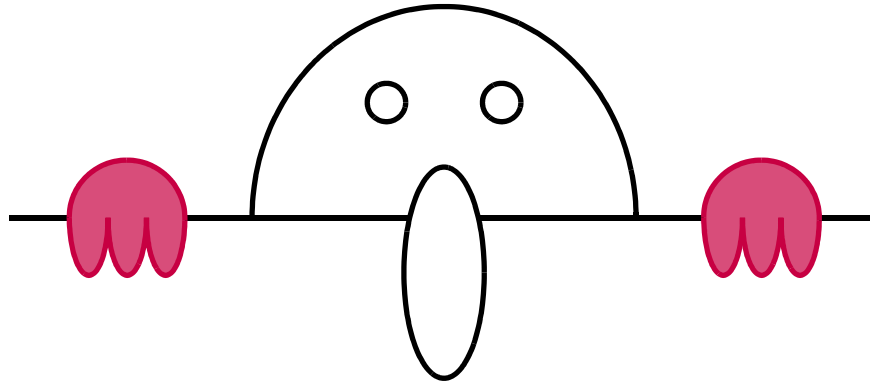


Figure 50 — SlimSAS HD 4i receptacle connector

Table 19 and table 20 define the pin assignments for the SlimSAS HD 4i receptacle connector. This connector plugs into the SlimSAS HD 4i cable plug connector (see 5.4.3.3.5.1).

5.4.3.3.5.5 SlimSAS HD 8i receptacle connector

The SlimSAS HD 8i receptacle connector is the mechanical interface that SFF-TA-1016 defines as the Receptacle Connector with 74 Contacts. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 51 shows the SlimSAS HD 8i receptacle connector.

Hungry for a better picture

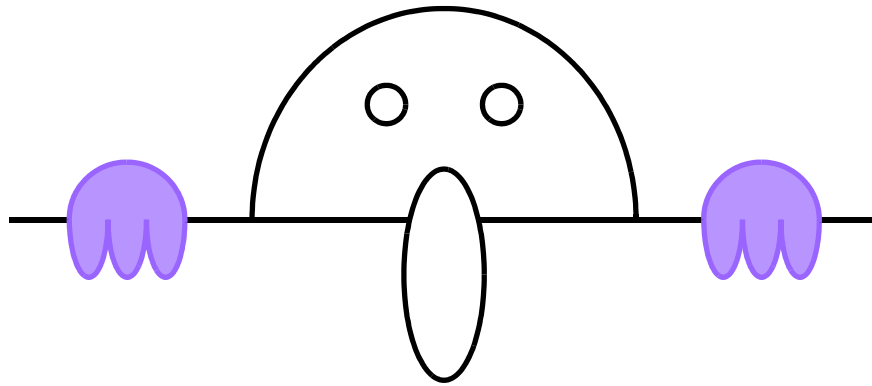


Figure 51 — SlimSAS HD 8i receptacle connector

Table 21 and table 22 define the pin assignments for the SlimSAS HD 8i receptacle connector. This connector plugs into the SlimSAS HD 8i cable plug connector (see 5.4.3.3.5.2).

5.4.3.3.5.6 SlimSAS HD 16i receptacle connector

The SlimSAS HD 16i receptacle connector is the mechanical interface that SFF-TA-1016 defines as the Receptacle Connector with 148 Contacts. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 52 shows the SlimSAS HD 16i receptacle connector.

Dreaming about a better picture

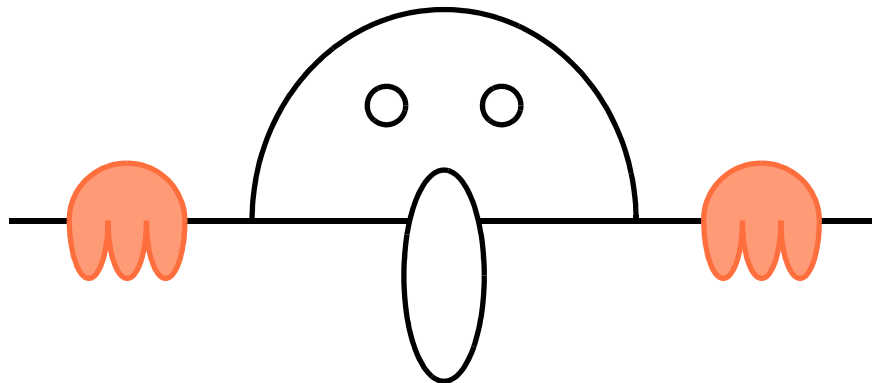


Figure 52 — SlimSAS HD 16i receptacle connector

Table 23 and table 24 define the pin assignments for the SlimSAS HD 16i receptacle connector. This connector plugs into the SlimSAS HD 16i cable plug connector (see 5.4.3.3.5.3).

5.4.3.3.5.7 SlimSAS HD connector pin assignments

Table 19 defines the pin assignments for SlimSAS HD 4i cable plug connectors (see 5.4.3.3.5.1) and SlimSAS HD 4i receptacle connectors (see 5.4.3.3.5.4) for controller applications using one, two, three, or four of the physical links.

Table 19 — Controller SlimSAS HD 4i connector pin assignments and physical link usage

Signal	Pin usage based on number of physical links supported by the cable assembly				Mating level ^a
	One	Two	Three	Four	
RX 0+	A2	A2	A2	A2	Second-mate
RX 0-	A3	A3	A3	A3	
RX 1+	N/C	A5	A5	A5	
RX 1-	N/C	A6	A6	A6	
SIDEBAND 7	A8	A8	A8	A8	Second-mate
SIDEBAND 4	A9	A9	A9	A9	
SIDEBAND 3	A10	A10	A10	A10	
SIDEBAND +	A11	A11	A11	A11	
SIDEBAND -	A12	A12	A12	A12	Second-mate
RX 2+	N/C	N/C	A14	A14	
RX 2-	N/C	N/C	A15	A15	
RX 3+	N/C	N/C	N/C	A17	
RX 3-	N/C	N/C	N/C	A18	Second-mate
TX 0+	B2	B2	B2	B2	
TX 0-	B3	B3	B3	B3	
TX 1+	N/C	B5	B5	B5	
TX 1-	N/C	B6	B6	B6	Second-mate
SIDEBAND 0	B8	B8	B8	B8	
SIDEBAND 1	B9	B9	B9	B9	
SIDEBAND 2	B10	B10	B10	B10	
SIDEBAND 5	B11	B11	B11	B11	Second-mate
SIDEBAND 6	B12	B12	B12	B12	
TX 2+	N/C	N/C	B14	B14	
TX 2-	N/C	N/C	B15	B15	
TX 3+	N/C	N/C	N/C	B17	Second-mate
TX 3-	N/C	N/C	N/C	B18	
SIGNAL GROUND	A1, A4, A7, A13, A16, A19, B1, B4, B7, B13, B16, B19				First-mate

^a The mating level indicates the physical dimension of the contact (see SFF-TA-1016).

The use of the sideband signals is vendor specific.

Table 20 defines pin assignments for SlimSAS HD 4i cable plug connectors (see 5.4.3.3.5.1) and SlimSAS HD 4i receptacle connectors (see 5.4.3.3.5.4) for backplane applications using one, two, three, or four of the physical links.

Table 20 — Backplane SlimSAS HD 4i connector pin assignments and physical link usage

Signal	Pin usage based on number of physical links supported by the cable assembly				Mating level ^a
	One	Two	Three	Four	
RX 0+	A2	A2	A2	A2	Second-mate
RX 0-	A3	A3	A3	A3	
RX 1+	N/C	A5	A5	A5	
RX 1-	N/C	A6	A6	A6	
SIDEBAND 0	A8	A8	A8	A8	Second-mate
SIDEBAND 1	A9	A9	A9	A9	
SIDEBAND 2	A10	A10	A10	A10	
SIDEBAND 5	A11	A11	A11	A11	
SIDEBAND 6	A12	A12	A12	A12	
RX 2+	N/C	N/C	A14	A14	Second-mate
RX 2-	N/C	N/C	A15	A15	
RX 3+	N/C	N/C	N/C	A17	
RX 3-	N/C	N/C	N/C	A18	
TX 0+	B2	B2	B2	B2	Second-mate
TX 0-	B3	B3	B3	B3	
TX 1+	N/C	B5	B5	B5	
TX 1-	N/C	B6	B6	B6	
SIDEBAND 7	B8	B8	B8	B8	Second-mate
SIDEBAND 4	B9	B9	B9	B9	
SIDEBAND 3	B10	B10	B10	B10	
SIDEBAND +	B11	B11	B11	B11	
SIDEBAND -	B12	B12	B12	B12	
TX 2+	N/C	N/C	B14	B14	Second-mate
TX 2-	N/C	N/C	B15	B15	
TX 3+	N/C	N/C	N/C	B17	
TX 3-	N/C	N/C	N/C	B18	
SIGNAL GROUND	A1, A4, A7, A13, A16, A19, B1, B4, B7, B13, B16, B19				First-mate
^a The mating level indicates the physical dimension of the contact (see SFF-TA-1016).					

The use of the sideband signals is vendor specific.

Table 21 defines the pin assignments for SlimSAS HD 8i cable plug connectors (see 5.4.3.3.5.2) and SlimSAS HD 8i receptacle connectors (see 5.4.3.3.5.5) for controller applications using one, two, three, four, five, six, seven, or eight of the physical links.

Table 21 — Controller SlimSAS HD 8i connector pin assignments and physical link usage (part 1 of 2)

Signal	Pin usage based on number of physical links supported by the cable assembly								Mating level ^a
	One	Two	Three	Four	Five	Six	Seven	Eight	
RX 0+	A2	A2	A2	A2	A2	A2	A2	A2	Second-mate
RX 0-	A3	A3	A3	A3	A3	A3	A3	A3	
RX 1+	N/C	A5	A5	A5	A5	A5	A5	A5	
RX 1-	N/C	A6	A6	A6	A6	A6	A6	A6	
SIDEBAND 7A	A8	A8	A8	A8	A8	A8	A8	A8	Second-mate
SIDEBAND 4A	A9	A9	A9	A9	A9	A9	A9	A9	
SIDEBAND 3A	A10	A10	A10	A10	A10	A10	A10	A10	
SIDEBAND A+	A11	A11	A11	A11	A11	A11	A11	A11	
SIDEBAND A-	A12	A12	A12	A12	A12	A12	A12	A12	
RX 2+	N/C	N/C	A14	A14	A14	A14	A14	A14	Second-mate
RX 2-	N/C	N/C	A15	A15	A15	A15	A15	A15	
RX 3+	N/C	N/C	N/C	A17	A17	A17	A17	A17	
RX 3-	N/C	N/C	N/C	A18	A18	A18	A18	A18	
RX 4+	N/C	N/C	N/C	N/C	A20	A20	A20	A20	Second-mate
RX 4-	N/C	N/C	N/C	N/C	A21	A21	A21	A21	
RX 5+	N/C	N/C	N/C	N/C	N/C	A23	A23	A23	
RX 5-	N/C	N/C	N/C	N/C	N/C	A24	A24	A24	
SIDEBAND 7B	A26	A26	A26	A26	A26	A26	A26	A26	Second-mate
SIDEBAND 4B	A27	A27	A27	A27	A27	A27	A27	A27	
SIDEBAND 3B	A28	A28	A28	A28	A28	A28	A28	A28	
SIDEBAND B+	A29	A29	A29	A29	A29	A29	A29	A29	
SIDEBAND B-	A30	A30	A30	A30	A30	A30	A30	A30	
RX 6+	N/C	N/C	N/C	N/C	N/C	N/C	A32	A32	Second-mate
RX 6-	N/C	N/C	N/C	N/C	N/C	N/C	A33	A33	
RX 7+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	A35	
RX 7-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	A36	
a The mating level indicates the physical dimension of the contact (see SFF-TA-1016).									

Table 21 — Controller SlimSAS HD 8i connector pin assignments and physical link usage (part 2 of 2)

Signal	Pin usage based on number of physical links supported by the cable assembly								Mating level ^a
	One	Two	Three	Four	Five	Six	Seven	Eight	
TX 0+	B2	B2	B2	B2	B2	B2	B2	B2	Second-mate
TX 0-	B3	B3	B3	B3	B3	B3	B3	B3	
TX 1+	N/C	B5	B5	B5	B5	B5	B5	B5	
TX 1-	N/C	B6	B6	B6	B6	B6	B6	B6	
SIDEBAND 0A	B8	B8	B8	B8	B8	B8	B8	B8	Second-mate
SIDEBAND 1A	B9	B9	B9	B9	B9	B9	B9	B9	
SIDEBAND 2A	B10	B10	B10	B10	B10	B10	B10	B10	
SIDEBAND 5A	B11	B11	B11	B11	B11	B11	B11	B11	
SIDEBAND 6A	B12	B12	B12	B12	B12	B12	B12	B12	
TX 2+	N/C	N/C	B14	B14	B14	B14	B14	B14	Second-mate
TX 2-	N/C	N/C	B15	B15	B15	B15	B15	B15	
TX 3+	N/C	N/C	N/C	B17	B17	B17	B17	B17	
TX 3-	N/C	N/C	N/C	B18	B18	B18	B18	B18	
TX 4+	N/C	N/C	N/C	N/C	B20	B20	B20	B20	Second-mate
TX 4-	N/C	N/C	N/C	N/C	B21	B21	B21	B21	
TX 5+	N/C	N/C	N/C	N/C	N/C	B23	B23	B23	
TX 5-	N/C	N/C	N/C	N/C	N/C	B24	B24	B24	
SIDEBAND 0B	B26	B26	B26	B26	B26	B26	B26	B26	Second-mate
SIDEBAND 1B	B27	B27	B27	B27	B27	B27	B27	B27	
SIDEBAND 2B	B28	B28	B28	B28	B28	B28	B28	B28	
SIDEBAND 5B	B29	B29	B29	B29	B29	B29	B29	B29	
SIDEBAND 6B	B30	B30	B30	B30	B30	B30	B30	B30	
TX 6+	N/C	N/C	N/C	N/C	N/C	N/C	B32	B32	Second-mate
TX 6-	N/C	N/C	N/C	N/C	N/C	N/C	B33	B33	
TX 7+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	B35	
TX 7-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	B36	
SIGNAL GROUND	A1, A4, A7, A13, A16, A19, A22, A25, A31, A34, A37, B1, B4, B7, B13, B16, B19, B22, B25, B31, B34, B37								First-mate
a The mating level indicates the physical dimension of the contact (see SFF-TA-1016).									

The use of the sideband signals is vendor specific.

Table 22 defines the pin assignments for SlimSAS HD 8i cable plug connectors (see 5.4.3.3.5.2) and SlimSAS HD 8i receptacle connectors (see 5.4.3.3.5.5) for backplane applications using one, two, three, four, five, six, seven, or eight of the physical links.

Table 22 — Backplane SlimSAS HD 8i connector pin assignments and physical link usage (part 1 of 2)

Signal	Pin usage based on number of physical links supported by the cable assembly								Mating level ^a
	One	Two	Three	Four	Five	Six	Seven	Eight	
RX 0+	A2	A2	A2	A2	A2	A2	A2	A2	Second-mate
RX 0-	A3	A3	A3	A3	A3	A3	A3	A3	
RX 1+	N/C	A5	A5	A5	A5	A5	A5	A5	
RX 1-	N/C	A6	A6	A6	A6	A6	A6	A6	
SIDEBAND 0A	A8	A8	A8	A8	A8	A8	A8	A8	Second-mate
SIDEBAND 1A	A9	A9	A9	A9	A9	A9	A9	A9	
SIDEBAND 2A	A10	A10	A10	A10	A10	A10	A10	A10	
SIDEBAND 5A	A11	A11	A11	A11	A11	A11	A11	A11	
SIDEBAND 6A	A12	A12	A12	A12	A12	A12	A12	A12	
RX 2+	N/C	N/C	A14	A14	A14	A14	A14	A14	Second-mate
RX 2-	N/C	N/C	A15	A15	A15	A15	A15	A15	
RX 3+	N/C	N/C	N/C	A17	A17	A17	A17	A17	
RX 3-	N/C	N/C	N/C	A18	A18	A18	A18	A18	
RX 4+	N/C	N/C	N/C	N/C	A20	A20	A20	A20	Second-mate
RX 4-	N/C	N/C	N/C	N/C	A21	A21	A21	A21	
RX 5+	N/C	N/C	N/C	N/C	N/C	A23	A23	A23	
RX 5-	N/C	N/C	N/C	N/C	N/C	A24	A24	A24	
SIDEBAND 0B	A26	A26	A26	A26	A26	A26	A26	A26	Second-mate
SIDEBAND 1B	A27	A27	A27	A27	A27	A27	A27	A27	
SIDEBAND 2B	A28	A28	A28	A28	A28	A28	A28	A28	
SIDEBAND 5B	A29	A29	A29	A29	A29	A29	A29	A29	
SIDEBAND 6B	A30	A30	A30	A30	A30	A30	A30	A30	
RX 6+	N/C	N/C	N/C	N/C	N/C	N/C	A32	A32	Second-mate
RX 6-	N/C	N/C	N/C	N/C	N/C	N/C	A33	A33	
RX 7+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	A35	
RX 7-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	A36	
TX 0+	B2	B2	B2	B2	B2	B2	B2	B2	Second-mate
TX 0-	B3	B3	B3	B3	B3	B3	B3	B3	
TX 1+	N/C	B5	B5	B5	B5	B5	B5	B5	
TX 1-	N/C	B6	B6	B6	B6	B6	B6	B6	
^a The mating level indicates the physical dimension of the contact (see SFF-TA-1016).									

Table 22 — Backplane SlimSAS HD 8i connector pin assignments and physical link usage (part 2 of 2)

Signal	Pin usage based on number of physical links supported by the cable assembly								Mating level ^a
	One	Two	Three	Four	Five	Six	Seven	Eight	
SIDEBAND 7A	B8	B8	B8	B8	B8	B8	B8	B8	Second-mate
SIDEBAND 4A	B9	B9	B9	B9	B9	B9	B9	B9	
SIDEBAND 3A	B10	B10	B10	B10	B10	B10	B10	B10	
SIDEBAND A+	B11	B11	B11	B11	B11	B11	B11	B11	
SIDEBAND A-	B12	B12	B12	B12	B12	B12	B12	B12	
TX 2+	N/C	N/C	B14	B14	B14	B14	B14	B14	Second-mate
TX 2-	N/C	N/C	B15	B15	B15	B15	B15	B15	
TX 3+	N/C	N/C	N/C	B17	B17	B17	B17	B17	
TX 3-	N/C	N/C	N/C	B18	B18	B18	B18	B18	
TX 4+	N/C	N/C	N/C	N/C	B20	B20	B20	B20	Second-mate
TX 4-	N/C	N/C	N/C	N/C	B21	B21	B21	B21	
TX 5+	N/C	N/C	N/C	N/C	N/C	B23	B23	B23	
TX 5-	N/C	N/C	N/C	N/C	N/C	B24	B24	B24	
SIDEBAND 7B	B26	B26	B26	B26	B26	B26	B26	B26	Second-mate
SIDEBAND 4B	B27	B27	B27	B27	B27	B27	B27	B27	
SIDEBAND 3B	B28	B28	B28	B28	B28	B28	B28	B28	
SIDEBAND B+	B29	B29	B29	B29	B29	B29	B29	B29	
SIDEBAND B-	B30	B30	B30	B30	B30	B30	B30	B30	
TX 6+	N/C	N/C	N/C	N/C	N/C	N/C	B32	B32	Second-mate
TX 6-	N/C	N/C	N/C	N/C	N/C	N/C	B33	B33	
TX 7+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	B35	
TX 7-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	B36	
SIGNAL GROUND	A1, A4, A7, A13, A16, A19, A22, A25, A31, A34, A37 B1, B4, B7, B13, B16, B19, B22, B25, B31, B34, B37								First-mate
^a The mating level indicates the physical dimension of the contact (see SFF-TA-1016).									

The use of the sideband signals is vendor specific.

Table 23 defines the pin assignments for SlimSAS HD 16i cable plug connectors (see 5.4.3.3.5.3) and SlimSAS HD 16i receptacle connectors (see 5.4.3.3.5.6) for controller applications using one to eight of the physical links.

Table 23 — Controller SlimSAS HD 16i connector pin assignments and physical link usage (part 1 of 4)

Signal	Pin usage based on number of physical links supported by the cable assembly								Mating level ^a
	One	Two	Three	Four	Five	Six	Seven	Eight	
RX 0+	A2	A2	A2	A2	A2	A2	A2	A2	Second-mate
RX 0-	A3	A3	A3	A3	A3	A3	A3	A3	
RX 1+	N/C	A5	A5	A5	A5	A5	A5	A5	
RX 1-	N/C	A6	A6	A6	A6	A6	A6	A6	
SIDEBAND 7A	A8	A8	A8	A8	A8	A8	A8	A8	Second-mate
SIDEBAND 4A	A9	A9	A9	A9	A9	A9	A9	A9	
SIDEBAND 3A	A10	A10	A10	A10	A10	A10	A10	A10	
SIDEBAND A+	A11	A11	A11	A11	A11	A11	A11	A11	
SIDEBAND A-	A12	A12	A12	A12	A12	A12	A12	A12	Second-mate
RX 2+	N/C	N/C	A14	A14	A14	A14	A14	A14	
RX 2-	N/C	N/C	A15	A15	A15	A15	A15	A15	
RX 3+	N/C	N/C	N/C	A17	A17	A17	A17	A17	
RX 3-	N/C	N/C	N/C	A18	A18	A18	A18	A18	Second-mate
RX 4+	N/C	N/C	N/C	N/C	A20	A20	A20	A20	
RX 4-	N/C	N/C	N/C	N/C	A21	A21	A21	A21	
RX 5+	N/C	N/C	N/C	N/C	N/C	A23	A23	A23	
RX 5-	N/C	N/C	N/C	N/C	N/C	A24	A24	A24	Second-mate
SIDEBAND 7B	A26	A26	A26	A26	A26	A26	A26	A26	
SIDEBAND 4B	A27	A27	A27	A27	A27	A27	A27	A27	
SIDEBAND 3B	A28	A28	A28	A28	A28	A28	A28	A28	
SIDEBAND B+	A29	A29	A29	A29	A29	A29	A29	A29	Second-mate
SIDEBAND B-	A30	A30	A30	A30	A30	A30	A30	A30	
RX 6+	N/C	N/C	N/C	N/C	N/C	N/C	A32	A32	
RX 6-	N/C	N/C	N/C	N/C	N/C	N/C	A33	A33	
RX 7+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	A35	Second-mate
RX 7-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	A36	
RX 8+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
RX 8-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
RX 9+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	Second-mate
RX 9-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	

^a The mating level indicates the physical dimension of the contact (see SFF-TA-1016).

Table 23 — Controller SlimSAS HD 16i connector pin assignments and physical link usage (part 2 of 4)

Signal	Pin usage based on number of physical links supported by the cable assembly								Mating level ^a
	One	Two	Three	Four	Five	Six	Seven	Eight	
SIDEBAND 7C	A45	A45	A45	A45	A45	A45	A45	A45	Second-mate
SIDEBAND 4C	A46	A46	A46	A46	A46	A46	A46	A46	
SIDEBAND 3C	A47	A47	A47	A47	A47	A47	A47	A47	
SIDEBAND C+	A48	A48	A48	A48	A48	A48	A48	A48	
SIDEBAND C-	A49	A49	A49	A49	A49	A49	A49	A49	
RX 10+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	Second-mate
RX 10-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
RX 11+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
RX 11-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
RX 12+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	Second-mate
RX 12-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
RX 13+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
RX 13-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
SIDEBAND 7D	A63	A63	A63	A63	A63	A63	A63	A63	Second-mate
SIDEBAND 4D	A64	A64	A64	A64	A64	A64	A64	A64	
SIDEBAND 3D	A65	A65	A65	A65	A65	A65	A65	A65	
SIDEBAND D+	A66	A66	A66	A66	A66	A66	A66	A66	
SIDEBAND D-	A67	A67	A67	A67	A67	A67	A67	A67	
RX 14+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	Second-mate
RX 14-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
RX 15+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
RX 15-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
TX 0+	B2	B2	B2	B2	B2	B2	B2	B2	Second-mate
TX 0-	B3	B3	B3	B3	B3	B3	B3	B3	
TX 1+	N/C	B5	B5	B5	B5	B5	B5	B5	
TX 1-	N/C	B6	B6	B6	B6	B6	B6	B6	
SIDEBAND 0A	B8	B8	B8	B8	B8	B8	B8	B8	Second-mate
SIDEBAND 1A	B9	B9	B9	B9	B9	B9	B9	B9	
SIDEBAND 2A	B10	B10	B10	B10	B10	B10	B10	B10	
SIDEBAND 5A	B11	B11	B11	B11	B11	B11	B11	B11	
SIDEBAND 6A	B12	B12	B12	B12	B12	B12	B12	B12	

^a The mating level indicates the physical dimension of the contact (see SFF-TA-1016).

Table 23 — Controller SlimSAS HD 16i connector pin assignments and physical link usage (part 3 of 4)

Signal	Pin usage based on number of physical links supported by the cable assembly								Mating level ^a
	One	Two	Three	Four	Five	Six	Seven	Eight	
TX 2+	N/C	N/C	B14	B14	B14	B14	B14	B14	Second-mate
TX 2-	N/C	N/C	B15	B15	B15	B15	B15	B15	
TX 3+	N/C	N/C	N/C	B17	B17	B17	B17	B17	
TX 3-	N/C	N/C	N/C	B18	B18	B18	B18	B18	
TX 4+	N/C	N/C	N/C	N/C	B20	B20	B20	B20	Second-mate
TX 4-	N/C	N/C	N/C	N/C	B21	B21	B21	B21	
TX 5+	N/C	N/C	N/C	N/C	N/C	B23	B23	B23	
TX 5-	N/C	N/C	N/C	N/C	N/C	B24	B24	B24	
SIDEBAND 0B	B26	B26	B26	B26	B26	B26	B26	B26	Second-mate
SIDEBAND 1B	B27	B27	B27	B27	B27	B27	B27	B27	
SIDEBAND 2B	B28	B28	B28	B28	B28	B28	B28	B28	
SIDEBAND 5B	B29	B29	B29	B29	B29	B29	B29	B29	
SIDEBAND 6B	B30	B30	B30	B30	B30	B30	B30	B30	
TX 6+	N/C	N/C	N/C	N/C	N/C	N/C	B32	B32	Second-mate
TX 6-	N/C	N/C	N/C	N/C	N/C	N/C	B33	B33	
TX 7+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	B35	
TX 7-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	B36	
TX 8+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	Second-mate
TX 8-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
TX 9+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
TX 9-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
SIDEBAND 0C	A45	A45	A45	A45	A45	A45	A45	A45	Second-mate
SIDEBAND 1C	A46	A46	A46	A46	A46	A46	A46	A46	
SIDEBAND 2C	A47	A47	A47	A47	A47	A47	A47	A47	
SIDEBAND 5C	A48	A48	A48	A48	A48	A48	A48	A48	
SIDEBAND 6C	A49	A49	A49	A49	A49	A49	A49	A49	
TX 10+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	Second-mate
TX 10-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
TX 11+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
TX 11-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
^a The mating level indicates the physical dimension of the contact (see SFF-TA-1016).									

Table 23 — Controller SlimSAS HD 16i connector pin assignments and physical link usage (part 4 of 4)

Signal	Pin usage based on number of physical links supported by the cable assembly								Mating level ^a
	One	Two	Three	Four	Five	Six	Seven	Eight	
TX 12+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	Second-mate
TX 12-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
TX 13+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
TX 13-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
SIDEBAND 0D	B63	B63	B63	B63	B63	B63	B63	B63	Second-mate
SIDEBAND 1D	B64	B64	B64	B64	B64	B64	B64	B64	
SIDEBAND 2D	B65	B65	B65	B65	B65	B65	B65	B65	
SIDEBAND 5D	B66	B66	B66	B66	B66	B66	B66	B66	
SIDEBAND 6D	B67	B67	B67	B67	B67	B67	B67	B67	
TX 14+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	Second-mate
TX 14-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
TX 15+	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
TX 15-	N/C	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
SIGNAL GROUND	A1, A4, A7, A13, A16, A19, A22, A25, A31, A34, A37, A38, A41, A44, A50, A53, A56, A59, A62, A68, A71, A74 B1, B4, B7, B13, B16, B19, B22, B25, B31, B34, B37, A38, B41, B44, B50, B53, B56, B59, B62, B68, B71, B74								First-mate
^a The mating level indicates the physical dimension of the contact (see SFF-TA-1016).									

The use of the sideband signals is vendor specific.

Table 24 defines the pin assignments for SlimSAS HD 16i cable plug connectors (see 5.4.3.3.5.3) and SlimSAS HD 16i receptacle connectors (see 5.4.3.3.5.6) for controller applications using 9 to 16 of the physical links.

Table 24 — Controller SlimSAS HD 16i connector pin assignments and physical link usage (part 1 of 4)

Signal	Pin usage based on number of physical links supported by the cable assembly								Mating level ^a
	9	10	11	12	13	14	15	16	
RX 0+	A2	A2	A2	A2	A2	A2	A2	A2	Second-mate
RX 0-	A3	A3	A3	A3	A3	A3	A3	A3	
RX 1+	A5	A5	A5	A5	A5	A5	A5	A5	
RX 1-	A6	A6	A6	A6	A6	A6	A6	A6	
SIDEBAND 7A	A8	A8	A8	A8	A8	A8	A8	A8	Second-mate
SIDEBAND 4A	A9	A9	A9	A9	A9	A9	A9	A9	
SIDEBAND 3A	A10	A10	A10	A10	A10	A10	A10	A10	
SIDEBAND A+	A11	A11	A11	A11	A11	A11	A11	A11	
SIDEBAND A-	A12	A12	A12	A12	A12	A12	A12	A12	Second-mate
RX 2+	A14	A14	A14	A14	A14	A14	A14	A14	
RX 2-	A15	A15	A15	A15	A15	A15	A15	A15	
RX 3+	A17	A17	A17	A17	A17	A17	A17	A17	
RX 3-	A18	A18	A18	A18	A18	A18	A18	A18	Second-mate
RX 4+	A20	A20	A20	A20	A20	A20	A20	A20	
RX 4-	A21	A21	A21	A21	A21	A21	A21	A21	
RX 5+	A23	A23	A23	A23	A23	A23	A23	A23	
RX 5-	A24	A24	A24	A24	A24	A24	A24	A24	Second-mate
SIDEBAND 7B	A26	A26	A26	A26	A26	A26	A26	A26	
SIDEBAND 4B	A27	A27	A27	A27	A27	A27	A27	A27	
SIDEBAND 3B	A28	A28	A28	A28	A28	A28	A28	A28	
SIDEBAND B+	A29	A29	A29	A29	A29	A29	A29	A29	Second-mate
SIDEBAND B-	A30	A30	A30	A30	A30	A30	A30	A30	
RX 6+	A32	A32	A32	A32	A32	A32	A32	A32	
RX 6-	A33	A33	A33	A33	A33	A33	A33	A33	
RX 7+	A35	A35	A35	A35	A35	A35	A35	A35	Second-mate
RX 7-	A36	A36	A36	A36	A36	A36	A36	A36	
RX 8+	A39	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
RX 8-	A40	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
RX 9+	A42	A42	N/C	N/C	N/C	N/C	N/C	N/C	Second-mate
RX 9-	A43	A43	N/C	N/C	N/C	N/C	N/C	N/C	

^a The mating level indicates the physical dimension of the contact (see SFF-TA-1016).

Table 24 — Controller SlimSAS HD 16i connector pin assignments and physical link usage (part 2 of 4)

Signal	Pin usage based on number of physical links supported by the cable assembly								Mating level ^a
	9	10	11	12	13	14	15	16	
SIDEBAND 7C	A45	A45	A45	A45	A45	A45	A45	A45	Second-mate
SIDEBAND 4C	A46	A46	A46	A46	A46	A46	A46	A46	
SIDEBAND 3C	A47	A47	A47	A47	A47	A47	A47	A47	
SIDEBAND C+	A48	A48	A48	A48	A48	A48	A48	A48	
SIDEBAND C-	A49	A49	A49	A49	A49	A49	A49	A49	
RX 10+	A51	A51	A51	N/C	N/C	N/C	N/C	N/C	Second-mate
RX 10-	A52	A52	A52	N/C	N/C	N/C	N/C	N/C	
RX 11+	A54	A54	A54	A54	N/C	N/C	N/C	N/C	
RX 11-	A55	A55	A55	A55	N/C	N/C	N/C	N/C	
RX 12+	A57	A57	A57	A57	A57	N/C	N/C	N/C	Second-mate
RX 12-	A58	A58	A58	A58	A58	N/C	N/C	N/C	
RX 13+	A60	A60	A60	A60	A60	A60	N/C	N/C	
RX 13-	A61	A61	A61	A61	A61	A61	N/C	N/C	
SIDEBAND 7D	A63	A63	A63	A63	A63	A63	A63	A63	Second-mate
SIDEBAND 4D	A64	A64	A64	A64	A64	A64	A64	A64	
SIDEBAND 3D	A65	A65	A65	A65	A65	A65	A65	A65	
SIDEBAND D+	A66	A66	A66	A66	A66	A66	A66	A66	
SIDEBAND D-	A67	A67	A67	A67	A67	A67	A67	A67	
RX 14+	A69	A69	A69	A69	A69	A69	A69	N/C	Second-mate
RX 14-	A70	A70	A70	A70	A70	A70	A70	N/C	
RX 15+	A72	A72	A72	A72	A72	A72	A72	A72	
RX 15-	A73	A73	A73	A73	A73	A73	A73	A73	
TX 0+	B2	B2	B2	B2	B2	B2	B2	B2	Second-mate
TX 0-	B3	B3	B3	B3	B3	B3	B3	B3	
TX 1+	B5	B5	B5	B5	B5	B5	B5	B5	
TX 1-	B6	B6	B6	B6	B6	B6	B6	B6	
SIDEBAND 0A	B8	B8	B8	B8	B8	B8	B8	B8	Second-mate
SIDEBAND 1A	B9	B9	B9	B9	B9	B9	B9	B9	
SIDEBAND 2A	B10	B10	B10	B10	B10	B10	B10	B10	
SIDEBAND 5A	B11	B11	B11	B11	B11	B11	B11	B11	
SIDEBAND 6A	B12	B12	B12	B12	B12	B12	B12	B12	

^a The mating level indicates the physical dimension of the contact (see SFF-TA-1016).

Table 24 — Controller SlimSAS HD 16i connector pin assignments and physical link usage (part 3 of 4)

Signal	Pin usage based on number of physical links supported by the cable assembly								Mating level ^a
	9	10	11	12	13	14	15	16	
TX 2+	B14	B14	B14	B14	B14	B14	B14	B14	Second-mate
TX 2-	B15	B15	B15	B15	B15	B15	B15	B15	
TX 3+	B17	B17	B17	B17	B17	B17	B17	B17	
TX 3-	B18	B18	B18	B18	B18	B18	B18	B18	
TX 4+	B20	B20	B20	B20	B20	B20	B20	B20	Second-mate
TX 4-	B21	B21	B21	B21	B21	B21	B21	B21	
TX 5+	B23	B23	B23	B23	B23	B23	B23	B23	
TX 5-	B24	B24	B24	B24	B24	B24	B24	B24	
SIDEBAND 0B	B26	B26	B26	B26	B26	B26	B26	B26	Second-mate
SIDEBAND 1B	B27	B27	B27	B27	B27	B27	B27	B27	
SIDEBAND 2B	B28	B28	B28	B28	B28	B28	B28	B28	
SIDEBAND 5B	B29	B29	B29	B29	B29	B29	B29	B29	
SIDEBAND 6B	B30	B30	B30	B30	B30	B30	B30	B30	
TX 6+	B32	B32	B32	B32	B32	B32	B32	B32	Second-mate
TX 6-	B33	B33	B33	B33	B33	B33	B33	B33	
TX 7+	B35	B35	B35	B35	B35	B35	B35	B35	
TX 7-	B36	B36	B36	B36	B36	B36	B36	B36	
TX 8+	B39	N/C	N/C	N/C	N/C	N/C	N/C	N/C	Second-mate
TX 8-	B40	N/C	N/C	N/C	N/C	N/C	N/C	N/C	
TX 9+	B42	B42	N/C	N/C	N/C	N/C	N/C	N/C	
TX 9-	B43	B43	N/C	N/C	N/C	N/C	N/C	N/C	
SIDEBAND 0C	A45	A45	A45	A45	A45	A45	A45	A45	Second-mate
SIDEBAND 1C	A46	A46	A46	A46	A46	A46	A46	A46	
SIDEBAND 2C	A47	A47	A47	A47	A47	A47	A47	A47	
SIDEBAND 5C	A48	A48	A48	A48	A48	A48	A48	A48	
SIDEBAND 6C	A49	A49	A49	A49	A49	A49	A49	A49	
TX 10+	B51	B51	B51	N/C	N/C	N/C	N/C	N/C	Second-mate
TX 10-	B52	B52	B52	N/C	N/C	N/C	N/C	N/C	
TX 11+	B54	B54	B54	B54	N/C	N/C	N/C	N/C	
TX 11-	B55	B55	B55	B55	N/C	N/C	N/C	N/C	
^a The mating level indicates the physical dimension of the contact (see SFF-TA-1016).									

Table 24 — Controller SlimSAS HD 16i connector pin assignments and physical link usage (part 4 of 4)

Signal	Pin usage based on number of physical links supported by the cable assembly								Mating level ^a
	9	10	11	12	13	14	15	16	
TX 12+	B57	B57	B57	B57	B57	N/C	N/C	N/C	Second-mate
TX 12-	B58	B58	B58	B58	B58	N/C	N/C	N/C	
TX 13+	B60	B60	B60	B60	B60	B60	N/C	N/C	
TX 13-	B61	B61	B61	B61	B61	B61	N/C	N/C	
SIDEBAND 0D	B63	B63	B63	B63	B63	B63	B63	B63	Second-mate
SIDEBAND 1D	B64	B64	B64	B64	B64	B64	B64	B64	
SIDEBAND 2D	B65	B65	B65	B65	B65	B65	B65	B65	
SIDEBAND 5D	B66	B66	B66	B66	B66	B66	B66	B66	
SIDEBAND 6D	B67	B67	B67	B67	B67	B67	B67	B67	
TX 14+	B69	B69	B69	B69	B69	B69	B69	N/C	Second-mate
TX 14-	B70	B70	B70	B70	B70	B70	B70	N/C	
TX 15+	B72	B72	B72	B72	B72	B72	B72	B72	
TX 15-	B73	B73	B73	B73	B73	B73	B73	B73	
SIGNAL GROUND	A1, A4, A7, A13, A16, A19, A22, A25, A31, A34, A37, A38, A41, A44, A50, A53, A56, A59, A62, A68, A71, A74 B1, B4, B7, B13, B16, B19, B22, B25, B31, B34, B37, A38, B41, B44, B50, B53, B56, B59, B62, B68, B71, B74								First-mate
^a The mating level indicates the physical dimension of the contact (see SFF-TA-1016).									

The use of the sideband signals is vendor specific.

5.4.3.4 SAS external connectors

5.4.3.4.1 Mini SAS HD external connectors

5.4.3.4.1.1 Mini SAS HD 4x cable plug connector

The Mini SAS HD 4x cable plug connector is the free (plug) 36-circuit connector mechanical interface defined in SFF-8644. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 53 shows the Mini SAS HD 4x cable plug connector.

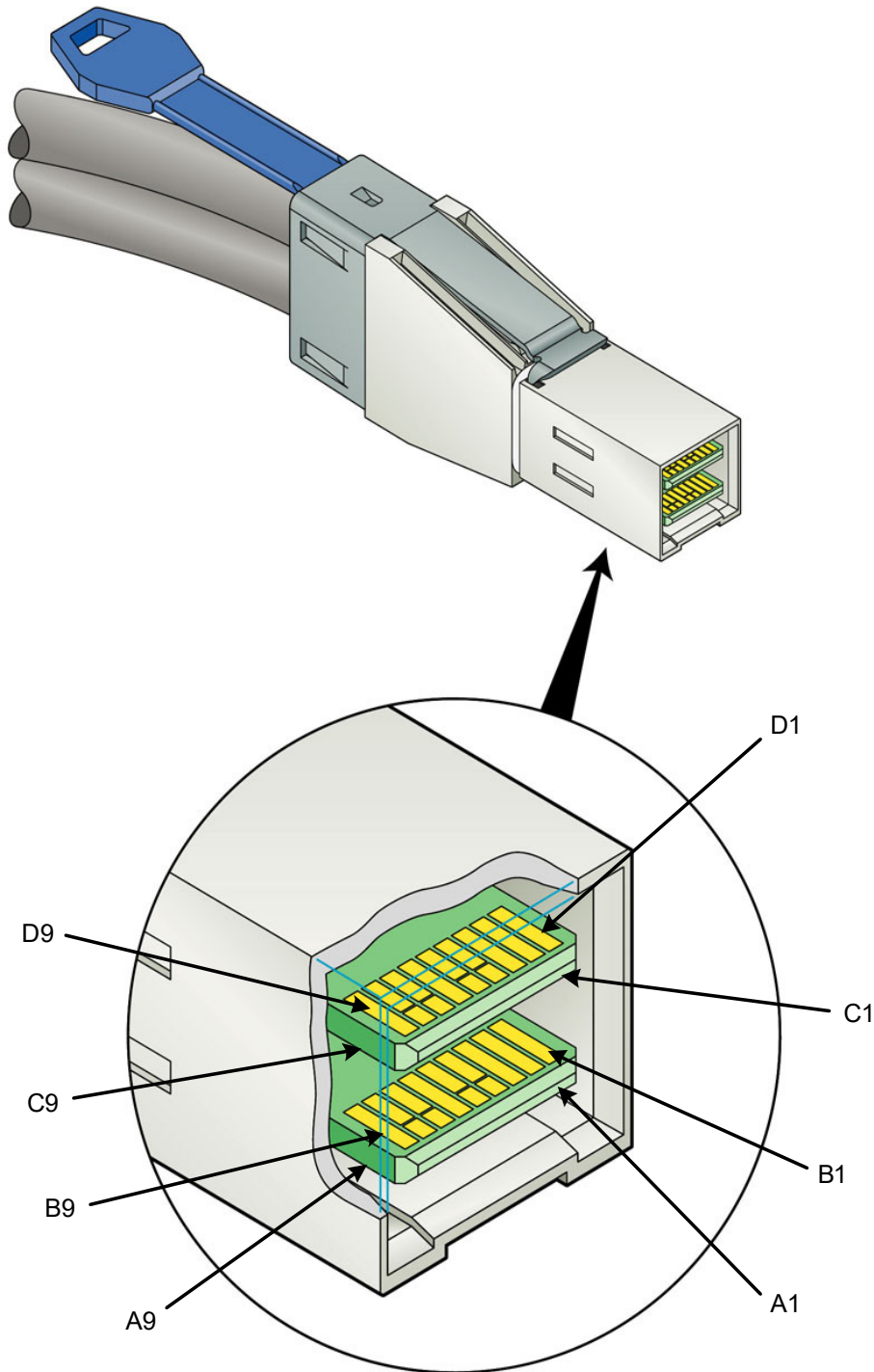


Figure 53 — Mini SAS HD 4x cable plug connector

If constructed with a pull tab as shown in figure 53, then the pull tab should use PANTONE 279 C (i.e., light blue).

Table 25 defines the pin assignments for the Mini SAS HD 4x cable plug connector.

The Mini SAS HD 4x cable plug connectors shall not include keying except for orientation.

5.4.3.4.1.2 Mini SAS HD 8x cable plug connector

The Mini SAS HD 8i cable plug connector is the dual four lane cable plug (free) connector mechanical interface defined in SFF-8644. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 54 shows the Mini SAS HD 8x cable plug connector. This connector is a modular version of repeating Mini SAS HD 4x cable plug connectors (see 5.4.3.4.1.1). Module labeling is shown in figure 54. See figure 53 for pin designations. Mini SAS HD 8x cable plug connectors shall not include keying except for orientation.

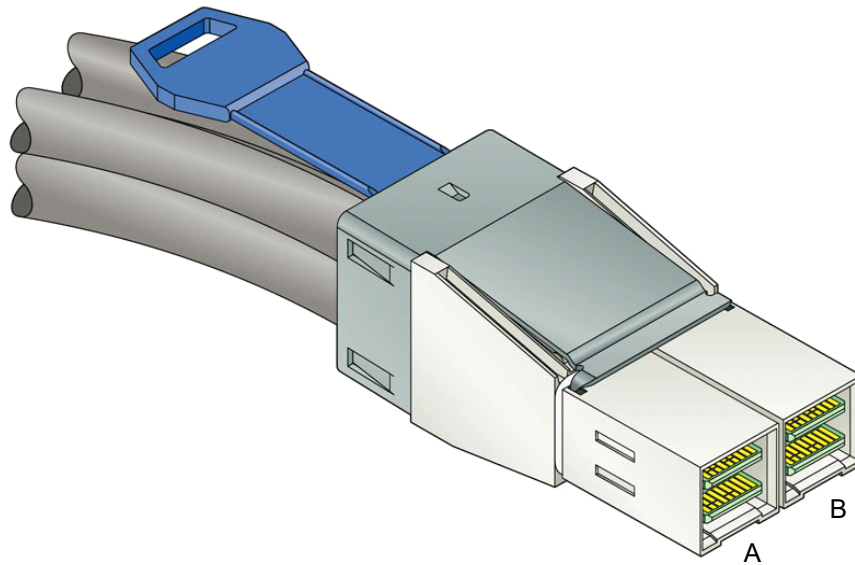


Figure 54 — Mini SAS HD 8x cable plug connector

Table 25 defines the pin assignments for the Mini SAS HD 4x cable plug connector (see 5.4.3.4.1.1). The pin assignments are repeated for each module of the Mini SAS 8x cable plug connector.

5.4.3.4.1.3 Mini SAS HD 4x receptacle connector

The Mini SAS HD 4x receptacle connector is the four-lane receptacle (fixed) connector mechanical interface defined in SFF-8644. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 55 shows the Mini SAS HD 4x receptacle connector.

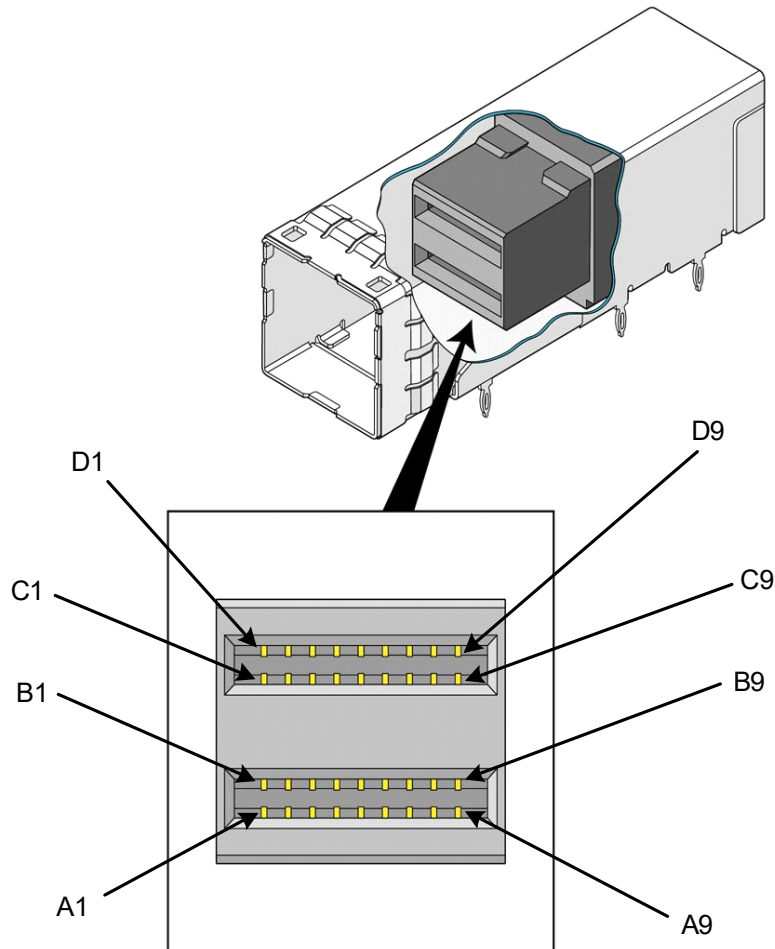


Figure 55 — Mini SAS HD 4x receptacle connector

Table 25 defines the pin assignments for the Mini SAS HD 4x receptacle connector.

5.4.3.4.1.4 Mini SAS HD 8x receptacle connector

The Mini SAS HD 8x receptacle connector is a dual four-lane receptacle (fixed) connector mechanical interface defined in SFF-8644. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 56 shows the Mini SAS HD 8x receptacle connector. This connector is a modular version of the Mini SAS HD 4x receptacle connector (see 5.4.3.4.1.3). Module labeling is shown in figure 56. See figure 55 for pin designations.

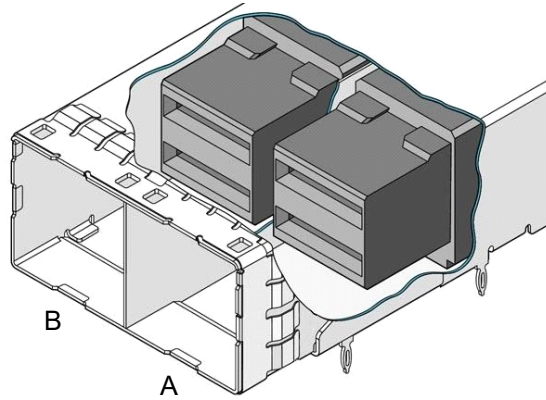


Figure 56 — Mini SAS HD 8x receptacle connector

Table 25 defines the pin assignments for the Mini SAS HD 8x receptacle connector. The connector is a modular design of repeating Mini SAS HD 4x receptacles (see 5.4.3.4.1.3). The Mini SAS HD 8x receptacle connector accepts one Mini SAS HD 8x plug connector (see 5.4.3.4.1.2) or one or two Mini SAS HD 4x plug connectors (see 5.4.3.4.1.1).

5.4.3.4.1.5 Mini SAS HD 16x receptacle connector

The Mini SAS HD 16x receptacle connector is a quad four-lane receptacle (fixed) connector mechanical interface defined in SFF-8644. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 57 shows the Mini SAS HD 16x receptacle connector. This connector is a modular version of the Mini SAS HD 4x receptacle connector (see 5.4.3.4.1.3). Module labeling is shown in figure 57. See figure 55 for pin designations.

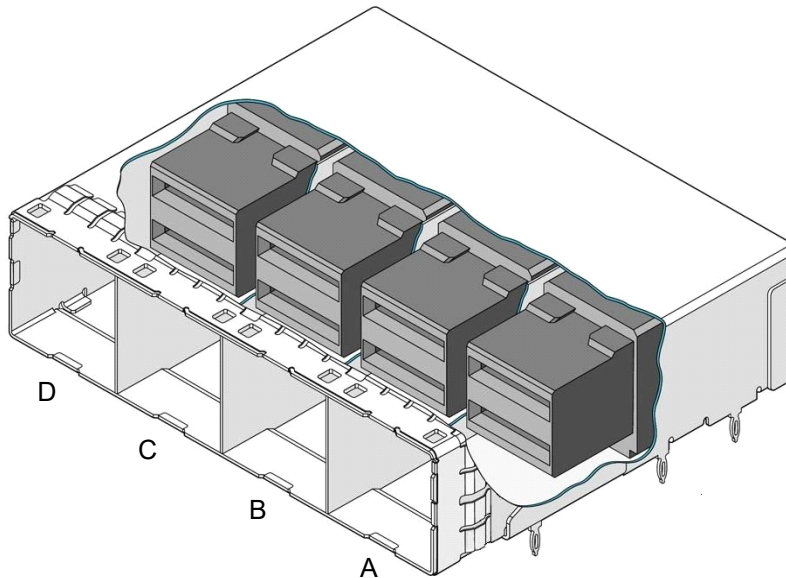


Figure 57 — Mini SAS HD 16x receptacle connector

Table 25 defines the pin assignments for the Mini SAS HD 16x receptacle connector. The connector is a modular design of repeating Mini SAS HD 4x receptacles (see 5.4.3.4.1.3). The Mini SAS HD 16x receptacle connector accepts:

- a) one or two Mini SAS HD 8x cable plug connectors (see 5.4.3.4.1.2);
- b) one, two, three, or four Mini SAS HD 4x cable plug connectors (see 5.4.3.4.1.1); or
- c) a combination of one Mini SAS HD 8x cable plug connector (see 5.4.3.4.1.2) and one or two Mini SAS HD 4x cable plug connectors (see 5.4.3.4.1.1).

A Mini SAS HD 4x cable plug connector (see 5.4.3.4.1.1) may be plugged into module A, module B, module C, or module D. A Mini SAS HD 8x cable plug connectors (see 5.4.3.4.1.2) may be plugged into module A and module B, module B and module C, or module C and module D.

5.4.3.4.1.6 Mini SAS HD 4x connector pin assignments

Table 25 defines the pin assignments for Mini SAS HD 4x cable plug connectors (see 5.4.3.4.1.1) and Mini SAS HD 4x receptacle connectors (see 5.4.3.4.1.3) for controller applications using one, two, three, or four of the physical links.

Table 25 — Mini SAS HD 4x connector pin assignments and physical link usage

Signal	Pin usage based on number of physical links supported by the cable assembly				Mating level ^a
	One	Two	Three	Four	
RX 0-	B5	B5	B5	B5	Third
RX 0+	B4	B4	B4	B4	
RX 1-	N/C	A5	A5	A5	
RX 1+	N/C	A4	A4	A4	
IntL ^b	A2	A2	A2	A2	Second
Reserved ^b	A1	A1	A1	A1	
ModPrsL ^b	B2	B2	B2	B2	
Vact ^b	B1	B1	B1	B1	
RX 2-	N/C	N/C	B8	B8	Third
RX 2+	N/C	N/C	B7	B7	
RX 3-	N/C	N/C	N/C	A8	
RX 3+	N/C	N/C	N/C	A7	
TX 0-	D5	D5	D5	D5	Third
TX 0+	D4	D4	D4	D4	
TX 1-	N/C	C5	C5	C5	
TX 1+	N/C	C4	C4	C4	
SDA ^b	C2	C2	C2	C2	Second
SCL ^b	C1	C1	C1	C1	
Vman ^b	D2	D2	D2	D2	
Vact ^b	D1	D1	D1	D1	
TX 2-	N/C	N/C	D8	D8	Third
TX 2+	N/C	N/C	D7	D7	
TX 3-	N/C	N/C	N/C	C8	
TX 3+	N/C	N/C	N/C	C7	
SIGNAL GROUND	A3, A6, A9, B3, B6, B9, C3, C6, C9, D3, D6, D9				First
^a The mating level indicates the physical dimension of the contact (see SFF-8644).					
^b Table 26 defines the connection requirements of this signal.					

5.4.3.4.1.7 Mini SAS HD external connector management interface

Each 4x module shall include a two-wire serial management interface to:

- a) monitor circuitry residing in the cable assembly;
- b) control circuitry residing in the cable assembly; and
- c) obtain physical characteristics of the cable encoded in a non-volatile storage device located in the cable assembly.

Table 26 defines the connection requirements of the management interface signals. The following connectors shall support the signals in table 26 in each 4x module:

- a) Mini SAS HD 4x receptacle connectors (see 5.4.3.4.1.3);
- b) Mini SAS HD 8x receptacle connectors (see 5.4.3.4.1.4);
- c) Mini SAS HD 16x receptacle connectors (see 5.4.3.4.1.5);
- d) Mini SAS HD 4x cable plug connectors (see 5.4.3.4.1.1); and
- e) Mini SAS HD 8x cable plug connectors (see 5.4.3.4.1.2).

See SFF-8449 and SFF-8636 for a complete signal definition, management interface memory map, and timing diagrams for the two-wire interface.

Table 26 — Management interface connection requirements

Signal	Connection requirements ^a
IntL	Active Low Module Interrupt: This pin shall be connected to Vman (see SFF-8449) on the receptacle side of the management interface. The source of the interrupt may be identified using the two-wire serial management interface. If the cable assembly supports interrupts, then the cable assembly shall assert this pin to indicate an interrupt bit has been set to one in the management interface memory map. If a cable assembly does not support interrupts, then all interrupt bits in the cable management interface memory map shall be set to zero and the cable assembly shall negate this pin (e.g., all interrupt bits of a passive cable assembly may be programmed to a clear state and the IntL pin not connected on the cable plug side of the management interface).
ModPrsL	Active Low Module Present: On the cable plug side of the management interface, ModPrsL shall be connected directly to the signal ground pins specified in table 25. ModPrsL shall be connected to Vman (see SFF-8449) on the receptacle side of the management interface to negate this signal when the plug is not fully mated to the receptacle.
Reserved	This pin shall be not connected on the receptacle side and cable plug side of the management interface.
SCL	Two-wire interface clock: The receptacle side of the management interface shall connect this signal to Vman (see SFF-8449).
SDA	Two-wire interface data: The receptacle side of the management interface shall connect this signal to Vman (see SFF-8449).
Vact	Active cable power: If the receptacle side of the management interface supports active cable assemblies, then it shall provide all non-management interface power to the cable assembly on the Vact pins. To support equal loading, both Vact pins shall be connected together on the receptacle side of the management interface. If the receptacle side of the management interface does not support active cable assemblies, then the Vact pins should be not connected.
Vman	Management interface power: The receptacle side of the management interface shall provide power on the Vman pin to enable the management interface circuitry of the cable. Power may be removed to reset the management circuitry in the cable assembly.
^a Electrical characteristics are defined in SFF-8449.	

5.4.3.4.1.8 Mini SAS HD external connector memory map

SFF-8636 defines the Mini SAS HD external connector management interface memory map. The Mini SAS HD external cable assembly shall support the following management interface memory map registers:

- a) supported SAS baud rate;
- b) vendor name;
- c) vendor part number;
- d) vendor revision;
- e) copper cable attenuation;
- f) power class;
- g) minimum operating voltage;
- h) transmitter technology;
- i) cable width; and
- j) propagation delay.

5.4.3.4.2 QSFP connectors

5.4.3.4.2.1 QSFP cable plug

The QSFP cable plug connector is the free (plug) 38-circuit connector mechanical interface defined in SFF-8662 and SFF-8672. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 58 shows the QSFP cable plug connector.

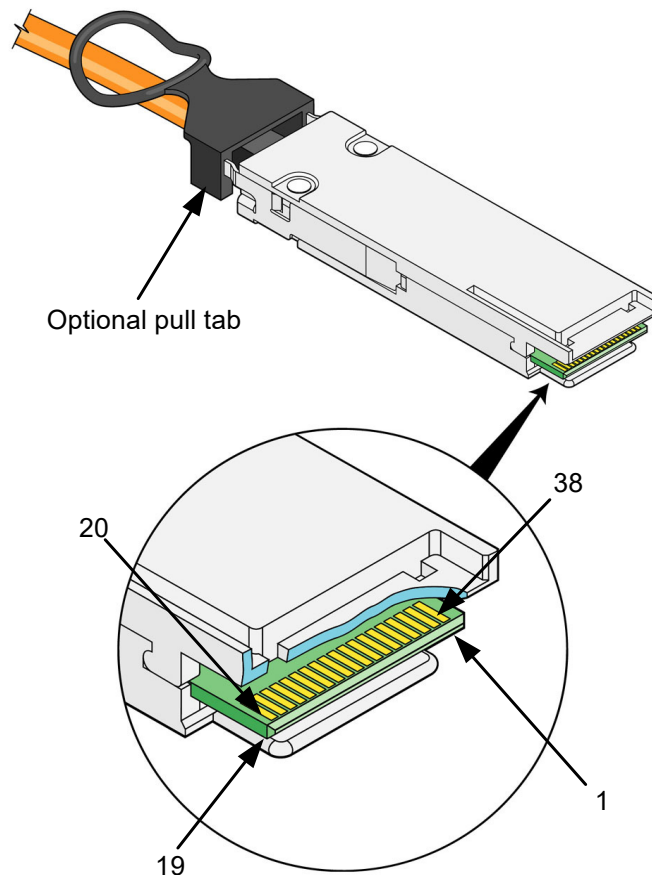


Figure 58 — QSFP cable plug connector

Table 27 defines the pin assignments for the QSFP cable plug connector.

The QSFP cable plug connectors shall not include keying except for orientation.

5.4.3.4.2.2 QSFP receptacle

The QSFP receptacle connector is the fixed (receptacle) 38-circuit connector mechanical interface defined in SFF-8662 and SFF-8672. The recommended electrical performance limits for mated connector pairs supporting rates of 22.5 Gbit/s are defined in Annex J.

Figure 59 shows the QSFP receptacle connector.

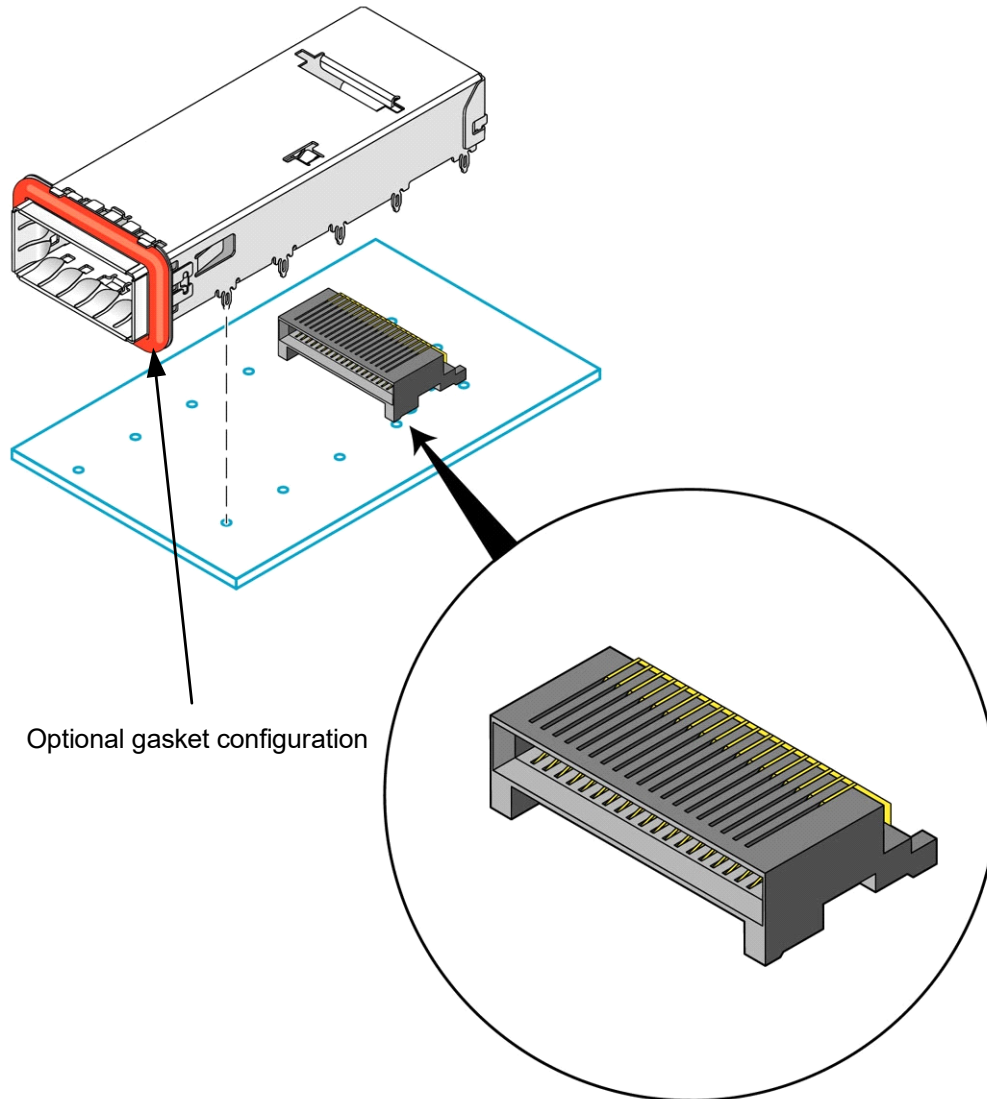


Figure 59 — QSFP receptacle connector

Table 27 defines the pin assignments for the QSFP receptacle connector.

The QSFP receptacle connectors shall not include keying except for orientation.

5.4.3.4.2.3 QSFP connector pin assignments

Table 27 defines the pin assignments for QSFP connectors (see 5.4.3.4.2.1 and 5.4.3.4.2.2). Specific pins are used to provide managed cable communication and power to the cable assembly.

Table 27 — QSFP connector pin assignments (part 1 of 2)

Pin	Signal	Description	Mating level ^a
1	GND ^b	Ground	First
2	Tx2n	Transmitter inverted data input	Third
3	Tx2p	Transmitter non-inverted data input	Third
4	GND ^b	Ground	First
5	Tx4n	Transmitter inverted data input	Third
6	Tx4p	Transmitter non-inverted data input	Third
7	GND ^b	Ground	First
8	ModSelL	Module select	Third
9	ResetL	Module reset	Third
10	Vcc Rx ^c	+3.3 V power supply receiver	Second
11	SCL	two-wire serial interface clock	Third
12	SDA	two-wire serial interface data	Third
13	GND ^b	Ground	First
14	Rx3p	Receiver non-inverted data output	Third
15	Rx3n	Receiver inverted data output	Third
16	GND ^b	Ground	First
17	Rx1p	Receiver non-inverted data output	Third
18	Rx1n	Receiver inverted data output	Third
19	GND ^b	Ground	First
20	GND ^b	Ground	First
21	Rx2n	Receiver inverted data output	Third
22	Rx2p	Receiver non-inverted data output	Third
23	GND ^b	Ground	First
24	Rx4n	Receiver inverted data output	Third
25	Rx4p	Receiver non-inverted data output	Third
26	GND ^b	Ground	First
27	ModPrsL	Module present	Third

^a The mating level indicates the physical dimension of the contact. See SFF-8662 and SFF-8672.

^b GND is the symbol for signal ground and power ground for QSFP. Signal ground and power ground are common within the QSFP cable connector and all voltages are referenced to this ground unless otherwise specified. Signal ground and power ground shall be connected directly to the host board signal ground.

^c Power shall be applied concurrently to Vcc Rx, Vcc1, and Vcc Tx. Within the QSFP cable connector, Vcc Rx, Vcc1, and Vcc Tx may be connected in any combination.

Table 27 — QSFP connector pin assignments (part 2 of 2)

Pin	Signal	Description	Mating level ^a
28	IntL	Interrupt	Third
29	Vcc Tx ^c	+3.3 V power supply transmitter	Second
30	Vcc1 ^c	+3.3 V power supply	Second
31	LPMode	Low power mode	Third
32	GND ^b	Ground	First
33	Tx3p	Transmitter non-inverted data input	Third
34	Tx3n	Transmitter inverted data input	Third
35	GND ^b	Ground	First
36	Tx1p	Transmitter non-inverted data input	Third
37	Tx1n	Transmitter inverted data input	Third
38	GND ^b	Ground	First
^a The mating level indicates the physical dimension of the contact. See SFF-8662 and SFF-8672. ^b GND is the symbol for signal ground and power ground for QSFP. Signal ground and power ground are common within the QSFP cable connector and all voltages are referenced to this ground unless otherwise specified. Signal ground and power ground shall be connected directly to the host board signal ground. ^c Power shall be applied concurrently to Vcc Rx, Vcc1, and Vcc Tx. Within the QSFP cable connector, Vcc Rx, Vcc1, and Vcc Tx may be connected in any combination.			

5.4.3.4.2.4 QSFP memory map

The memory map for QSFP is used for identification information, cable characteristics, control functions, and digital monitoring. The two-wire serial interface is required for all QSFP devices. SFF-8636 defines the supported SAS baud rate codes. See SFF-8636 for register map details and the operation of the two-wire serial interface.

5.4.4 Cable assemblies

5.4.4.1 SAS internal cable assemblies

5.4.4.1.1 SAS Drive cable assemblies

A SAS Drive cable assembly is either:

- a) a single-port SAS Drive cable assembly;
- b) a dual-port SAS Drive cable assembly; or
- c) a MultiLink SAS Drive cable assembly.

A SAS single-port Drive cable assembly or SAS dual-port Drive cable assembly has:

- a) a SAS Drive cable connector (see 5.4.3.3.1.2) on the SAS target device end; and
- b) a SATA signal cable receptacle connector (see SATA) on the SAS initiator device or expander device end (see SPL-5).

A SAS MultiLink Drive cable assembly has:

- a) a SAS MultiLink Drive cable connector (see 5.4.3.3.1.2) on the SAS target device end; and
- b) a SATA signal cable receptacle connector (see SATA) on the SAS initiator device or expander device end (see SPL-5).

The power, READY LED, and POWER DISABLE signal connection is vendor specific.

A SAS initiator device shall use a SATA host plug connector (see SATA) for connection to a SAS Drive cable assembly. The signal assignment for the SAS initiator device or expander device (see SPL-5) with this connector shall be the same as that defined for a SATA host (see SATA).

Figure 60 shows the Single-port SAS Drive cable assembly.

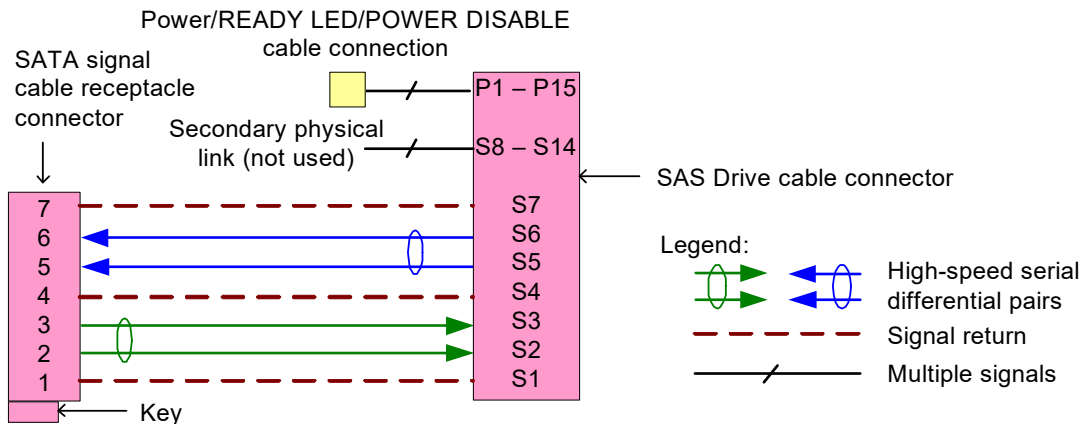


Figure 60 — Single-port SAS Drive cable assembly

Figure 61 shows the Dual-port SAS Drive cable assembly.

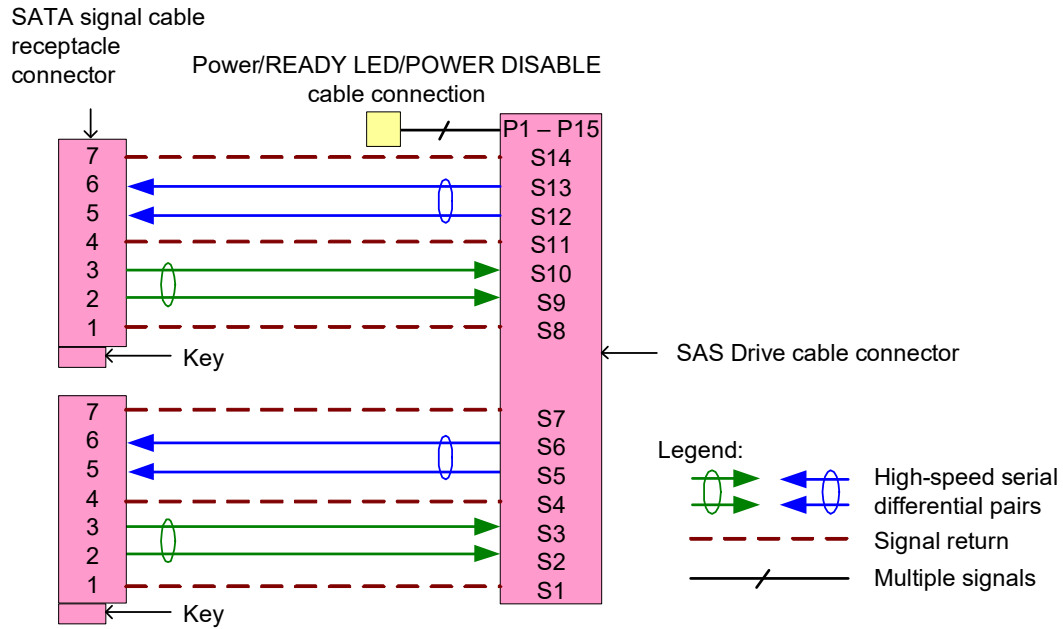


Figure 61 — Dual-port SAS Drive cable assembly

Figure 62 shows the MultiLink SAS Drive cable assembly.

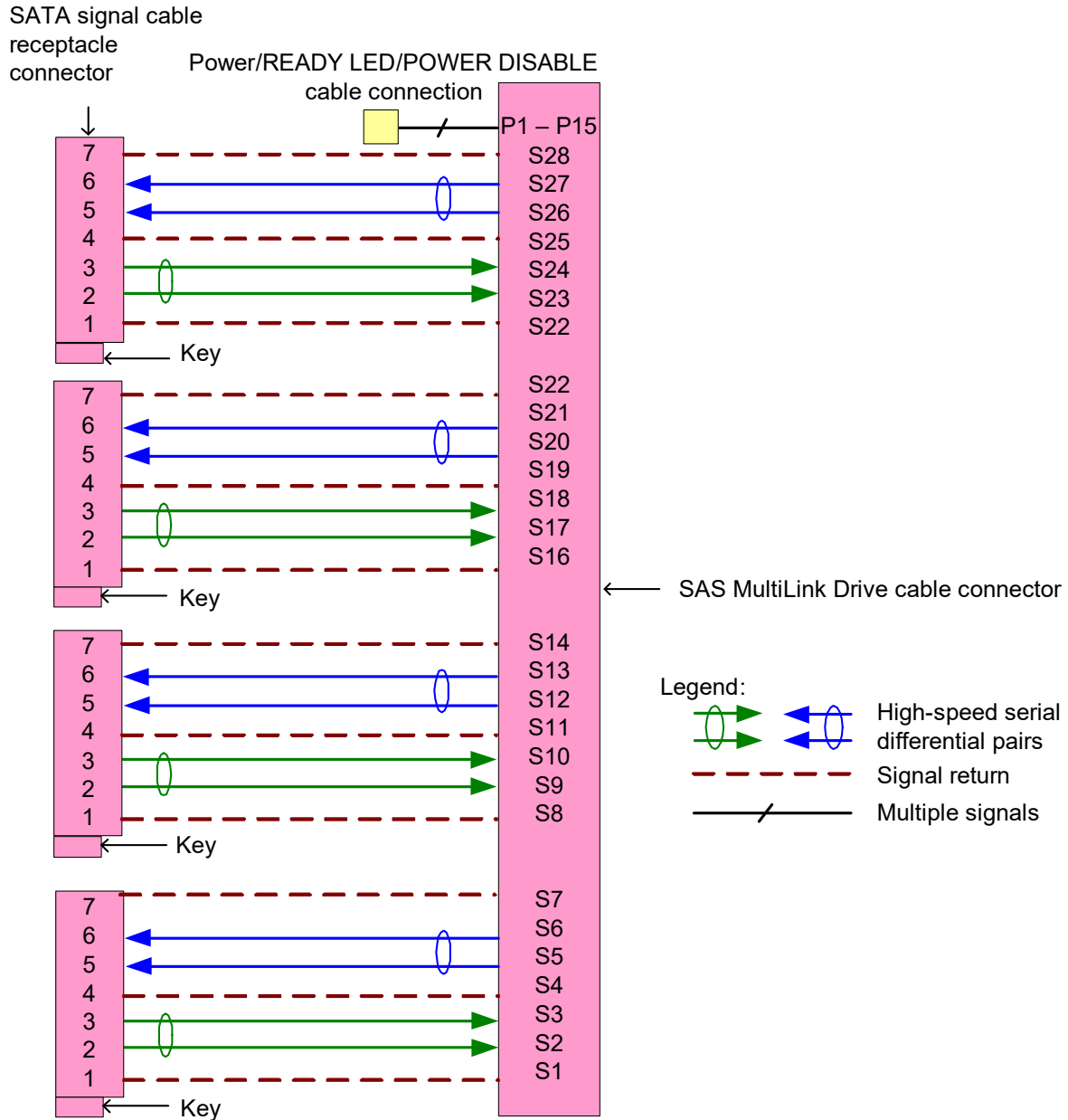


Figure 62 — MultiLink SAS Drive cable assembly

5.4.4.1.2 SAS internal symmetric cable assemblies

5.4.4.1.2.1 SAS internal symmetric cable assemblies overview

A SAS internal symmetric cable assembly has:

- a) a Mini SAS HD 4i cable plug connector (see 5.4.3.3.2.1) on each end (see 5.4.4.1.2.2);
- b) a Mini SAS HD 8i cable plug connector (see 5.4.3.3.2.2) on each end (see 5.4.4.1.2.3);
- c) a SlimSAS 4i cable plug connector (see 5.4.3.3.3.1) on each end (see 5.4.4.1.2.4);
- d) a SlimSAS 4i cable plug connector (see 5.4.3.3.3.1) on one end and a Mini SAS HD 4i cable plug connector (see 5.4.3.3.2.1) on the other end (see 5.4.4.1.2.5); a SlimSAS 8i cable plug connector (see 5.4.3.3.3.2) on each end (see 5.4.4.1.2.6);
- e) a SlimSAS 8i cable plug connector (see 5.4.3.3.3.2) on one end and a Mini SAS HD 8i cable plug connector (see 5.4.3.3.2.2) on the other end (see 5.4.4.1.2.7);
- f) a SAS MiniLink 4i cable plug connector (see 5.4.3.3.3.1) on each end (see 5.4.4.1.2.8);
- g) a SAS MiniLink 4i cable plug connector (see 5.4.3.3.3.1) on one end and a Mini SAS HD 4i cable plug connector (see 5.4.3.3.2.1) on the other end (see 5.4.4.1.2.9); a SAS MiniLink 8i cable plug connector (see 5.4.3.3.3.2) on each end (see 5.4.4.1.2.10); or
- h) a SAS MiniLink 8i cable plug connector (see 5.4.3.3.3.2) on one end and a Mini SAS HD 8i cable plug connector (see 5.4.3.3.2.2) on the other end (see 5.4.4.1.2.11).

In a SAS internal symmetric cable assembly, the TX signals on one end shall be connected to RX signals on the other end (e.g., a TX+ of one connector shall connect to an RX+ of the other connector). SAS internal symmetric cable assemblies should be labeled to indicate how many physical links are included (e.g., 1X, 2X, 3X, and 4X on each connector's housing).

In addition to the signal return connections shown in the figures, one or more of the signal returns may be connected together in the cable assemblies.

For controller-to-backplane applications, SIDEBAND signals on the controller are attached to the corresponding SIDEBAND signals on the backplane (e.g., SIDEBAND 0 of the controller is attached to SIDEBAND 0 of the backplane) on cable assemblies that have the same type of connector on each end. If the cable assembly has different connector types on each end, then the applicable pin assignment tables in 5.4.3.3 may require different signal connections than shown in the figures to attach the corresponding SIDEBAND signals, depending on the connector type that is connected to the controller. The SIDEBAND + and SIDEBAND - signals are not supported on the Mini SAS HD 4i cable plug connector (see 5.4.3.3.2.1) or the Mini SAS HD 8i cable plug connector (see 5.4.3.3.2.2).

For controller-to-controller applications, SIDEBAND signals on one controller are not attached to their corresponding SIDEBAND signals on the other controller (e.g., SIDEBAND 0 of one controller is attached to SIDEBAND 7 of the other controller). The SIDEBAND 8 signal and SIDEBAND 9 signal are not supported on the Mini SAS HD 4i cable plug connector (see 5.4.3.3.2.1) or the Mini SAS HD 8i cable plug connector (see 5.4.3.3.2.2).

There are multiple applications for these cable assemblies that involve interfaces other than SAS. SFF-9402 provides a reference for signal assignment of SAS and PCIe for specific cable assemblies defined in this standard. For compatibility of SIDEBAND signals, recommended SIDEBAND signal pin assignment information is provided in SFF-8448.

5.4.4.1.2.2 SAS internal symmetric cable assembly - Mini SAS HD 4i

Figure 63 shows the SAS internal cable assembly with Mini SAS HD 4i cable plug connectors at each end.

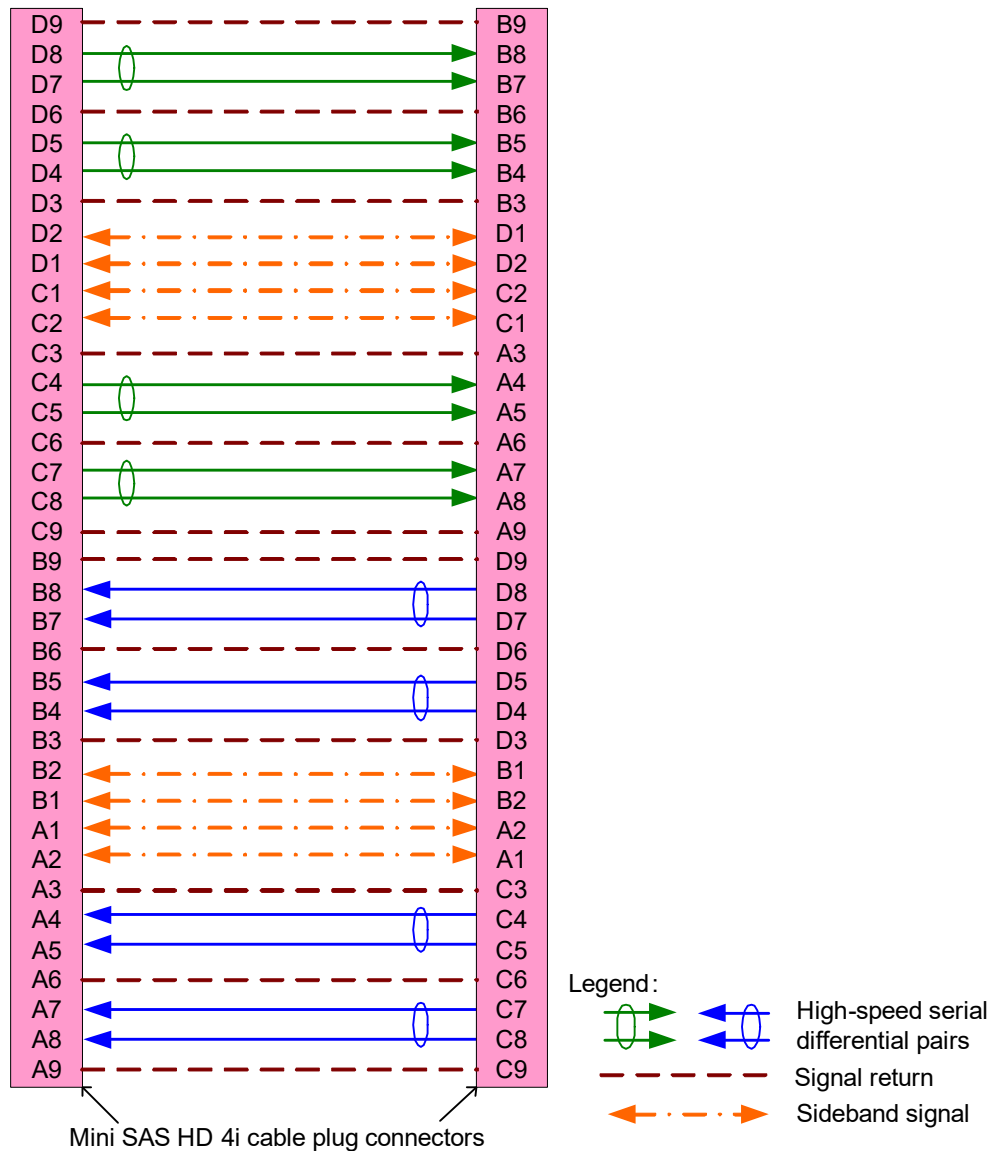


Figure 63 — SAS internal symmetric cable assembly - Mini SAS HD 4i

This cable assembly may support one to four physical links.

5.4.4.1.2.3 SAS internal symmetric cable assembly - Mini SAS HD 8i

Figure 64 shows the SAS internal cable assembly with Mini SAS HD 8i cable plug connectors at each end.

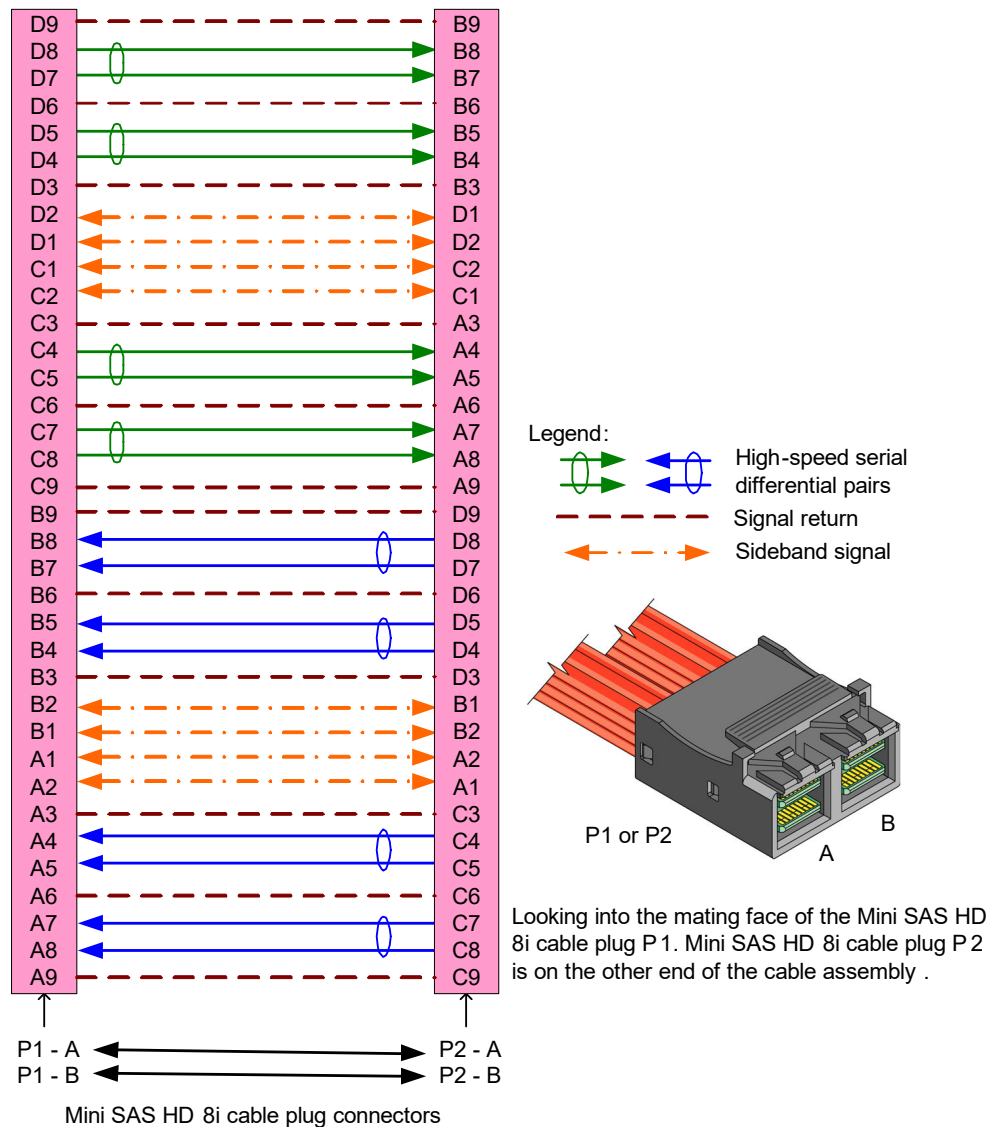


Figure 64 — SAS internal symmetric cable assembly - Mini SAS HD 8i

This cable assembly may support one to eight physical links. If less than eight physical links are supported, then module A shall be populated first, followed by module B (e.g., if six physical links are supported, then module A has four physical links connected and module B has two physical links connected). See 5.4.3.3.2.6 for connector module pin assignments.

5.4.4.1.2.4 SAS internal symmetric cable assembly - SlimSAS 4i

Figure 65 shows the SAS internal cable assembly with SlimSAS 4i cable plug connectors at each end.

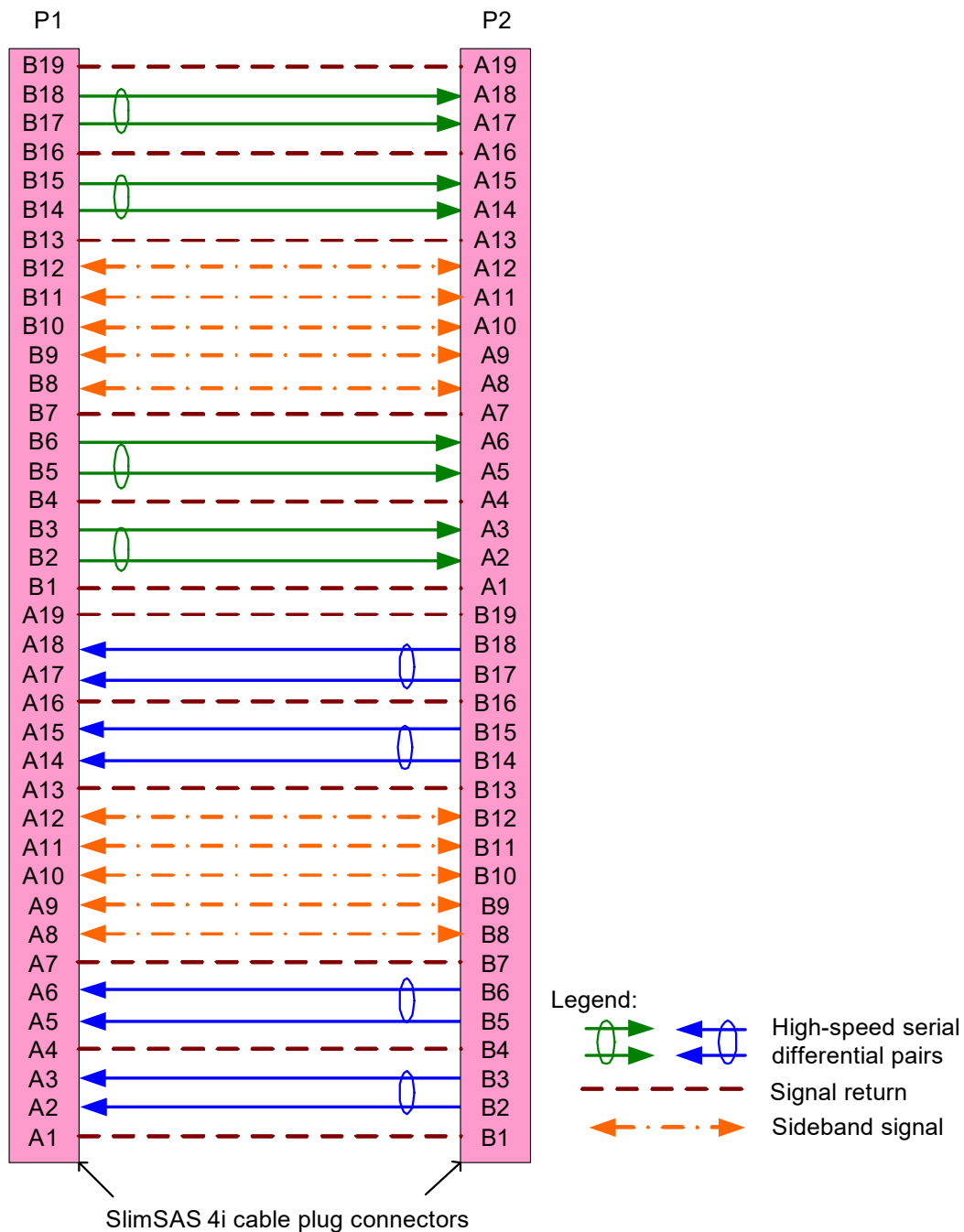


Figure 65 — SAS internal symmetric cable assembly - SlimSAS 4i

This cable assembly may support one to four physical links.

5.4.4.1.2.5 SAS internal symmetric cable assembly - SlimSAS 4i to Mini SAS HD 4i

Figure 66 shows the SAS internal cable assembly with a SlimSAS 4i cable plug connector on one end and a Mini SAS HD 4i cable plug connector on the other end.

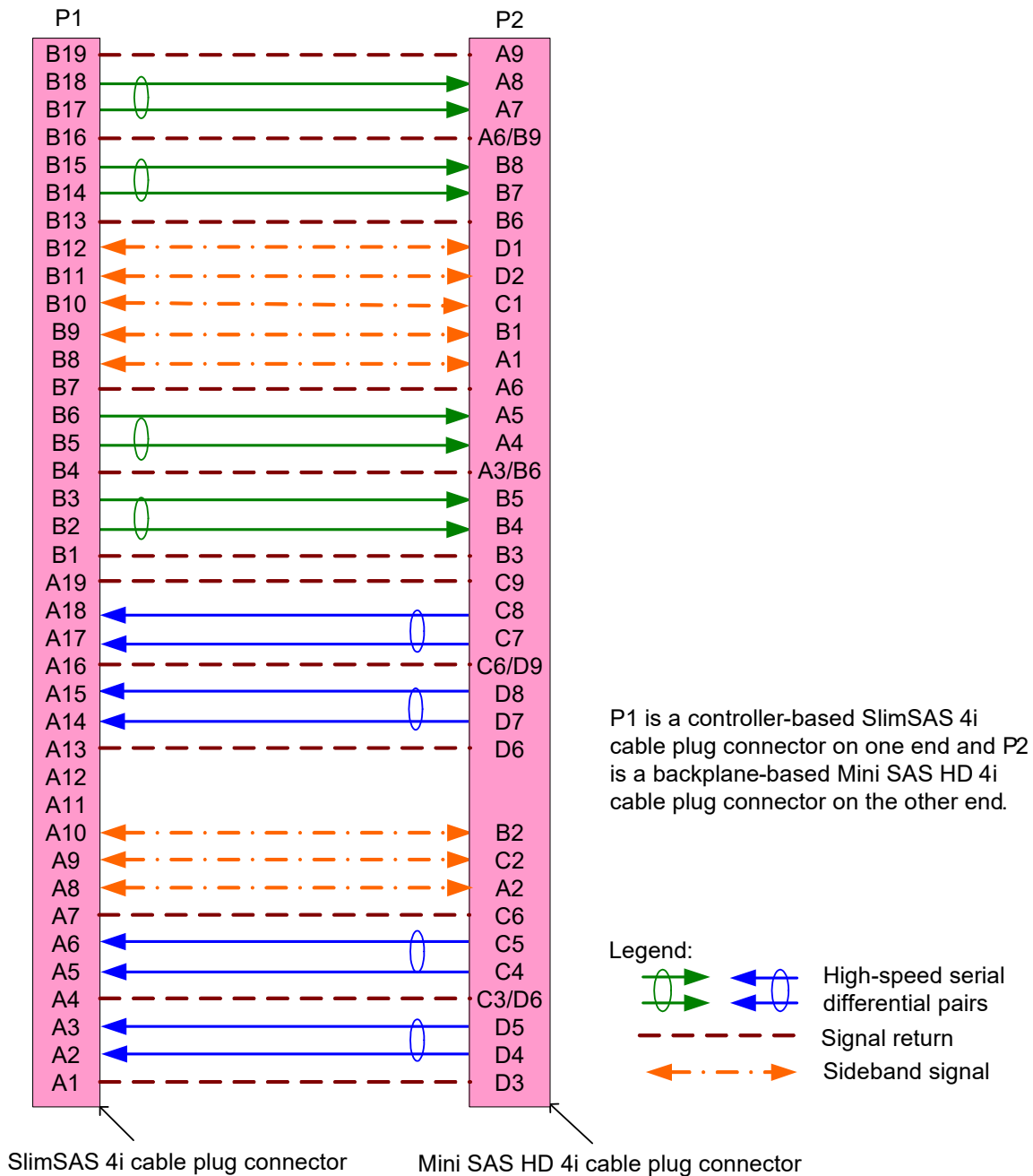


Figure 66 — SAS internal symmetric cable assembly - SlimSAS 4i to Mini SAS HD 4i

This cable assembly may support one to four physical links.

5.4.4.1.2.6 SAS internal symmetric cable assembly - SlimSAS 8i

Figure 67 shows the SAS internal cable assembly with SlimSAS 8i cable plug connectors at each end.

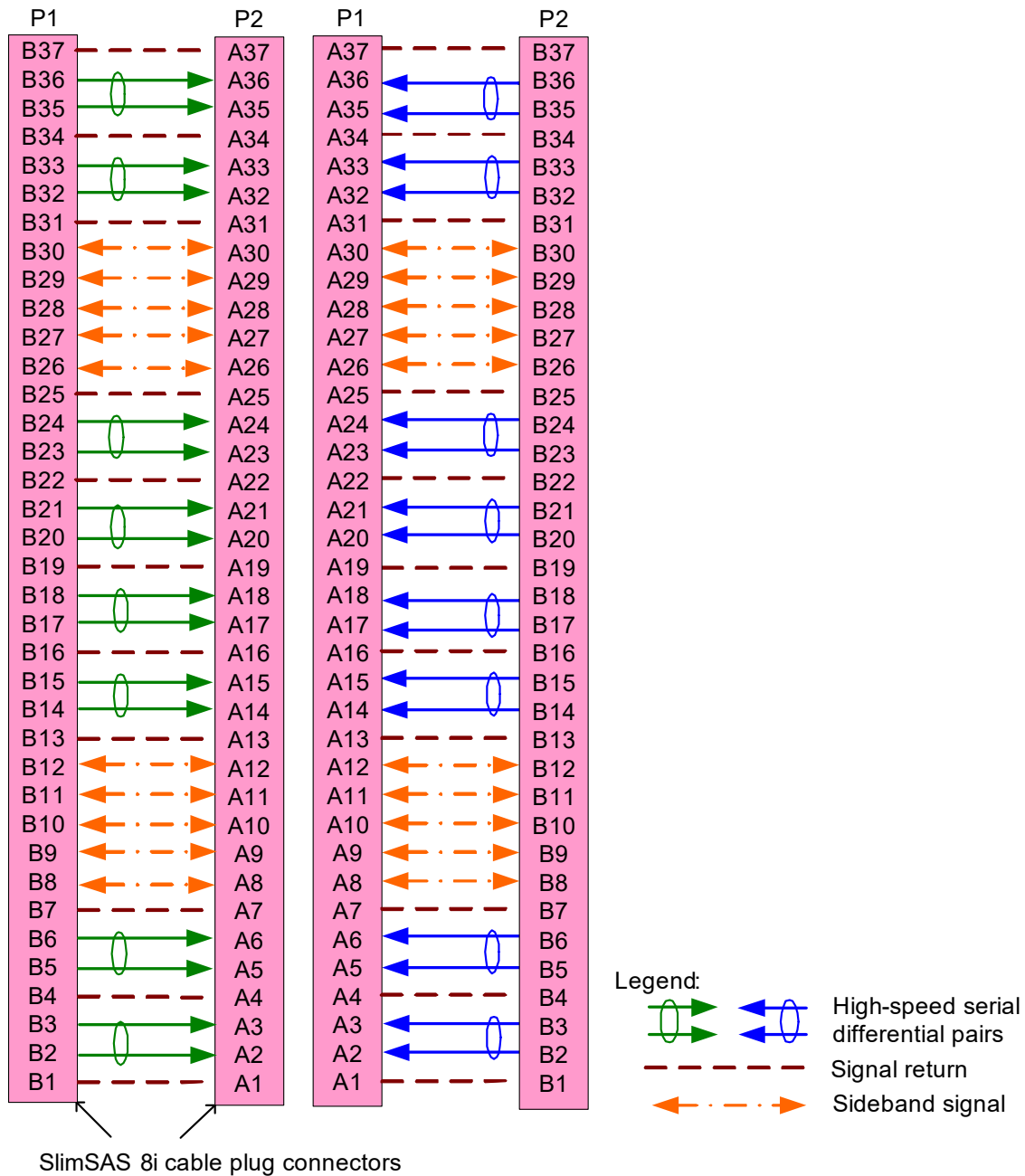


Figure 67 — SAS internal symmetric cable assembly - SlimSAS 8i

This cable assembly may support one to eight physical links.

5.4.4.1.2.7 SAS internal symmetric cable assembly - SlimSAS 8i to Mini SAS HD 8i

Figure 68 shows the SAS internal cable assembly with a SlimSAS 8i cable plug connector on one end and a Mini SAS HD 8i cable plug connector on the other end.

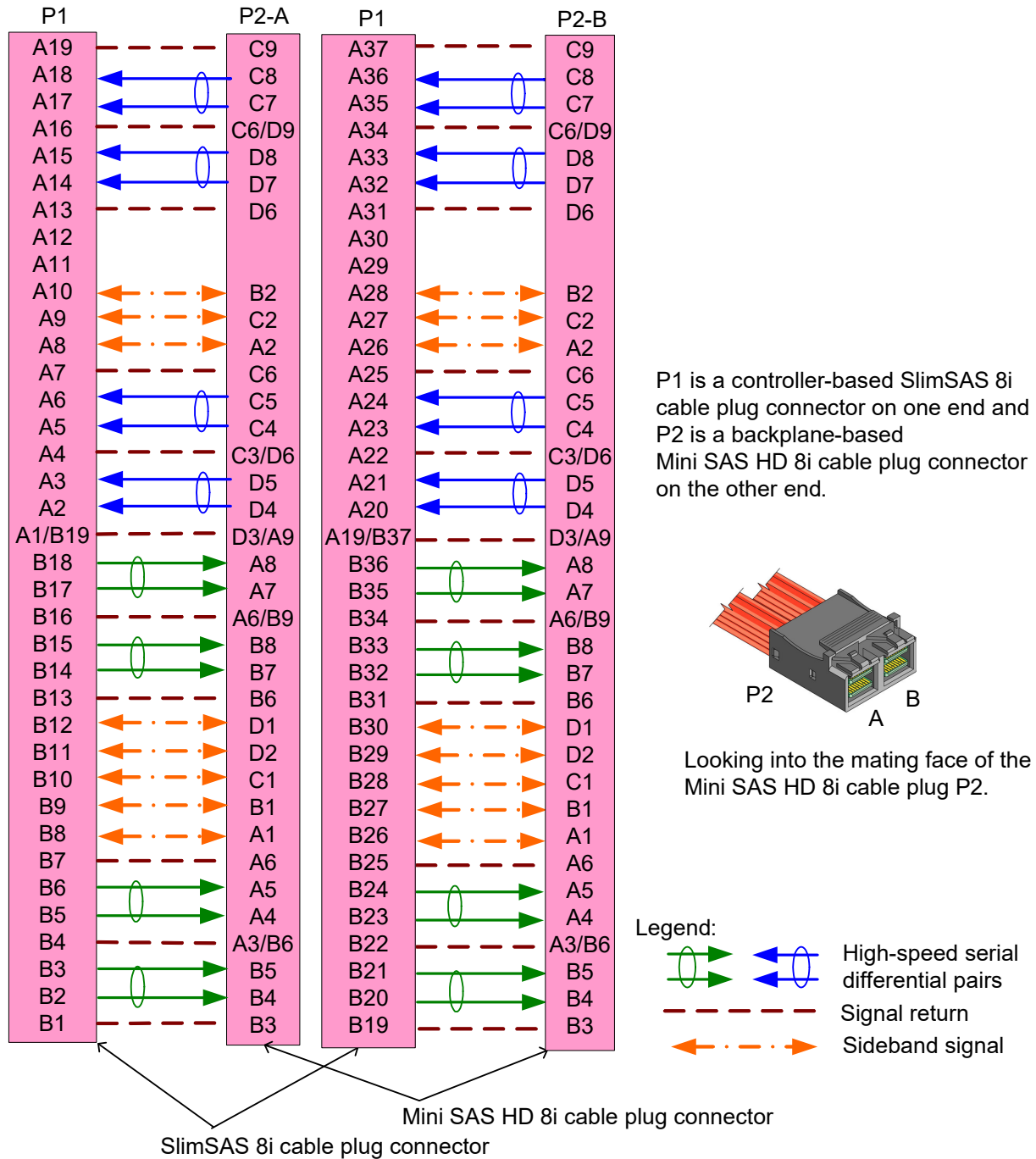


Figure 68 — SAS internal symmetric cable assembly - SlimSAS 8i to Mini SAS HD 8i

This cable assembly may support one to eight physical links.

5.4.4.1.2.8 SAS internal symmetric cable assembly - SAS MiniLink 4i

Figure 69 shows the SAS internal cable assembly with SAS MiniLink 4i cable plug connectors at each end.

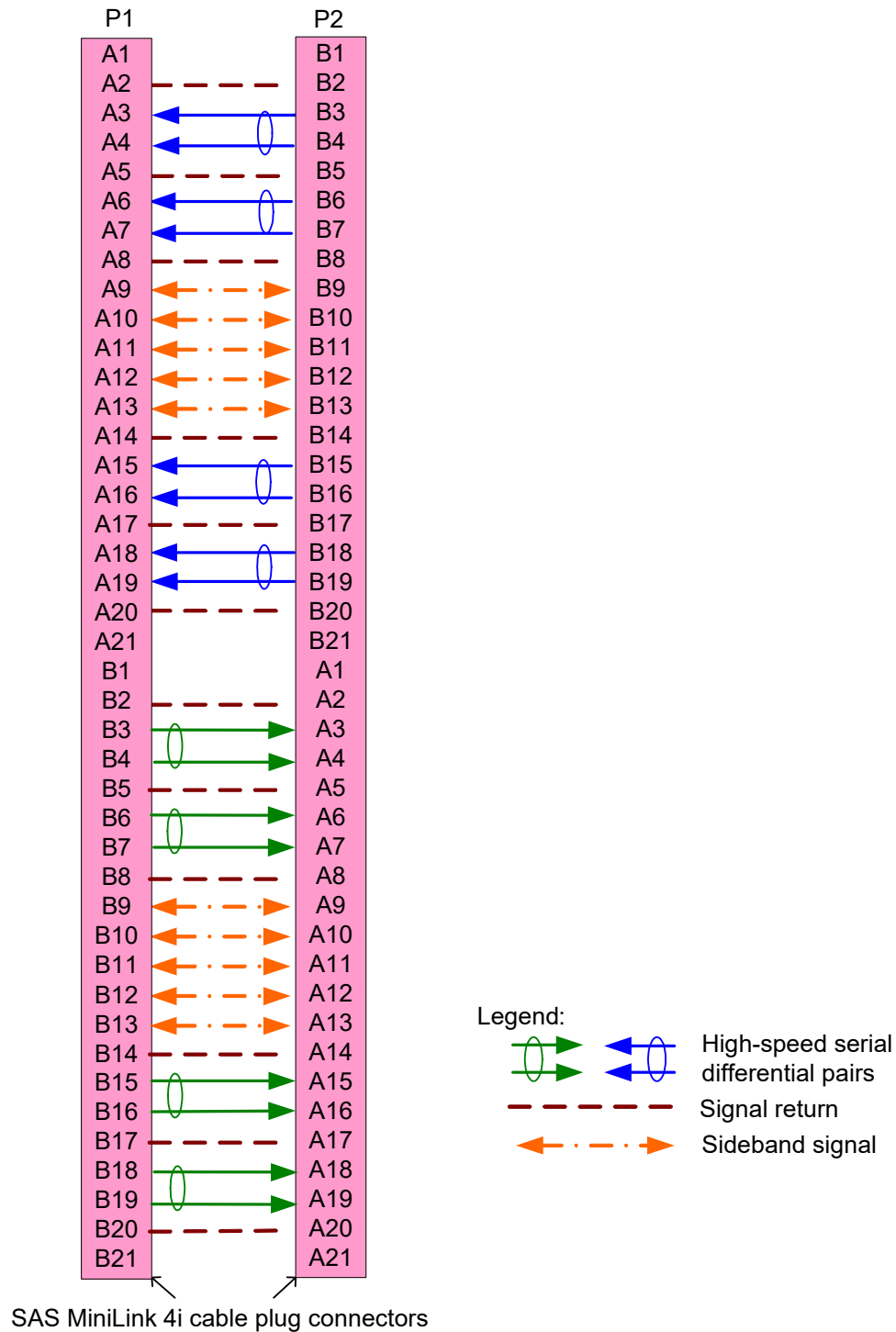


Figure 69 — SAS internal symmetric cable assembly - SAS MiniLink 4i

This cable assembly may support one to four physical links.

5.4.4.1.2.9 SAS internal symmetric cable assembly - SAS MiniLink 4i to Mini SAS HD 4i

Figure 70 shows the SAS internal cable assembly with a SAS MiniLink 4i cable plug connector on one end and a Mini SAS HD 4i cable plug connector on the other end.

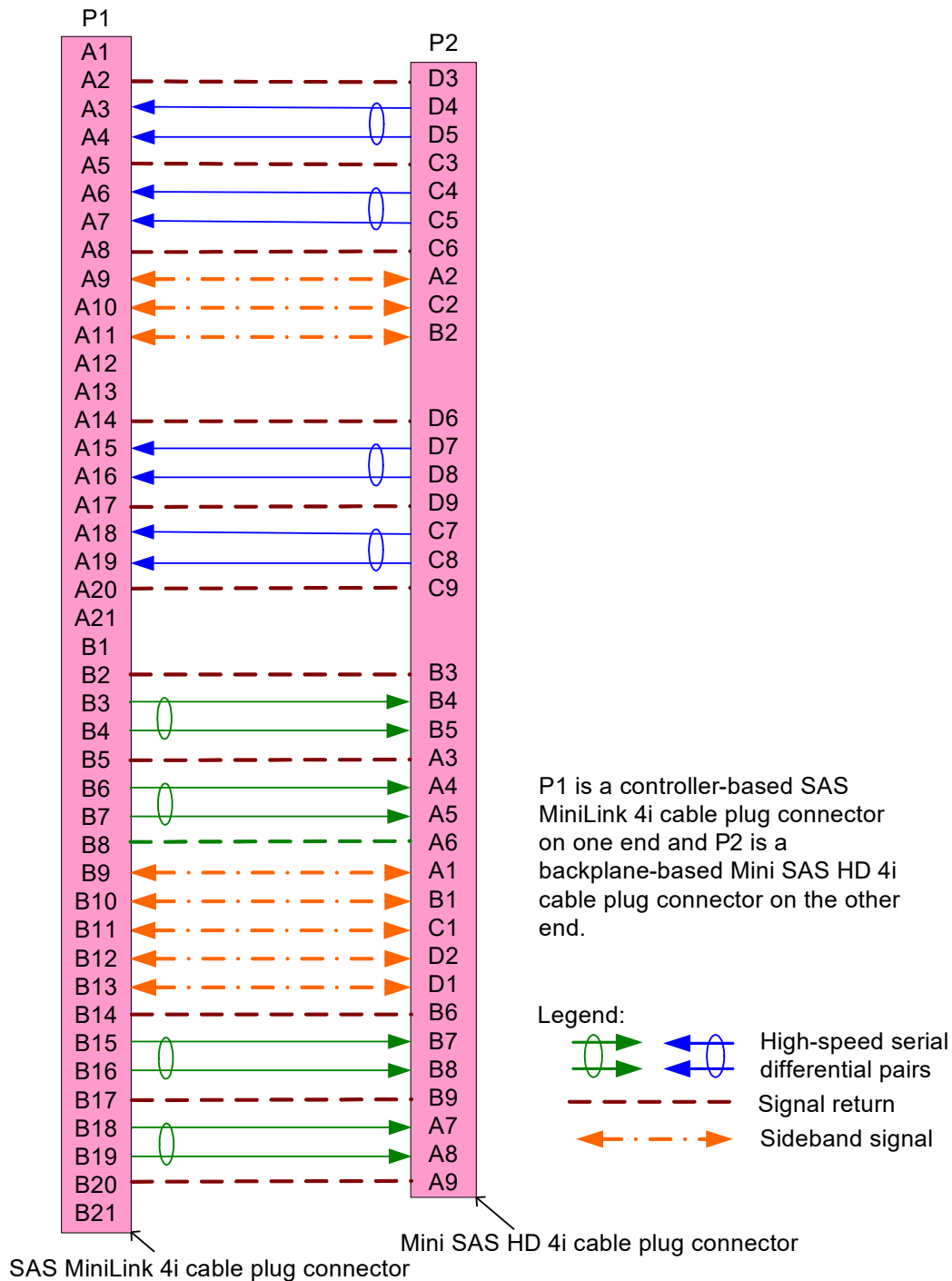


Figure 70 — SAS internal symmetric cable assembly - SAS MiniLink 4i to Mini SAS HD 4i

This cable assembly may support one to four physical links.

5.4.4.1.2.10 SAS internal symmetric cable assembly - SAS MiniLink 8i

Figure 71 shows the SAS internal cable assembly with SAS MiniLink 8i cable plug connectors at each end.

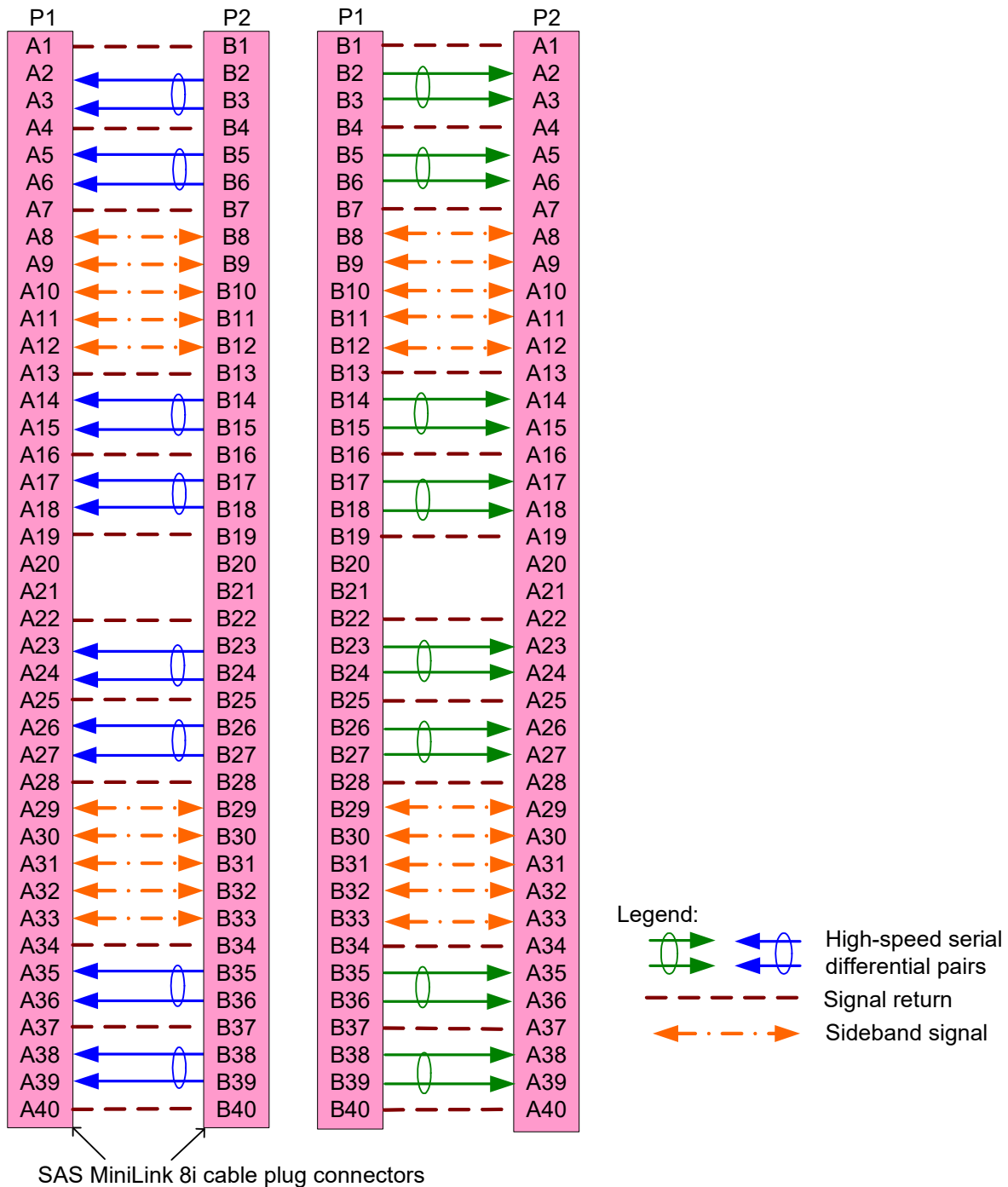


Figure 71 — SAS internal symmetric cable assembly - SAS MiniLink 8i

This cable assembly may support one to eight physical links.

5.4.4.1.2.11 SAS internal symmetric cable assembly - SAS MiniLink 8i to Mini SAS HD 8i

Figure 72 shows the SAS internal cable assembly with a SAS MiniLink 8i cable plug connector on one end and a Mini SAS HD 8i cable plug connector on the other end.

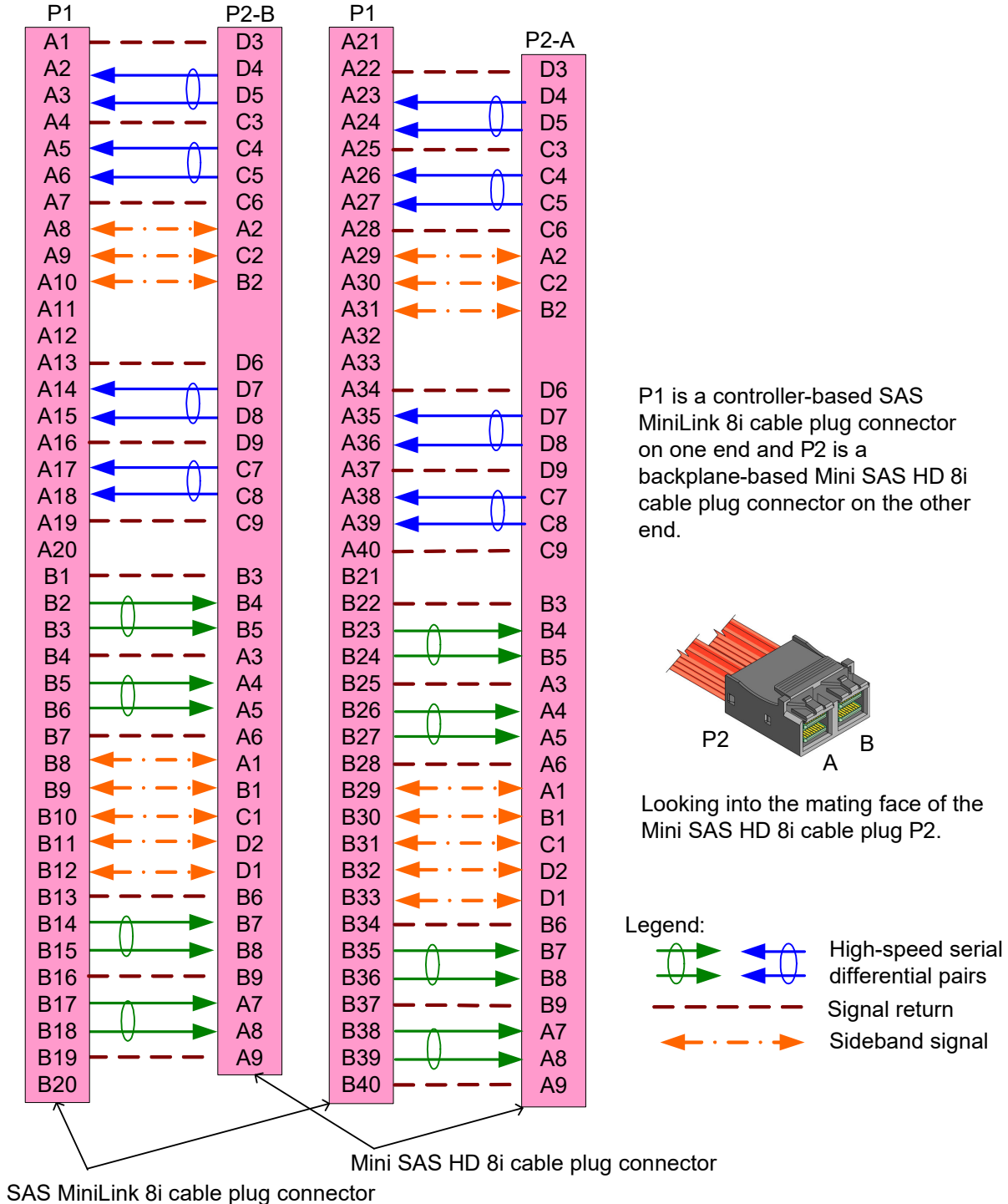


Figure 72 — SAS internal symmetric cable assembly - SAS MiniLink 8i to Mini SAS HD 8i

This cable assembly may support one to eight physical links.

5.4.4.1.3 SAS internal fanout cable assemblies

5.4.4.1.3.1 SAS internal fanout cable assemblies overview

A SAS internal fanout cable assembly is either:

- a) a SAS internal controller-based fanout cable assembly with:
 - A) a Mini SAS HD 4i cable plug connector on one end (i.e., the controller end) and four SAS Drive cable connectors on the other end (see 5.4.4.1.3.2);
 - B) a SlimSAS 4i cable plug connector on one end (i.e., the controller end) and four SAS Drive cable connectors on the other end (see 5.4.4.1.3.3);
 - C) a SlimSAS 4i cable plug connector on one end and four SATA signal cable receptacle connectors on the other end (see 5.4.4.1.3.4);
 - D) a SlimSAS 8i cable plug connector (see 5.4.3.3.2) on one end and two SlimSAS 4i cable plug connectors (see 5.4.3.3.1) on the other end (see 5.4.4.1.3.5);
 - E) a SlimSAS 8i cable plug connector (see 5.4.3.3.2) on one end and two Mini SAS HD 4i cable plug connectors (see 5.4.3.3.1) on the other end (see 5.4.4.1.3.6);
 - F) a SAS MiniLink 4i cable plug connector on one end and four SAS Drive cable connectors on the other end (see 5.4.4.1.3.7);
 - G) a SAS MiniLink 4i cable plug connector on one end and four SATA signal cable receptacle connectors on the other end (see 5.4.4.1.3.8);
 - H) a SAS MiniLink 8i cable plug connector (see 5.4.3.3.2) on one end and two SAS MiniLink 4i cable plug connectors (see 5.4.3.3.1) on the other end (see 5.4.4.1.3.9); or
 - I) a SAS MiniLink 8i cable plug connector (see 5.4.3.3.2) on one end and two Mini SAS HD 4i cable plug connectors (see 5.4.3.3.1) on the other end (see 5.4.4.1.3.10);

or

- A) a SAS internal backplane-based fanout cable assembly with four SATA signal cable receptacle connectors on one end (i.e., the controller end) and a Mini SAS HD 4i cable plug connector on the other end (i.e., the backplane end) (see 5.4.4.1.3.11).

In a SAS internal fanout symmetric cable assembly, the TX signals on one end shall be connected to RX signals on the other end (e.g., a TX+ of one connector shall connect to an RX+ of the other connector).

Each signal return on one end of the cable assembly shall be connected to at least one signal return on the other end of the cable assembly. One or more of the signal returns may be connected together in the cable assembly.

For controller-to-backplane applications, SIDEBAND signals on the controller are attached to the corresponding SIDEBAND signals on the backplane (e.g., SIDEBAND 0 of the controller is attached to SIDEBAND 0 of the backplane) on cable assemblies that have the same type of connector on each end. If the cable assembly has different connector types on each end, then the applicable pin assignment tables in 5.4.3.3 may require different signal connections than shown in the figures to attach the corresponding SIDEBAND signals, depending on the connector type that is connected to the controller. The SIDEBAND + and SIDEBAND - signals are not supported on the Mini SAS HD 4i cable plug connector (see 5.4.3.3.2.1) or the Mini SAS HD 8i cable plug connector (see 5.4.3.3.2.2). No sidebands are supported on the SAS Drive cable receptacle connector or the SATA signal cable receptacle connector.

For controller-to-controller applications, SIDEBAND signals on one controller are not attached to their corresponding SIDEBAND signals on the other controller (e.g., SIDEBAND 0 of one controller is attached to SIDEBAND 7 of the other controller). The SIDEBAND 8 signal and SIDEBAND 9 signal are not supported on the Mini SAS HD 4i cable plug connector (see 5.4.3.3.2.1) or the Mini SAS HD 8i cable plug connector (see 5.4.3.3.2.2). No sidebands are supported on the SAS Drive cable receptacle connector or the SATA signal cable receptacle connector.

5.4.4.1.3.2 SAS internal controller-based fanout cable assembly - Mini SAS HD 4i to SAS Drive

Figure 73 shows the SAS internal controller-based fanout cable assembly with a Mini SAS HD 4i cable plug connector at the controller end and four SAS Drive cable connectors on the other end.

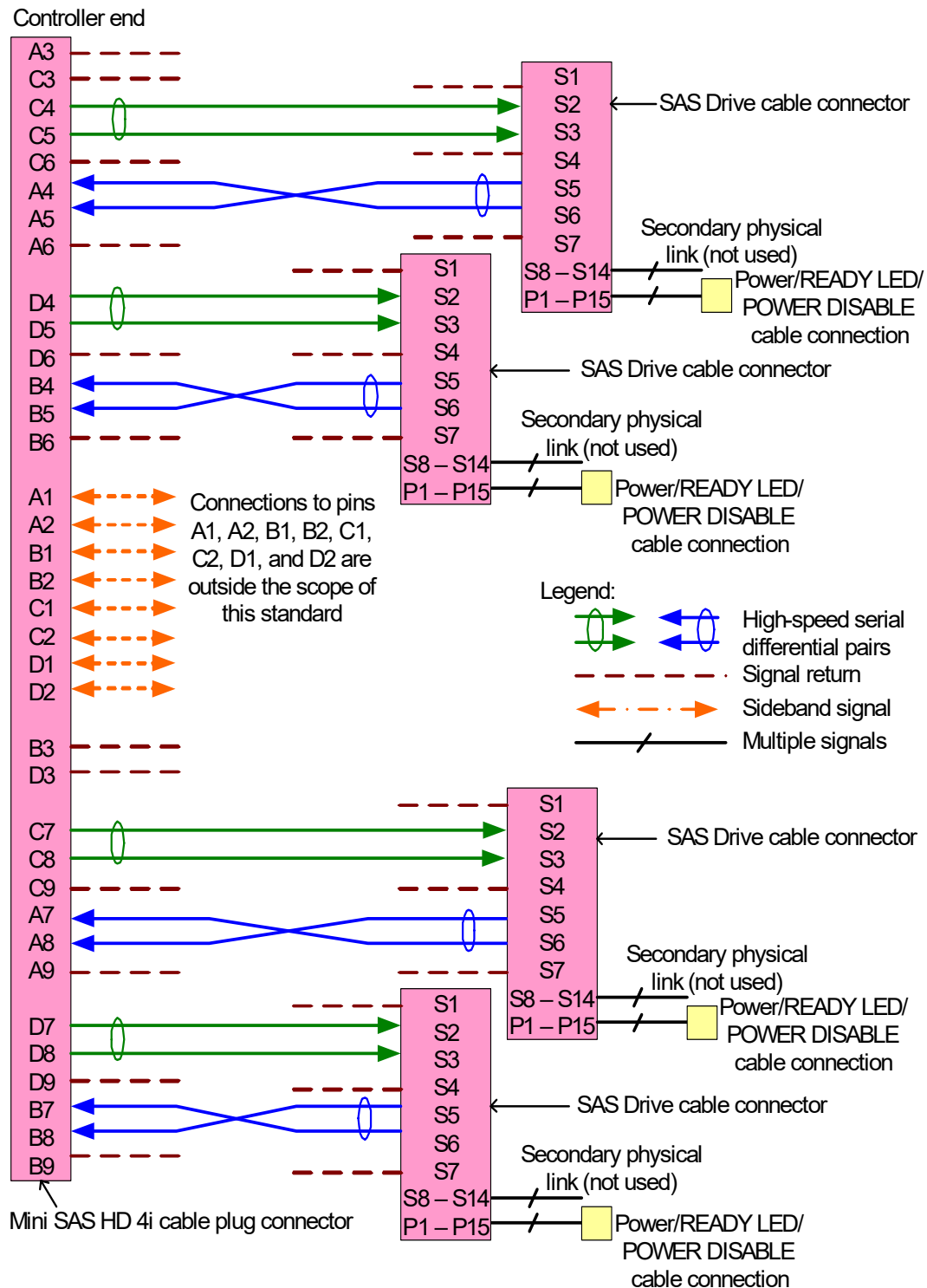


Figure 73 — SAS internal controller-based fanout cable assembly - Mini SAS HD 4i to SAS Drive

5.4.4.1.3.3 SAS internal controller-based fanout cable assembly - SlimSAS 4i to SAS Drive

Figure 74 shows the SAS internal controller-based fanout cable assembly with a SlimSAS 4i cable plug connector at the controller end and four SAS Drive cable connectors on the other end.

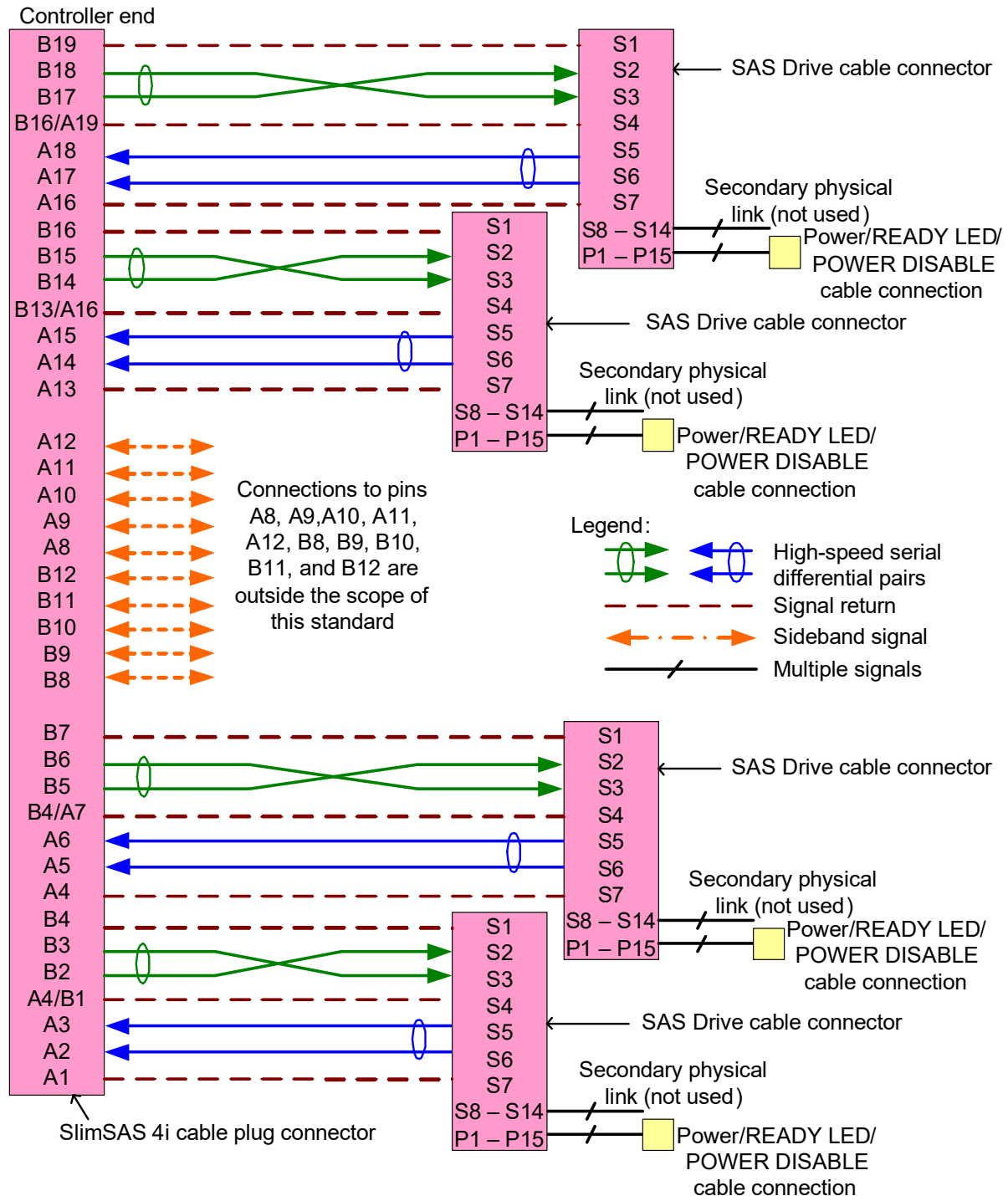


Figure 74 — SAS internal controller-based fanout cable assembly - SlimSAS 4i to SAS Drive

5.4.4.1.3.4 SAS internal controller-based fanout cable assembly - SlimSAS 4i to SATA signal

Figure 75 shows the SAS internal controller-based fanout cable assembly with the SlimSAS 4i cable plug connector at the controller end and four SATA signal cable receptacle connectors on the other end.

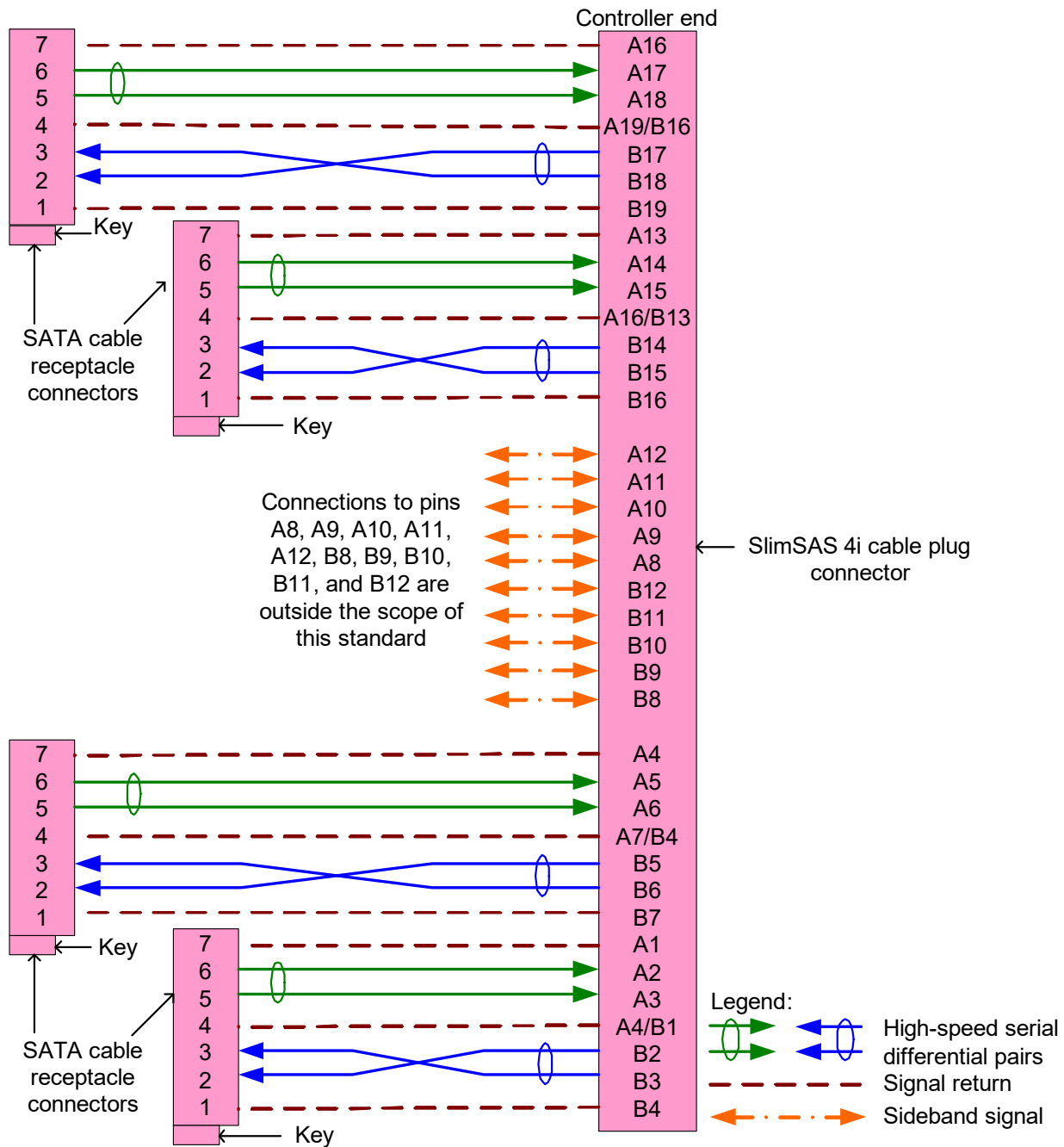


Figure 75 — SAS internal controller-based fanout cable assembly - SlimSAS 4i to SATA signal

5.4.4.1.3.5 SAS internal controller-based fanout cable assembly - SlimSAS 8i to SlimSAS 4i

Figure 76 shows the SAS internal controller-based fanout cable assembly with a SlimSAS 8i cable plug connector on one end and two SlimSAS 4i cable plug connectors on the other end.

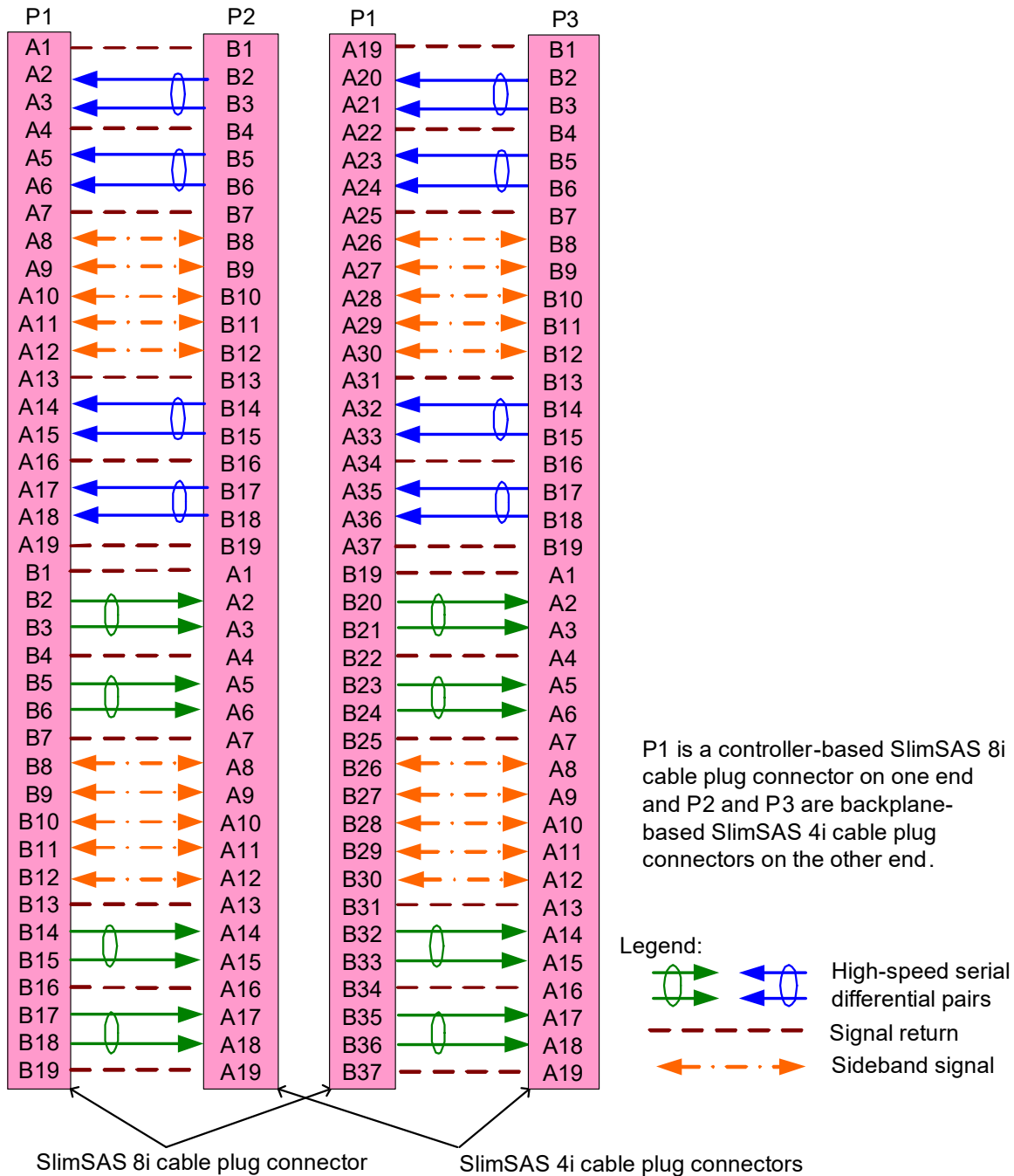


Figure 76 — SAS internal controller-based fanout cable assembly - SlimSAS 8i to SlimSAS 4i

5.4.4.1.3.6 SAS internal controller-based fanout cable assembly - SlimSAS 8i to Mini SAS HD 4i

Figure 77 shows the SAS internal controller-based fanout cable assembly with a SlimSAS 8i cable plug connector on one end and two Mini SAS HD 4i cable plug connectors on the other end.

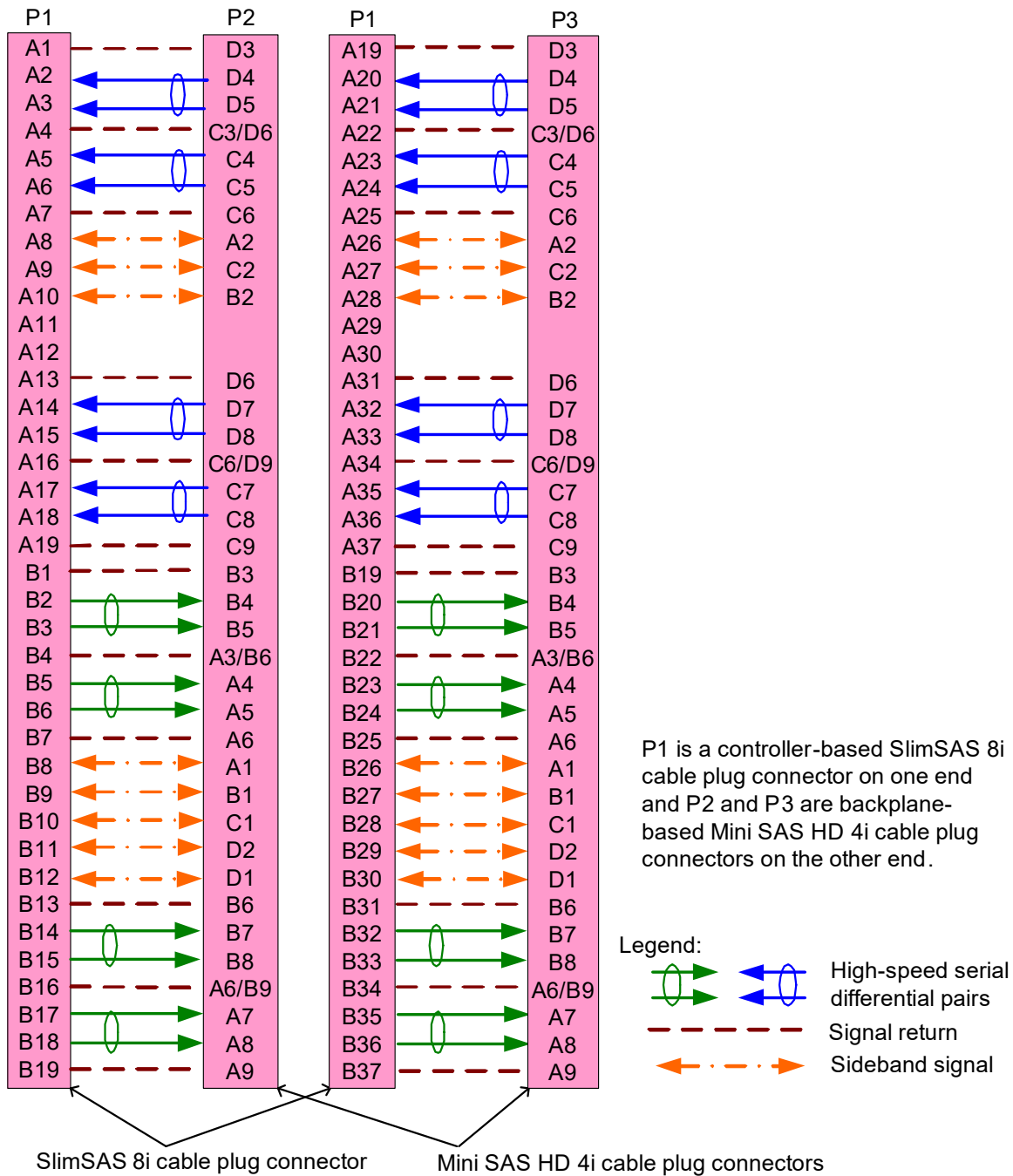


Figure 77 — SAS internal controller-based fanout cable assembly - SlimSAS 8i to Mini SAS HD 4i

5.4.4.1.3.7 SAS internal controller-based fanout cable assembly - SAS MiniLink 4i to SAS Drive

Figure 78 shows the SAS internal controller-based fanout cable assembly with a SAS MiniLink 4i cable plug connector at the controller end and four SAS Drive cable connectors on the other end.

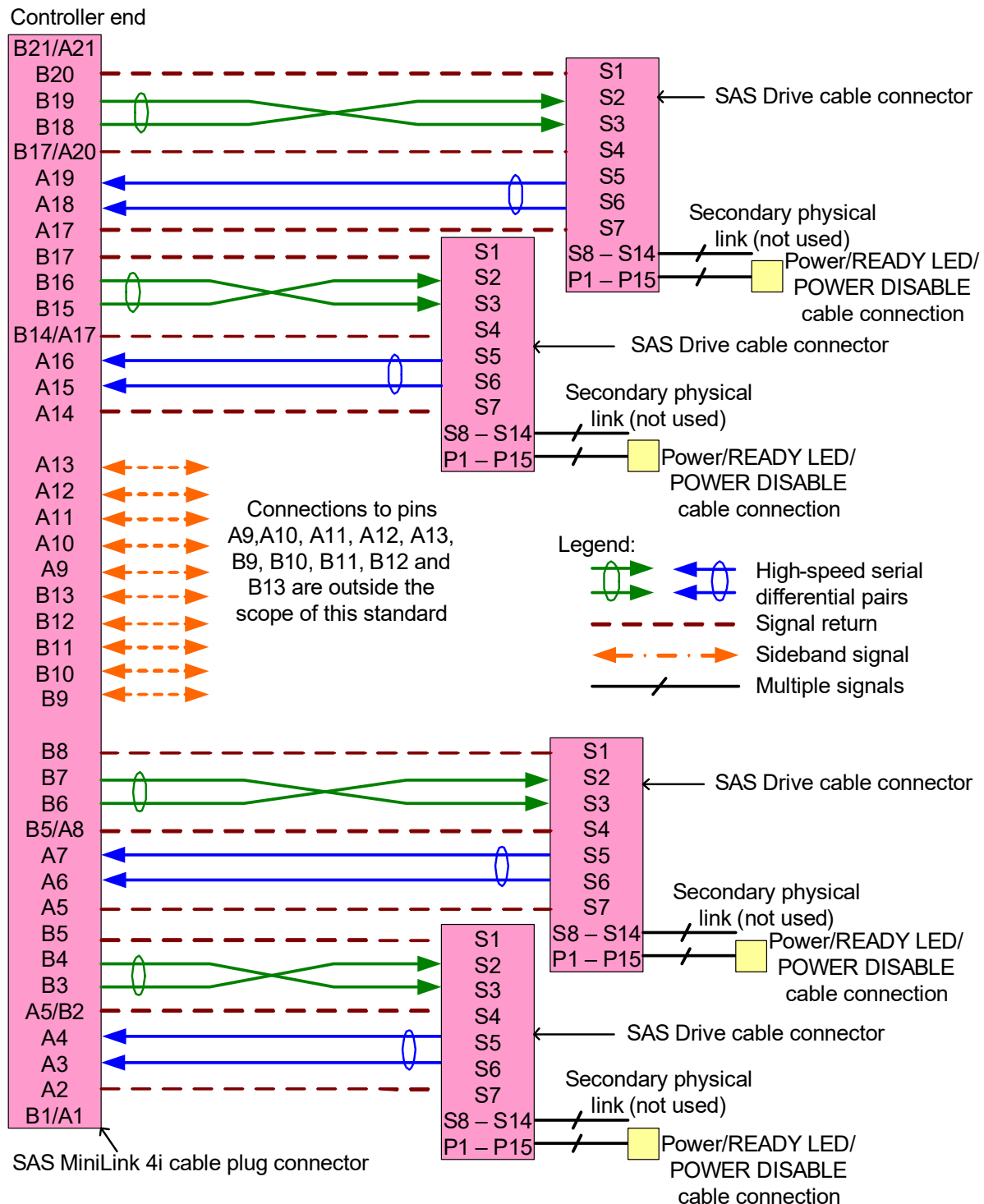


Figure 78 — SAS internal controller-based fanout cable assembly - SAS MiniLink 4i to SAS Drive

5.4.4.1.3.8 SAS internal controller-based fanout cable assembly - SAS MiniLink 4i to SATA signal

Figure 79 shows the SAS internal controller-based fanout cable assembly with the SAS MiniLink 4i cable plug connector at the controller end and four SATA signal cable receptacle connectors on the other end.

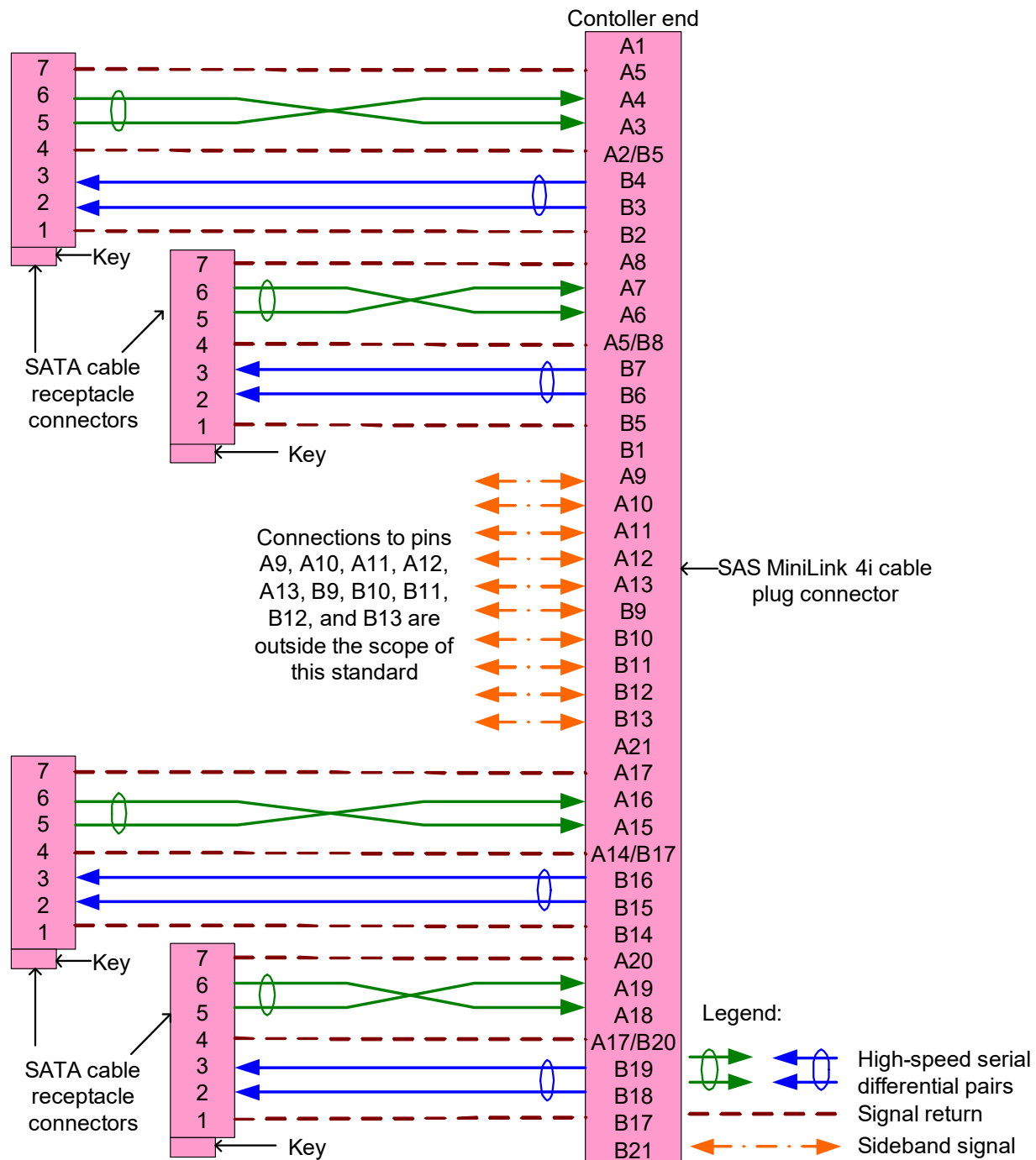


Figure 79 — SAS internal controller-based fanout cable assembly - SAS MiniLink 4i to SATA signal

5.4.4.1.3.9 SAS internal controller-based fanout cable assembly - SAS MiniLink 8i to SAS MiniLink 4i

Figure 80 shows the SAS internal controller-based fanout cable assembly with a SAS MiniLink 8i cable plug connector on one end and two SAS MiniLink 4i cable plug connectors on the other end.

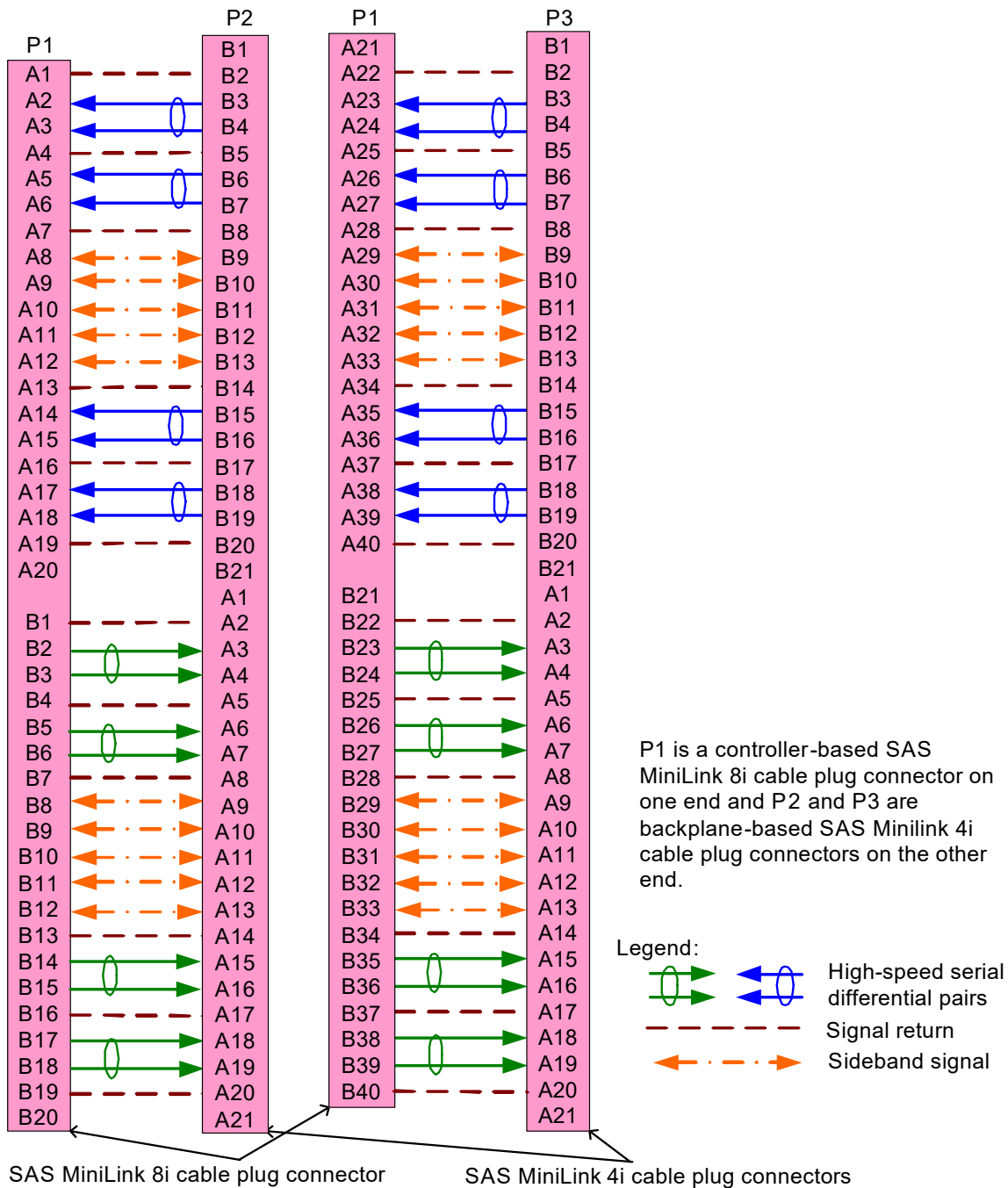


Figure 80 — SAS internal controller-based fanout cable assembly - SAS MiniLink 8i to SAS MiniLink 4i

5.4.4.1.3.11 SAS internal backplane-based fanout cable assembly - SATA signal to Mini SAS HD 4i

Figure 82 shows the SAS internal backplane-based fanout cable assembly with the Mini SAS HD 4i cable plug connector.

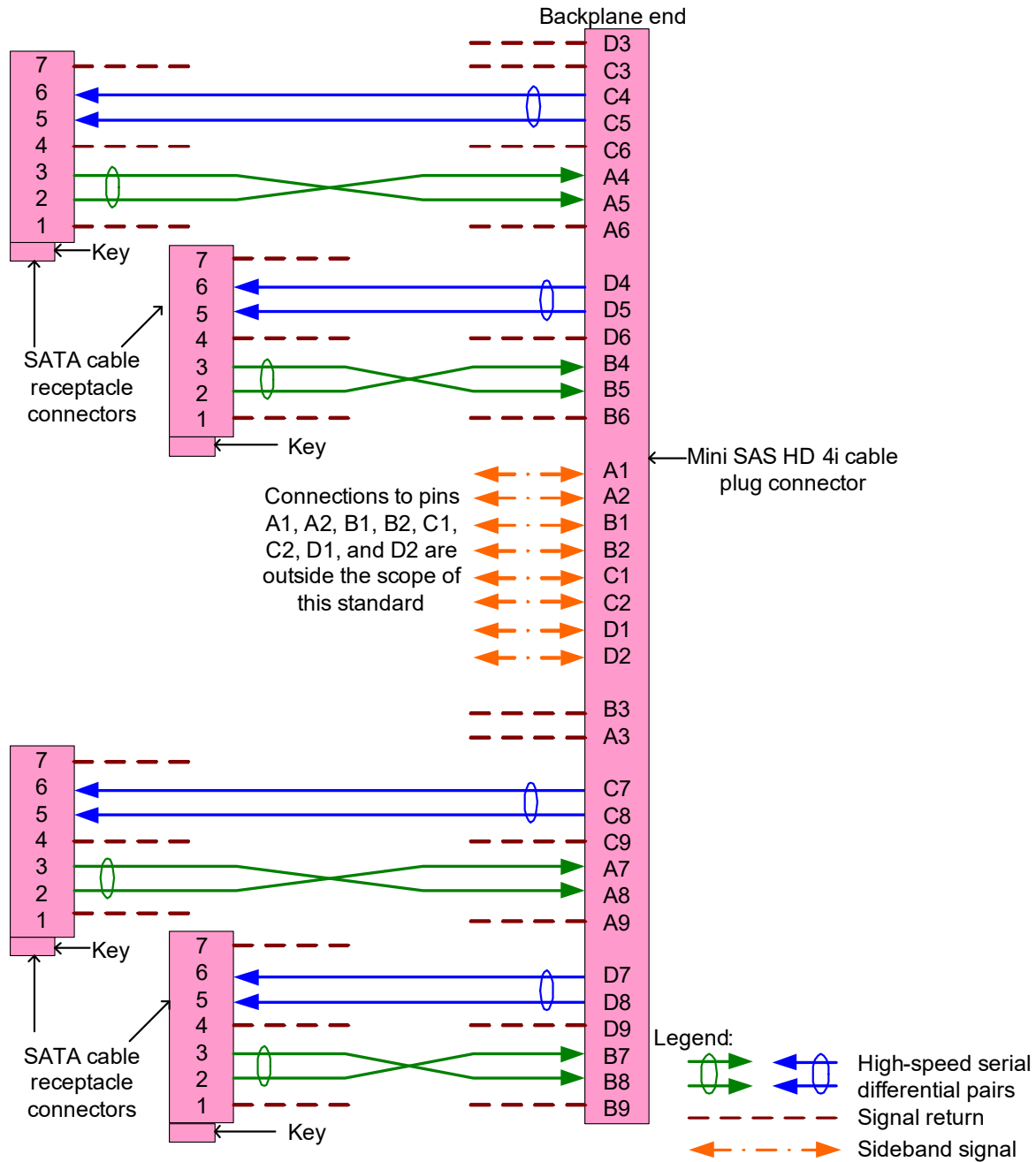


Figure 82 — SAS internal backplane-based fanout cable assembly - SATA signal to Mini SAS HD 4i

5.4.4.2 SAS external cable assemblies

5.4.4.2.1 SAS external cable assemblies overview

A SAS external cable assembly has:

- a) a Mini SAS HD 4x cable plug connector (see 5.4.3.4.1.1) at each end (see 5.4.4.2.2);
- b) a Mini SAS HD 8x cable plug connector (see 5.4.3.4.1.2) at each end (see 5.4.4.2.3);
- c) a Mini SAS HD 8x cable plug connector (see 5.4.3.4.1.2) at one end and two Mini SAS HD 4x cable plug connectors (see 5.4.3.4.1.1) at the other end (see 5.4.4.2.4); or
- d) a QSFP cable plug connector (see 5.4.3.4.2.1) at each end (see 5.4.4.2.5).

SAS external cable assemblies do not include power, the READY LED signal, or the POWER DISABLE signal.

Although the connector always supports four or eight physical links, a SAS external cable assembly may support one to eight physical links. SAS external cable assemblies should be labeled to indicate how many physical links are included (i.e., 1X, 2X, 3X, 4X, 5X, 6X, 7X, or 8X on each connector's housing).

The TX signals on one end shall be connected to the corresponding RX signals of the other end (e.g., TX 0+ of one connector shall be connected to RX 0+ of the other connector).

Signal returns shall not be connected to CHASSIS GROUND in the cable assembly.

5.4.4.2.2 SAS external cable assembly - Mini SAS HD 4x

Figure 83 shows the SAS external cable assembly with Mini SAS HD 4x cable plug connectors at each end.

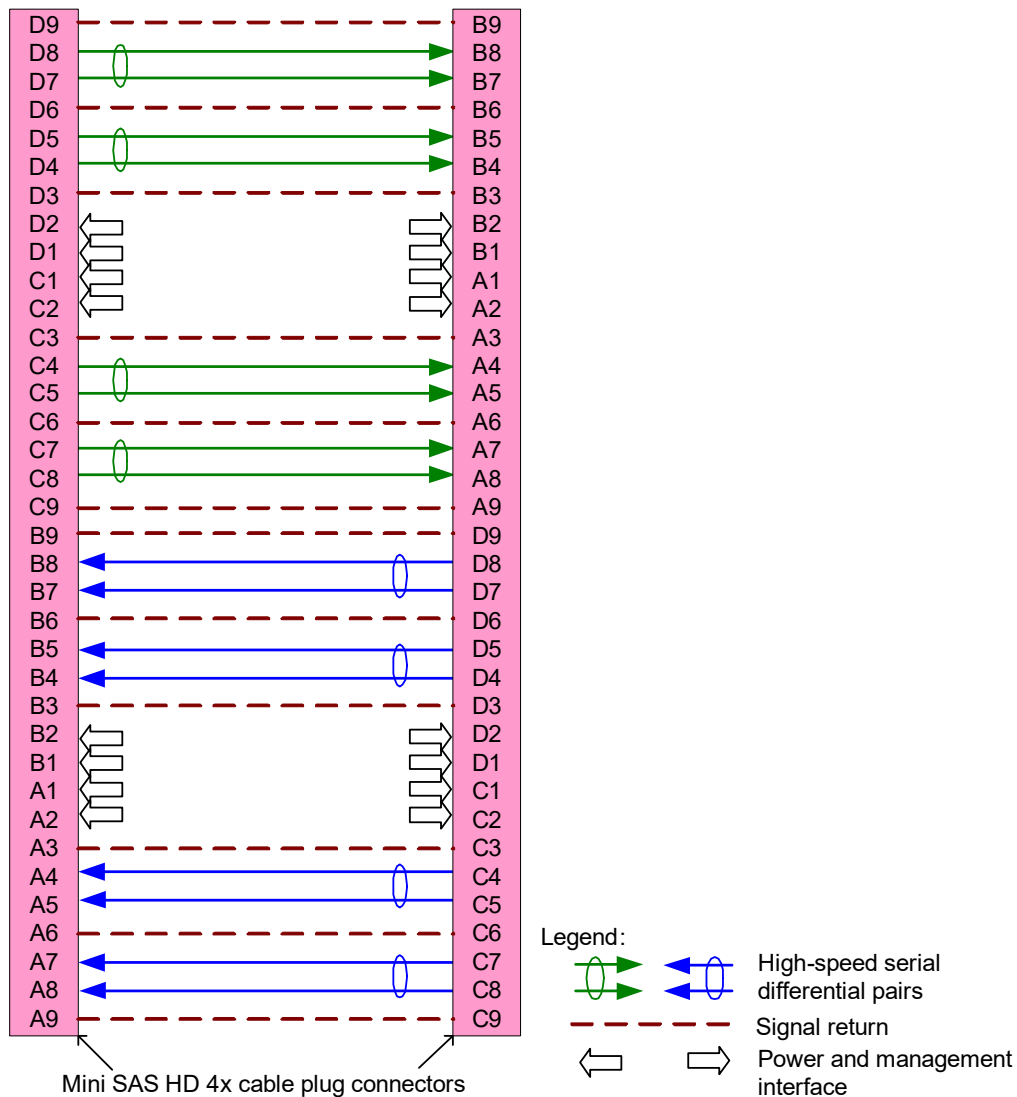


Figure 83 — SAS external cable assembly - Mini SAS HD 4x

In addition to the signal return connections shown in figure 83, one or more of the signal returns may be connected together in this cable assembly.

Figure 84 shows an example SAS external cable assembly with Mini SAS HD 4x cable plug connectors at each end.

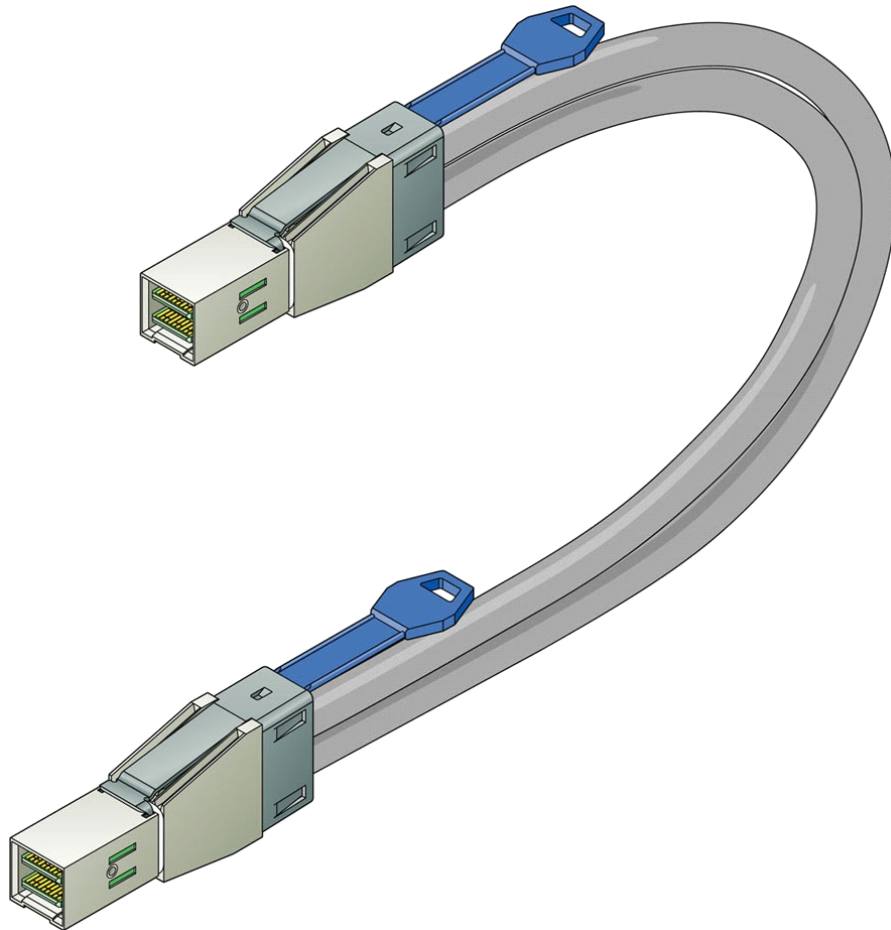


Figure 84 — SAS external cable assembly with Mini SAS HD 4x cable plug connectors

5.4.4.2.3 SAS external cable assembly - Mini SAS HD 8x

Figure 85 shows the SAS external cable assembly with Mini SAS HD 8x cable plug connectors at each end.

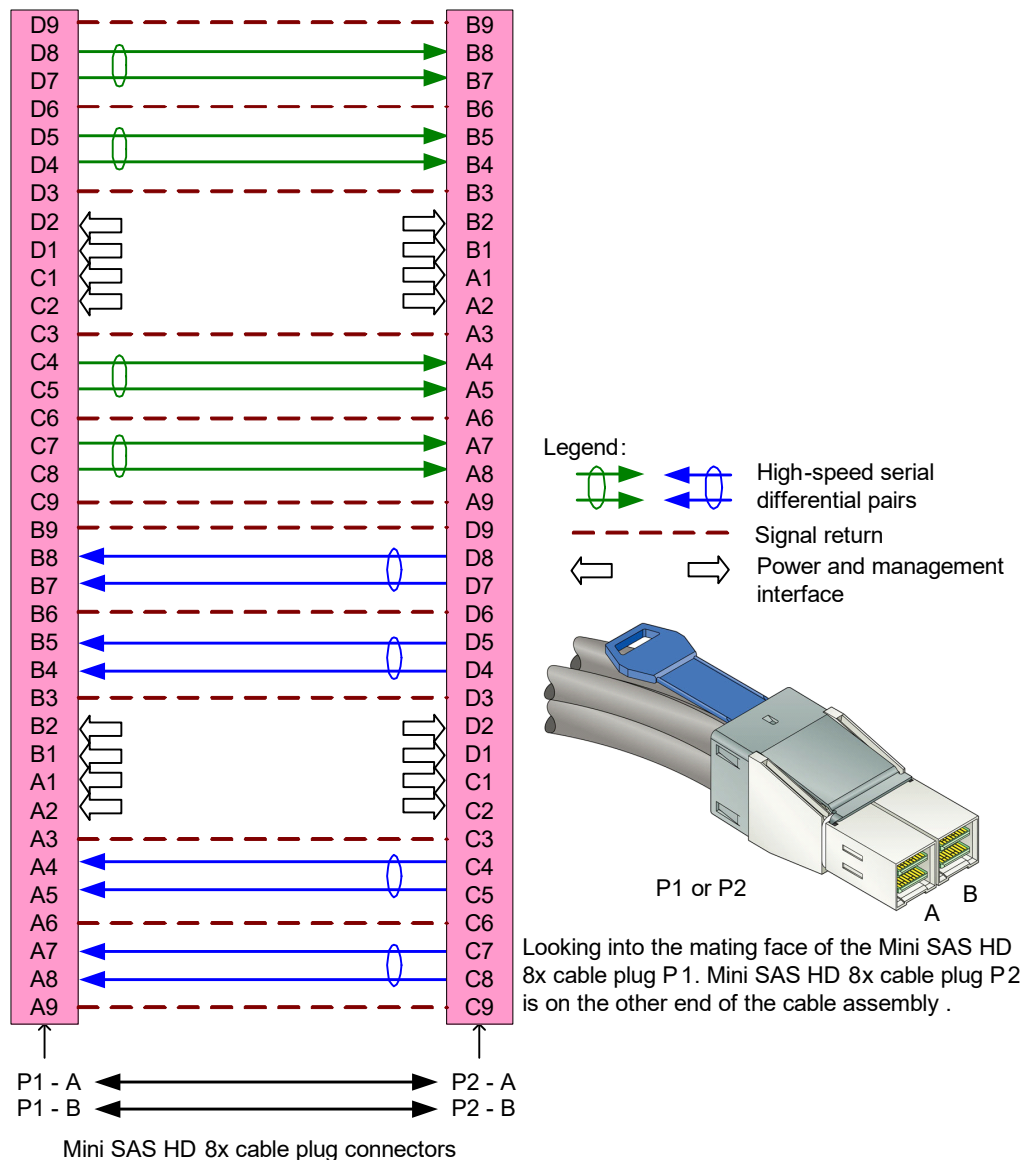


Figure 85 — SAS external cable assembly - Mini SAS HD 8x

In addition to the signal return connections shown in figure 85, one or more of the signal returns may be connected together in this cable assembly.

The cable assembly shown in figure 85 may support one to eight physical links. If less than eight physical links are supported, then module A shall be populated first, followed by module B (e.g., if six physical links are supported, then module A has four physical links connected and module B has two physical links connected). See 5.4.3.4.1.6 for connector module pin assignments.

Figure 86 shows an example SAS external cable assembly with Mini SAS HD 8x cable plug connectors at each end.

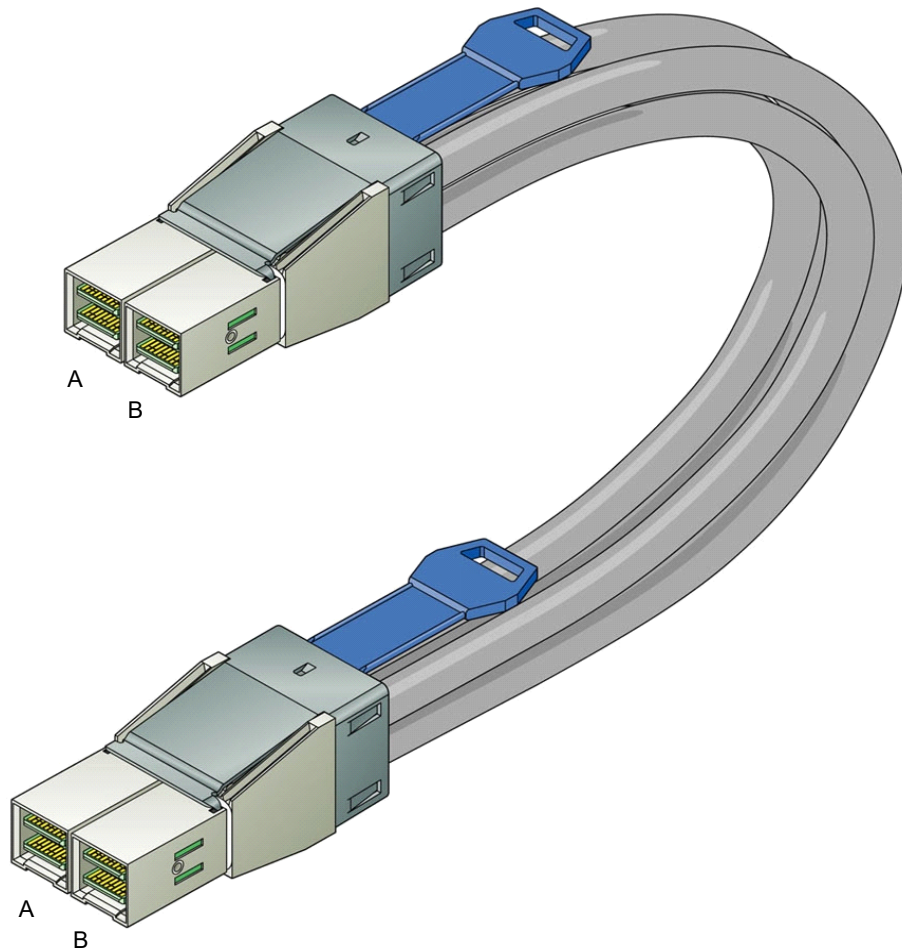


Figure 86 — SAS external cable assembly with Mini SAS HD 8x cable plug connectors

5.4.4.2.4 SAS external cable assembly - Mini SAS HD 8x to Mini SAS HD 4x

Figure 87 shows the SAS external cable assembly with a Mini SAS HD 8x cable plug connector at one end and two Mini SAS HD 4x cable plug connectors at the other end.

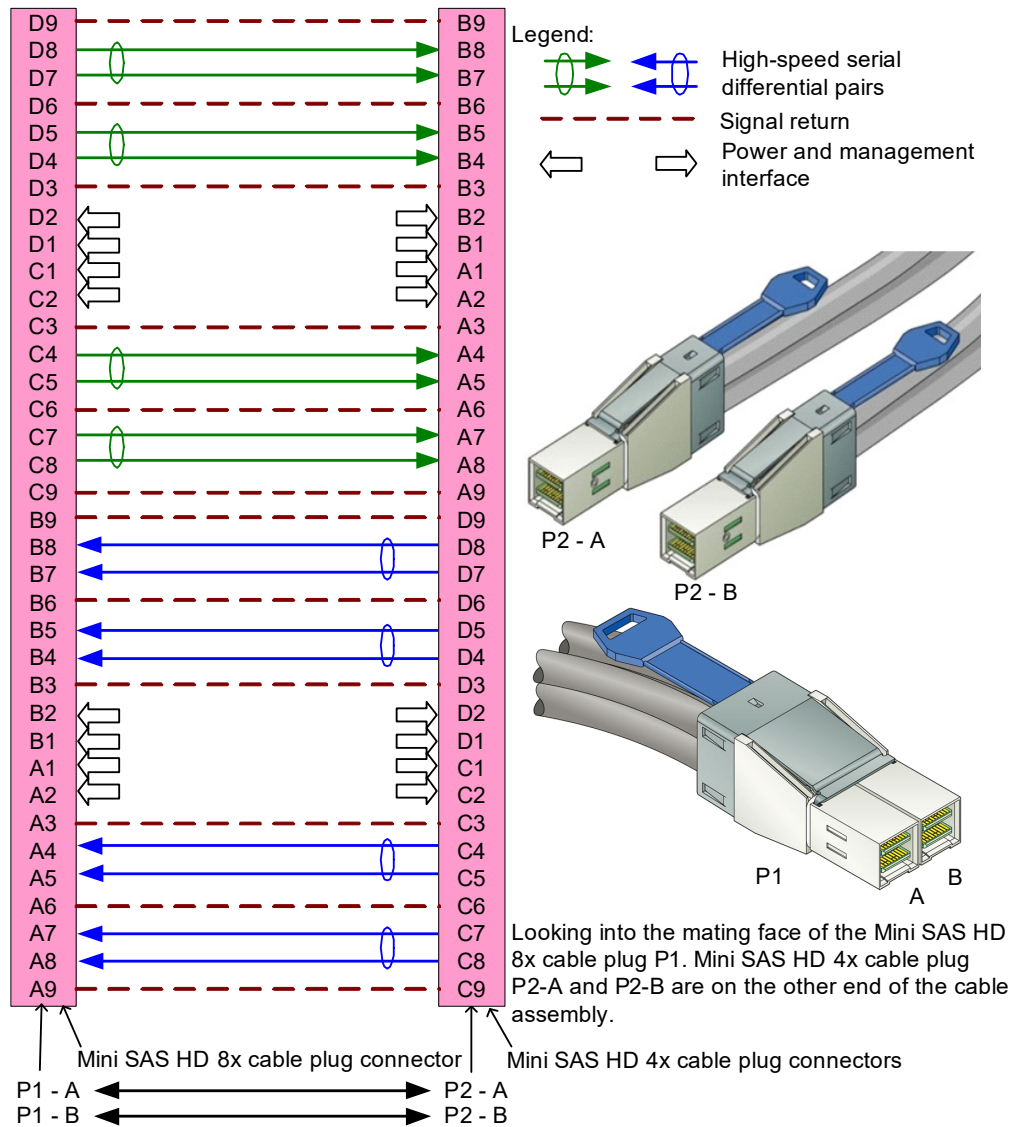


Figure 87 — SAS external cable assembly - Mini SAS HD 8x to Mini SAS HD 4x

In addition to the signal return connections shown in figure 87, one or more of the signal returns may be connected together in this cable assembly.

The cable assembly shown in figure 87 may support one to eight physical links. If less than eight physical links are supported, then module A shall be populated first, followed by module B (e.g., if six physical links are supported, then module A has four physical links connected and module B has two physical links connected). See 5.4.3.4.1.6 for connector module pin assignments.

Figure 88 shows an example SAS external cable assembly with a Mini SAS HD 8x cable plug connector at one end and two Mini SAS HD 4x cable plug connectors at the other end.

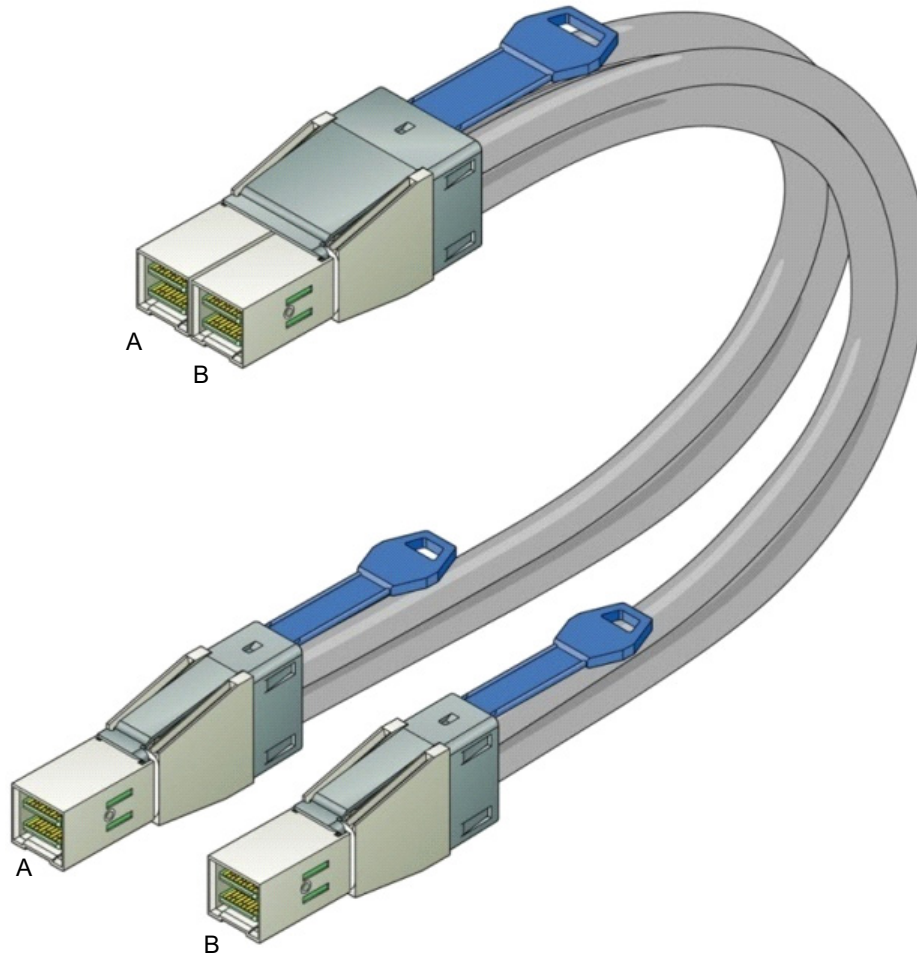


Figure 88 — SAS external cable assembly with a Mini SAS HD 8x cable plug connector and two Mini SAS HD 4x cable plug connectors

5.4.4.2.5 SAS external cable assembly - QSFP

QSFP cable assemblies are defined in SFF-8685. QSFP cable assemblies for SAS shall comply with the TxRx connection characteristics specified in this standard (see 5.5).

5.5 TxRx connection characteristics

5.5.1 TxRx connection characteristics overview

Each TxRx connection shall support a bit error ratio (BER) that is less than 10^{-12} (i.e., fewer than one bit error per 10^{12} bits). The parameters specified in this standard support meeting this requirement under all conditions including the minimum input and output amplitude levels.

A TxRx connection may be constructed from multiple TxRx connection segments (e.g., backplanes and cable assemblies). It is the responsibility of the implementer to ensure that the TxRx connection is constructed from individual TxRx connection segments such that the overall TxRx connection requirements are met. Loss characteristics for individual TxRx connection segments are beyond the scope of this standard.

Each TxRx connection segment shall comply with the impedance requirements detailed in 5.5.2 for the conductive material from which they are formed. A passive equalizer network, if present, shall be considered part of the TxRx connection.

TxRx connections shall be applied only to homogeneous ground applications (e.g., between devices within an enclosure or rack, or between enclosures interconnected by a common ground return or ground plane).

Compliance points referenced in the electrical requirement tables are shown in 5.3 unless otherwise specified.

5.5.2 TxRx connection general characteristics

Table 28 defines the TxRx connection general characteristics.

Table 28 — TxRx connection general characteristics

Characteristic ^{a b}	Units	Value
Differential impedance (nominal)	Ω	100
Bulk cable or backplane:		
Differential characteristic impedance ^{c d}	Ω	100
Mated connectors:		
Differential characteristic impedance ^e	Ω	100
Passive cable assembly and backplane:		
Maximum propagation delay ^f	ns	53
Minimum S _{DD21} for internal cable assemblies from 10 MHz to 4 500 MHz ^{f g h}	dB	-6
Minimum S _{DD21} for internal cable assemblies from 4 500 MHz to 9 000 MHz ⁱ	dB	-11
Minimum S _{DD21} for external cable assemblies and backplanes	See 5.5.4, 5.5.5, 5.5.6, and 5.5.7	
Managed cable assembly:		
Maximum propagation delay ^j	ns	510
Differential characteristic impedance ^e	Ω	100
<div>^a All measurements are made through mated connector pairs.</div> <div>^b The equivalent maximum TDR rise time from 20 % to 80 % shall be 70 ps. Filtering may be used to obtain the equivalent rise time. The filter consists of the two-way launch/return path of the test fixture, the two-way launch/return path of the test cable, and the software or hardware filtering of the TDR scope. The equivalent rise time is the rise time of the TDR scope output after application of all filter components. When configuring software or hardware filters of the TDR scope to obtain the equivalent rise time, filtering effects of test cables and test fixtures shall be included.</div> <div>^c The impedance measurement identifies the impedance mismatches present in the bulk cable or backplane when terminated in its characteristic impedance. This measurement excludes mated connectors at both ends of the bulk cable or backplane, when present, but includes any intermediate connectors or splices.</div> <div>^d Where the bulk cable or backplane has an electrical length of > 4 ns the procedure detailed in SFF-8410, or an equivalent procedure, shall be used to determine the impedance.</div> <div>^e The characteristic impedance is a measurement reference impedance for the test environment.</div> <div>^f This is based on propagation delay for a 10 m passive cable assembly. See SPL-5 for STP flow control details.</div> <div>^g An internal cable assembly may be a TxRx connection segment or a full TxRx connection. The full TxRx connection is required to comply with the requirements at intra-enclosure compliance points defined in 5.3.</div> <div>^h For 22.5 Gbit/s, S_{DD21} is defined in 5.5.7 and applies to all implementations of the TxRx connection.</div> <div>ⁱ This requirement applies only for 12 Gbit/s passive cable assemblies.</div> <div>^j This is based on propagation delay for a 100 m optical cable. Managed cables shall report the propagation delay through the cable management interface (see 5.4.3.4.1.7). TxRx connections with propagation delay > 53 ns may or may not support STP unless the necessary STP flow control buffer size is implemented. See SPL-5 for STP flow control details.</div>		

5.5.3 Passive TxRx connection S-parameter limits

S-parameters limits are calculated per the following formula:

$$\text{Measured value} < \max [L, \min [H, N + 13.3 \times \log_{10}(f / 3 \text{ GHz})]]$$

where:

- L is the minimum value (i.e., the low frequency asymptote);
- H is the maximum value (i.e., the high frequency asymptote);
- N is the value at 3 GHz;
- f is the frequency of the signal in Hz;
- max [A, B] is the maximum of A and B; and
- min [A, B] is the minimum of A and B.

The frequency for N is based on the Nyquist at 6 Gbit/s.

Table 29 defines the maximum limits for S-parameter of the passive TxRx connection segment between IT_S and IR or CT_S and CR for 6 Gbit/s and 12 Gbit/s. For 22.5 Gbit/s see 5.5.7.

Table 29 — Maximum limits for S-parameters of the passive TxRx connection between IT_S and IR or CT_S and CR for 6 Gbit/s and 12 Gbit/s

Characteristic ^{a b c d}	L ^e (dB)	N ^e (dB)	H ^e (dB)	S ^e (dB / decade)	f _{min} ^e (MHz)	f _{max} ^{e f} (GHz)	f _{max} ^{e g} (GHz)
[20 × log ₁₀ (S _{CD21})] - [20 × log ₁₀ (S _{DD21})]	-10			0	100	6.0	9.0
Maximum near-end crosstalk (NEXT) for each receive signal pair ^{f h}	-26			0	100	6.0	
20 × log ₁₀ (S _{DD22})	-10	-7.9	-3.9	13.3	100	6.0	9.0
20 × log ₁₀ (S _{CD22})	-26	-12.7	-10	13.3	100	6.0	9.0
20 × log ₁₀ (S _{CD21})	-18			0	100	6.0	9.0
Insertion loss to crosstalk ratio (ICR(f)) ^{g h i}	-15			0	100		6.0

^a All measurements are made through mated connector pairs.

^b Specifications apply to any combination of cable assemblies and backplanes that are used to form a passive TxRx connection.

^c |S_{CC22}| and |S_{DC22}| are not specified.

^d For 12 Gbit/s, these characteristics only apply to cable assemblies between CT_S and CR compliance points. 12 Gbit/s passive cable assemblies shall also comply with passive TxRx connection characteristics for trained 12 Gbit/s (see 5.5.6).

^e See figure 4 in 5.2 for definitions of L, N, H, S, f_{min}, and f_{max}.

^f Only applies for 6 Gbit/s.

^g Only applies for 12 Gbit/s.

^h Determine all near-end and far-end significant crosstalk sources. The sum of the crosstalk transfer ratios is measured in the frequency domain. The following equation details the summation process of the valid near-end crosstalk sources:

$$\text{TotalNEXT}(f) = 10 \times \log_{10} \sum_{1}^n 10^{(\text{NEXT}(f)/10)}$$

where:
f is frequency; and
n is the number of the near-end crosstalk source.

All NEXT values expressed in dB format in a passive transfer network shall have negative dB magnitude.

The following equation details the summation process of the valid far-end crosstalk sources:

$$\text{TotalFEXT}(f) = 10 \times \log_{10} \sum_{1}^n 10^{(\text{FEXT}(f)/10)}$$

where:
f is frequency; and
n is the number of the far-end crosstalk source.

All FEXT values expressed in dB format in a passive transfer network shall have negative dB magnitude.

ⁱ The following equation defines the insertion loss to crosstalk ratio:

$$\text{ICR}(f) = [10 \times \log_{10}(10^{\text{TotalNEXT}(f)/10} + 10^{\text{TotalFEXT}(f)/10})] - [20 \times \log_{10}(|S_{DD21}|)]$$

where:
f is frequency;
TotalNEXT(f) is near-end crosstalk;
TotalFEXT(f) is far-end crosstalk; and
S_{DD21} is insertion loss.

Figure 89 shows the passive TxRx connection $|S_{DD22}|$, $|S_{CD22}|$, $|S_{CD21}|$, and NEXT limits defined in table 29.

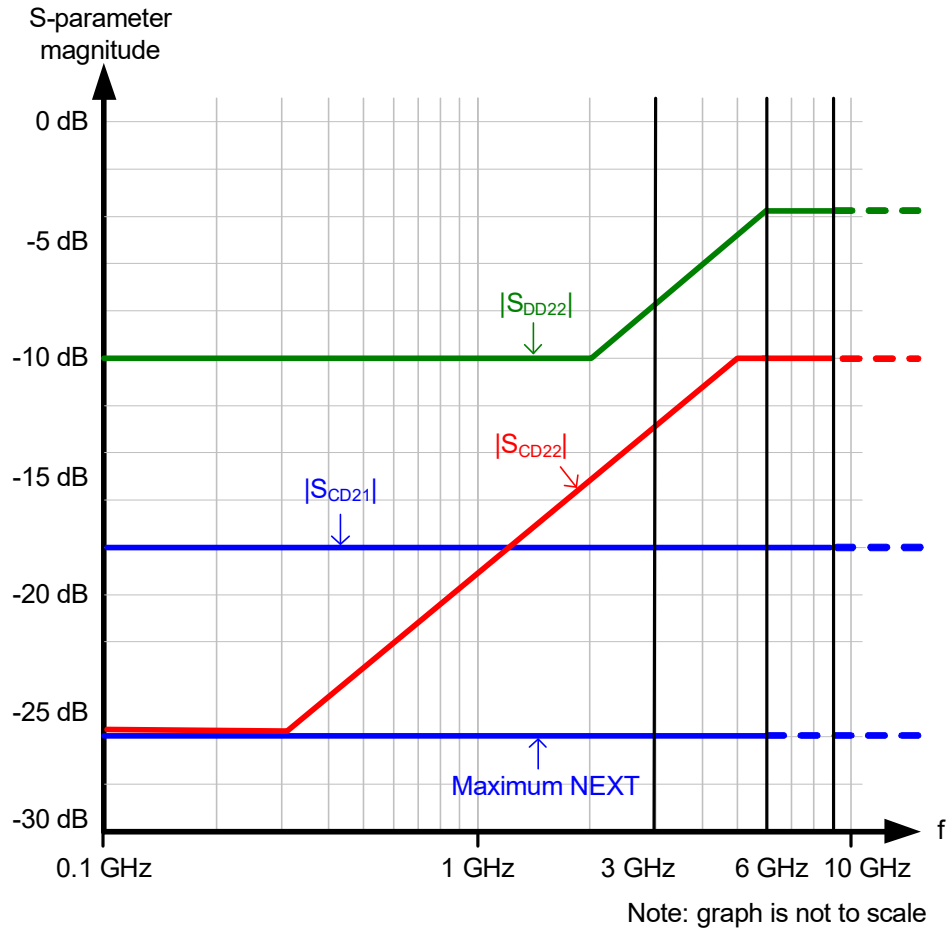


Figure 89 — Passive TxRx connection $|S_{DD22}|$, $|S_{CD22}|$, $|S_{CD21}|$, and NEXT limits for 6 Gbit/s and 12 Gbit/s

5.5.4 Passive TxRx connection characteristics for untrained 6 Gbit/s

For untrained 6 Gbit/s (i.e., SATA devices using Gen3i levels (see SATA)), the internal passive TxRx connection should be less than the CIC (see SATA). See SATA for delivered signal specifications.

5.5.5 Passive TxRx connection characteristics for trained 6 Gbit/s

For trained 6 Gbit/s, the passive TxRx connection shall support a bit error ratio (BER) that is less than 10^{-15} (i.e., fewer than one bit error per 10^{15} bits) based on simulation results using:

- S-parameter measurements of the passive TxRx connection;
- the reference transmitter device (see 5.8.4.5.5); and
- the reference receiver device (see 5.8.5.7.3).

The simulation shall not include sources of crosstalk. Since simulations do not include all aspects of noise that may degrade the received signal quality, a BER that is less than 10^{-15} is expected to yield an actual BER that is less than 10^{-12} .

The S-parameter measurements shall:

- have a maximum step size of 10 MHz;
- have a maximum frequency of at least 20 GHz;
- be passive (i.e., the output power is less than or equal to the input power); and
- be causal (i.e., the output depends only on past inputs).

Figure 90 shows an example circuit for simulation. The specific simulation program used is not specified by this standard. Annex F includes the StatEye program from <https://web.archive.org/web/20190926033423/http://www.stateye.org/>, which is one such simulation program.

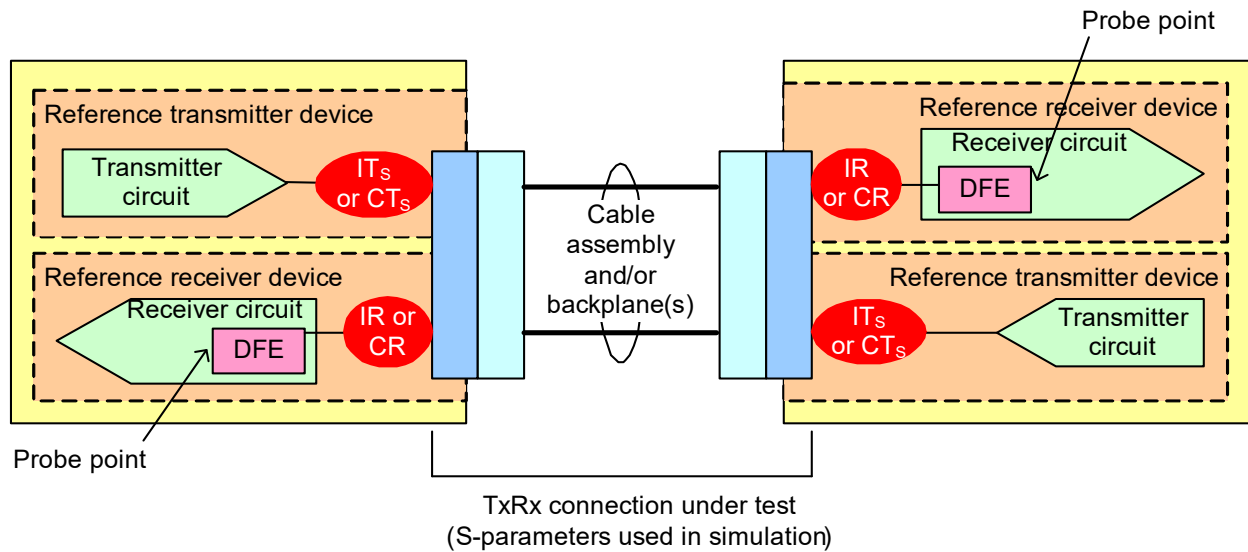


Figure 90 — Example passive TxRx connection compliance testing for trained 6 Gbit/s

Table 30 defines the required passive TxRx connection characteristics.

Table 30 — Passive TxRx connection characteristics for trained 6 Gbit/s

Characteristic	Units	6 Gbit/s
Minimum voltage ^a	mV(P-P)	84
Maximum TJ ^a	UI	0.64
^a As reported by simulation of the passive TxRx connection S-parameters with the reference transmitter device and the reference receiver device. Values are reported at a BER of 10^{-15} inside the reference receiver device after equalization at 6 Gbit/s.		

For external cable assemblies, these electrical requirements are consistent with using good quality passive cable assemblies constructed with shielded twinaxial cable with 24 AWG solid wire up to 10 m long, provided that no other TxRx connection segments are included in the TxRx connection.

A passive TxRx connection supporting trained 6 Gbit/s may or may not support SATA. Trained transceiver devices incorporate features to allow them to operate over the following passive TxRx connections:

- a) passive TxRx connections with higher loss than TxRx connections; and
- b) passive TxRx connections supporting SATA.

5.5.6 Passive TxRx connection characteristics for trained 12 Gbit/s

For trained 12 Gbit/s, the passive TxRx connection shall support a BER that is less than 10^{-15} (i.e., fewer than one bit error per 10^{15} bits) based on end to end simulation results (see 5.7.1) using:

- a) S-parameter measurements or model of the passive TxRx connection segment from CT_S to CR or IT_S to IR (see figure 13);
- b) S-parameter measurements of the passive connection, S-parameter models of the passive connection, or reference S-parameter models (see C.2) from all significant crosstalk aggressors;
- c) reference transmitter devices (see 5.8.4.6.4) providing signals to the through channel and crosstalk channels:
 - A) using the reference transmitter device peak to peak voltage defined in table 55;
 - B) using reference equalization coefficients (see 5.7.4); and
 - C) generating no RJ or TJ;
- d) the reference receiver device with optimal DFE weights (see 5.8.5.7.3 and table 31); and
- e) reference S-parameter models to complete the simulation diagram (see figure 91), according to the appropriate usage model (see C.2.3).

The simulation shall include all significant crosstalk sources. The crosstalk sources shall be modeled as asynchronous to the TxRx connection segment under test (see C.1).

Simulations do not include all aspects of noise that may degrade the received signal quality, a BER that is less than 10^{-15} is expected to yield an actual BER that is less than 10^{-12} .

The S-parameter measurements shall:

- a) have a maximum step size of 10 MHz;
- b) have a maximum frequency of at least 20 GHz;
- c) be passive (i.e., the output power is less than or equal to the input power); and
- d) be causal (i.e., the output depends only on past inputs).

Figure 91 shows an example TxRx connection for trained 12 Gbit/s. The TxRx connection segment under test is the segment between CT_S and CR or IT_S and IR. XCS_n represents the crosstalk connection segments, where n is a numerical index identifying multiple crosstalk aggressors.

The specific simulation program used is not specified by this standard. See Annex C and Annex E.

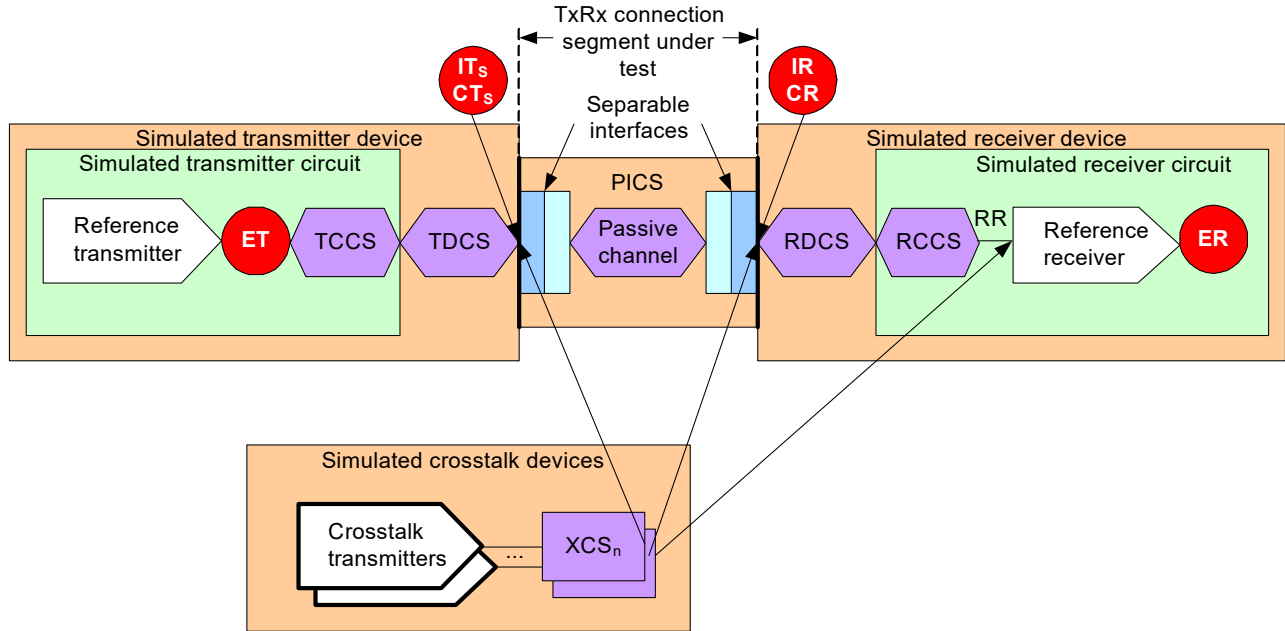


Figure 91 — Example passive TxRx connection compliance testing for trained 12 Gbit/s

The following reference through S-parameter files shall be used for this simulation, according to the appropriate usage model:

- <usage>_ET_ITs.s4p**: through between ET and CT_S or between ET and IT_S ; and
- <usage>_CR_RR.s4p**: through between CR and RR or between IR and RR.

Labels beginning by <usage> indicate reference S-parameter files. <usage> represents a prefix that is set according to the selected usage model (see C.2.3). RR is the receiver die attachment point to RCCS.

Symmetrical models have the same through transfer function between ET and CT_S or between ET and IT_S as between CR and RR or between IR and RR. Symmetrical models shall use the same transfer function for both directions (i.e., **<usage>_ET_ITs.s4p**).

Asymmetrical models do not have the same through transfer function between ET and CT_S or between ET and IT_S as between CR and RR or between IR and RR. For asymmetrical models, the reverse transfer function between ET and CT_S or between ET and IT_S shall also be used (i.e., **<usage>_ET_ITs_rev.s4p**).

For each usage model, four types of crosstalk aggressor reference S-parameter files are defined for this simulation:

- <usage>_ET_ITs_FEXT.s4p**: crosstalk caused by elements between ET and CT_S or between ET and IT_S ;
- <usage>_CR_RR_FEXT.s4p**: crosstalk caused by elements between CR and RR or between IR and RR;
- <usage>_CR_RR_NEXT.s4p**: crosstalk caused by elements between CR and RR or between IR and RR; and
- <usage>_ET_ITs_NEXT.s4p**: crosstalk caused by elements between ET and CT_S or between ET and IT_S .

Figure 92 shows the usage of the crosstalk and through files defined for the end to end simulation of TxRx connection segments between CT_S and CR or IT_S and IR. The boxes labeled PICS FEXT, PICS NEXT, PICS rev, and PICS indicate measured transfer functions (e.g., S-parameters). The boxes with a dashed boundary indicate reference S-parameter files. <usage> represents a prefix that is set according to the selected usage model (see C.2.3).

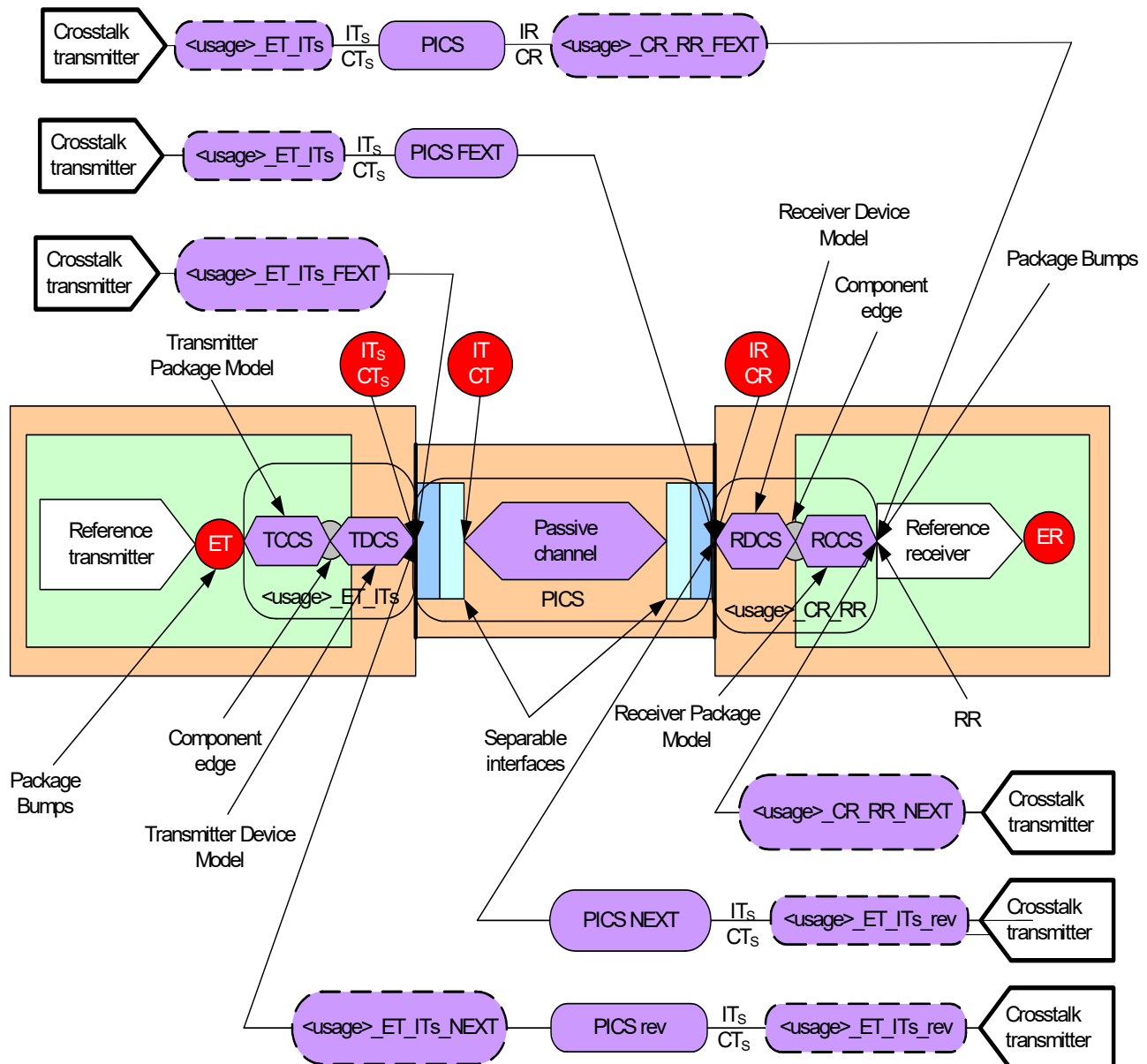


Figure 92 — Passive TxRx connection segment between CT_S and CR or IT_S and IR end to end simulation diagram for trained 12 Gbit/s

Table 31 defines the required passive TxRx connection characteristics. Refer to the reference transmitter device (see 5.8.4.6.4) for definitions of coefficient 1 (i.e., C1), coefficient 2 (i.e., C2), and coefficient 3 (i.e., C3) used in table 31.

Table 31 — Passive TxRx connection characteristics for trained 12 Gbit/s at ET and ER

Characteristic	Units	Minimum	Maximum	Compliance point
Coefficient 1 (i.e., C1) ^{a b c}	V/V	-0.15	0	ET
VMA ^{d e}	mV(P-P)	80		ET
Coefficient 3 (i.e., C3) ^{a b f}	V/V	-0.3	0	ET
Reference pulse response cursor peak to peak amplitude ^g	mV(P-P)	135		ER
Vertical eye opening to reference pulse response cursor ratio ^{h i}	%	45		ER
DFE coefficient amplitude to reference pulse response cursor ratio ^j	%	-50	50	ER
<p>^a If C1 or C3 exceeds its maximum (positive) limit, then that coefficient is forced to its maximum limit and the other coefficients are recalculated.</p> <p>^b $C2 = 1 - C1 - C3$.</p> <p>^c If C1 exceeds its minimum (negative) limit, then that coefficient is forced to its minimum limit and C3 is recalculated.</p> <p>^d $VMA = 2K_0 (C1 + C2 + C3)$ where: K₀ is the output gain; C1 is coefficient 1 (see 5.8.4.6.4); C2 is coefficient 2 (see 5.8.4.6.4); and C3 is coefficient 3 (see 5.8.4.6.4).</p> <p>^e If VMA exceeds its minimum limit, then C1 and C3 are forced to values that have the smallest distance to a point compliant to the VMA specification in the C1/C3 plane. The distance is defined as:</p> $\sqrt{(C1' - C1)^2 + (C3' - C3)^2}$ <p>where: C1' and C3' are values that satisfy the minimum VMA criterion.</p> <p>^f If C3 exceeds its minimum limit, then it is forced to its minimum limit and C1 is recalculated. If C1 had already reached or exceeded its minimum limit, then both C1 and C3 are forced to their minimum limit.</p> <p>^g The average amplitude of the eye for a random pattern digital input at the compliance point may be used for this measurement. See figure 115.</p> <p>^h The vertical eye opening includes the effects of crosstalk (see C.1).</p> <p>ⁱ The end to end simulation removes any remaining RJ and TJ (i.e., non-ISI) of the transmitter device.</p> <p>^j This is the maximum of the absolute value of the reference DFE coefficients (i.e., max(abs(di)) divided by the reference pulse response cursor) (see 5.8.5.7.3).</p>				

For external cable assemblies, these electrical requirements are consistent with using good quality passive Mini SAS HD cable assemblies constructed with shielded twinaxial cable with 24 AWG solid wire up to 6 m long, provided that no other TxRx connection segments are included between CT_S and CR in the TxRx connection and the total ICR is below the limit specified in table 29.

5.5.7 Passive TxRx connection electrical characteristics for trained 22.5 Gbit/s

5.5.7.1 Passive TxRx connection electrical characteristics for trained 22.5 Gbit/s overview

The passive TxRx connection electrical characteristics for trained 22.5 Gbit/s measurement methodology is based on OIF-CEI-03.1. The TxRx connection shall be designed such that the electrical characteristics comply with the requirements defined in 5.5.7. The TxRx connection S-parameters (see G.11) are measured at the PT and PR compliance points (see 5.3.4). The TxRx connection electrical characteristics for trained 22.5 Gbit/s are based on a maximum insertion loss of approximately 30 dB as shown in the example in figure 93. See Annex J for a test methodology to evaluate the electrical characteristics of cable assemblies supporting 22.5 Gbit/s.

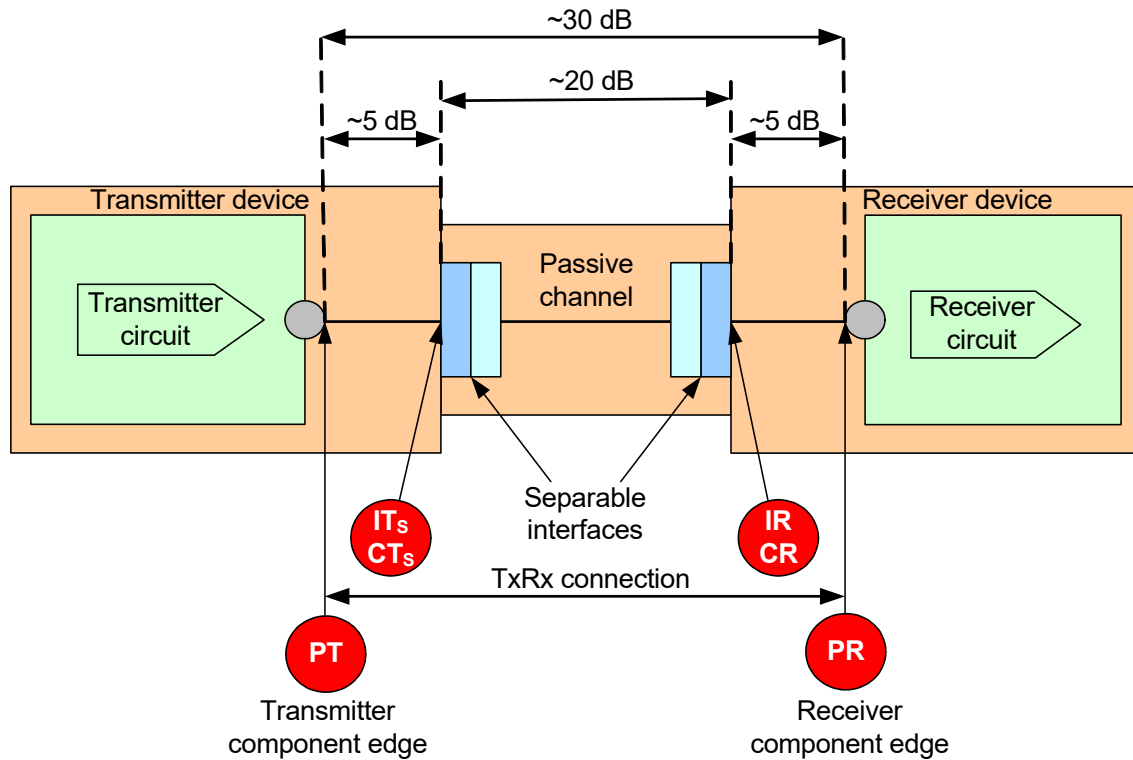


Figure 93 — Example TxRx connection for trained 22.5 Gbit/s

Measured characteristics are shown in table 32 and calculated characteristics are shown in table 33.

Table 32 — Measured S-parameters for passive TxRx connections supporting 22.5 Gbit/s

Characteristic	Description
$IL(f)$	Differential insertion loss (i.e., $ S_{DD21} $)
$RL_1(f)$	Differential input return loss (i.e., $ S_{DD11} $)
$RL_2(f)$	Differential output return loss (i.e., $ S_{DD22} $)
$NEXT_m(f)$	Differential near end crosstalk loss (m^{th} aggressor) (i.e., $ S_{DD21} $)
$FEXT_n(f)$	Differential far end crosstalk loss (n^{th} aggressor) (i.e., $ S_{DD21} $)

Table 33 — Calculated electrical characteristics for passive TxRx connections supporting 22.5 Gbit/s

Characteristic	Description
$IL_{\text{fitted}}(f)$	Fitted insertion loss
$ILD(f)$	Insertion loss deviation
$ICN(f)$	Integrated crosstalk noise
$ILD(\text{rms})$	RMS value of the insertion loss deviation

For external cable assemblies, the TxRx connection electrical requirements are consistent with using good quality passive Mini SAS HD cable assemblies constructed with shielded twinaxial cable with 24 AWG solid wire up to 6 m long, provided that no other TxRx connection segments are included between CT_S and CR in the TxRx connection.

5.5.7.2 Passive TxRx connection insertion loss for trained 22.5 Gbit/s

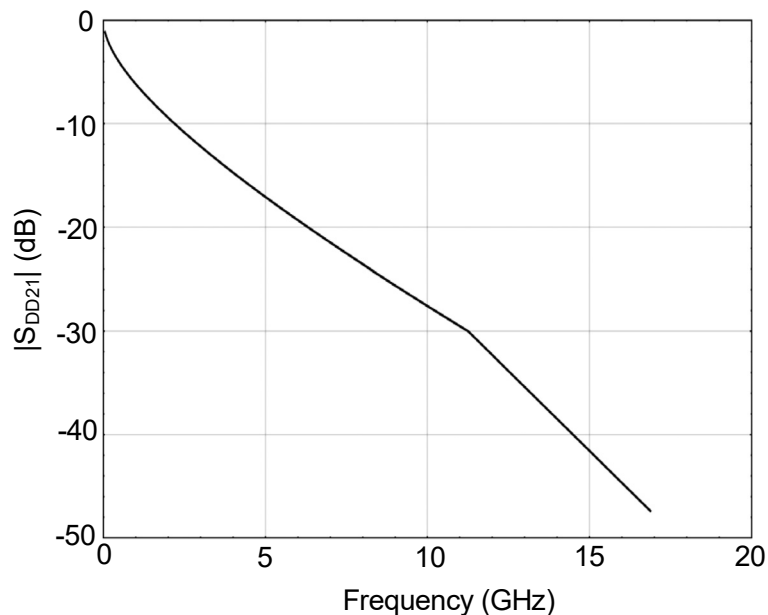
The maximum differential insertion loss of the passive TxRx connection for trained 22.5 Gbit/s shall comply with the following equations:

$$\begin{aligned}
 IL(f) &= -0.043 + 5.031\sqrt{f} + 1.171f && \text{for } 0.05 \text{ GHz} \leq f \leq 11.25 \text{ GHz; and} \\
 IL(f) &= -4.752 + 3.089f && \text{for } 11.25 \text{ GHz} < f \leq 16.875 \text{ GHz (i.e., } (3/4) f_{\text{baud}})
 \end{aligned}$$

where:

$IL(f)$ is the differential insertion loss (i.e., $-|S_{DD21}|$); and
 f is the signal frequency in GHz.

Figure 94 shows the differential insertion loss of the passive TxRx connection for trained 22.5 Gbit/s.

**Figure 94 — Passive TxRx connection differential insertion loss for trained 22.5 Gbit/s**

5.5.7.3 Passive TxRx connection fitted insertion loss for trained 22.5 Gbit/s

The TxRx connection shall meet the fitted insertion loss characteristics defined in table 34

where:

- f_{baud} is the baud rate in gigasymbols/s (e.g., 22.5 gigasymbols/s for 22.5 Gbit/s);
- f_{ILmin} is the minimum measurement frequency of 0.05 GHz; and
- f_{ILmax} is the maximum measurement frequency of 16.875 GHz (i.e., $(3/4) f_{\text{baud}}$).

Table 34 — Passive TxRx connection fitted insertion loss requirements for trained 22.5 Gbit/s

Symbol	Description	Minimum	Maximum
	Insertion loss at Nyquist ^a		30.0
a_0 ^b	Fitted insertion loss coefficient	-1.0	2.0
a_1 ^b	Fitted insertion loss coefficient	0	24.1
a_2 ^b	Fitted insertion loss coefficient	0	58.1
a_4 ^b	Fitted insertion loss coefficient	0	25.9
^a See 5.5.7.2 for the insertion loss limit profile. ^b Equations to calculate the fitted insertion loss profile and the fitted insertion loss coefficients are found in F.1.			

A method for calculating fitted insertion loss is found in F.1.

5.5.7.4 Passive TxRx connection insertion loss deviation for trained 22.5 Gbit/s

The insertion loss deviation (ILD) is the difference between the measured insertion loss and the fitted insertion loss defined by the following equation:

$$\text{ILD} = \text{IL} - \text{IL}_{\text{fitted}} \quad \text{for } 0.05 \text{ GHz} \leq f \leq 16.875 \text{ GHz (i.e., } (3/4) f_{\text{baud}})$$

where:

- ILD is the insertion loss deviation;
- IL is the insertion loss; and
- $\text{IL}_{\text{fitted}}$ is the fitted insertion loss.

The ILD shall meet the requirements defined in table 35.

ILD_{rms} is defined by the following equation:

$$\text{ILD}_{\text{rms}} = \sqrt{\frac{\sum W(f) \times \text{ILD}(f)^2}{N}} \quad \text{for } 0.05 \text{ GHz} \leq f \leq 16.875 \text{ GHz (i.e., } (3/4) f_{\text{baud}})$$

where:

- ILD_{rms} is the rms value of the ILD curve;
- $\sum W(f)$ is the weighting function (see F.2);
- $\text{ILD}(f)$ is the insertion loss deviation at frequency f ; and
- N is the number of frequency points.

5.5.7.5 Passive TxRx connection integrated crosstalk noise for trained 22.5 Gbit/s

Table 35 — Passive TxRx connection ILD requirements for trained 22.5 Gbit/s

Characteristic	Units	Minimum ^a	Maximum ^a	Frequency range ^a	Insertion loss ^b
ILD	dB	-1.0 - 12.0 (f/f _{baud})	1.0 + 12.0 (f/f _{baud})	f _{ILmin} ≤ f < (1/4) f _{baud}	
		-4.0	4.0	(1/4) f _{baud} ≤ f ≤ f _{ILmax}	
ILD _{rms}	dB _{rms}		0.3		3 dB < IL ≤ 25 dB
			1.3 - 0.04 IL ^b		25 dB < IL ≤ 30 dB
^a For values of f _{baud} , f _{ILmin} , and f _{ILmax} see 5.5.7.3.					
^b IL is the TxRx connection insertion loss in dB at (1/2) f _{baud} .					

Table 36 defines the variables for calculating ICN as defined in F.3.

Table 36 — Passive TxRx connection ICN variables for trained 22.5 Gbit/s

Variable	Symbol	Units	Minimum	Nominal	Maximum
Frequency range	f	GHz	0.05 ^a		16.875 ^b
Baud rate	f _{baud}	Gigasymbols/s		22.5	
Near end aggressor output amplitude	A _{nt}	mV(P-P)			1 200
Far end aggressor output amplitude	A _{ft}	mV(P-P)			1 200
Near end aggressor 20 % to 80 % rise/fall time	T _{nt}	ps	11		
Far end aggressor 20 % to 80 % rise/fall time	T _{ft}	ps	11		
^a This value equals f _{min} .					
^b This value equals f _{max} and is (3/4) f _{baud} for 22.5 Gbit/s.					

The ICN limits are defined by the following equations:

For 3 dB < IL ≤ 5.3 dB:

$$\sigma_x \leq 10 \text{ mV rms; and}$$

for 5.3 dB < IL ≤ 30 dB:

$$\sigma_x \leq 11.47 - 0.277 (\text{IL}) \text{ mV rms}$$

where:

σ_x is the calculated ICN; and

IL is the TxRx connection insertion loss in dB at (1/2) f_{baud}.

Figure 95 shows the allowable ICN of a TxRx connection.

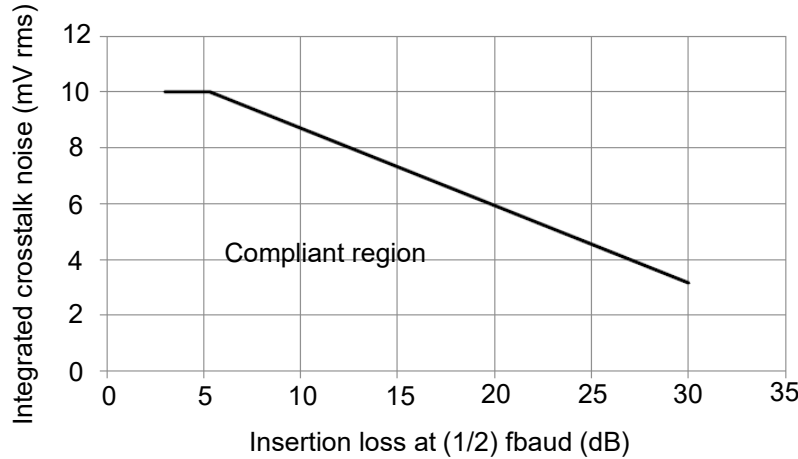


Figure 95 — Integrated crosstalk noise limit

5.5.7.6 Passive TxRx maximum limits for S_{CD21} - S_{DD21} for trained 22.5 Gbit/s between PT and PR

Passive TxRx maximum limits for S_{CD21} - S_{DD21} for trained 22.5 Gbit/s between PT and PR shall comply with the following equations:

For $50 \text{ MHz} \leq f < 12.89 \text{ GHz}$:

$$[20 \times \log_{10}(|S_{CD21}(f)|)] - [20 \times \log_{10}(|S_{DD21}(f)|)] \leq -10 \text{ dB};$$

for $12.89 \text{ GHz} \leq f < 15.7 \text{ GHz}$:

$$[20 \times \log_{10}(|S_{CD21}(f)|)] - [20 \times \log_{10}(|S_{DD21}(f)|)] \leq [-27 + ((29/22) \times f)] \text{ dB}; \text{ and}$$

for $15.7 \text{ GHz} \leq f \leq 16.875 \text{ GHz}$:

$$[20 \times \log_{10}(|S_{CD21}(f)|)] - [20 \times \log_{10}(|S_{DD21}(f)|)] \leq -6.3 \text{ dB}$$

where:

$20 \times \log_{10}(|S_{CD21}(f)|)$ is the magnitude of $S_{CD21}(f)$ in dB;

$20 \times \log_{10}(|S_{DD21}(f)|)$ is the magnitude of $S_{DD21}(f)$ in dB; and

f is the signal frequency in GHz.

Figure 96 shows the TxRx maximum limits for S_{CD21} - S_{DD21} for trained 22.5 Gbit/s between PT and PR.

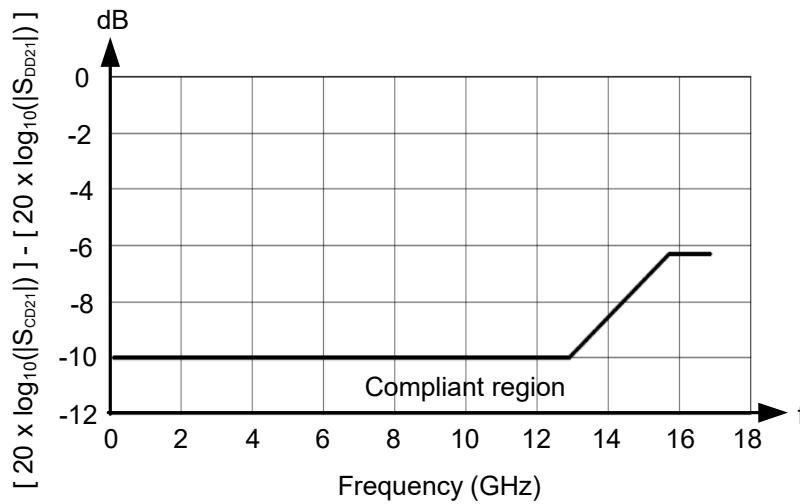


Figure 96 — Passive TxRx maximum limits for S_{CD21} - S_{DD21} for trained 22.5 Gbit/s

5.5.7.7 Passive TxRx maximum limits for S_{DD22} for trained 22.5 Gbit/s between PT and PR

Passive TxRx maximum limits for S_{DD22} for trained 22.5 Gbit/s between PT and PR shall comply with the following equations:

For $50 \text{ MHz} \leq f < 2.08 \text{ GHz}$:

$$20 \times \log_{10}(|S_{DD22}(f)|) \leq -10 \text{ dB};$$

for $2.08 \text{ GHz} \leq f < 6.00 \text{ GHz}$:

$$20 \times \log_{10}(|S_{DD22}(f)|) \leq [-7.9 - 13.3 \log_{10}(3 \text{ GHz}/f)] \text{ dB};$$

and, for $6.00 \text{ GHz} \leq f \leq 16.875 \text{ GHz}$:

$$20 \times \log_{10}(|S_{DD22}(f)|) \leq -3.9 \text{ dB}$$

where:

$20 \times \log_{10}(|S_{DD22}(f)|)$ is the magnitude of $S_{DD22}(f)$ in dB; and

f is the signal frequency in GHz.

Figure 97 shows the TxRx maximum limits for S_{DD22} for trained 22.5 Gbit/s between PT and PR.

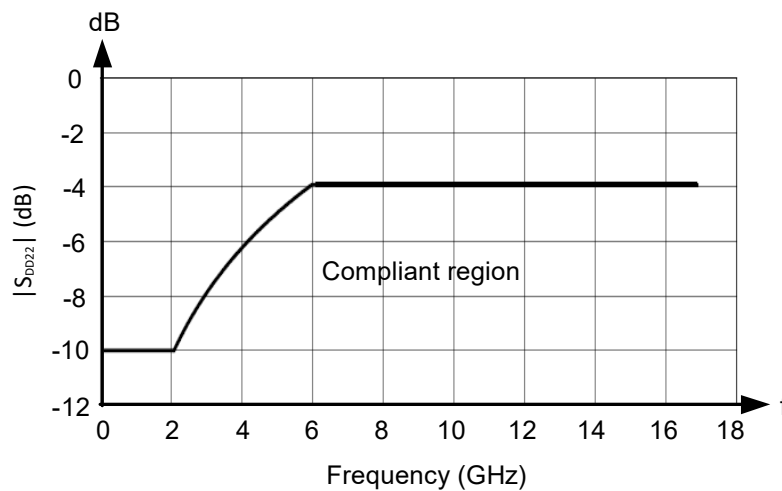


Figure 97 — Passive TxRx maximum limits for S_{DD22} for trained 22.5 Gbit/s

5.5.7.8 Passive TxRx maximum limits for S_{CD22} for trained 22.5 Gbit/s between PT and PR

Passive TxRx maximum limits for S_{CD22} for trained 22.5 Gbit/s between PT and PR shall comply with the following equations:

For $50 \text{ MHz} \leq f < 0.30 \text{ GHz}$:

$$20 \times \log_{10}(|S_{CD22}(f)|) \leq -26 \text{ dB};$$

for $0.30 \text{ GHz} \leq f < 4.79 \text{ GHz}$:

$$20 \times \log_{10}(|S_{CD22}(f)|) \leq [-12.7 - 13.3 \log_{10}(3 \text{ GHz}/f)] \text{ dB}; \text{ and}$$

for $4.79 \text{ GHz} \leq f \leq 16.875 \text{ GHz}$:

$$20 \times \log_{10}(|S_{CD22}(f)|) \leq -10 \text{ dB}$$

where:

$20 \times \log_{10}(|S_{CD22}(f)|)$ is the magnitude of $S_{CD22}(f)$ in dB (i.e., differential to common mode conversion); and

f is the signal frequency in GHz.

Figure 98 shows the TxRx maximum limits for S_{CD22} for trained 22.5 Gbit/s between PT and PR.

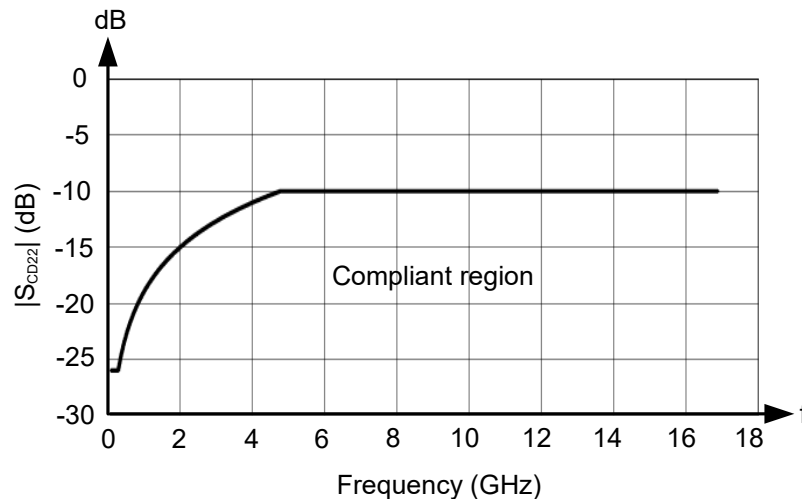


Figure 98 — Passive TxRx maximum limits for S_{CD22} for trained 22.5 Gbit/s

5.5.8 TxRx connection characteristics for active cable assemblies

5.5.8.1 Active cable assembly electrical characteristics for trained 6 Gbit/s overview

Active cable assemblies shall support a bit error ratio (BER) that is less than 10^{-12} when used with transmitter devices and trained receiver devices defined in 5.8.

In addition to complying with electrical characteristics necessary for the required BER performance, active cable assemblies shall comply with the OOB signaling defined in 5.11. The circuitry incorporated in unmanaged cable assemblies shall operate in the D.C. mode. Managed active cable assemblies supporting 6 Gbit/s operation may operate in the D.C. mode or in the optical mode (see 5.11). The circuitry incorporated in active cable assemblies shall preserve OOB signals with response times that support the OOB signal receiver device detection requirements in table 93.

5.5.8.2 Active cable assembly output electrical characteristics for trained 6 Gbit/s

Table 37 defines active cable assembly output electrical characteristics for trained 6 Gbit/s.

Table 37 — Active cable assembly output electrical characteristics for trained 6 Gbit/s

Signal characteristic	Units	Minimum	Nominal	Maximum
Peak to peak voltage	mV (P-P)	400		1 200
RJ ^{a b d}	UI			0.22
TJ ^{a c d}	UI			0.56
^a Based on TX input per table 45 and recommended TX interoperability settings per table 48. ^b The RJ measurement shall be performed with a repeating 0011b pattern or 1100b pattern (e.g., D24.3)(see the phy test patterns in the Protocol Specific diagnostic page in SPL-5) with SSC disabled. RJ is 14 times the RJ 1 sigma value, based on a BER of 10^{-12} . ^c The TJ measurement shall be performed with at least 58 dwords (i.e., 2 320 bits on the physical link) of the SCRAMBLED_0 pattern (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5) with SSC enabled. ^d The measurement shall include the effects of the JTF (see 5.8.3.2).				

For active cable assemblies, these characteristics are consistent with good quality half-active (i.e., with circuitry only on the receive end of the assembly) cable assemblies constructed with shielded twinaxial cable with 24 AWG solid wire up to 25 m long, provided that no other TxRx connection segments are included in the TxRx connection.

5.5.8.3 Active cable assembly S-parameter limits for trained 6 Gbit/s, trained 12 Gbit/s, and trained 22.5 Gbit/s

S-parameter limits are calculated per the following formula:

$$\text{Measured value} < \max [L, \min [H, N + 13.3 \times \log_{10}(f / 3 \text{ GHz})]]$$

where:

- L is the minimum value (i.e., the low frequency asymptote);
- H is the maximum value (i.e., the high frequency asymptote);
- N is the value at 3 GHz;
- f is the frequency of the signal in Hz;
- max [A, B] is the maximum of A and B; and
- min [A, B] is the minimum of A and B.

The frequency for N is based on the Nyquist at 6 Gbit/s.

Table 38 defines the maximum limits for S-parameters of the active cable assembly.

Table 38 — Maximum limits for S-parameters for active cable assemblies

Characteristic ^{a b}	L ^c (dB)	N ^c (dB)	H ^c (dB)	S ^c (dB / decade)	f _{min} ^c (MHz)	f _{max} ^{c d} (GHz)	f _{max} ^{c e} (GHz)	f _{max} ^{c f} (GHz)
S _{CC22} ^g	-6.0	-5.0	-1.0	13.3	100	6.0	9.0	16.875
S _{DD11} , S _{DD22} ^g	-10	-7.9	-3.9	13.3	100	6.0	9.0	16.875
S _{CD11} , S _{CD22} ^g	-20	-12.7	-10	13.3	100	6.0	9.0	16.875
^a Power shall be applied to the active cable assembly during these measurements. ^b S _{CC11} , S _{DC11} and S _{DC22} are not specified. ^c See figure 4 in 5.2 for definitions of L, N, H, S, f _{min} , and f _{max} . ^d Applies for 6 Gbit/s. ^e Applies for 12 Gbit/s. ^f Applies for 22.5 Gbit/s. ^g For S _{CC22} , S _{DD22} and S _{CD22} measurements, the transmitter device attached to the active cable assembly under test shall transmit a repeating 0011b pattern or 1100b pattern (e.g., D24.3)(see the phy test patterns in the Protocol Specific diagnostic page in SPL-5). The amplitude applied by the test equipment shall be less than -4.4 dBm (190 mV zero to peak) per port. See G.11.4.4 and G.11.4.5.								

Figure 99 shows the active cable assembly $|S_{CC22}|$, $|S_{DD11}|$, $|S_{DD22}|$, $|S_{CD11}|$, and $|S_{CD22}|$ limits defined in table 38.

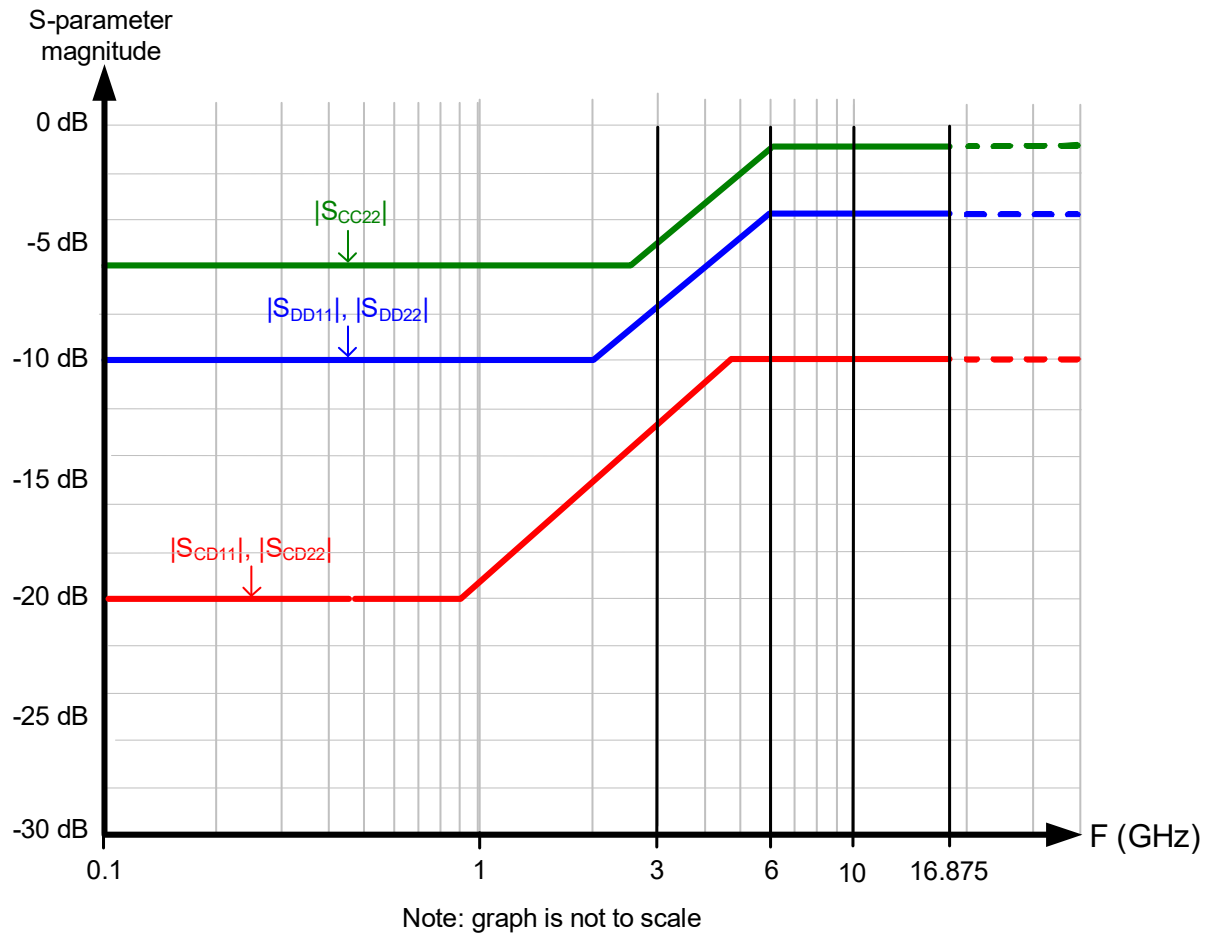


Figure 99 — Active cable S-parameter limits

5.5.8.4 Active cable assembly electrical characteristics overview for 12 Gbit/s and 22.5 Gbit/s

Active cable assemblies supporting 12 Gbit/s and 22.5 Gbit/s operation shall comply with OOB in the optical mode (see 5.11) and shall support pass through of SSC. The optical mode does not support transmitter training. The circuitry incorporated in these cable assemblies preserves OOB signals with response times that support the OOB signal receiver device detection requirements in table 93.

5.5.8.5 Active cable assembly electrical characteristics for 12 Gbit/s and 22.5 Gbit/s

Figure 100 describes the eye mask used to calibrate the input in an active cable assembly at CT_S (see figure 14) to test the output of an active cable assembly at CR (see figure 14) for 12 Gbit/s and 22.5 Gbit/s.

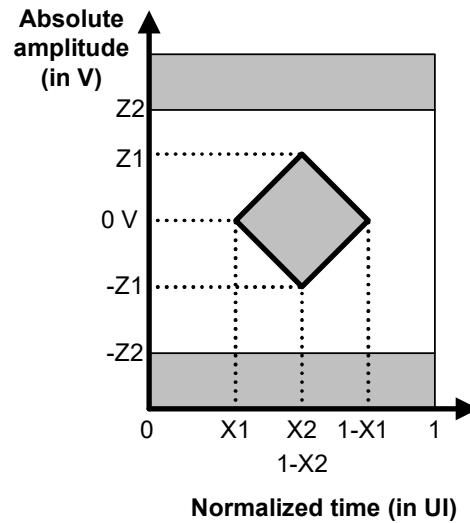


Figure 100 — Active cable eye mask for 12 Gbit/s and 22.5 Gbit/s

Table 39 defines the signal input and output characteristics for an active cable assembly for 12 Gbit/s and 22.5 Gbit/s.

Table 39 — Active cable assembly electrical characteristics for 12 Gbit/s and 22.5 Gbit/s

Signal characteristic	Units	CT_S ^a	CR
Maximum peak to peak voltage (i.e., $2 \times Z2$ in figure 100) ^{b c d}	mV(P-P)	1 200	1 200
Minimum eye opening (i.e., $2 \times Z1$ in figure 100) ^{b c e}	mV(P-P)	200	360
Maximum half of TJ (i.e., $X1$ in figure 100) ^{b c e f}	UI	0.175	0.35
Maximum RJ ^{b d f g}	UI	0.15	0.45
Center of bit time (i.e., $X2$ in figure 100)	UI	0.5	0.5
^a This column represents signal input characteristics to a cable assembly under test. ^b All crosstalk sources shall be active with representative traffic during the measurement. ^c Maximum TJ at CT_S and maximum RJ at CT_S shall be applied during this measurement. ^d The maximum peak to peak voltage measurement and RJ measurement shall be performed with a repeating 0011b pattern or 1100b pattern (e.g., D24.3) (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5) with SSC disabled. RJ is 14 times the RJ 1 sigma value, based on a BER of 10^{-12} . ^e The minimum eye opening measurement and TJ measurement shall be performed with the SCRAMBLED_0 pattern (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5) with SSC enabled for a period of at least $33.3 \mu s$ (i.e., a full SSC cycle). ^f The measurement shall include the effects of the JTF (see 5.8.3.2). ^g The maximum RJ at CT_S shall be applied during this measurement.			

For active cable assemblies supporting 12 Gbit/s operation, these characteristics are consistent with good quality full-active cable assemblies (i.e., with circuitry on both ends of each differential signal pair of the cable assembly) constructed with shielded twinaxial cable with 26 AWG solid wire up to 15 m or optical cable

assemblies up to 100 m, provided that no other TxRx connection segments are included in the TxRx connection. For active cable assemblies supporting 22.5 Gbit/s operation, these characteristics are consistent with good quality full-active cable assemblies (i.e., with circuitry on both ends of each differential signal pair of the cable assembly) constructed with shielded twinaxial cable with 26 AWG solid wire up to 10 m or optical cable assemblies up to 100 m, provided that no other TxRx connection segments are included in the TxRx connection.

Active cable assemblies that comply with active cable assembly electrical characteristics for 12 Gbit/s and 22.5 Gbit/s characteristics should also comply with active cable assembly electrical characteristics for 6 Gbit/s (see 5.5.8) with optical mode enabled and should operate within the specified bit error ratio at slower physical link rates.

5.6 Test loads

5.6.1 Test loads overview

This standard uses a test load methodology to specify transmitter device signal output characteristics (see 5.8.4.4) and delivered signal characteristics (see 5.8.5.4). This methodology specifies the signal as measured at specified probe points in specified test loads.

For OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s, the test loads used by the methodology are:

- a) zero-length test load (see 5.6.2): used for testing transmitter device compliance points and receiver device compliance points;
- b) transmitter compliance transfer function (TCTF) test load (see 5.6.3): used for testing transmitter device compliance points; and
- c) CIC (see SATA): used for testing transmitter device compliance points if SATA devices using Gen3i levels (see SATA) are supported.

For trained (e.g., the physical link rate is negotiated in Train_Rx-SNW (see SPL-5)) 6 Gbit/s, the test loads used by the methodology are:

- a) zero-length test load (see 5.6.2) used for:
 - A) testing transmitter device compliance points;
 - B) testing receiver device compliance points; and
 - C) used with a reference receiver device (see 5.8.5.7.3) in simulation to determine the delivered signal;
 and
- b) reference transmitter test load (see 5.6.4) is used with a reference receiver device (see 5.8.5.7.3) in simulation to determine the delivered signal.

For 12 Gbit/s, the zero-length test load (see 5.6.2) test load is used for:

- a) testing transmitter device compliance points;
- b) testing receiver device compliance points;
- c) measuring crosstalk; and
- d) capturing signals for use in simulation.

In addition to measurement with the zero-length test load, 12 Gbit/s may use end to end simulation and, depending on the usage model, use reference transfer functions to determine the delivered signal. See 5.7 and Annex C.

Physical positions denoted as probe points identify the position in the test load where the signal properties are measured, but do not imply that physical probing is used for the measurement. Physical probing may be disruptive to the signal and should not be used unless verified to be non-disruptive.

5.6.2 Zero-length test load

Figure 101 shows the zero-length test load as used for testing a transmitter device compliance point.

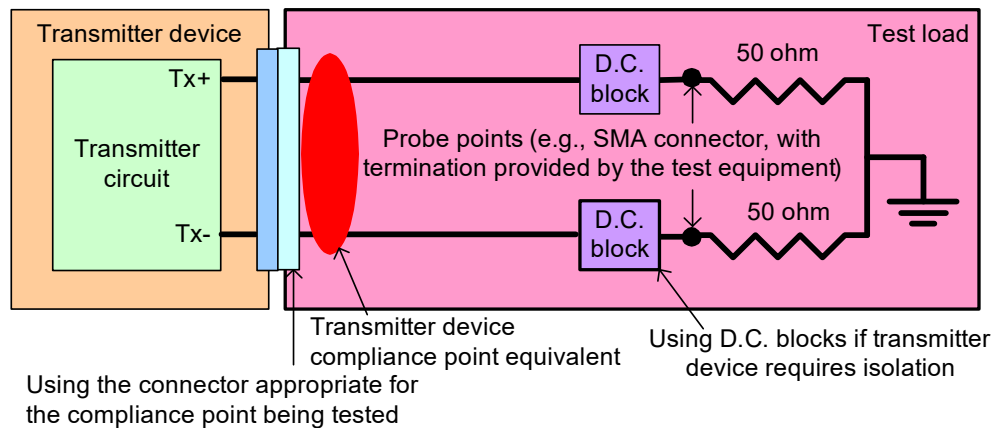


Figure 101 — Zero-length test load for transmitter device compliance point

Figure 102 shows the zero-length test load as used for testing a receiver device compliance point.

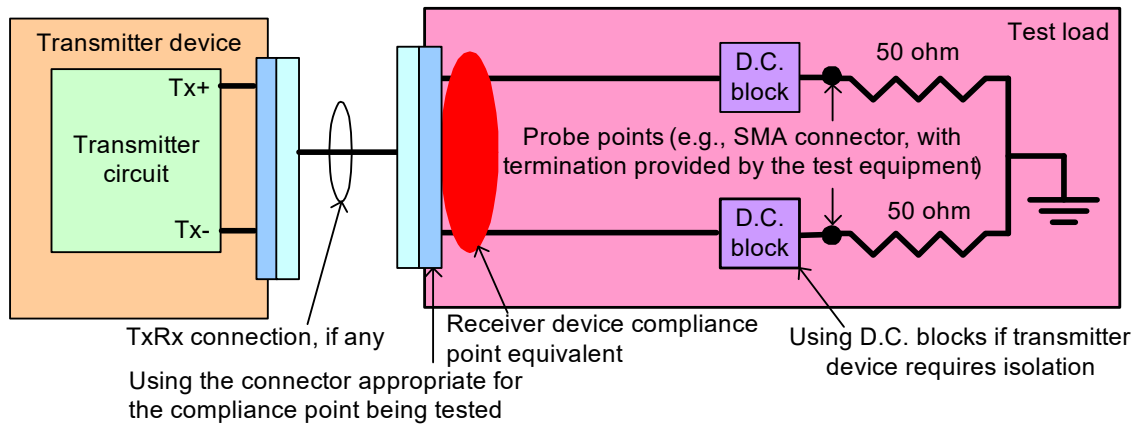


Figure 102 — Zero-length test load for receiver device compliance point

Figure 101 and figure 102 show ideal designs. Implementations may include:

- insertion loss between the compliance and probe points; and
- return loss due to one or more impedance mismatches between the compliance point and 50 Ω termination points.

Not shown are non-ideal effects of the test equipment raw measurements (e.g., additional insertion loss and return loss). For de-embedding methods to remove non-ideal effects, see Annex G.

Usage of fixturing and test equipment shall comply with the requirements defined in this subclause. The requirements in this subclause include the combined effects of the fixturing and test equipment.

The zero-length test load is defined by a set of S-parameters (see G.11). Only the magnitude of $S_{DD21}(f)$ and the magnitude of $S_{DD11}(f)$ are specified by this standard.

The zero-length test load for 6 Gbit/s and 12 Gbit/s, including all fixturing and instrumentation required for the measurement, shall comply with the following equations:

For $50 \text{ MHz} < f \leq 6.0 \text{ GHz}$:

$$|S_{DD21}(f)| \leq -20 \times \log_{10}(e) \times ((1.0 \times 10^{-6} \times \sqrt{f}) + (2.8 \times 10^{-11} \times f) + (5.3 \times 10^{-21} \times f^2)) - 0.2 \text{ dB}$$

$$|S_{DD11}(f)| \leq -15 \text{ dB}$$

where:

$|S_{DD21}(f)|$ is the magnitude of $S_{DD21}(f)$;

$|S_{DD11}(f)|$ is the magnitude of $S_{DD11}(f)$; and

f is the signal frequency in Hz.

Figure 103 shows the allowable $|S_{DD21}(f)|$ of a zero-length test load for 6 Gbit/s and 12 Gbit/s.

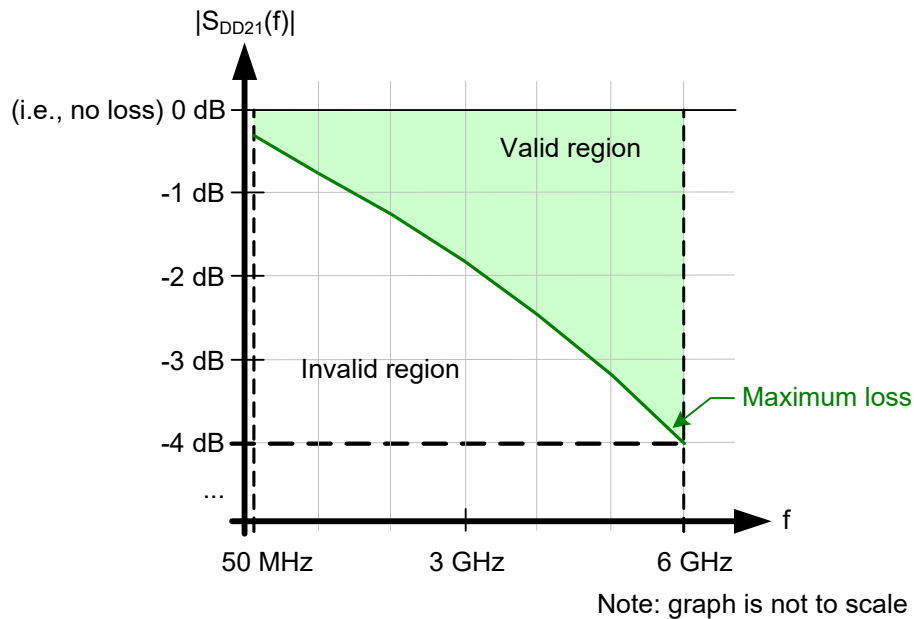


Figure 103 — Zero-length test load $|S_{DD21}(f)|$ requirements for 6 Gbit/s and 12 Gbit/s

The zero-length test load for 22.5 Gbit/s, including all fixturing and instrumentation required for the measurement, shall comply with the following equations:

For $50 \text{ MHz} < f \leq 11.25 \text{ GHz}$:

$$|S_{DD11}(f)| \leq -15 \text{ dB}; \text{ and}$$

$$|S_{DD21}(f)| \leq -20 \times \log_{10}(e) \times ((4.0 \times 10^{-7} \times \sqrt{f}) + (1.1 \times 10^{-11} \times f) + (2 \times 10^{-21} \times f^2)) - 0.2 \text{ dB}$$

where:

$|S_{DD11}(f)|$ is the magnitude of $S_{DD11}(f)$;

$|S_{DD21}(f)|$ is the magnitude of $S_{DD21}(f)$; and

f is the signal frequency in Hz.

Figure 104 shows the allowable $|S_{DD21}(f)|$ of a zero-length test load for 22.5 Gbit/s.

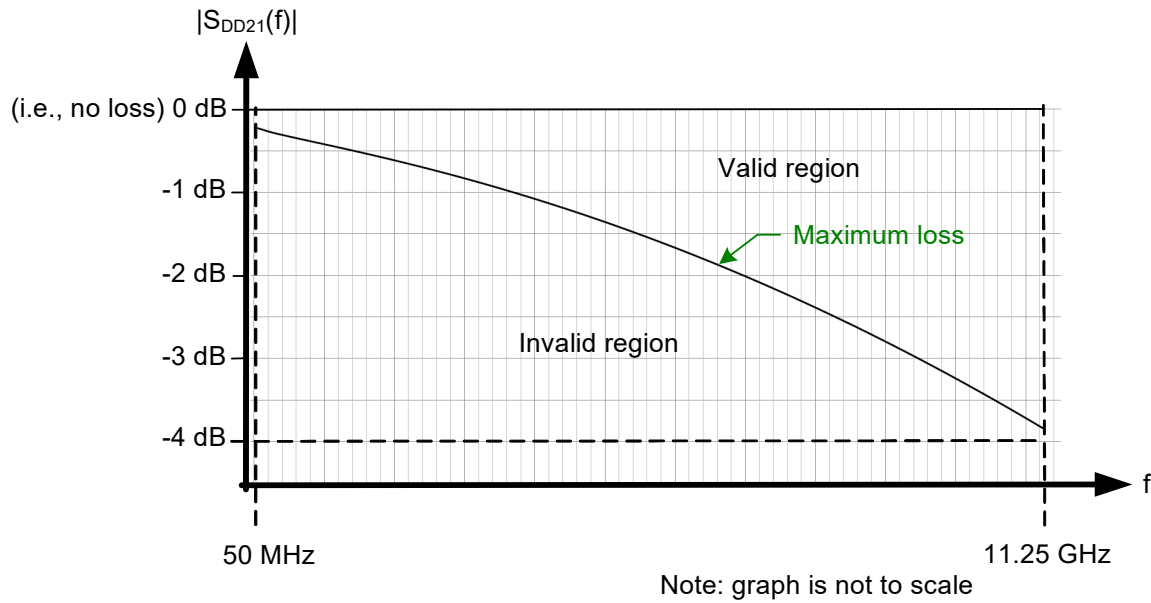


Figure 104 — Zero-length test load $|S_{DD21}(f)|$ requirements for 22.5 Gbit/s

5.6.3 TCTF test load

Figure 105 shows the TCTF test load. This test load is used for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s characterization.

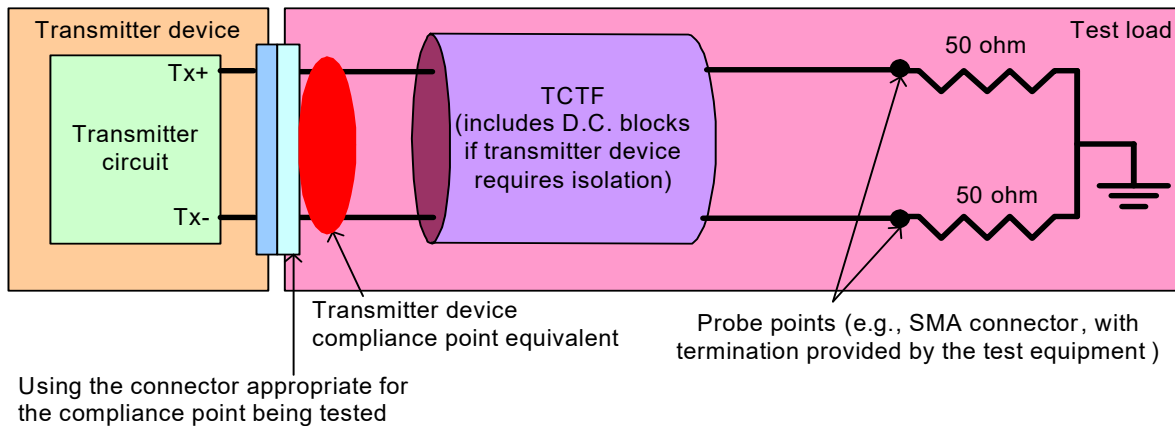


Figure 105 — TCTF test load

The TCTF test load shall meet the requirements in 5.5.2. The nominal impedance shall be the target impedance.

The TCTF test load is defined by a set of S-parameters (see G.11). Only the magnitude of $S_{DD21}(f)$ is specified by this standard.

For testing a transmitter device with an OOB signaling rate of 3 Gbit/s at IT, the TCTF test load shall comply with the following equations:

For 50 MHz < $f \leq 3.0$ GHz:

$$|S_{DD21}(f)| \leq -20 \times \log_{10}(e) \times ((6.5 \times 10^{-6} \times \sqrt{f}) + (2.0 \times 10^{-10} \times f) + (3.3 \times 10^{-20} \times f^2)) \text{ dB}$$

and for 3.0 GHz < $f \leq 5.0$ GHz:

$$|S_{DD21}(f)| \leq -10.9 \text{ dB}$$

and, specifying a minimum ISI loss:

$$|S_{DD21}(f = 300 \text{ MHz})| - |S_{DD21}(f = 1\,500 \text{ MHz})| > 3.9 \text{ dB}$$

where:

$|S_{DD21}(f)|$ is the magnitude of $S_{DD21}(f)$; and

f is the signal frequency in Hz.

Figure 106 shows the allowable $|S_{DD21}(f)|$ and minimum ISI loss of a TCTF test load and the $|S_{DD21}(f)|$ of a sample TCTF test load at IT for an OOB signaling rate of 3 Gbit/s.

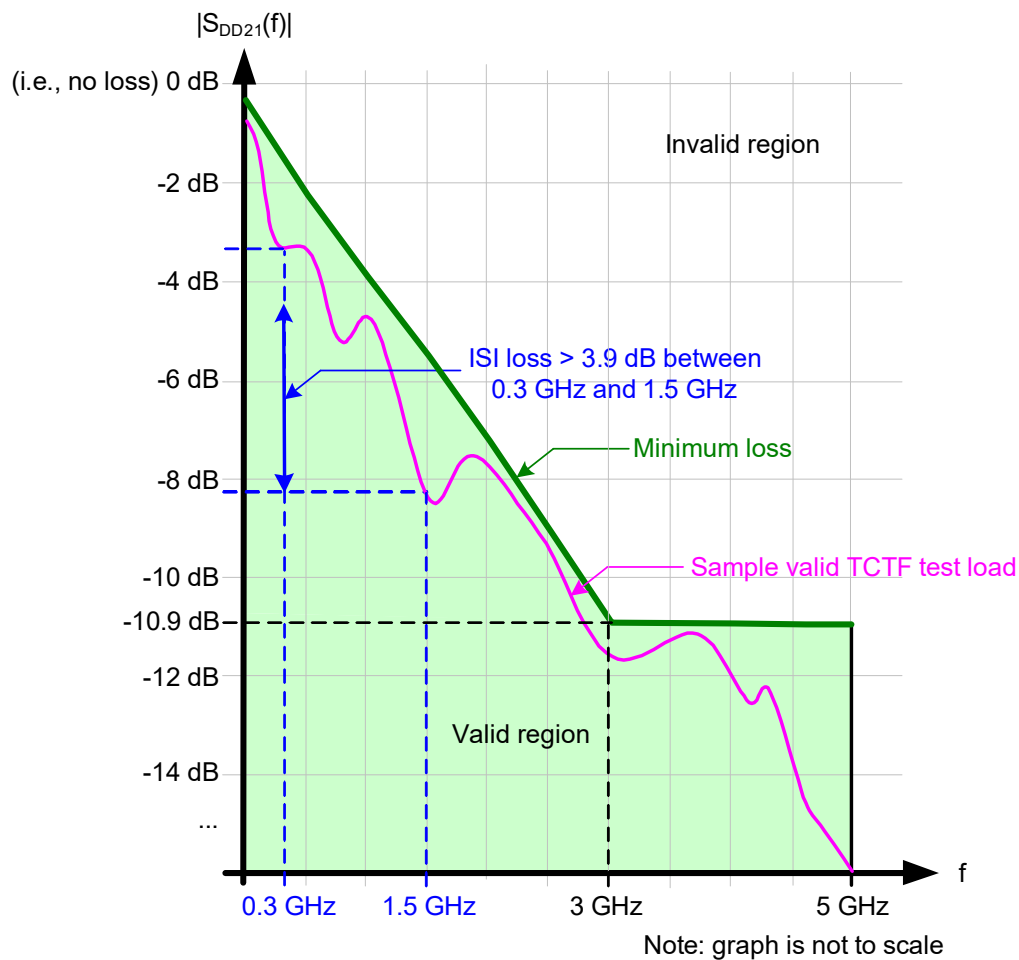


Figure 106 — TCTF test load $|S_{DD21}(f)|$ and ISI loss requirements at IT for an OOB signaling rate of 3 Gbit/s

For testing a transmitter device with an OOB signaling rate of 3 Gbit/s at CT, the TCTF test load shall comply with the following equations:

For $50 \text{ MHz} < f \leq 3.0 \text{ GHz}$:

$$|S_{DD21}(f)| \leq -20 \times \log_{10}(e) \times ((1.7 \times 10^{-5} \times \sqrt{f}) + (1.0 \times 10^{-10} \times f)) \text{ dB}$$

and for $3.0 \text{ GHz} < f \leq 5.0 \text{ GHz}$:

$$|S_{DD21}(f)| \leq -10.7 \text{ dB}$$

and, specifying a minimum ISI loss:

$$|S_{DD21}(f = 300 \text{ MHz})| - |S_{DD21}(f = 1500 \text{ MHz})| > 3.9 \text{ dB}$$

where:

$|S_{DD21}(f)|$ is the magnitude of $S_{DD21}(f)$; and

f is the signal frequency in Hz.

Figure 107 shows the allowable $|S_{DD21}(f)|$ and minimum ISI loss of a TCTF test load and the $|S_{DD21}(f)|$ of a sample TCTF test load at CT for an OOB signaling rate of 3 Gbit/s.

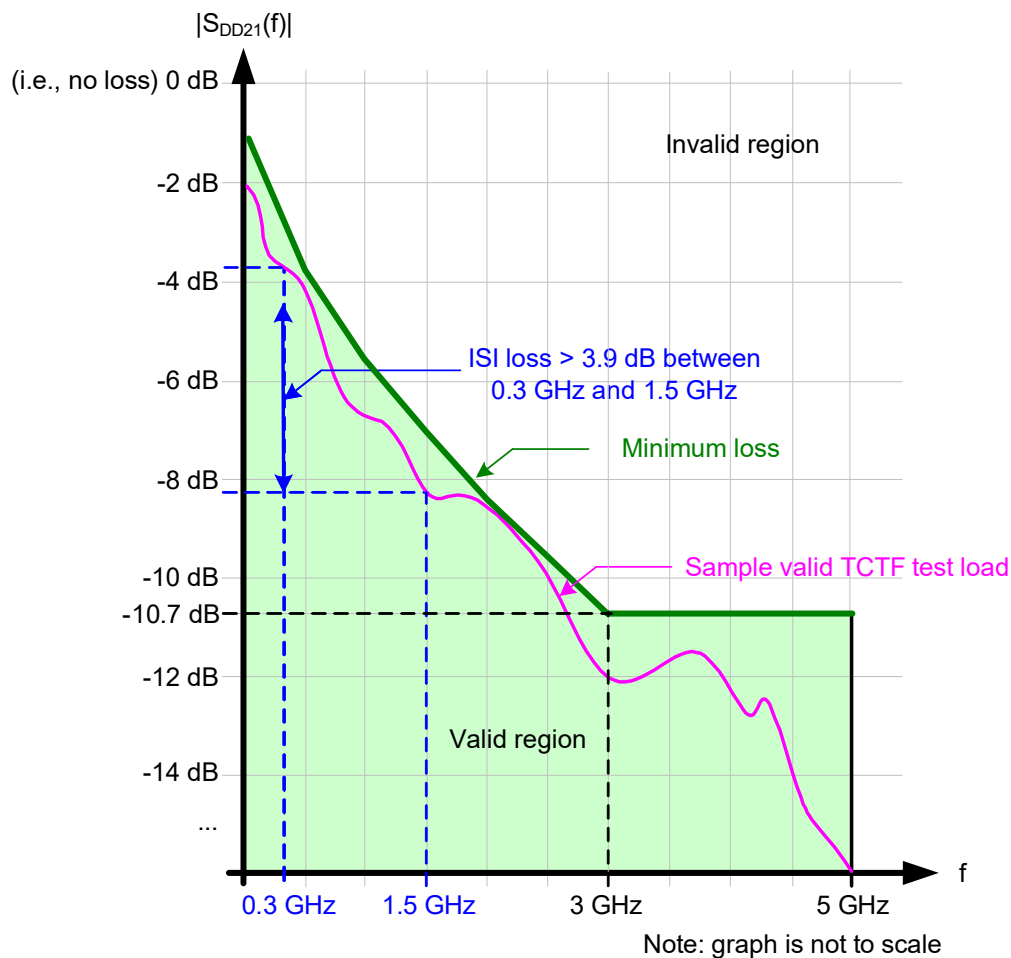


Figure 107 — TCTF test load $|S_{DD21}(f)|$ and ISI loss requirements at CT for an OOB signaling rate of 3 Gbit/s

For testing a transmitter device with an OOB signaling rate of 1.5 Gbit/s at IT, the TCTF test load shall comply with the following equations:

For $50 \text{ MHz} < f \leq 1.5 \text{ GHz}$:

$$|S_{DD21}(f)| \leq -20 \times \log_{10}(e) \times ((6.5 \times 10^{-6} \times \sqrt{f}) + (2.0 \times 10^{-10} \times f) + (3.3 \times 10^{-20} \times f^2)) \text{ dB}$$

and for $1.5 \text{ GHz} < f \leq 5.0 \text{ GHz}$:

$$|S_{DD21}(f)| \leq -5.4 \text{ dB}$$

and, specifying a minimum ISI loss:

$$|S_{DD21}(f = 150 \text{ MHz})| - |S_{DD21}(f = 750 \text{ MHz})| > 2.0 \text{ dB}$$

where:

$|S_{DD21}(f)|$ is the magnitude of $S_{DD21}(f)$; and

f is the signal frequency in Hz.

Figure 108 shows the allowable $|S_{DD21}(f)|$ and minimum ISI loss of a TCTF test load and the $|S_{DD21}(f)|$ of a sample TCTF test load at IT for an OOB signaling rate of 1.5 Gbit/s.

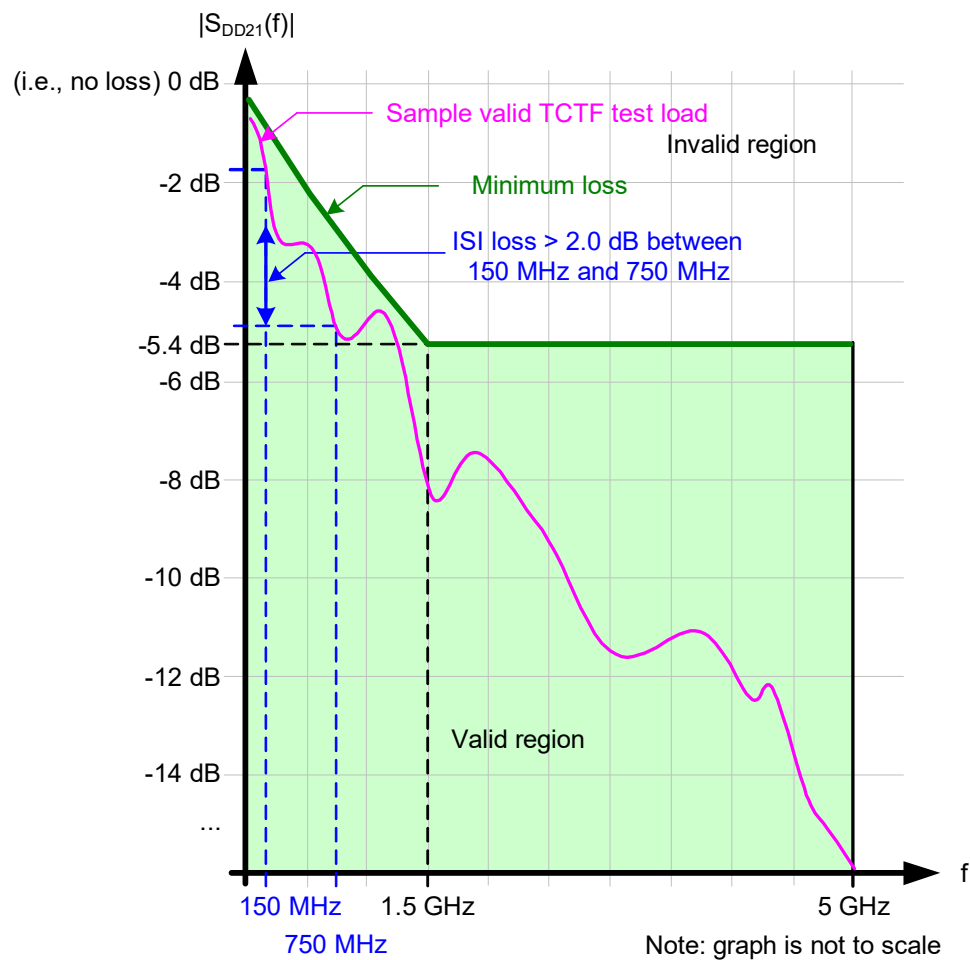


Figure 108 — TCTF test load $|S_{DD21}(f)|$ and ISI loss requirements at IT for an OOB signaling rate of 1.5 Gbit/s

For testing a transmitter device with an OOB signaling rate of 1.5 Gbit/s at CT, the TCTF test load shall comply with the following equations:

For 50 MHz < f ≤ 1.5 GHz:

$$|S_{DD21}(f)| \leq -20 \times \log_{10}(e) \times ((1.7 \times 10^{-5} \times \sqrt{f}) + (1.0 \times 10^{-10} \times f)) \text{ dB}$$

and for 1.5 GHz < f ≤ 5.0 GHz:

$$|S_{DD21}(f)| \leq -7.0 \text{ dB}$$

and, specifying a minimum ISI loss:

$$|S_{DD21}(f = 150 \text{ MHz})| - |S_{DD21}(f = 750 \text{ MHz})| > 2.0 \text{ dB}$$

where:

$|S_{DD21}(f)|$ is the magnitude of $S_{DD21}(f)$; and

f is the signal frequency in Hz.

Figure 109 shows the allowable $|S_{DD21}(f)|$ and minimum ISI loss of a TCTF test load and the $|S_{DD21}(f)|$ of a sample TCTF test load at CT for an OOB signaling rate of 1.5 Gbit/s.

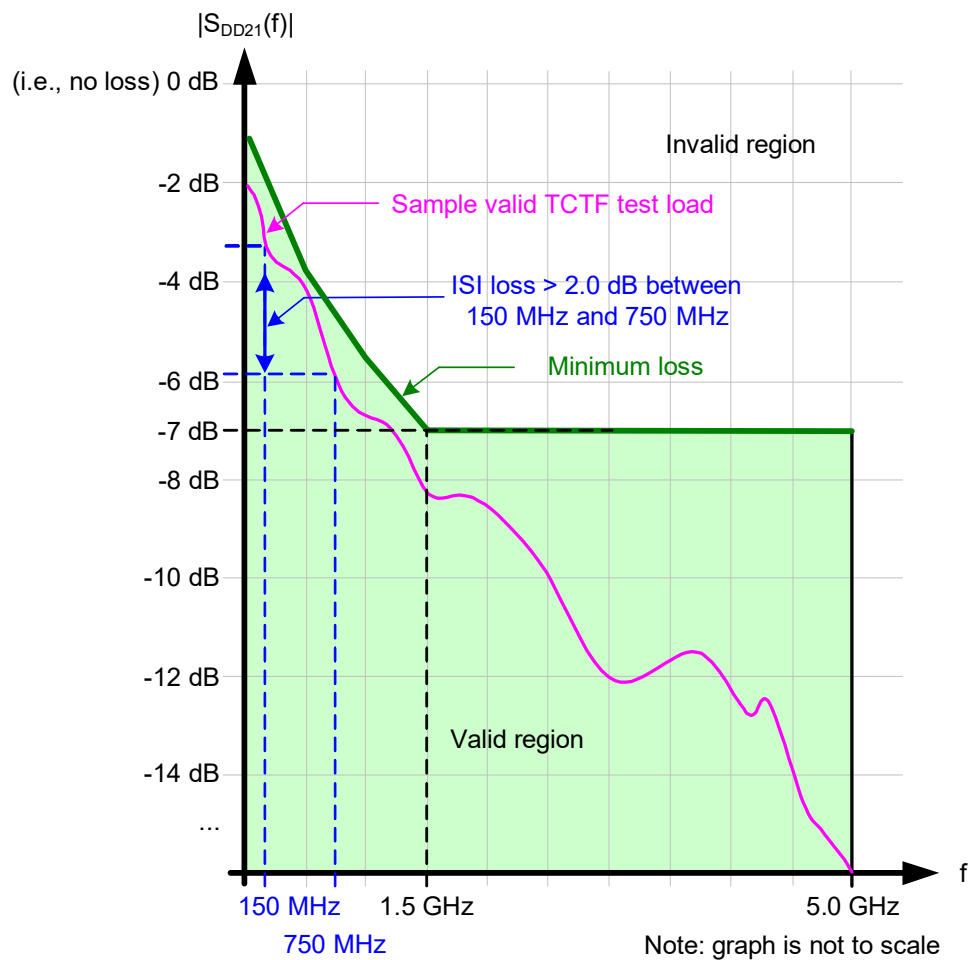


Figure 109 — TCTF test load $|S_{DD21}(f)|$ and ISI loss requirements at CT for an OOB signaling rate of 1.5 Gbit/s

5.6.4 Trained 6 Gbit/s reference transmitter test load

The reference transmitter test load for trained 6 Gbit/s is a set of parameters defining the electrical performance characteristics of a 10 m cable assembly, used:

- in simulation to determine compliance of a transmitter device (see 5.8.4.5); and
- as a representative component of an ISI generator used to determine compliance of a receiver device (see 5.8.5.7.6).

The following Touchstone model of the reference transmitter test load is included with this standard:

- SAS2_transmittertestload.s4p.

See Annex H for a description of how the Touchstone model was created.

Figure 110 shows the reference transmitter test load $|S_{DD21}(f)|$ up to 6 GHz.

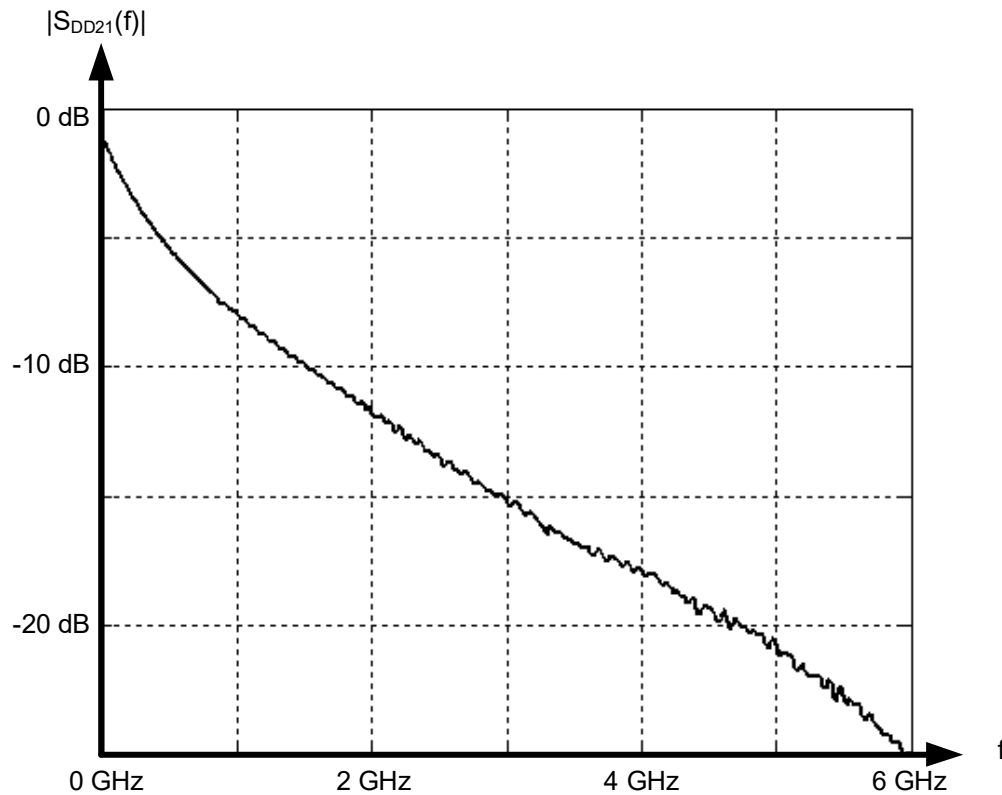


Figure 110 — Trained 6 Gbit/s reference transmitter test load $|S_{DD21}(f)|$ up to 6 GHz

Figure 111 shows the trained 6 Gbit/s reference transmitter test load pulse response.

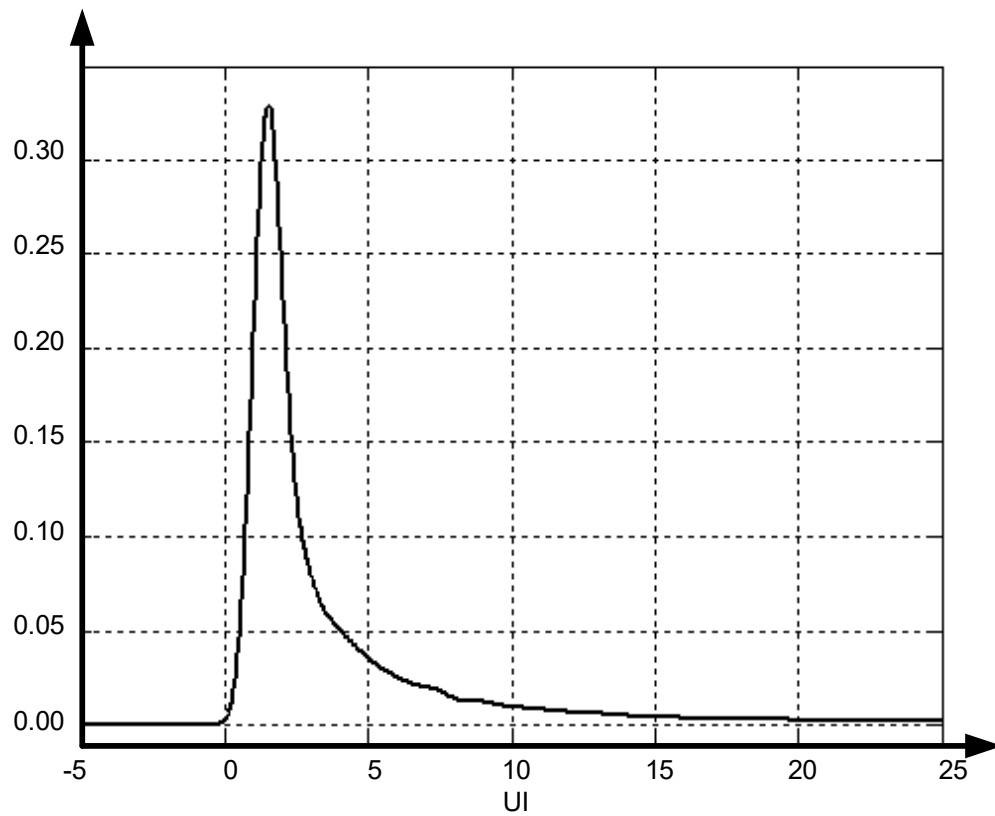


Figure 111 — Trained 6 Gbit/s reference transmitter test load pulse response

The following impulse response model of the trained 6 Gbit/s reference transmitter test load is included with this standard:

a) sas2_stressor_6g0_16x.txt.

Figure 112 shows the trained 6 Gbit/s reference transmitter test load impulse response found in the sas2_stressor_6g0_16x.txt.

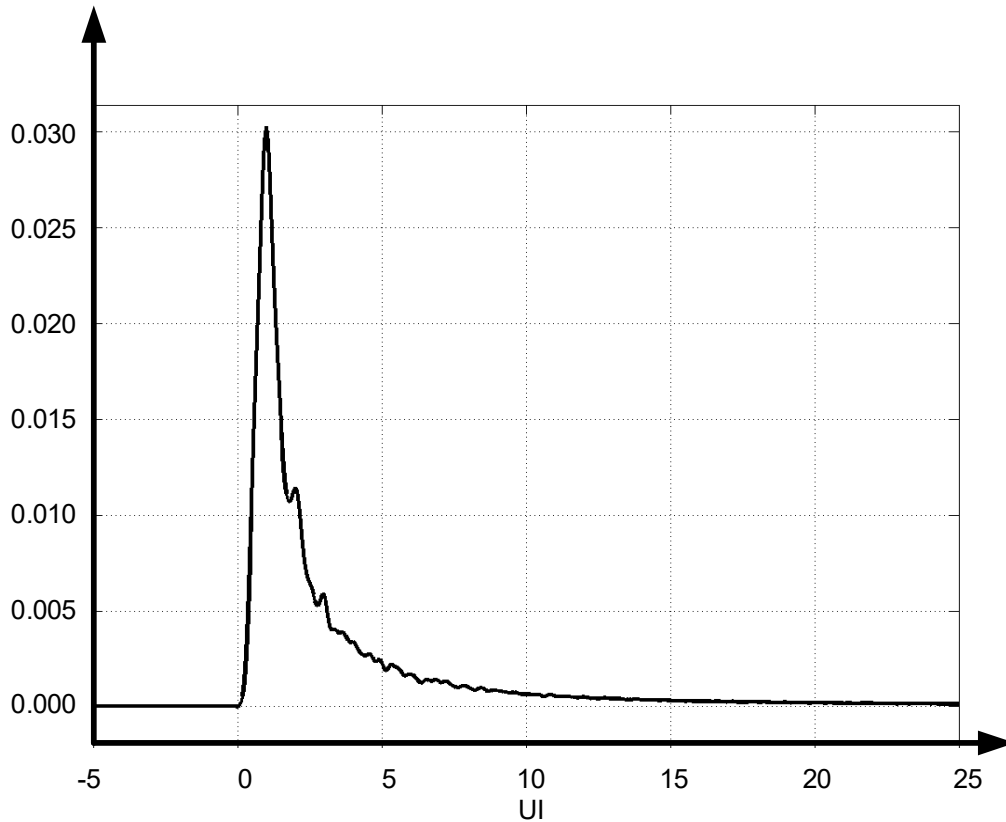


Figure 112 — Trained 6 Gbit/s reference transmitter test load impulse response for 6 Gbit/s

Figure 113 shows the trained 6 Gbit/s reference transmitter test load repeating 0011b pattern or 1100b pattern (e.g., D24.3) response.

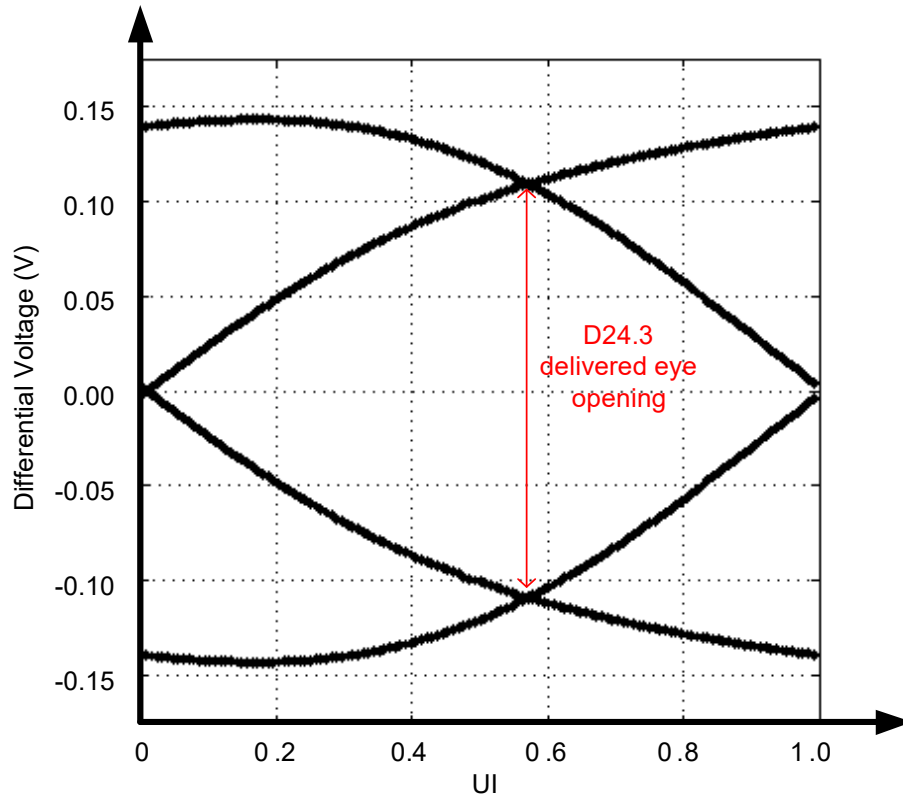


Figure 113 — Trained 6 Gbit/s reference transmitter test load D24.3 response

5.7 End to end simulation for trained 12 Gbit/s

5.7.1 End to end simulation for trained 12 Gbit/s overview

End to end simulation shall be used to verify characteristics of:

- transmitter devices connected to passive TxRx connections (see 5.8.4.6.5);
- passive TxRx connections (see 5.5.6); and
- ISI generators providing the stressed receiver signal input for receiver devices connected to passive TxRx connections (see 5.8.5.7.6.6).

The specific end to end simulation procedures defined in 5.8.4.6.5, 5.5.6, and 5.8.5.7.6.6 follow this sequence:

- capture the signal from a transmitter device with no equalization and without SSC into a zero-length test load or model the transmitter using the reference transmitter (see 5.8.4.6.4);
- connect passive TxRx connection segments, crosstalk, reference transmitter, and reference receiver according to the reference end to end simulation diagram (see 5.7.2 and C.2);
- in the simulator, set the transmitter reference equalization (see 5.7.3 and figure 148) and set the receiver reference DFE equalization (see 5.8.5.7.3); and
- perform a linear simulation, including the effects of edge rates, ISI, and crosstalk (see C.1).

The end to end simulation uses a reference transmitter with RJ and TJ set to zero. RJ and TJ and non-linear behavior present in the captured signal used for simulation are removed by the simulation process. Margins for these effects are provided in the required simulation characteristics. The simulation characteristics are processed at a BER of 10^{-15} .

Crosstalk transmitters are simulated using reference transmitters. These reference transmitters shall be set to the characteristics of table C.1. The crosstalk transmitters shall be asynchronous to the data sent to the channel under test.

Characteristics are measured from the simulation at specified measurement points for the usage model and characterization type (see table 31, table 56, and table 77).

5.7.2 Usage models for end to end simulation for trained 12 Gbit/s

A set of transfer functions is required to complement the measured S-parameter or captured signal to provide an end to end simulation model. C.2 describes the different S-parameter files that shall be used for each usage model, with their associated measurement points.

Each transmitter device, receiver device, or passive TxRx connection segment shall be simulated with the appropriate usage model (see C.2).

The S-parameter files provided in the SAS3 directory of SAS-4_1.zip use the port mapping of G.11.3. The FEXT S-parameters and NEXT S-parameters are extracted as shown in figure 114.

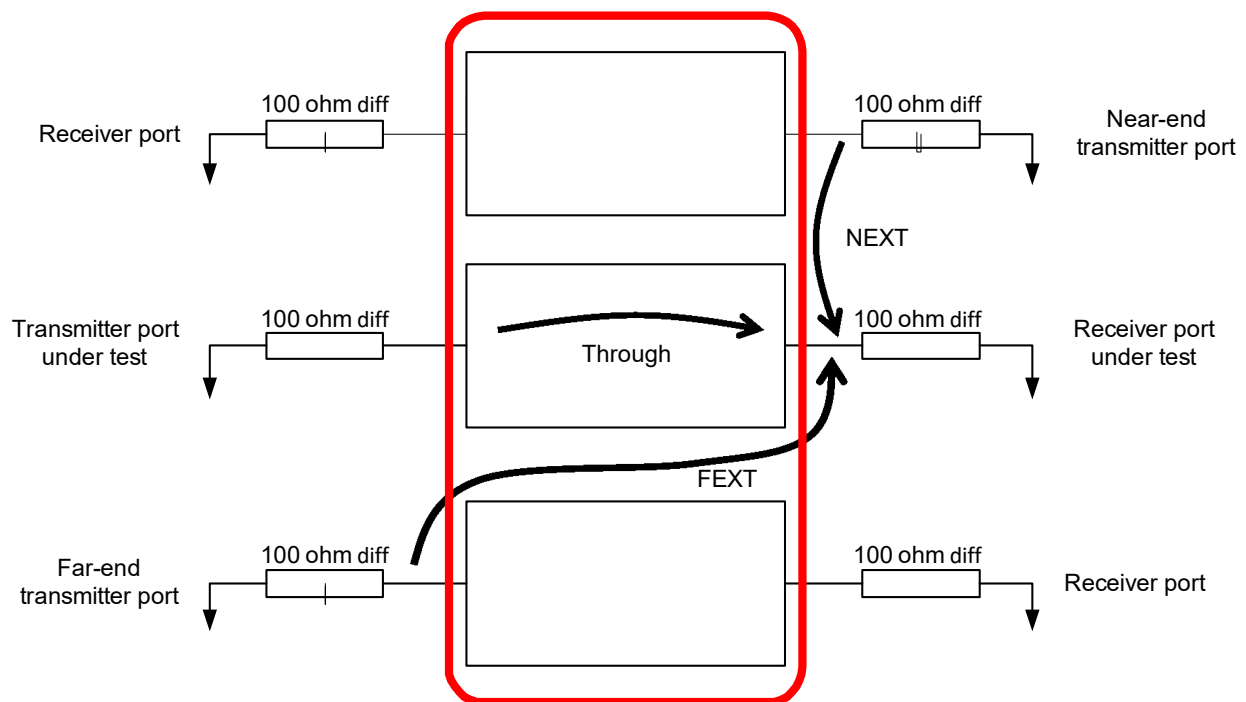


Figure 114 — NEXT and FEXT measurement definition

See Annex C for a description of the procedure that shall be used for end to end simulations. See E.1 for additional information regarding the S-parameter for 12 Gbit/s simulations.

5.7.3 Reference transmitter equalization for trained 12 Gbit/s

The reference transmitter equalization shall be calculated using the procedure described in this subclause, which requires the unequalized pulse response of the TxRx connection between ET and the input of the reference receiver (i.e., RR) (see C.2). Extraction of pulse responses from captured signals or transfer functions is beyond the scope of this standard, however, an example is provided in SAS3_EYEOPENING (see the SAS3 directory of SAS-4_1.zip).

The reference transmitter equalization procedure is as follows:

- 1) compute the reference sampling instant from the unequalized pulse response between ET and RR (see figure 115);
- 2) set coefficient 2 (i.e., C_2) of a reference transmitter to one and K_0 to one;
- 3) provide the unequalized pulse response between ET and RR as the input of the reference transmitter, and compute the coefficient 1 (i.e., C_1) and coefficient 3 (i.e., C_3) that result in a pulse response with the smallest sum of squared error to an ideal pulse, at instants separated from the reference sampling instant by integer multiples of a one UI period (see figure 116);
- 4) calculate an equalized pulse response by convolving the coefficients obtained in steps 2) and 3) with the unequalized pulse response between ET and RR;
- 5) calculate the reference sampling instant from the equalized pulse response;
- 6) repeat steps 2) through 5) until the coefficients and sampling point converge (see figure 117); and
- 7) normalize the final coefficients found in steps 3) and 4) by dividing them by $(|C_1| + |C_3| + 1)$.

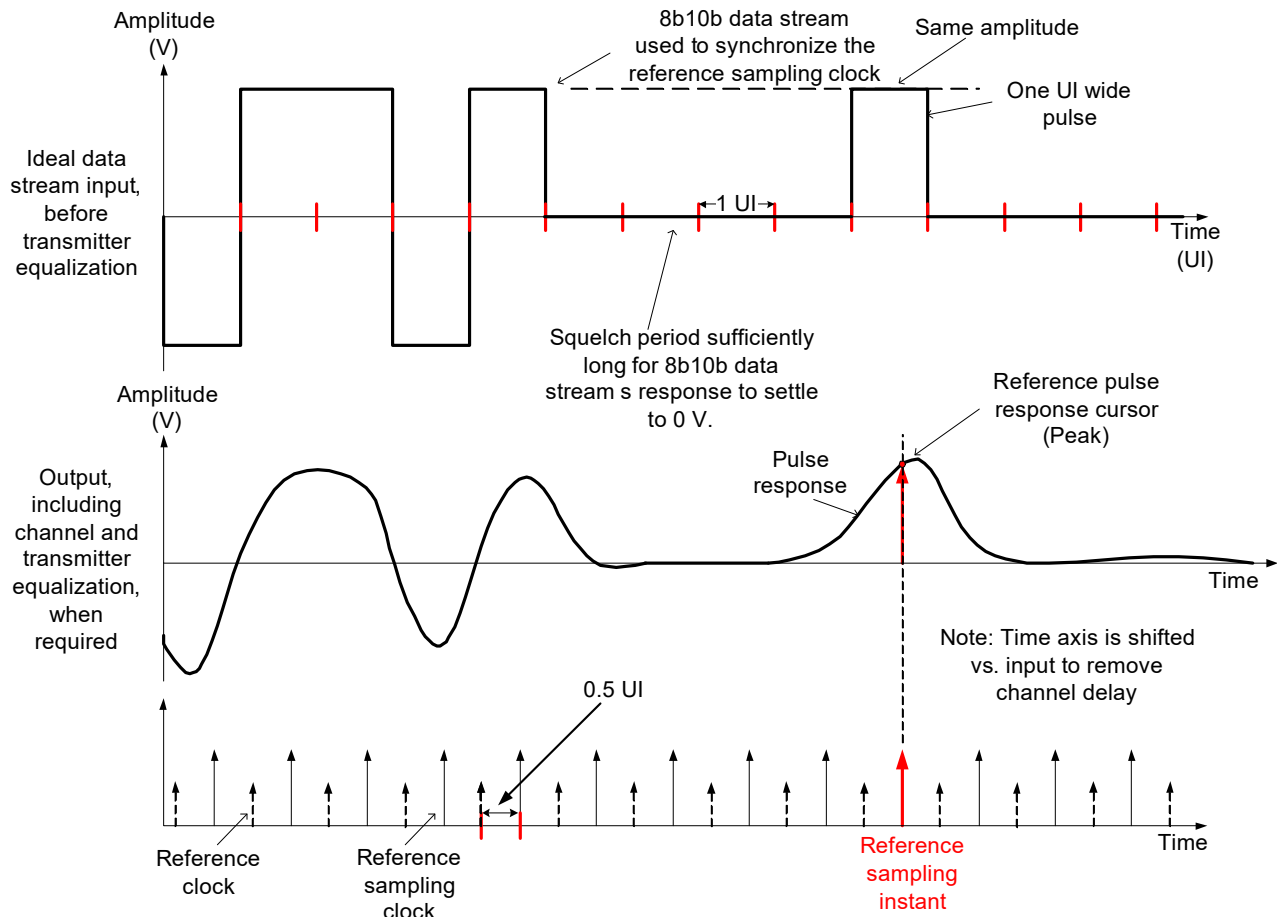


Figure 115 — Reference sampling point and reference pulse response cursor

Figure 116 shows the computations of step 3). A one UI spaced filter of coefficients $[C1, C2 = 1, C3]$ is convolved with the extracted end to end pulse response. Coefficient 1 and coefficient 3 are computed to produce an equalized pulse response that has the smallest sum of squared errors at the sampling instants defined by a reference sampling clock.

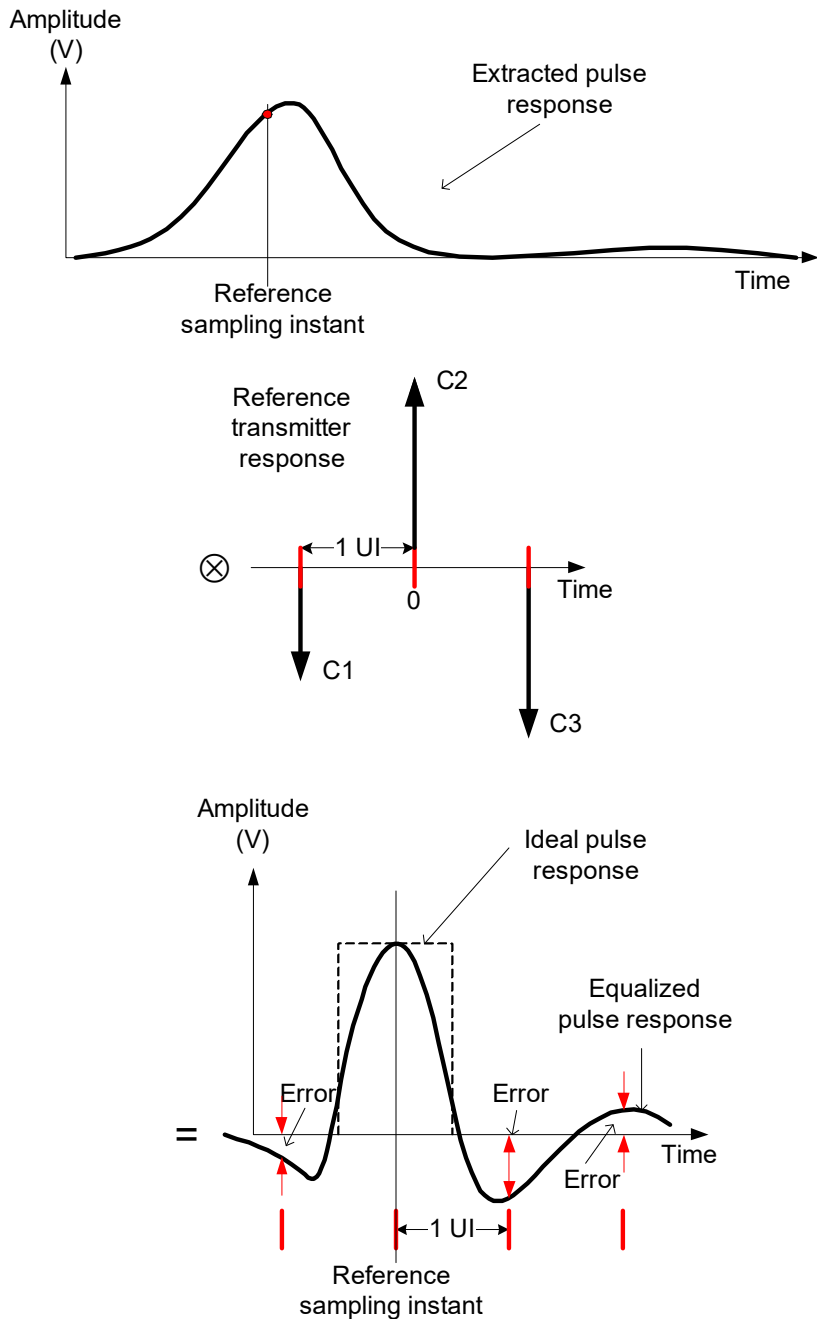


Figure 116 — Reference transmitter coefficient error computation

The reference sampling instant is computed from:

- 1) the unequalized pulse response from ET to RR, for the first iteration; and
- 2) the equalized pulse response using transmitter coefficients from the previous iteration, for other iterations.

The reference sampling instant changes when the coefficients from the current iteration are used to compute the equalized pulse response. As shown in figure 117, the process of calculating C1 and C3 is repeated with the reference sampling instant computed from the last equalized pulse response, until the coefficients and reference sampling instant converge to stable values.

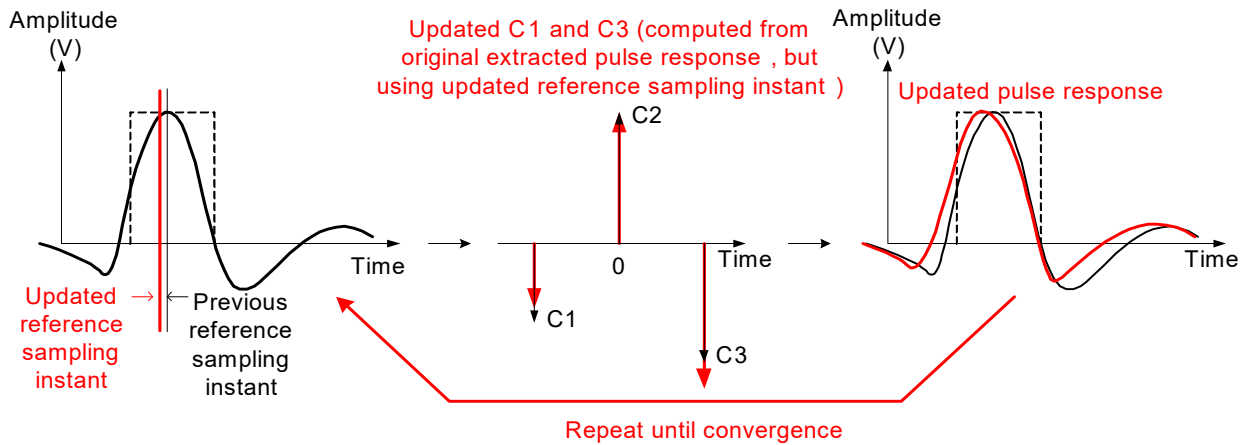


Figure 117 — Convergence of reference transmitter equalization

If either coefficient 1 (i.e., C1) or coefficient 3 (i.e., C3) takes a positive value during this procedure, then its value is forced to zero and only the other coefficient is computed. If both coefficients need to be forced to zero, then the procedure stops.

5.7.4 Crosstalk measurement for end to end simulations and 12 Gbit/s jitter tolerance

End to end channel simulation shall include crosstalk. Crosstalk shall be measured using:

- a) crosstalk transfer functions (e.g., S-parameters, see G.11); or
- b) total peak to peak crosstalk measurement.

The following procedure shall be used to measure total peak to peak crosstalk:

- 1) calculate the reference transmitter equalization for the TxRx connection segment under test (see 5.7.3);
- 2) terminate the TxRx connection segment under test on the transmitter end;
- 3) connect 12 Gbit/s transmitters to the source of all or a subset of crosstalk channels;
- 4) set the crosstalk transmitters to transmit asynchronous IDLE dwords (see SPL-5) using the characteristics in table C.1;
- 5) measure the asynchronous amplitude histogram at the end of the TxRx connection segment under test, into a zero-length test load, with an acquisition bandwidth of at least 9 GHz, and a capture of at least 2×10^7 UI;
- 6) repeat steps 2) through 4) until all crosstalk sources have been measured;
- 7) when multiple measurements are made, convolve the histograms to obtain the total crosstalk histogram; and
- 8) from the total crosstalk histogram evaluate the crosstalk amplitude that is met or exceeded at a cumulative probability of 10^{-6} using the following procedure:
 - 1) separate positive samples from negative samples, ensuring at least 10^7 samples are collected for each type;
 - 2) calculate the vertical histogram for the positive samples;
 - 3) from the histogram, compute the crosstalk voltage that is met or exceeded at a probability of 10^{-6} ;
 - 4) calculate the vertical histogram for the opposite of the negative samples (i.e., zero minus the samples);
 - 5) from the histogram, calculate the crosstalk voltage that is met or exceeded at a probability of 10^{-6} ; and
 - 6) sum the peak crosstalk voltages calculated in steps 3) and 5).

To provide a variety of pattern combinations for the crosstalk measurement, the digital IDLE dwords should be aligned differently one crosstalk channel to another and the transmission frequencies of the crosstalk transmitters should be different one from another.

The channel under test shall be terminated with the characteristics of the transmitter device termination (see table 43) on the transmitter end. The termination should be implemented using:

- a) a high-bandwidth termination having impedance close to the nominal differential impedance (see table 28), for TxRx connection segments; or
- b) a transmitter device set to transmit D.C. idle while maintaining the characteristics of table 43 for transmitter circuits and ISI generators.

Active circuits create noise when transmitting signals, including D.C. idle. By measuring the crosstalk with active circuits connected, the crosstalk value reported includes this noise. This is representative of the noise generated when the active circuit is transmitting data. When multiple crosstalk measurements are performed, this noise may however be overestimated in the final crosstalk amplitude calculation. Appropriate measurement techniques should be used to minimize these effects.

For transmitter device characterization, the crosstalk transmitters shall set coefficient 1 (i.e., C1) to zero, set coefficient 3 (i.e., C3) to zero, and set maximum peak to peak voltage.

For receiver ISI stress generators, the crosstalk is measured into a zero-length test load, and shall not include crosstalk from the receiver under test. A crosstalk generator channel should be selected to provide signal characteristics as close as possible to the required crosstalk signal characteristics (see table C.5), with the crosstalk generator characteristics defined by table C.1. Peak to peak voltage should then be adjusted to meet the required crosstalk characteristics.

5.8 Transmitter device and receiver device electrical characteristics

5.8.1 General electrical characteristics

Table 40 defines the general electrical characteristics, which apply to both transmitter devices and receiver devices.

Table 40 — General electrical characteristics

Characteristic	Units	1.5 Gbit/s (i.e., G1) ^a	3 Gbit/s (i.e., G2) ^a	6 Gbit/s (i.e., G3)	12 Gbit/s (i.e., G4)	22.5 Gbit/s (i.e., G5)
Physical link rate (nominal)	MBps	150	300	600	1 200	2 400
Unit interval (UI) (nominal) ^b	ps	666. $\overline{6}$	333. $\overline{3}$	166. $\overline{6}$	83. $\overline{3}$	44. $\overline{4}$
Baud rate (f _{baud}) (nominal)	Gigasymbols/s	1.5	3	6	12	22.5
Minimum A.C. coupling capacitor ^{c d}	nF	N/A				176
Maximum A.C. coupling capacitor ^{c d}	nF	12				265
Maximum noise during OOB idle time ^{e f}	mV(P-P)	120				
<div>^a Applies only for OOB signaling characteristics.</div> <div>^b 666.$\overline{6}$ (i.e., 2 000 / 3), 333.$\overline{3}$ (i.e., 1 000 / 3), 166.$\overline{6}$ (i.e., 500 / 3), 83.$\overline{3}$ (i.e., 250 / 3), and 44.$\overline{4}$ (i.e., 133.$\overline{3}$ / 3).</div> <div>^c The coupling capacitor value for A.C. coupled transmit and receive pairs. See 5.8.4.2 for coupling requirements for transmitter devices. See 5.8.5.2 for coupling requirements for receiver devices. The equivalent series resistance at 3 GHz should be less than 1 Ω.</div> <div>^d The G5 coupling capacitor value may be used at rates of 6 Gbit/s and 12 Gbit/s.</div> <div>^e With a measurement bandwidth of 1.5 × f_{baud} (e.g., 18 GHz for 12 Gbit/s), no signal level during the idle time shall exceed the specified maximum differential amplitude.</div> <div>^f This is not applicable when optical mode is enabled.</div>						

5.8.2 Transmitter device and receiver device transients

Transients may occur at transmitter devices or receiver devices as a result of changes in supply power conditions or mode transitions.

A mode transition is an event that may result in a measurable transient due to the response of the transmitter device or receiver device. The following conditions constitute a mode transition:

- enabling or disabling driver circuitry;
- enabling or disabling receiver common mode circuitry;
- hot plug event;
- adjusting driver amplitude;
- enabling or disabling de-emphasis; and
- adjusting terminator impedance.

Transmitter device transients are measured at nodes V_P and V_N with respect to GROUND on the test circuit shown in figure 118 during all power state and mode transitions. Receiver device transients are measured at nodes V_P and V_N with respect to GROUND on the test circuit shown in figure 119 during all power state and mode transitions. Test conditions shall include power supply power on and power off conditions, voltage sequencing, and mode transitions.

Figure 118 shows the test circuit attached to IT or CT to test transmitter device transients.

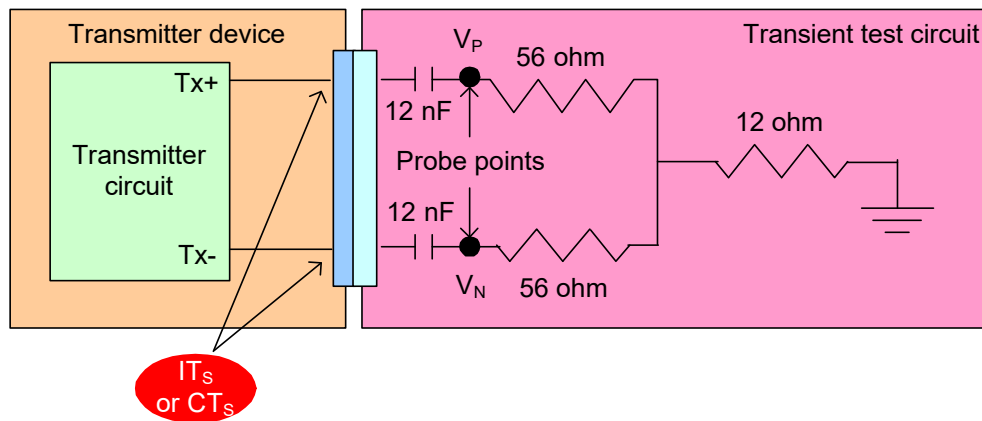


Figure 118 — Transmitter device transient test circuit

Figure 119 shows the test circuit attached to IR or CR to test receiver device transients.

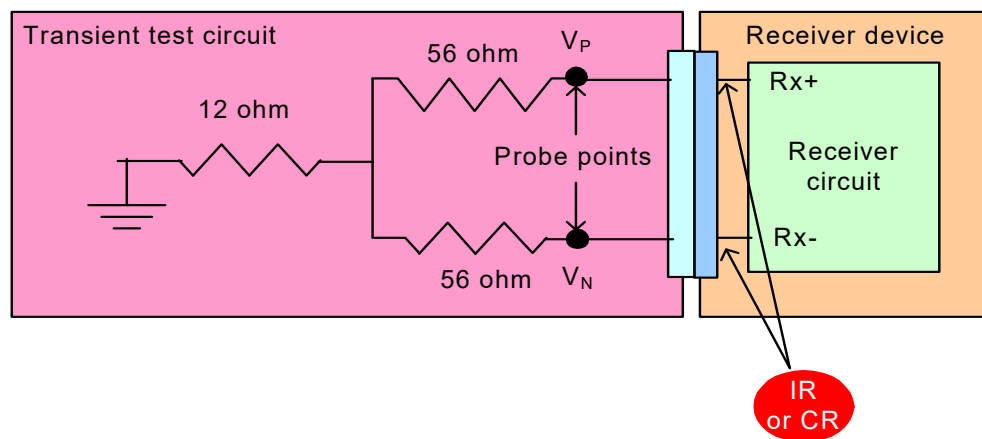


Figure 119 — Receiver device transient test circuit

5.8.3 Eye masks and the JTF

5.8.3.1 Eye masks overview

The eye masks shown in 5.8.3 shall be interpreted as graphical representations of the voltage and time limits of the signal. The eye mask boundaries define the eye contour of the 10^{-12} jitter population for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s measured eyes.

For OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s, equivalent time sampling oscilloscope technology is not practical for measuring compliance to the eye masks. See MJSQ for methods that are suitable for verifying compliance to these eye masks.

CJTPAT (see Annex A) shall be used for all jitter testing unless otherwise specified. Annex A defines the required pattern on the physical link and provides information regarding special considerations for running disparity (see SPL-5) and scrambling (see SPL-5).

5.8.3.2 JTF

With the possible presence of SSC, the application of a single pole high-pass frequency-weighting function that progressively attenuates jitter at 20 dB/decade below a frequency of ($f_{\text{baud}} / 1\ 667$) as specified in To differentiate between allowable timing variation due to SSC and jitter, the frequency-weighting JTF shall be applied to the signal at the compliance point when determining the eye mask.

The jitter measurement device shall comply with the JTF. The reference clock characteristics are controlled by the resulting JTF characteristics obtained by taking the time difference between the PLL output (i.e., the reference clock) and the data stream sourced to the PLL. The PLL's closed loop transfer function's -3 dB corner frequency and other adjustable parameters (e.g., peaking) are determined by the value required to meet the requirements of the JTF.

The JTF shall have the characteristics specified in table 41 for a repeating 0011b pattern or 1100b pattern (e.g., D24.3). See the phy test patterns in the Protocol Specific diagnostic page in SPL-5.

The JTF -3 dB corner frequency and the magnitude peaking requirements shall be measured with SJ applied, with a peak to peak amplitude of 0.3 UI, with a relative tolerance of $\pm 10\%$. The relative attenuation at 30 kHz shall be measured with sinusoidal phase (i.e., time) modulation applied, with a peak to peak amplitude of 20.8 ns with a relative tolerance of $\pm 10\%$. See Annex G for the calibration procedure.

A proportional decrease of the JTF -3 dB corner frequency should be observed for a decrease in pattern transition density compared to a 0.5 transition density. If a JMD shifts the JTF -3 dB corner frequency in a manner that does not match this characteristic, or does not shift at all, then measurements of jitter with patterns with transition densities different than 0.5 may lead to discrepancies in reported jitter levels. In the case of reported jitter discrepancies between JMDs, the JMD with the shift of the -3 dB corner frequency that is closest to the proportional characteristic of the reference transmitter test load (see 5.6.4) shall be considered correct. This characteristic may be measured with the conditions defined above for measuring the -3 dB corner frequency but substituting other patterns with different transition densities.

Table 41 — JTF parameters

Characteristic	Without SSC support			With SSC support		
	6 Gbit/s ^a	12 Gbit/s	22.5 Gbit/s	6 Gbit/s ^a	12 Gbit/s	22.5 Gbit/s
JTF -3 dB point (kHz) ^{b c}	3 600 ± 500	3 600 ± 500	3 600 ± 500	2 600 ± 500	2 600 ± 500	2 600 ± 500
JTF slope (dB/decade)	20	20	20	40	40	40
Attenuation at 30 kHz ± 1 % (dB) ^d	N/A	N/A	N/A	73.5 ± 1.5	73.5 ± 1.5	73.5 ± 1.5
Maximum Peaking (dB)	3.5	3.5	3.5	3.5	3.5	3.5
Key: N/A = not applicable f _{baud} = Units of Hz (i.e., 6.0 GHz for 6 Gbit/s). 12 Gbit/s and 22.5 Gbit/s use the value for 6 Gbit/s.						
^a OOB signaling at 1.5 Gbit/s and 3 Gbit/s use the 6 Gbit/s values. ^b For trained without SSC support this value equals $f_{\text{baud}}/1\,667 \pm 500$ kHz for 6 Gbit/s, 12 Gbit/s, and 22.5 Gbit/s,. ^c For trained with SSC support this value equals $(f_{\text{baud}})^{0.5} \times 33.566 \times \text{Hz}^{0.5} \pm 500$ kHz for 6 Gbit/s, 12 Gbit/s, and 22.5 Gbit/s,. ^d For ,trained with SSC support this value equals $73.5 \text{ dB} + [20 \times \log_{10}(f_{\text{baud}} / 6 \times 10^9 \text{ Hz})] \text{ dB} \pm 1.5 \text{ dB}$ for 6 Gbit/s, 12 Gbit/s, and 22.5 Gbit/s,.						

5.8.3.3 Transmitter device eye mask for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s

Figure 120 describes the eye mask used for testing the signal output of the transmitter device at IT and CT for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s (see table 63). This eye mask applies to jitter after the application of the JTF (see 5.8.3.2).

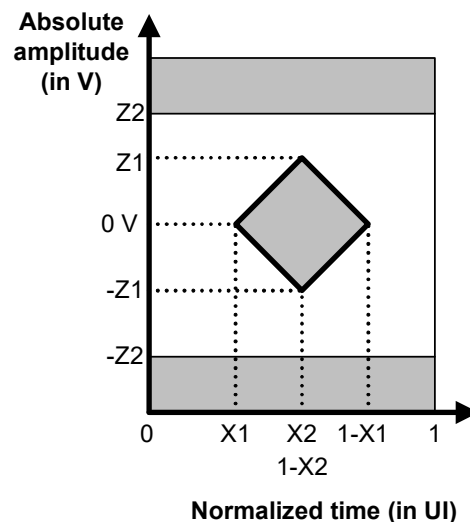


Figure 120 — Transmitter device eye mask

Verifying compliance with the limits represented by the transmitter device eye mask should be done with reverse channel traffic present on the channel under test and with forward and reverse traffic present on all other channels, in order that the effects of crosstalk are taken into account.

5.8.3.4 Receiver device eye mask for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s

Figure 121 describes the eye mask used for testing the signal delivered to the receiver device at IR and CR for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s (see table 67). This eye mask applies to jitter after the application of the JTF (see 5.8.3.2). This requirement accounts for the low frequency tracking properties and response time of the CDR circuitry in receiver devices.

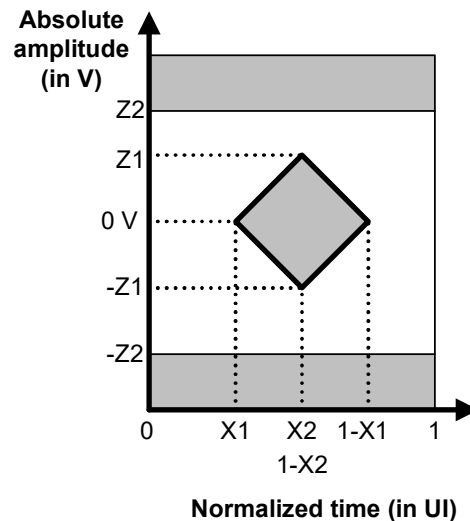


Figure 121 — Receiver device eye mask

Verifying compliance with the limits represented by the receiver device eye mask should be done with reverse channel traffic present on the channel under test and with forward and reverse traffic present on all other channels, in order that the effects of crosstalk are taken into account.

5.8.3.5 Receiver device jitter tolerance eye mask for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s

Figure 122 describes the eye mask used to test the jitter tolerance of the receiver device at IR and CR for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s (see table 67).

The eye mask shall be constructed as follows:

- X2 and Z2 shall be the values for the delivered signal listed in table 67;
- $X1_{OP}$ shall be half the value of TJ for maximum delivered jitter listed in table 68; and
- $X1_{TOL}$ shall be half the value of TJ for receiver device jitter tolerance listed in table 69, for applied SJ frequencies above $(f_{baud} / 1667)$.

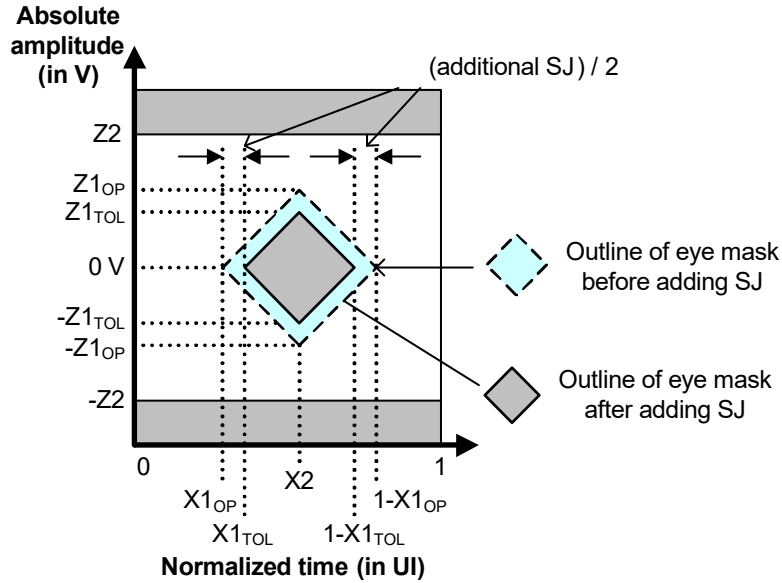


Figure 122 — Deriving a receiver device jitter tolerance eye mask for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s

The leading and trailing edge slopes of the receiver device eye mask in figure 121 shall be preserved. As a result, the amplitude value of Z1 is less than that given for the delivered signal in table 67, and $Z1_{TOL}$ and $Z1_{OP}$ shall be defined from those slopes by the following equation:

$$Z1_{TOL} = Z1_{OP} \times \frac{X2 - \left(\frac{ASJ}{2}\right) - X1_{OP}}{X2 - X1_{OP}}$$

where:

- $Z1_{TOL}$ is the value for Z1 to be used for the receiver device jitter tolerance eye mask;
- $Z1_{OP}$ is the Z1 value for the delivered signal in table 67;
- $X1_{OP}$ is the X1 value for the delivered signal in table 67;
- X2 is the X2 value for the delivered signal in table 67; and
- ASJ is the additional SJ for applied SJ frequencies above ($f_{baud} / 1\ 667$) (see figure 139 in 5.8.5.6).

The X1 points in the receiver device jitter tolerance eye mask (see figure 122) are greater than the X1 points in the receiver device eye mask (see figure 121) due to the addition of SJ.

5.8.4 Transmitter device characteristics

5.8.4.1 Transmitter device characteristics overview

Transmitter devices operating at 6 Gbit/s should use the transmitter equalization settings provided in table 48. See SATA for untrained 6 Gbit/s (i.e., SATA Gen3i) transmitter device signal output characteristics. Transmitter devices operating at 12 Gbit/s and 22.5 Gbit/s shall support transmitter training (see SPL-5) unless the transmitter device is operating in the optical mode.

Compliance points referenced in the electrical requirement tables are shown in 5.3 unless otherwise specified.

See G.7 for a methodology for measuring transmitter device signal output.

5.8.4.2 Transmitter device coupling requirements

Coupling requirements for transmitter devices are as follows:

- a) transmitter devices using inter-enclosure TxRx connections (i.e., attached to CT compliance points) should be D.C. coupled, however, may be A.C. coupled to the interconnect through a transmission network; or
- b) transmitter devices using intra-enclosure TxRx connections (i.e., attached to IT compliance points) should be D.C. coupled, however, may be A.C. coupled.

If the transmitter device is attached to an IT compliance point supporting a PCIe device, then the coupling requirements of PCIe devices (see PCIe) should be considered regarding its impact to the implementation.

See table 40 for the coupling capacitor value.

5.8.4.3 Transmitter device general electrical characteristics

Table 42 defines the transmitter device general electrical characteristics.

Table 42 — Transmitter device general electrical characteristics

Characteristic	Units	1.5 Gbit/s ^a	3 Gbit/s ^a	6 Gbit/s	12 Gbit/s	22.5 Gbit/s
Physical link rate accuracy ^b at IT and CT	ppm	± 100				
Physical link rate SSC modulation at IT and CT	ppm	See table 83, table 84, and table 85				
Maximum transmitter device transients ^c	V	± 1.2				
^a Applies only for OOB signaling characteristics. ^b Physical link rate accuracy shall be measured over a minimum of 1 x 10 ⁶ UI and should be measured using a minimum resolution of 100 Hz. ^c See 5.8.2 for transient test circuits and conditions.						

Table 43 defines the transmitter device termination characteristics.

Table 43 — Transmitter device termination characteristics

Characteristic	Units	Trained 6 Gbit/s	Trained 12 Gbit/s	Trained 22.5 Gbit/s
Differential impedance ^a	Ω	See 5.8.4.5.1	See 5.8.4.6.1	See 5.8.4.7.1
Maximum differential impedance imbalance ^{a b}	Ω	See 5.8.4.5.3 ^c	See 5.8.4.6.3 ^c	See 5.8.4.7.3 ^c
Common mode impedance ^b	Ω	See 5.8.4.5.1	See 5.8.4.6.1	See 5.8.4.7.1
^a All transmitter device termination measurements are made through mated connector pairs. ^b The difference in measured impedance to SIGNAL GROUND on the plus and minus terminals on the interconnect, transmitter device, or receiver device, with a differential test signal applied to those terminals. ^c Measurement replaced by S_{CD22} specifications (i.e., differential to common mode conversion).				

5.8.4.4 Transmitter device OOB signal output characteristics for rates of 1.5 Gbit/s and 3 Gbit/s as measured with the zero-length test load

Table 44 specifies the OOB signal output characteristics for the transmitter device for rates of 1.5 Gbit/s and 3 Gbit/s as measured with the zero-length test load (see 5.6.2) attached at a transmitter device compliance point (i.e., IT or CT). All specifications are based on differential measurements.

Table 44 — Transmitter device OOB signal output characteristics for rates of 1.5 Gbit/s and 3 Gbit/s as measured with the zero-length test load at IT and CT

OOB Signal characteristic ^a	Units	1.5 Gbit/s	3 Gbit/s
Maximum intra-pair skew ^b	ps	20	15
Maximum transmitter device off voltage ^{c d}	mV(P-P)	50	
Maximum (i.e., slowest) rise/fall time ^e	ps	273	137
Maximum transmitter output imbalance ^f	%	10	
<div><div><div><div><div><div>^a</div><div>All tests in this table shall be performed with zero-length test load (see 5.6.2).</div></div></div><div><div><div>^b</div><div>The intra-pair skew measurement shall be made at the midpoint of the transition with a repeating 01b pattern or 10b pattern (e.g., D10.2 or D21.5) (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5) on the physical link. The same stable trigger, coherent to the data stream, shall be used for both the TX+ and TX- signals. Intra-pair skew is defined as the time difference between the means of the midpoint crossing times of the TX+ signal and the TX- signal.</div></div></div><div><div><div>^c</div><div>The transmitter device off voltage is the maximum A.C. voltage measured at compliance points IT and CT when the transmitter is unpowered or transmitting D.C. idle (e.g., during idle time of an OOB signal).</div></div></div><div><div><div>^d</div><div>This is not applicable when optical mode is enabled.</div></div></div><div><div><div>^e</div><div>Rise/fall times are measured from 20 % to 80 % of the transition with a repeating 01b pattern or 10b pattern (e.g., D10.2 or D21.5) (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5) on the physical link.</div></div></div><div><div><div>^f</div><div>The maximum difference between the V+ and V- A.C. rms transmitter device amplitudes measured with CJTPAT (see Annex A) into the zero-length test load shown in figure 101, as a percentage of the average of the V+ and V- A.C. rms amplitudes.</div></div></div></div></div></div>			

5.8.4.5 Transmitter device signal output characteristics for trained 6 Gbit/s

5.8.4.5.1 Transmitter device signal output characteristics for trained 6 Gbit/s overview

Table 45 specifies the signal output characteristics for the transmitter device for trained 6 Gbit/s as measured with the zero-length test load (see 5.6.2), unless otherwise specified, attached at a transmitter device compliance point (i.e., IT or CT). All specifications are based on differential measurements except for common mode measurements.

Table 45 — Transmitter device signal output characteristics for trained 6 Gbit/s at IT and CT

Signal characteristic	Units	Minimum	Nominal	Maximum
Peak to peak voltage (V_{P-P}) ^a	mV(P-P)	850		1 200
Transmitter device off voltage ^{b c}	mV(P-P)			50
Reference differential impedance ^d	Ω		100	
Reference common mode impedance ^d	Ω		25	
Common mode voltage limit (rms) ^e	mV			30
RJ ^{f g}	UI			0.15 ^h
TJ ^{g i}	UI			0.25 ^j
WDP at 6 Gbit/s ^k	dB			13

^a See 5.8.4.5.6 for the V_{P-P} measurement method.

^b The transmitter device off voltage is the maximum A.C. voltage measured at compliance points IT and CT when the transmitter is unpowered or transmitting D.C. idle (e.g., during idle time of an OOB signal).

^c This is not applicable when optical mode is enabled.

^d See 5.8.4.5.3 for transmitter device S-parameters characteristics.

^e This is a broadband limit. For additional limits on spectral content, see figure 123 and table 46.

^f The RJ measurement shall be performed with a repeating 0011b pattern or 1100b pattern (e.g., D24.3) (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5) with SSC disabled. RJ is 14 times the RJ 1 sigma value, based on a BER of 10^{-12} . For simulations based on a BER of 10^{-15} , the RJ specified is 16 times the RJ 1 sigma value.

^g The measurement shall include the effects of the JTF (see 5.8.3.2).

^h 0.15 UI is 25 ps at 6 Gbit/s.

ⁱ The TJ measurement shall be performed with a repeating 0011b pattern or 1100b pattern (e.g., D24.3) (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5). If the transmitter device supports SSC, then this test shall be performed with both SSC enabled and SSC disabled. TJ is equivalent to BUJ + RJ. ISI is minimized by the test pattern.

^j 0.25 UI is 41.6 ps at 6 Gbit/s.

^k See 5.8.4.5.2 for the transmitter device test procedure.

Table 46 defines the transmitter device common mode voltage limit characteristics.

Table 46 — Transmitter device common mode voltage limit characteristics

Characteristic	Reference	L ^a (dBmV) ^b	N ^a (dBmV) ^{b c}	S ^a (dBmV/decade) ^b	f _{min} ^a (MHz)	f _{max} ^a (GHz)
Spectral limit of common mode voltage ^d	Figure 123	12.7	26.0	13.3	100	6.0
<p>^a See figure 4 in 5.2 for definitions of L, N, S, f_{min}, and f_{max}. For this parameter, units of dBmV is used in place of dB.</p> <p>^b For dBmV, the reference level of 0 dBmV is 1 mV (rms). Hence, 0 dBm is 1 mW which is 158 mV (rms) across 25 Ω (i.e., the reference impedance for common mode voltage) which is $20 \times \log_{10}(158) = +44$ dBmV. +26 dBmV is therefore -18 dBm.</p> <p>^c Maximum value at the Nyquist frequency (i.e., 3 GHz) (see figure 123).</p> <p>^d The transmitter device common mode voltage shall be measured with a 1 MHz resolution bandwidth through the range of 100 MHz to 6 GHz with the transmitter device output of CJTPAT (see Annex A). The end points of the range shall be at the center of the measurement bandwidth.</p>						

Figure 123 shows the transmitter device common mode voltage limit defined in table 46.

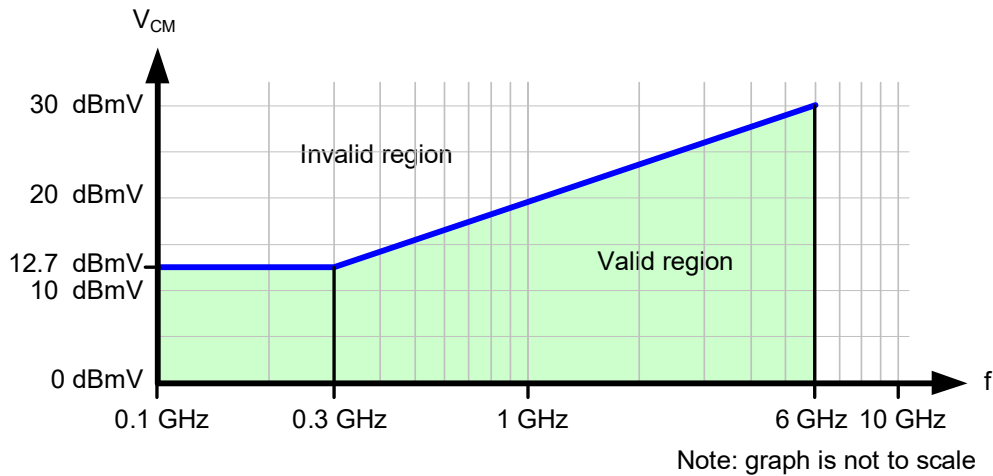


Figure 123 — Transmitter device common mode voltage limit

5.8.4.5.2 Trained 6 Gbit/s transmitter device test procedure

The transmitter device test procedure is as follows:

- 1) attach the transmitter device to a zero-length test load, where its signal output is captured by an oscilloscope;
- 2) configure the transmitter device to transmit the SCRAMBLED_0 pattern (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5);
- 3) configure the transmitter device to minimize DCD and BUJ;
- 4) capture multiple sets of the first 58 data dwords (i.e., 2 320 bits on the physical link) of the SCRAMBLED_0 pattern. Use averaging to minimize RJ; and
- 5) input the captured pattern into SASWDP simulation (see Annex B) with the usage variable set to 'SAS2_TWDP'.

The WDP value is a characterization of the signal output within the reference receiver device (see 5.8.5.7.3) after equalization. WDP values computed by SASWDP are influenced by all sources of eye closure including DCD, BUJ, and ISI, and increased variability in results may occur due to increases in those sources other than ISI.

5.8.4.5.3 Trained 6 Gbit/s transmitter device S-parameter limits

S-parameter limits are calculated per the following formula:

$$\text{Measured value} < \max [L, \min [H, N + 13.3 \times \log_{10}(f / 3 \text{ GHz})]]$$

where:

- L is the minimum value (i.e., the low frequency asymptote);
- H is the maximum value (i.e., the high frequency asymptote);
- N is the value at 3 GHz;
- f is the frequency of the signal in Hz;
- $\max [A, B]$ is the maximum of A and B; and
- $\min [A, B]$ is the minimum of A and B.

The frequency for N is based on the Nyquist at 6 Gbit/s.

Table 47 defines the maximum limits for S-parameters of the transmitter device.

Table 47 — Maximum limits for S-parameters at IT_S or CT_S

Characteristic ^{a b}	L ^c (dB)	N ^c (dB)	H ^c (dB)	S ^c (dB / decade)	f _{min} ^c (MHz)	f _{max} ^c (GHz)
S _{CC22}	-6.0	-5.0	-1.0	13.3	100	6.0
S _{DD22}	-10	-7.9	-3.9	13.3	100	6.0
S _{CD22}	-26	-12.7	-10	13.3	100	6.0
^a For S-parameter measurements, the transmitter device under test shall transmit a repeating 0011b pattern or 1100b pattern (e.g., D24.3) (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5). The amplitude applied by the test equipment shall be less than -4.4 dBm (i.e., 190 mV zero to peak) per port (see G.11.4.2). ^b S _{DC22} is not specified. ^c See figure 4 for definitions of L, N, H, S, f _{min} , and f _{max} .						

Figure 124 shows the transmitter device $|S_{CC22}|$, $|S_{DD22}|$, and $|S_{CD22}|$ limits defined in table 47.

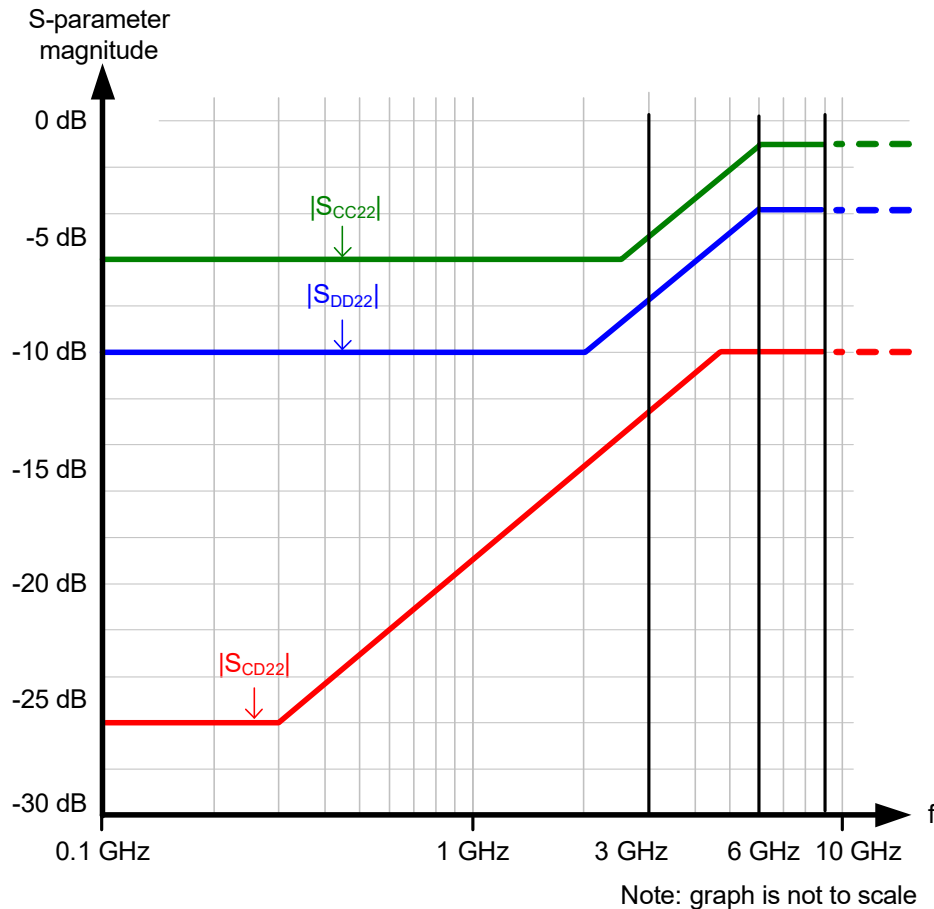


Figure 124 — Transmitter device $|S_{CC22}|$, $|S_{DD22}|$, and $|S_{CD22}|$ limits

5.8.4.5.4 Recommended trained 6 Gbit/s transmitter device settings for interoperability

Table 48 defines recommended values for trained 6 Gbit/s transmitter devices to provide interoperability with a broad range of implementations utilizing compliant TxRx connections and compliant receiver devices. The values are based on the evaluation of simulations with a variety of characterized physical hardware. Use of the recommended values does not guarantee that an implementation is capable of achieving a specific BER.

Specific implementations may obtain increased margin by deviating from the recommended values, however, such implementations are beyond the scope of this standard.

Table 48 — Recommended 6 Gbit/s transmitter device settings at IT and CT

Characteristic	Units	Minimum	Nominal	Maximum
Differential voltage swing (mode) (VMA) ^a	mV	600	707	
Transmitter equalization ^a	dB	2	3	4
^a See 5.8.4.5.6 for measurement method.				

5.8.4.5.5 Trained 6 Gbit/s reference transmitter device characteristics

The trained 6 Gbit/s reference transmitter device is a set of parameters defining the electrical performance characteristics of a transmitter device used in simulation to determine compliance of a TxRx connection (see 5.5.5).

Figure 125 shows a trained 6 Gbit/s reference transmitter device.

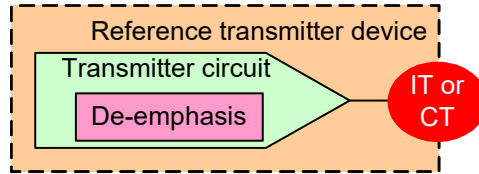


Figure 125 — Trained 6 Gbit/s reference transmitter device

Table 49 defines the trained 6 Gbit/s reference transmitter device characteristics.

Table 49 — Trained 6 Gbit/s reference transmitter device characteristics at IT and CT

Characteristic	Units	Value
Peak to peak voltage (V_{P-P}) ^a	mV(P-P)	850
Transmitter equalization ^a	dB	2
Maximum (i.e., slowest) rise/fall time ^b	UI	0.41 ^c
RJ	UI	0.15 ^d
BUJ	UI	0.10 ^e
^a See 5.8.4.5.6 for measurement method. ^b Rise/fall times are measured from 20 % to 80 % of the transition with a repeating 01b pattern or 10b pattern (e.g., D10.2 or D21.5) (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5). ^c 0.41 UI is 68.3 ps at 6 Gbit/s. ^d 0.15 UI is 25 ps at 6 Gbit/s. ^e 0.10 UI is 16.6 ps at 6 Gbit/s.		

The following Touchstone model of the reference transmitter device termination is included with this standard:

- a) SAS2_TxRefTerm.s4p.

Figure 126 shows the S-parameters of the trained 6 Gbit/s reference transmitter device termination model.

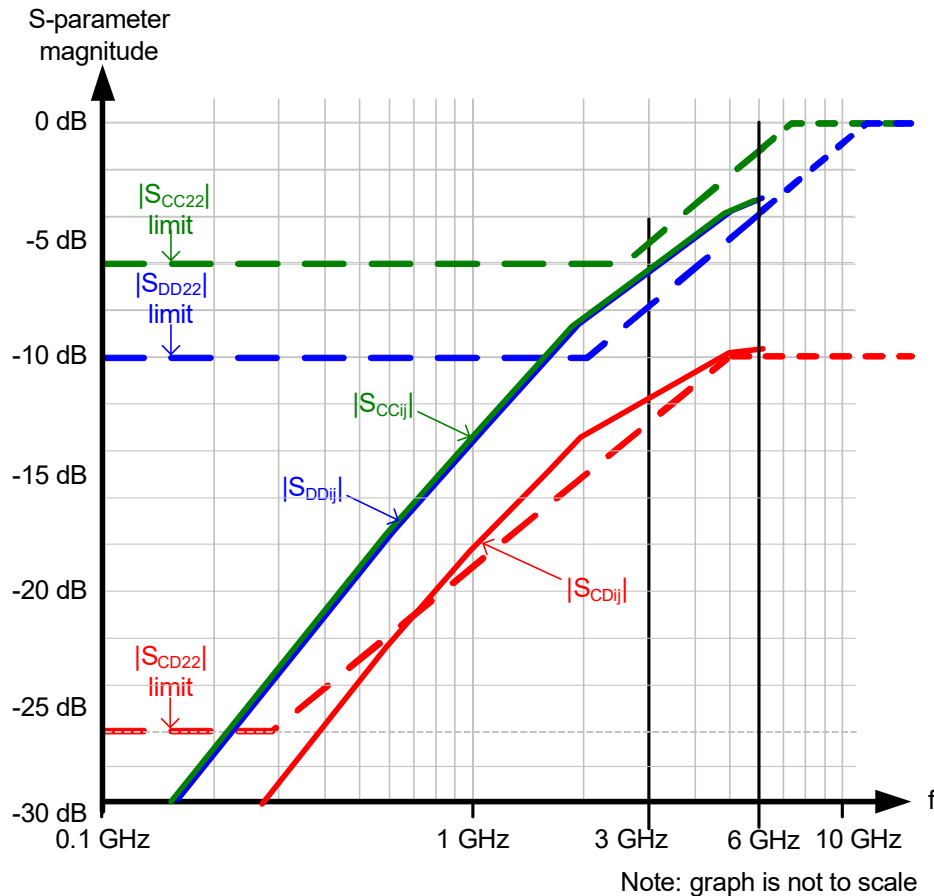


Figure 126 — Trained 6 Gbit/s reference transmitter device termination S-parameters

The Touchstone model does not exactly match the $|S_{CC22}|$, $|S_{DD22}|$, and $|S_{CD22}|$ limits defined in 5.8.4.5.3 at all frequencies, however, it is a reasonable approximation for use in simulations. See Annex H for a description of how the Touchstone model was created.

5.8.4.5.6 Trained 6 Gbit/s transmitter equalization, VMA, and $V_{P,P}$ measurement

The trained 6 Gbit/s transmitter equalization measurement shall be based on the following values:

- VMA: a mode (i.e., the most frequent value of a set of data) measurement; and
- $V_{P,P}$: a peak to peak measurement with a repeating 7Eh (i.e., D30.3) pattern (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5).

The VMA and $V_{P,P}$ measurements shall be made with the transmitter device terminated through the interoperability point into a zero-length test load (see 5.6.2).

The VMA and V_{P-P} measurements shall be made using an equivalent time sampling scope with a histogram function with the following or an equivalent procedure:

- 1) calibrate the sampling scope for measurement of a 3 GHz signal; and
- 2) determine VMA and V_{P-P} as shown in figure 127. A sample size of 1 000 minimum to 2 000 maximum histogram hits for VMA shall be used to determine the values. The histogram is a combination of two histograms (i.e., an upper histogram for TX+ and a lower histogram for TX-). The histograms on the left represent the test pattern signal displayed on the right. VMA and V_{P-P} are determined by adding the values measured for TX+ and TX-.

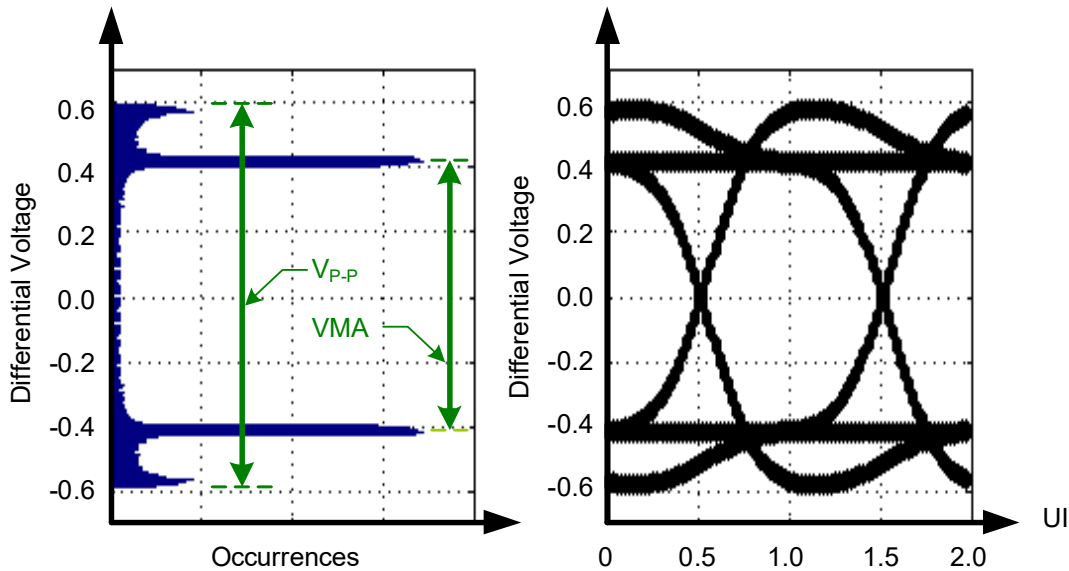


Figure 127 — Transmitter equalization measurement

The following formula shall be used to calculate the transmitter equalization value:

$$\text{Transmitter equalization} = 20 \times \log_{10}(V_{P-P} / \text{VMA}) \text{ dB}$$

where:

V_{P-P} is the peak to peak value; and
 VMA is the mode value.

5.8.4.6 Transmitter device signal output characteristics for trained 12 Gbit/s

5.8.4.6.1 Transmitter device signal output characteristics for trained 12 Gbit/s overview

Table 50 specifies the signal output characteristics for the transmitter device for trained 12 Gbit/s.

Table 50 — Transmitter device signal output characteristics for trained 12 Gbit/s at ET, IT, and CT
(part 1 of 2)

Signal characteristic	Units	Minimum	Nominal	Maximum
Peak to peak voltage (V_{P-P}) ^a	mV(P-P)	850		1 200
Transmitter device off voltage at IT or CT ^{b c}	mV(P-P)			50
Reference differential impedance at IT or CT ^d	Ω		100	
Reference common mode impedance at IT or CT ^d	Ω		25	

^a The V_{P-P} measurement shall be made with the transmitter device set to no equalization (see table 53) and amplitude set to maximum. The minimum value applies at ET (see 5.3.3) and the maximum value applies at IT (see 5.3.3) or CT (see 5.3.3). The measurement is made with a repeating 7Eh (i.e., D30.3) pattern (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5). If using SAS3_EYEOPENING or equivalent tool for the measurement at ET, then IDLE dwords (see SPL-5) may be used for the test pattern.

^b The transmitter device off voltage is the maximum A.C. voltage measured at compliance points IT and CT when the transmitter is unpowered or transmitting D.C. idle (e.g., during idle time of an OOB signal).

^c If optical mode is enabled, then the transmitter device off voltage is not applicable.

^d See 5.8.4.6.3 for transmitter device S-parameters characteristics.

^e Ratio measured with post cursor equalization disabled and peak to peak voltage set to maximum with a repeating TRAIN_DONE primitive (see SPL-5 and figure 131). When both precursor and post cursor equalization are active the maximum observed R_{pre} may be as high as 3.8 at the VMA limit.

^f If a simulation tool (e.g., SAS3_EYEOPENING) is used, then this measurement may be performed with IDLE dwords (see SPL-5) as the test pattern.

^g Ratio measured with precursor equalization disabled and peak to peak voltage set to maximum with a repeating TRAIN_DONE primitive (see SPL-5 and figure 131). When both precursor and post cursor equalization are active the maximum observed R_{post} may be as high as 5.5 at the VMA limit.

^h Measured as $v_2 - v_5$ (see figure 131) with a repeating TRAIN_DONE primitive (see SPL-5).

ⁱ This is a broadband limit. For additional limits on spectral content, see figure 128 and table 51.

^j The RJ measurement shall be performed with a repeating 0011b pattern or 1100b pattern (e.g., D24.3) (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5) with SSC disabled. RJ is 14 times the RJ 1 sigma value, based on a BER of 10^{-12} . For simulations based on a BER of 10^{-15} , the RJ specified is 16 times the RJ 1 sigma value.

^k The measurement shall include the effects of the JTF (see 5.8.3.2).

^l RJ and TJ are measured at IT (see 5.3.3) or CT (see 5.3.3).

^m 0.15 UI is 12.5 ps at 12 Gbit/s.

ⁿ The TJ measurement shall be performed with a repeating 0011b pattern or 1100b pattern (e.g., D24.3) (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5). If the transmitter device supports SSC, then this test shall be performed with both SSC enabled and SSC disabled. TJ is equivalent to BUJ + RJ. ISI is minimized by the test pattern.

^o 0.25 UI is 20.8 ps at 12 Gbit/s.

Table 50 — Transmitter device signal output characteristics for trained 12 Gbit/s at ET, IT, and CT
(part 2 of 2)

Signal characteristic	Units	Minimum	Nominal	Maximum
Precursor equalization ratio $R_{pre}^{e f}$	V/V	1		1.66
Post cursor equalization ratio $R_{post}^{f g}$	V/V	1		3.33
VMA $^{f h}$	mV(P-P)	80		
Common mode voltage limit (rms) i	mV			30
RJ $^{j k l}$	UI			0.15 m
TJ $^{k l n}$	UI			0.25 o

^a The V_{P-P} measurement shall be made with the transmitter device set to no equalization (see table 53) and amplitude set to maximum. The minimum value applies at ET (see 5.3.3) and the maximum value applies at IT (see 5.3.3) or CT (see 5.3.3). The measurement is made with a repeating 7Eh (i.e., D30.3) pattern (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5). If using SAS3_EYEOPENING or equivalent tool for the measurement at ET, then IDLE dwords (see SPL-5) may be used for the test pattern.
^b The transmitter device off voltage is the maximum A.C. voltage measured at compliance points IT and CT when the transmitter is unpowered or transmitting D.C. idle (e.g., during idle time of an OOB signal).
^c If optical mode is enabled, then the transmitter device off voltage is not applicable.
^d See 5.8.4.6.3 for transmitter device S-parameters characteristics.
^e Ratio measured with post cursor equalization disabled and peak to peak voltage set to maximum with a repeating TRAIN_DONE primitive (see SPL-5 and figure 131). When both precursor and post cursor equalization are active the maximum observed R_{pre} may be as high as 3.8 at the VMA limit.
^f If a simulation tool (e.g., SAS3_EYEOPENING) is used, then this measurement may be performed with IDLE dwords (see SPL-5) as the test pattern.
^g Ratio measured with precursor equalization disabled and peak to peak voltage set to maximum with a repeating TRAIN_DONE primitive (see SPL-5 and figure 131). When both precursor and post cursor equalization are active the maximum observed R_{post} may be as high as 5.5 at the VMA limit.
^h Measured as $v_2 - v_5$ (see figure 131) with a repeating TRAIN_DONE primitive (see SPL-5).
ⁱ This is a broadband limit. For additional limits on spectral content, see figure 128 and table 51.
^j The RJ measurement shall be performed with a repeating 0011b pattern or 1100b pattern (e.g., D24.3) (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5) with SSC disabled. RJ is 14 times the RJ 1 sigma value, based on a BER of 10^{-12} . For simulations based on a BER of 10^{-15} , the RJ specified is 16 times the RJ 1 sigma value.
^k The measurement shall include the effects of the JTF (see 5.8.3.2).
^l RJ and TJ are measured at IT (see 5.3.3) or CT (see 5.3.3).
^m 0.15 UI is 12.5 ps at 12 Gbit/s.
ⁿ The TJ measurement shall be performed with a repeating 0011b pattern or 1100b pattern (e.g., D24.3) (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5). If the transmitter device supports SSC, then this test shall be performed with both SSC enabled and SSC disabled. TJ is equivalent to BUJ + RJ. ISI is minimized by the test pattern.
^o 0.25 UI is 20.8 ps at 12 Gbit/s.

Table 51 defines the transmitter device common mode voltage limit characteristics.

Table 51 — 12 Gbit/s transmitter device common mode voltage limit characteristics

Characteristic	Reference	L ^a (dBmV) ^b	N ^a (dBmV) ^{b c}	S ^a (dBmV/decade) ^b	H ^a (dBmV) ^b	f _{min} ^a (MHz)	f _{max} ^a (GHz)
Spectral limit of common mode voltage ^d	Figure 128	12.7	26.0	13.3	30.0	100	9.0
<p>^a See figure 4 in 5.2 for definitions of L, N, S, f_{min}, and f_{max}. For this parameter, units of dBmV is used in place of dB.</p> <p>^b For dBmV, the reference level of 0 dBmV is 1 mV (rms). Hence, 0 dBm is 1 mW which is 158 mV (rms) across 25 Ω (i.e., the reference impedance for common mode voltage) which is $20 \times \log_{10}(158) = +44$ dBmV. +26 dBmV is therefore -18 dBm.</p> <p>^c Maximum value at 3 GHz (see figure 128).</p> <p>^d The transmitter device common mode voltage shall be measured with a 1 MHz resolution bandwidth through the range of 100 MHz to 9 GHz with the transmitter device output of CJTPAT (see Annex A). The end points of the range shall be at the center of the measurement bandwidth.</p>							

Figure 128 shows the transmitter device common mode voltage limit defined in table 51.

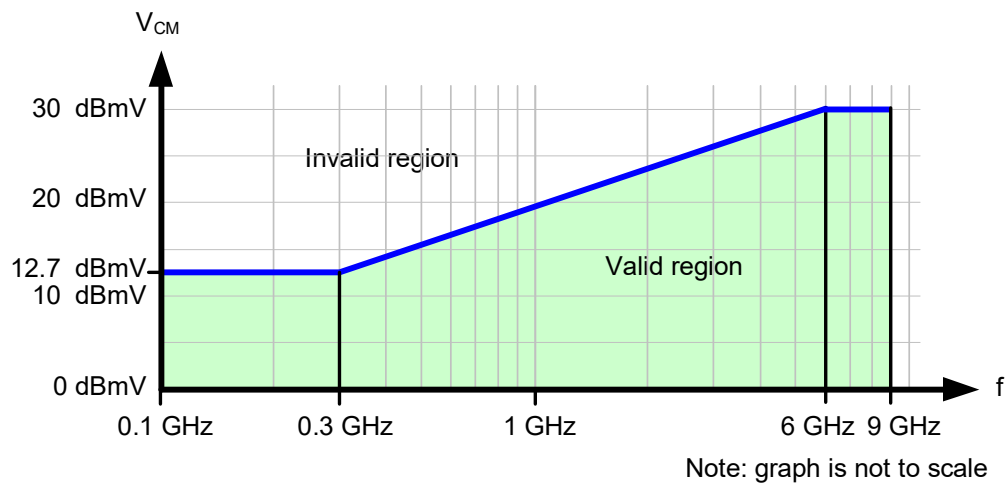


Figure 128 — 12 Gbit/s transmitter device common mode voltage limit

5.8.4.6.2 Transmitter device equalization for trained 12 Gbit/s and 22.5 Gbit/s

Figure 129 specifies the transmitter coefficient ranges when the transmitter peak to peak voltage is maximum. The coefficients are defined according to the 12 Gbit/s reference transmitter (see 5.8.4.6.4). The bottom left area of the minimum and maximum ranges in figure 129 are limited by VMA and vary according to V_{P-P_noeq} . V_{P-P_noeq} is the amplitude at ET for 12 Gbit/s and PT for 22.5 Gbit/s measured with the no_equalization setting as specified in table 53.

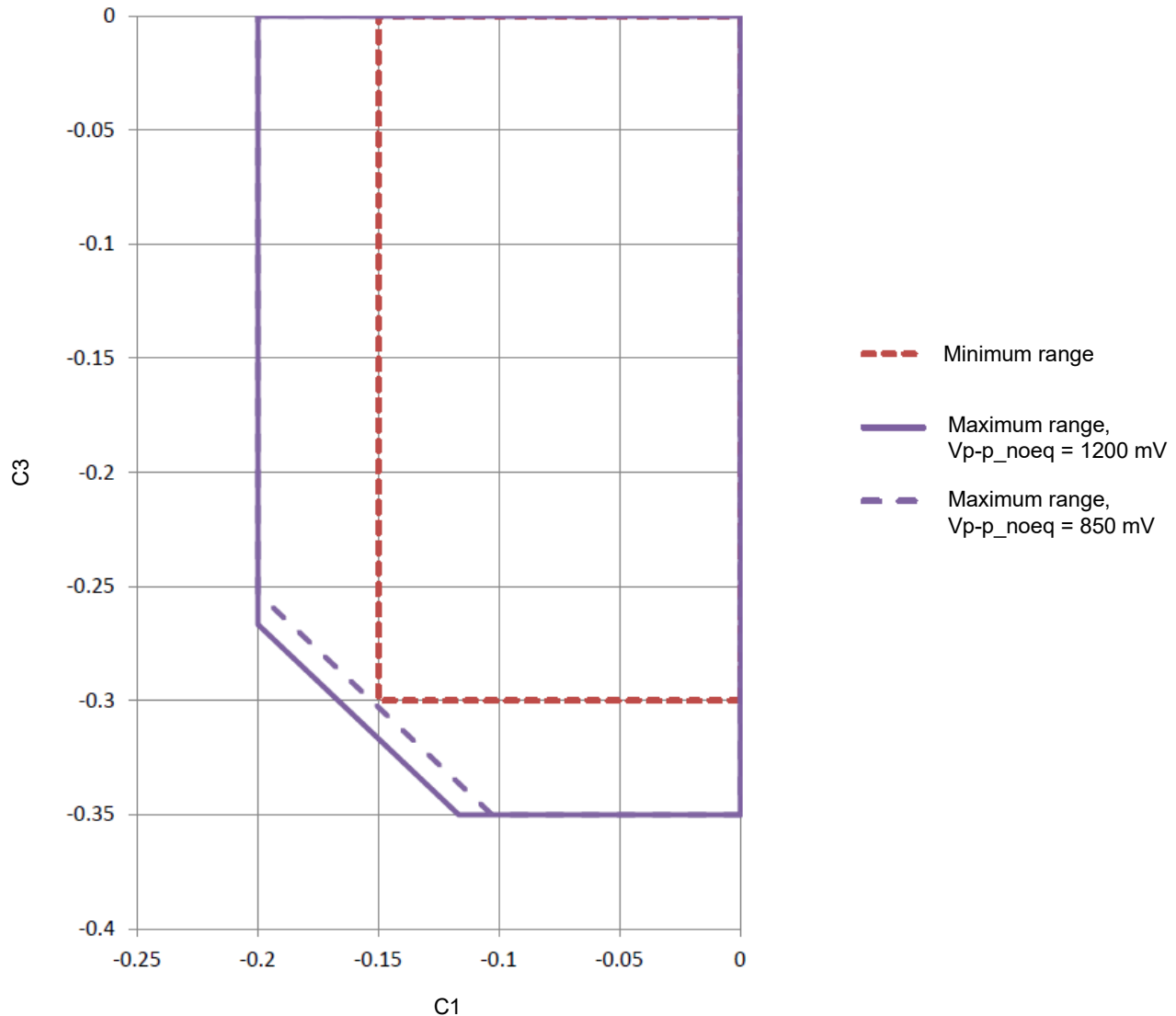


Figure 129 — Minimum and maximum coefficient ranges at maximum peak to peak voltage

Transmitter equalization coefficient adjustments are controlled using the protocol defined in SPL-5. Transmitter circuits that support 12 Gbit/s and 22.5 Gbit/s, and not operating in optical mode, shall support the coefficient requests shown in table 52. Transmitter circuits that support 12 Gbit/s, and not in optical mode, shall provide equalization equivalent to the reference transmitter device (see 5.8.4.6.4).

The algorithm for optimizing the transmitter coefficient is beyond the scope of this standard.

Table 52 — Transmitter coefficient requests and corresponding transmitter circuit response

Coefficient 1 request	Coefficient 2 request	Coefficient 3 request	Description	$v_{HL}(k+1) - v_{HL}(k)$ mV(P-P)	$v_1(k+1) - v_1(k)$ mV	$v_2(k+1) - v_2(k)$ mV	$v_3(k+1) - v_3(k)$ mV
hold	hold	hold	Hold peak to peak voltage and hold equalization	-20 to +20 ^a	-10 to +10 ^a	-10 to +10 ^a	-10 to +10 ^a
dec	dec	hold	Increase precursor and hold peak to peak voltage	-20 to +20	-40 to -10	-40 to -10	-10 to +10
inc	inc	hold	Decrease precursor and hold peak to peak voltage	-20 to +20	+40 to +10	+40 to +10	-10 to +10
hold	dec	dec	Increase post cursor and hold peak to peak voltage	-20 to +20	-10 to +10	-40 to -10	-40 to -10
hold	inc	inc	Decrease post cursor and hold peak to peak voltage	-20 to +20	-10 to +10	+40 to +10	+40 to +10
hold	dec	hold	Decrease peak to peak voltage and hold equalization	-40 to -10	-20 to -5	-20 to -5	-20 to -5
hold	inc	hold	Increase peak to peak voltage and hold equalization	+40 to +10	+20 to +5	+20 to +5	+20 to +5
dec	hold	hold	Increase precursor and increase peak to peak voltage	+40 to +10	-20 to -5	-20 to -5	+20 to +5
inc	hold	hold	Decrease precursor and decrease peak to peak voltage	-40 to -10	+20 to +5	+20 to +5	-20 to -5
hold	hold	dec	Increase post cursor and increase peak to peak voltage	+40 to +10	+20 to +5	-20 to -5	-20 to -5
hold	hold	inc	Decrease post cursor and decrease amplitude	-40 to -10	-20 to -5	+20 to +5	+20 to +5
<p>Key:</p> <p>hold = Requests no change be made to the coefficient. Equivalent to hold in SPL-5.</p> <p>dec = Request to make the coefficient more negative. Equivalent to decrement in SPL-5.</p> <p>inc = Request to make the coefficient more positive. Equivalent to increment in SPL-5.</p> <p>^a The peak to peak voltage and equalization voltage differences between the initial condition and following any single or consecutive hold/hold/hold command shall not be greater than the specified range.</p>							

The transmitter circuit responses specified in table 52 shall be measured with a zero-length test load as shown in figure 130 for 12 Gbit/s transmitter devices. The test fixture is de-embedded back to the output of the transmitter circuit ET (see 5.3.3). D.C. losses are not de-embedded. For de-embedding methods see G.6. For 22.5 Gbit/s transmitter devices, the measurement may be made directly at the PT compliance point (see 5.3.4) or by a de-embedding process similar to the method shown in figure 130 but changed from the ET compliance point to the PT compliance point.

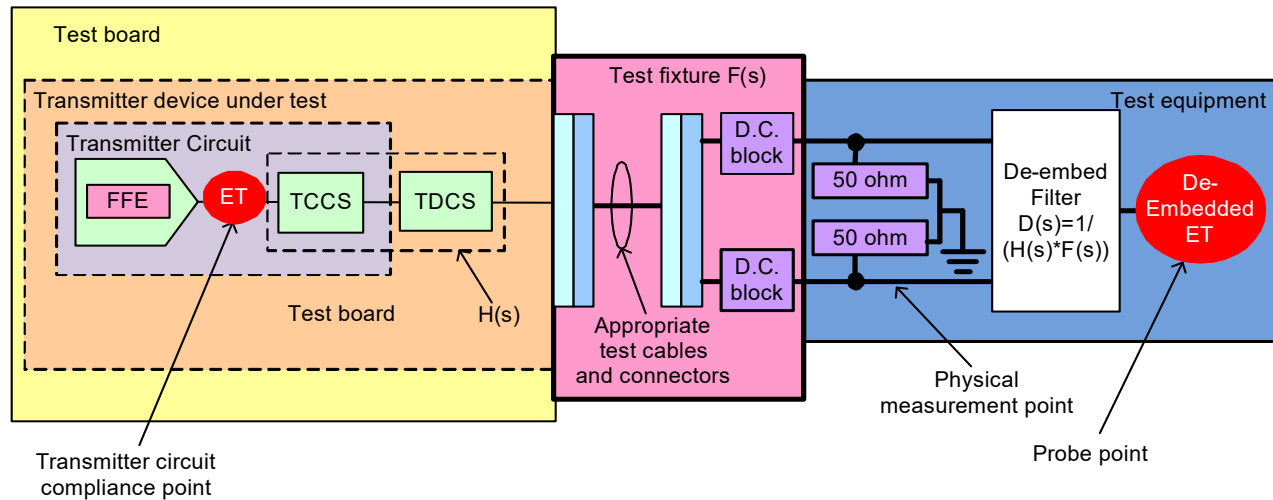


Figure 130 — Transmitter circuit compliance test configuration

All response specifications are based on differential measurements. The output waveform for a TRAIN_DONE primitive (see SPL-5) is shown in figure 131 where:

- a) T is the symbol period;
- b) t_1 is the zero-crossing point of the rising edge of the positive 5 UI CID;
- c) t_2 is the zero-crossing point of the falling edge of the positive 5 UI CID;
- d) t_3 is the zero-crossing point of the falling edge of the negative 5 UI CID;
- e) t_4 is the zero-crossing point of the rising edge of the negative 5 UI CID;
- f) v_1 is the maximum voltage measured in the interval t_1 to $t_1 + T$;
- g) v_2 is the average voltage measured in the interval $t_1 + 2T$ to $t_1 + 3T$;
- h) v_3 is the maximum voltage measured in the interval $t_2 - T$ to t_2 ;
- i) v_4 is the minimum voltage measured in the interval t_3 to $t_3 + T$;
- j) v_5 is the average voltage measured in the interval $t_3 + 2T$ to $t_3 + 3T$;
- k) v_6 is the minimum voltage measured in the interval $t_4 - T$ to t_4 ;
- l) VMA is $v_2 - v_5$; and
- m) v_{HL} is the peak to peak voltage measured in the interval t_1 to $t_1 + 80T$.

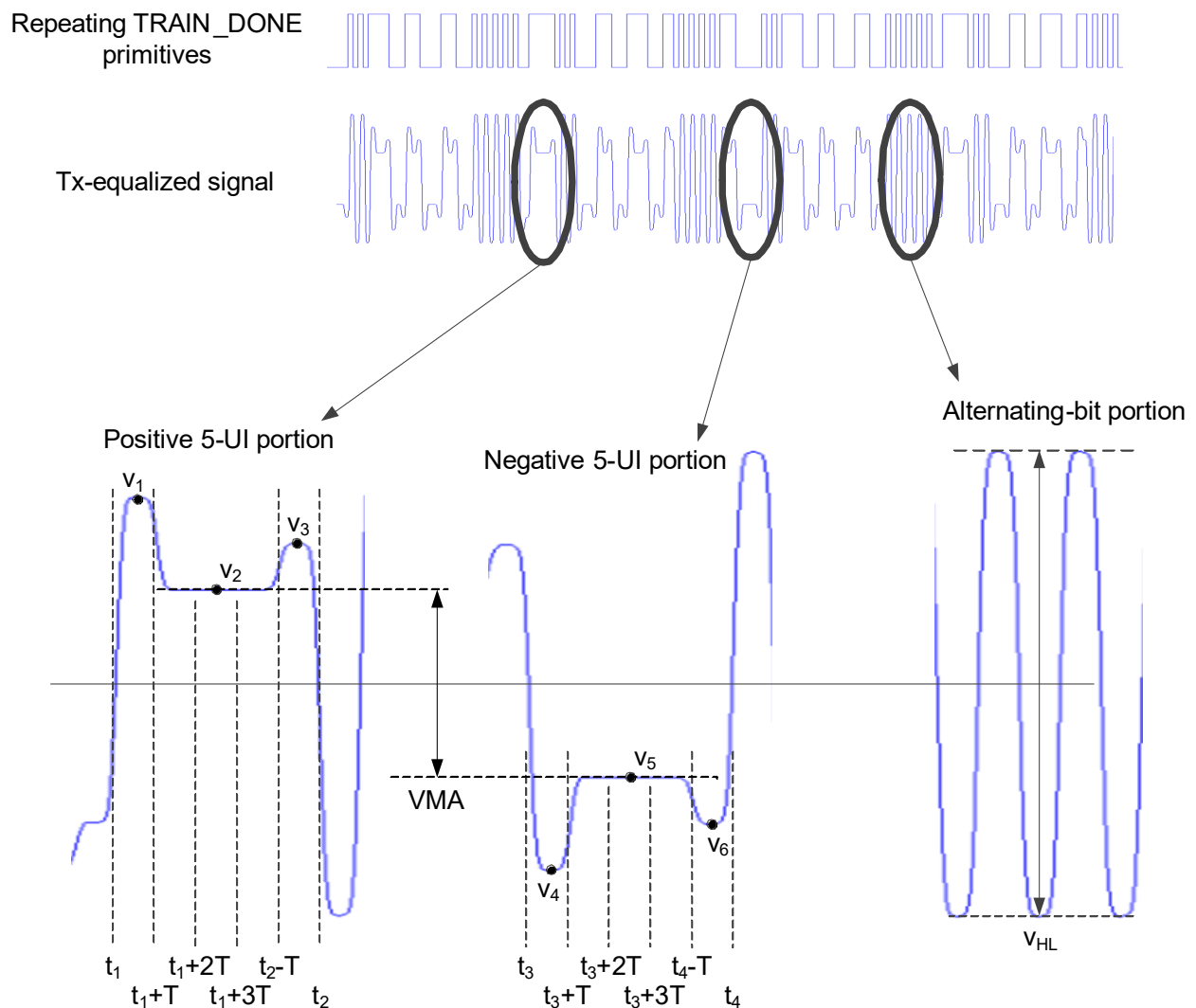


Figure 131 — 12 Gbit/s transmitter circuit output waveform

Equalization ratios are defined based on these voltages,

$$R_{pre} = \frac{V_3}{V_2}$$

$$R_{post} = \frac{V_1}{V_2}$$

Transmitter coefficient presets may be requested using a protocol that is defined in the SPL-5 standard. Transmitter circuits that support 12 Gbit/s and 22.5 Gbit/s shall support the coefficient settings shown in table 53. Transmitter circuits that support 12 Gbit/s shall also provide equalization equivalent to the reference transmitter device (see 5.8.4.6.4).

Table 53 — Transmitter circuit coefficient presets at ET

Coefficient settings ^a	R _{pre} (V/V) ^b			R _{post} (V/V) ^b		
	Min	Nom	Max	Min	Nom	Max
normal ^c						
reference_1 ^{d e}	2.10	2.52	2.97	2.94	3.52	4.16
reference_2 ^{e f}	1.05	1.26	1.49	1.19	1.43	1.68
no_equalization ^{e g}	0.84	1.00	1.19	0.84	1.00	1.19
Key: Max = Maximum Min = Minimum Nom = Nominal						
^a The coefficient setting field in the TTIU (see SPL-5). ^b All measurements are performed with a repeating TRAIN_DONE primitive (see SPL-5 and figure 130). If a simulation tool (e.g., SAS3_EYEOPENING) is used, then this measurement may be performed with IDLE dwords (see SPL-5) as the test pattern. ^c See SPL-5. ^d Equivalent to the reference transmitter setting transmitter circuit coefficient 1 (i.e., C1) set to -0.15, coefficient 2 (i.e., C2) set to 0.6, and coefficient 3 (i.e., C3) set to -0.25 with a ± 1.5 dB tolerance on R _{pre} and R _{post} . ^e The reference_1, reference_2, and no_equalization presets shall set the transmitter to its maximum peak to peak voltage (V _{P-P}). ^f Equivalent to the reference transmitter setting transmitter circuit C1 set to -0.075, C2 set to 0.8, and C3 set to -0.125 with a ± 1.5 dB tolerance on R _{pre} and R _{post} . ^g Equivalent to the reference transmitter setting transmitter circuit C1 set to zero, C2 set to one, and C3 set to zero with a ± 1.5 dB tolerance on R _{pre} and R _{post} .						

5.8.4.6.3 12 Gbit/s transmitter device S-parameter limits

S-parameter limits are calculated per the following formula:

$$\text{Measured value} < \max [L, \min [H, N + 13.3 \times \log_{10}(f / 3 \text{ GHz})]]$$

where:

- L is the minimum value (i.e., the low frequency asymptote);
- H is the maximum value (i.e., the high frequency asymptote);
- N is the value at 3 GHz;
- f is the frequency of the signal in Hz;
- $\max [A, B]$ is the maximum of A and B; and
- $\min [A, B]$ is the minimum of A and B.

The frequency for N is based on the Nyquist at 6 Gbit/s.

Table 54 defines the maximum limits for S-parameters of the 12 Gbit/s transmitter device.

Table 54 — 12 Gbit/s maximum limits for S-parameters at IT_S or CT_S

Characteristic ^{a b}	L ^c (dB)	N ^c (dB)	H ^c (dB)	S ^c (dB / decade)	f _{min} ^c (MHz)	f _{max} ^c (GHz)
S _{CC22}	-6.0	-5.0	-1.0	13.3	100	9.0
S _{DD22}	-10	-7.9	-3.9	13.3	100	9.0
S _{CD22}	-26	-12.7	-10	13.3	100	9.0
^a For S-parameter measurements, the transmitter device under test shall transmit a repeating 0011b pattern or 1100b pattern (e.g., D24.3) (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5). The amplitude applied by the test equipment shall be less than -4.4 dBm (i.e., 190 mV zero to peak) per port (see G.11.4.2). ^b S _{DC22} is not specified. ^c See figure 4 for definitions of L, N, H, S, f _{min} , and f _{max} .						

Figure 132 shows the 12 Gbit/s transmitter device $|S_{CC22}|$, $|S_{DD22}|$, and $|S_{CD22}|$ limits defined in table 54.

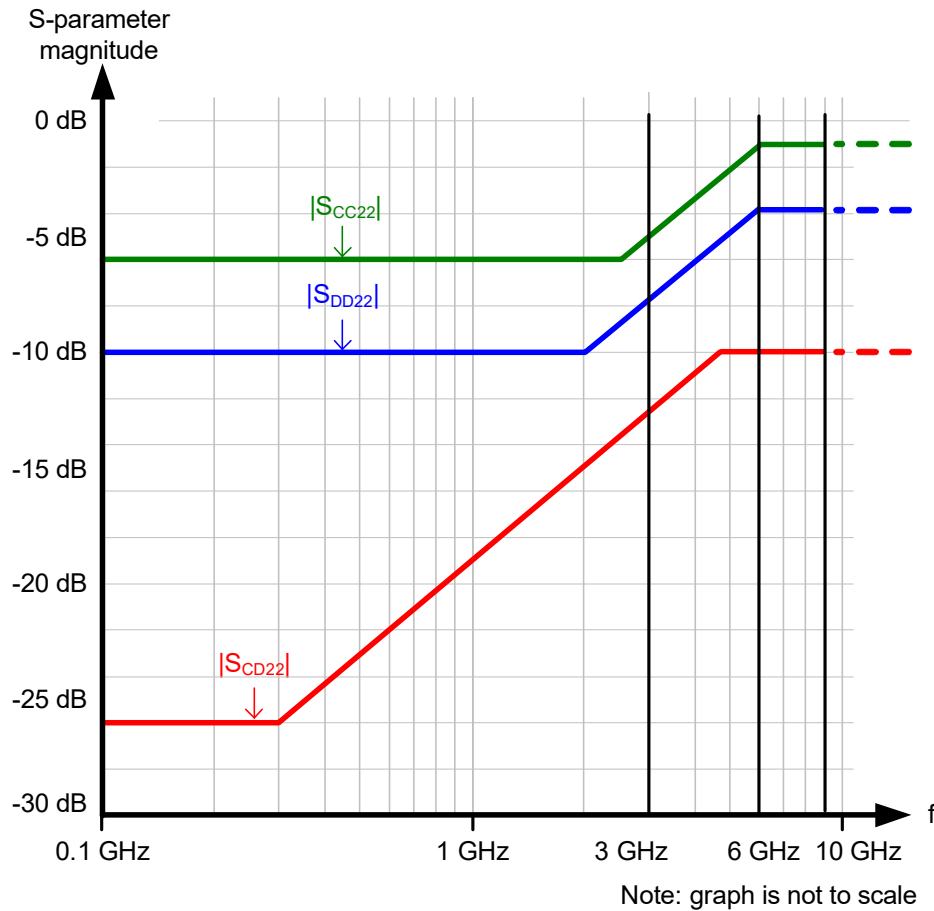


Figure 132 — 12 Gbit/s transmitter device $|S_{CC22}|$, $|S_{DD22}|$, and $|S_{CD22}|$ limits

5.8.4.6.4 12 Gbit/s reference transmitter device

The 12 Gbit/s reference transmitter device is a set of parameters and equalization filters defining the electrical performance characteristics of a transmitter circuit used in simulation. Figure 133 illustrates the reference transmitter device.

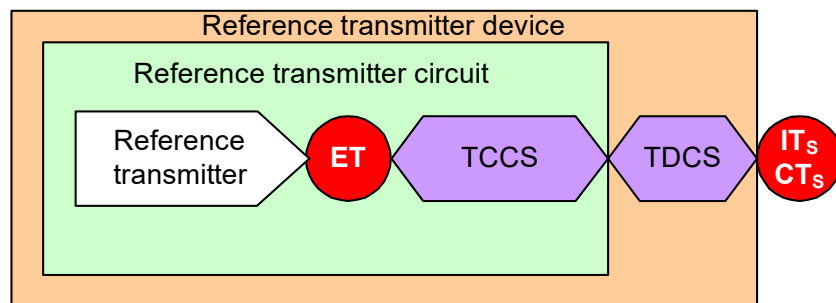


Figure 133 — 12 Gbit/s reference transmitter device

Figure 134 shows the reference transmitter generating the signal at ET. Passive TxRx connection segments TCCS and TDCS simulate the reference TxRx connection segment between ET and CT_S or ET and IT_S. See C.2 for the description of the reference TxRx connection segments.

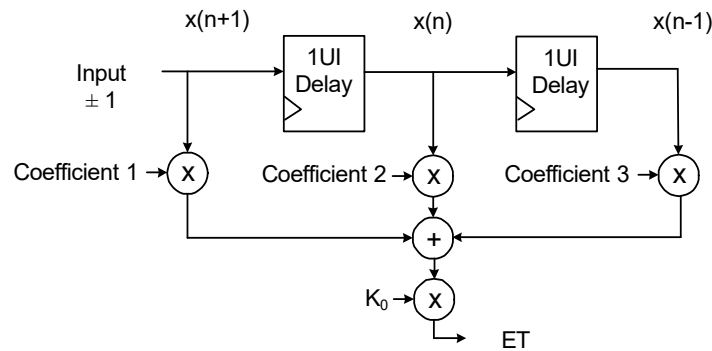


Figure 134 — 12 Gbit/s reference transmitter

During 12 Gbit/s end to end simulations (see 5.7), the reference transmitter device parameters are optimized to maximize the eye opening at the output of the reference receiver device (5.8.5.7.3) using the procedure defined in 5.7.3. Table 55 defines the reference transmitter device characteristics. The reference transmitter device shall use the minimum peak to peak voltage and minimum rise/fall time. The input is a unitless stream of pulses representing transmitted data. The amplitude of these pulses reach +1 or -1. The stream of pulses contain the jitter and rise/fall time characteristics defined in table 55.

Table 55 — 12 Gbit/s reference transmitter device characteristics at ET

Signal characteristic	Units	Minimum	Nominal	Maximum
Output gain (K_0)	V/V	0.425		
Peak to peak voltage (V_{P-P}) ^a	mV(P-P)	850		
Precursor coefficient (i.e., coefficient 1) ^a	V/V	-0.15		0
VMA ^b	mV(P-P)	80		
Post cursor coefficient (i.e., coefficient 3) ^a	V/V	-0.3		0
Rise/fall time ^c	ps	25		
RJ ^{d e}	UI			0.15
DJ ^f	UI			0.1

^a V_{P-P} is constrained in the reference transmitter device by
 $C2 = 1 - |C1| - |C3|$
where:
C1 = coefficient 1;
C2 = coefficient 2; and
C3 = coefficient 3.

^b $VMA = 2K_0 (C1 + C2 + C3) V$.

^c Rise/fall times are measured from 20 % to 80 % of the transition with a repeating 01b pattern or 10b pattern (e.g., D10.2 or D21.5) (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5).

^d 0.15 UI is 12.5 ps at 12 Gbit/s.

^e RJ is 14 times the RJ 1 sigma value, based on a BER of 10^{-12} .

^f 0.1 UI is 8.3 ps at 12 Gbit/s.

5.8.4.6.5 Transmitter device end to end simulation characteristics for trained 12 Gbit/s

The end to end simulation procedure for transmitter devices connected to passive TxRx connections is as follows:

- 1) set the transmitter to output IDLE dwords (see SPL-5);
- 2) set the transmitter to the no_equalization coefficient setting (see SPL-5);
- 3) capture the signal at IT (see 5.3.3) or CT (see 5.3.3) into a zero-length test load (see 5.6.2);
- 4) measure the total crosstalk amplitude (see 5.7.4) or extract crosstalk transfer functions (e.g., S-parameters);
- 5) connect TxRx connection segments, crosstalk segments, reference transmitter and reference receiver according to the reference end to end simulation diagram (see 5.7.2, C.2.1 and C.2.2);
- 6) set the reference transmitter equalization (see 5.7.3) and reference receiver DFE equalization (see 5.8.5.7.3); and
- 7) perform a linear simulation, including the effects of edge rates, ISI and crosstalk (see C.1).

The characteristics of the signal at specified points in the simulation are defined in table 56. See the reference transmitter device (see 5.8.4.6.4) for definitions of coefficient 1 (i.e., C1), coefficient 2 (i.e., C2), and coefficient 3 (i.e., C3).

Table 56 — Transmitter device characteristics for trained 12 Gbit/s at ET and ER

Characteristic	Units	Minimum	Maximum	Compliance point
Coefficient 1 (i.e., C1) ^{a b c}	V/V	-0.15	0	ET
VMA ^{d e}	mV(P-P)	80		ET
Coefficient 3 (i.e., C3) ^{a b f}	V/V	-0.3	0	ET
Reference pulse response cursor peak to peak amplitude ^g	mV(P-P)	135		ER
Vertical eye opening to reference pulse response cursor ratio ^{h i}	%	45		ER
DFE coefficient amplitude to reference pulse response cursor ratio ^j	%	-50	50	ER
<p>^a If C1 or C3 exceeds its maximum (positive) limit, then it is forced to its maximum limit and the other coefficients are recalculated.</p> <p>^b $C2 = 1 - C1 - C3$.</p> <p>^c If C1 exceeds its minimum (negative) limit, then it is forced to its minimum limit and C3 is recalculated.</p> <p>^d $VMA = 2K_0 (C1 + C2 + C3) V$. See 5.8.4.6.4.</p> <p>^e If VMA exceeds its minimum limit, then C1 and C3 are forced to values that have the smallest distance to a point compliant to the VMA specification in the C1/C3 plane. The distance is defined as:</p> $\sqrt{(C1' - C1)^2 + (C3' - C3)^2}$ <p>where:</p> <p>C1' and C3' are values that satisfy the minimum VMA criterion.</p> <p>^f If C3 exceeds its minimum limit, then it is forced to its minimum limit and C1 is recalculated. If C1 had already reached or exceeded its minimum limit, then both C1 and C3 are forced to their minimum limit.</p> <p>^g The average amplitude of the eye for an IDLE pattern (see SPL-5) digital input at the compliance point may be used for this measurement. See figure 115.</p> <p>^h The vertical eye opening includes the effects of crosstalk (see C.1).</p> <p>ⁱ The end to end simulation removes any remaining RJ and TJ (i.e., non-ISI) of the transmitter device.</p> <p>^j The maximum of the absolute value of the reference DFE coefficients (i.e., $\max(\text{abs}(d_i))$) divided by the reference pulse response cursor (see 5.8.5.7.3).</p>				

The transmitter coefficients are simulated by replacing the test transmitter by the reference transmitter generating no jitter (i.e., no RJ or TJ). This is equivalent to inserting a jitter-free reference transmitter with K_0 set to one (i.e., unit-less value) at the output of the transmitter device (see 5.8.4.6.4), using the transmitter device output as the input of the reference transmitter instead of the $+1/-1$ digitized stream (see figure 135). For non-separable TxRx connection segments, the reference simulation channel (i.e., <usage>_IR_RR) does not include the reference PICS.

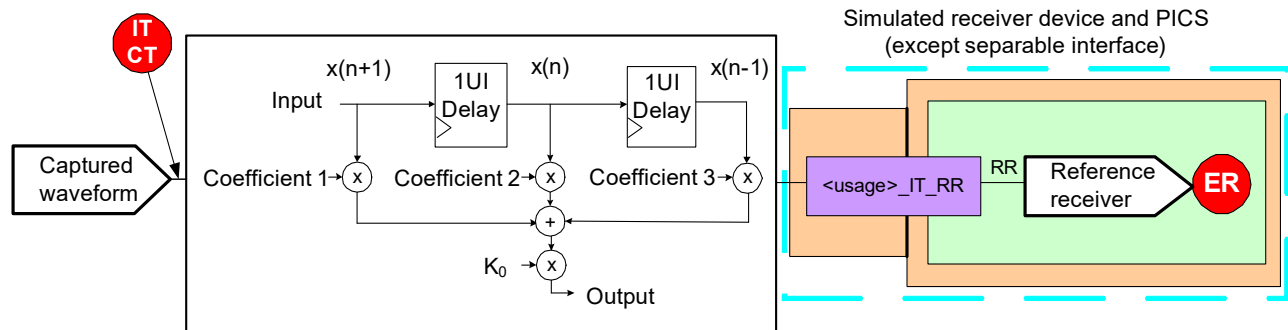


Figure 135 — Simulation of the reference transmitter from a captured signal

5.8.4.6.6 Transmitter device signal output characteristics at CT_S for 12 Gbit/s when an active cable is connected

Transmitter devices supporting trained 12 Gbit/s that are connected to an external cable connector shall support the signal characteristics specified in table 57 at CT_S when an active cable is connected.

Table 57 — Transmitter device signal output characteristics for 12 Gbit/s at CT_S when an active cable is connected

Signal characteristic	Units	CT_S
Maximum peak to peak voltage (i.e., $2 \times Z2$ in figure 100) ^{a b}	mV(P-P)	1 200
Minimum eye opening (i.e., $2 \times Z1$ in figure 100) ^{a c}	mV(P-P)	200
Maximum half of TJ (i.e., $X1$ in figure 100) ^{a c d}	UI	0.175
Maximum RJ ^{a b d}	UI	0.15
Center of bit time (i.e., $X2$ in figure 100)	UI	0.5
^a All crosstalk sources shall be active with representative traffic during the measurement. ^b The maximum peak to peak voltage measurement and RJ measurement shall be performed with a repeating 0011b pattern or 1100b pattern (e.g., D24.3) (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5) with SSC disabled. RJ is 14 times the RJ 1 sigma value, based on a BER of 10^{-12} . ^c The minimum eye opening measurement and TJ measurement shall be performed with the SCRAMBLED_0 pattern (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5) with SSC enabled for a period of at least 33.3 μ s (i.e., a full SSC cycle). ^d The measurement shall include the effects of the JTF (see 5.8.3.2).		

5.8.4.7 Transmitter device signal output characteristics for trained 22.5 Gbit/s

5.8.4.7.1 Transmitter device signal output characteristics for trained 22.5 Gbit/s overview

Table 58 specifies the signal output characteristics for the transmitter device for trained 22.5 Gbit/s.

Table 58 — Transmitter device signal output characteristics for trained 22.5 Gbit/s at PT, IT, and CT

Signal characterisitic	Symbol	Units	Minimum	Nominal	Maximum
Peak to peak voltage (V_{P-P}) ^a		mV(P-P)	850		1 200
Transmitter device off voltage at IT or CT ^{b c}		mV(P-P)			50
Reference differential impedance at IT or CT ^d		Ω		100	
Reference common mode impedance at IT or CT ^d		Ω		25	
Common mode noise ^e	T_Ncm	mV rms			12
Uncorrelated unbounded Gaussian jitter ^{f g h i}	T_UUGJ	UI			0.15
Uncorrelated bounded high probability jitter ^{f g h}	T_UBHPJ	UI			0.15
Duty cycle distortion ^{j k}	T_DCD	UI			0.035
Total jitter ^{f g l}	T_TJ	UI			0.28

^a The V_{P-P} measurement shall be made with the transmitter device set to no equalization (see table 53) and amplitude set to maximum. The minimum value applies at PT (see 5.3.4) and the maximum value applies at IT (see 5.3.4) or CT (see 5.3.4). The measurement is made with a repeating 7Eh (i.e., D30.3) pattern (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5).

^b The transmitter device off voltage is the maximum A.C. voltage measured at compliance points IT and CT when the transmitter is unpowered or transmitting D.C. idle (e.g., during idle time of an OOB signal).

^c If optical mode is enabled, then the transmitter device off voltage is not applicable.

^d See 5.8.4.7.3 for transmitter device S-parameters characteristics.

^e Common mode noise is measured using the PRBS15 (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5) (see ITU-T) on the physical link. See OIF-CEI for the measurement method. For additional limits on spectral content, see figure 136 and table 59.

^f For jitter measurements, see 5.8.4.7.4.

^g The measurement shall include the effects of the JTF (see 5.8.3.2).

^h 0.15 UI is 6.6 ps at 22.5 Gbit/s.

ⁱ The T_UUGJ maximum value of 0.15 UI corresponds to a value of 0.01 UI rms.

^j T_DCD is measured with a repeating 01b pattern or 10b pattern (e.g., D10.2 or D21.5) (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5) on the physical link. Duty cycle distortion is part of the CBHPJ (correlated bounded high probability jitter) distribution (see OIF-CEI) and is measured at the time-averaged signal level. T_DCD shall be measured with transmitter device equalization on and transmitter device equalization set to no_equalization (see table 53).

^k 0.035 UI is 1.5 ps at 22.5 Gbit/s.

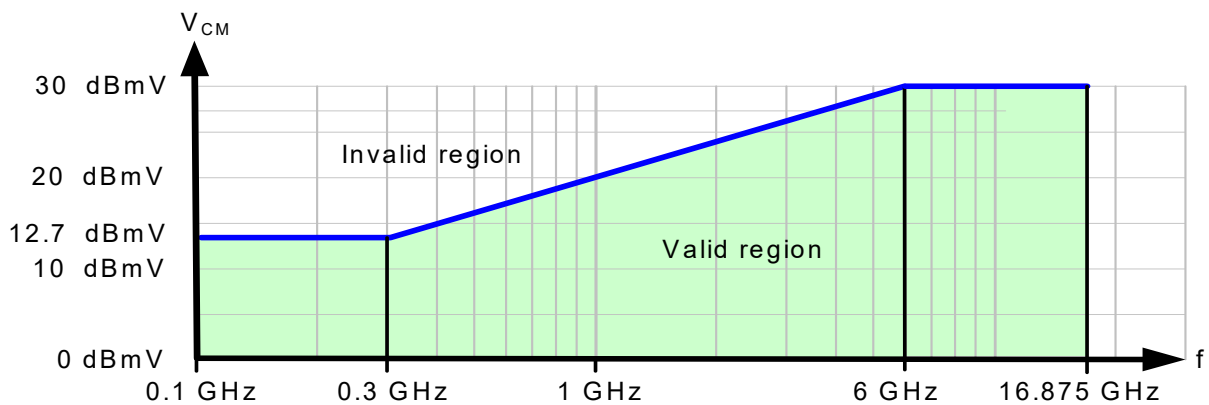
^l 0.28 UI is 12.4 ps at 22.5 Gbit/s.

Table 59 defines the transmitter device common mode voltage limit characteristics.

Table 59 — 22.5 Gbit/s transmitter device common mode voltage limit characteristics

Characteristic	Reference	L ^a (dBmV) ^b	N ^a (dBmV) ^{b c}	S ^a (dBmV/decade) ^b	H ^a (dBmV) ^b	f _{min} ^a (MHz)	f _{max} ^a (GHz)
Spectral limit of common mode voltage ^d	Figure 128	12.7	26.0	13.3	30.0	100	16.875
<p>^a See figure 4 in 5.2 for definitions of L, N, S, f_{min}, and f_{max}. For this parameter, units of dBmV is used in place of dB.</p> <p>^b For dBmV, the reference level of 0 dBmV is 1 mV (rms). Hence, 0 dBm is 1 mW which is 158 mV (rms) across 25 Ω (i.e., the reference impedance for common mode voltage) which is $20 \times \log_{10}(158) = +44$ dBmV. +26 dBmV is therefore -18 dBm.</p> <p>^c Maximum value at 3 GHz (see figure 128).</p> <p>^d The transmitter device common mode voltage shall be measured with a 1 MHz resolution bandwidth through the range of 100 MHz to 16.875 GHz with the transmitter device output of PRBS15 (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5) (see ITU-T). The end points of the range shall be at the center of the measurement bandwidth.</p>							

Figure 136 shows the transmitter device common mode voltage limit defined in table 59.



Note: graph is not to scale

Figure 136 — 22.5 Gbit/s transmitter device common mode voltage limit

5.8.4.7.2 Transmitter device equalization for trained 22.5 Gbit/s

See 5.8.4.6.2.

5.8.4.7.3 22.5 Gbit/s transmitter device S-parameter limits

S-parameter limits are calculated per the following formula:

$$\text{Measured value} < \max [L, \min [H, N + 13.3 \times \log_{10}(f / 3 \text{ GHz})]]$$

where:

- L is the minimum value (i.e., the low frequency asymptote);
- H is the maximum value (i.e., the high frequency asymptote);
- N is the value at 3 GHz;
- f is the frequency of the signal in Hz;
- max [A, B] is the maximum of A and B; and
- min [A, B] is the minimum of A and B.

The frequency for N is based on the Nyquist at 6 Gbit/s.

Table 60 defines the maximum limits for S-parameters of the 22.5 Gbit/s transmitter device at IT_S and CT_S .

Table 60 — 22.5 Gbit/s maximum limits for S-parameters at IT_S or CT_S

Characteristic ^{a b}	L ^c (dB)	N ^c (dB)	H ^c (dB)	S ^c (dB / decade)	f _{min} ^c (MHz)	f _{max} ^c (GHz)
S _{CC22}	-6.0	-5.0	-1.0	13.3	100	16.875
S _{DD22}	-10	-7.9	-3.9	13.3	100	16.875
S _{CD22}	-26	-12.7	-10	13.3	100	16.875
^a For S-parameter measurements, the transmitter device under test shall transmit a repeating 0011b pattern or 1100b pattern (e.g., D24.3)(see the phy test patterns in the Protocol Specific diagnostic page in SPL-5). The amplitude applied by the test equipment shall be less than -4.4 dBm (i.e., 190 mV zero to peak) per port (see G.11.4.2). ^b S _{DC22} is not specified. ^c See figure 4 for definitions of L, N, H, S, f _{min} , and f _{max} .						

Figure 137 shows the 22.5 Gbit/s transmitter device $|S_{CC22}|$, $|S_{DD22}|$, and $|S_{CD22}|$ limits defined in table 60.

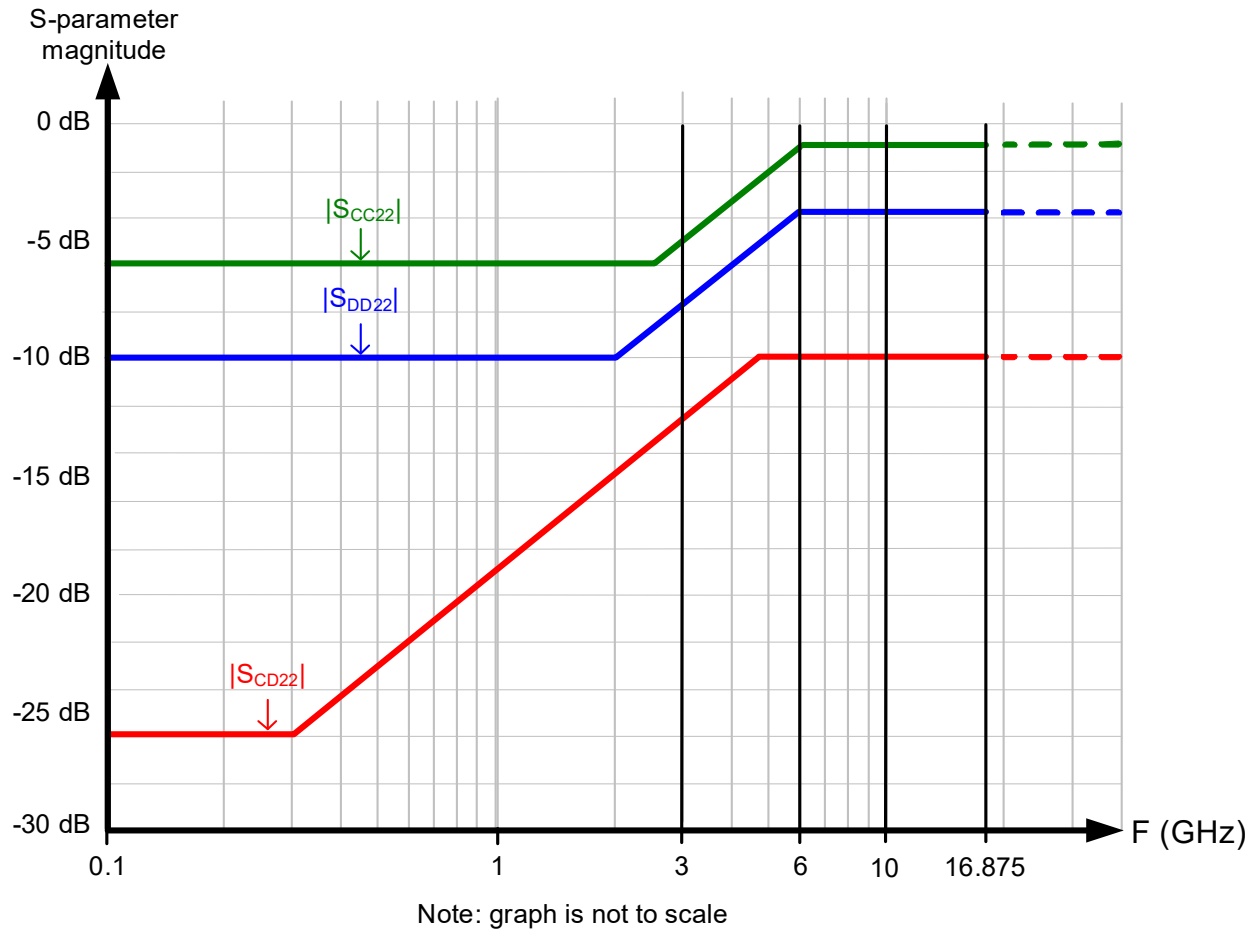


Figure 137 — 22.5 Gbit/s transmitter device $|S_{CC22}|$, $|S_{DD22}|$, and $|S_{CD22}|$ limits at IT_S and CT_S

The 22.5 Gbit/s transmitter device $|S_{DD22}|$ limit at PT is calculated per the following formula:

$$\text{Measured value} < \max [L, \min [H, N + 13.3 \times \log_{10}(f / 5.625 \text{ GHz})]]$$

where:

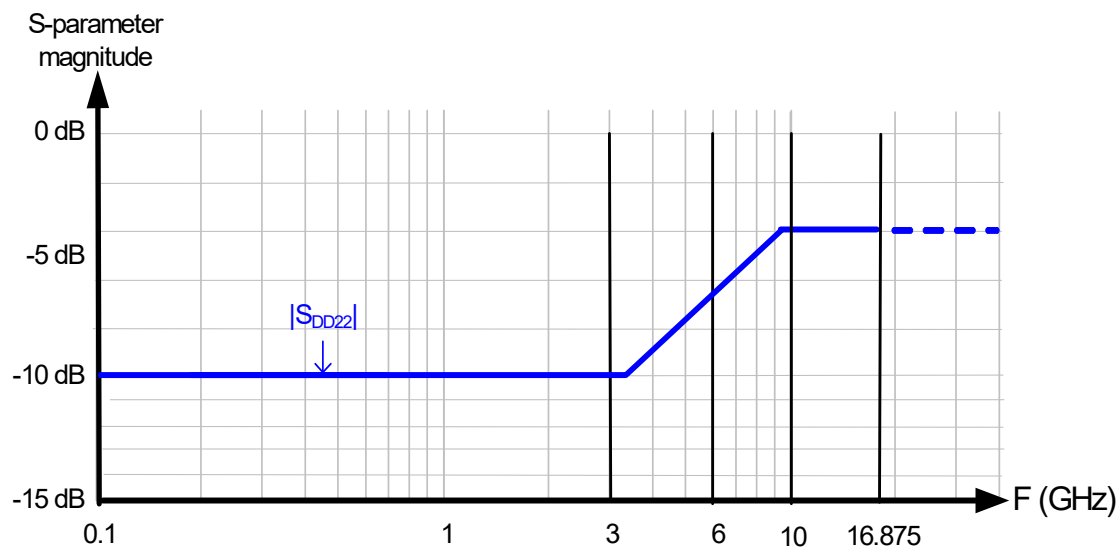
- L is the minimum value (i.e., the low frequency asymptote);
- H is the maximum value (i.e., the high frequency asymptote);
- N is the value at 5.625 GHz;
- f is the frequency of the signal in Hz;
- $\max [A, B]$ is the maximum of A and B; and
- $\min [A, B]$ is the minimum of A and B.

Table 61 defines the maximum limit for $|S_{DD22}|$ of the 22.5 Gbit/s transmitter device at PT.

Table 61 — 22.5 Gbit/s transmitter device maximum limit for $|S_{DD22}|$ at PT

Characteristic ^a	L ^b (dB)	N (dB)	H ^b (dB)	S ^b (dB / decade)	f _{min} ^b (MHz)	f _{max} ^b (GHz)
$ S_{DD22} $	-10	-7.0	-3.9	13.3	100	16.875
^a For S-parameter measurements, the transmitter device under test shall transmit a repeating 0011b pattern or 1100b pattern (e.g., D24.3)(see the phy test patterns in the Protocol Specific diagnostic page in SPL-5). The amplitude applied by the test equipment shall be less than -4.4 dBm (i.e., 190 mV zero to peak) per port (see G.11.4.2). ^b See figure 4 for definitions of L, H, S, f _{min} , and f _{max} .						

Figure 138 shows the 22.5 Gbit/s transmitter device $|S_{DD22}|$ limit at PT defined in table 61.



Note: graph is not to scale

Figure 138 — 22.5 Gbit/s transmitter device $|S_{DD22}|$ limit at PT

5.8.4.7.4 22.5 Gbit/s transmitter device jitter measurements

Transmitter device jitter measurements for 22.5 Gbit/s transmitter devices are based on the methods defined for CEI-25G-LR applications in OIF-CEI. The BER requirement is 1×10^{-15} and is extrapolated from testing based on a BER of 1×10^{-12} (see OIF-CEI). If the jitter measurements are made at the PT compliance point (see 5.3), then the transmitter device equalization shall be off (i.e., equalization set to no_equalization (see table 53)). If the jitter measurements are made at the IT compliance point (see 5.3) or CT compliance point (see 5.3), then the transmitter device equalization should be set to minimize jitter, accounting for the TxRx connection segment between the PT compliance point (see 5.3) and the IT compliance point (see 5.3) or CT compliance point (see 5.3). DDJ is measured using PRBS9 (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5) (see ITU-T) on the physical link. All other transmitter device jitter measurements are performed using PRBS15 (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5) (see ITU-T) on the physical link. The measurement instrument bandwidth should be at least 33 GHz. If the measurement bandwidth affects the result, then post-processing may be used for correction.

The jitter distributions (see OIF-CEI) are the basis for determining the jitter parameters. The measurement shall include the effects of the JTF (see 5.8.3.2).

T_UUGJ, T_UBHPJ, and T_TJ are derived with the method defined in OIF-CEI from the BER CDF. If the transmitter device supports SSC, then T_TJ shall be measured with both SSC enabled and SSC disabled.

T_UBHPJ is calculated from the following equation:

$$T_UBHPJ = HPJ_{total} - DDJ$$

where:

- T_UBHPJ is the uncorrelated bounded high probability jitter;
- HPJtotal is the total high probability jitter (see OIF-CEI); and
- DDJ is the data dependent jitter.

5.8.4.7.5 Transmitter device signal output characteristics at CT_S for 22.5 Gbit/s when an active cable is connected

Transmitter devices supporting trained 22.5 Gbit/s that are connected to an external cable connector shall support the signal characteristics specified in table 62 at CT_S when an active cable is connected.

Table 62 — Transmitter device signal output characteristics for 22.5 Gbit/s at CT_S when an active cable is connected

Signal characteristic	Units	CT _S
Maximum peak to peak voltage (i.e., 2 × Z2 in figure 100) ^{a b}	mV(P-P)	1 200
Minimum eye opening (i.e., 2 × Z1 in figure 100) ^{a c}	mV(P-P)	200
Maximum half of TJ (i.e., X1 in figure 100) ^{a c d}	UI	0.175
Maximum RJ ^{a b d}	UI	0.15
Center of bit time (i.e., X2 in figure 100)	UI	0.5
^a All crosstalk sources shall be active with representative traffic during the measurement. ^b The maximum peak to peak voltage measurement and RJ measurement shall be performed with a repeating 0011b pattern or 1100b pattern (e.g., D24.3) (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5) with SSC disabled. RJ is 14 times the RJ 1 sigma value, based on a BER of 10 ⁻¹² . ^c The minimum eye opening measurement and TJ measurement shall be performed with the SCRAMBLED_0 pattern (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5) with SSC enabled for a period of at least 33.3 μs (i.e., a full SSC cycle). ^d The measurement shall include the effects of the JTF (see 5.8.3.2).		

5.8.4.8 Transmitter device signal output characteristics for OOB signals

Transmitter devices supporting SATA shall use SATA Gen3i signal output levels (see SATA) during the first OOB sequence (see SPL-5) after a power on or hard reset. If the phy does not receive COMINIT within a hot-plug timeout (see SPL-5), then the transmitter device shall increase its transmit levels to the OOB signal output levels specified in table 63 and perform the OOB sequence again. If no COMINIT is received within a hot-plug timeout of the second OOB sequence, then the transmitter device shall initiate another OOB sequence using Gen3i signal output levels. The transmitter device shall continue alternating between transmitting COMINIT using Gen3i signal output levels and transmitting COMINIT with SAS signal output levels until the phy receives COMINIT.

If the phy both transmits and receives COMSAS (i.e., a SAS phy or expander phy is attached), then the transmitter device shall set its transmit levels to the SAS signal output levels (see 5.8.4.4 and 5.8.4.5) prior to beginning the SAS speed negotiation sequence (see SPL-5). If transmitter device had been using Gen3i signal output levels, then this mode transition (i.e., output voltage change) may result in a transient (see 5.8.2) during the idle time between COMSAS and the SAS speed negotiation sequence.

If the transmitter device is using SAS signal output levels and the phy does not receive COMSAS (i.e., a SATA phy is attached), then the transmitter device shall set its transmit levels to the SATA Gen3i signal output levels and restart the OOB sequence.

Transmitter devices that do not support SATA or that have optical mode enabled shall transmit OOB signals using SAS signal output levels. In phy low power conditions (see SPL-5) the output common mode specification OOB common mode delta (see table 63) is relaxed to enable transmitter device power savings. During phy low power conditions, the transmitter device should reduce its output swing level to save power. Before exiting a phy low power condition the transmitter device shall wait for its common mode to settle.

Table 63 defines the transmitter device signal output characteristics for OOB signals.

Table 63 — Transmitter device signal output characteristics for OOB signals

Characteristic	Units	IT	CT
Maximum peak to peak voltage (i.e., $2 \times Z_2$ in figure 120)	mV(P-P)	1 200	
OOB offset delta ^{a b}	mV	± 25	
OOB common mode delta ^{b c}	mV	± 50	
Minimum OOB burst amplitude ^d , if SATA is not supported	mV(P-P)	240 ^e	
Minimum OOB burst amplitude ^d , if SATA is supported	mV(P-P)	240 ^{e f}	N/A
^a The maximum difference in the average differential voltage (D.C. offset) component between the burst times and the idle times of an OOB signal. ^b This is not applicable when optical mode is enabled or in phy low power conditions. ^c The maximum difference in the average of the common mode voltage between the burst times and the idle times of an OOB signal. ^d With a measurement bandwidth of 4.5 GHz, each signal level during the OOB burst shall exceed the specified minimum differential amplitude before transitioning to the opposite bit value or before termination of the OOB burst as measured with the zero-length test load (see 5.6.2) and the TCTF test load (see 5.6.3) at IT and CT. ^e The OOB burst contains either 1.5 Gbit/s repeating 0011b pattern or 1100b pattern (e.g., D24.3), 1.5 Gbit/s ALIGN (0) primitives, or 3 Gbit/s ALIGN (0) primitives (see SPL-5 and SATA). ^f Amplitude measurement methodologies of SATA and this standard differ. Under conditions of maximum rise/fall time and jitter, eye diagram methodologies used in this standard may indicate less signal amplitude than the technique specified by SATA. Implementers of designs supporting SATA are required to ensure interoperability and should perform additional system characterization with an eye diagram methodology using SATA devices.			

5.8.5 Receiver device characteristics

5.8.5.1 Receiver device characteristics overview

The receiver device shall operate within the required BER (see 5.5.1) when a signal with valid voltage and timing characteristics is delivered to the receiver device compliance point from a nominal 100 Ω source. The received signal shall be considered valid if it meets the voltage and timing limits specified in table 71 for trained 6 Gbit/s and 12 Gbit/s. See SATA for untrained 6 Gbit/s (i.e., SATA Gen3i) receiver device requirements.

When testing the jitter tolerance capability of a receiver device, the additional 0.1 UI of SJ may be reduced by an amount proportional to the actual externally induced interference between the application point of the test and the input to the receiver device. The additional jitter reduces the eye opening in both voltage and time. For trained 6 Gbit/s and 12 Gbit/s the additional jitter is included in the stressed receiver device jitter tolerance test (see 5.8.5.7.6).

Compliance points referenced in the electrical requirement tables are shown in 5.3 unless otherwise specified. See G.10 for a methodology for measuring receiver device signal tolerance.

A receiver device shall provide equivalent performance to the reference receiver device (see 5.8.5.7.3) and shall operate within the required BER when attached to:

- a) any transmitter device compliant with this standard (see 5.8.4); and
- b) any TxRx connection compliant with this standard (see 5.5).

5.8.5.2 Receiver device coupling requirements

Coupling requirements for receiver devices are as follows:

- a) all receiver devices (i.e., attached to IR (see 5.3) or CR (see 5.3) compliance points) shall be A.C. coupled to the interconnect through a receive network.

See table 40 for the coupling capacitor value.

5.8.5.3 Receiver device general electrical characteristics

Table 64 defines the receiver device general electrical characteristics.

Table 64 — Receiver device general electrical characteristics

Characteristic	Units	6 Gbit/s	12 Gbit/s	22.5 Gbit/s
Physical link rate accuracy ^a tolerance at IR if SATA is not supported	ppm	± 100		
Physical link rate accuracy ^a tolerance at IR if SATA is supported	ppm	± 350		
Physical link rate SSC modulation tolerance at IR and CR	ppm	See table 86		
Maximum receiver device transients ^b	V	± 1.2		
Minimum receiver A.C. common mode voltage tolerance V _{CM} ^{c d}	mV(P-P)	See table 65		
Receiver A.C. common mode frequency tolerance range F _{CM} ^c	MHz	See table 65		
^a Physical link rate accuracy shall be measured over a minimum of 1 x 10 ⁶ UI and should be measured using a minimum resolution of 100 Hz. ^b See 5.8.2 for transient test circuits and conditions. ^c Receiver devices shall tolerate sinusoidal common mode noise components within the peak to peak amplitude (V _{CM}) and the frequency range (F _{CM}). ^d The measurement shall be made with a channel equivalent to the channel used in the zero-length test load (see figure 103).				

The common mode frequency tolerance range for 6 Gbit/s, 12 Gbit/s, and 22.5 Gbit/s is extended to include the effects of duty cycle distortion. Measurement methods for testing the extended frequency ranges for A.C. common mode tolerance are not defined by this standard; therefore the common mode signal characteristics defined in table 65 are recommended design guidelines for receiver devices supporting 6 Gbit/s, 12 Gbit/s, and 22.5 Gbit/s.

Table 65 — Recommended receiver device common mode tolerance for 6 Gbit/s, 12 Gbit/s, and 22.5 Gbit/s

Characteristic	Units	6 Gbit/s	12 Gbit/s	22.5 Gbit/s
Minimum receiver A.C. common mode voltage tolerance V_{CM} ^{a b}	mV(P-P)	150		
Receiver A.C. common mode frequency tolerance range F_{CM} ^b	MHz	2 to 3 000	2 to 6 000	2 to 11 250
^a Receiver devices should be designed to tolerate sinusoidal common mode noise components within the peak to peak amplitude (V_{CM}) and the frequency range (F_{CM}). ^b The value represents the signal characteristic at IR or CR when the channel between the transmitter device and IR or CR is equivalent to the channel used in the zero-length test load (see figure 103).				

Table 66 defines the receiver device termination characteristics.

Table 66 — Receiver device termination characteristics

Characteristic	Units	Trained 6 Gbit/s, 12 Gbit/s, and 22.5 Gbit/s
Differential impedance ^{a b c}	Ω	See 5.8.5.7.1
Maximum differential impedance imbalance ^{a b c d}	Ω	See 5.8.5.7.2 ^e
Maximum receiver termination time constant ^{a b c}	ps	N/A
Common mode impedance ^{a b}	Ω	See 5.8.5.7.1
<p>^a All receiver device termination measurements are made through mated connector pairs.</p> <p>^b The receiver device termination impedance specification applies to all receiver devices in a TxRx connection and covers all time points between the connector nearest the receiver device, the receiver device, and the transmission line terminator. This measurement shall be made from that connector.</p> <p>^c At the time point corresponding to the connection of the receiver device to the transmission line, the input capacitance of the receiver device and its connection to the transmission line may cause the measured impedance to fall below the minimum impedances specified in this table. With impedance measured using amplitude in units of ρ (i.e., the reflection coefficient, a dimensionless unit) and duration in units of time, the area of the impedance dip caused by this capacitance is the receiver termination time constant. The receiver termination time constant shall not be greater than the values shown in this table.</p> <p>An approximate value for the receiver termination time constant is given by the following equation: $RTTC = \text{amp} \times \text{width}$ where: RTTC receiver termination time constant in seconds; amp amplitude of the dip in units of ρ (i.e., the difference between the reflection coefficient at the nominal impedance and the reflection coefficient at the minimum impedance point); and width width of the dip in units of time, as measured at the half amplitude point.</p> <p>The value of the receiver device excess input capacitance is given by the following equation: $C = \frac{RTTC}{(R_0 \parallel R_R)}$ where: C receiver device excess input capacitance in farads; RTTC receiver termination time constant in seconds; R_0 transmission line characteristic impedance in Ω; R_R termination resistance at the receiver device in Ω; and $(R_0 \parallel R_R)$ parallel combination of R_0 and R_R.</p> <p>^d The difference in measured impedance to SIGNAL GROUND on the plus and minus terminals on the interconnect, transmitter device, or receiver device, with a differential test signal applied to those terminals.</p> <p>^e Measurement replaced by S_{CD11} specifications (i.e., differential to common mode conversion).</p>		

5.8.5.4 Delivered signal characteristics for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s

Table 67 specifies the requirements of the OOB signal delivered by the system with the zero-length test load (see 5.6.2) at the receiver device compliance point (i.e., IR (see 5.3.2) or CR (see 5.3.2)) for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s

Table 67 — Delivered signal characteristics for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s as measured with the zero-length test load at IR and CR

Signal characteristic	Units	IR		CR	
		1.5 Gbit/s	3 Gbit/s	1.5 Gbit/s	3 Gbit/s
Maximum voltage (non-operational)	mV(P-P)	2 000			
Maximum peak to peak voltage (i.e., 2 × Z2 in figure 121) if a SATA phy is not attached	mV(P-P)	1 200		1 200	
Maximum peak to peak voltage (i.e., 2 × Z2 in figure 121) if a SATA phy is attached	mV(P-P)	see SATA ^a		N/A	
Minimum eye opening (i.e., 2 × Z1 in figure 121), if a SATA phy is not attached	mV(P-P)	325	275	275	
Jitter tolerance (see figure 122) ^{b c}	N/A	See table 69			
Maximum half of TJ (i.e., X1 in figure 121) ^d	UI	0.275			
Center of bit time (i.e., X2 in figure 121)	UI	0.50			
Maximum intra-pair skew ^e	ps	80	75	80	75

^a Amplitude measurement methodologies of SATA and this standard differ. Under conditions of maximum rise/fall time and jitter, eye diagram methodologies used in this standard may indicate less signal amplitude than the technique specified by SATA. Implementers of designs supporting SATA are required to ensure interoperability and should perform additional system characterization with an eye diagram methodology using SATA devices.

^b The value for X1 applies at a TJ probability of 10⁻¹². At this level of probability direct visual comparison between the mask and actual signals is not a valid method for determining compliance with the jitter requirements.

^c SSC shall be enabled if the receiver device supports being attached to SATA. Jitter setup shall be performed prior to application of SSC.

^d The value for X1 shall be half the value given for TJ in table 68. When SSC is disabled, the test or analysis shall include the effects of a single pole high-pass frequency-weighting function that progressively attenuates jitter at 20 dB/decade below a frequency of (f_{baud} / 1 667).

^e The intra-pair skew measurement shall be made at the midpoint of the transition with a repeating 01b pattern or 10b pattern (e.g., D10.2 or D21.5) (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5) on the physical link. The same stable trigger, coherent to the data stream, shall be used for both the Rx+ and Rx- signals. Intra-pair skew is defined as the time difference between the means of the midpoint crossing times of the Rx+ signal and the Rx- signal at the probe points.

5.8.5.5 Maximum delivered jitter for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s

Table 68 defines the maximum jitter the system shall deliver to the receiver device at the receiver device compliance point (i.e., IR (see 5.3.2) or CR (see 5.3.2)) for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s. For trained 6 Gbit/s and 12 Gbit/s see 5.8.5.7.6.

Table 68 — Maximum delivered jitter for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s at IR and CR

Signal characteristic ^{a b}	Units	OOB signaling rate	
		1.5 Gbit/s	3 Gbit/s
Deterministic jitter (DJ) ^c	UI	0.35	
Total jitter (TJ) ^{c d e}	UI	0.55	
<div><div>^a All DJ and TJ values are level 1 (see MJSQ).</div><div>^b The values for jitter in this table are measured at the average signal amplitude point.</div><div>^c The DJ and TJ values in this table apply to jitter measured as described in 5.8.3.3. Values for DJ and TJ shall be calculated from the CDF for the jitter population using the calculation of level 1 jitter compliance levels method in MJSQ.</div><div>^d TJ is specified at a CDF level of 10⁻¹².</div><div>^e If TJ received at any point is less than the maximum allowed, then the jitter distribution of the signal is allowed to be asymmetric. The TJ plus the magnitude of the asymmetry shall not exceed the allowed maximum TJ. The numerical difference between the average of the peaks with a BER that is less than 10⁻¹² and the average of the individual events is the measure of the asymmetry. Jitter peak to peak measured < (maximum TJ - Asymmetry)</div></div>			

5.8.5.6 Receiver device jitter tolerance for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s

Table 69 defines the amount of jitter the receiver device shall tolerate at the receiver device compliance point (i.e., IR (see 5.3.2) or CR (see 5.3.2)) for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s. Receiver device jitter testing shall be performed with the maximum (i.e., slowest) rise/fall times, minimum signal amplitude, and maximum TJ, and should be performed with normal activity in the receiver device (e.g., with other transmitter circuits and receiver circuits on the same board as the receiver device performing normal activity) with SSC enabled if SSC is supported by the receiver device. Jitter setup shall be performed prior to application of SSC. For trained 6 Gbit/s and 12 Gbit/s see 5.8.5.7.6.

Table 69 — Receiver device jitter tolerance for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s at IR and CR

Signal characteristic	Units	OOB signaling rate	
		1.5 Gbit/s	3 Gbit/s
Applied sinusoidal jitter (SJ) from f_c to f_{max} ^a	UI	0.10 ^e	0.10 ^f
Deterministic jitter (DJ) ^{b c}	UI	0.35 ^g	0.35 ^h
Total jitter (TJ) ^{b c d}	UI	0.65	

^a The jitter values given are normative for a combination of applied SJ, DJ, and TJ that receiver devices shall be able to tolerate without exceeding the required BER (see 5.5.1). Receiver devices shall tolerate applied SJ of progressively greater amplitude at lower frequencies than f_c , according to figure 139, with the same DJ and RJ levels as were used from f_c to f_{max} .

^b All DJ and TJ values are level 1 (see MJSQ).

^c The DJ and TJ values in this table apply to jitter measured as described in 5.8.3.4. Values for DJ and TJ shall be calculated from the CDF for the jitter population using the calculation of level 1 jitter compliance levels method in MJSQ.

^d No value is given for RJ. For compliance with this standard, the actual RJ amplitude shall be the value that brings TJ to the stated value at a probability of 10^{-12} . The additional 0.1 UI of applied SJ is added to ensure the receiver device has sufficient operating margin in the presence of external interference.

^e Applied sinusoidal swept frequency for 1.5 Gbit/s: 900 kHz to 5 MHz.

^f Applied sinusoidal swept frequency for 3 Gbit/s: 1 800 kHz to 7.5 MHz.

^g The measurement bandwidth for 1.5 Gbit/s shall be 900 kHz to 750 MHz.

^h The measurement bandwidth for 3 Gbit/s shall be 1 800 kHz to 1 500 MHz.

Figure 139 defines the applied SJ for table 69.

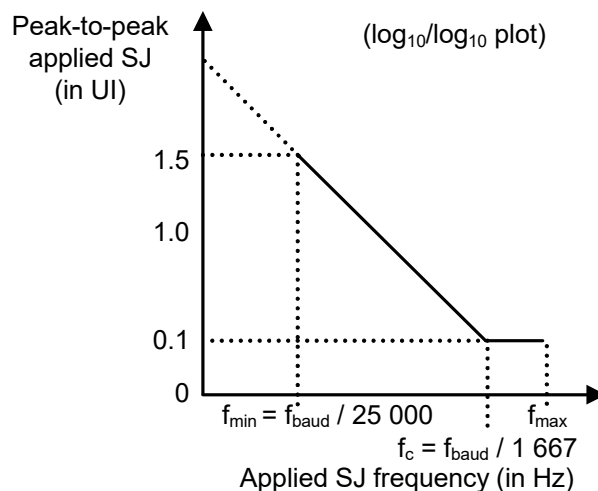


Figure 139 — Applied SJ for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s

Table 70 defines f_{\min} , f_c , and f_{\max} for figure 139. f_{baud} is defined in table 40 (see 5.8.1).

Table 70 — f_{\min} , f_c , and f_{\max} for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s

Physical link rate	f_{\min}	f_c	f_{\max}
1.5 Gbit/s	60 kHz	900 kHz	5 MHz
3 Gbit/s	120 kHz	1 800 kHz	7.5 MHz

5.8.5.7 Receiver device and delivered signal characteristics for trained 6 Gbit/s, 12 Gbit/s, and 22.5 Gbit/s

5.8.5.7.1 Delivered signal characteristics for trained 6 Gbit/s, 12 Gbit/s, and 22.5 Gbit/s

Table 71 specifies the requirements of the signal delivered by the system with the zero-length test load (see 5.6.2), unless otherwise specified, attached at the receiver device compliance point (i.e., IR (see 5.3) or CR (see 5.3)) for trained 6 Gbit/s, 12 Gbit/s, and 22.5 Gbit/s. These also specify the required signal tolerance characteristics of the receiver device. All specifications are based on differential measurements unless otherwise stated.

Table 71 — Delivered signal characteristics for trained 6 Gbit/s, 12 Gbit/s, and 22.5 Gbit/s at IR and CR

Characteristic	Units	Minimum	Nominal	Maximum
Peak to peak voltage for trained 6 Gbit/s, 12 Gbit/s, and 22.5 Gbit/s ^{a b c d}	mV(P-P)			1 200
Non-operational input voltage	mV(P-P)			2 000
Reference differential impedance ^e	Ω		100	
Reference common mode impedance ^e	Ω		25	
^a See 5.8.4.5.6 for the measurement method for trained 6 Gbit/s. ^b See table 50 for the measurement method for 12 Gbit/s. ^c See table 58 for the measurement method for 22.5 Gbit/s. ^d During OOB, SNW-1, SNW-2, and SNW-3 (see SPL-5), the characteristics for OOB signaling rates of 1.5 Gbit/s and 3 Gbit/s specifications in 5.8.5.4 apply. ^e For receiver device S-parameter characteristics, see 5.8.5.7.2.				

5.8.5.7.2 Receiver device S-parameter limits

S-parameter limits are calculated per the following formula:

$$\text{Measured value} < \max [L, \min [H, N + 13.3 \times \log_{10}(f / 3 \text{ GHz})]]$$

where:

- L is the minimum value (i.e., the low frequency asymptote);
- H is the maximum value (i.e., the high frequency asymptote);
- N is the value at 3 GHz;
- f is the frequency of the signal in Hz;
- max [A, B] is the maximum of A and B; and
- min [A, B] is the minimum of A and B.

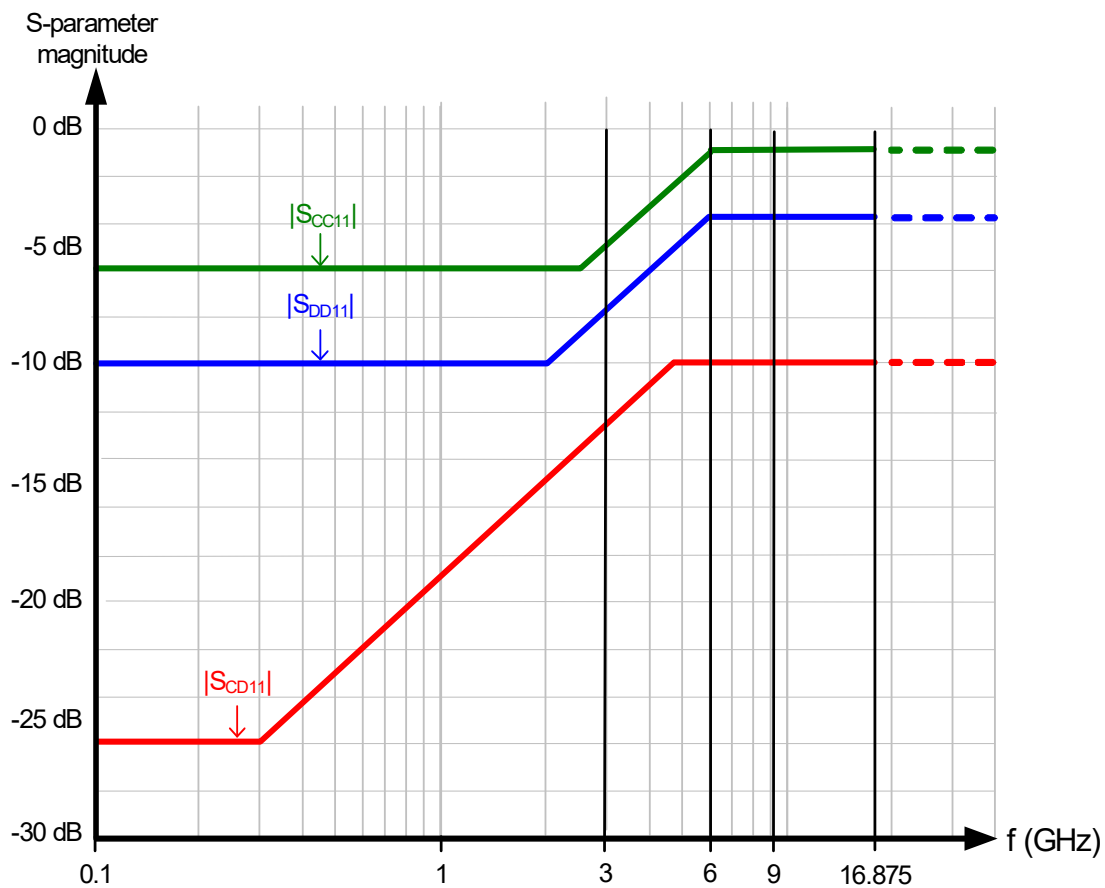
The frequency for N is based on the Nyquist at 6 Gbit/s.

Table 72 defines the maximum limits for S-parameters of the receiver device at IR and CR.

Table 72 — Maximum limits for S-parameters at IR or CR

Characteristic ^a	L ^b (dB)	N ^b (dB)	H ^b (dB)	S ^b (dB / decade)	f _{min} ^b (MHz)	f _{max} ^{b c} (GHz)	f _{max} ^d (GHz)	f _{max} ^e (GHz)
S _{CC11}	-6.0	-5.0	-1.0	13.3	100	6.0	9.0	16.875
S _{DD11}	-10	-7.9	-3.9	13.3	100	6.0	9.0	16.875
S _{CD11}	-26	-12.7	-10	13.3	100	6.0	9.0	16.875
^a S _{DC11} is not specified. ^b See figure 4 in 5.2 for definitions of L, N, H, S, f _{min} , and f _{max} . ^c Applies only for 6 Gbit/s. ^d Applies only for 12 Gbit/s. ^e Applies only for 22.5 Gbit/s.								

Figure 140 shows the receiver device |S_{CC11}|, |S_{DD11}|, and |S_{CD11}| limits defined in table 72.



Note: graph is not to scale

Figure 140 — Receiver device |S_{CC11}|, |S_{DD11}|, and |S_{CD11}| limits at IR and CR

The 22.5 Gbit/s receiver device $|S_{DD11}|$ limit at PR is calculated per the following formula:

$$\text{Measured value} < \max [L, \min [H, N + 13.3 \times \log_{10}(f / 5.625 \text{ GHz})]]$$

where:

- L is the minimum value (i.e., the low frequency asymptote);
- H is the maximum value (i.e., the high frequency asymptote);
- N is the value at 5.625 GHz;
- f is the frequency of the signal in Hz;
- $\max [A, B]$ is the maximum of A and B; and
- $\min [A, B]$ is the minimum of A and B.

Table 73 defines the maximum limit for $|S_{DD11}|$ of the 22.5 Gbit/s receiver device at PR.

Table 73 — 22.5 Gbit/s receiver device maximum limit for $|S_{DD11}|$ at PR

Characteristic	L ^a (dB)	N (dB)	H ^a (dB)	S ^a (dB / decade)	f _{min} ^a (MHz)	f _{max} ^a (GHz)
$ S_{DD22} $	-10	-7.0	-3.9	13.3	100	16.875
^a See figure 4 for definitions of L, H, S, f _{min} , and f _{max} .						

Figure 141 shows the 22.5 Gbit/s receiver device $|S_{DD11}|$ limit at PR defined in table 73.

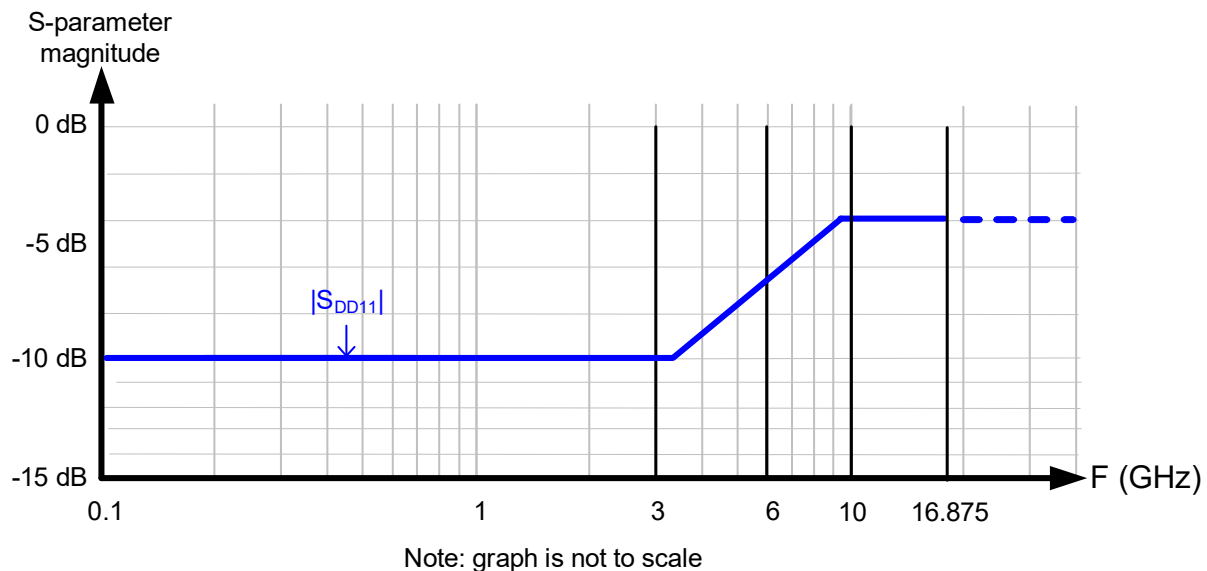


Figure 141 — 22.5 Gbit/s receiver device $|S_{DD11}|$ limit at PR

5.8.5.7.3 Reference receiver device characteristics

5.8.5.7.3.1 Reference receiver device overview

The reference receiver device is a set of parameters defining the electrical performance characteristics of a receiver device used in simulation to:

- a) determine compliance of a transmitter device (see 5.8.4.5 and 5.8.4.6); and
- b) determine compliance of a TxRx connection (see 5.5.5 and 5.5.6).

No reference receiver device is defined for 22.5 Gbit/s.

Figure 142 shows the reference receiver device for trained 6 Gbit/s.

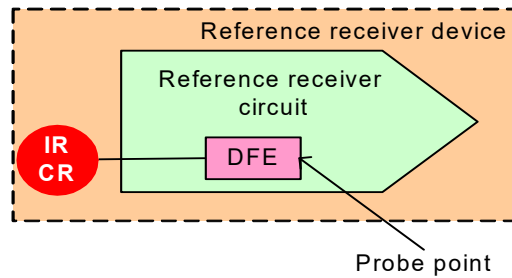


Figure 142 — Reference receiver device for trained 6 Gbit/s

Figure 143 shows the reference receiver device for trained 12 Gbit/s. Passive TxRx connection segments RDCS and RCCS simulate the reference TxRx connection segment between IR and RR or CR and RR. See C.2 for the description of the reference TxRx connection segments.

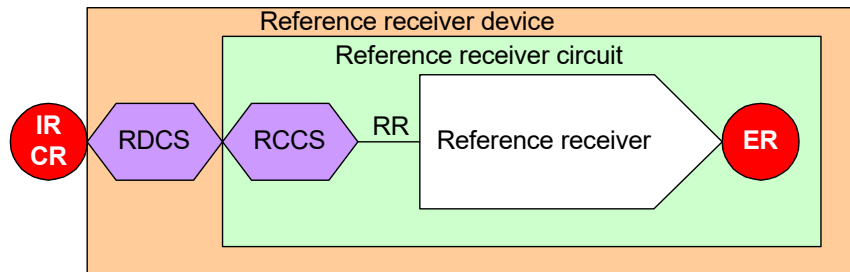


Figure 143 — Reference receiver device for trained 12 Gbit/s

For trained 6 Gbit/s, the reference receiver circuit performs the reference DFE equalization at the center of the eye.

For trained 12 Gbit/s, the reference receiver device:

- 1) applies the reference receiver equalization (see 5.8.5.7.3.3);
- 2) samples the incoming data according to a reference sampling clock (see 3.1.81); and
- 3) performs the reference DFE equalization.

The signal at the probe point or at ER is an analog signal.

5.8.5.7.3.2 Reference receiver device DFE

The reference receiver device includes a multiple tap DFE with infinite precision taps and unit interval tap spacing. The reference coefficient adaptation algorithm is the LMS algorithm. The DFE may be modeled at the reference sampling instants as:

$$y_k = x_k - \sum_{i=1}^{N_{\text{dfe}}} d_i \times \text{sgn}(y_{k-i})$$

where:

y	is the equalizer differential output voltage;
x	is the equalizer differential input voltage;
d	is the equalizer feedback coefficient;
k	is the sample index in UI; and
	is the number of equalizer DFE taps.
N_{dfe}	$N_{\text{dfe}} = 3$ for the trained 6 Gbit/s reference receiver device. $N_{\text{dfe}} = 5$ for the 12 Gbit/s reference receiver device.

The trained 6 Gbit/s, and 12 Gbit/s reference receiver device feedback coefficients (i.e., d_i) have absolute magnitudes that are less than 0.5 times the peak of the equivalent pulse response of the reference receiver device.

NOTE 9 - For more information on DFE and LMS, see John R. Barry, Edward A. Lee, and David G. Messerschmitt. *Digital Communication - Third Edition*. Kluwer Academic Publishing, 2003 (see <https://barry.ece.gatech.edu/digital/>).

5.8.5.7.3.3 Reference receiver device equalization for trained 12 Gbit/s

The reference receiver applies a filter composed of three cascaded identical equalization stages. Each of these stages has the characteristics described in table 74. The frequency response of each stage is of the form:

$$H(s) = (1 + s/(2\pi \times fz_0)) / [(1 + s/(2\pi \times fp_0)) \times (1 + s/(2\pi \times fp_1))]$$

where:

s	represents $2\pi \times f \times (-1)^{0.5}$;
fz_0	is the zero corner frequency;
fp_0	is the first pole corner frequency; and
fp_1	is the second pole corner frequency.

Table 74 — Reference receiver equalization stage characteristics for trained 12 Gbit/s

Characteristic	Units	Value
Zero corner frequency (fz_0)	GHz	2.5
First pole corner frequency (fp_0)	GHz	4
Second pole corner frequency (fp_1)	GHz	10

5.8.5.7.4 Reference receiver device termination characteristics for trained 6 Gbit/s

The following Touchstone model of the reference receiver device termination is included with this standard:

a) SAS2_RxRefTerm.s4p.

Figure 144 shows the S-parameters of the reference receiver device termination model for trained 6 Gbit/s.

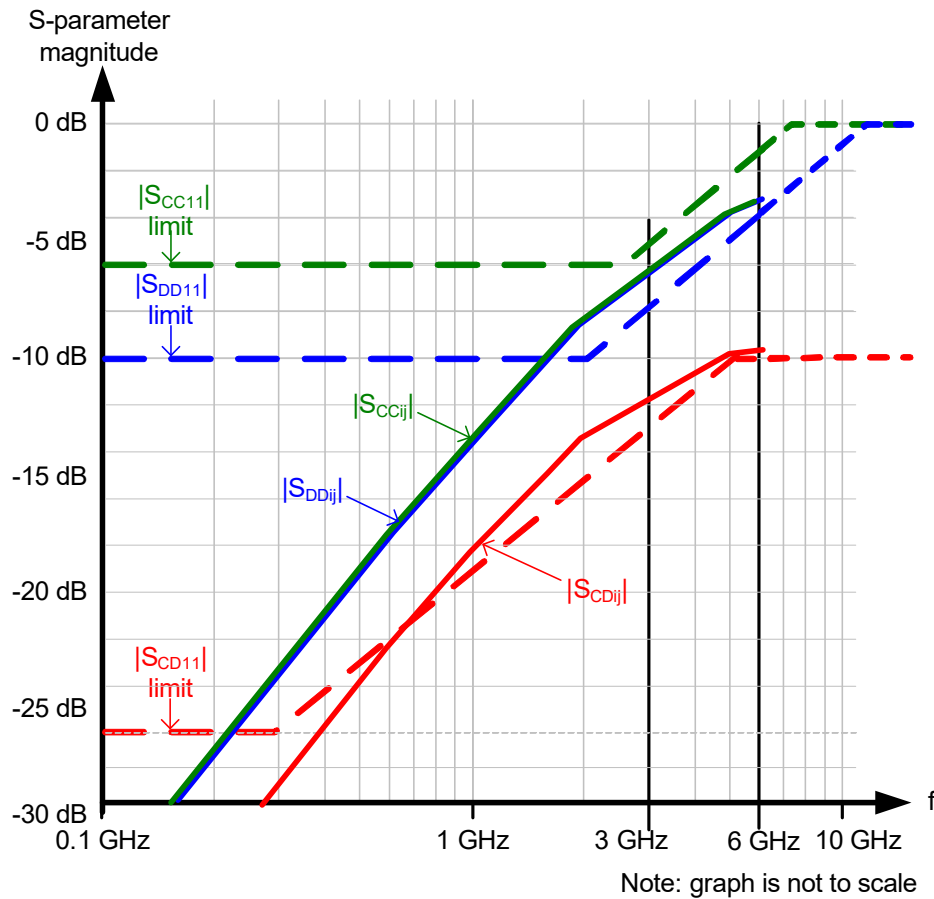


Figure 144 — Reference receiver device termination S-parameters for trained 6 Gbit/s

The Touchstone model does not exactly match the $|S_{CC11}|$, $|S_{DD11}|$, and $|S_{CD11}|$ limits defined in 5.8.5.7.2 at all frequencies, however, it is a reasonable approximation for use in simulations. See Annex H for a description of how the Touchstone model was created.

5.8.5.7.5 Reference receiver device termination characteristics for trained 12 Gbit/s

The termination characteristics of the reference receiver device for trained 12 Gbit/s are determined by the reference TxRx connection segments used in the simulations (see C.2). The reference transmitter presents an ideal termination at RR.

5.8.5.7.6 Stressed receiver device jitter tolerance test

5.8.5.7.6.1 Stressed receiver device jitter tolerance test overview for trained 6 Gbit/s

A receiver device shall pass the stressed receiver device jitter tolerance test described in this subclause.

The stressed receiver device jitter tolerance test for trained 6 Gbit/s shall be applied at the receiver device compliance point (i.e., IR (see 5.3.2) or CR (see 5.3.2)) as a means to perform physical validation of predicted performance of the receiver device. Any implementation of the stressed signal generation hardware is permitted for the stressed receiver signal as long as it provides the ISI-stressed signal with jitter and noise as defined in this subclause.

Figure 145 shows the block diagram of the stressed receiver device jitter tolerance test.

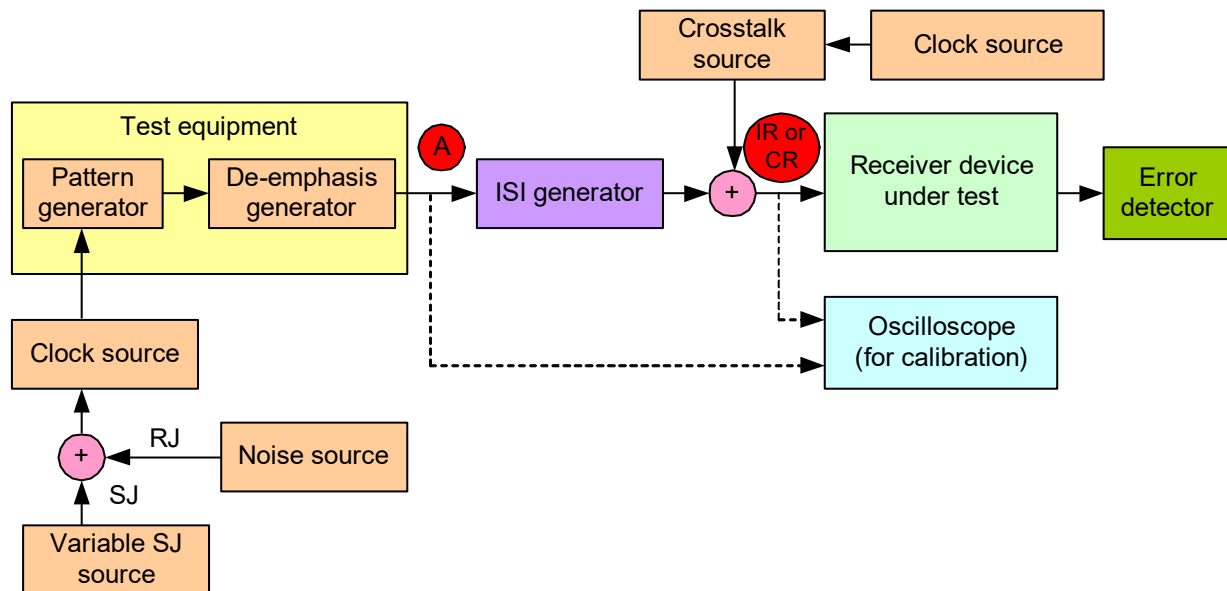


Figure 145 — Stressed receiver device jitter tolerance test block diagram for trained 6 Gbit/s

The ISI generator shall be representative of, and at least as stressful as, the reference transmitter test load (see 5.6.4). The reference transmitter test load (see 5.6.4), with a nominal $|S_{DD21}|$ of -15 dB at $(f_{\text{baud}} / 2)$, may be used as a component of the ISI generator.

The receiver device under test demonstrates its ability to compensate for channel intersymbol interference (ISI) representative of the reference transmitter test load (see 5.6.4) while subjected to the budgeted jitter and crosstalk sources.

Table 75 defines the stressed receiver device jitter tolerance test characteristics for trained 6 Gbit/s. Unless otherwise noted, characteristics are measured at IR (see 5.3.2) or CR (see 5.3.2) in figure 145.

Table 75 — Stressed receiver device jitter tolerance test characteristics for trained 6 Gbit/s

Characteristic	Units	Minimum	Nominal	Maximum	Reference
TX peak to peak voltage ^a	mV(P-P)		850		5.8.4.5.1
Transmitter equalization ^a	dB		2		5.8.4.5.6
TX RJ ^{b c d}	UI	0.135 ^e	0.150 ^f	0.165 ^g	5.8.4.5.1
TX SJ ^c	UI	See figure 149 and figure 150			5.8.5.7.6.10
WDP at 6 Gbit/s ^{b h}	dB	13		14.5	
D24.3 eye opening ^{b i}	mV(P-P)	200	215	230	5.8.3.4
NEXT offset frequency ^{i j k}	ppm	2 500			
Total crosstalk amplitude ^{i k}	mV _{rms}	4			
Receiver device configuration ^l					

^a For a characteristic with only a nominal value, the test setup shall be configured to be as close to that value as possible while still complying with other characteristics in this table.

^b For characteristics with minimum and maximum values, the test setup shall be configured to be within the range specified by the minimum and maximum values. The range shall not be used to define corner test conditions required for compliance.

^c Measured at point A in figure 145.

^d Measured after application of the JTF (see 5.8.3.2).

^e 0.135 UI is 22.5 ps at 6 Gbit/s.

^f 0.150 UI is 25 ps at 6 Gbit/s.

^g 0.165 UI is 27.5 ps at 6 Gbit/s.

^h This value is obtained by simulation with SASWDP (see Annex B). BUJ and RJ shall be minimized for WDP simulations. The WDP value is a characterization of the signal output within the reference receiver device (see 5.8.5.7.3) after equalization.

ⁱ The repeating 0011b pattern or 1100b pattern (e.g., D24.3) eye opening pertains to the delivered signal at IR or CR. Figure 146 defines this value in an eye diagram.

^j The NEXT source may use SSC modulation rather than have a fixed offset frequency.

^k Observed with a histogram of at least 1 000 samples. Additional pseudo-random crosstalk shall be added, if needed, to meet the total crosstalk amplitude specification.

^l All transmitter devices and receiver devices adjacent to the receiver device under test shall be active with representative traffic with their maximum amplitude and maximum frequency of operation.

Figure 146 shows the stressed receiver device jitter tolerance test repeating 0011b pattern or 1100b pattern (e.g., D24.3) eye opening for trained 6 Gbit/s.

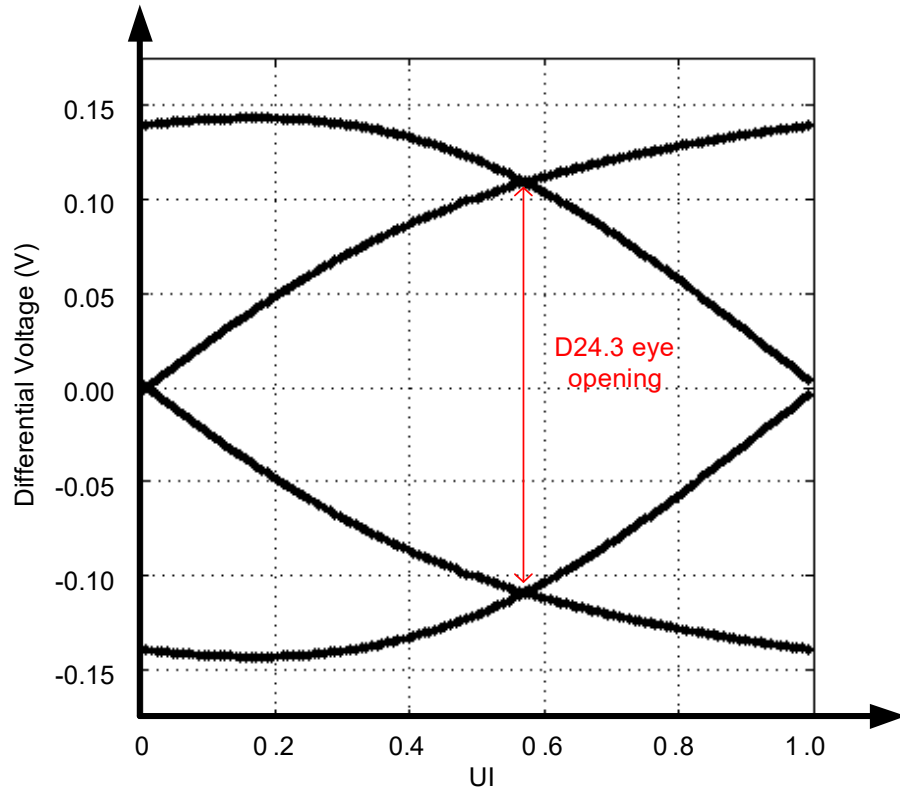


Figure 146 — Stressed receiver device jitter tolerance test D24.3 eye opening for trained 6 Gbit/s

5.8.5.7.6.2 Stressed receiver device jitter tolerance test procedure for trained 6 Gbit/s

The stressed receiver device jitter tolerance test procedure for trained 6 Gbit/s is as follows:

- 1) calibrate the test equipment and ISI generator as specified in 5.8.5.7.6.3;
- 2) calibrate the crosstalk source as specified in 5.8.5.7.6.4;
- 3) attach the test equipment and ISI generator and the crosstalk source to the receiver device under test;
- 4) configure the pattern generator to transmit a Train_Rx-SNW pattern (see SPL-5);
- 5) allow the receiver device to complete the Train_Rx-SNW;
- 6) configure the applied SJ as specified in 5.8.5.7.6.10;
- 7) configure the pattern generator to transmit CJTPAT (see Annex A); and
- 8) ensure that the receiver device under test has a BER that is less than 10^{-12} with a confidence level of 95 %.

This procedure requires the receiver under test to train during Train_Rx-SNW as specified in SPL-5. This training may be performed by:

- a) using the mechanisms defined in SPL-5; or
- b) using an equivalent procedure.

The use of an equivalent procedure is outside the scope of this standard.

Table 76 defines the number of bits that shall be received with a certain number of errors to have a confidence level of 95 % that the BER is less than 10^{-12} .

Table 76 — Number of bits received per number of errors for desired BER

Number of errors	Number of bits
0	3.00×10^{12}
1	4.74×10^{12}
2	6.30×10^{12}
3	7.75×10^{12}
4	9.15×10^{12}
5	1.05×10^{13}

5.8.5.7.6.3 Test equipment and ISI generator calibration for trained 6 Gbit/s

The test equipment and ISI generator calibration procedure for trained 6 Gbit/s is as follows:

- 1) ensure that the ISI generator has an $|S_{DD21}|$ comparable to that of the reference transmitter test load (see 5.6.4). $|S_{DD21}|$ delivered by the ISI generator shall be measured by observing the D24.3 eye opening at IR or CR as defined in table 75;
- 2) attach the test equipment and ISI generator to a zero-length test load, where its signal output is captured by an oscilloscope;
- 3) disable the crosstalk source;
- 4) disable the variable SJ source and the random noise source;
- 5) configure the pattern generator to transmit the SCRAMBLED_0 pattern (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5);
- 6) capture multiple sets of the first 58 data dwords (i.e., 2 320 bits on the physical link) of the SCRAMBLED_0 pattern. Waveform averaging shall be used to minimize the impact of measurement noise and jitter on the WDP calculations;
- 7) input the captured pattern into SASWDP simulation (see Annex B) with the usage variable set to 'SAS2_LDP'; and
- 8) adjust the ISI generator until the WDP is within the range defined in table 75.

WDP values computed by SASWDP are influenced by all sources of eye closure including DCD, BUJ, and ISI, and increased variability in results may occur due to increases in those sources other than ISI.

5.8.5.7.6.4 Crosstalk source calibration for trained 6 Gbit/s

The crosstalk source calibration procedure for trained 6 Gbit/s is as follows:

- 1) attach the test equipment and ISI generator and the crosstalk source to a zero-length test load, where its signal output is captured by an oscilloscope;
- 2) disable the pattern generator;
- 3) enable the crosstalk source;
- 4) set the center frequency of the crosstalk source to be frequency offset from the pattern generator to sweep all potential relative phase alignments between the crosstalk source and the signal from the ISI generator;
- 5) generate a histogram of the signal delivered to the test equipment; and
- 6) adjust the crosstalk source until the crosstalk amplitude complies with table 75.

5.8.5.7.6.5 Stressed receiver device jitter tolerance test procedure for trained 12 Gbit/s

The stressed receiver device jitter tolerance test procedure for 12 Gbit/s is as follows:

- 1) calibrate the test equipment and ISI generator as specified in 5.8.5.7.6.6;
- 2) calibrate the crosstalk source as specified in 5.8.5.7.6.7;
- 3) attach the test equipment and ISI generator and the crosstalk generator to the receiver device under test;
- 4) configure the devices on the receiver device board to transmit and receive representative traffic, including the transmitter device associated with the receiver device under test;
- 5) configure the pattern generator to transmit a Train_Tx-SNW pattern (see SPL-5);
- 6) allow the receiver to complete the Train_Tx-SNW;
- 7) configure the pattern generator to transmit a Train_Rx-SNW pattern (see SPL-5);
- 8) allow the receiver to complete the Train_Rx-SNW;
- 9) configure the applied RJ as specified in 5.8.5.7.6.8;
- 10) configure the applied SJ as specified in 5.8.5.7.6.10;
- 11) configure the pattern generator to transmit CJTPAT (see Annex A); and
- 12) ensure that the receiver device under test has a BER that is less than 10^{-12} with a confidence level of 95 %.

The configuration of the transmitter device associated with the receiver device under test may be performed after the receiver training completes.

This procedure requires the receiver under test to train during Train_Tx-SNW and Train_Rx-SNW as specified in SPL-5 (see figure 147). This training may be performed by:

- a) using the mechanisms defined in SPL-5; or
- b) using an equivalent procedure.

The test equipment shall be capable of adjusting its transmitter coefficients as requested by the receiver under test. The use of an equivalent procedure is outside the scope of this standard.

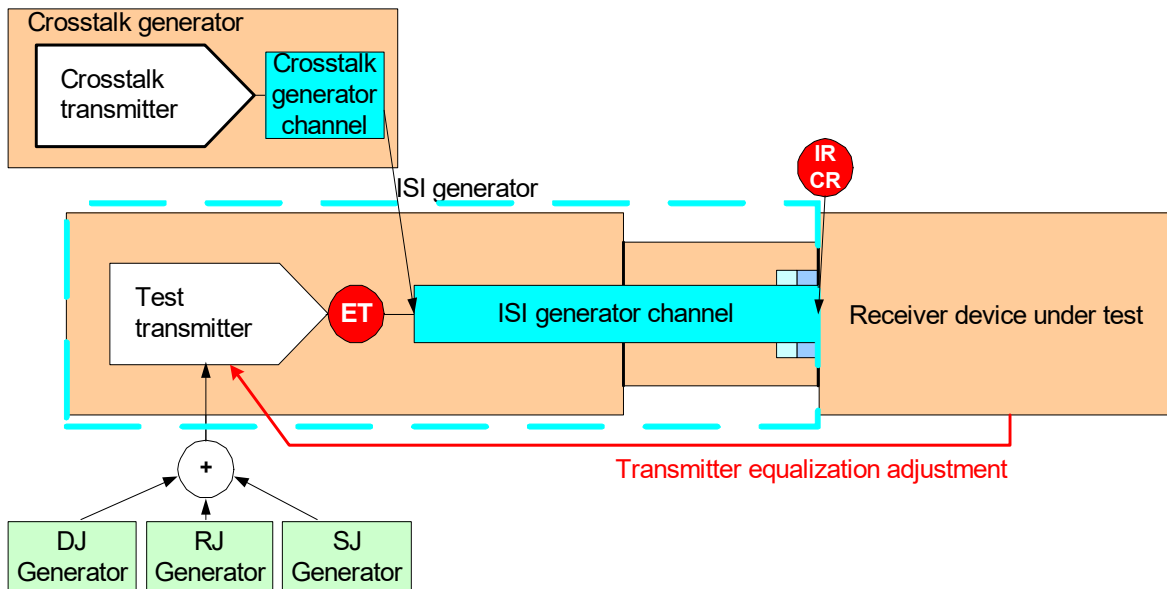


Figure 147 — Stressed receiver transmitter equalization adjustment for 12 Gbit/s

5.8.5.7.6.6 ISI generator calibration for trained 12 Gbit/s

The delivered signal for stressed receiver device jitter tolerance test for 12 Gbit/s (see 5.8.5.7.6) shall provide ISI characteristics defined in table 77.

The characteristics at ER shall be measured using end to end simulations (see 5.7.1 and Annex C).

To simplify de-embedding to ET, the peak to peak voltage may be measured from the output of the ISI generator's transmitter, if the ISI channel has insertion loss less than 1.5 dB at 10 MHz (e.g., 10 MHz represents effective D.C., excluding A.C. coupling). Using this method, the peak to peak voltage is computed by scaling down the measured amplitude by the loss of the ISI channel at 10 MHz. This simplified de-embedding method requires verification of the ISI channel insertion loss.

The effective ISI generator's transmitter output may include attenuators or power combiners. The characteristics of the ISI generator's transmitter, including transmitter circuit response to coefficient steps and coefficient preset settings, are measured including the attenuators or power combiners.

The transmitter coefficients are simulated by replacing the test transmitter by the reference transmitter generating no jitter (i.e., no RJ or TJ). This is equivalent to inserting a jitter free reference transmitter with K_0 set to 1 (unit-less value) at the output of the ISI generator, using the ISI generator's output as the input of the reference transmitter, instead of the +1/-1 digitized stream (see figure 148).

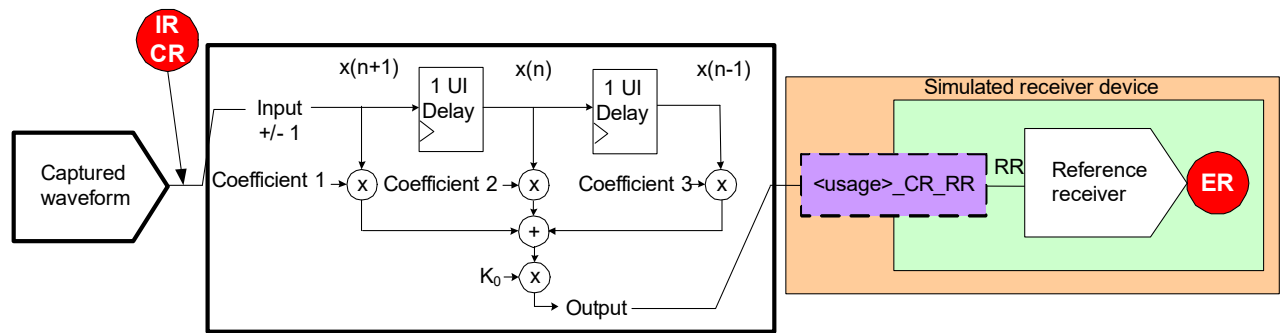


Figure 148 — Simulation of the reference transmitter from a captured signal

The ISI generator's transmitter device shall have the trained 12 Gbit/s transmitter characteristics (see 5.8.4.6). The ISI generator shall be capable of changing its equalization in response to the attached receiver device's back channel requests (see SPL-5). This may be performed using a duplex link as defined in SPL-5, or through the use of an equivalent procedure. The use of an equivalent procedure is outside the scope of this standard.

The ISI generator calibration procedure is as follows:

- 1) set the transmitter of the ISI generator to output no equalization (i.e., coefficient 1 set to zero, coefficient 2 set to one, coefficient 3 set to zero);
- 2) attach the test equipment and ISI generator to a zero-length test load;
- 3) disable:
 - A) the crosstalk source;
 - B) the RJ source;
 - C) the DJ source;
 - D) the SSC source; and
 - E) the variable SJ source;
- 4) configure the pattern generator to transmit a repeating 7Eh (i.e., D30.3) pattern (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5);
- 5) set the transmitter peak to peak voltage to the characteristics of table 77;
- 6) configure the pattern generator to transmit IDLE dwords (see SPL-5);
- 7) capture the signal at IR or CR;
- 8) simulate signal characteristics and reference transmitter characteristics (see C.1), using reference <usage>_CR_RR channel models of the appropriate usage model (see C.2); and
- 9) adjust the ISI generator channel for end to end simulation characteristics defined in table 77.

Table 77 defines the characteristics measured in end to end simulation of the delivered signal for trained 12 Gbit/s stressed receiver device jitter tolerance test.

See the reference transmitter device (see 5.8.4.6.4) for definitions of coefficient 1 (i.e., C1), coefficient 2 (i.e., C2), and coefficient 3 (i.e., C3) used in table 77.

Table 77 — ISI generator characteristics for trained 12 Gbit/s at ET and ER

Characteristic	Units	Minimum	Maximum	Compliance point
Peak to peak voltage ^{a b}	mV(P-P)	850	1 000	ET (see 5.3.3)
Coefficient 1 (i.e., C1) ^{c d e}	V/V	-0.15	0	ET
Coefficient 3(i.e., C3) ^{c d f}	V/V	-0.3	0	ET
VMA ^{g h}	mV(P-P)	80		ET
Reference pulse response cursor peak to peak amplitude ^{i j}	mV(P-P)	125	145	ER (see 5.3.3)
Vertical eye opening to reference pulse response cursor ratio ^{j k l}	%	65	80	ER
DFE coefficient magnitude to reference pulse response cursor ratio ^m	%	5	50	ER

^a The measurement shall be made with the ISI generator transmitter set to no equalization and a repeating 7Eh (i.e., D30.3) pattern (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5).

^b The peak to peak voltage is adjusted as close as possible to the minimum limit.

^c If C1 or C3 exceeds its maximum (positive) limit, then it is forced to its maximum limit and the other coefficients are recalculated.

^d $C2 = 1 - |C1| - |C3|$.

^e If C1 exceeds its minimum (negative) limit, then it is forced to its minimum limit and C3 is recalculated.

^f If C3 exceeds its minimum limit, then it is forced to its minimum limit and C1 is recalculated. If C1 had already reached or exceeded its minimum limit, then both C1 and C3 are forced to their minimum limit.

^g $VMA = 2K_0 (C1 + C2 + C3) V$. See 5.8.4.6.4.

^h If VMA exceeds its minimum limit, then C1 and C3 are forced to values that have the smallest distance to a point compliant to the VMA specification in the C1/C3 plane. The distance is defined as:

$$\sqrt{(C1' - C1)^2 + (C3' - C3)^2}$$

where:

C1' and C3' are values that satisfy the minimum VMA criterion.

ⁱ The average amplitude of the eye for a random pattern digital input at the compliance point may be used for this measurement. See figure 115.

^j The end to end simulation removes any remaining RJ and TJ (i.e., non-ISI) of the ISI generator's transmitter.

^k The vertical eye opening does not include crosstalk. Crosstalk representing FEXT is calibrated as specified in 5.8.5.7.6.7, while representative traffic is present during the test to provide NEXT crosstalk (see 5.8.5.7.6.5).

^l The ISI generator is adjusted as close as possible to the maximum reference pulse response cursor and vertical eye opening to reference pulse response cursor ratio limits.

^m This is the maximum of the absolute value of the reference DFE coefficients (i.e., $\max(\text{abs}(d_i))$) divided by the reference pulse response cursor (see 5.8.5.7.3)).

5.8.5.7.6.7 Crosstalk calibration for trained 12 Gbit/s stressed receiver device jitter tolerance test

Total peak to peak crosstalk noise shall be measured as defined in 5.7.4 at IR (see 5.3.3) or CR (see 5.3.3). The crosstalk is added to the simulation as a measured peak to peak amplitude at a cumulative probability of 10^{-6} (see 5.7.4). The characteristics of the crosstalk amplitude are defined in table C.5. The crosstalk shall be generated by a single transmitter with:

- a) a minimum fixed offset frequency of 1 000 ppm; or
- b) using SSC modulation rather than the fixed offset frequency.

5.8.5.7.6.8 Applied RJ for trained 12 Gbit/s stressed receiver device jitter tolerance test

The delivered signal for stressed receiver device jitter tolerance test (see 5.8.5.7.6.5) shall provide RJ characteristics defined in table 78.

Table 78 — RJ characteristics for trained 12 Gbit/s stressed receiver device tolerance test

Characteristic	Units	Minimum	Nominal	Maximum
RJ ^{a b c d}	UI	0.135 ^e	0.150 ^f	0.165 ^g
^a For characteristics with minimum and maximum values, the test setup shall be configured to be within the range specified by the minimum and maximum values. The range shall not be used to define corner test conditions required for compliance. ^b Measured at ER, IR, or CR as shown in figure 148. ^c The RJ measurement shall be performed with a repeating 0011b pattern or 1100b pattern (e.g., D24.3) with SSC disabled. RJ is 14 times the RJ 1 sigma value, based on a BER of 10^{-12} . ^d Measured after application of the JTF (see 5.8.3.2). ^e 0.135 UI is 11.25 ps at 12 Gbit/s. ^f 0.150 UI is 12.5 ps at 12 Gbit/s. ^g 0.165 UI is 13.75 ps at 12 Gbit/s.				

5.8.5.7.6.9 Stressed receiver device jitter tolerance test procedure for trained 22.5 Gbit/s

The stressed receiver device jitter tolerance test procedure for 22.5 Gbit/s is as follows:

- 1) configure the devices on the receiver device board to transmit and receive representative traffic, including the transmitter device associated with the receiver device under test;
- 2) configure the test equipment transmitter device to comply with the characteristics defined in table 79 prior to training the test equipment transmitter device;
- 3) configure the channel characteristics between the transmitter device associated with the receiver device under test and the receiver device under test to represent the worst case set of characteristics specified for a compliant 22.5 Gbit/s channel (see 5.5.7);
- 4) configure the pattern generator to transmit a Train_Tx-SNW pattern (see SPL-5);
- 5) allow the receiver to complete the Train_Tx-SNW;
- 6) the test equipment transmitter device shall use the transmitter coefficients as requested by the receiver device under test;
- 7) configure the pattern generator to transmit a Train_Rx-SNW pattern (see SPL-5);
- 8) allow the receiver to complete the Train_Rx-SNW;
- 9) configure the applied SJ as specified in 5.8.5.7.6.10;
- 10) configure the pattern generator to transmit PRBS31 (see ITU-T) on the physical link; and
- 11) ensure that the receiver device under test has a BER that is less than 10^{-9} with a confidence level of 95 %.

Table 79 specifies the test equipment transmitter device signal output characteristics for stressed receiver device testing for trained 22.5 Gbit/s.

Table 79 — Test equipment transmitter device signal output characteristics for stressed receiver device testing for trained 22.5 Gbit/s at PT, IT, and CT

Signal characteristic	Symbol	Units	Minimum	Nominal	Maximum
Peak to peak voltage (V_{P-P}) ^{a b}		mV(P-P)	850		1 000
Transmitter device off voltage at IT or CT ^{c d}		mV(P-P)			50
Reference differential impedance at IT or CT ^e		Ω		100	
Reference common mode impedance at IT or CT ^e		Ω		25	
Rise/fall time at IT or CT ^f		UI	0.30 ^g		0.41 ^h
Common mode noise ⁱ		mV rms			12
Uncorrelated unbounded Gaussian jitter ^{j k l}	T_UUGJ	UI	0.135 ^m	0.15 ⁿ	0.165 ^o
Uncorrelated bounded high probability jitter ^{j k}	T_UBHPJ	UI	0.085 ^p	0.10 ^q	0.115 ^r
Duty cycle distortion ^s	T_DCD	UI			0.035 ^t
Total jitter ^{j k}	T_TJ	UI			0.28 ^u

^a The V_{P-P} measurement shall be made with the transmitter device set to no equalization (see table 53) and amplitude set to maximum. The minimum value applies at PT (see 5.3.4) and the maximum value applies at IT (see 5.3.4) or CT (see 5.3.4). The measurement is made with a repeating 7Eh (i.e., D30.3) pattern (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5).
^b The V_{P-P} amplitude should be set as close as possible to the minimum value.
^c The transmitter device off voltage is the maximum A.C. voltage measured at compliance points IT and CT when the transmitter is unpowered or transmitting D.C. idle (e.g., during idle time of an OOB signal).
^d If optical mode is enabled, then the transmitter device off voltage is not applicable.
^e See 5.8.4.7.3 for transmitter device S-parameters characteristics.
^f Rise/fall times are measured from 20 % to 80 % of the transition with a repeating 01b pattern or 10b pattern (e.g., D10.2 or D21.5) (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5).
^g 0.30 UI is 13.3 ps at 22.5 Gbit/s.
^h 0.41 UI is 18.2 ps at 22.5 Gbit/s.
ⁱ Common mode noise is measured using the PRBS15 (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5) (see ITU-T) on the physical link.
^j For jitter measurements, see 5.8.4.7.4.
^k The measurement shall include the effects of the JTF (see 5.8.3.2).
^l The T_UUGJ nominal value of 0.15 UI corresponds to a value of 0.01 UI rms.
^m 0.135 UI is 5.9 ps at 22.5 Gbit/s.
ⁿ 0.15 UI is 6.6 ps at 22.5 Gbit/s.
^o 0.165 UI is 7.3 ps at 22.5 Gbit/s.
^p 0.085 UI is 3.7 ps at 22.5 Gbit/s.
^q 0.10 UI is 4.4 ps at 22.5 Gbit/s.
^r 0.115 UI is 5.1 ps at 22.5 Gbit/s.
^s T_DCD is measured with a repeating 01b pattern or 10b pattern (e.g., D10.2 or D21.5) (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5) on the physical link. Duty cycle distortion is part of the CBHPJ (correlated bounded high probability jitter) distribution (see OIF-CEI) and is measured at the time-averaged signal level. T_DCD shall be measured with transmitter device equalization on and transmitter device equalization set to no_equalization (see table 53).
^t 0.035 UI is 1.5 ps at 22.5 Gbit/s.
^u 0.28 UI is 12.4 ps at 22.5 Gbit/s.

S-parameter files representing example TxRx connections for testing receiver devices supporting rates of 22.5 Gbit/s are included in the SAS4 directory of SAS-4_1.zip in rar format. Multiple TxRx connections are used to represent the set of worst case TxRx connection characteristics for verifying receiver device compliance, as variations in insertion loss are required to achieve the worst case conditions of other TxRx connection characteristics. The S-parameter files in the SAS4 directory of SAS-4_1.zip representing TxRx connections are informative.

This procedure requires the receiver under test to train during Train_Tx-SNW and Train_Rx-SNW as specified in SPL-5 (see figure 147). This training may be performed by:

- a) using the mechanisms defined in SPL-5; or
- b) using an equivalent procedure.

The test equipment shall be capable of adjusting its transmitter coefficients as requested by the receiver under test. The use of an equivalent procedure is outside the scope of this standard.

The BER of less than 10^{-9} for the PRBS31 (see ITU-T) pattern is representative of a BER of less than 10^{-15} for a compliant 22.5 Gbit/s data signal with FEC on the physical link.

5.8.5.7.6.10 Applied SJ

Figure 149 defines the applied SJ for trained receiver devices that do not support SSC.

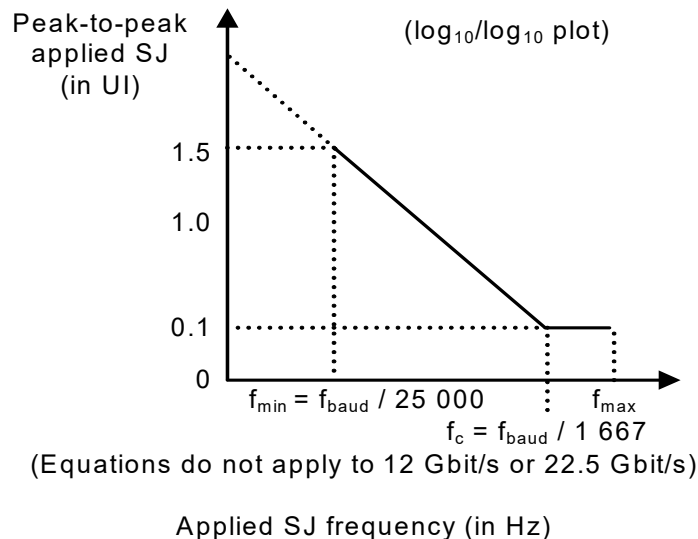


Figure 149 — Applied SJ for trained Gbit/s, 12 Gbit/s, and 22.5 Gbit/s without SSC support

Table 80 defines f_{\min} , f_c , and f_{\max} for figure 149. f_{baud} is defined in table 40 (see 5.8.1).

Table 80 — f_{\min} , f_c , and f_{\max} for trained 6 Gbit/s, 12 Gbit/s, and 22.5 Gbit/s without SSC support

Physical link rate	f_{\min}	f_c	f_{\max}
6 Gbit/s	240 kHz	3 600 kHz	15 MHz
12 Gbit/s	240 kHz	3 600 kHz	15 MHz
22.5 Gbit/s	240 kHz	3 600 kHz	15 MHz

Figure 150 defines the applied SJ for trained receiver devices that support SSC.

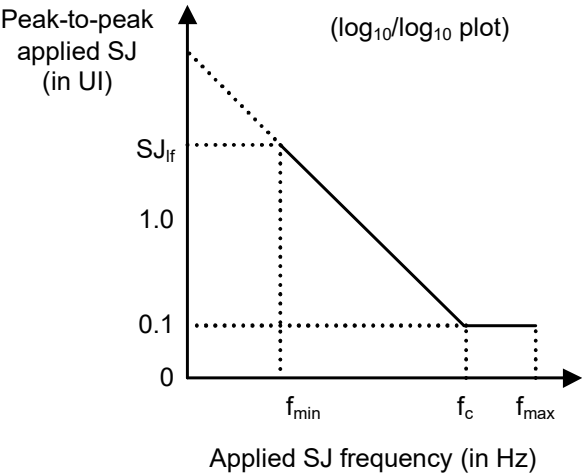


Figure 150 — Applied SJ for trained 6 Gbit/s, 12 Gbit/s, and 22.5 Gbit/s with SSC support

Table 81 defines f_{min} , f_c , f_{max} , and SJ_{if} for figure 150.

Table 81 — f_{min} , f_c , f_{max} , and SJ_{if} for trained 6 Gbit/s, 12 Gbit/s, and 22.5 Gbit/s with SSC support

Physical link rate	f_{min}	f_c	f_{max}	SJ_{if}
6 Gbit/s	97 kHz	2.06 MHz	15 MHz	45.3 UI
12 Gbit/s	111 kHz	2.06 MHz	15 MHz	34.6 UI
22.5 Gbit/s	119 kHz	2.06 MHz	30 MHz	30.1 UI

5.8.5.8 Delivered signal characteristics for OOB signals

Table 82 defines the amplitude requirements of the OOB signal delivered by the system with the zero-length test load (see 5.6.2) at the receiver device compliance point (i.e., IR (see 5.3) or CR (see 5.3)). These also serve as the required signal tolerance characteristics of the receiver device.

Table 82 — Delivered signal characteristics for OOB signals

Characteristic	Units	IR	CR
Minimum OOB burst amplitude ^a , if SATA is not supported	mV(P-P)	240 ^b	
Minimum OOB burst amplitude ^a , if SATA is supported	mV(P-P)	225 ^{c d}	N/A
^a With a measurement bandwidth of 4.5 GHz, each signal level during the OOB burst shall exceed the specified minimum differential amplitude before transitioning to the opposite bit value or before termination of the OOB burst. ^b The OOB burst contains either 1.5 Gbit/s repeating 0011b pattern or 1100b pattern (e.g., D24.3), 1.5 Gbit/s ALIGN (0) primitives, or 3 Gbit/s ALIGN (0) primitives (see SPL-5). ^c The OOB burst contains either 1.5 Gbit/s repeating 0011b pattern or 1100b pattern (e.g., D24.3) or 1.5 Gbit/s ALIGN (0) primitives (see SPL-5 and SATA). ^d Amplitude measurement methodologies of SATA and this standard differ. Under conditions of maximum rise/fall time and jitter, eye diagram methodologies used in this standard may indicate less signal amplitude than the technique specified by SATA. Implementers of designs supporting SATA are required to ensure interoperability and should perform additional system characterization with an eye diagram methodology using SATA devices.			

5.8.6 Spread spectrum clocking (SSC)

5.8.6.1 SSC overview

Spread spectrum clocking (SSC) is the technique of modulating the operating frequency of a transmitted signal to reduce the measured peak amplitude of radiated emissions.

Phys transmit with SSC as defined in 5.8.6.2 and receive with SSC as defined in 5.8.6.3.

Table 83 defines the SSC modulation types.

Table 83 — SSC modulation types

SSC modulation type	Maximum SSC frequency deviation (SSC _{tol}) ^a				
	1.5 Gbit/s ^b	3 Gbit/s ^b	6 Gbit/s	12 Gbit/s	22.5 Gbit/s
Center-spreading	+2 300 / -2 300 ppm			+1 000 / -1 000 ppm	+500 / -500 ppm
No-spreading	+0 / -0 ppm			+0 / -0 ppm	+0 / -0 ppm
Down-spreading	+0 / -2 300 ppm			+0 / -1 000 ppm	+0 / -500 ppm
SATA down-spreading ^c	+0 / -5 000 ppm			N/A	N/A
<div><div>^a This is in addition to the physical link rate accuracy and tolerance defined in table 42 and table 64.</div><div>^b Applies only for OOB signaling characteristics.</div><div>^c This is only used as a receiver parameter.</div></div>					

A phy may transmit with a different SSC modulation type than it receives (e.g., a phy may transmit with center-spreading while it receives with down-spreading).

If the SSC modulation type is not no-spreading, then the phy shall transmit within the specified maximum SSC frequency deviation with an SSC modulation frequency that is a minimum of 30 kHz and a maximum of 33 kHz.

The SSC modulation profile (e.g., triangular) is vendor specific, but should provide the maximum amount of EMI reduction. For center-spreading, the average amount of up-spreading (i.e., > 0 ppm) in the SSC modulation profile shall be the same as the average amount of down-spreading (i.e., < 0 ppm). The amount of asymmetry in the SSC modulation profile shall be less than 288 ppm.

NOTE 10 - 288 ppm is the rate of deletable primitives (see SPL-5) that are left over after accounting for the physical link rate accuracy. It is calculated as the deletable primitive rate defined in the SAS standard of $1 / 2 \text{ 048}$ (i.e., 488 ppm) minus the width between the extremes of the physical link rate accuracy of +100 ppm to -100 ppm (i.e., 200 ppm).

SSC induced jitter is included in TJ at the transmitter output.

The slope of the frequency deviation should not exceed 850 ppm/μs when computed over any $0.27 \text{ μs} \pm 0.01 \text{ μs}$ interval of the SSC modulation profile, after filtering of the transmitter device jitter output by a second order Butterworth low pass filter with a cutoff frequency of $3.7 \text{ MHz} \pm 0.2 \text{ MHz}$.

The slope is computed from the difference equation:

$$\text{slope} = (f(t) - f(t - 0.27 \text{ μs})) / 0.27 \text{ μs}$$

where:

$f(t)$ is the SSC frequency deviation expressed in ppm.

A $\pm 2 \text{ 300 ppm}$ triangular SSC modulation profile has a slope of approximately 310 ppm/μs and meets the informative slope specification. Other SSC modulation profiles (e.g., exponential) may or may not meet the slope requirement. A modulation profile that has a slope of $\pm 850 \text{ ppm/μs}$ over 0.27 μs creates a residual jitter of approximately 16.7 ps (i.e., 0.10 UI at 6 Gbit/s) after filtering by the JTF. This consumes the total BUJ budget of the transmitter device, which does not allow the transmitter device to contribute any other type of BUJ.

Activation or deactivation of SSC on a physical link that is not OOB idle or negotiation idle (see SPL-5) shall be done without violating TJ at the transmitter device output after application of the JTF.

5.8.6.2 Transmitter SSC modulation

A SAS phy transmits with the SSC modulation types defined in table 84.

Table 84 — SAS phy transmitter SSC modulation types

Condition	SSC modulation type(s) ^a	
	Mandatory	Optional
While attached to a phy that does not support SSC	No-spreading	
While attached to a phy that supports SSC	No-spreading	Down-spreading
^a SAS phys compliant with SAS-1.1 only transmitted with an SSC modulation type of no-spreading.		

An expander phy transmits with the SSC modulation types defined in table 85.

Table 85 — Expander phy transmitter SSC modulation types

Condition	SSC modulation type(s) ^a	
	Mandatory	Optional
While attached to a SAS phy or expander phy that does not support SSC	No-spreading	
While attached to a SAS phy or expander phy that supports SSC	No-spreading	Center-spreading
While attached to a SATA phy	No-spreading	Down-spreading
^a Expander phys compliant with SAS-1.1 only transmitted with an SSC modulation type of no-spreading.		

A SAS device (see SPL-5) or expander device (see SPL-5) should provide independent control of SSC on each transmitter device. However, a SAS device or expander device may implement a common SSC transmit clock in which multiple transmitter devices do not have independent controls to enable and disable SSC. In such implementations, SSC may be disabled on a transmitter device that is already transmitting with SSC enabled when another transmitter device sharing the same common SSC transmit clock is required to perform SNW-1, SNW-2, SNW-3, or Final-SNW (see SPL-5) or SAS speed negotiation (see SPL-5).

If any transmitter device sharing a common SSC transmit clock enters a non-SSC transmission state (e.g., SNW-1, SNW-2, Final-SNW, Train_Tx-SNW, or Train_Rx-SNW with SSC disabled (see SPL-5)), then any transmitter device sharing that common SSC transmit clock may disable SSC. These transmitter devices are compliant with the SSC requirements even if the transmitter device has negotiated SSC enabled but its transmit clock has SSC disabled, provided that the transmitted signal does not exceed the maximum SSC frequency deviation limits specified in table 83.

The disabling and enabling of SSC may occur at any time (see 5.8.6.1) except during SNW-1, SNW-2, and Final-SNW (see SPL-5).

5.8.6.3 Receiver SSC modulation tolerance

SAS phys and expander phys support (i.e., tolerate) receiving with SSC modulation types defined in table 86.

Table 86 — Receiver SSC modulation types tolerance

Type of phys	SSC modulation type(s) ^{a b}	
	Mandatory	Optional ^c
Phys that support being attached to SATA phys	No-spreading and SATA down-spreading	Center-spreading and down-spreading
Phys that do not support being attached to SATA phys	No-spreading	Center-spreading and down-spreading
^a This is in addition to the physical link rate accuracy tolerance defined in table 64. ^b Phys compliant with SAS-1.1 that do not support being attached to SATA devices were only required to tolerate an SSC modulation type of no-spreading. Phys compliant with SAS-1.1 that support being attached to SATA devices were only required to tolerate SSC modulation types of no-spreading and SATA down-spreading. ^c If either the SSC modulation type of center-spreading or down-spreading is supported, then both shall be supported.		

5.8.6.4 Expander device center-spreading tolerance buffer

Expander devices supporting the SSC modulation type of center-spreading shall support a center-spreading tolerance buffer for each connection with the buffer size defined in table 87. The expander device uses this buffer to hold any dwords that it receives during the up-spreading portions of the SSC modulation period that expander device is unable to forward as a result of:

- a) the ECR (see SPL-5) and/or the transmitting expander phy is slower than the receiving expander phy; and
- b) the dword stream does not include enough deletable primitives (see SPL-5).

The expander device unloads the center-spreading tolerance buffer during the down-spreading portions of the SSC modulation period when the receiving expander phy is slower than the ECR and the transmitting expander phy.

Table 87 — Expander device center-spreading tolerance buffer

Physical link rate	Minimum buffer size
22.5 Gbit/s	4 SPL packets
12 Gbit/s	14 dwords
6 Gbit/s	14 dwords

NOTE 11 - The minimum buffer size is based on the number of dwords or SPL packets that are allowed to be transmitted during half of the longest allowed SSC modulation period (i.e., half of the period indicated by 30 kHz) at the maximum physical link rate (i.e., +2 400 ppm for 6 Gbit/s; +1 100 ppm for 12 Gbit/s; or +600 ppm for 22.5 Gbit/s) minus the number that are allowed to be transmitted at the minimum physical link rate (i.e., -2 400 ppm for 6 Gbit/s; -1 100 ppm for 12 Gbit/s; or -600 ppm for 22.5 Gbit/s). This accounts for forwarding dwords in a connection (see SPL-5) that originated from a phy compliant with SAS-1.1 (i.e., a phy with an SSC modulation type of no-spreading and inserting deletable primitives at a rate supporting only the frequency accuracy).

Table 88 describes the output characteristics of the READY LED signal.

Table 88 — Output characteristics of the READY LED signal

State	Test condition	Requirement
Negated (LED off)	$0\text{ V} \leq V_{OH} \leq 3.6\text{ V}$	$-100\text{ }\mu\text{A} < I_{OH} < 100\text{ }\mu\text{A}$
Asserted (LED on)	$I_{OL} = 15\text{ mA}$	$0 \leq V_{OL} \leq 0.225\text{ V}$

The READY LED signal behavior is defined in SPL-5.

NOTE 12 - SATA devices use the pin used by the READY LED signal (i.e., P11) for activity indication and disable staggered spin-up (see SATA). The output characteristics differ from those in table 88.

5.10 POWER DISABLE signal electrical characteristics

The POWER DISABLE signal, if implemented, may be used to disable power to the SAS target device circuitry.

Implementation of the POWER DISABLE signal is optional on a SAS target device with the SAS Drive plug connector (see 5.4.3.3.1.1) or the SAS MultiLink Drive plug connector (see 5.4.3.3.1.5).

If the POWER DISABLE signal is supported by a SAS target device with the SAS Drive plug connector (see 5.4.3.3.1.1) or SAS MultiLink Drive plug connector (see 5.4.3.3.1.5), then the SAS target device shall:

- a) indicate that the POWER DISABLE signal is supported on the Protocol Specific Port Information VPD page and the IDENTIFY address frame (see SPL-5);
- b) allow power to be applied to the SAS target device circuitry if the POWER DISABLE signal is not connected on the SAS Drive backplane connector (see 5.4.3.3.1.3), SAS Drive cable connector (see 5.4.3.3.1.2), SAS MultiLink Drive backplane connector (see 5.4.3.3.1.7), or SAS MultiLink Drive cable connector (see 5.4.3.3.1.6);
- c) allow power to be applied to the SAS target device circuitry if the POWER DISABLE signal is negated as defined in table 89;
- d) disable power applied to the SAS target device circuitry if:
 - 1) the minimum negated hold time in table 89 is met; and
 - 2) the POWER DISABLE signal is asserted as defined in table 89;
- e) perform the actions defined for power on (see SPL-5) if:
 - 1) the minimum negated hold time in table 89 is met;
 - 2) the POWER DISABLE signal is asserted as defined in table 89; and
 - 3) the POWER DISABLE signal transitions from asserted to negated;
 and
- f) not respond to a change of the POWER DISABLE signal from negated to asserted or asserted to negated until the POWER DISABLE signal is held at the asserted or negated level for a minimum of 1 μs .

Table 89 describes the characteristics of the POWER DISABLE signal applied to the SAS target device.

Table 89 — Characteristics of the POWER DISABLE signal applied to the SAS target device

Characteristic	Units	Minimum	Typical	Maximum
Absolute maximum input voltage range	V	-0.5		3.6
Negated voltage (power enabled) ^{a b}	V	-0.5		0.7
Asserted voltage (power disabled) ^c	V	2.1		3.6
Driver sink/source current capability ^{b c}	μA	100		
POWER DISABLE asserted hold time ^{d e}	s	5.0		
POWER DISABLE negated hold time ^{d e}	s	30.0		
<p>^a The SAS target device shall allow power to be applied to the SAS target device circuitry when P3 is not connected on the SAS Drive backplane connector (see 5.4.3.3.1.3), P3 is not connected on the SAS Drive cable connector (see 5.4.3.3.1.2), P3 is not connected on the SAS MultiLink Drive backplane connector (see 5.4.3.3.1.7), or P3 is not connected on the SAS MultiLink Drive cable connector (see 5.4.3.3.1.6).</p> <p>^b The POWER DISABLE signal should be actively negated. If the POWER DISABLE signal is not actively negated (e.g., open), then the specified values for POWER DISABLE signal negated voltage and driver sink current capability applied to the SAS target device do not apply.</p> <p>^c The POWER DISABLE signal shall be actively asserted.</p> <p>^d The hold time is the length of time the POWER DISABLE signal is asserted or negated. The length of time after the POWER DISABLE signal is asserted or negated until the disabling or allowing of power application to the SAS target device circuitry is vendor specific.</p> <p>^e The POWER DISABLE signal should not transition from negated to asserted or asserted to negated for the negated hold time:</p> <p>a) after power is applied to the SAS Drive backplane connector (see 5.4.3.3.1.3), SAS Drive cable connector (see 5.4.3.3.1.2), SAS MultiLink Drive backplane connector (see 5.4.3.3.1.7), or SAS MultiLink Drive cable connector (see 5.4.3.3.1.6); or</p> <p>b) after the detection of a hot plug event.</p>				

5.11 Out of band (OOB) signals

5.11.1 OOB signals overview

If D.C. mode is enabled, then OOB signals are low-speed signal patterns that do not appear in normal data streams. If optical mode is enabled, then OOB signals consist of a defined series of dwords. OOB signals consist of defined amounts of idle time followed by defined amounts of burst time. During the idle time, the physical link carries OOB idle. During the burst time, the physical link carries dwords. The signals are differentiated by the length of idle time between the burst times. OOB signals are not decoded unless dword synchronization has been lost (see SPL-5). Once high-speed data transfers are underway, the data pattern amplitude may fall to levels that are falsely detected as OOB signals. A phy shall either have D.C. mode enabled or optical mode enabled. The method to enable D.C. mode or optical mode is outside the scope of this standard.

SATA defines two OOB signals (i.e., COMINIT/COMRESET and COMWAKE). COMINIT and COMRESET are used in this standard interchangeably. Phys compliant with this standard identify themselves with an additional SAS specific OOB signal called COMSAS.

Table 90 defines the timing specifications for OOB signals.

Table 90 — OOB signal timing specifications

Parameter	Minimum	Nominal	Maximum	Comments
OOB Interval (OOBI) ^a	665.06 ps ^b	666.6 ps ^c	668.26 ps ^d	The time basis for burst times and idle times used to create OOB signals.
COMSAS detect timeout	13.686 μs ^e			The minimum time a receiver device shall allow to detect COMSAS after transmitting COMSAS.
^a OOBI is different than UI(OOB) defined in SATA (e.g., SAS has tighter physical link rate accuracy and different SSC frequency deviation). OOBI is based on: A) 1.5 Gbit/s UI (see table 40); B) physical link rate accuracy (see table 42); and C) center-spreading SSC (see table 83). ^b 665.06 ps equals 666.6 ps × (1 - 0.002 4). ^c 666.6 ps equals 2 000 ps / 3. ^d 668.26 ps equals 666.6 ps × 1.002 4. ^e 13.686 μs is 512 × 40 × Maximum OOBI.				

5.11.2 Transmitting OOB signals

Table 91 describes the OOB signal transmitter requirements for the burst time, idle time, negation times, and signal times that are used to form each OOB signal.

Table 91 — OOB signal transmitter device requirements

Signal	Burst time	Idle time	Negation time	Signal time ^a
COMWAKE	160 OOBi ^b	160 OOBi ^b	280 OOBi ^c	2 200 OOBi ^g
COMINIT/COMRESET	160 OOBi ^b	480 OOBi ^d	800 OOBi ^e	4 640 OOBi ⁱ
COMSAS	160 OOBi ^b	1 440 OOBi ^f	2 400 OOBi ^h	12 000 OOBi ^j
^a A signal time is six burst times plus six idle times plus one negation time. ^b 160 OOBi is nominally 106.6 ns (see table 90). ^c 280 OOBi is nominally 186.6 ns. ^d 480 OOBi is nominally 320 ns. ^e 800 OOBi is nominally 533.3 ns. ^f 1 440 OOBi is nominally 960 ns. ^g 2 200 OOBi (e.g., COMWAKE) is nominally 1 466.6 ns. ^h 2 400 OOBi is nominally 1 600 ns. ⁱ 4 640 OOBi (e.g., COMINIT/COMRESET) is nominally 3 093.3 ns. ^j 12 000 OOBi (e.g., COMSAS) is nominally 8 000 ns.				

If D.C. mode is enabled, then an OOB idle consists of the transmission of D.C. idle.

If optical mode is enabled, then an OOB idle consists of repetitions of the following steps:

- 1) transmission of six OOB_IDLE primitives with either starting disparity at 3 Gbit/s; and
- 2) transmission of up to 512 data dwords (e.g., two data dwords for COMWAKE idle time, 18 data dwords for COMINIT/COMRESET idle time, and 66 data dwords for COMSAS idle time) set to 0000_0000h that are 8b10b encoded, scrambled, and transmitted at 3 Gbit/s.

An OOB burst consists of:

- a) if D.C. mode is enabled, then transmission of a repeating 0011b pattern or 1100b pattern (e.g., D24.3) or ALIGN (0) primitives with either starting disparity. The OOB burst should consist of a repeating 0011b pattern or 1100b pattern (e.g., D24.3) at 1.5 Gbit/s; or
- b) if optical mode is enabled, then transmission of ALIGN (3) primitives with either starting disparity at 3 Gbit/s.

To transmit an OOB signal, the transmitter device shall:

- 1) transmit OOB idle for an idle time;
- 2) transmit an OOB burst for a burst time; and
- 3) repeat steps 1) and 2) five additional times.

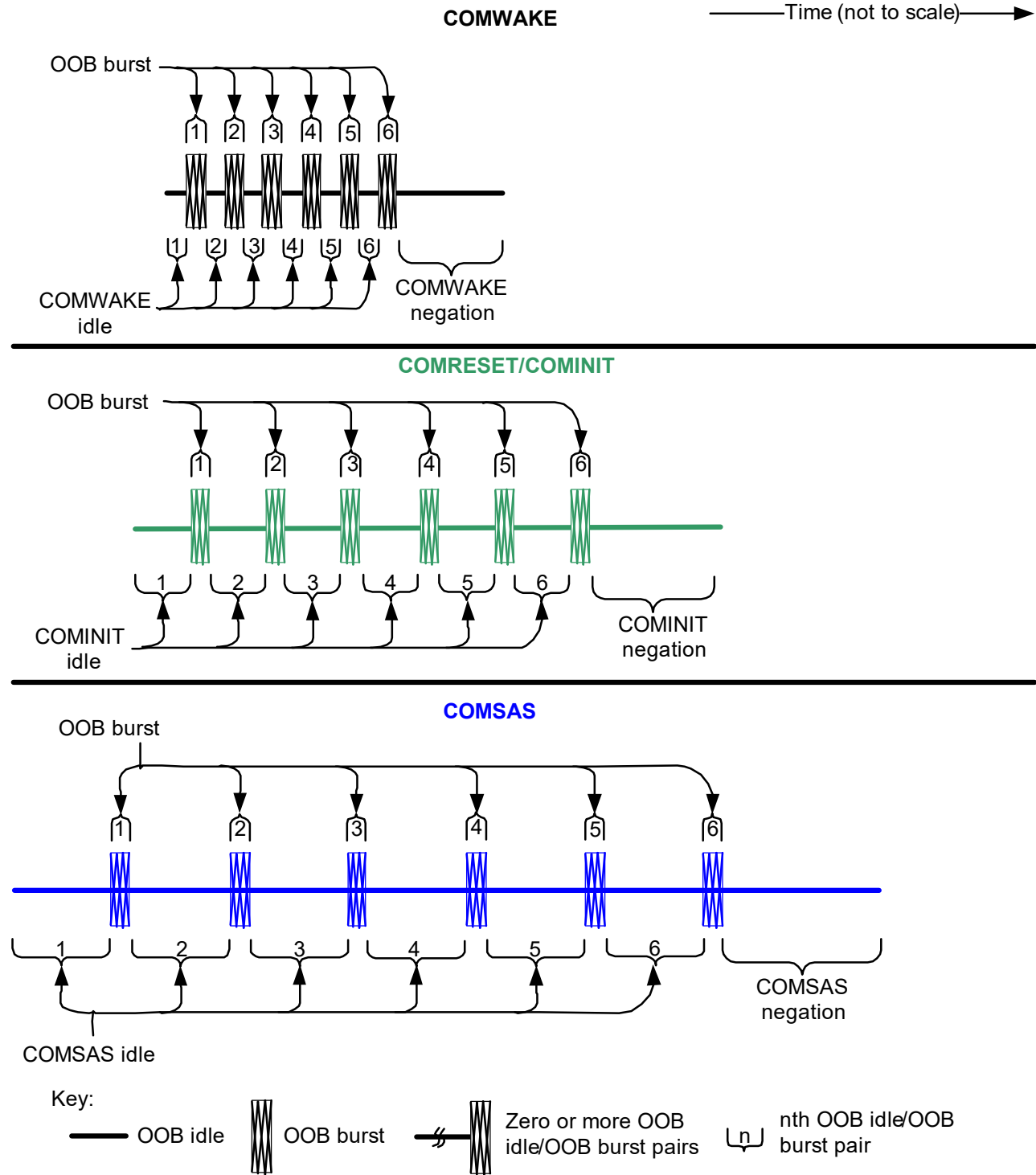
The transmitter device shall then transmit OOB idle for an OOB signal negation time.

The transmitter device shall use signal output levels during burst time and idle time as described in 5.8.4.8.

If D.C. mode is enabled, then the repeating 0011b pattern or 1100b pattern (e.g., D24.3) or ALIGN (0) primitives (see SPL-5) used in OOB signals shall be transmitted and the OOB burst is only required to generate an envelope for the detection circuitry, as required for any signaling that may be A.C. coupled. A burst of a repeating 0011b pattern or 1100b pattern (e.g., D24.3) at 1.5 Gbit/s is equivalent to a square wave pattern that has a one for two OOBi and a zero for two OOBi. A transmitter may use this square wave pattern for the OOB burst. The start of the pattern may be one or zero. The signal rise and fall times:

- a) shall be greater than (i.e., slower) or equal to the minimum (i.e., fastest) rise and fall times allowed by the fastest supported physical link rate of the transmitter device (see table 44); and
- b) shall be less than (i.e., faster) or equal to the maximum (i.e., slowest) rise and fall times allowed at 1.5 Gbit/s.

Figure 152 describes OOB signal transmission.



Note: OOB idle is shown here as a neutral signal for visual clarity only

Figure 152 — OOB signal transmission

5.11.3 Receiving OOB signals

Table 92 describes the OOB signal receiver device requirements for detecting burst times, assuming T_{burst} is the length of the detected burst time. The burst time is not used to distinguish between signals.

Table 92 — OOB signal receiver device burst time detection requirements

Signal ^a	may detect	shall detect
COMWAKE	$T_{burst} \leq 100 \text{ ns}$ or $T_{burst} > 112 \text{ ns}$	$100 \text{ ns} < T_{burst} \leq 112 \text{ ns}$
COMINIT/COMRESET	$T_{burst} \leq 100 \text{ ns}$ or $T_{burst} > 112 \text{ ns}$	$100 \text{ ns} < T_{burst} \leq 112 \text{ ns}$
COMSAS	$T_{burst} \leq 100 \text{ ns}$ or $T_{burst} > 112 \text{ ns}$	$100 \text{ ns} < T_{burst} \leq 112 \text{ ns}$
^a Each burst time is transmitted as 160 OOB, which is nominally 106.6 ns (see table 91).		

Table 93 describes the OOB signal receiver device requirements for detecting idle times, assuming T_{idle} is the length of the detected idle time.

Table 93 — OOB signal receiver device idle time detection requirements

Signal	may detect	shall detect	shall not detect
COMWAKE ^a	$35 \text{ ns} \leq T_{idle} < 175 \text{ ns}$	$101.3 \text{ ns} \leq T_{idle} \leq 112 \text{ ns}$	$T_{idle} < 35 \text{ ns}$ or $T_{idle} \geq 175 \text{ ns}$
COMINIT/COMRESET ^b	$175 \text{ ns} \leq T_{idle} < 525 \text{ ns}$	$304 \text{ ns} \leq T_{idle} \leq 336 \text{ ns}$	$T_{idle} < 175 \text{ ns}$ or $T_{idle} \geq 525 \text{ ns}$
COMSAS ^c	$525 \text{ ns} \leq T_{idle} < 1\,575 \text{ ns}$	$911.7 \text{ ns} \leq T_{idle} \leq 1\,008 \text{ ns}$	$T_{idle} < 525 \text{ ns}$ or $T_{idle} \geq 1\,575 \text{ ns}$
^a COMWAKE idle time is transmitted as 160 OOB, which is nominally 106.6 ns (see table 91). ^b COMINIT/COMRESET idle time is transmitted as 480 OOB, which is nominally 320 ns. ^c COMSAS idle time is transmitted as 1 440 OOB, which is nominally 960 ns.			

Table 94 describes the OOB signal receiver device requirements for detecting negation times, assuming T_{idle} is the length of the detected idle time.

Table 94 — OOB signal receiver device negation time detection requirements

Signal	shall detect
COMWAKE ^a	$T_{idle} > 175 \text{ ns}$
COMINIT/COMRESET ^b	$T_{idle} > 525 \text{ ns}$
COMSAS ^c	$T_{idle} > 1\,575 \text{ ns}$
^a COMWAKE negation time is transmitted as 280 OOB, which is nominally 186.6 ns (see table 91). ^b COMINIT/COMRESET negation time is transmitted as 800 OOB, which is nominally 533.3 ns. ^c COMSAS negation time, which is transmitted as 2 400 OOB, which is nominally 1 600 ns.	

If D.C. mode is enabled, then a SAS receiver device shall detect OOB bursts formed from any of the following:

- a) D24.3 characters (see SPL-5) at 1.5 Gbit/s;
- b) ALIGN (0) primitives (see SPL-5) at 1.5 Gbit/s; or
- c) ALIGN (0) primitives at 3 Gbit/s.

If D.C. mode is enabled, then a SAS receiver device shall not qualify the OOB burst based on the characters received.

If optical mode is enabled, then a SAS receiver device shall detect OOB bursts formed from ALIGN (3) primitives at 3 Gbit/s.

5.11.4 Transmitting the SATA port selection signal

The SATA port selection signal shown in figure 153 causes the attached SATA port selector (see SPL-5) to select the attached phy (i.e., one of the SATA port selector's host phys) as the active phy (see SATA).

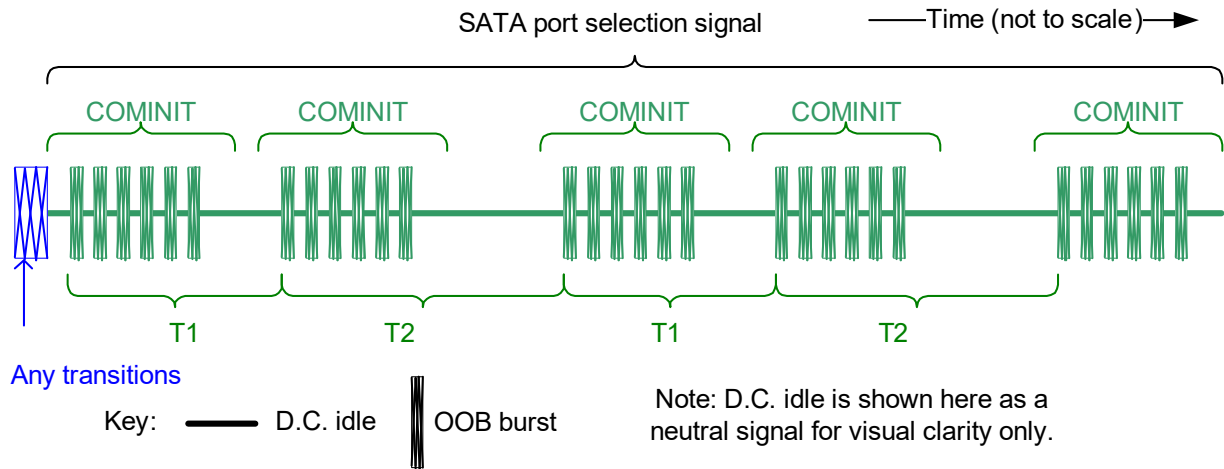


Figure 153 — SATA port selection signal

The SATA port selection signal shall be composed of five COMINIT signals, each starting a specified time interval, T1 or T2, as shown in figure 153, after the start of the OOB burst portion of the previous COMINIT signal. The values of T1 and T2 shall be as shown in table 95.

Table 95 — SATA port selection signal transmitter device requirements

Parameter	Time
T1	3×10^6 OOB ^a
T2	12×10^6 OOB ^b
^a 3×10^6 OOB is nominally 2 ms (see table 90). ^b 12×10^6 OOB is nominally 8 ms.	

See SPL-5 for information on usage of the SATA port selection signal.

Annex A

(Normative)

Jitter tolerance pattern (JTPAT)

The jitter tolerance pattern (JTPAT) consists of:

- 1) a long run of low transition density pattern;
- 2) a long run of high transition density pattern; and
- 3) another short run of low transition density pattern.

The transitions between the pattern segments stress the receiver. The JTPAT is designed to contain the phase shift in both polarities, from zero to one and from one to zero. The critical pattern sections with the phase shifts are underlined in table A.1 and table A.2.

Table A.1 shows the JTPAT when there is positive running disparity (RD+) (see SPL-5) at the beginning of the pattern. The 8b and 10b values of each character (see SPL-5) are shown.

Table A.1 — JTPAT for RD+

Dword(s)	Beginning RD	First character	Second character	Third character	Fourth character	Ending RD
0 to 40	RD+	D30.3 (7Eh)	D30.3 (7Eh)	D30.3 (7Eh)	D30.3 (7Eh)	RD+
		10 0001 1100b	01 1110 0011b	10 0001 1100b	01 1110 0011b	
	The above dword of low transition density pattern is sent a total of forty-one times					
41	RD+	D30.3 (7Eh)	D30.3 (7Eh)	D30.3 (7Eh)	D20.3 (74h)	RD-
		10 0001 1100b	01 1110 0011b	10 0001 1100b	00 1011 1100b	
	The above dword containing phase shift 111 0000 1011b is sent one time					
42	RD-	D30.3 (7Eh)	D11.5 (ABh)	D21.5 (B5h)	D21.5 (B5h)	RD+
		01 1110 0011b	11 0100 1010b	10 1010 1010b	10 1010 1010b	
	The above dword containing phase shift 000 1111 0100b is sent one time					
43 to 54	RD+	D21.5 (B5h)	D21.5 (B5h)	D21.5 (B5h)	D21.5 (B5h)	RD+
		10 1010 1010b	10 1010 1010b	10 1010 1010b	10 1010 1010b	
	The above dword of high transition density pattern is sent a total of twelve times					
55	RD+	D21.5 (B5h)	D30.2 (5Eh)	D10.2 (4Ah)	D30.3 (7Eh)	RD+
		10 1010 1010b	10 0001 0101b	01 0101 0101b	01 1110 0011b	
	The above dword containing phase shift 0101 0000b and 1010 1111b is sent one time					

If the same 8b characters specified in table A.1 are used when there is negative running disparity (RD-) at the beginning of the pattern, then the resulting 10b pattern is different than the positive running disparity for the same 8b character and does not provide the critical phase shifts. To achieve the same phase shift effects with RD-, a different 8b pattern is required. Table A.2 shows the JTPAT when there is negative running disparity (RD-) at the beginning of the pattern. The 8b and 10b values of each character are shown.

Table A.2 — JTPAT for RD-

Dword(s)	Beginning RD	First character	Second character	Third character	Fourth character	Ending RD
0 to 40	RD-	D30.3 (7Eh)	D30.3 (7Eh)	D30.3 (7Eh)	D30.3 (7Eh)	RD-
		01 1110 0011b	10 0001 1100b	01 1110 0011b	10 0001 1100b	
	The above dword of low transition density pattern is sent a total of forty-one times					
41	RD-	D30.3 (7Eh)	D30.3 (7Eh)	D30.3 (7Eh)	D11.3 (6Bh)	RD+
		01 1110 0011b	10 0001 1100b	01 1110 0011b	11 0100 0011b	
	The above dword containing phase shift 000 1111 0100b is sent one time					
42	RD+	D30.3 (7Eh)	D20.2 (54h)	D10.2 (4Ah)	D10.2 (4Ah)	RD-
		10 0001 1100b	00 1011 0101b	01 0101 0101b	01 0101 0101b	
	The above dword containing phase shift 111 0000 1011b is sent one time					
43 to 54	RD-	D10.2 (4Ah)	D10.2 (4Ah)	D10.2 (4Ah)	D10.2 (4Ah)	RD-
		01 0101 0101b	01 0101 0101b	01 0101 0101b	01 0101 0101b	
	The above dword of high transition density pattern is sent a total of twelve times					
55	RD-	D10.2 (4Ah)	D30.5 (BEh)	D21.5 (B5h)	D30.3 (7Eh)	RD-
		01 0101 0101b	01 1110 1010b	10 1010 1010b	10 0001 1100b	
	The above dword containing phase shift 10101111b and 01010000b is sent one time					

The compliant jitter tolerance pattern (CJTPAT) is the JTPAT for RD+ (see table A.1) and RD- (see table A.2) included as the payload in an SSP DATA frame or an SMP frame. A phy or test equipment transmitting CJTPAT outside connections may transmit it with fixed content. See SPL-5.

Annex B

(Normative)

SASWDP

SASWDP is a MATLAB program used for transmitter device compliance for trained 6 Gbit/s (see 5.8.4.5.1) and for receiver device compliance for trained 6 Gbit/s (see 5.8.5.7.6). Several files including SASWDP.m and SASWDP_testcase.m are included in the SAS2_1 directory of SAS-4_1.zip. SASWDP.m includes comments within the file explaining input requirements and outputs of the script. Equivalent simulation programs may be used if they lead to the same results.

Annex C

(Normative)

End to end simulation for trained 12 Gbit/s

C.1 Detailed end to end simulation procedure description for trained 12 Gbit/s

The trained 12 Gbit/s simulation model is based on a die to die insertion loss of approximately 24 dB as shown in figure C.1.

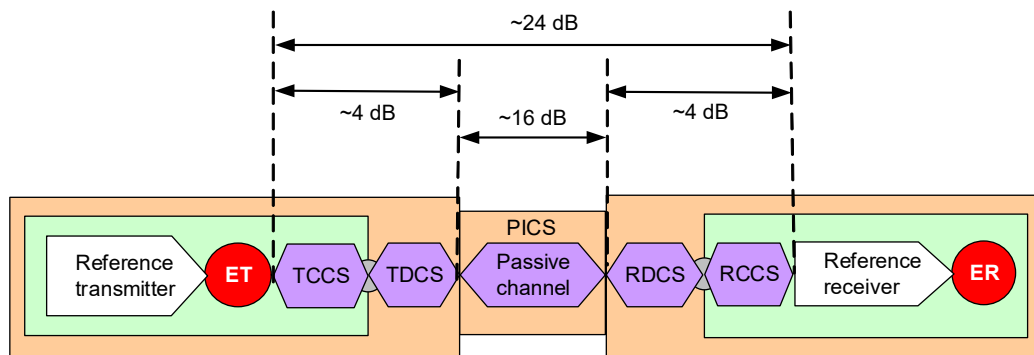


Figure C.1 — Trained 12 Gbit/s die to die insertion loss model

The following procedure describes the end to end simulation process:

- 1) extract the unequalized pulse response between ET (see 5.3.3) and RR (see 5.5.6) from:
 - a) the captured signal into a zero-length test load or measured transfer function; and
 - b) the reference transfer functions of the appropriate end to end simulation diagram (see C.2);
- 2) compute the reference transmitter equalization (see 5.7.3);
- 3) compute reference receiver DFE equalization (see 5.8.5.7.3);
- 4) compute an equalized pulse response by applying the reference transmitter equalization and the reference receiver DFE equalization to the unequalized pulse response between ET and RR;
- 5) compute the vertical eye opening at the sampling instants defined by a reference sampling clock (see figure 115), for a BER of 10^{-15} assuming 8b10b data, using the equalized pulse response and the asynchronous crosstalk from all significant crosstalk sources;
- 6) measure the peak to peak reference pulse response cursor from the equalized pulse response (see figure 115); and
- 7) compute the vertical eye opening to reference pulse response cursor ratio.

Crosstalk information is provided as:

- a) crosstalk transfer functions; or
- b) a crosstalk signal amplitude that is met or exceeded at a cumulative probability of 10^{-6} (see 5.7.2).

When crosstalk information is provided as crosstalk transfer functions, the vertical eye opening is simulated at a BER of 10^{-15} , using the following procedure:

- 1) connect asynchronous reference transmitters to generate crosstalk according to the appropriate end to end simulation diagram (see C.2);
- 2) set the characteristics of the crosstalk transmitters per table C.1;
- 3) simulate the resulting amplitude due to crosstalk; and
- 4) compute the vertical eye opening at a BER of 10^{-15} .

Table C.1 — Crosstalk transmitter characteristics

Characteristic	Units	Value
Minimum peak to peak voltage (V_{P-P})	mV(P-P)	850 ^a
Output gain (K_0)	V/V	0.425 ^a
Rise/fall time ^b	ps	25 ^a
Differential impedance (nominal)	Ω	100
Common mode impedance (nominal)	Ω	25
Coefficient 1	V/V	See ^a
Coefficient 2	V/V	See ^a
Coefficient 3	V/V	See ^a
^a Peak to peak voltage, rise/fall time, and coefficients should match the characteristics of the transmitter device used for the TxRx connection segment under test after reference transmitter equalization (see 5.7.3). ^b Rise/fall times are measured from 20 % to 80 % of the transition with a repeating 01b pattern or 10b pattern (e.g., D10.2 or D21.5) (see the phy test patterns in the Protocol Specific diagnostic page in SPL-5).		

If crosstalk information is provided as a signal amplitude at a cumulative probability of 10^{-6} , then the vertical eye opening is computed by summing:

- a) the simulated ISI not equalized by the transmitter equalization and receiver DFE equalization, at a BER of 10^{-15} assuming 8b10b data; and
- b) the total crosstalk at a cumulative probability of 10^{-6} , scaled by the maximum gain of the TxRx connection segment between the crosstalk measurement point and the reference receiver input.

The maximum gain of the TxRx connection segment between the crosstalk measurement point and the reference receiver input is computed by simulation using the following procedure:

- 1) connect a reference transmitter to the TxRx connection segment between the crosstalk measurement point and the reference receiver input;
- 2) terminate the TxRx connection segment on the receiver end;
- 3) set the reference transmitter coefficient 1 to zero, coefficient 2 to one, coefficient 3 to zero and K_0 (see 5.8.4.6.4) to 0.5; and
- 4) compute the maximum gain as the maximum peak to peak voltage at the output of the TxRx connection segment, assuming 8b10b data.

C.2 Trained 12 Gbit/s usage models, S-parameter files, and crosstalk amplitude

C.2.1 Transmitter device connected to a separable passive TxRx connection segment

Table C.2 defines the S-parameter files for a transmitter device connected to a separable passive TxRx connection.

Table C.2 — S-parameter files for transmitter devices connected to a separable TxRx connection segment

End to end simulation type	S-parameter files ^{a b c}	Description of S-parameter files	Measurement point
Transmitter device connected to a separable TxRx connection segment (from SAS target device)	LongPassiveD2H_ITs_IR.s4p	TxRx connection channel	IT, IT _S , CT, or CT _S
	LongPassiveD2H_CR_RR.s4p	Rx initiator/expander device channel	
	LongPassiveD2H_ET_ITs_rev.s4p	Rx initiator/expander device NEXT Tx channel	
	LongPassiveD2H_ITs_IR_NEXTx.s4p	TxRx connection NEXT channels	
	LongPassiveD2H_ITs_IR_FEXTx.s4p	TxRx connection FEXT channels	
Transmitter device connected to a separable TxRx connection segment (to SAS target device)	LongPassiveD2H_CR_RR_NEXTx.s4p	Rx initiator/expander device NEXT channels	IT, IT _S , CT, or CT _S
	LongPassiveD2H_CR_RR_FEXTx.s4p	Rx initiator/expander device FEXT channels	
	LongPassiveH2D_ITs_IR.s4p	TxRx connection channel	
	LongPassiveH2D_CR_RR.s4p	Rx target device channel	
	LongPassiveH2D_ET_ITs_rev.s4p	Rx target device NEXT Tx channel	
	LongPassiveH2D_ITs_IR_NEXTx.s4p	TxRx connection NEXT channels	IT, IT _S , CT, or CT _S
	LongPassiveH2D_ITs_IR_FEXTx.s4p	TxRx connection FEXT channels	
	LongPassiveH2D_CR_RR_NEXTx.s4p	Rx target device NEXT channels	
	LongPassiveH2D_CR_RR_FEXTx.s4p	Rx target device FEXT channels	
^a NEXTx and FEXTx indicate multiple aggressor channels.			
^b See figure 114 for a description of the NEXT and FEXT extraction.			
^c The <usage>_ET_ITs_rev.s4p transfer function may be calculated by de-embedding (see G.6).			

Figure C.2 shows the usage models for a transmitter device connected to a separable passive TxRx connection.

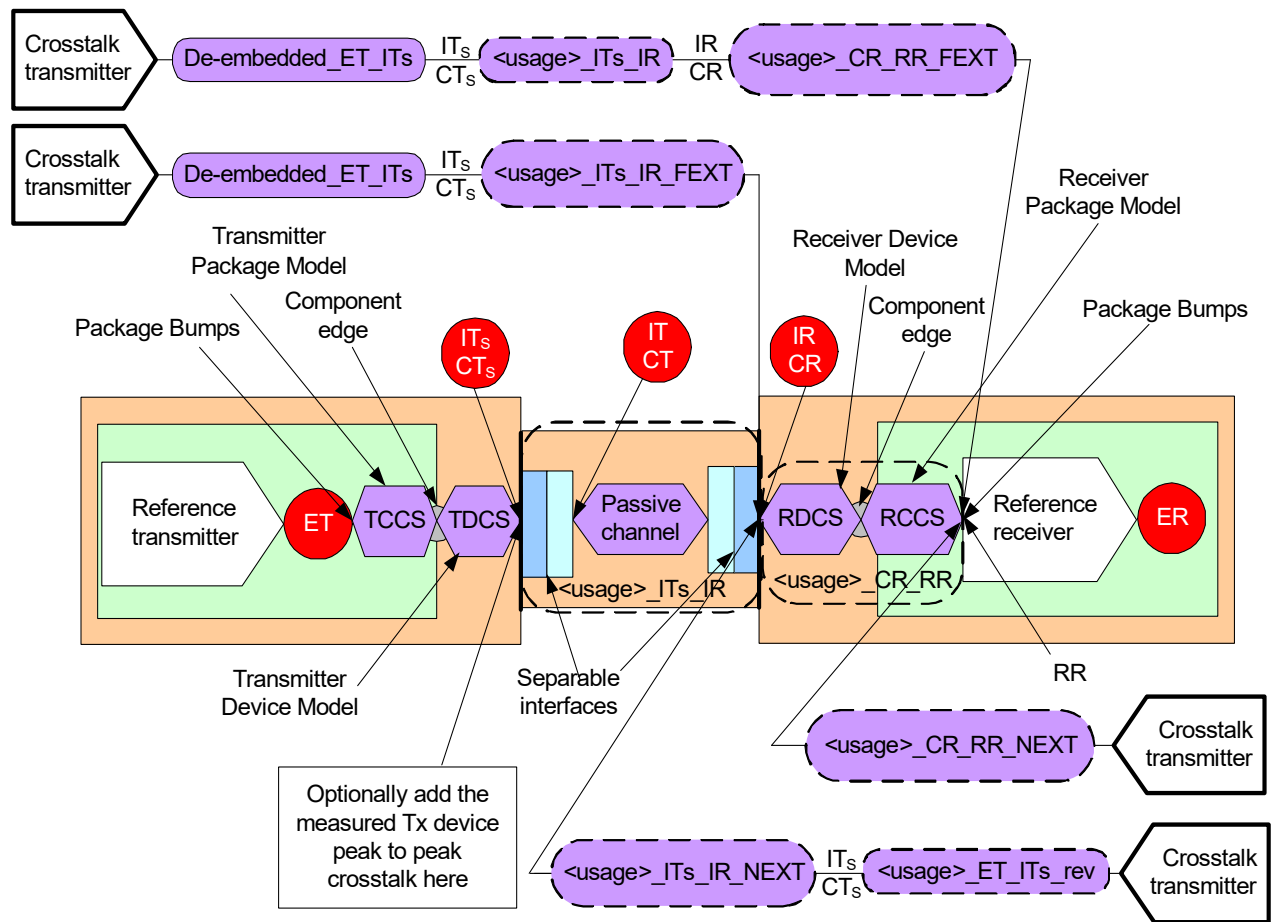


Figure C.2 — Transmitter device end to end simulation diagram that includes a separable TxRx connection segment

C.2.2 Transmitter device connected to a non-separable passive TxRx connection segment

Table C.3 defines the S-parameter files for a transmitter device connected to a non-separable passive TxRx connection.

Table C.3 — S-parameter files for transmitter devices connected to a non-separable TxRx connection segment

End to end simulation type	S-parameter files ^{a b c}	Description of S-parameter files	Measurement point
Transmitter device connected to a non-separable TxRx connection segment (from SAS target device) ^d	LongPassiveD2H_IR_RR.s4p	Rx initiator/expander device channel	IT, IT _S , CT, or CT _S
	LongPassiveD2H_IR_RR_NEXTx.s4p	Rx initiator/expander device NEXT channels	
	LongPassiveD2H_IR_RR_FEXTx.s4p	Rx initiator/expander device FEXT channels	
Transmitter device connected to a non-separable TxRx connection segment (to SAS target device) ^e	LongPassiveH2D_CR_RR.s4p	Rx target device channel	IT, IT _S , CT, or CT _S
	LongPassiveH2D_CR_RR_NEXTx.s4p LongPassiveH2D_CR_RR_FEXTx.s4p	Rx target device NEXT channels Rx target device FEXT channels	

^a NEXTx and FEXTx indicate multiple aggressor channels.

^b See figure 114 for a description of the NEXT and FEXT extraction.

^c The <usage>_ET_ITs_rev.s4p transfer function may be calculated by de-embedding (see G.6).

^d See figure C.3.

^e See figure C.4.

Figure C.3 shows the target device to initiator device and target device to expander device usage models (i.e., from target device usage model) for a transmitter device connected to a non-separable passive TxRx connection.

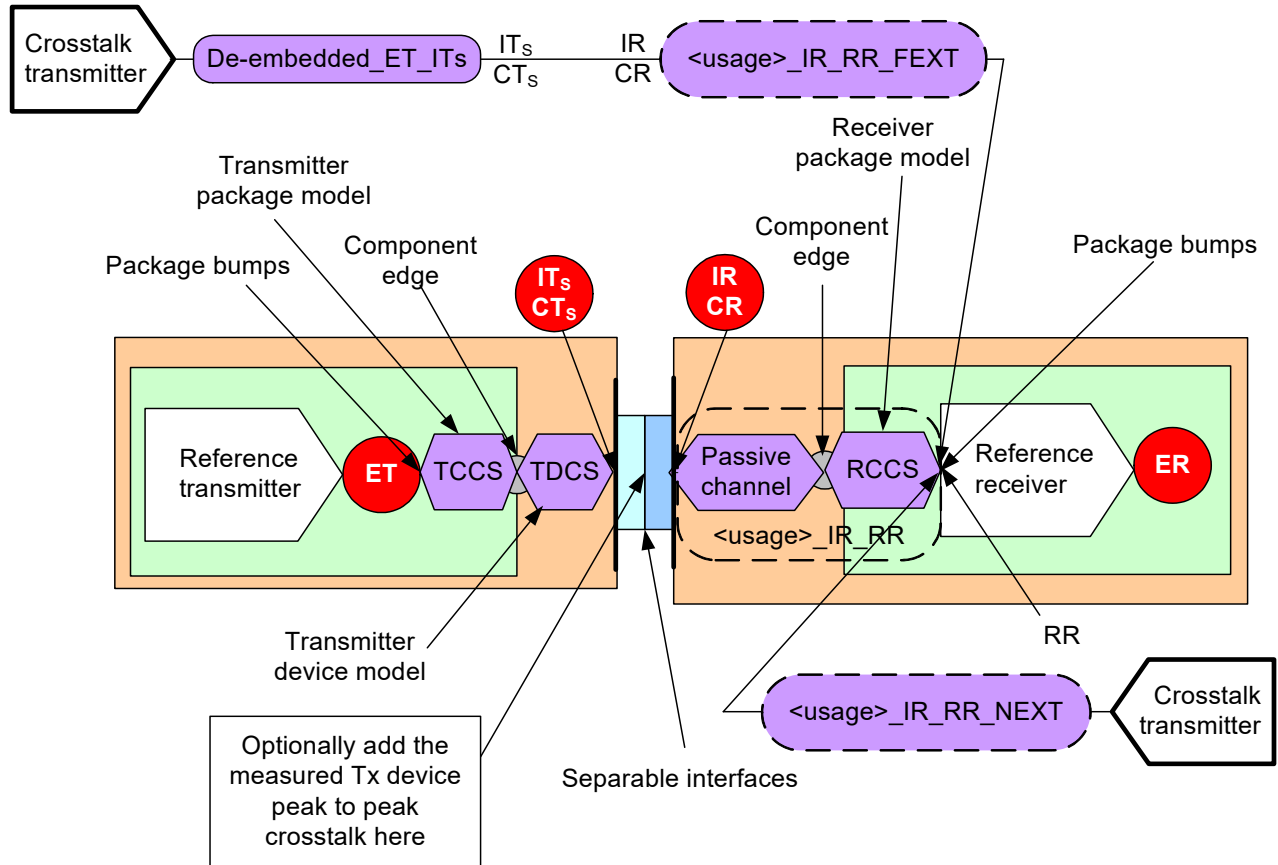


Figure C.3 — End to end simulation diagram of the from target device usage model for a transmitter device connected to a non-separable TxRx connection segment

Figure C.4 shows the initiator device to target device and expander device to target device usage models (i.e., to target device usage model) for a transmitter device connected to a non-separable passive TxRx connection.

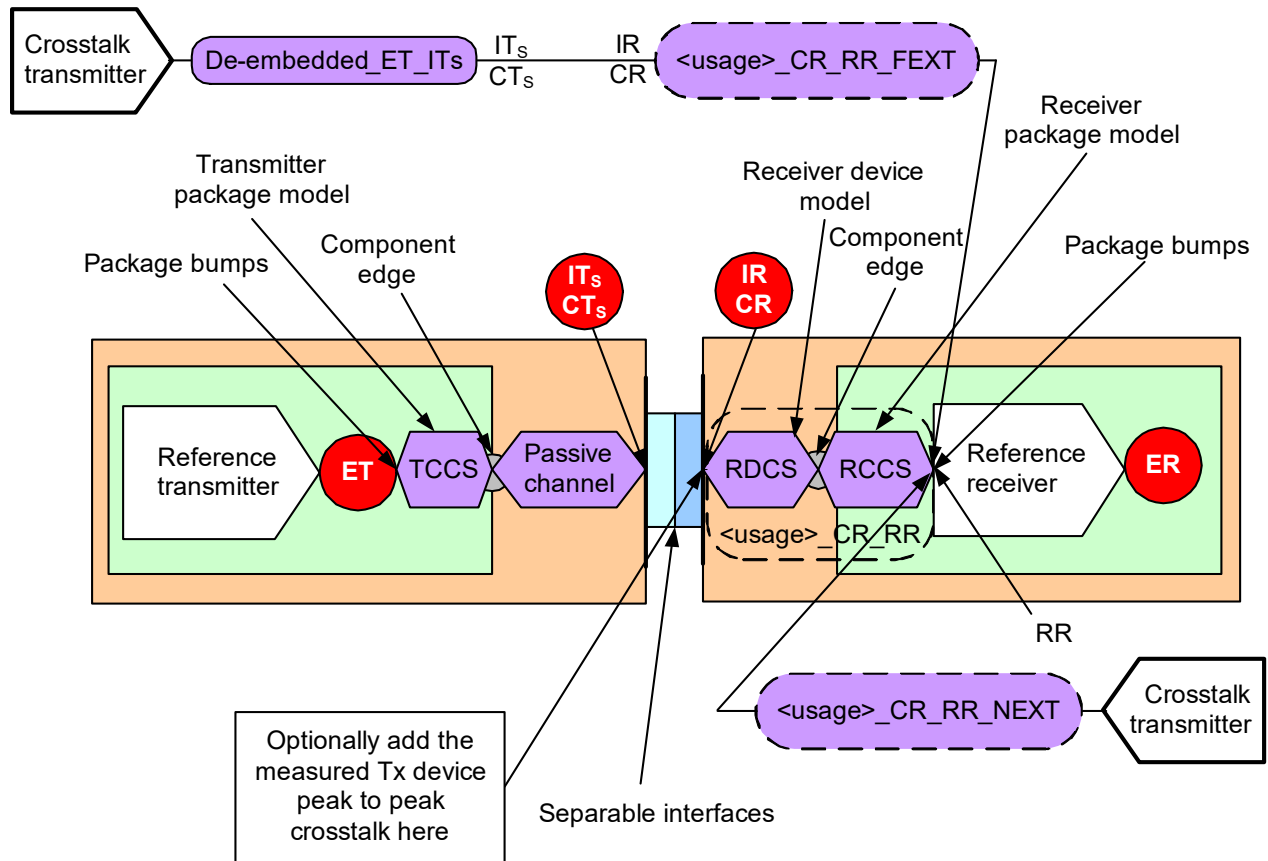


Figure C.4 — End to end simulation diagram of the to target device usage model for a transmitter device connected to a non-separable TxRx connection segment

C.2.3 TxRx connection segment

Table C.4 defines the S-parameter files to verify compliance of a TxRx connection segment.

Table C.4 — S-parameter files for a TxRx connection segment

End to end simulation type ^a	S-parameter files ^{a b c}	Description of S-parameter files
TxRx connection segment (SAS target device to SAS initiator device or SAS target device to SAS expander device)	LongPassiveD2H_ET_ITs.s4p LongPassiveD2H_CR_RR.s4p	Tx target device channel Rx initiator/expander device channel
	LongPassiveD2H_ET_ITs_NEXTx.s4p LongPassiveD2H_ET_ITs_FEXTx.s4p LongPassiveD2H_CR_RR_NEXTx.s4p LongPassiveD2H_CR_RR_FEXTx.s4p LongPassiveD2H_ET_ITs_rev.s4p	Tx target device NEXT channels Tx target device FEXT channels Rx initiator/expander device NEXT channels Rx initiator/expander device FEXT channels Rx initiator/expander device NEXT Tx channel
TxRx connection segment (SAS initiator device to SAS target device or SAS expander device to SAS target device)	LongPassiveH2D_ET_ITs_rev.s4p LongPassiveH2D_CR_RR.s4p	Tx initiator/expander device channel Rx target device channel
	LongPassiveH2D_ET_ITs_NEXTx.s4p LongPassiveH2D_ET_ITs_FEXTx.s4p LongPassiveH2D_CR_RR_NEXTx.s4p LongPassiveH2D_CR_RR_FEXTx.s4p LongPassiveH2D_ET_ITs_rev.s4p	Tx initiator/expander device NEXT channels Tx initiator/expander device FEXT channels Rx target device NEXT channels Rx target device FEXT channels Rx target device NEXT Tx channel
^a If multiple through files are provided, then the first one used shall be before the PICS under test (i.e., between ET and the first measurement point), and the second one used shall be after the PICS under test (i.e., between the second measurement point and RR) (see 5.5.6). ^b NEXTx and FEXTx indicate multiple aggressor channels. ^c See figure 114 for a description of the NEXT and FEXT extraction.		

Figure 92 shows the end to end simulation diagram for passive TxRx connection segments between IT_S and IR or between CT_S and CR for trained 12 Gbit/s.

C.2.4 Stressed receiver device delivered signal calibration end to end simulation diagram

Figure C.5 shows the end to end simulation diagram for the stressed receiver device delivered signal calibration for trained 12 Gbit/s (see 5.8.5.7.6.6). For calibration, noise sources (i.e., DJ, RJ, SJ, and SSC) shall not be activated.

The crosstalk from the crosstalk transmitter represents FEXT and should be applied closer to ET than to IR or CR to optimize the amplitude distribution. Equivalent configurations are allowed.

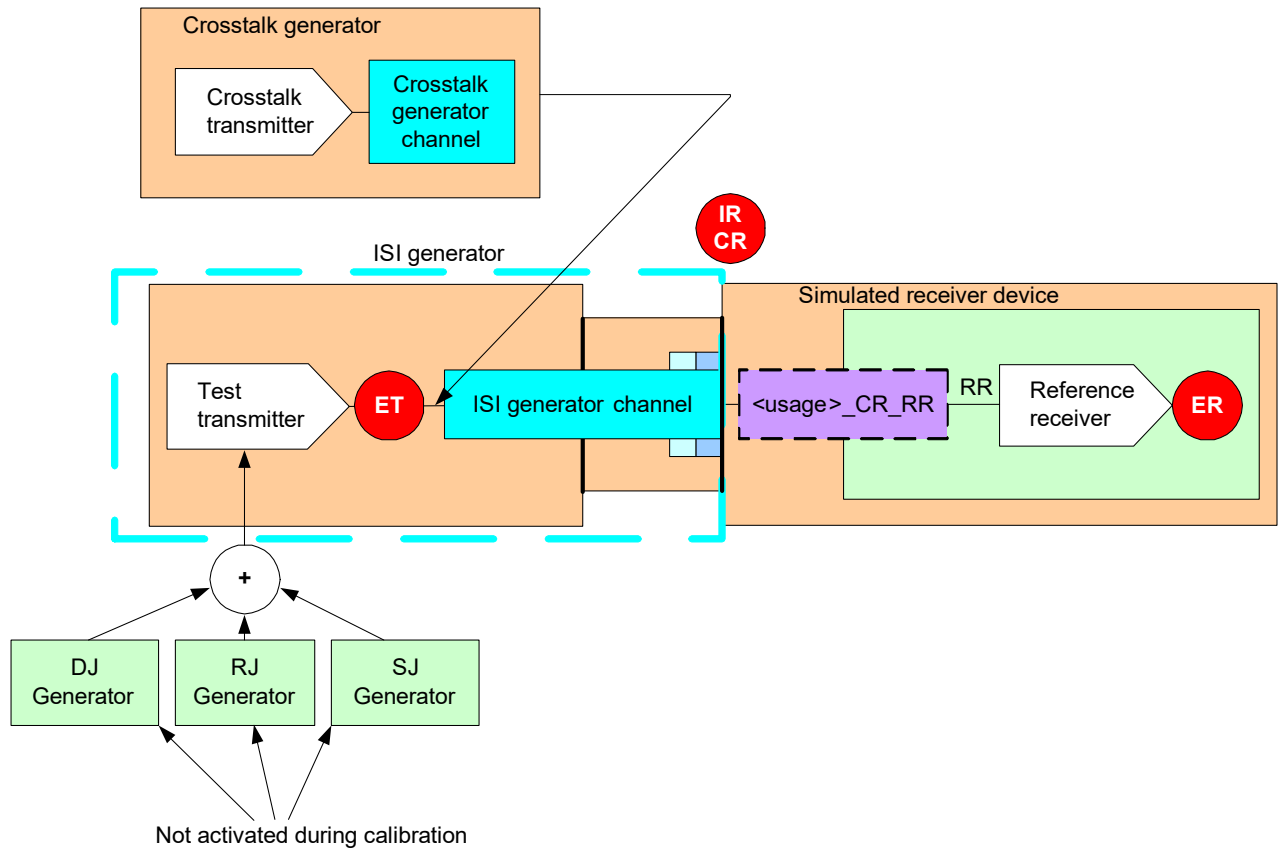


Figure C.5 — Stressed receiver device delivered signal calibration end to end simulation diagram

Table C.5 defines the S-parameter files for stressed receiver device delivered signal calibration.

Table C.5 — S-parameter files for stressed receiver device delivered signal calibration

End to end simulation type	S-parameter files	Description of S-parameter files	Measurement point	Crosstalk amplitude ^a	
				Minimum	Maximum
Stressed receiver device (SAS target device to SAS initiator device or SAS target device to SAS expander device)	LongPassiveD2H_CR_RR.s4p	Rx initiator/expander device channel	IR or CR	15 mV _{P-P}	20 mV _{P-P}
Stressed receiver device (SAS initiator device to SAS target device or SAS expander device to SAS target device)	LongPassiveH2D_CR_RR.s4p	Rx target device channel	IR or CR	10 mV _{P-P}	15 mV _{P-P}
^a The peak to peak amplitude of the crosstalk that is met or exceeded with a cumulative probability of 10 ⁻⁶ (see 5.8.4).					

Annex D

(Informative)

StatEye

StatEye is a Python program that may be used for simulating TxRx connection compliance for trained 6 Gbit/s (see 5.5.5). Equivalent simulation programs may be used if they lead to the same results.

The SAS_1.zip file includes a directory named SAS2_1. The files in the SAS2_1 directory of SAS-4_1.zip may be used to run StatEye on the SAS-2 reference channel with the appropriate reference transmitter and receiver settings. Python files included in the SAS2_1 directory of SAS-4_1.zip and their function are listed in table D.1.

Table D.1 — Python files included in the SAS2_1 directory of SAS-4_1.zip

File name	Function
analysis.py	This file loads pattern measurement files, and is not used for TxRx connection compliance simulations.
cdr.py	This file extracts the clock from a pattern measurement and is not used for TxRx connection compliance simulations.
extractJitter.py	This file extracts jitter from a pattern measurement and is not used for TxRx connection compliance simulations.
penrose.py	This file extracts the step response from a pattern measurement and is not used for TxRx connection compliance simulations.
portalocker.py	This file locks files for exclusive access. (See the ActiveState Code web site at https://code.activestate.com/recipes/65203/ for information about the portalocker code recipe.)
stateye.py	This file computes the statistical eye.
testcase.py	This file runs a single StatEye simulation.
testall.py	This file runs a set of StatEye simulations.

A file named Stateye_readme.pdf is included in the SAS2_1 directory of SAS-4_1.zip to aid the user in setting up and verifying the installation of StatEye.

NOTE 13 - See <https://web.archive.org/web/20190926033423/http://www.stateye.org/> for more information on StatEye.

Annex E

(Informative)

12 Gbit/s S-parameters and end to end simulation

E.1 S-parameters for 12 Gbit/s simulation

E.1.1 Measurement procedure

Figure E.1 shows the connections that are made to a four port VNA to measure S-parameters. The following procedure describes the recommended measurement method:

- 1) connect the through channel as shown in figure E.1;
- 2) measure the S-parameters between 50 MHz to 20 GHz with a maximum step size of 10 MHz;
- 3) repeat step 2) for NEXT of the link under test; and
- 4) repeat step 2) for NEXT and FEXT of each aggressor link.

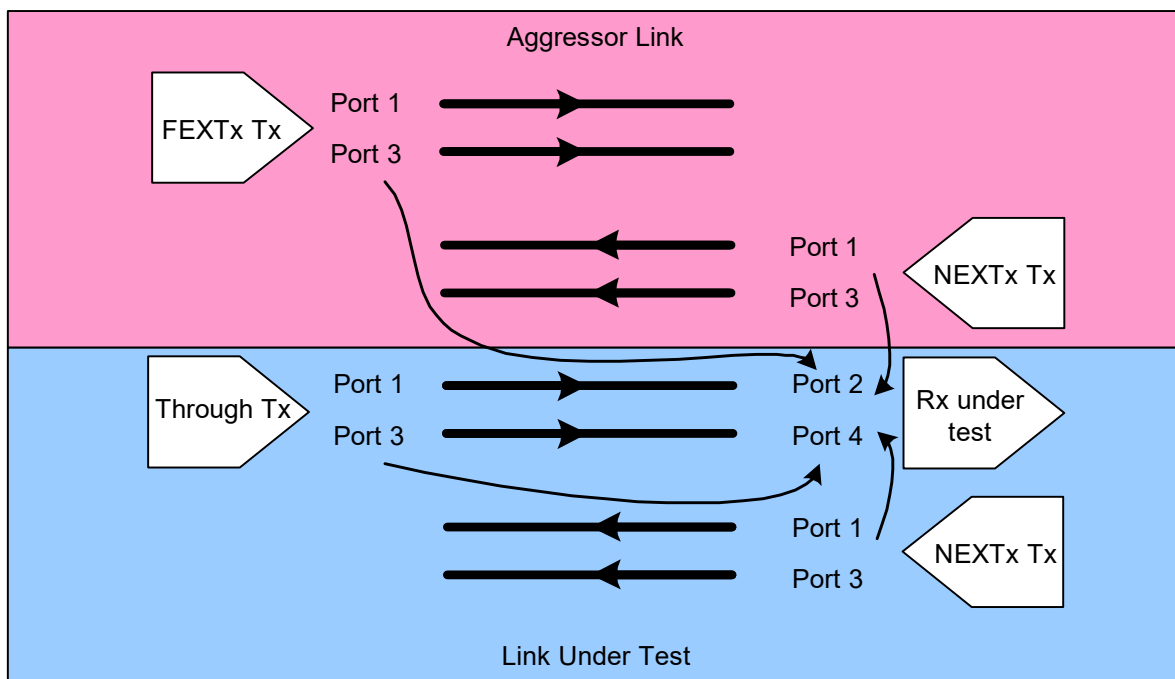


Figure E.1 — S-parameter measurement connections for a four port VNA

E.1.2 Multiple channel segments

If the channel consists of multiple segments, then the complete through channel and crosstalk channels are not directly measurable. One method of computing a channel consisting of multiple measured segments is by cascading the S-parameters in order.

For example a three TxRx connection segment SAS environment is shown in figure E.2.

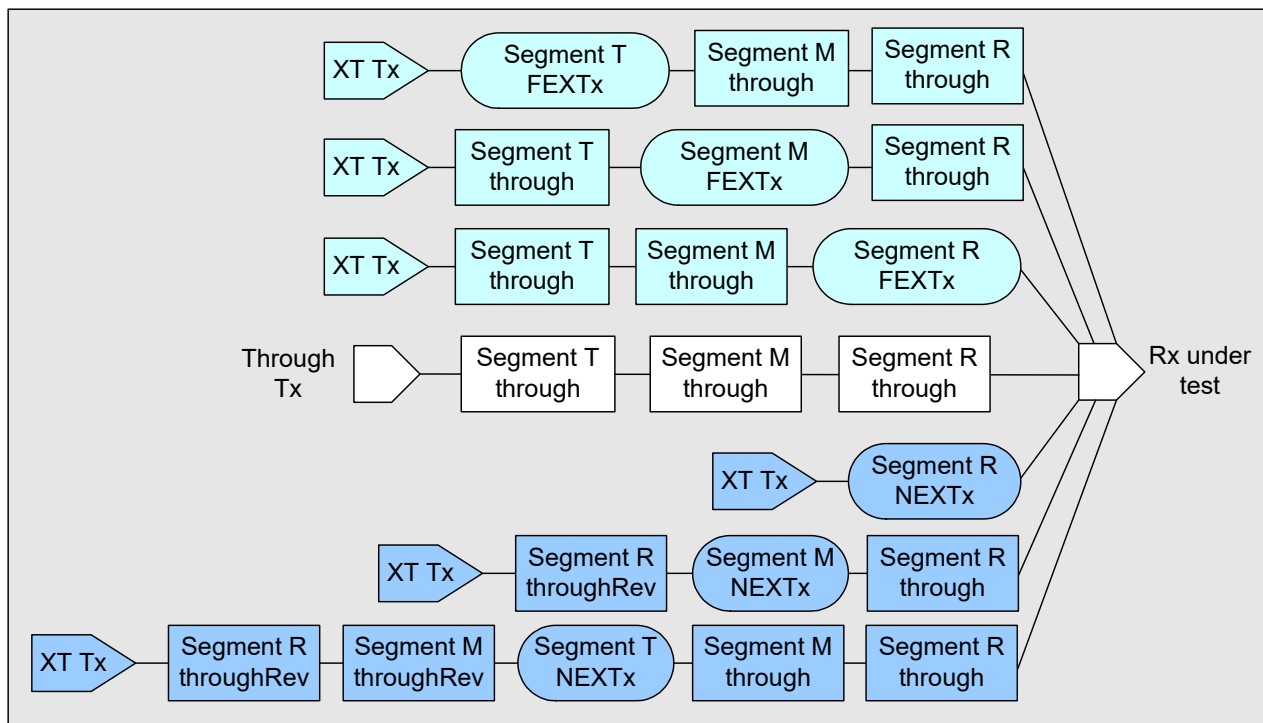
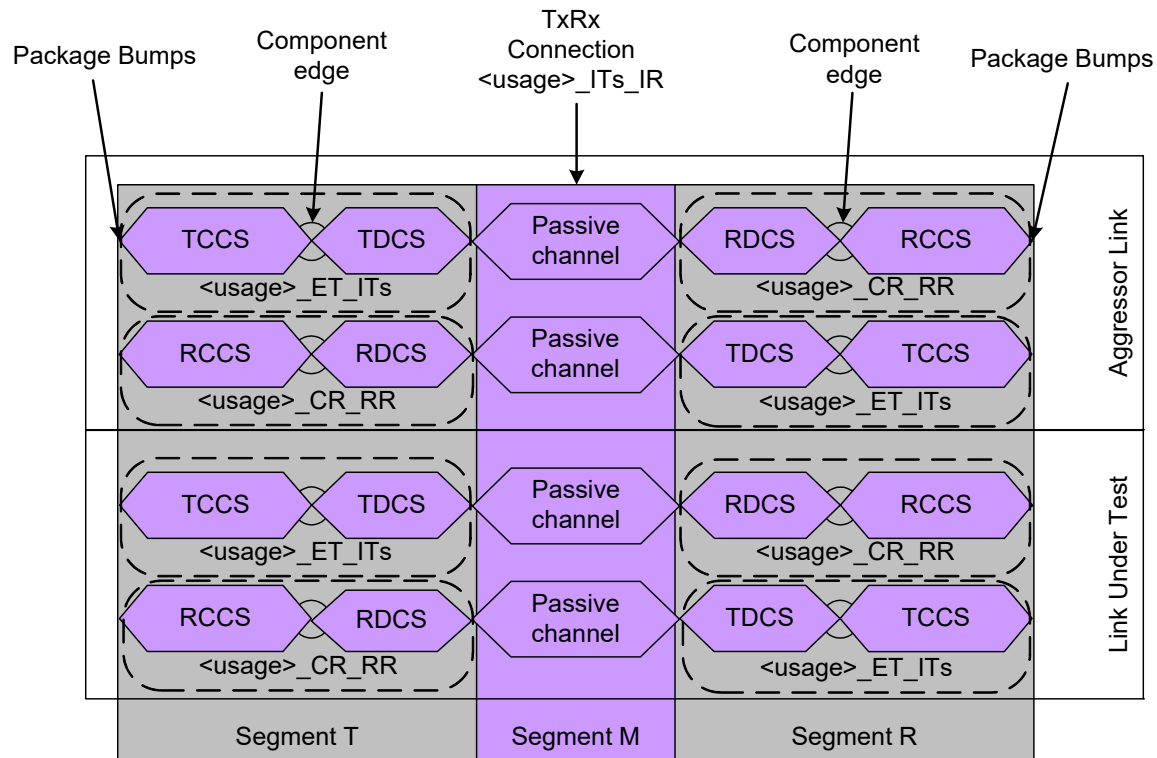


Figure E.2 — Example of a SAS three TxRx connection segment

E.2 End to end simulation using SAS3_EYEOPENING

The SAS3_EYEOPENING Octave/Matlab script may be used for end-to-end simulations and trained 12 Gbit/s transmitter device characterization (see 5.8.4.6). The script and its documentation (i.e., SAS3_EYEOPENING_Usage_Guide) are included in the SAS3 directory of SAS-4_1.zip. A wrapper script (i.e., SAS3_Usage) is included in the SAS3 directory of SAS-4_1.zip for running the end-to-end simulation described in Annex C. This wrapper script may be run in either interactive mode or batch mode. See SAS3_EYEOPENING_Usage_Guide for full details.

Annex F

(Informative)

Fitted insertion loss, frequency weighting function, and integrated crosstalk noise calculation methods

F.1 Fitted insertion loss

The fitted insertion loss as a function of frequency is defined by the following equation:

$$IL_{\text{fitted}}(f) = a_0 + a_1 \sqrt{\frac{f}{f_{\text{baud}}}} + a_2 \frac{f}{f_{\text{baud}}} + a_4 \left(\frac{f}{f_{\text{baud}}} \right)^2 \text{ (dB)}$$

where:

- f is the frequency of the signal in GHz;
- f_{baud} is the baud rate in gigasymbols/s (e.g., 22.5 gigasymbols/s for 22.5 Gbit/s); and
- $a_0, a_1, a_2,$ and a_4 are coefficients calculated by the method defined in this annex.

The TxRx connection or TxRx connection segment insertion loss is measured at N uniformly spaced frequencies, f_n , for the frequency range of $f_{\text{ILmin}} \leq f \leq f_{\text{ILmax}}$ with a maximum frequency increment of 10 MHz. The weighted frequency matrix is defined by the following equation:

$$F = \begin{bmatrix} \text{mag}(IL_{f_1}) & \text{mag}(IL_{f_1}) \times \sqrt{\frac{f_1}{f_{\text{baud}}}} & \text{mag}(IL_{f_1}) \times \frac{f_1}{f_{\text{baud}}} & \text{mag}(IL_{f_1}) \times \left(\frac{f_1}{f_{\text{baud}}} \right)^2 \\ \text{mag}(IL_{f_2}) & \text{mag}(IL_{f_2}) \times \sqrt{\frac{f_2}{f_{\text{baud}}}} & \text{mag}(IL_{f_2}) \times \frac{f_2}{f_{\text{baud}}} & \text{mag}(IL_{f_2}) \times \left(\frac{f_2}{f_{\text{baud}}} \right)^2 \\ \dots & \dots & \dots & \dots \\ \text{mag}(IL_{f_N}) & \text{mag}(IL_{f_N}) \times \sqrt{\frac{f_N}{f_{\text{baud}}}} & \text{mag}(IL_{f_N}) \times \frac{f_N}{f_{\text{baud}}} & \text{mag}(IL_{f_N}) \times \left(\frac{f_N}{f_{\text{baud}}} \right)^2 \end{bmatrix}$$

where:

- $\text{mag}(IL_{f_n})$ is the magnitude of the measured insertion loss at each frequency (see G.11.1);
- f_1 is the minimum measurement frequency (i.e., f_{ILmin}); and
- f_N is the maximum measurement frequency (i.e., f_{ILmax}).

The polynomial coefficients $a_0, a_1, a_2,$ and a_4 are calculated using the following equation:

$$\begin{bmatrix} a_0 \\ a_1 \\ a_2 \\ a_4 \end{bmatrix} = \langle F^T F \rangle^{-1} F^T [\text{mag}(IL_f) \times IL_f]$$

where:

- T denotes the matrix transpose operator;
- $\text{mag}(\text{IL}_{f_n})$ is the magnitude of the measured insertion loss at each frequency (see G.11.1); and
- IL_f is a column vector of the measured insertion loss value in dB (see G.11.1).

This polynomial fit process is expected to yield values for the coefficients a_0 , a_1 , a_2 , and a_4 that comply with the values specified by the fitted insertion loss coefficient requirements. If any of the coefficients in the equation are below the minimum allowed value, then they are forced to the minimum value and the fitting process is iterated. Iteration is done by:

- 1) creating a new insertion loss, newIL , by subtracting all coefficients below the minimum allowed value from the original insertion loss;
- 2) removing these coefficients from F and recalculating the remaining coefficients;
- 3) at the end of the iteration, limit all coefficients to the maximum allowed; and
- 4) following with a final iteration on any coefficients not previously limited.

For each iteration only one additional coefficient should be forced to a value. If multiple coefficients are below the minimum value or above the maximum value, then the coefficients should be forced to a value in the following order:

- 1) a_4 ;
- 2) a_1 ;
- 3) a_2 ; and
- 4) a_0 .

An example of creating a new IL and solving for a_0 , a_1 , and a_4 where a_2 needs to be set to zero but all other coefficients are within the specified range is demonstrated by the following process:

$$\text{newIL} = \text{IL} - \left[a_{2\text{fixed}} \times \frac{f}{f_{\text{baud}}} \right]$$

This results in the frequency matrix defined by the following equation:

$$F = \begin{bmatrix} \text{mag}(\text{IL}_{f_1}) & \text{mag}(\text{IL}_{f_1}) \times \sqrt{\frac{f_1}{f_{\text{baud}}}} & \text{mag}(\text{IL}_{f_1}) \times \left(\frac{f_1}{f_{\text{baud}}}\right)^2 \\ \text{mag}(\text{IL}_{f_2}) & \text{mag}(\text{IL}_{f_2}) \times \sqrt{\frac{f_2}{f_{\text{baud}}}} & \text{mag}(\text{IL}_{f_2}) \times \left(\frac{f_2}{f_{\text{baud}}}\right)^2 \\ \dots & \dots & \dots \\ \text{mag}(\text{IL}_{f_N}) & \text{mag}(\text{IL}_{f_N}) \times \sqrt{\frac{f_N}{f_{\text{baud}}}} & \text{mag}(\text{IL}_{f_N}) \times \left(\frac{f_N}{f_{\text{baud}}}\right)^2 \end{bmatrix}$$

where:

- $\text{mag}(\text{IL}_{f_n})$ is the magnitude of the measured insertion loss at each frequency (see G.11.1);
- f_1 is the minimum measurement frequency (i.e., f_{ILmin}); and
- f_N is the maximum measurement frequency (i.e., f_{ILmax}).

The polynomial coefficients a_0 , a_1 , and a_4 are calculated using the following equation:

$$\begin{bmatrix} a_0 \\ a_1 \\ a_4 \end{bmatrix} = \langle F^T F \rangle^{-1} F^T [\text{mag}(\text{IL}_f) \times \text{IL}_f]$$

where:

- T denotes the matrix transpose operator;
- $\text{mag}(\text{IL}_{f_n})$ is the magnitude of the measured insertion loss at each frequency (see G.11.1); and
- IL_f is a column vector of the measured insertion loss value in dB (see G.11.1).

If after this iteration a_1 is below minimum allowed value, then another newIL is calculated using the following equation:

$$\text{newIL} = \text{IL} - \left[a_{1_{\text{fixed}}} \times \sqrt{\frac{f}{f_{\text{baud}}}} + a_{2_{\text{fixed}}} \times \frac{f}{f_{\text{baud}}} \right]$$

This results in the frequency matrix defined by the following equation:

$$F = \begin{bmatrix} \text{mag}(\text{IL}_{f_1}) & \text{mag}(\text{IL}_{f_1}) \times \left(\frac{f_1}{f_{\text{baud}}} \right)^2 \\ \text{mag}(\text{IL}_{f_2}) & \text{mag}(\text{IL}_{f_2}) \times \left(\frac{f_2}{f_{\text{baud}}} \right)^2 \\ \dots & \dots \\ \text{mag}(\text{IL}_{f_N}) & \text{mag}(\text{IL}_{f_N}) \times \left(\frac{f_N}{f_{\text{baud}}} \right)^2 \end{bmatrix}$$

where:

- $\text{mag}(\text{IL}_{f_n})$ is the magnitude of the measured insertion loss at each frequency (see G.11.1);
- f_1 is the minimum measurement frequency (i.e., f_{ILmin}); and
- f_N is the maximum measurement frequency (i.e., f_{ILmax}).

The polynomial coefficients a_0 and a_4 are calculated using the following equation:

$$\begin{bmatrix} a_0 \\ a_4 \end{bmatrix} = \langle F^T F \rangle^{-1} F^T [\text{mag}(\text{IL}_f) \times \text{IL}_f]$$

where:

- T denotes the matrix transpose operator;
- $\text{mag}(\text{IL}_{f_n})$ is the magnitude of the measured insertion loss at each frequency (see G.11.1); and
- IL_f is a column vector of the measured insertion loss value in dB (see G.11.1).

If after this calculation all coefficients are within their specified range, then the iteration process is complete.

F.2 Frequency weighting function

Some calculations use a weighting function to scale the magnitude of electrical characteristic equations to provide an approximation of the spectral content of a signal up to the baud rate. The weighting function is defined by the following equation:

$$W(f) = \text{sinc}^2\left(\frac{f}{f_{\text{baud}}}\right) \left[\frac{1}{1 + \left(\frac{f}{f_r}\right)^4} \right] \left[\frac{1}{1 + \left(\frac{f}{f_r}\right)^8} \right]$$

where:

$$f_t = \frac{0.2365}{T_t}$$

and:

$$\text{sinc}(x) \text{ is } \frac{\sin(\pi x)}{\pi x};$$

f is the frequency of the signal in GHz;

f_{baud} is the baud rate in gigasymbols/s (e.g., 22.5 gigasymbols/s for 22.5 Gbit/s);

f_r is the 3 dB reference receiver bandwidth = (3/4) f_{baud} in GHz (e.g., 16.875 GHz at 22.5 Gbit/s); and

T_t is the 20 % to 80 % rise time in ns.

F.3 Integrated crosstalk noise

Integrated crosstalk noise (ICN) is the weighted rms value of multi-disturber near-end crosstalk loss and multi-disturber far-end crosstalk loss, MDNEXT_{loss}(f) and MDFEXT_{loss}(f), respectively).

MDNEXT_{loss}(f) is determined from all individual pair-to-pair differential NEXT loss values by the following equation:

$$\text{MDNEXT}_{\text{loss}}(f) = -10 \times \log_{10} \left(\sum_{i=0}^{\text{allNEXTs}} 10^{-\left(\frac{\text{NLI}(f)}{10}\right)} \right) (\text{dB})$$

for $f_{\text{min}} \leq f \leq f_{\text{max}}$

where:

MDNEXT_{loss}(f) is the MDNEXT loss at frequency f;

NLI(f) is the NEXT loss at frequency f of pair combination i, in dB;

f is the frequency in GHz; and

i is all pair-to-pair combinations.

MDFEXT_{loss}(f) is determined from all individual pair-to-pair differential FEXT loss values by the following equation:

$$\text{MDFEXT}_{\text{loss}}(f) = -10 \times \log_{10} \left(\sum_{i=0}^{\text{allFEXTs}} 10^{-\left(\frac{\text{FLi}(f)}{10}\right)} \right) (\text{dB})$$

for $f_{\text{min}} \leq f \leq f_{\text{max}}$

where:

- MDFEXT_{loss}(f) is the MDFEXT loss at frequency f;
 FLi(f) is the FEXT loss at frequency f of pair combination i, in dB;
 f is the frequency in GHz; and
 i is all pair-to-pair combinations.

The weighting at each frequency is defined by the following equations:

$$W_{nt}(f) = \left(\frac{A_{nt}^2}{4f_{baud}} \right) \text{sinc}^2\left(\frac{f}{f_{baud}}\right) \left[\frac{1}{1 + \left(\frac{f}{f_{nt}}\right)^4} \right] \left[\frac{1}{1 + \left(\frac{f}{f_r}\right)^8} \right]; \text{ and}$$

$$W_{ft}(f) = \left(\frac{A_{ft}^2}{4f_{baud}} \right) \text{sinc}^2\left(\frac{f}{f_{baud}}\right) \left[\frac{1}{1 + \left(\frac{f}{f_{ft}}\right)^4} \right] \left[\frac{1}{1 + \left(\frac{f}{f_r}\right)^8} \right]$$

for $f_{min} \leq f \leq f_{max}$

where:

$$f_{nt} = f_{ft} = f_t = \frac{0.2365}{T_{nt}} = \frac{0.2365}{T_{ft}}$$

and:

- $\text{sinc}(x)$ is $\frac{\sin(\pi x)}{\pi x}$;
 A_{nt} is the near end Tx peak to peak maximum voltage;
 A_{ft} is the far end Tx peak to peak maximum voltage;
 f is the frequency of the signal in GHz;
 f_{baud} is the baud rate;
 f_r is the -3 dB reference receiver bandwidth (set at $(3/4) f_{baud}$);
 T_{nt} is the near end 20 % to 80 % rise time in ns;
 T_{ft} is the far end 20 % to 80 % rise time in ns;

The near end ICN for $f_{min} \leq f \leq f_{max}$ is calculated by the following equation:

$$\sigma_{nx} = \sqrt{2\Delta f \sum_n W_{nt}(f_n) 10^{-(MDNEXT_{loss}(f_n))/10}}$$

The far end ICN for $f_{min} \leq f \leq f_{max}$ is calculated by the following equation:

$$\sigma_{fx} = \sqrt{2\Delta f \sum_n W_{ft}(f_n) 10^{-(MDFEXT_{loss}(f_n))/10}}$$

The total ICN for $f_{min} \leq f \leq f_{max}$ is calculated using the following equation:

$$ICN = \sigma_x = \sqrt{\sigma_{nx}^2 + \sigma_{fx}^2}$$

Annex G

(Informative)

Signal performance measurements

G.1 Signal performance measurements overview

This annex describes methodologies for making electrical performance measurements, including signal output, signal tolerance, and return loss. Standard loads are used in all cases so that independent specification of connection components and transportability of the measurement results are possible.

G.2 Glossary

G.2.1 port: In this annex, the physical input or output connection of an instrument or device.

G.3 Simple physical link

G.3.1 Simple physical link overview

The physical link consists of the following component parts:

- the transmitter device;
- the interconnect; and
- the receiver device.

Each of these components is connected by a separable connector. On a TxRx connection, signals travel in opposite directions down the same nominal path.

Figure G.1 shows a physical link and the location of the connectors.

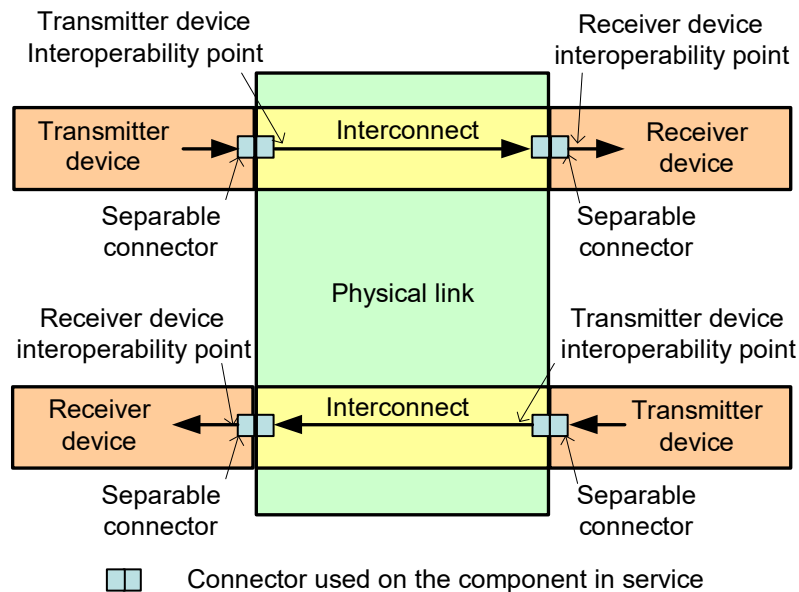


Figure G.1 — A simple physical link

Since connectors are always used in the mated condition, the only practical access to the signals is before the signal enters the mated connector (i.e., upstream) or after the signal exits the connector (i.e., downstream). Even if signals were able to be accessed at the point of mating within the connector, such access may disturb the connector to the point that the measurement of the signal is compromised (e.g., attempting to access the unmated connector with probes does not provide valid results because the connector is not in the same

condition when unmated as when mated and the probe contact points are not at the same location as the connector contact points).

In this annex, signal outputs are always measured downstream of the mated connector (see figure G.1) so that the contribution of the mated connector to the signal properties is included in the measurement. This approach assigns a portion of the connector losses to the upstream component, but it also makes the signal measurement conservative. If the connectors on both ends of the interconnect are the same, then the additional loss at the downstream connector is offset by the reduced loss at the upstream connector.

G.3.2 Assumptions for the structure of the transmitter device and the receiver device

Figure G.2 shows the details of a transmitter device.

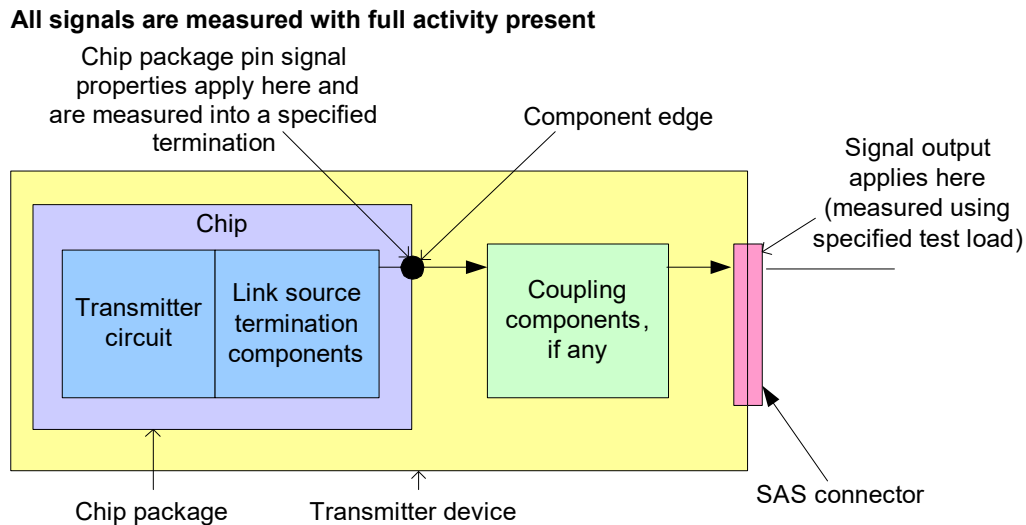


Figure G.2 — Transmitter device details

As figure G.2 shows, any of the following internal parts of this transmitter device may be labeled as the transmitter:

- a) the transmitter circuit in the chip;
- b) the chip itself; or
- c) the chip and its associated chip package.

The term *transmitter* is therefore not well defined and is not used in the terminology without a modifier.

The transmitter device contains:

- a) a connector (i.e., half a mated pair);
- b) coupling components, if any;
- c) PCB traces and vias;
- d) the chip package;
- e) ESD protection devices, if any;
- f) the source termination; and
- g) the transmitter circuit.

It is assumed that the source termination is contained within the chip package.

Figure G.3 shows the details of a receiver device. It is similar to the transmitter device.

All signals measured with full activity present

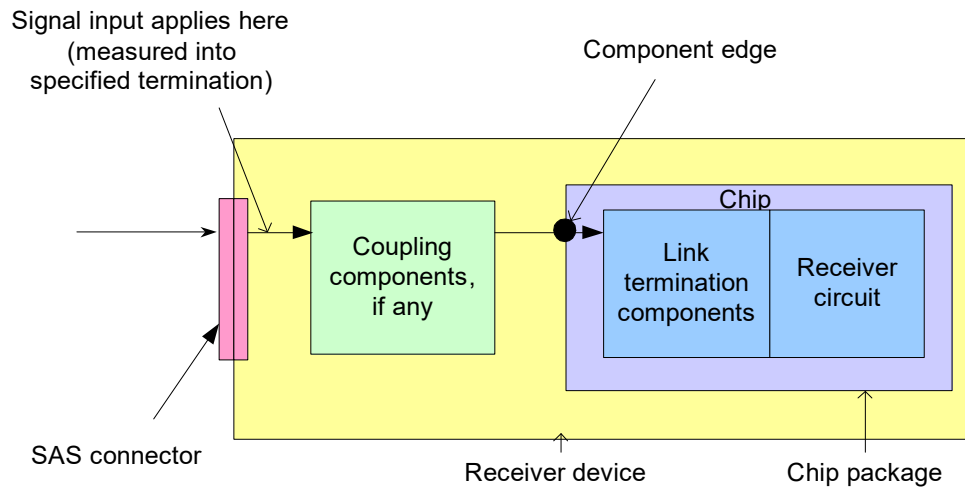


Figure G.3 — Receiver device details

As figure G.3 shows, any of the following internal parts of this receiver device may be labeled as the receiver:

- a) the receiver circuit in the chip;
- b) the chip itself; or
- c) the chip and its associated chip package.

The term *receiver* is therefore not well defined and is not used in the terminology without a modifier.

The receiver device contains:

- a) a connector (i.e., half a mated pair);
- b) coupling components, if any;
- c) PCB traces and vias;
- d) the chip package;
- e) ESD protection devices, if any;
- f) the physical link termination; and
- g) the receiver circuit.

It is assumed that the physical link termination is contained within the chip package.

G.3.3 Definition of receiver sensitivity and receiver device sensitivity

The term *receiver sensitivity* is not well defined and is therefore not used in this standard. A related term applicable to the receiver device input signal is *receiver device sensitivity*. While these two terms are related, they are significantly different because of the noise environment assumed. The description in this subclause is used to define these terms with the understanding that this standard discourages usage of either term.

For 1.5 Gbit/s and 3 Gbit/s, receiver device sensitivity is defined as the minimum vertical inner eye opening measured at the signal output point for the input to the receiver device at which the receiver chip (i.e., the receiver circuit in the chip package on the board containing the receiver device interoperability point as shown in figure G.3) delivers the required BER (see 5.8.1) with:

- a) the minimum horizontal eye opening;
- b) all activity expected in the application for the receiver circuit present (i.e., not quiesced as for the receiver sensitivity definition); and
- c) the CJTPAT pattern being received (see Annex A).

For 6 Gbit/s, receiver device sensitivity is defined as the minimum vertical inner eye opening determined by simulation. The signal measured at the input to the receiver device is processed in a manner to simulate the additional interconnect losses (e.g., board traces, chip package). Then, the equalization function provided by the receiver circuit is applied to determine the resulting eye opening.

G.10 describes special test conditions to measure these sensitivities.

For 12 Gbit/s, receiver device sensitivity is verified to achieve the specified BER by testing the receiver device with a stressed signal equivalent to the reference transmitter and reference TxRx connection applied to the receiver device. See 5.8.5.7.6.5 for the test procedure.

This standard uses the term *signal tolerance* instead of *receiver device sensitivity*.

G.4 Signal measurement architecture

G.4.1 General

Signal specifications are only meaningful if the signals are able to be measured with practical instrumentation and if different laboratories making measurements on the same signal get the same results within acceptable measurement error (i.e., the measurements need to be accessible, verifiable, and transportable).

Some of the elements necessary for practical, verifiable, and transportable signal measurements are included in this standard.

Having signal specifications at interoperability points that do not depend on the actual properties of the other physical link components not under test requires that specified known test loads be used for the signal measurements. In service, the load presented to the interoperability point is that of the actual component and environment.

Interfacing with practical instruments requires that specified impedance environments be used. This forces a signal measurement architecture where the impedance environment is 50 Ω single ended (i.e., 100 Ω differential) and also forces the requirement for instrumentation quality loads of the correct value.

Instrumentation quality loads are readily available for simple transmission line termination. However, no instrumentation quality loads are available for more complex loads that include specified propagation time, insertion loss properties, crosstalk properties, and jitter creation properties.

For signal tolerance measurements, the signal is calibrated before applying it to the interoperability point under test. This signal calibration is done by adjusting the properties of the specified signal source system as measured into a laboratory quality test load until the desired signal tolerance specifications are met. The signal source system is then disconnected from the laboratory quality test load and connected to the interoperability point under test. It is assumed that any changes to the signal from the calibration state to the measurement state are caused by the interoperability point under test and are therefore part of the performance sought by the measurement.

G.4.2 Relationship between signal compliance measurements at interoperability points and operation in systems

The signal measurements in this standard apply under specified test conditions that simulate some parts of the conditions existing in service (e.g., this simulation includes full-duplex traffic on all phys and under all applicable environmental conditions). Other features existing in service (e.g., non-ideal return loss in parts of the physical link that are not present when measuring signals in the specified test conditions) may be included in the signal specifications themselves. This methodology results in signal performance requirements for each side of the interoperability point that do not depend on knowing the properties of the other side.

Measuring signals in an actual functioning system at an interoperability point does not verify compliance for the components on either side of the interoperability point, although it does verify that the specific combination of components in the system at the time of the measurement produces compliant signals. Interaction between components on either side of the interoperability point may allow the signal measured to be compliant, but this compliance may have resulted because one component does not meet the signal specifications while the other exceeds the signal specifications.

Additional margin should be allowed when performing signal compliance measurements to account for conditions existing in service that have not been accounted for in the specified measurements and signal specifications.

G.5 De-embedding connectors in test fixtures

Connectors are part of the test fixtures (e.g. test loads) needed for obtaining access to the interoperability points. This is intrinsic for most practical measurements because the connectors used on the service components are different from those used on the instrumentation.

The effects of the portions of the connector used on the test fixture are taken into account when measurements are made using the fixture so that the results of interoperability point under test are not influenced by the performance of the test fixture connector. This accounting process is termed de-embedding.

Figure G.4 shows two cases that apply.

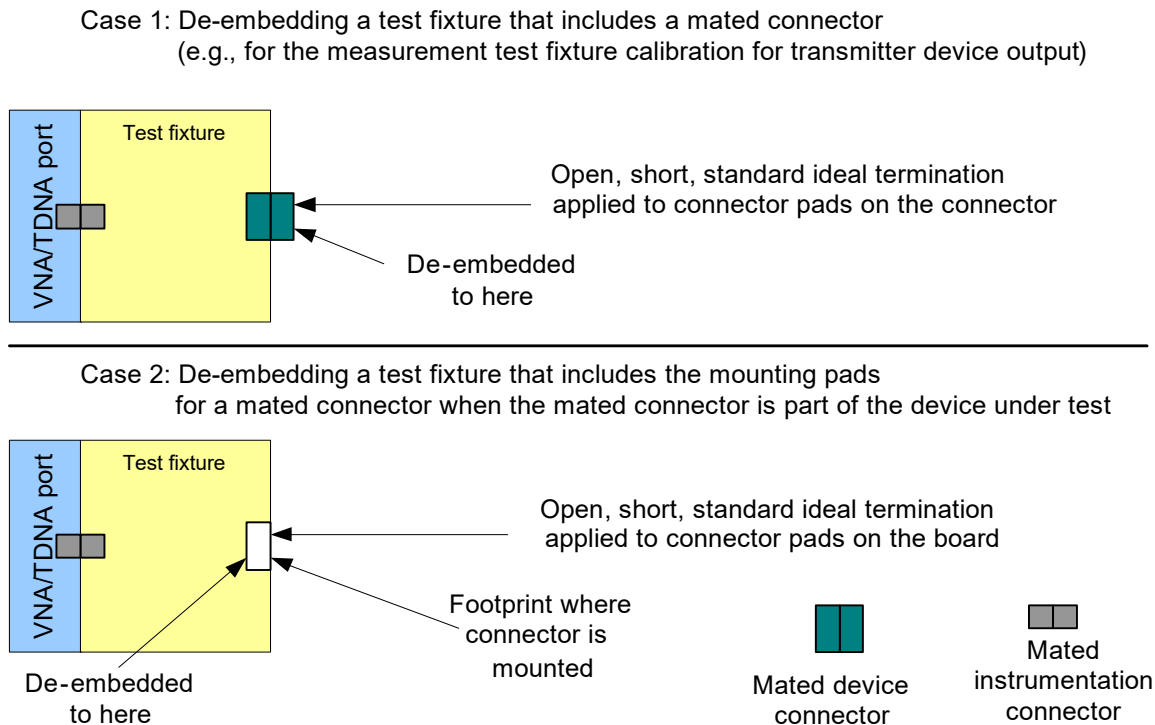


Figure G.4 — De-embedding of connectors in test fixtures

The de-embedding process assumes that the test fixture is linear and that S-parameter methodologies (see G.11) are used. An S-parameter model for the test fixture with or without the connector in place is the result. Knowing this model for the test fixture, with or without the connector in place, allows simulation of the impact of the test fixture on the signal measurement.

G.6 De-embedding test fixture for 12 Gbit/s transmitter compliance

Connectors and board traces are part of the test fixtures (e.g., test loads) needed for obtaining access to the transmitter compliance point ET (see 5.3.3). The effects of the test fixture and test board de-embedding by creation of a de-embedding filter to cancel their effects on the measurements.

Figure G.5 shows the test fixture for a 12 Gbit/s transmitter compliance test.

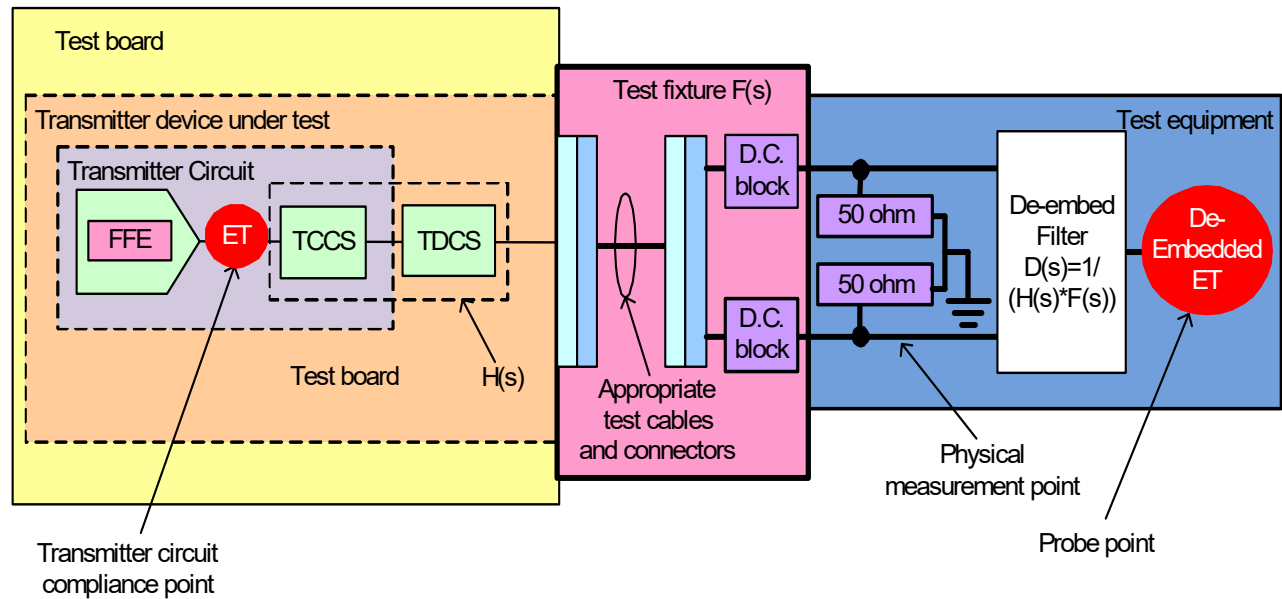


Figure G.5 — De-embedding to ET for 12 Gbit/s transmitter compliance

Figure G.6 shows a test structure for measuring the channel to be de-embedded.

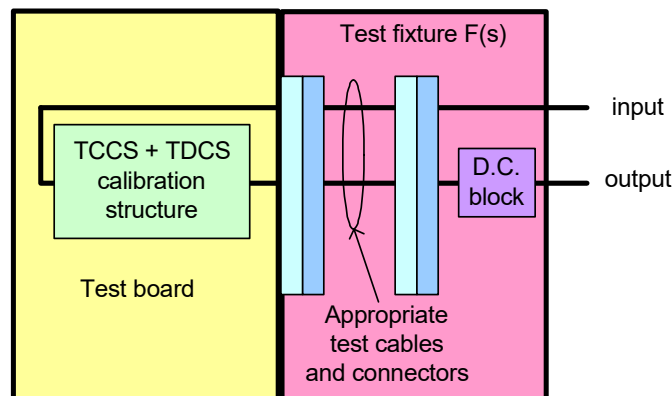


Figure G.6 — De-embedding calibration test structure

The de-embedding process consist of the following steps:

- 1) measure a de-embedding test structure equivalent to the TCCS and TDCS $H(s)$ and test fixture $F(s)$;
- 2) compute an appropriate de-embedding filter $D(s)$; and
- 3) exercise the transmitter to demonstrate compliance observed at the output of the de-embedding filter.

G.7 Measurement conditions for signal output at the transmitter device

The measurement conditions for a differential transmitter device signal output are shown in figure G.7.

Figure G.7 applies to the following cases the transmitter device:

- a) is directly attached to the zero-length test load (see 5.6.2); and
- b) is attached to the TCTF test load (see 5.6.3).

To simulate the properties of the interconnect assembly, instrumentation quality test loads as shown in figure G.8 are used.

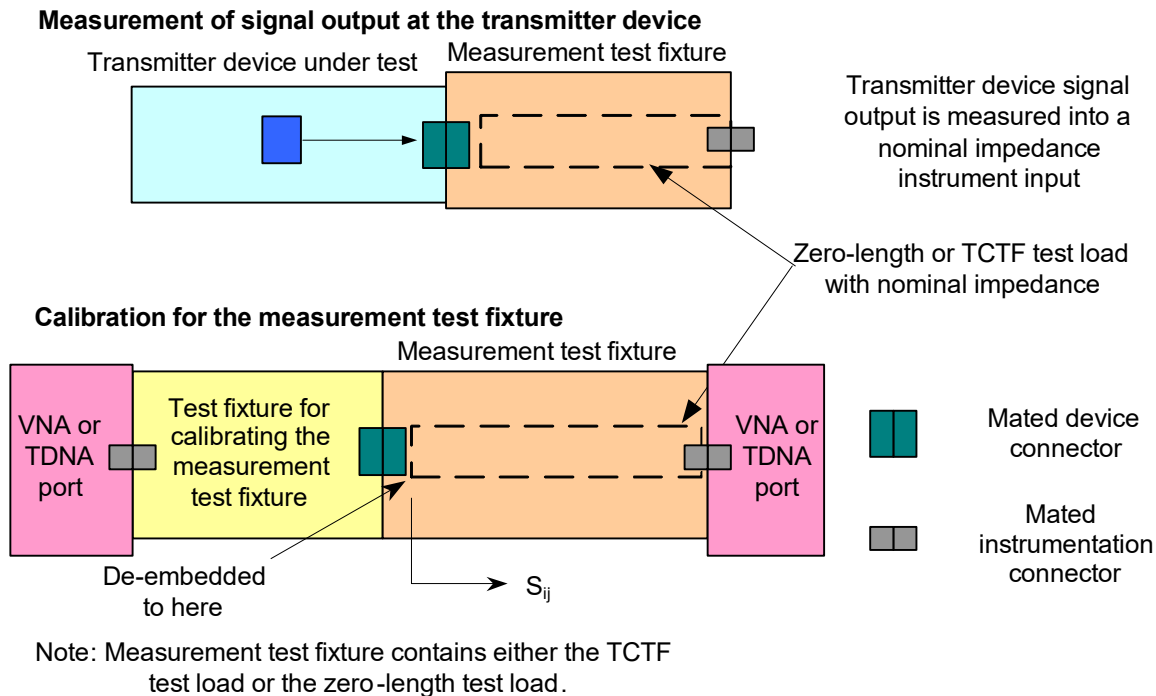


Figure G.7 — Measurement conditions for signal output at the transmitter device

An instrumentation quality cable assembly connects the measurement test fixture to the instrumentation port. This cable assembly is considered part of the instrumentation and is not specifically shown in figure G.7, figure G.8, figure G.9, figure G.10, figure G.11, figure G.12, and figure G.13.

A measurement test fixture may be constructed from an instrumentation quality TCTF test load with instrumentation quality connectors and a connector adapter as shown in figure G.8. This method may be useful when using multiple device connector types but adds extra components that may increase loss and delay. For best accuracy, this method is not recommended. Extra components make it more difficult for the transmitter device to meet the required output specifications.

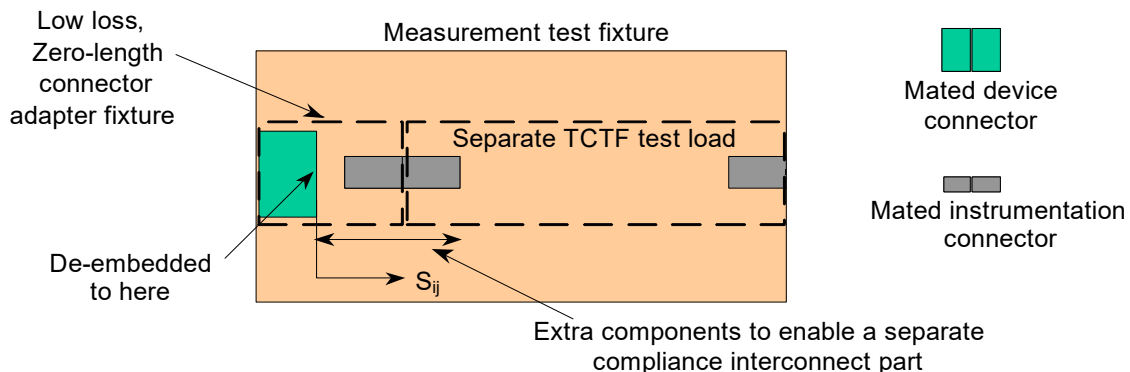


Figure G.8 — Transmitter device signal output measurement test fixture details

G.8 Measurement conditions for signal tolerance at the transmitter device

The measurement conditions for the signal tolerance at the differential transmitter device interoperability point are shown in figure G.9. Figure G.9 shows the test signal is launched into the interconnect assembly (e.g., cable assembly or PCB) that is attached to the receiver device.

This standard does not specify this performance requirement. It is included here for completeness.

Measurement of signal tolerance at transmitter device (e.g., IT and CT)

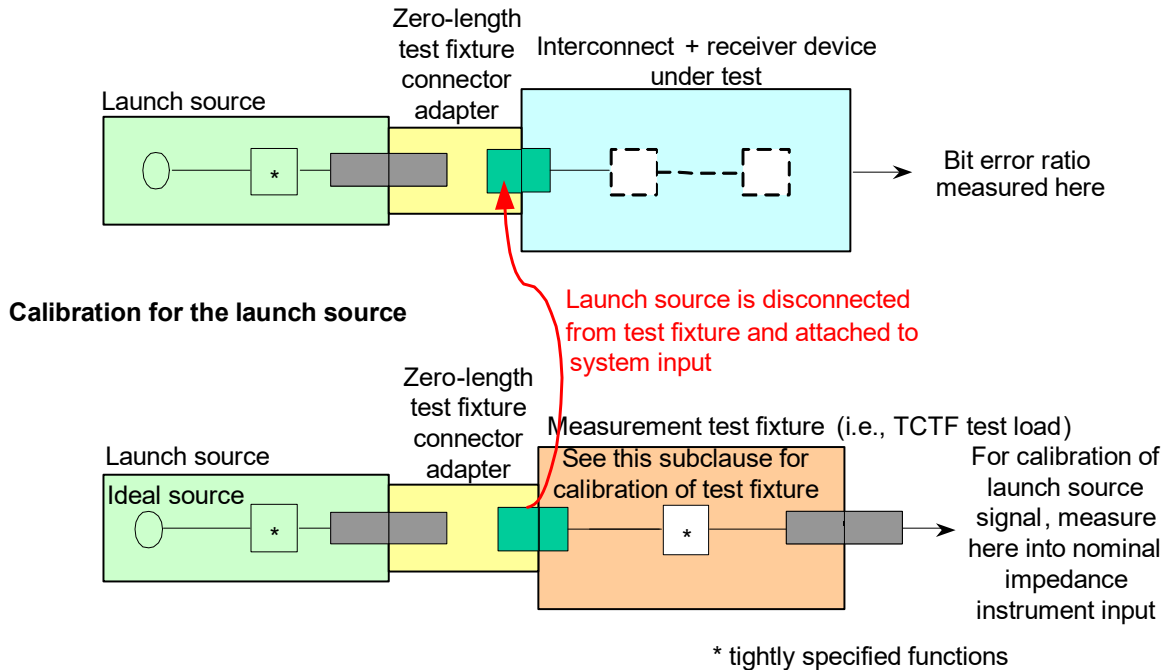


Figure G.9 — Measurement conditions for signal tolerance at the transmitter device

Figure G.10 shows calibration of the measurement test fixture.

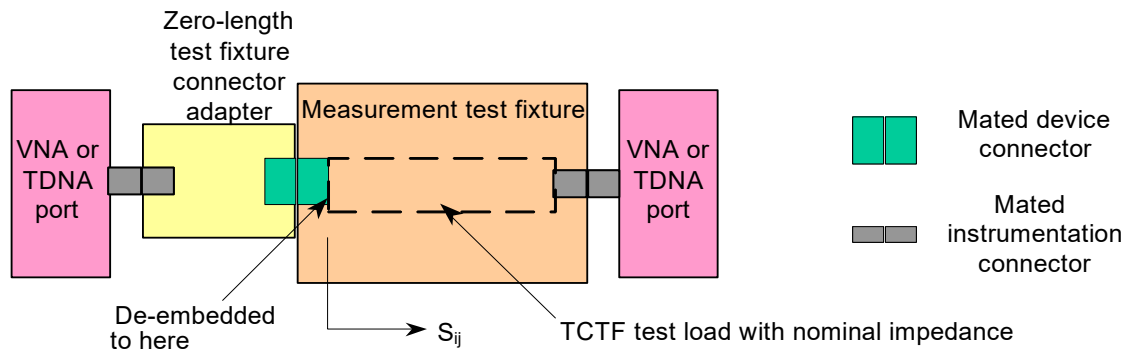


Figure G.10 — Calibration of test fixture for signal tolerance at the transmitter device

G.9 Measurement conditions for signal output at the receiver device

Figure G.11 shows the measurement conditions for the signal output at the receiver device.

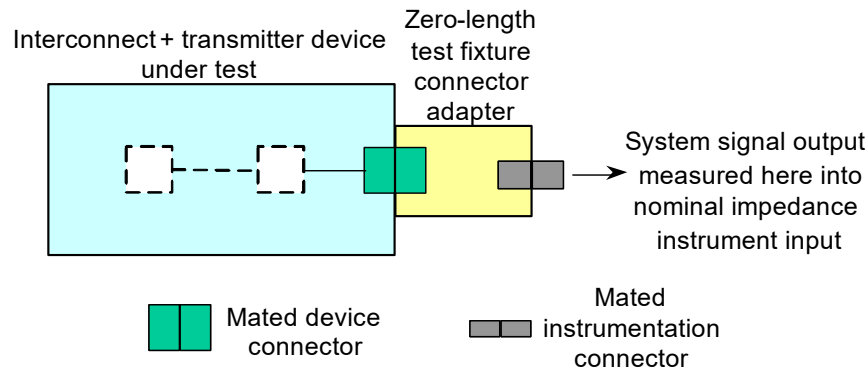


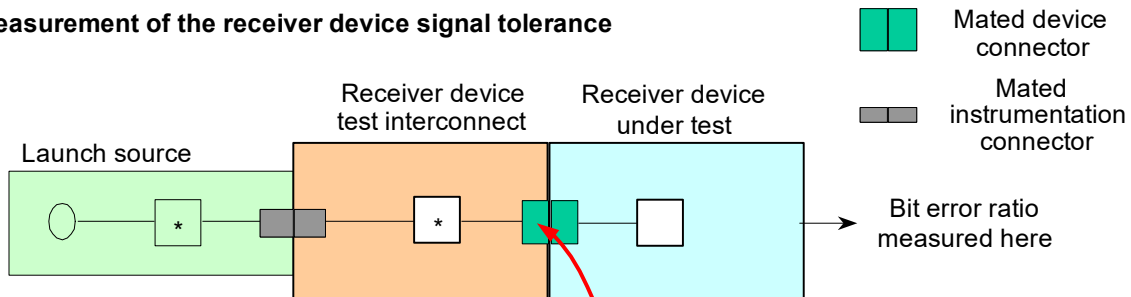
Figure G.11 — Measurement conditions for signal output at the receiver device

The interconnect may be the zero-length connector adaptor where the transmitter device is connected directly to the receiver device.

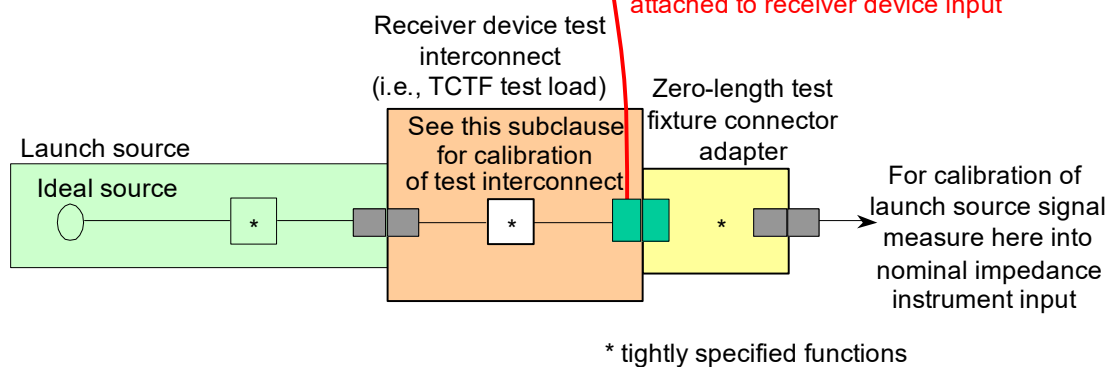
G.10 Measurement conditions for signal tolerance at the receiver device

Figure G.12 shows the measurement conditions for the signal tolerance at the differential receiver device interoperability point (see 5.8.5.4).

Measurement of the receiver device signal tolerance



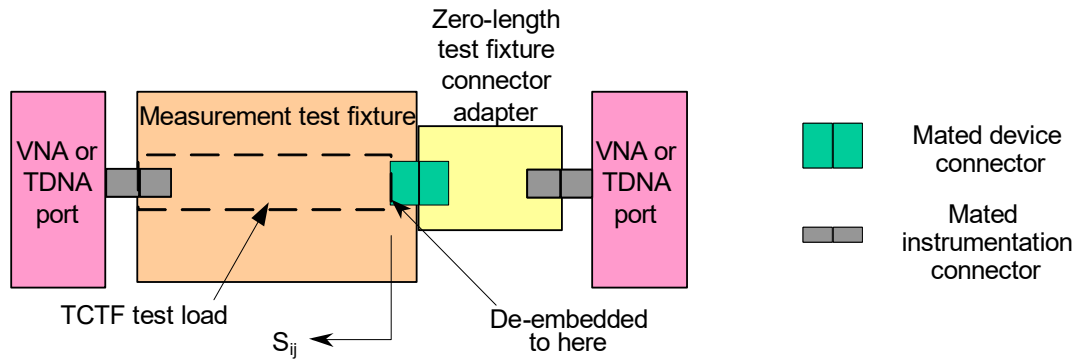
Calibration for the receiver device input signal



* tightly specified functions

Figure G.12 — Measurement conditions for signal tolerance at the receiver device

Figure G.13 shows calibration of the measurement test fixture.



NOTE 1 - This is not identical to the measurement test fixture used for the transmitter output signal even though the connector genders are the same. The pins used in the SAS connector are for the Rx (i.e., not the Tx) signals and the signals flow the other way. The S_{22} measurement here is the same as the S_{11} measurement for the transmitter output signal but on different pins.

NOTE 2 - The S_{21} and S_{12} are used to create the desired jitter in this application and are not as critical.

Figure G.13 — Calibration of test fixture for signal tolerance at the receiver device

G.11 S-parameter measurements

G.11.1 Gain parameter and loss parameter overview

Properties of physical link elements that are linear may be represented by S-parameter (i.e., scattering parameter) spectra. G.11.4 describes using special test fixtures to make S-parameter measurements.

S-parameters are the preferred method of capturing the linear properties of physical link elements. A frequency domain spectrum output is used for all S-parameters and specifying pass/fail limits to such a spectrum may overconstrain the system because some peaks and properties are benign to the application.

There are four problematic areas when applying S-parameters to differential electrical physical links:

- naming conventions (see G.11.2);
- use of single ended vector network methods on differential and common mode systems (see G.11.3);
- unit domain (i.e., linear or dB); and
- relationship to other parameters (e.g., insertion loss).

Several parameters are used to characterize physical link elements. They fall into one of two classes:

- gain parameters (e.g., S-parameters); or
- loss parameters (e.g., return loss).

A gain parameter is the ratio of an output relative to an input. A loss parameter is the ratio of an input relative to an output. Since a gain parameter and a loss parameter are ratios of values having the same unit, they are both dimensionless. These ratios are typically complex numbers with magnitude and phase components. The phase component is typically less critical and not specified. The gain parameter and the loss parameter for the same physical link element measurement are the reciprocal of each other.

Gain parameters and loss parameters are commonly expressed in units of dB calculated by the following equation:

$$\text{parameter(dB)} = 20 \times \log_{10}(|\text{parameter(linear)}|)$$

The equation defines two unit domains:

- a) a dB domain on the left of the equal sign for the conversion of the parameter to a dB value; and
- b) a linear domain on the right of the equal sign for the magnitude of the parameter.

The domain distinction is important to consider when calculating fitted insertion loss because values for insertion loss from both domains are used in the insertion loss fitting equations (see F.1).

The gain parameter magnitude component is denoted by single vertical bars in this standard (e.g., $|S_{DD21}|$) and is always assumed to be in the dB domain. Although the vertical bars suggest a positive absolute value, $|S_{DD21}|$ is always a positive number in the linear domain but, if the value in the linear domain is less than 1 (i.e., exhibits loss), then the value in the dB domain is a negative number. The gain parameter (e.g., $|S_{DD21}|$) and the loss parameter (e.g., insertion loss) are reciprocals in the linear domain and have opposite signs in the dB domain.

Table G.1 shows the reciprocal and sign behavior between $|S_{DD21}|$ and insertion loss in the linear domain and dB domain. For passive physical link elements (e.g., gain < 1), $|S_{DD21}|$ is negative and insertion loss is positive in the dB domain.

Table G.1 — $|S_{DD21}|$ and insertion loss in the linear domain and dB domain

Ratio of output voltage to input voltage	$ S_{DD21} $		Insertion loss	
	Linear	dB	Linear	dB
10	10	+20	0.1	-20
2	2	+6 ^a	0.5	-6 ^a
1	1	0	1	0
0.5	0.5	-6 ^a	2	+6 ^a
0.1	0.1	-20	10	+20
0	0	$-\infty$	$+\infty$	$+\infty$
^a Approximate value.				

Table G.2 shows the reciprocal and sign behavior between $|S_{DD11}|$ and return loss in the linear domain and dB domain. For passive physical link elements (e.g., gain < 1), $|S_{DD11}|$ is negative and return loss is positive in the dB domain.

Table G.2 — $|S_{DD11}|$ and return loss in the linear domain and dB domain

Ratio of output voltage to input voltage	$ S_{DD11} $		Return loss	
	Linear	dB	Linear	dB
10	10	+20	0.1	-20
2	2	+6 ^a	0.5	-6 ^a
1	1	0	1	0
0.5	0.5	-6 ^a	2	+6 ^a
0.1	0.1	-20	10	+20
0	0	$-\infty$	$+\infty$	$+\infty$
^a Approximate value.				

G.11.2 S-parameter naming conventions

There are two types of measurements performed with S-parameters:

- a) return loss from the same port of the element; and
- b) insertion loss across the element.

Each S-parameter is a function of frequency returning complex numbers and is expressed with:

- a) a magnitude component, usually expressed in dB; and
- b) a phase component.

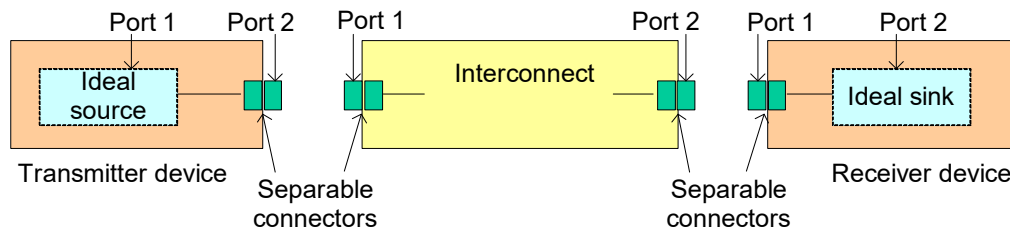
For a two port linear element having ports i and j with the signals being either differential or common mode, S_{ij} is the ratio of the signal coming out of the ith port (i.e., the response) to the signal coming into the jth port (i.e., the stimulus).

A port number convention is used where the downstream port is always port 2 and the upstream port is always port 1. The stream direction is determined by the direction of the primary signal launched from the transmitter device to the receiver device (e.g., in this standard, since each differential pair carries a signal in only one direction, the port nearest the transmitter device is port 1 and the port nearest the receiver device is port 2).

There are four combinations of ports for a two ported system yielding the following S-parameters:

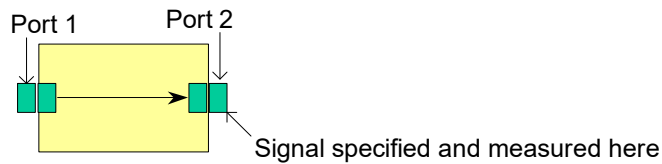
- a) S_{11} (i.e., negative return loss): measured at port 1;
- b) S_{21} (i.e., negative insertion loss): measured at port 1;
- c) S_{22} (i.e., negative upstream return loss): measured at port 2 of the element. The measurement is the same kind of measurement that is done at port 1 to measure S_{11} ; and
- d) S_{12} (i.e., negative upstream insertion loss): measured at port 2 of the element. The measurement is the same kind of measurement that is done at port 1 to measure S_{21} .

Figure G.14 shows the port naming conventions for physical link elements, loads, and where those elements exit.



The transmitter device port 1 and receiver device port 2 are internal and are not defined.

Port definitions for loads used for signal output testing and S-parameter measurements in multiline configurations



This load has ideal differential and common mode properties

Figure G.14 — S-parameter port naming conventions

G.11.3 Use of single ended instrumentation in differential applications

There are four categories of S-parameters for a differential system:

- S_{DDij} , differential stimulus, differential response;
- S_{CDij} , differential stimulus, common mode response (i.e., mode conversion causing emissions);
- S_{DCij} , common mode stimulus, differential response (i.e., mode conversion causing susceptibility); and
- S_{CCij} , common mode stimulus, common mode response.

Figure G.15 shows the connections that are made to a four port VNA or TDNA for measuring S-parameters on a four single ended port black box device.

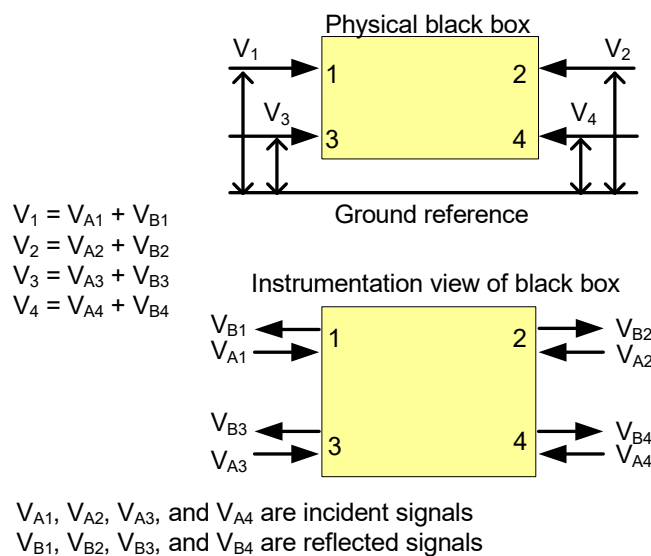


Figure G.15 — Four single ended port or two differential port element

Since VNA ports are all single ended, the differential and common mode properties for differential ports are calculated internal to the VNA or are mathematically derived. If using a TDNA, consult the details for the specific instrument. Four analyzer ports are needed to measure the properties of two differential ports.

Figure G.16 shows the set of S-parameters for a single ended system and for a differential system.

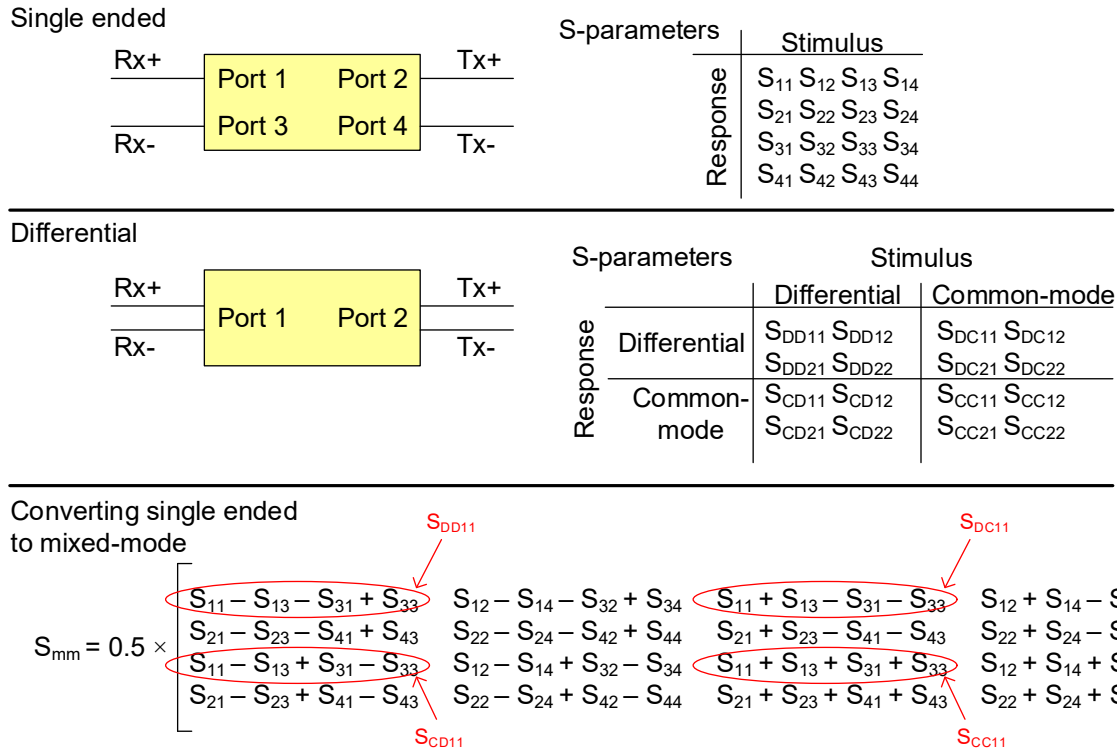


Figure G.16 — S-parameters for single ended and differential systems

See SFF-8416 for details on differential S-parameter measurements.

G.11.4 Measurement configurations for physical link elements

G.11.4.1 Measurement configuration overview

Special test fixtures are needed to make S-parameter measurements partly because the connectors used on real physical link elements are different from those used on instrumentation. The goal is for these test fixtures to be as invisible as possible.

All of the measurements in this annex are of S_{11} or S_{22} . A more complete set of S-parameters is used as part of the calibration process for test fixtures.

G.11.4.2 Transmitter device S_{22} measurements

Figure G.17 shows the configuration to be used for the transmitter device S_{22} measurements.

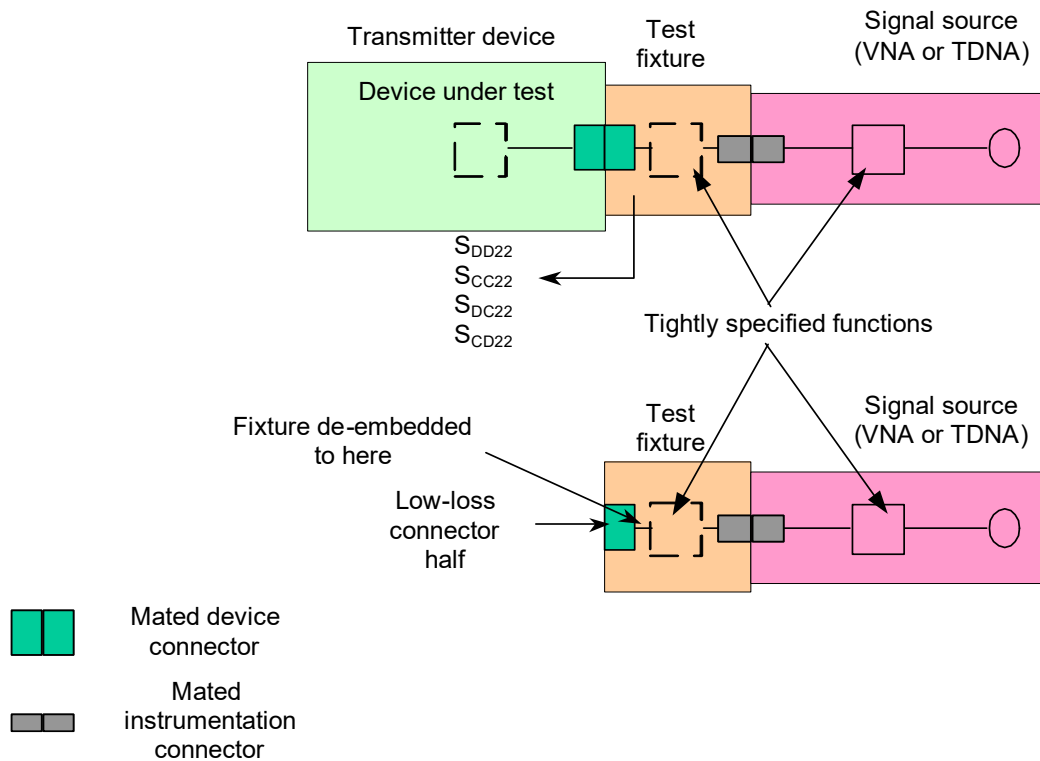


Figure G.17 — Measurement conditions for S_{22} at the transmitter device connector

The test fixture in figure G.17 uses low loss connectors to avoid penalizing the transmitter device under test for the test fixture half of the connector.

The test fixture losses up to the mounting points for the device connector are de-embedded using the methods described in figure G.4.

G.11.4.3 Receiver device S_{11} measurements

Figure G.18 shows the configuration to be used for the receiver device S_{11} measurements.

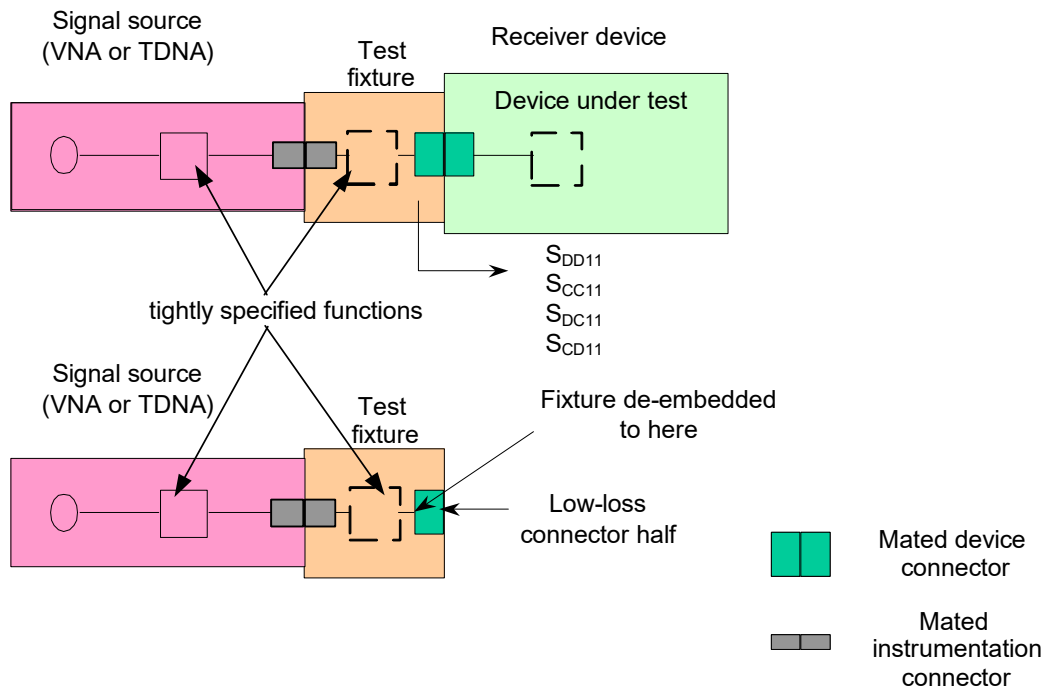


Figure G.18 — Measurement conditions for S_{11} at the receiver device connector

The test fixture in figure G.18 uses low loss connectors to avoid penalizing the receiver device under test for the test fixture half of the connector.

The test fixture losses up to the mounting points for the device connector are de-embedded using the methods described in figure G.4.

G.11.4.4 TxRx connection S_{11} measurements at IT or CT

Figure G.19 shows the conditions for making S_{11} measurements of the interconnect attached to the transmitter device.

This measurement, like the signal tolerance measurement at the transmitter device connector, has both the interconnect and the receiver device in place when the combination is measured. If the receiver device is replaced by an ideal load, then S_{11} does not represent in-service conditions. If the interconnect is very lossy, then the effects of the load on the far end (i.e., where the receiver device is located) are not significant and an ideal load may be used. However, if the interconnect is not very lossy (e.g., the zero-length test load), then the measured S_{11} may be dominated by the properties of the receiver device and not the properties of the interconnect.

For short physical links, S_{11} performance may be the limiting factor for the entire physical link due to severe unattenuated reflections that create large DJ.

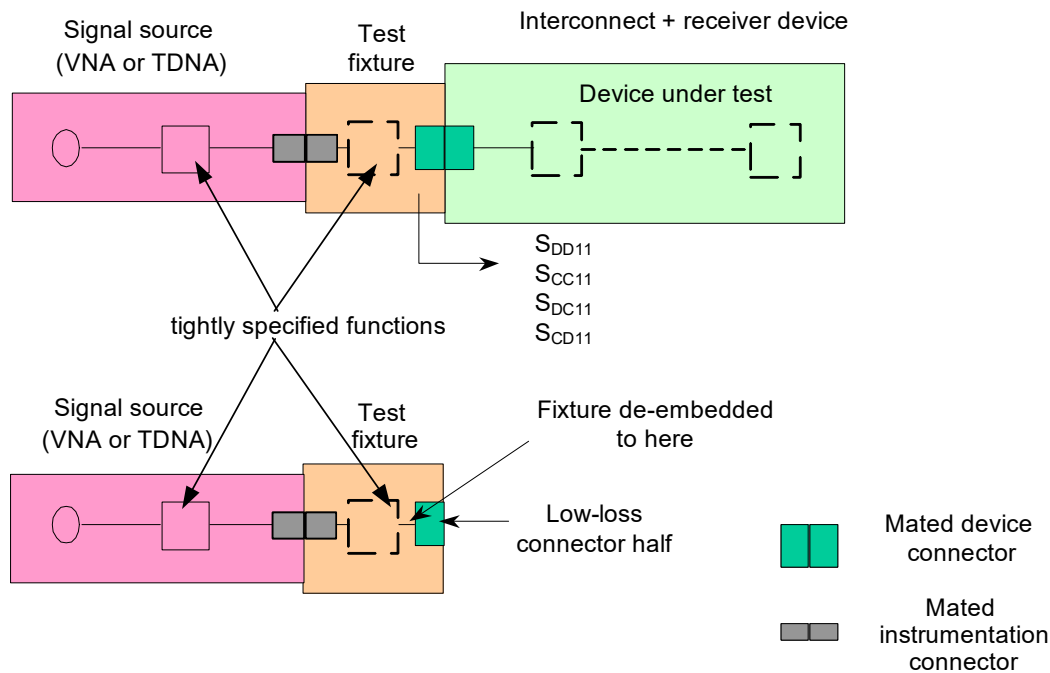


Figure G.19 — Measurement conditions for S_{11} at IT or CT

G.11.4.5 TxRx connection S_{22} measurements at IR or CR

Figure G.20 shows the conditions for making S_{22} measurements of the interconnect attached to the receiver device.

This measurement has both the interconnect and the transmitter device in place when the combination is measured. This may be considered a reverse direction signal tolerance measurement. If the transmitter device is replaced by an ideal load, then S_{22} does not represent in-service conditions. If the interconnect is very lossy, then the effects of the load on the far end (i.e., where the transmitter device is located) are not significant and an ideal load may be used. However, if the interconnect is not very lossy (e.g., the zero-length test load), then the measured S_{22} may be dominated by the properties of the transmitter device and not the properties of the interconnect.

For short physical links, S_{22} may be the limiting factor for the entire physical link due to severe unattenuated reflections that create large DJ.

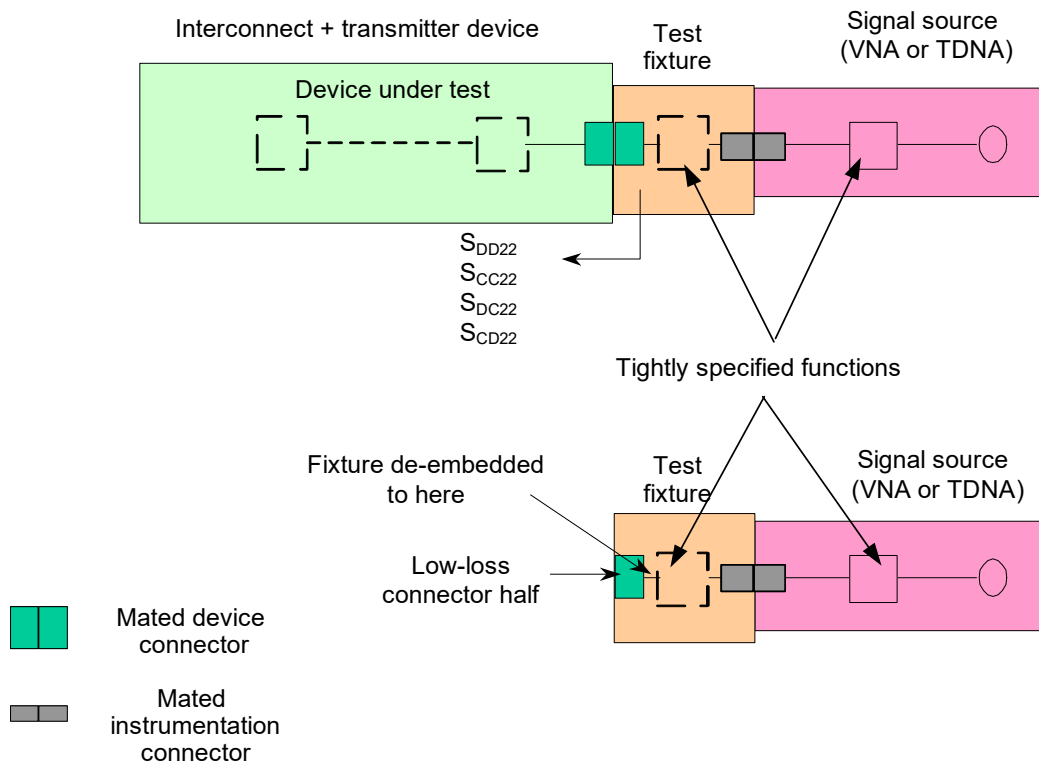


Figure G.20 — Measurement conditions for S_{22} at IR or CR

G.12 Calibration of JMDs

G.12.1 Calibration of JMDs overview

G.12.1.1 Purpose of JMD calibration

The response of a JMD to known jitter levels is calibrated and verified in two frequency bands:

- the lower frequency band; and
- the frequency band around the -3 dB frequency and the peak frequency of the JTF.

By calibrating the JMD to these two bands, the response to jitter is calibrated and allows for improved correlation among JMDs.

The test sequence for all measurements removes the baseline DJ, the DJ of the source, and the DJ of the JMD so that the measurement only reports the added test jitter.

G.12.1.2 Overview of low frequency calibration for SSC configurations

For configurations supporting SSC, the lower frequency band requirement is tested with a repeating 0011b pattern or 1100b pattern (e.g., D24.3) on which a sinusoidal phase modulation of 30 kHz with a relative tolerance of 1 % is added. The amplitude of this modulation is 20.83 ns peak to peak. The ratio of the reported jitter to the amount applied is the attenuation (see 5.8.3.2).

This calibration procedure ensures that the measurement equipment responds properly to the fundamental characteristics of the JTF.

For any SSC modulation, there are three important characteristics that affect the response of the JMD and the ability to generate jitter:

- a) the peak to peak phase excursion experienced through an SSC cycle;
- b) the extreme instantaneous frequency modulation; and
- c) the extreme instantaneous frequency modulation rate.

The peak to peak phase excursion experienced through an SSC cycle is an important parameter for jitter generating equipment.

The extreme instantaneous frequency modulation stresses the ability of the JMD to track large frequency modulation. All systems have practical limitations beyond which the response changes shape (e.g. the system response becomes 20 dB/decade instead of 40 dB/decade). The amplitude of the peak to peak frequency modulation under which the JMD maintains a 40 dB/decade response indicates the JMD's limitation to behave as a linear system.

The extreme instantaneous frequency modulation rate (e.g., the minimal negative and maximal positive) stresses the ability of the JMD to respond with the 40 dB/decade low frequency JTF slope specified by this standard. The remaining jitter, after being filtered by the JTF, is proportional to the extreme frequency modulation rate. The maximal amount of remaining jitter a JMD reports is a direct indication of its linear performance in the expected 40 dB/decade response region.

An example of an SSC profile is a balanced triangular SSC waveform (e.g., $\pm 2\ 300$ ppm).

In this calibration procedure, a sinusoidal phase modulation is applied. Even though this modulation is defined as a phase modulation, its variation in time makes it equivalent to a frequency modulation having comparable characteristics to that of a triangular SSC profile.

The triangular SSC profile is defined by the following equations.

For $k/f_m \leq t < (k+0.5)/f_m$:

$$\Delta f(t) = f_{\text{baud}} \times \text{mod_max} \times (-1 + \text{modulo}(t, 1/f_m) \times f_m \times 4) \text{ Hz}$$

and for $(k+0.5)/f_m \leq t < (k+1)/f_m$:

$$\Delta f(t) = f_{\text{baud}} \times \text{mod_max} \times (3 - \text{modulo}(t, 1/f_m) \times f_m \times 4) \text{ Hz}$$

where:

$\Delta f(t)$	is the frequency deviation in Hz;
f_{baud}	is the baud rate (e.g., 6 GHz for 6 Gbit/s) (see 5.8.1);
mod_max	is the peak excursion of the frequency modulation as a ratio of the current baud rate (e.g., 2.3×10^{-3} for a $\pm 2\ 300$ ppm modulation);
$\text{modulo}(t, 1/f_m)$	modulo operator, the result is $x \text{ modulo } y$ and limited to range $[0, y]$;
f_m	is the modulation frequency in Hz; and
k	is an integer.

The bit transitions are expected to happen for t where the following equation reaches any integer value m :

$$(f_{\text{baud}} + \Delta f(t)) \times t = m$$

where the characteristics for this pattern are:

- a) peak to peak phase excursion = $2 \times \pi \times \text{mod_max} \times f_{\text{baud}} / (4 \times f_m)$ radians (or peak to peak time excursion = $\text{mod_max} / (4 \times f_m)$ seconds);
- b) extreme instantaneous frequency modulation = $\pm \text{mod_max} \times f_{\text{baud}}$ Hz; and
- c) extreme instantaneous frequency modulation rate = $\pm 4 \times \text{mod_max} \times f_m \times f_{\text{baud}}$ Hz/s (or $\pm 4 \times \text{mod_max} \times f_m$ ppm/ μ s).

A sinusoidal phase modulation is defined by:

$$PJ(t) = A_{ppu}/2 \times \sin(2 \times \pi \times f_{ms} \times t) \text{ UI}$$

where:

A_{ppu} is the peak to peak modulation in UI; and
 f_{ms} is the frequency of the phase modulation in Hz.

This is equivalent to A_{pps} , the peak to peak time modulation in seconds, knowing that:

$$A_{pps} = A_{ppu}/f_{baud}$$

The bit transitions are expected to happen for t where the following equation reaches any integer value n :

$$f_{baud} \times t + PJ(t) = n$$

where the characteristics for this pattern are:

- peak to peak phase excursion = $2 \times \pi \times A_{pps} \times f_{baud}$ radians (or A_{ppu} UI);
- extreme instantaneous frequency modulation = $\pm \pi \times A_{pps} \times f_{baud} \times f_{ms}$ Hz; and
- extreme instantaneous frequency modulation rate = $\pm 2 \times (\pi \times f_{ms})^2 \times A_{pps} \times f_{baud}$ Hz/s
 (or $\pm 2 \times (\pi \times f_{ms})^2 \times A_{pps}$ ppm/ μ s).

The JMD calibration procedure uses sinusoidal phase modulation where:

- $A_{pps} = 20.83$ ns; and
- $f_{ms} = 30$ kHz.

By comparing the equations of the characteristics, it is possible to compute the parameters of the equivalent triangular SSC profile to the prescribed sinusoidal phase modulation. Defining that $f_m = f_{ms} = 30$ kHz the equivalent:

- peak to peak phase excursion of the sinusoidal phase modulation (i.e., 20.83 ns) corresponds to a triangular SSC profile having a mod_max parameter of $\pm 2\,500$ ppm;
- extreme instantaneous frequency modulation of the sinusoidal phase modulation (i.e., 11.78 UI/ μ s) to a triangular SSC profile having a mod_max parameter of $\pm 1\,963$ ppm; and
- extreme instantaneous frequency modulation rate of the sinusoidal phase modulation (i.e., 370 ppm/ μ s) corresponds to a triangular SSC profile having a mod_max parameter of $\pm 3\,084$ ppm.

As a result, using a sinusoidal jitter with a 20.83 ns peak to peak excursion at 30 kHz produces a modulation with fundamental parameters balanced around the specified maximal $\pm 2\,300$ ppm amplitude of the SSC profile at a modulation rate of 30 kHz.

G.12.1.3 Overview of low frequency calibration for non-SSC configurations

For configurations not supporting SSC, the lower frequency band requirement is tested with a repeating 0011b pattern or 1100b pattern (e.g., D24.3) at the desired baud rate on which sinusoidal phase modulation is added. The ratio of the jitter applied to the jitter reported is the attenuation.

Unlike the SSC supported cases, there is no specific frequency defined for this measurement. It is recommended to verify the attenuation using PJ at a frequency 10 times below the -3 dB frequency (e.g., 360 kHz for 6 Gbit/s, or 720 kHz for 12 Gbit/s). The phase modulation amplitude used for these tests is calibrated to be 3 UI peak to peak at the current baud rate, which is 20 dB more than the 0.3 UI used at high frequency (see G.12.1.4).

G.12.1.4 High frequency calibration

The calibration described in this subclause applies for all configurations, independent of SSC support.

To do a high frequency calibration, two tests are performed in the higher frequency band:

- adjustment of the -3 dB bandwidth of the JTF; and
- verification of the peaking (see 5.8.3.2).

Both of these tests use a repeating 0011b pattern or 1100b pattern (e.g., D24.3) with sinusoidal periodic phase modulation or PJ that has been independently verified to produce 0.3 UI with a relative tolerance of 10 % peak to peak at the baud rate being tested over a frequency range of 0.5 MHz to 50 MHz. This corresponds to the values in table G.3.

Table G.3 — High frequency jitter source amplitudes

Baud rate (Gbit/s)	Peak to peak jitter for high frequency test (ps)	Tolerance (ps)	Range (MHz)
6	50	± 5	0.5 to 50
12	25	± 2.5	0.5 to 50

The programmed source PJ level may vary over the frequency range in order to keep the generated PJ at 0.3 UI with a relative tolerance of 10 %.

There are two typical JMD adjustments for clock recovery:

- a) loop bandwidth; and
- b) peaking (i.e., damping).

These adjustments may refer to the closed loop response or be specific to a particular design, so they are not used directly to ensure the JTF response to jitter. The loop bandwidth is initially adjusted with the peaking fixed. If both the low frequency band requirements and the high frequency band requirements are not able to be simultaneously met, then the peaking is adjusted to modify the JTF shape in the upper band. In the case of hardware based reference clocks, moderate levels of peaking may be needed to achieve the proper attenuation at 30 kHz. The peaking setting is usually specific to the JMD. With software based clock recovery, the suggested starting peaking level may be low, close to the critically damped condition of peaking of 0.707.

G.12.2 JMD calibration procedure

G.12.2.1 General characteristics and equipment

This calibration procedure is based on the JTF characteristics defined in 5.8.3.2 for:

- a) the -3 dB corner frequency of the JTF;
- b) the magnitude peaking of the JTF;
- c) the attenuation at 30 kHz when SSC is supported; and
- d) the low frequency attenuation when SSC is not supported.

The required JMD calibration equipment for configurations supporting SSC is as follows:

- a) a pattern generator for SAS signals;
- b) a sine wave source of 30 kHz;
- c) test cables; and
- d) a JMD.

The JMD calibration equipment is as follows:

- a) a pattern generator for SAS signals;
- b) a sine wave source covering the range from 90 kHz to 360 kHz;
- c) a sine wave source covering the range from 0.5 MHz to 50 MHz;
- d) test cables; and
- e) a JMD.

The response to jitter of the JMD is measured with three different jitter modulation frequencies corresponding to the three cases:

- a) low frequency jitter (i.e., the JMD fully tracks);
- b) high-frequency jitter (i.e., the JMD does not track); and
- c) the boundary between low-frequency jitter and high-frequency jitter.

The jitter source is independently verified by separate means to ensure that the jitter response of the JMD is reproducible across different test setups.

The JMD calibration pattern is a square wave at $0.25 \times f_{\text{baud}}$ with a relative tolerance of 0.01 % (i.e., a repeating 0011b pattern or 1100b pattern (e.g., D24.3)) with rise time longer than 0.25 UI measured from 20 % to 80 % of the transition.

When testing 6 Gbit/s or 12 Gbit/s, a repeating 0011b pattern or 1100b pattern (e.g., D24.3) at 6 Gbit/s is used. This applies to all jitter frequencies.

An independent, separate means of verification of the JMD calibration pattern is used to ensure that the level of the modulation is correct.

G.12.2.2 Calibration of the JMD for testing SSC configurations

This procedure checks the JTF attenuation and the JTF bandwidth for testing configurations with training and SSC support.

The following test procedure is performed for each baud rate tested (e.g., 6 Gbit/s and 12 Gbit/s as applicable):

- 1) set the pattern generator to output the JMD calibration pattern with a sinusoidal phase modulation of 20.8 ns with a relative tolerance of 10 % peak to peak at 30 kHz with a relative tolerance of 1 %;
- 2) verify the level of modulation meets the requirements and record the peak to peak level as DJ_SSC (e.g., the independent, separate means of verification of the 30 kHz test signal is equivalent to a frequency demodulator or wide range phase demodulator) measured with:
 - A) a time interval error plot with constant frequency clock on a real time oscilloscope;
 - B) an equivalent time oscilloscope; or
 - C) a frequency demodulator;
- 3) apply the test signal to the JMD, turn off the sinusoidal phase modulation, record the reported DJ as DJ_SSCOFF;
- 4) turn on the sinusoidal phase modulation. Record the reported DJ as DJ_SSCON;
- 5) calculate and record the reported DJ as DJ_MSSC by subtracting the DJ with modulation off from DJ with modulation on (i.e., $DJ_MSSC = DJ_SSCON - DJ_SSCOFF$), calculate the jitter attenuation by $20 \times \log_{10}(DJ_MSSC / DJ_SSC)$, adjust the JMD settings so the value falls within the range specified in 5.8.3.2 for the selected baud rate;
- 6) set the pattern generator to output the JMD calibration pattern with sinusoidal phase modulation of 0.3 UI with a relative tolerance of 10 % peak to peak over a frequency range of 0.5 MHz to 50 MHz for the selected baud rate (see table G.3);
- 7) verify the level of modulation meets the requirements and record the peak to peak level as DJ_M (e.g., the independent verification of the 50 MHz test signal is a jitter measurement by separate means from the JMD under calibration) measured with:
 - A) a time interval error plot with constant frequency clock on a real time oscilloscope;
 - B) an equivalent time oscilloscope with histogram and constant frequency clock;
 - C) a bit error rate tester (BERT) using a constant frequency clock; or
 - D) a spectral analysis with the Bessel expansion of angle modulated sidebands;
- 8) apply the test signal to the JMD, turn off the sinusoidal phase modulation, record the reported DJ as DJ_MOFF;
- 9) turn on the sinusoidal phase modulation, record the reported DJ as DJ_MON;
- 10) calculate the following:
 - A) the difference in reported DJ (i.e., $DJ_MM = DJ_MON - DJ_MOFF$); and
 - B) the -3 dB value (i.e., $DJ_3DB = DJ_MM \times 0.707$);
- 11) adjust the frequency of the PJ source to the specified -3 dB frequency for the baud rate being tested per table 41, measure the reported DJ difference between PJ on versus PJ off (i.e., $DJ = DJ_ON - DJ_OFF$) and compare DJ to DJ_3DB. Shift the frequency of the PJ source until the reported DJ difference between PJ on and PJ off is equal to DJ_3DB. The PJ frequency is the -3 dB bandwidth of the JTF, record this value as F_3DB;
- 12) adjust the JMD settings to bring F_3DB to the corner frequency specified in table 41 for the baud rate being tested;

- 13) repeat steps 4) through 12) until both the jitter attenuation and -3 dB frequency are in the acceptable ranges;
- 14) check the peaking of the JTF, set the pattern generator to output the JMD calibration pattern with sinusoidal phase modulation of 0.3 with a relative tolerance of 10 % UI peak to peak at F_3DB, increase the frequency of the modulation to find the maximum reported DJ (i.e., it is not necessary to increase beyond 20 MHz), measure the reported DJ difference between PJ on versus PJ off as $DJ_PK = DJ_PKON - DJ_PKOFF$; and
- 15) calculate the JTF Peaking value: $20 \times \log_{10}(DJ_PK / DJ_MM)$, verify that the peaking is below the limits set in 5.8.3.2, if peaking is above the limits repeat the procedure until all specifications are met.

G.12.2.3 Calibration of the JMD for testing non-SSC configurations

This test procedure verifies the JTF attenuation and the JTF bandwidth for SAS devices that:

- a) support training with no SSC support; or
- b) do not support training.

This procedure is performed for each baud rate tested (e.g., 6 Gbit/s and 12 Gbit/s as applicable):

- 1) set the pattern generator to output the JMD calibration pattern with a sinusoidal phase modulation of 1.5 UI with a relative tolerance of 10 % peak to peak at $f_{baud}/33.333$ kHz (see table G.4);
- 2) verify the level of modulation meets the requirements and record the peak to peak level as DJ_LF (e.g., the independent, separate means of verification of the low frequency test signal is equivalent to a frequency demodulator or wide range phase demodulator), measured with:
 - A) continuously gated frequency counter;
 - B) a time interval error plot with constant frequency clock on a real time oscilloscope;
 - C) an equivalent time oscilloscope; or
 - D) a frequency demodulator;
- 3) apply the test signal to the JMD, turn off the sinusoidal phase modulation, record the reported DJ as DJ_LFOFF;
- 4) turn on the sinusoidal phase modulation, record the reported DJ as DJ_LFON;
- 5) calculate and record the reported DJ as DJ_MLF by subtracting the DJ with modulation off from DJ with modulation on (i.e., $DJ_MLF = DJ_LFON - DJ_LFOFF$), calculate the jitter attenuation by $20 \times \log_{10}(DJ_MLF / DJ_LF)$, adjust the JMD settings so the attenuation value falls within the range specified in table G.5; and
- 6) continue with the high frequency tests of the corner frequency and peaking by following steps 6) through 15) in G.12.2.2, repeat this procedure until all specifications are met.

Table G.4 — Low frequency jitter source calibration amplitudes

Baud rate (Gbit/s)	Phase modulation frequency (kHz)	Peak to peak modulation (UI)	Peak to peak modulation (ns)	Modulation tolerance
6	180	1.5	0.25	± 0.15
12	360	1.5	0.125	± 0.15

Table G.5 — Low frequency jitter attenuation targets

Baud rate (Gbit/s)	Phase modulation frequency (kHz)	Peak to peak modulation (UI)	Target attenuation (dB) ^{a b}	Target attenuation tolerance (dB)
6	180	1.5	26	± 1.5
12	360	1.5	26	± 1.5

^a Target Attenuation = $20 \times \log_{10}((f / f_c) / (1 + (f / f_c)^2)^{0.5})$, where f_c is the -3 dB frequency.
^b This is derived from a nominal first-order frequency response.

Annex H (Informative)

Description of the included Touchstone models for trained 6 Gbit/s

H.1 Description of the included Touchstone models for trained 6 Gbit/s overview

Touchstone models for trained 6 Gbit/s are included with this standard to represent:

- reference transmitter device termination (see 5.8.4.5.5 and H.2);
- reference receiver device termination (see 5.8.5.7.3 and H.3); and
- reference transmitter test load (see 5.6.4 and H.5).

Figure H.1 shows the circuit models used to create the Touchstone models of reference transmitter device termination and reference receiver device termination.

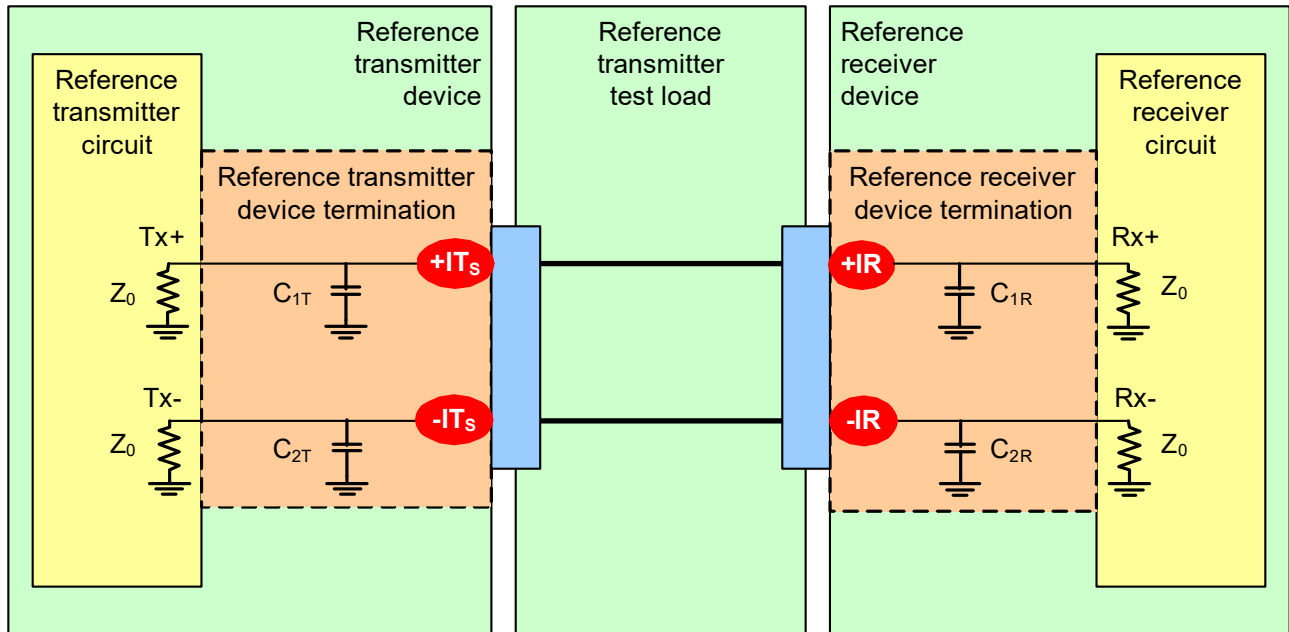


Figure H.1 — Reference transmitter device and reference receiver device termination circuit model

H.2 Reference transmitter device termination model for trained 6 Gbit/s

From the circuit model shown in figure H.1, the S-parameters of the reference transmitter device termination for trained 6 Gbit/s were derived using the following calculations:

$$\tau_1 = \frac{Z_0 \times C_{1T}}{2}$$

$$\tau_2 = \frac{Z_0 \times C_{2T}}{2}$$

$$S_{11} = \frac{-s \times \tau_1}{1 + (s \times \tau_1)}$$

$$S_{12} = 0$$

$$S_{22} = \frac{-s \times \tau_2}{1 + (s \times \tau_2)}$$

$$S_{DDij} = S_{CCij} = \frac{S_{11} + S_{22}}{2}$$

$$S_{CDij} = S_{DCij} = \frac{S_{11} - S_{22}}{2}$$

where:

- τ_1 is the Tx+ termination time constant;
- τ_2 is the Tx- termination time constant;
- Z_0 is the impedance as specified by this standard (i.e., 50 Ω);
- C_{1T} is the Tx+ termination capacitance; and
- C_{2T} is the Tx- termination capacitance.

Figure 126 (see 5.8.4.5.5) shows the graph of the S-parameters based on the following values:

- a) Z_0 is set to 50 Ω ;
- b) C_{1T} is set to 0.5 pF, so τ_1 becomes 12.5 ps; and
- c) C_{2T} is set to 2 pF, so τ_2 becomes 50 ps.

H.3 Reference receiver device termination model for trained 6 Gbit/s

From the circuit model shown in figure H.1, the S-parameters of the reference receiver device termination for trained 6 Gbit/s were derived using the following calculations:

$$\tau_1 = \frac{Z_0 \times C_{1R}}{2}$$

$$\tau_2 = \frac{Z_0 \times C_{2R}}{2}$$

$$S_{11} = \frac{-s \times \tau_1}{1 + (s \times \tau_1)}$$

$$S_{12} = 0$$

$$S_{22} = \frac{-s \times \tau_2}{1 + (s \times \tau_2)}$$

$$S_{DDij} = S_{CCij} = \frac{S_{11} + S_{22}}{2}$$

$$S_{CDij} = S_{DCij} = \frac{S_{11} - S_{22}}{2}$$

where:

- τ_1 is the Rx+ termination time constant;
- τ_2 is the Rx- termination time constant;
- Z_0 is the impedance as specified by this standard (i.e., 50 Ω);
- C_{1R} is the Rx+ termination capacitance; and
- C_{2R} is the Rx- termination capacitance.

Figure 144 shows the graph of the S-parameters based on the following values:

- a) Z_0 is set to 50 Ω ;
- b) C_{1R} is set to 2 pF, so τ_1 becomes 50 ps; and
- c) C_{2R} is set to 0.5 pF, so τ_2 becomes 12.5 ps.

H.4 Generic return loss circuit model for trained 6 Gbit/s

Figure H.2 shows a generic circuit model for return loss for trained 6 Gbit/s, upon which the circuit models for transmitter device termination in H.2 and receiver device termination in H.3 are based.

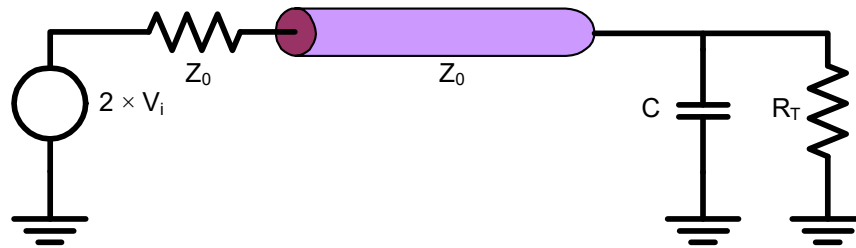


Figure H.2 — Generic return loss circuit model

$|S_{11}|$ (i.e., negative return loss) may be derived by defining points on a curve using the following calculations:

$$LF = 20 \times \log_{10} \left(\frac{\text{tol}}{2 + \text{tol}} \right)$$

$$R_T = Z_0 \times (1 + \text{tol})$$

$$F_{\text{zero}} = \frac{\text{tol}}{(2 \times \pi \times R_T \times C \times (1 + \text{tol}))}$$

$$F_{\text{pole}} = \frac{2 + \text{tol}}{(2 \times \pi \times R_T \times C \times (1 + \text{tol}))}$$

where:

- LF is the low frequency asymptote of $|S_{11}|$;
- tol is the tolerance of R_T ;
- Z_0 is the impedance specified by this standard (i.e., 50 Ω);
- R_T is the far end load;
- C is the far end capacitance;
- F_{zero} is the frequency at which a 20 dB/decade asymptote intersects the LF asymptote; and
- F_{pole} is the frequency at which a 20 dB/decade asymptote intersects the 0 dB asymptote.

Because the effects of the far end load are not significant, the equations may be simplified as follows:

$$LF \sim 20 \times \log_{10}\left(\frac{tol}{2}\right)$$

$$F_{zero} \sim \frac{tol}{(2 \times \pi \times R_T \times C)}$$

$$F_{pole} \sim \frac{1}{(\pi \times R_T \times C)}$$

Using the simplified equations, $|S_{11}|$ may be derived from LF, F_{zero} , and F_{pole} as shown in figure H.3.

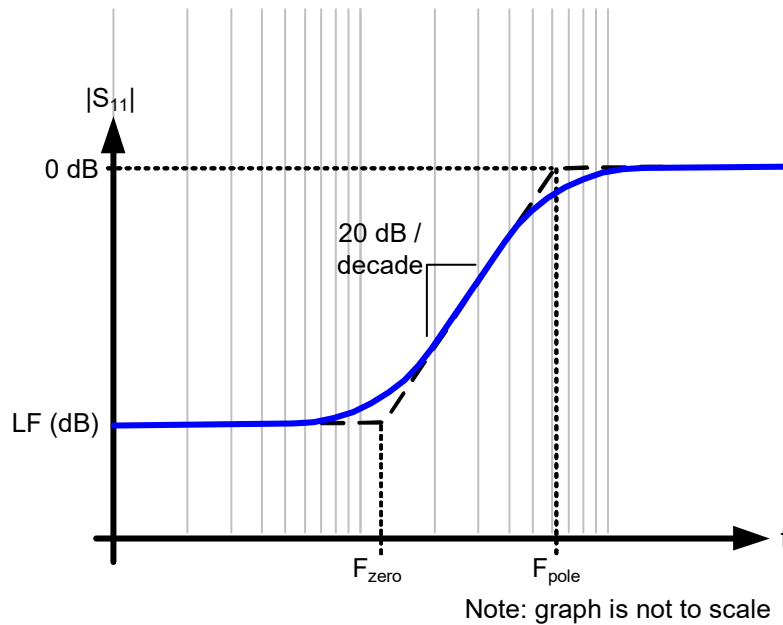


Figure H.3 — Generic return loss model $|S_{11}|$

H.5 Reference transmitter test load for trained 6 Gbit/s

The Touchstone model of the reference transmitter test load for trained 6 Gbit/s (see 5.6.4) is based on physical measurements.

The following components of a TxRx connection were measured:

- an etch length of 50.8 mm with an etch width of 177.8 μm between IT_S (see 5.3.2) and the Mini SAS 4x cable plug in a Nelco[®] 4000-13 material environment. This etch is part of the transmitter device;
- a 10 m Mini SAS 4x cable assembly using 24 AWG solid wire from pin B5 to pin A5 and from pin B6 to pin A6; and
- an etch length of 50.8 mm with an etch width of 177.8 μm between IR (see 5.3.2) and the Mini SAS 4x cable plug in a Nelco[®] 4000-13 material environment. This etch is part of the receiver device.

NOTE 14 - Nelco[®] 4000-13 material is a product supplied by Park Electrochemical Corporation. This information is given for the convenience of users of this standard and does not constitute an endorsement by IEC, ISO, ISO/IEC, or ANSI. Equivalent products are acceptable if they lead to the same results.

Although the etches between the transmission points and probe points add extra loss to the TxRx connection, they are considered to be an acceptable amount of loss for simulation purposes.

The following list of equipment was used to perform the measurement:

- Agilent N1957B Physical Layer Test System (PLTS), including:

- A) Agilent E8364B PNA Network Analyzer (10 MHz to 50 GHz);
 - B) Agilent N4421B S-parameter Test Set (10 MHz to 50 GHz); and
 - C) Agilent N1930B Physical Layer Test System Software version 3.01;
- and

- b) Molex 26-circuit External iPass™ Test Fixture (PCB 73931-2540).

NOTE 15 - The Agilent Technologies® Corporation and Molex® equipment are examples of a suitable product(s) available commercially. iPass™ is a product supplied by Molex Incorporated. This information is given for the convenience of users of this standard and does not constitute an endorsement by IEC, ISO, ISO/IEC, or ANSI of these products. Equivalent products are acceptable if they lead to the same results.

The equipment was interconnected as shown in figure H.4.

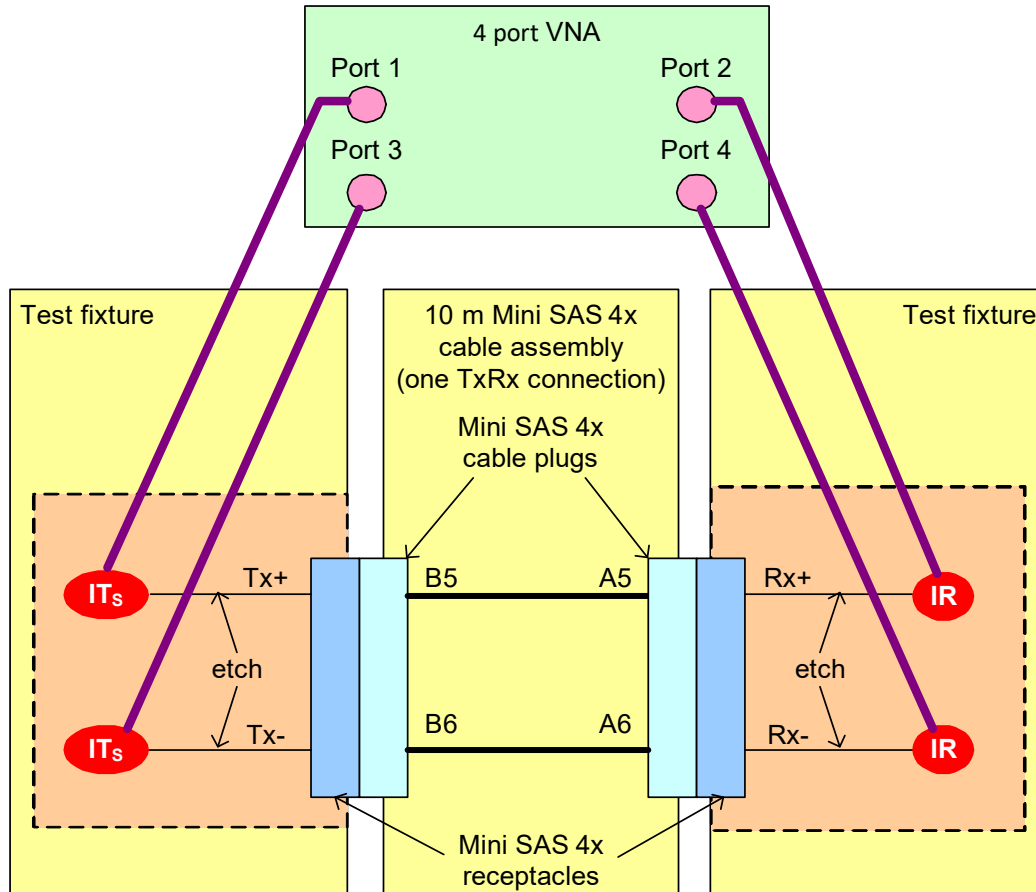


Figure H.4 — Reference transmitter test load measurement setup

The Short-Open-Load-Through (SOLT) calibration procedure should be run before generating the S-parameters.

Samples were taken from 10 MHz to 20 GHz in 1 MHz steps.

Figure 110 shows the graph of the reference transmitter test load $|S_{DD21}(f)|$ up to 6 GHz.

Figure H.5 shows the reference transmitter test load $|S_{DD21}(f)|$ up to 20 GHz.

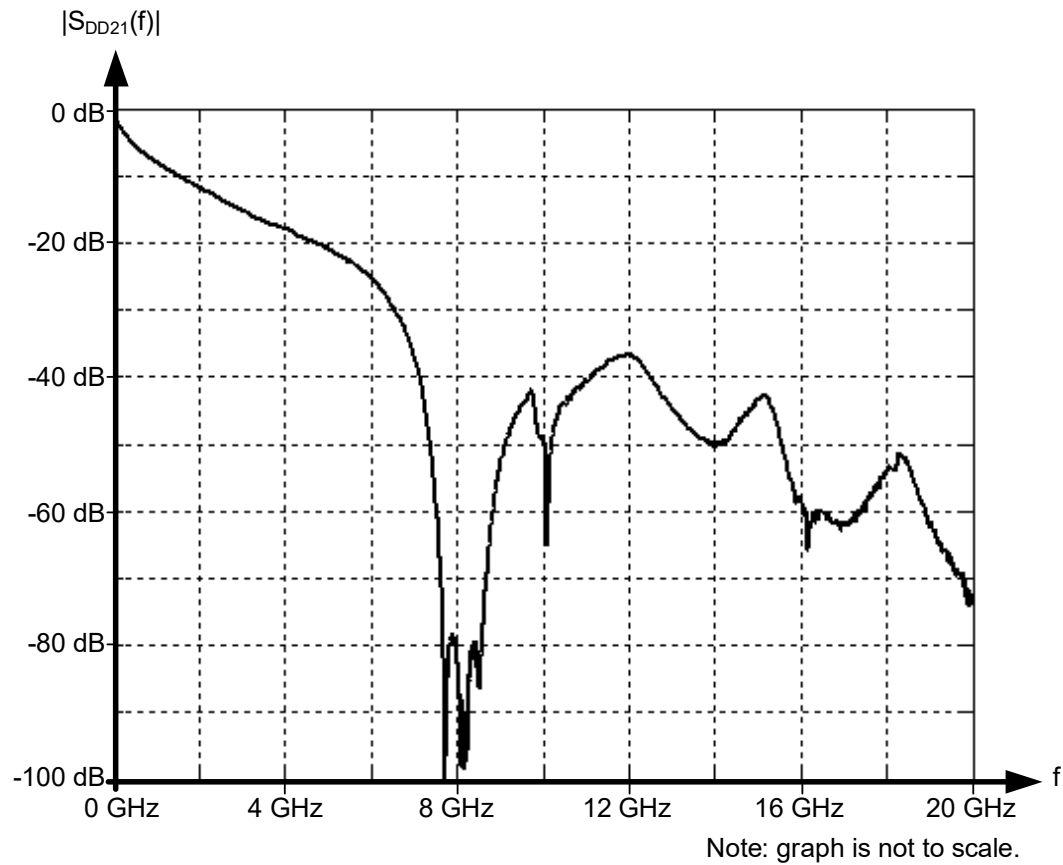


Figure H.5 — Reference transmitter test load $|S_{DD21}(f)|$ up to 20 GHz

Annex I

(Informative)

Recommended electrical performance limits for mated connector pairs supporting rates of 12 Gbit/s

The recommended electrical performance limits for connector mated pairs supporting rates of 12 Gbit/s are defined in table I.1 and shown in figure I.1.

Table I.1 — Recommended electrical performance limits for mated connector pairs supporting rates of 12 Gbit/s

Characteristic ^{a b}	Units	Value
Maximum near-end crosstalk (NEXT) for each signal pair ^{c d}	dB	-39
Maximum far-end crosstalk (FEXT) for each signal pair ^{c d}	dB	-39
Maximum S _{DD22}	dB	-12
Maximum S _{CC22}	dB	-3.0
Minimum S _{DD21}	dB	-1.0
<p>^a All measurements apply to connector mated pairs supporting rates of 12 Gbit/s and include the mounting footprint or wire termination.</p> <p>^b All characteristic values apply to the frequency range from 100 MHz to 6 000 MHz. The measurement output should include results to a minimum of 20 GHz.</p> <p>^c Determine all near-end and far-end significant crosstalk transfer modes. The sum of the crosstalk transfer ratios is measured in the frequency domain. The following equation details the summation process of the valid near-end crosstalk sources:</p> $\text{TotalNEXT}(f) = 10 \times \log_{10} \sum_{1}^n 10^{(\text{NEXT}(f)/10)}$ <p>where: f frequency; and n number of the near-end crosstalk source.</p> <p>All NEXT values expressed in dB format in a passive transfer network shall have negative dB magnitude.</p> <p>The following equation details the summation process of the valid far-end crosstalk sources:</p> $\text{TotalFEXT}(f) = 10 \times \log_{10} \sum_{1}^n 10^{(\text{FEXT}(f)/10)}$ <p>where: f frequency; and n number of the far-end crosstalk source.</p> <p>All FEXT values expressed in dB format in a passive transfer network shall have negative dB magnitude.</p> <p>^d Total TxRx connection crosstalk should be at least 15 dB less than its total insertion loss. A total TxRx connection crosstalk of -39 dB implies an acceptable TxRx connection total insertion loss of 24 dB as shown in figure C.1.</p>		

Figure I.1 shows the recommended |S_{DD21}|, |S_{CC22}|, |S_{DD22}|, NEXT, and FEXT limits for connector mated pairs supporting rates of 12 Gbit/s.

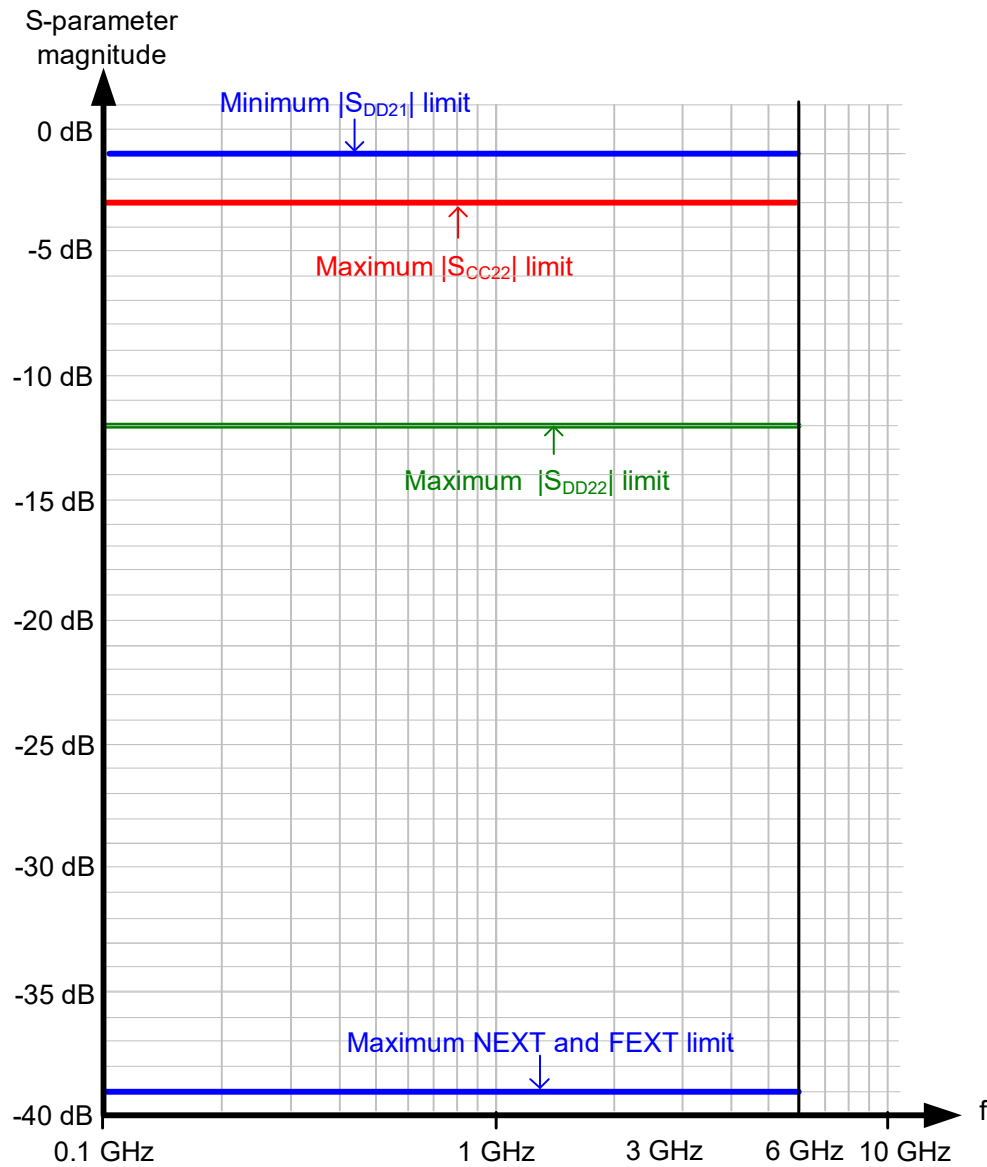


Figure I.1 — Recommended $|S_{DD21}|$, $|S_{CC22}|$, $|S_{DD22}|$, NEXT, and FEXT limits for connector mated pairs supporting rates of 12 Gbit/s

Annex J

(Informative)

Recommended electrical performance limits for mated connector pairs and cable assemblies supporting rates of 22.5 Gbit/s

Recommended electrical characteristics for connector mated pairs supporting rates of 22.5 Gbit/s are defined in table J.1 and table J.3, and illustrated in figure J.1, figure J.2, figure J.3, and figure J.4. The characteristics include the test fixtures in addition to the mated connector pair. The test fixtures should comply with the electrical characteristics defined in table J.4.

Table J.1 defines the recommended electrical characteristics for connector mated pairs supporting rates of 22.5 Gbit/s. The recommended electrical performance characteristics for cable assemblies supporting rates of 22.5 Gbit/s should comply with electrical TxRx connection electrical characteristics defined in 5.5.7. These electrical characteristics include test fixtures in addition to the mated cable assembly. The test fixtures should comply with the electrical characteristics defined in table J.4. The recommended insertion loss of the mated cable assembly without test fixtures (i.e., IT_S to IR or CT_S to CR) at Nyquist should not exceed 20 dB (see figure 93).

Table J.1 — Recommended electrical characteristic limits for mated connector pairs supporting rates of 22.5 Gbit/s

Characteristic ^a	Equation	Units	Range
Minimum S _{DD21} (f) ^b	$-0.08\sqrt{f/1\times10^9} - 0.336(f/1\times10^9)$	dB	$0.05\text{ GHz} \leq f \leq \left(\frac{3}{4}\right)f_{\text{baud}}$
Maximum S _{DD21} (f) ^b	$-0.12 - 0.475\sqrt{f/1\times10^9} - 0.364(f/1\times10^9)$	dB	$0.05\text{ GHz} \leq f \leq \left(\frac{3}{4}\right)f_{\text{baud}}$
Maximum S _{DD22} (f) ^{c d}	$-20\log_{10}[W(f)^{0.353}] - 12$	dB	$0.05\text{ GHz} \leq f \leq \left(\frac{3}{4}\right)f_{\text{baud}}$
Maximum S _{CD21} (f) ^e	$\begin{cases} -25 + 20\left(\frac{f}{f_{\text{baud}}}\right) \\ -18 + 6\left(\frac{f}{f_{\text{baud}}}\right) \end{cases}$	dB	$\begin{cases} 0.05\text{ GHz} \leq f \leq \frac{f_{\text{baud}}}{2} \\ \frac{f_{\text{baud}}}{2} < f \leq \left(\frac{3}{4}\right)f_{\text{baud}} \end{cases}$
Maximum S _{CD22} (f) ^f	$\begin{cases} -25 + 20\left(\frac{f}{f_{\text{baud}}}\right) \\ -18 + 6\left(\frac{f}{f_{\text{baud}}}\right) \end{cases}$	dB	$\begin{cases} 0.05\text{ GHz} \leq f \leq \frac{f_{\text{baud}}}{2} \\ \frac{f_{\text{baud}}}{2} < f \leq \left(\frac{3}{4}\right)f_{\text{baud}} \end{cases}$
^a These characteristics apply to all Tx pairs. ^b See figure J.1. ^c See figure J.2. ^d See F.2 for the definition of W(f). ^e See figure J.3. ^f See figure J.4.			

Figure J.1 shows the recommended $|S_{DD21}|$ limits for connector mated pairs supporting rates of 22.5 Gbit/s.

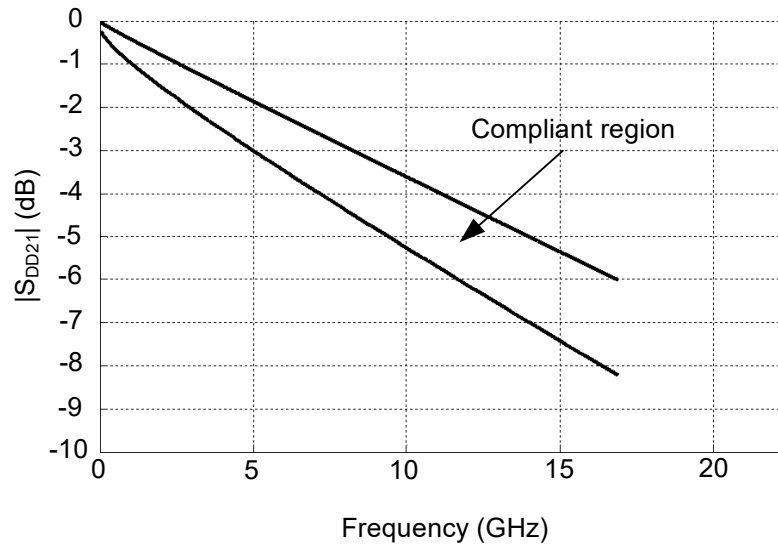


Figure J.1 — Recommended $|S_{DD21}|$ limits for connector mated pairs supporting rates of 22.5 Gbit/s

Figure J.2 shows the recommended $|S_{DD22}|$ limit for connector mated pairs supporting rates of 22.5 Gbit/s.

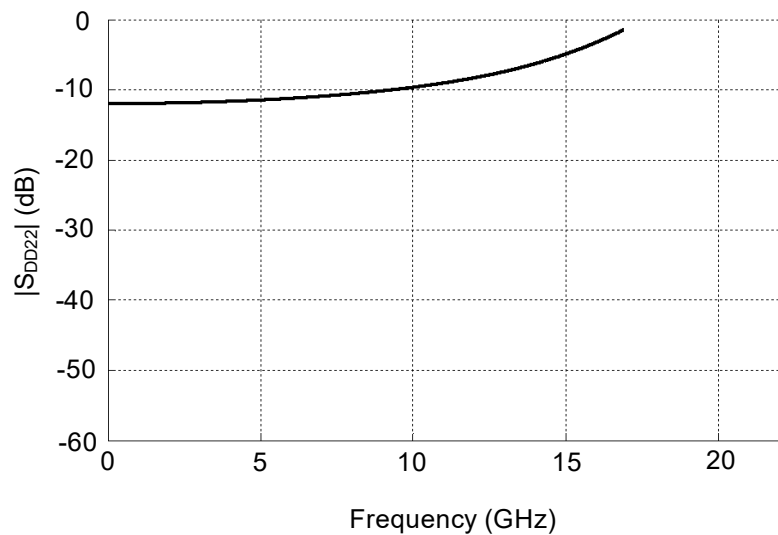


Figure J.2 — Recommended $|S_{DD22}|$ limit for connector mated pairs supporting rates of 22.5 Gbit/s

Figure J.3 shows the recommended $|S_{CD21}|$ limit for connector mated pairs supporting rates of 22.5 Gbit/s.

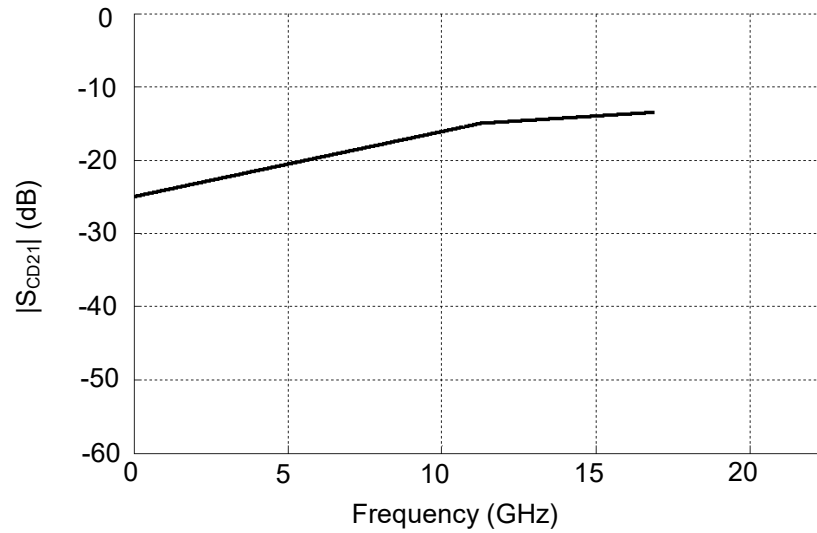


Figure J.3 — Recommended $|S_{CD21}|$ limit for connector mated pairs supporting rates of 22.5 Gbit/s

Figure J.4 shows the recommended $|S_{CD22}|$ limit for connector mated pairs supporting rates of 22.5 Gbit/s.

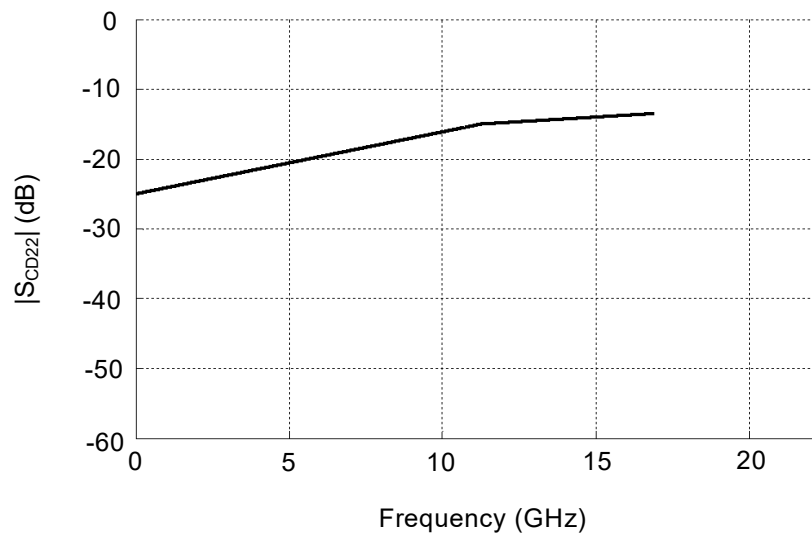


Figure J.4 — Recommended $|S_{CD22}|$ limit for connector mated pairs supporting rates of 22.5 Gbit/s

Table J.2 defines the variables for calculating the mated connector pair ICN as defined in F.3.

Table J.2 — Mated connector pair ICN variables supporting rates of 22.5 Gbit/s

Variable	Symbol	Units	Minimum	Nominal	Maximum
Frequency range	f	GHz	0.05 ^a		16.875 ^b
Baud rate	f_{baud}	Gigasymbols/s		22.5	
Near end aggressor output amplitude	A_{nt}	mV(P-P)			1 200
Far end aggressor output amplitude	A_{ft}	mV(P-P)			1 200
Near end aggressor 20 % to 80 % rise/fall time	T_{nt}	ps	11		
Far end aggressor 20 % to 80 % rise/fall time	T_{ft}	ps	11		
^a This value equals f_{min} . ^b This value equals f_{max} and is $(3/4) f_{\text{baud}}$ for 22.5 Gbit/s.					

Table J.3 defines the recommended ICN limits for mated connector pairs supporting rates of 22.5 Gbit/s.

Table J.3 — Recommended ICN limits for mated connector pairs supporting rates of 22.5 Gbit/s

Connector type ^a	Value ^b
SAS Drive connectors	3.5 mV rms
All other SAS connectors	3 mV rms
^a See table 4 for the list of SAS connectors by connector type. ^b Applies to all Rx pairs.	

The test fixture with plug (TFP) etch insertion loss and test fixture with receptacle (TFR) etch insertion loss are defined in table J.4. The target $|S_{\text{DD}21}|$ is defined as the etch insertion loss of the test fixture from the calibrated reference plane of the test equipment, including any RF connector, up to but not including the reference plane of the plug under test or the reference plane of the receptacle under test. The reference plane of the plug under test is defined as the footprint, surface mount pads, or plated through holes of the plug under test. If the plug under test has no solder connections, then the reference plane of the plug under test is defined as the mating contacts of the plug under test. The reference plane of the receptacle under test is defined as the footprint, surface mount pads, or plated through holes of the receptacle under test.

Table J.4 — Recommended etch $|S_{DD21}|$ for a TFP or a TFR supporting rates of 22.5 Gbit/s

Characteristic ^a	Equation	Units	Range
Target $ S_{DD21} $ TFP	$0.003 - 0.15\sqrt{f} - 0.147f$	dB	$0.05 \text{ GHz} \leq f \leq \left(\frac{3}{4}\right)f_{\text{baud}}$
Maximum $ S_{DD21} $ TFP	$0.003 - 0.15\sqrt{f} - 0.147f + 0.4$	dB	$f = \frac{f_{\text{baud}}}{2}$
Minimum $ S_{DD21} $ TFP	$0.003 - 0.15\sqrt{f} - 0.147f - 0.4$	dB	$f = \frac{f_{\text{baud}}}{2}$
Target $ S_{DD21} $ TFR	$0.003 - 0.15\sqrt{f} - 0.147f$	dB	$0.05 \text{ GHz} \leq f \leq \left(\frac{3}{4}\right)f_{\text{baud}}$
Maximum $ S_{DD21} $ TFR	$0.003 - 0.15\sqrt{f} - 0.147f + 0.4$	dB	$f = \frac{f_{\text{baud}}}{2}$
Minimum $ S_{DD21} $ TFR	$0.003 - 0.15\sqrt{f} - 0.147f - 0.4$	dB	$f = \frac{f_{\text{baud}}}{2}$
^a See figure J.5.			

The TFP etch insertion loss or TFR etch insertion loss is measured using a calibration structure on the test fixture that represents two times the etch insertion loss of each respective test fixture including a single RF connector at the end of each etch (i.e., two times the insertion loss of the TFP or two times the insertion loss of the TFR). The TFP and TFR may have different amounts of etch insertion loss. The measured insertion loss of the calibration structure in units of dB is divided by two and compared with the minimum $|S_{DD21}|$ and the maximum $|S_{DD21}|$ limits defined in table J.4.

**Figure J.5 — Recommended etch $|S_{DD21}|$ for a TFP or a TFR supporting rates of 22.5 Gbit/s**

Annex K

(Informative)

SAS icons

A SAS icon should be included on or near all connectors used by devices compliant with both this standard and SPL-5. Icons indicating support of 22.5 Gbit/s are shown. If only speeds slower than 22.5 Gbit/s are supported, then contact the SCSI Trade Association for the appropriate icons.

NOTE 16 - Contact the SCSI Trade Association (see <https://www.scsita.org>) for versions of the SAS icons in various graphics formats.

Figure K.1 shows the primary SAS icon.

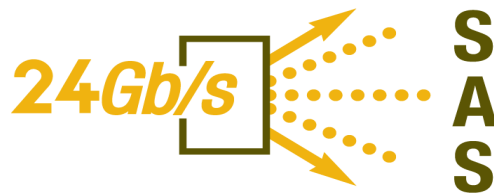


Figure K.1 — Primary SAS icon

Figure K.2 shows the MultiLink SAS icon.



Figure K.2 — MultiLink SAS icon

Annex L

(Informative)

Standards bodies contact information

Table L.1 shows standards bodies and their web sites.

Table L.1 — Standards bodies

Abbreviation	Standards body	Web site
ANSI ^{® a}	American National Standards Institute	https://www.ansi.org
DIN	German Institute for Standardization	https://www.din.de
IEC ^{® b}	International Electrotechnical Commission	https://www.iec.ch
IEEE ^{® c}	Institute of Electrical and Electronics Engineers	https://www.ieee.org
INCITS	InterNational Committee for Information Technology Standards	https://www.incits.org
ISO ^{® d}	International Organization for Standardization	https://www.iso.ch
ITIC	Information Technology Industry Council	https://www.itic.org
ITU-T	Telecommunication Standardization Sector of ITU	https://www.itu.int
JIS	Japanese Industrial Standards Committee	https://www.jisc.co.jp
OIF	Optical Internetworking Forum	https://www.oiforum.com
T10	INCITS Technical Committee T10 SCSI storage interfaces	https://www.t10.org
T11	INCITS/T11 Fibre Channel	https://standards.incits.org/apps/group_public/workgroup.php?wg_abbrev=t11
T13	INCITS Technical Committee T13 AT Attachment	https://www.t13.org
^a ANSI is a registered trademark of the American National Standards Institute. ^b IEC is a registered trademark of the International Electrotechnical Commission. ^c IEEE is a registered trademark of the Institute of Electrical Electronics Engineers, Inc. ^d ISO is a registered trademark of the International Organization for Standardization.		

Annex M

(Informative)

Bibliography

INCITS 367, *SCSI Paralell Interfdace - 5 (SPI-5)*.

INCITS 451, *Information technology - AT Attachment-8 ATA/ATAPI Architecture Model (ATA8-AAM)*.

INCITS 481, *Fiber Channel Protocol - 4 (FCP-4)*.

INCITS 502, *SCSI Primary Commands - 4 (SBC-4)*.

INCITS 503, *SCSI Stream Commands - 5 (SSC-5)*.

INCITS 506, *SCSI Block Commands - 4 (SBC-4)*.

INCITS 549, *Zoned ATA Comand Set - 2 (ZAC-2)*.

INCITS 550, *Zoned Block Commands - 2 (ZBC-2)*.INCITS 557, *SCSI/ATA Translation - 5 (SAT-5)*.

INCITS 558, *ATA/ATAPI Command Set - 5 (ACS-5)*.

John R. Barry, Edward A. Lee, and David G. Messerschmitt, *Digital Communication - Third Edition*. Kluwer Academic Publishing, 2003.